US010957679B2

(12) **United States Patent**
Lee et al.

(10) **Patent No.: US 10,957,679 B2**
(45) **Date of Patent: Mar. 23, 2021**

(54) **LOGIC DRIVE BASED ON STANDARDIZED COMMODITY PROGRAMMABLE LOGIC SEMICONDUCTOR IC CHIPS**

(71) Applicant: **iCometrue Company Ltd.**, Zhubei (TW)

(72) Inventors: **Jin-Yuan Lee**, Hsinchu (TW); **Mou-Shiung Lin**, Hsinchu (TW)

(73) Assignee: **iCometrue Company Ltd.**, Hsinchu County (TW)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 11 days.

(21) Appl. No.: **16/056,566**

(22) Filed: **Aug. 7, 2018**

(65) **Prior Publication Data**

US 2019/0051641 A1 Feb. 14, 2019

Related U.S. Application Data

(60) Provisional application No. 62/542,793, filed on Aug. 8, 2017, provisional application No. 62/630,369, filed
(Continued)

(51) **Int. Cl.**
H01L 25/18 (2006.01)
H01L 23/31 (2006.01)
(Continued)

(52) **U.S. Cl.**
CPC ***H01L 25/18*** (2013.01); ***H01L 21/563*** (2013.01); ***H01L 23/3128*** (2013.01);
(Continued)

(58) **Field of Classification Search**
CPC ... H01L 25/18; H01L 21/563; H01L 23/5226; H01L 23/528; H01L 24/13; H01L 25/105; H01L 25/50; H01L 24/11; H03K 19/17796
(Continued)

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,870,302 A 9/1989 Freeman et al.
5,272,368 A 12/1993 Turner et al.
(Continued)

FOREIGN PATENT DOCUMENTS

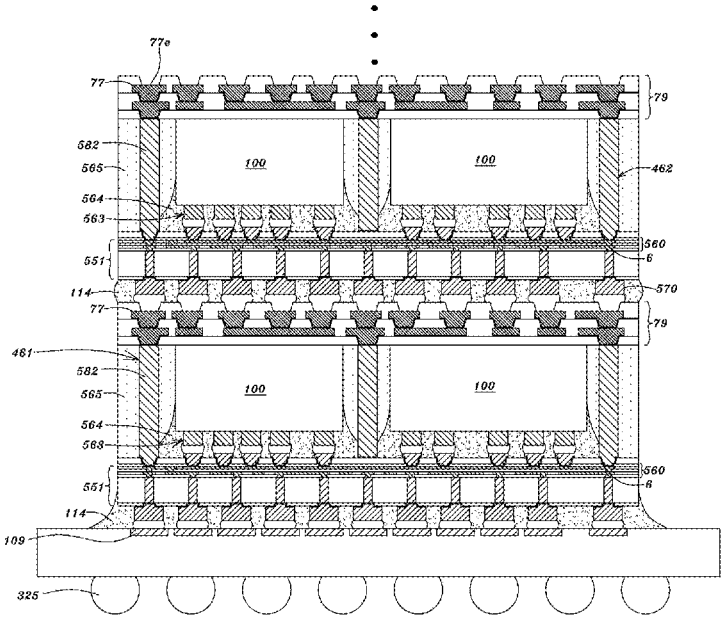
CN 103681367 3/2014
CN 105745752 7/2016
(Continued)

Primary Examiner — Thinh T Nguyen

(57) **ABSTRACT**

A chip package includes an interposer comprising a silicon substrate, multiple metal vias passing through the silicon substrate, a first interconnection metal layer over the silicon substrate, a second interconnection metal layer over the silicon substrate, and an insulating dielectric layer over the silicon substrate and between the first and second interconnection metal layers; a field-programmable-gate-array (FPGA) integrated-circuit (IC) chip over the interposer; multiple first metal bumps between the interposer and the FPGA IC chip; a first underfill between the interposer and the FPGA IC chip, wherein the first underfill encloses the first metal bumps; a non-volatile memory (NVM) IC chip over the interposer; multiple second metal bumps between the interposer and the NVM IC chip; and a second underfill between the interposer and the NVM IC chip, wherein the second underfill encloses the second metal bumps.

20 Claims, 200 Drawing Sheets



Related U.S. Application Data

on Feb. 14, 2018, provisional application No. 62/675,785, filed on May 24, 2018.

(51) **Int. Cl.**

H01L 23/532	(2006.01)
H03K 19/17736	(2020.01)
H03K 19/17796	(2020.01)
H01L 23/522	(2006.01)
H01L 23/498	(2006.01)
H01L 23/00	(2006.01)
H01L 23/528	(2006.01)
H01L 21/56	(2006.01)
H01L 27/118	(2006.01)
H01L 23/14	(2006.01)

(52) **U.S. Cl.**

CPC ***H01L 23/49827*** (2013.01); ***H01L 23/528*** (2013.01); ***H01L 23/5226*** (2013.01); ***H01L 24/17*** (2013.01); ***H03K 19/17736*** (2013.01); ***H03K 19/17796*** (2013.01); *H01L 21/561* (2013.01); *H01L 23/145* (2013.01); *H01L 23/147* (2013.01); *H01L 23/53238* (2013.01); *H01L 27/11803* (2013.01); *H01L 27/11807* (2013.01); *H01L 2924/1431* (2013.01); *H01L 2924/1434* (2013.01)

(58) **Field of Classification Search**

USPC 257/737, 693.686, 777, 778, 723; 538/108, 109; 716/52, 100; 438/108, 438/109

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,587,603	A	12/1996	Kowshik	
6,020,633	A *	1/2000	Erikson	H01L 25/105 257/723
6,356,478	B1	3/2002	McCollum	
6,388,466	B1	5/2002	Wittig et al.	
6,687,167	B2	2/2004	Guaitini et al.	
6,812,086	B2	11/2004	Cai	
6,828,823	B1	12/2004	Tsui et al.	
6,943,580	B2	9/2005	Lewis et al.	
6,998,872	B1	2/2006	Chirania et al.	
7,030,652	B1	4/2006	Lewis et al.	
7,061,271	B1	6/2006	Young et al.	
7,193,433	B1	3/2007	Young	
7,219,237	B1	5/2007	Trimberger	
7,366,306	B1	4/2008	Trimberger	
7,385,417	B1	6/2008	Agrawal et al.	
7,550,994	B1	6/2009	Camarota et al.	
7,598,555	B1	10/2009	Papworth Parkin	
7,653,891	B1	1/2010	Anderson et al.	
7,747,025	B1	6/2010	Trimberger	
7,853,799	B1	12/2010	Trimberger	
7,933,140	B2	4/2011	Wang et al.	
7,944,231	B2	5/2011	Javerliac	
7,973,556	B1	7/2011	Noguera Serra et al.	
8,064,224	B2	11/2011	Mahajan et al.	
8,243,527	B2	8/2012	Hung et al.	
8,354,297	B2	1/2013	Pagaila et al.	
8,378,407	B2	2/2013	Audzeyeu et al.	
8,531,032	B2	9/2013	Yu et al.	
8,546,955	B1 *	10/2013	Wu	H01L 23/5384 257/777
8,592,886	B2	11/2013	Hsu et al.	
8,742,579	B2	6/2014	Pagaila et al.	
8,786,060	B2	7/2014	Yen et al.	
8,796,137	B2	8/2014	Pagaila et al.	
8,866,292	B2	10/2014	Beer et al.	
8,872,349	B2	10/2014	Chiu et al.	
8,878,360	B2	11/2014	Meyer et al.	
8,883,561	B2	11/2014	Park et al.	
8,885,334	B1 *	11/2014	Baxter	G06F 13/1684 361/679.31
8,895,440	B2	11/2014	Choi et al.	
8,912,822	B2	12/2014	Yasuda et al.	
8,916,421	B2	12/2014	Gong et al.	
8,941,230	B2	1/2015	Kyozuka et al.	
8,952,489	B2	2/2015	Elian et al.	
8,952,521	B2	2/2015	Wojnowski et al.	
8,987,918	B2	3/2015	Razdan et al.	
8,993,377	B2	3/2015	Koo et al.	
9,003,221	B1 *	7/2015	Abugharbieh et al.	G06F 1/04 713/503
9,082,806	B2	7/2015	Lin et al.	
9,106,229	B1	8/2015	Hutton et al.	
9,135,185	B2	9/2015	Loh et al.	
9,147,638	B2	9/2015	Liu et al.	
9,224,647	B2	12/2015	Koo et al.	
9,225,512	B1	12/2015	Trimberger	
9,263,370	B2	2/2016	Shenoy et al.	
9,281,292	B2	3/2016	Hu et al.	
9,324,672	B2	4/2016	Pagaila et al.	
9,331,060	B2	5/2016	Otremba et al.	
9,343,442	B2	5/2016	Chen et al.	
9,349,713	B2	5/2016	Kim et al.	
9,362,187	B2	6/2016	Ossimitz	
9,385,006	B2	7/2016	Lin	
9,385,009	B2	7/2016	Lin et al.	
9,385,105	B2	7/2016	Meyer et al.	
9,396,998	B2	7/2016	Kurita et al.	
9,397,050	B2	7/2016	Shin et al.	
9,406,619	B2	8/2016	Pagaila et al.	
9,406,658	B2	8/2016	Lee et al.	
9,437,260	B2	9/2016	Prenat et al.	
9,449,930	B2	9/2016	Kim et al.	
9,508,626	B2	11/2016	Pagaila et al.	
9,524,955	B2	12/2016	Huang et al.	
9,543,276	B2	1/2017	Jee et al.	
9,583,431	B1	2/2017	Rahman et al.	
9,593,009	B2	3/2017	Fuergut et al.	
9,627,365	B1	4/2017	Yu et al.	
9,640,259	B2	5/2017	Li et al.	
9,679,863	B2	6/2017	Lin et al.	
9,704,843	B2	7/2017	Kilger et al.	
9,735,113	B2	8/2017	Chi et al.	
9,763,329	B1	9/2017	Mason et al.	
9,773,757	B2	9/2017	Yu et al.	
9,806,058	B2	10/2017	Wei et al.	
9,812,337	B2	11/2017	Chen et al.	
9,818,720	B2	11/2017	Wei et al.	
9,831,148	B2	11/2017	Yu et al.	
9,859,896	B1	1/2018	Gaide et al.	
9,881,850	B2	1/2018	Yu et al.	
9,887,206	B2	2/2018	Su et al.	
9,899,248	B2	2/2018	Yu et al.	
9,899,355	B2	2/2018	Yuan et al.	
9,935,113	B2	4/2018	Wu et al.	
9,966,325	B2	5/2018	Beyne	
9,997,464	B2	6/2018	Hsieh et al.	
10,015,916	B1 *	7/2018	Karp	
10,026,681	B2	7/2018	Ko et al.	
10,033,383	B1	7/2018	Richter et al.	
10,037,963	B2	7/2018	Chen et al.	
10,043,768	B2	8/2018	Meyer et al.	
10,056,351	B2	8/2018	Yu et al.	
10,056,907	B1	8/2018	Asnaashari et al.	
10,062,648	B2	8/2018	Hsieh et al.	
10,062,651	B2	8/2018	Liang et al.	
10,079,243	B2	9/2018	Ramkumar	
10,109,588	B2	10/2018	Jeong et al.	
10,109,617	B2	10/2018	Lee et al.	
10,153,222	B2	12/2018	Yu et al.	
10,153,239	B2	12/2018	Wang et al.	
10,157,828	B2	12/2018	Hsu et al.	
10,157,849	B2	12/2018	Huang et al.	
10,163,802	B2	12/2018	Lin et al.	
10,204,684	B2	2/2019	Widjaja	
10,211,070	B2	2/2019	Lee et al.	

(56) **References Cited**

U.S. PATENT DOCUMENTS

10,211,182	B2	2/2019	Meyer et al.	
10,256,219	B2	4/2019	Chew	
10,333,623	B1	6/2019	Liao et al.	
10,340,249	B1	7/2019	Yu et al.	
10,373,885	B2	8/2019	Yu et al.	
10,419,001	B2	9/2019	Jo et al.	
10,431,536	B2	10/2019	Kim et al.	
10,447,274	B2	10/2019	Lee et al.	
10,504,835	B1	12/2019	Wang et al.	
10,510,634	B2	12/2019	Lin et al.	
10,510,650	B2	12/2019	Yu et al.	
10,522,449	B2	12/2019	Chen et al.	
10,541,227	B2	1/2020	Yeh et al.	
10,541,228	B2	1/2020	Chen et al.	
10,622,321	B2	4/2020	Yu et al.	
2001/0045844	A1	11/2001	New et al.	
2003/0122578	A1	7/2003	Masui et al.	
2004/0041584	A1	3/2004	Sunaga et al.	
2004/0145850	A1	7/2004	Fukumoto et al.	
2004/0222817	A1	11/2004	Madurawe	
2005/0218929	A1	10/2005	Wang et al.	
2007/0166912	A1	7/2007	Fenigstein et al.	
2007/0279987	A1	12/2007	Fang et al.	
2009/0114971	A1	5/2009	Cai et al.	
2009/0267238	A1	10/2009	Joseph	
2010/0039136	A1	2/2010	Chua-Eoan et al.	
2010/0157669	A1	6/2010	Audzeyeu et al.	
2010/0283085	A1	11/2010	Bemanian et al.	
2011/0221470	A1	9/2011	Javerliac et al.	
2012/0217549	A1	8/2012	Widjaja	
2013/0257477	A1	10/2013	Yasuda et al.	
2014/0017882	A1	1/2014	Lei et al.	
2014/0070403	A1	3/2014	Pan et al.	
2014/0131858	A1*	5/2014	Pan et al.	H01L 24/18 257/737
2014/0210097	A1	7/2014	Chen et al.	
2014/0254232	A1	9/2014	Wu	
2014/0302659	A1	10/2014	Phatak et al.	
2015/0008957	A1	1/2015	Olgiati et al.	
2015/0014844	A1*	1/2015	Wu et al.	H01L 21/82 257/737
2015/0116965	A1	4/2015	Kim et al.	
2015/0327367	A1	11/2015	Shen et al.	
2016/0118390	A1	4/2016	Liaw	
2016/0133571	A1	5/2016	Lee et al.	
2016/0173101	A1	6/2016	Gao et al.	
2016/0190113	A1	6/2016	Sharan et al.	
2016/0217835	A1	7/2016	Blott et al.	
2016/0351626	A1	12/2016	McCollum et al.	
2016/0372449	A1	12/2016	Stefan et al.	
2017/0301650	A1	10/2017	Yu et al.	
2018/0053730	A1	2/2018	Shao et al.	
2018/0061742	A1	3/2018	Ananiev et al.	
2018/0076179	A1	3/2018	Hsu et al.	
2018/0150667	A1	5/2018	Yu et al.	
2018/0151477	A1	5/2018	Yu et al.	
2018/0151501	A1	5/2018	Yu et al.	
2018/0158746	A1	6/2018	Lin	
2018/0165396	A1	6/2018	Lin et al.	
2018/0174865	A1	6/2018	Yu et al.	
2018/0204810	A1	7/2018	Yu et al.	
2018/0204828	A1	7/2018	Yu et al.	
2018/0226349	A1	8/2018	Yu et al.	
2018/0247905	A1	8/2018	Yu et al.	
2018/0269188	A1	9/2018	Yu et al.	
2018/0275193	A1	9/2018	Rouge et al.	
2018/0284186	A1	10/2018	Chadha	
2018/0286776	A1	10/2018	Yu et al.	
2018/0301351	A1	10/2018	Yu et al.	
2018/0301376	A1	10/2018	Shih et al.	
2018/0350629	A1	12/2018	Liu et al.	
2018/0350763	A1	12/2018	Yu et al.	
2018/0358312	A1	12/2018	Yu et al.	
2018/0374824	A1	12/2018	Yu et al.	
2019/0013276	A1*	1/2019	Lee et al.	H01L 23/5398
2019/0019756	A1	1/2019	Yu et al.	
2019/0020343	A1	1/2019	Lee et al.	
2019/0051641	A1	2/2019	Lee et al.	
2019/0057932	A1	2/2019	Wu et al.	
2019/0097304	A1	3/2019	Hsiao et al.	
2019/0221547	A1	7/2019	Drab et al.	
2019/0238134	A1	8/2019	Lee et al.	
2019/0238135	A1	8/2019	Lin et al.	
2019/0245543	A1	8/2019	Lee et al.	
2019/0253056	A1	8/2019	Lin et al.	
2019/0304803	A1	10/2019	Hu et al.	
2019/0333871	A1	10/2019	Chen et al.	
2019/0347790	A1	11/2019	Lee et al.	
2019/0363715	A1	11/2019	Lee et al.	
2019/0372574	A1	12/2019	Lee et al.	
2020/0058617	A1	2/2020	Wu et al.	

FOREIGN PATENT DOCUMENTS

WO	WO2000036748	A1	6/2000
WO	WO2005010976	A1	2/2005
WO	WO2016160063	A1	10/2016

* cited by examiner

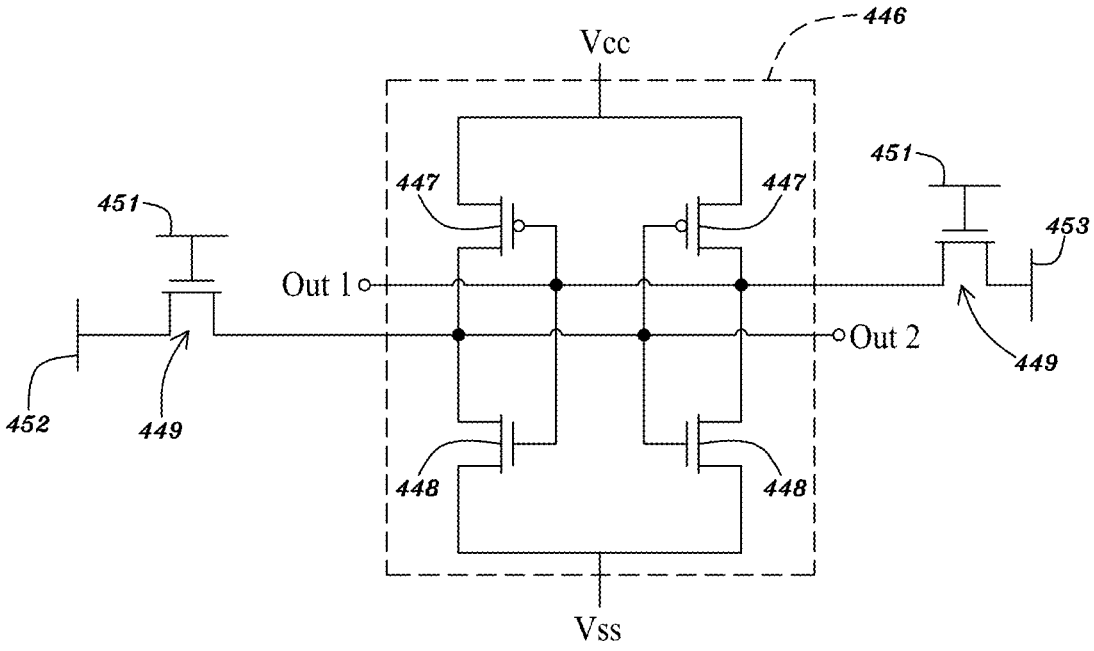

Vcc
446
451
447
447
451
453
Out 1
Out 2
449
452
449
448
448
Vss
398

Fig. 1A

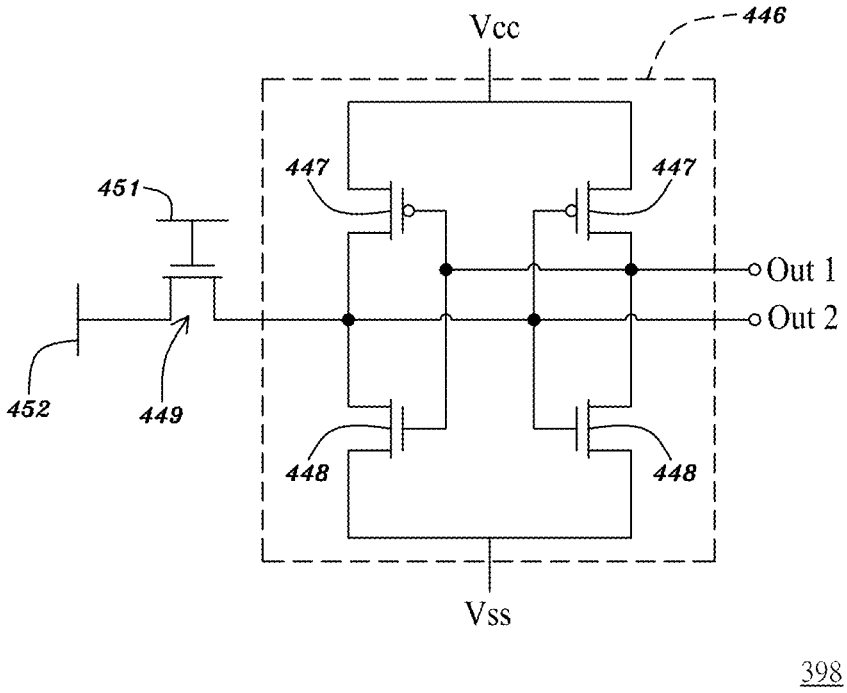

Vcc
446
447
447
451
Out 1
Out 2
452
449
448
448
Vss
398

Fig. 1B

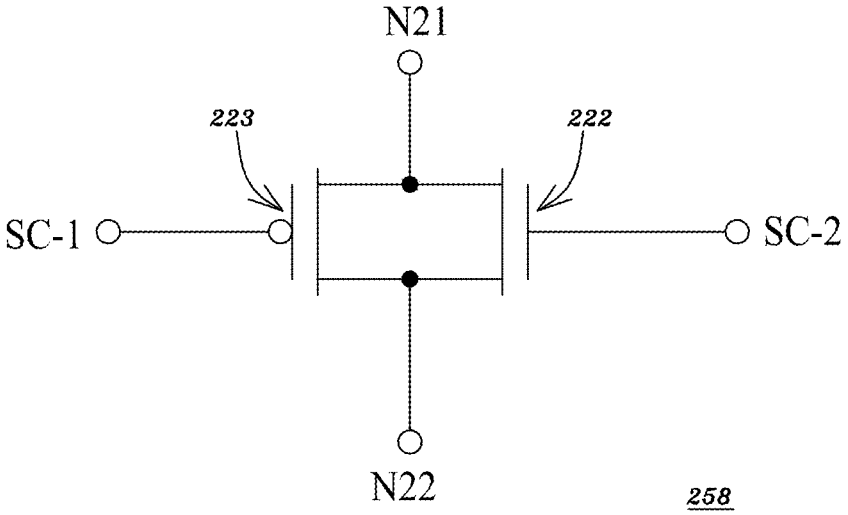


Fig. 2A

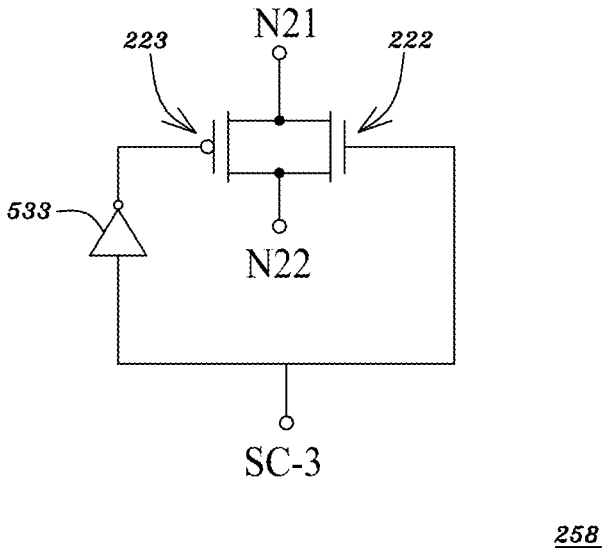


Fig. 2B

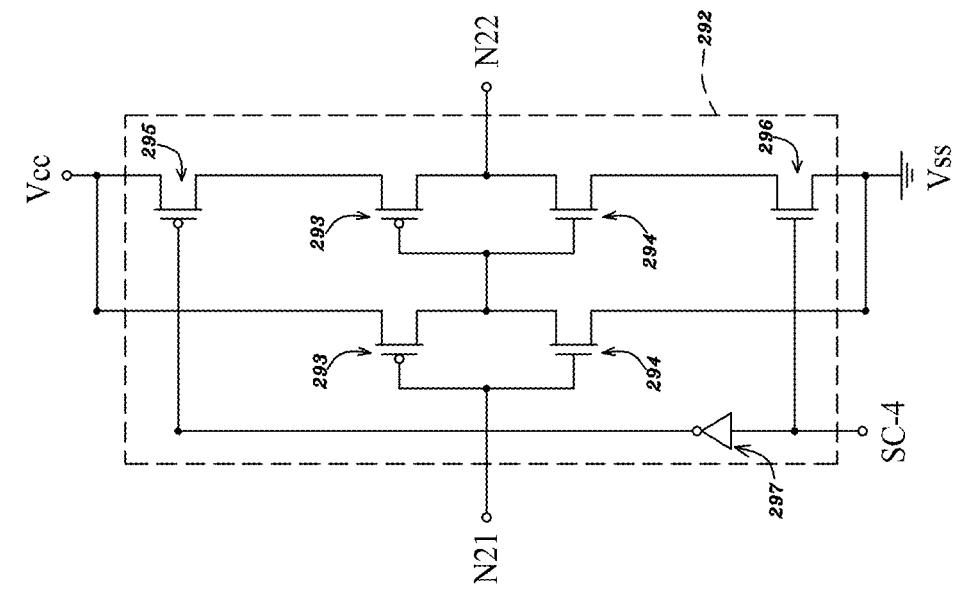

N22
292
258
Vcc
295
296
Vss
293
294
293
294
SC-4
297
N21

Fig. 2D

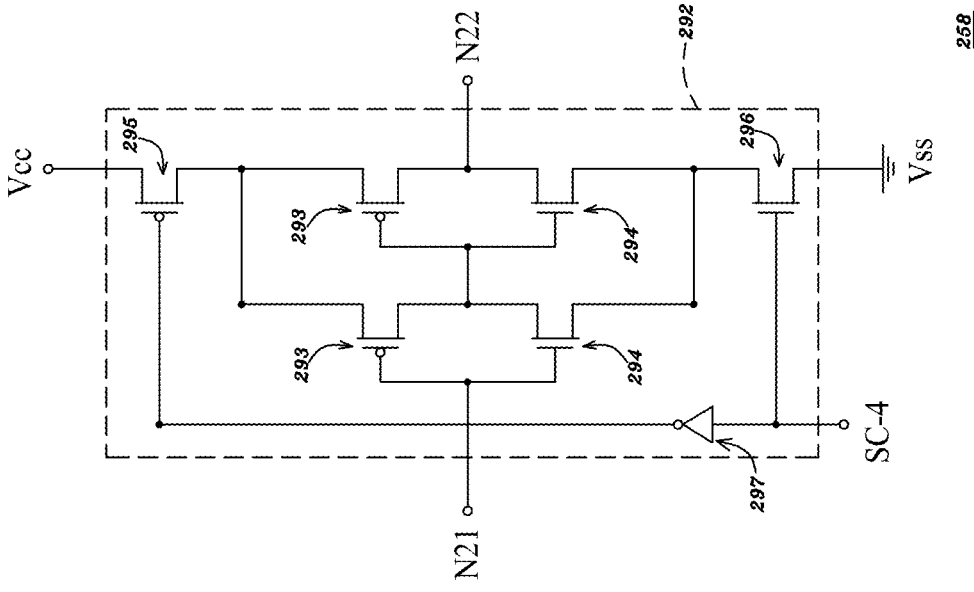

N22
292
258
Vcc
295
296
Vss
293
294
293
294
SC-4
297
N21

Fig. 2C

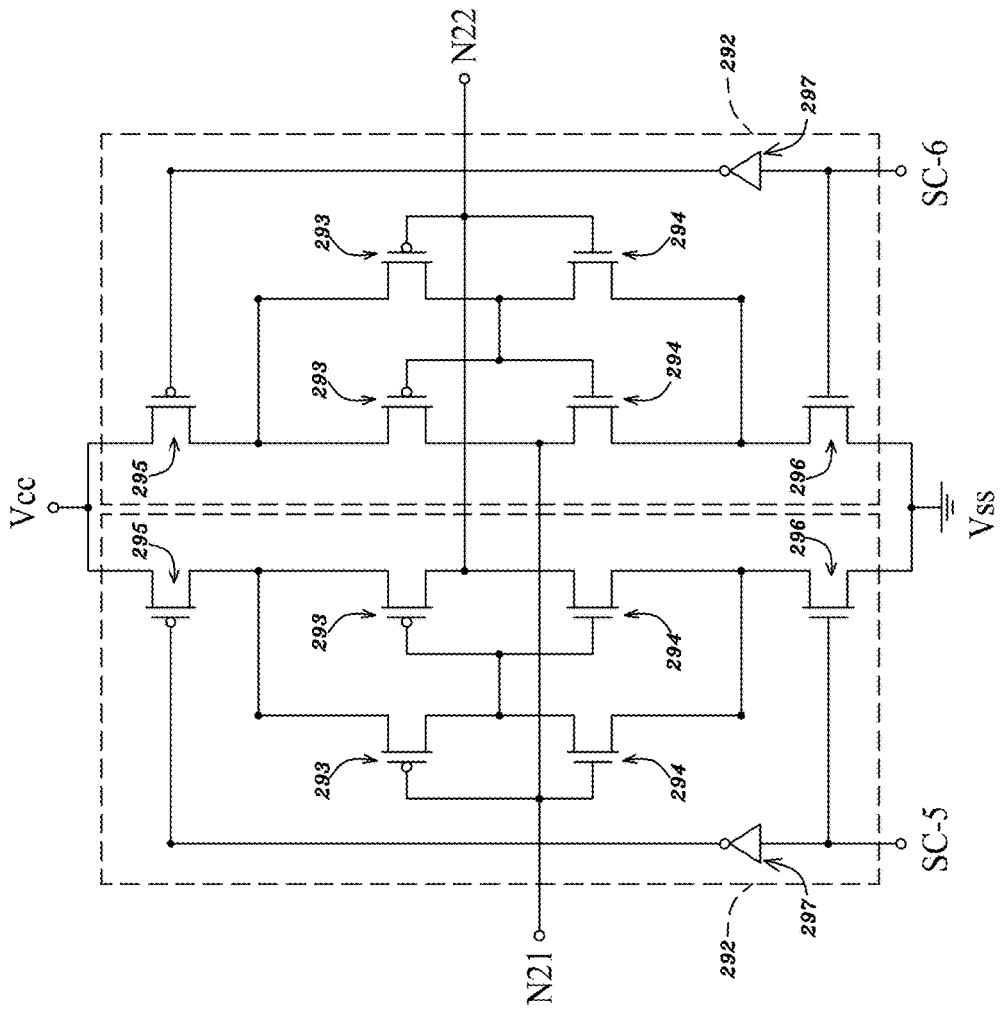

N22
292
297
SC-6
293
294
293
294
Vcc
295
296
Vss
295
296
293
294
293
294
SC-5
297
292
N21
258

Fig. 2E

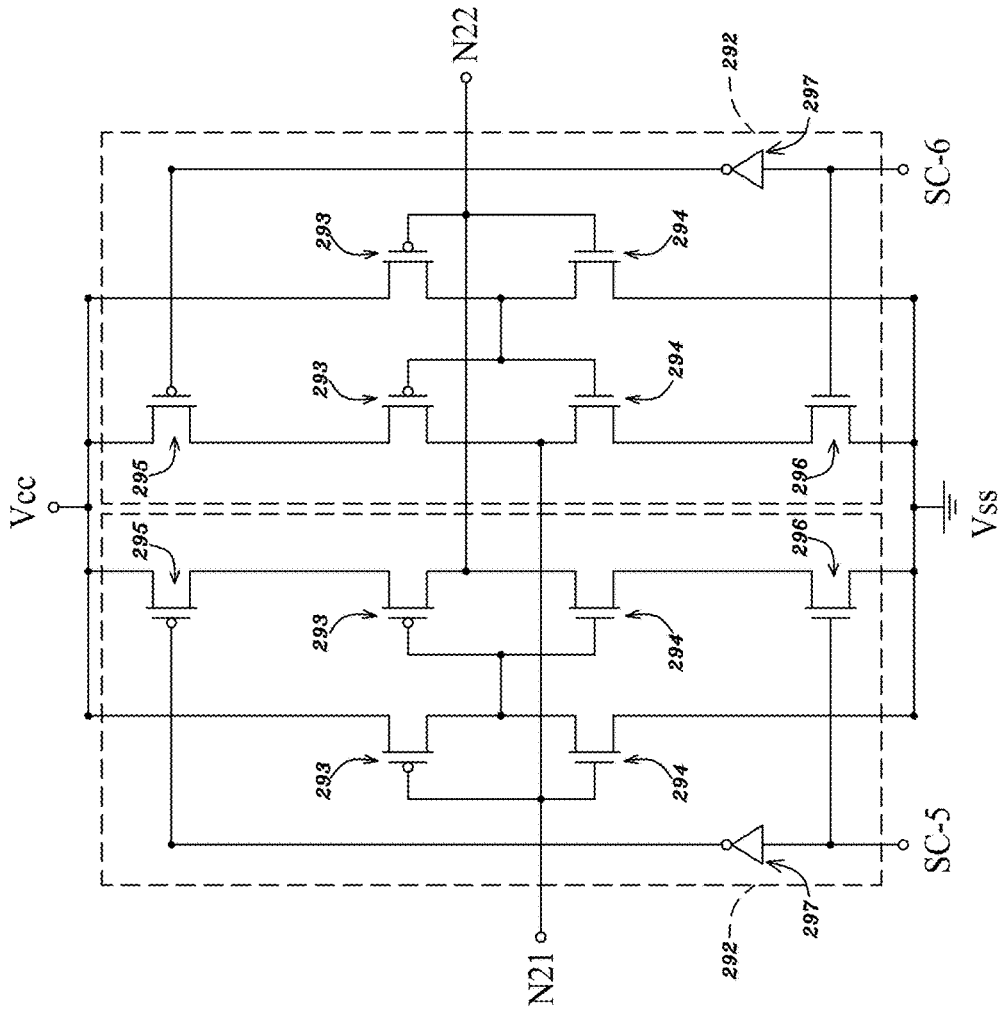


Fig. 2F

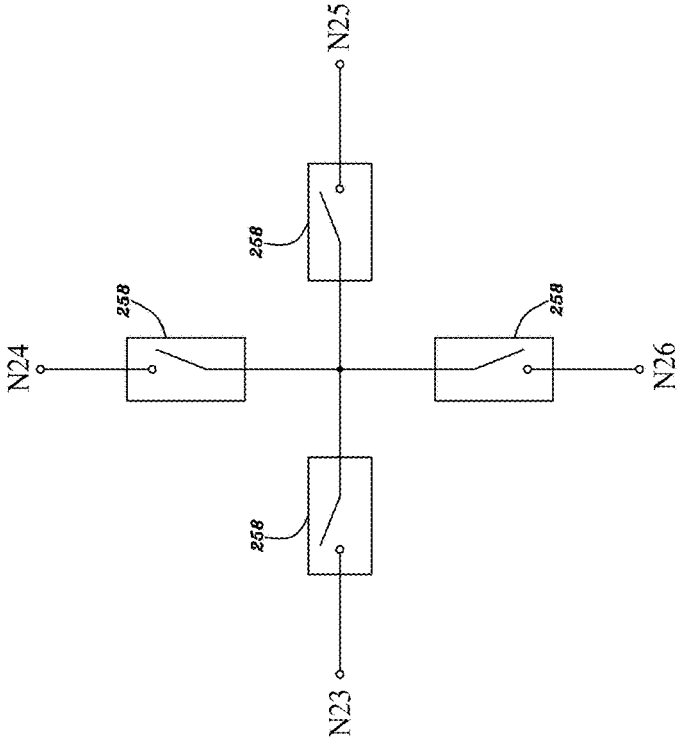


Fig. 3B

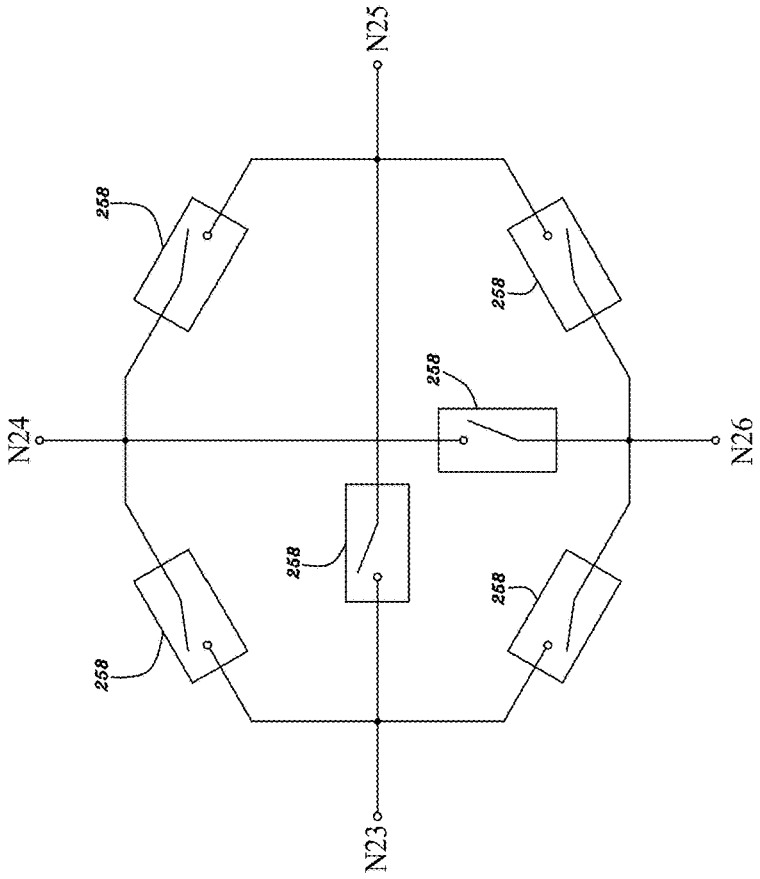


Fig. 3A

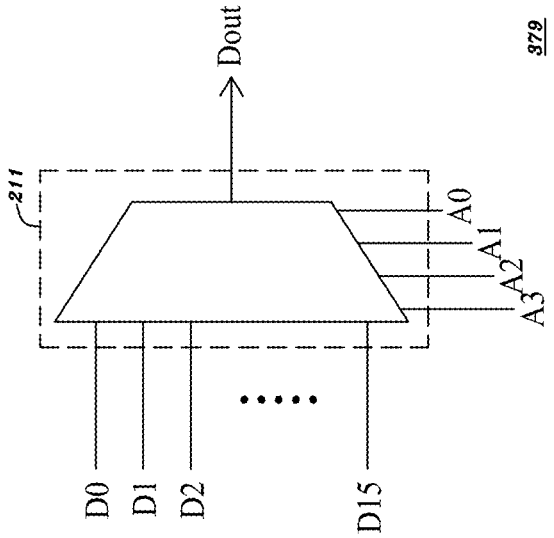

Dout
379
211
A0
A1
A2
A3
D0
D1
D2
D15

Fig. 3D

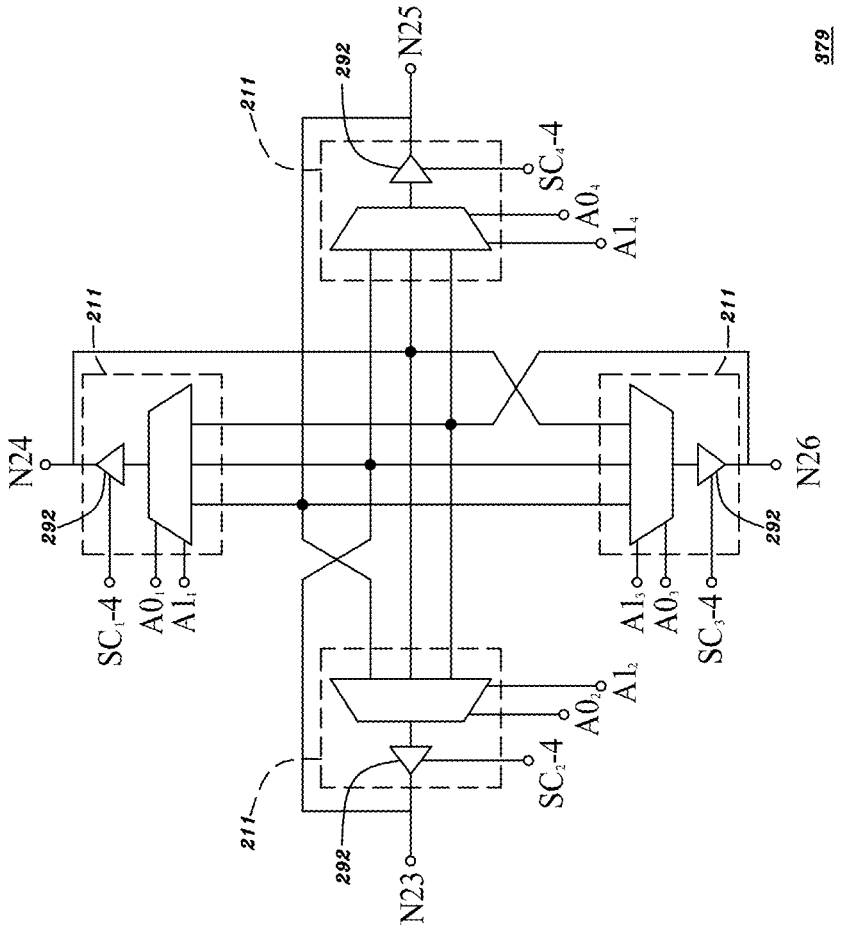

379
211
292
N25
SC4-4
A04
A14
211
211
N24
292
SC1-4
A01
A11
A13
A03
SC3-4
292
N26
211
A12
A02
SC2-4
211
292
N23

Fig. 3C

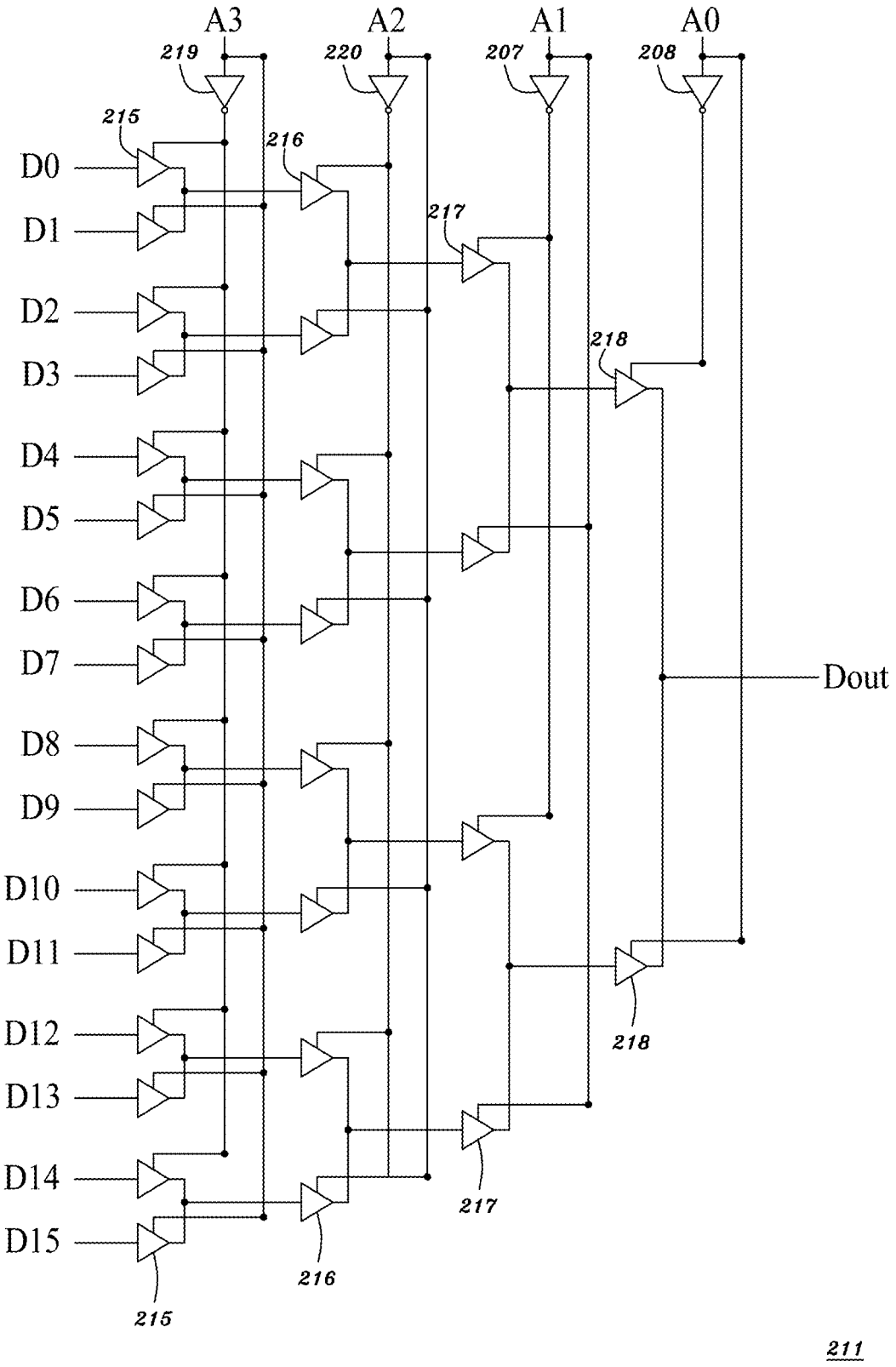

A3
A2
A1
A0
219
220
207
208
215
216
217
218
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15
Dout
211

Fig. 4A

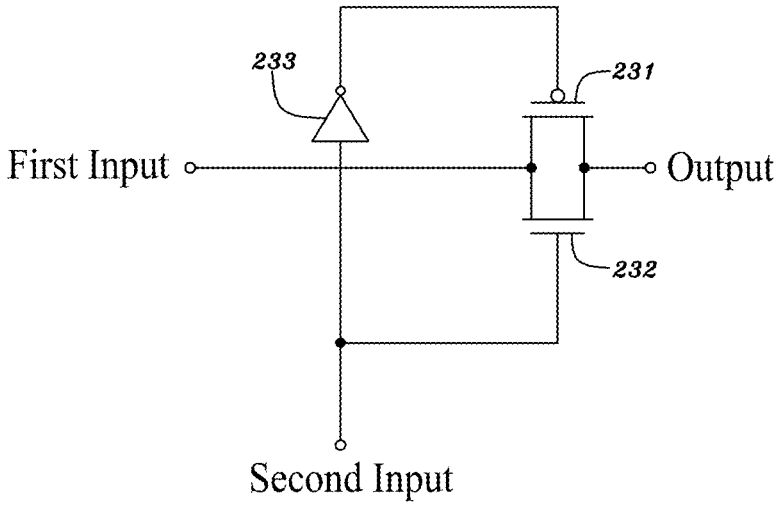


Fig. 4B

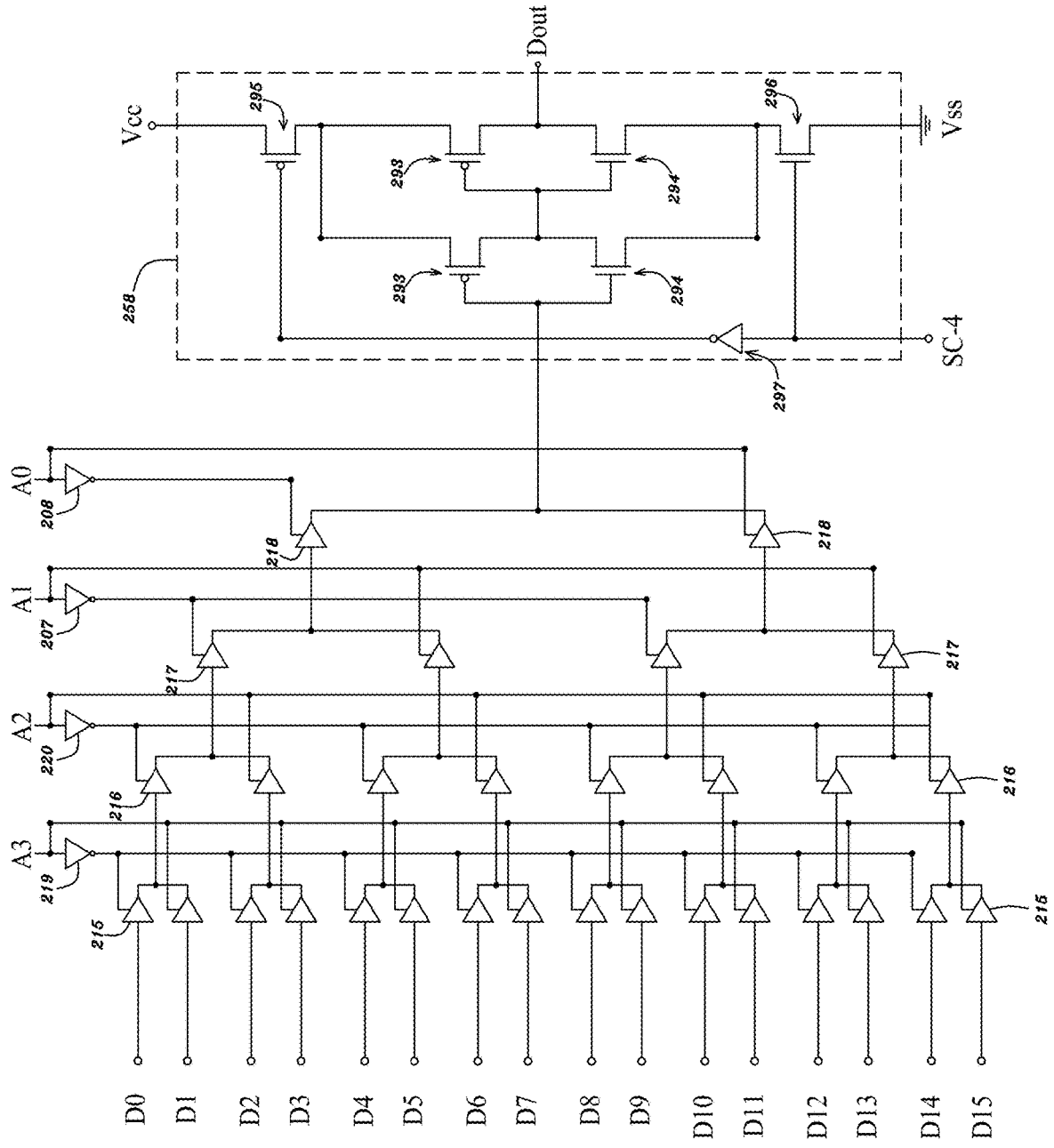

211
Dout
Vcc
Vss
SC-4
295
296
298
294
293
294
258
297
A0
208
218
218
A1
207
217
217
A2
220
216
216
A3
219
215
215
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15

Fig. 4C

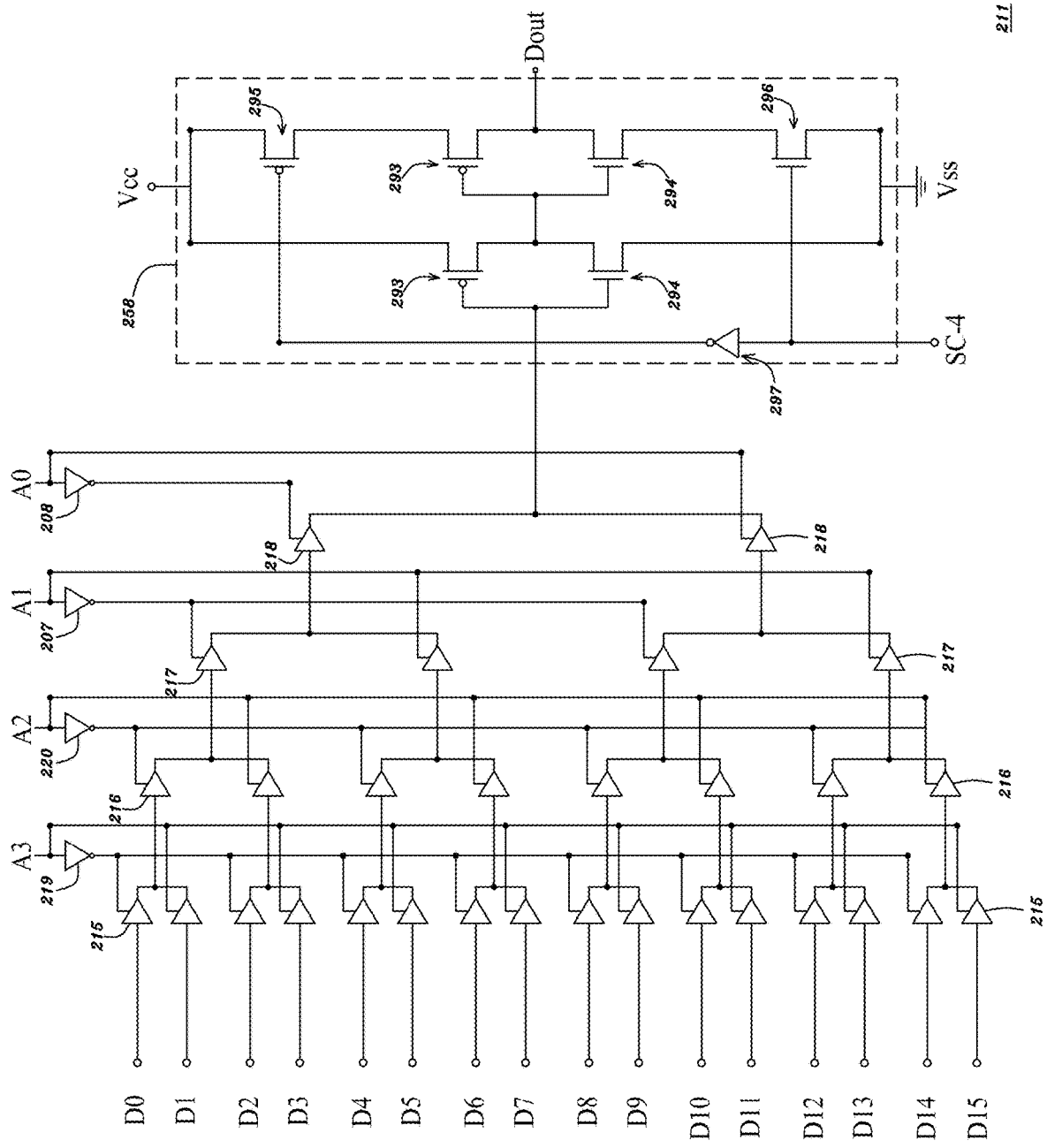

Dout
211
Vcc
Vss
SC-4
295
296
293
294
297
258
A0
A1
A2
A3
208
207
220
219
218
217
216
215
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15

Fig. 4D

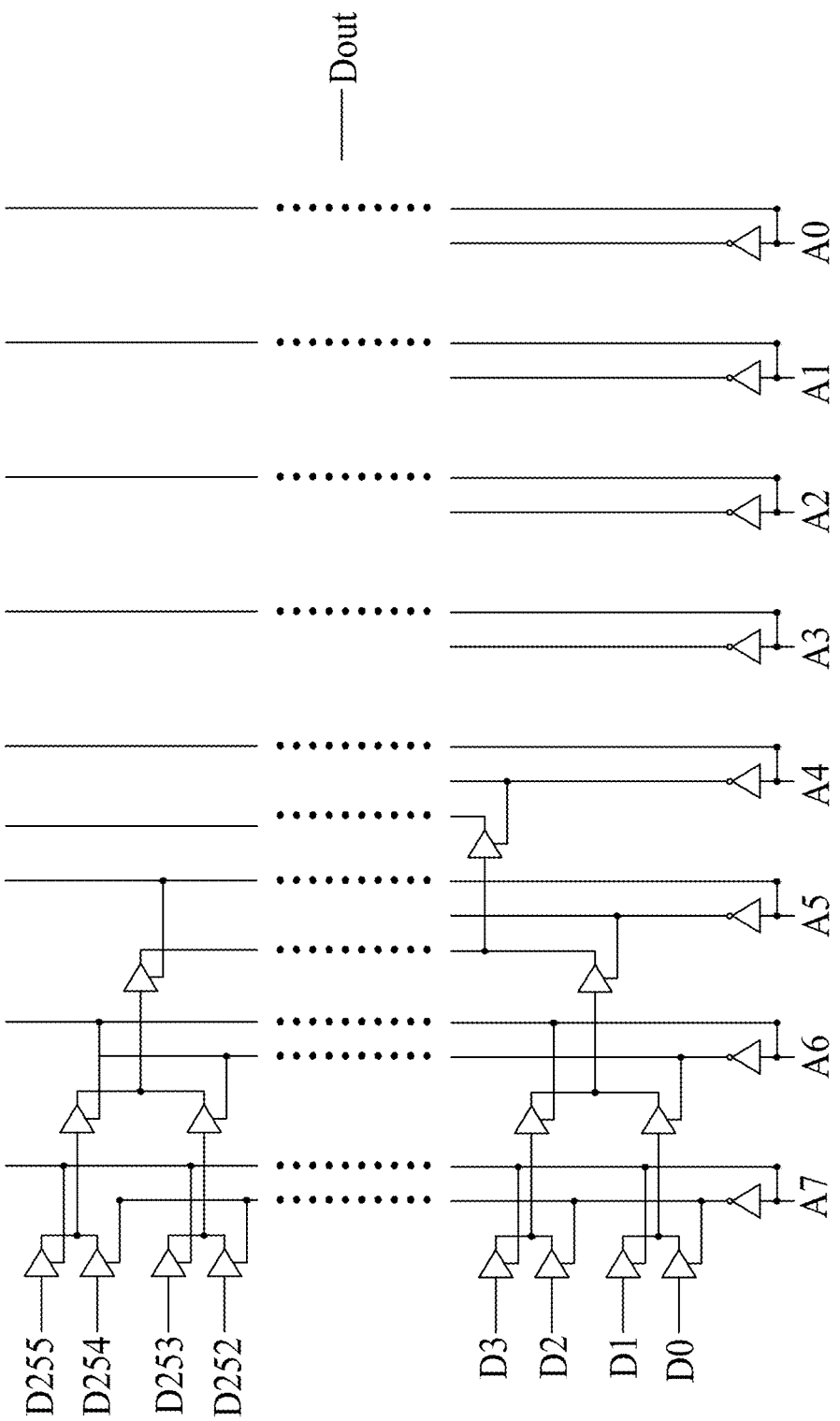


Fig. 4E

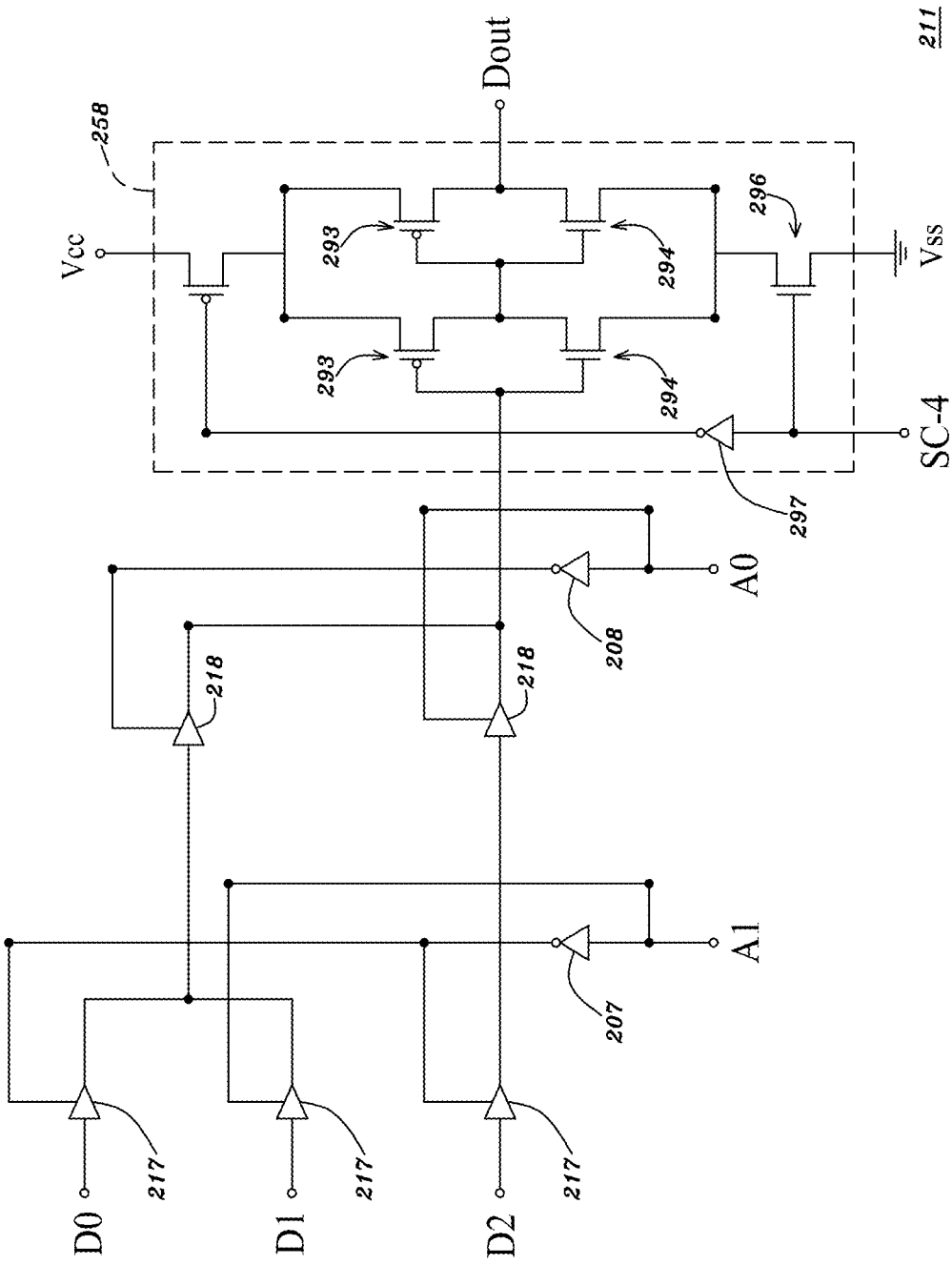

211
Dout
258
Vcc
293
294
296
Vss
293
294
SC-4
297
A0
208
218
218
A1
207
217
217
217
D0
D1
D2

Fig. 4F

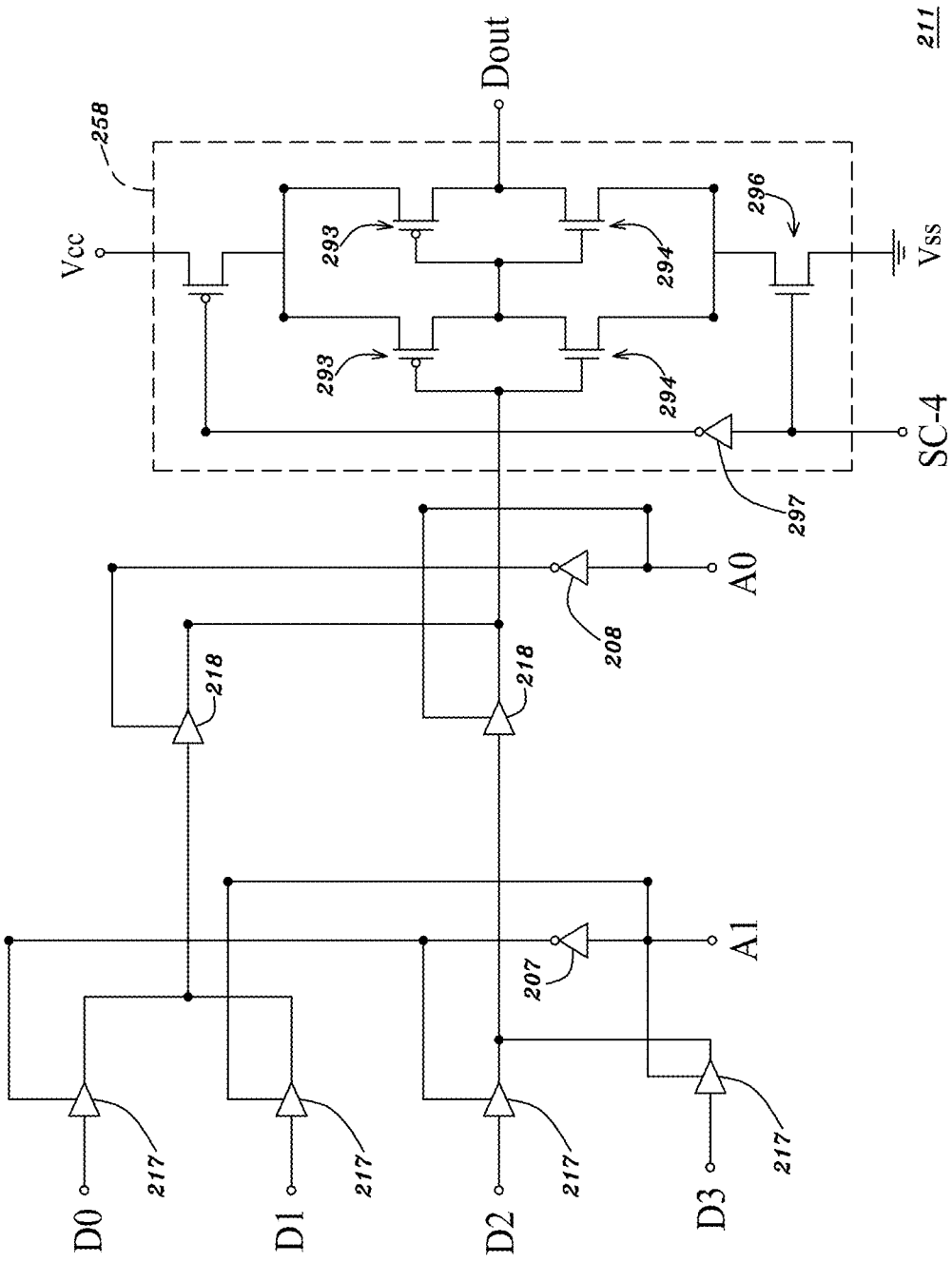

211
Dout
258
Vcc
293
294
296
Vss
293
294
SC-4
297
A0
208
218
218
A1
207
217
217
217
217
D0
D1
D2
D3

Fig. 4G

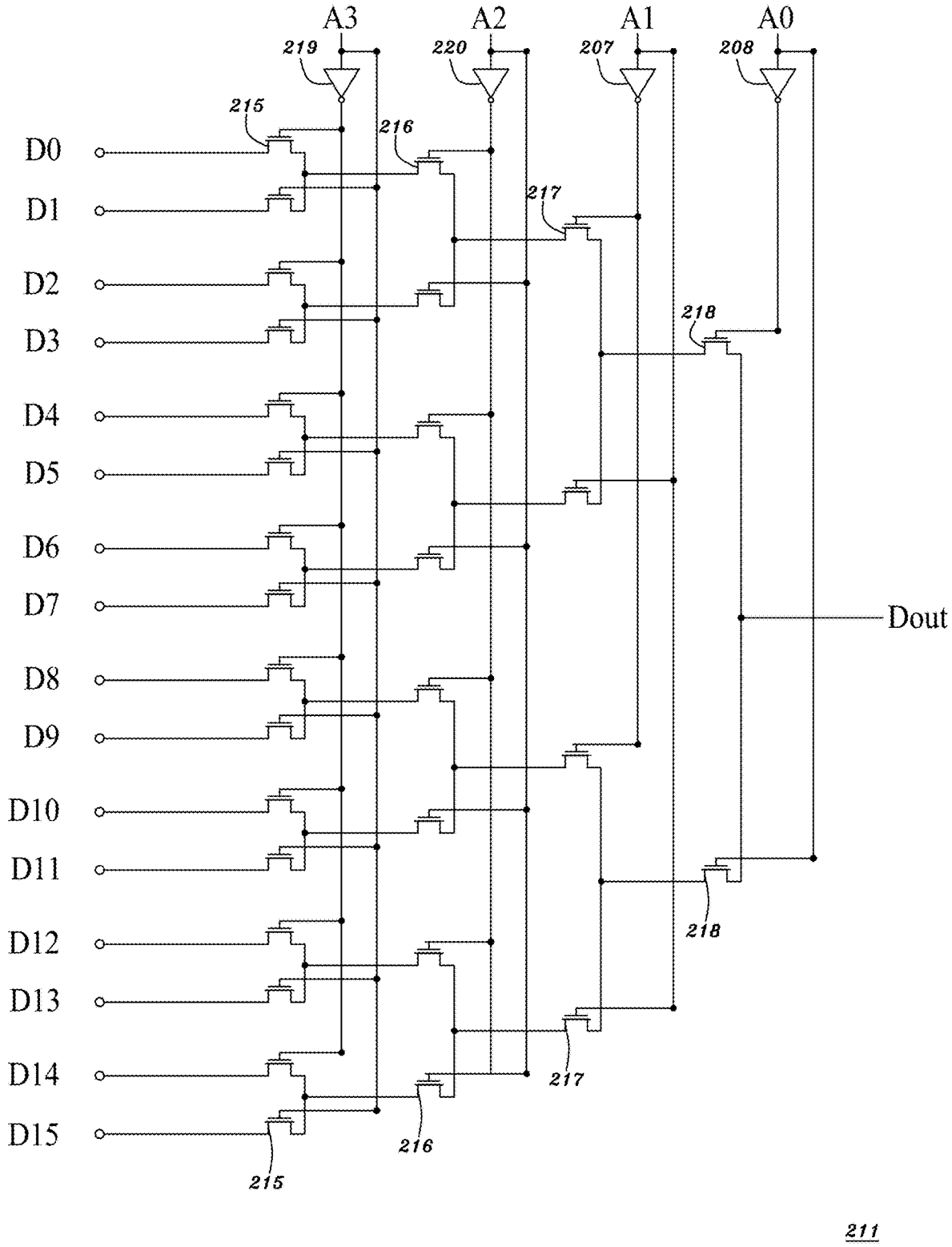
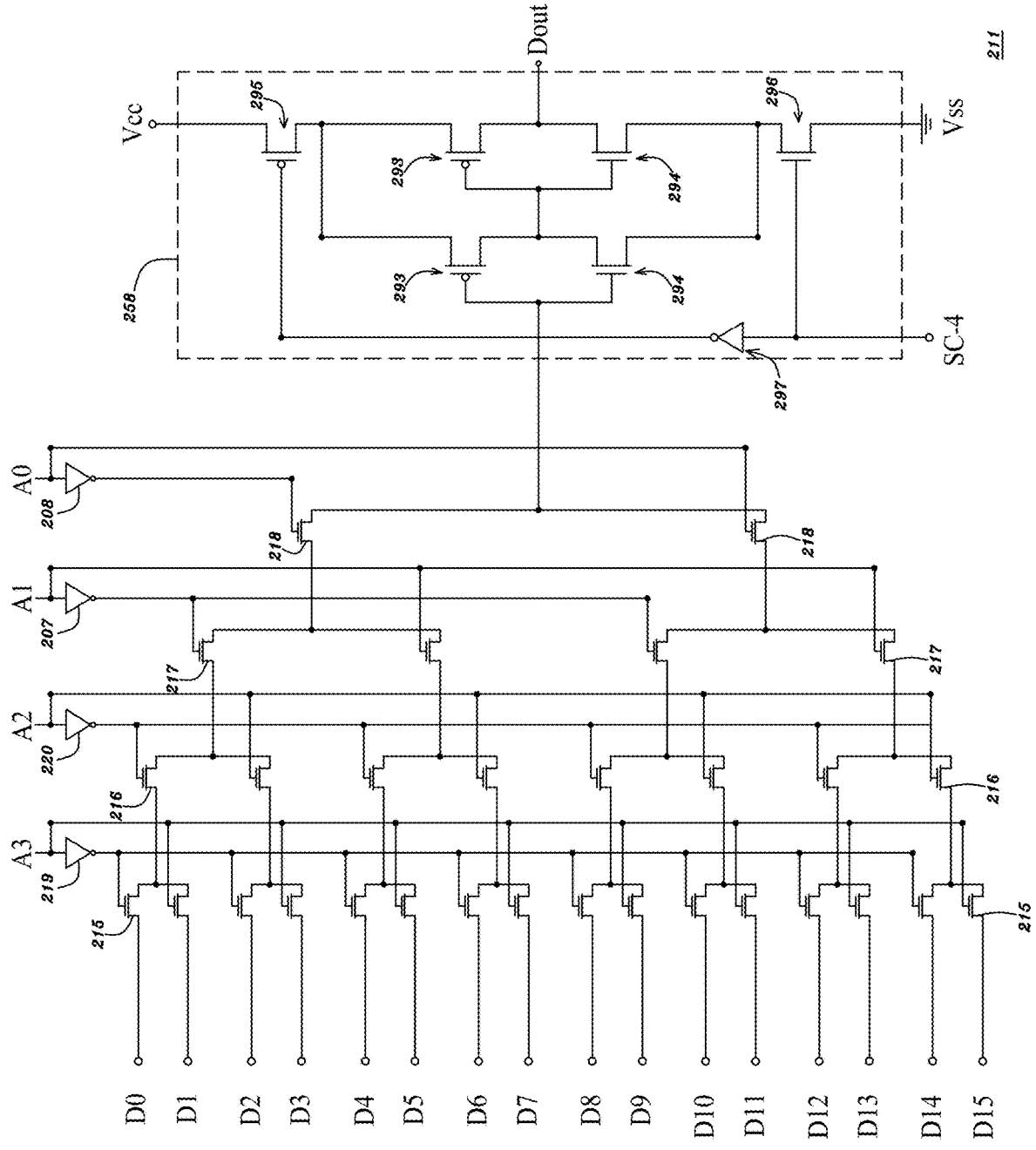

A3
A2
A1
A0
219
220
207
208
215
216
217
218
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15
Dout
211

Fig. 4H

Fig. 4I


Dout
211
Vcc
Vss
SC-4
295
296
293
294
297
258
A0
A1
A2
A3
208
207
220
219
218
217
216
215
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15

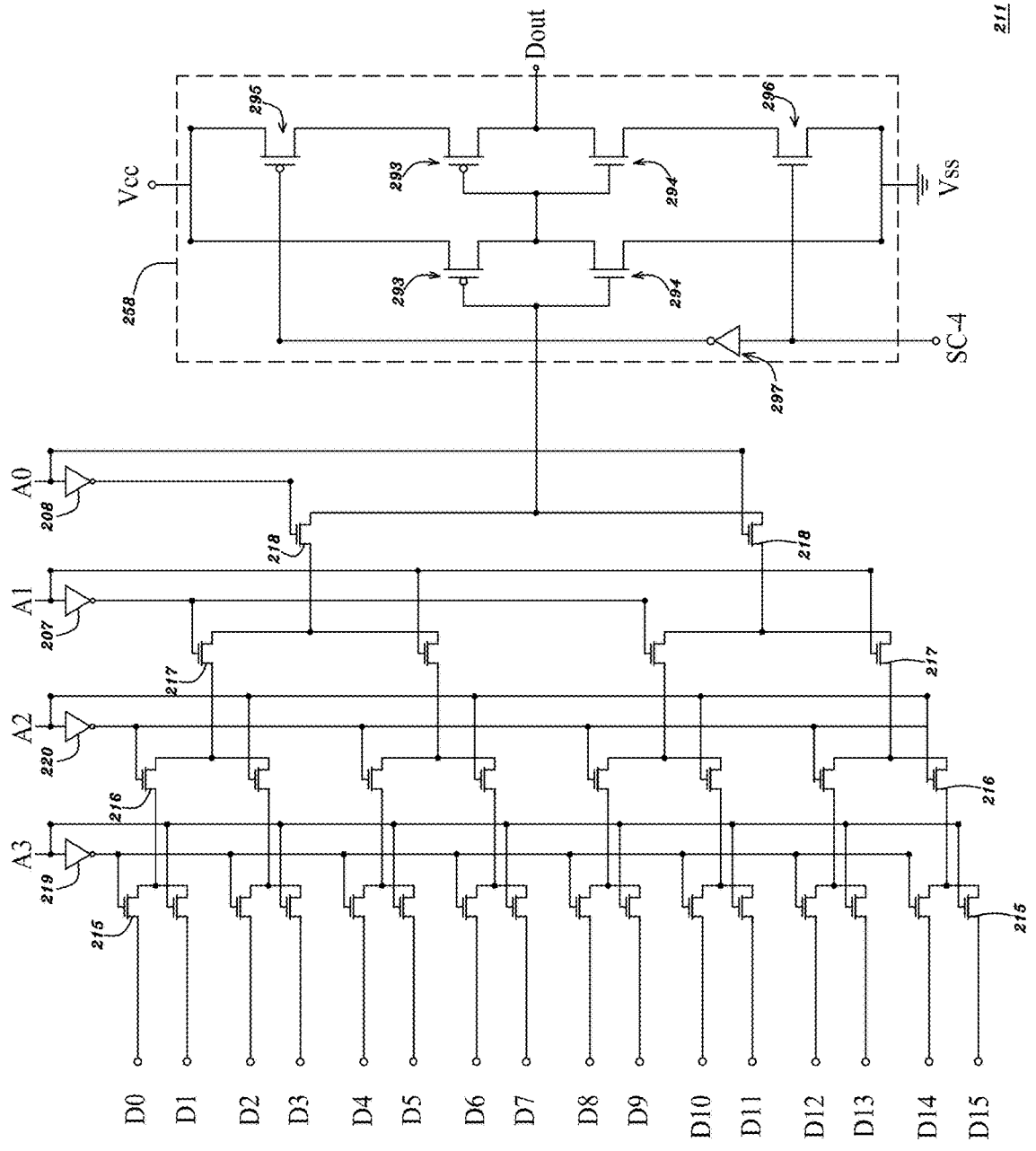

Dout
211
Vcc
Vss
SC-4
258
295
296
293
294
297
A0
A1
A2
A3
208
207
220
219
218
217
216
215
D0
D1
D2
D3
D4
D5
D6
D7
D8
D9
D10
D11
D12
D13
D14
D15

Fig. 4J

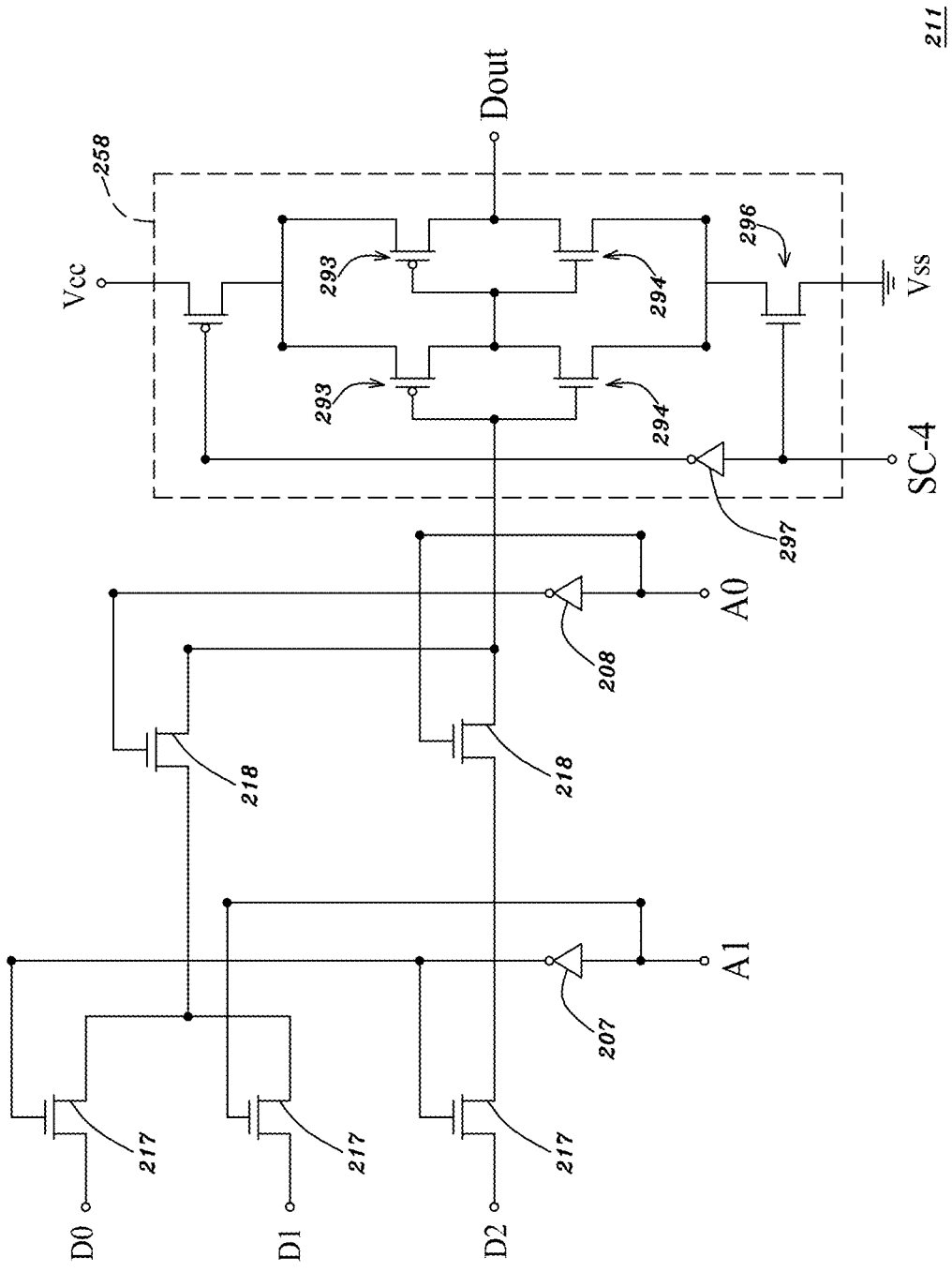

211
Dout
258
Vcc
293
294
296
Vss
293
294
SC-4
297
A0
208
218
218
A1
207
217
217
217
D0
D1
D2

Fig. 4K

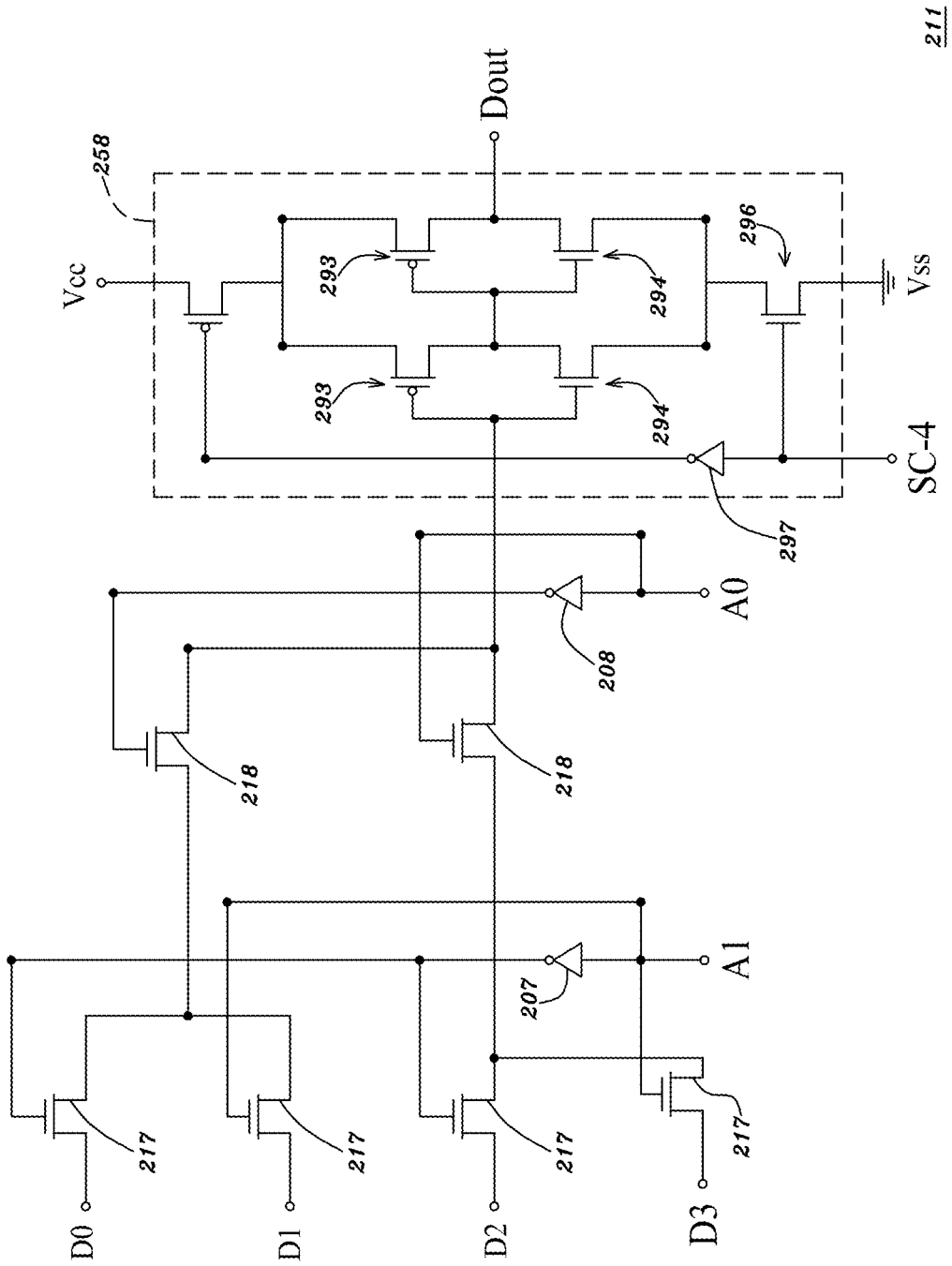

211
Dout
258
Vcc
293
294
296
Vss
293
294
SC-4
297
A0
208
218
218
A1
207
217
217
217
217
D0
D1
D2
D3

Fig. 4L

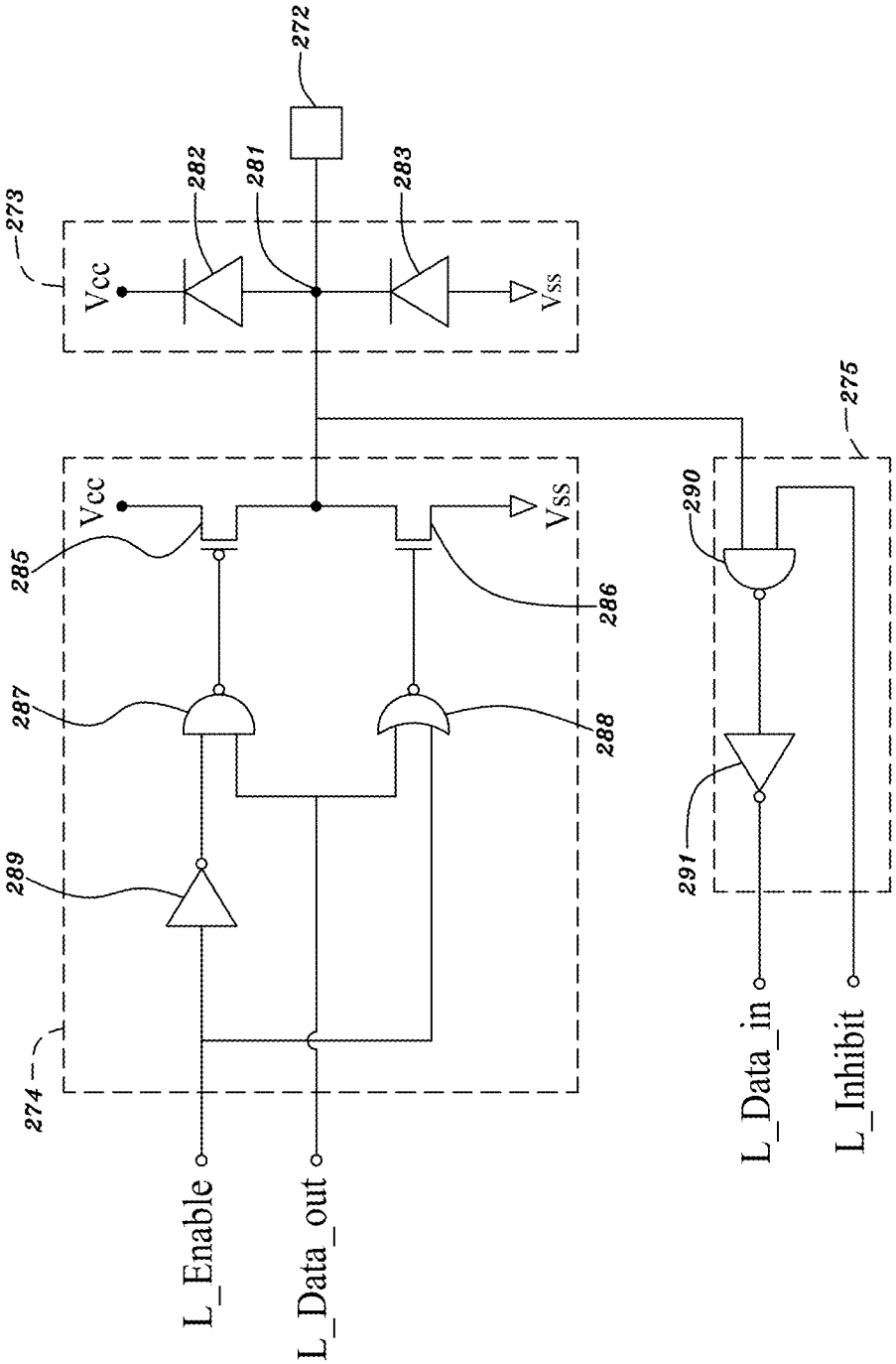

341
272
273
282
281
283
Vcc
Vss
275
Vcc
Vss
285
286
290
287
288
289
291
274
L_Enable
L_Data_out
L_Data_in
L_Inhibit

Fig. 5A

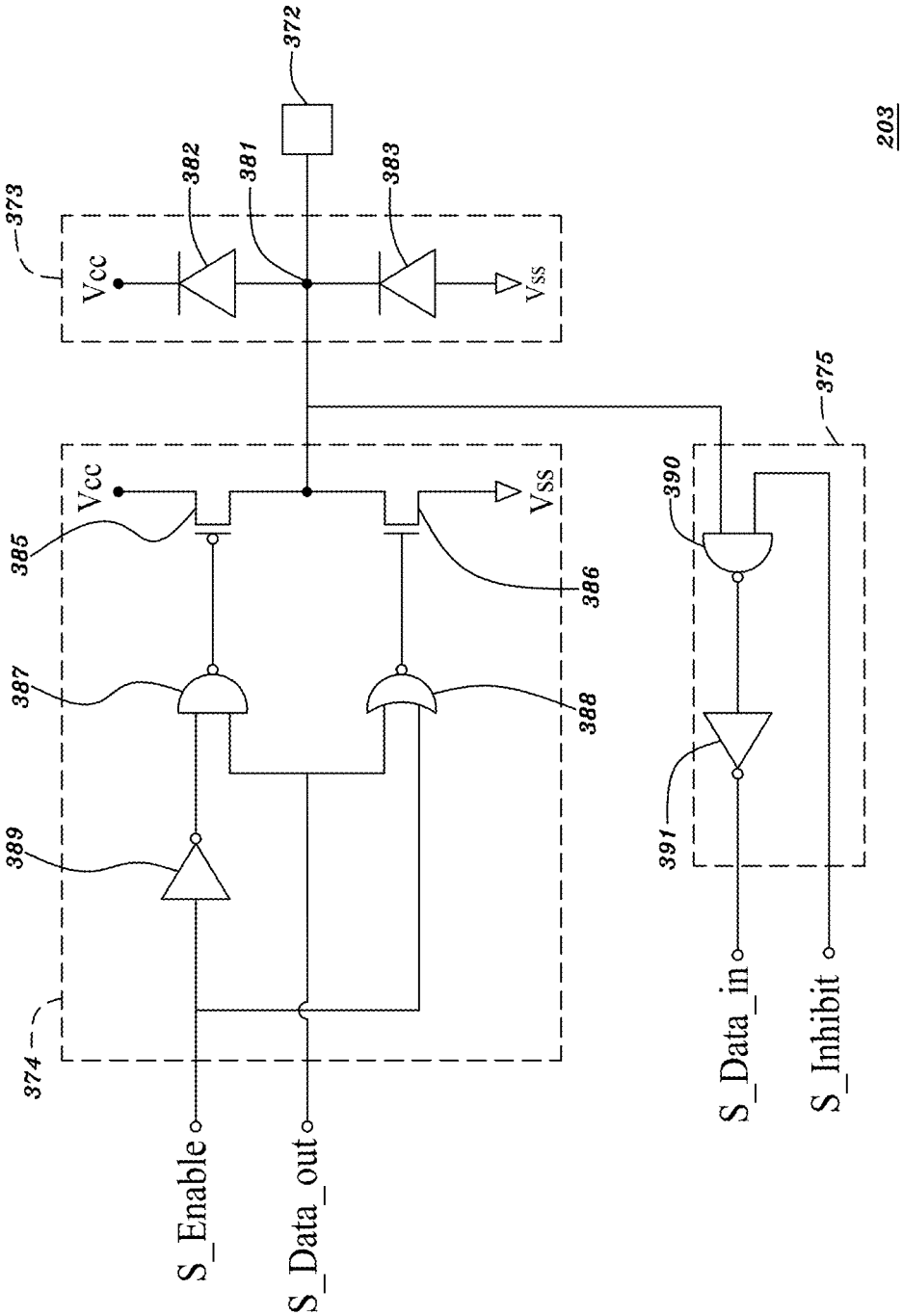

203
372
373
382
381
383
Vcc
Vss
375
Vcc
Vss
385
386
387
388
389
390
391
374
S_Enable
S_Data_out
S_Data_in
S_Inhibit

Fig. 5B

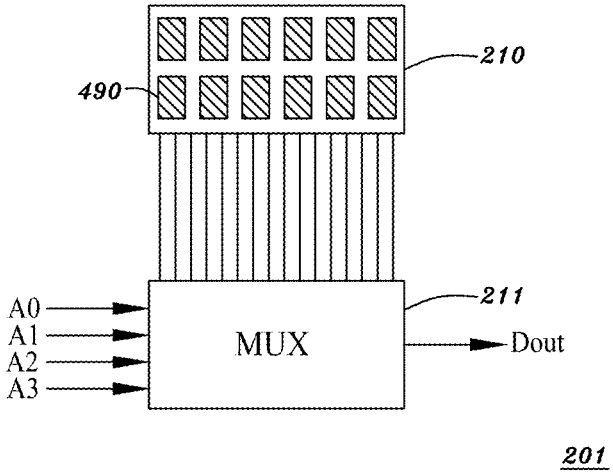


Fig. 6A

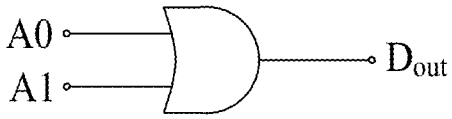


Fig. 6B

A0	A1	Dout	
0	0	0	D0
0	1	1	D1
1	0	1	D2
1	1	1	D3

Fig. 6C

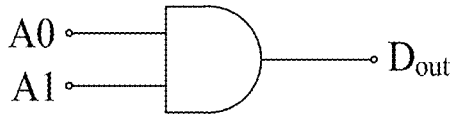


Fig. 6D

A0	A1	Dout	
0	0	0	D0
0	1	0	D1
1	0	0	D2
1	1	1	D3

Fig. 6E

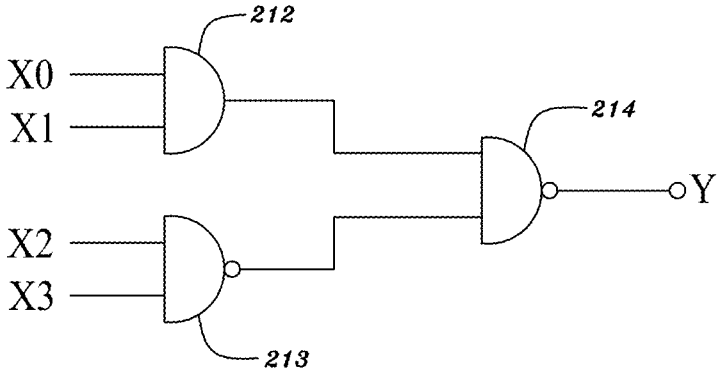


Fig. 6F

Input				Onput	
A0	A1	A2	A3	Dout	
0	0	0	0	1	D0
0	0	0	1	1	D1
0	0	1	0	1	D2
0	0	1	1	1	D3
0	1	0	0	1	D4
0	1	0	1	1	D5
0	1	1	0	1	D6
0	1	1	1	1	D7
1	0	0	0	1	D8
1	0	0	1	1	D9
1	0	1	0	1	D10
1	0	1	1	1	D11
1	1	0	0	0	D12
1	1	0	1	0	D13
1	1	1	0	0	D14
1	1	1	1	1	D15

210

Fig. 6G

Input				Output				
A1	A0 x	A3	A2	Dout C3	C2	C1	C0	
0	0	0	0	0	0	0	0	D0
0	0	0	1	0	0	0	0	D1
0	0	1	0	0	0	0	0	D2
0	0	1	1	0	0	0	0	D3
0	1	0	0	0	0	0	0	D4
0	1	0	1	0	0	0	1	D5
0	1	1	0	0	0	1	0	D6
0	1	1	1	0	0	1	1	D7
1	0	0	0	0	0	0	0	D8
1	0	0	1	0	0	1	0	D9
1	0	1	0	0	1	0	0	D10
1	0	1	1	0	1	1	0	D11
1	1	0	0	0	0	0	0	D12
1	1	0	1	0	0	1	1	D13
1	1	1	0	0	1	1	0	D14
1	1	1	1	1	0	0	1	D15

Fig. 6I

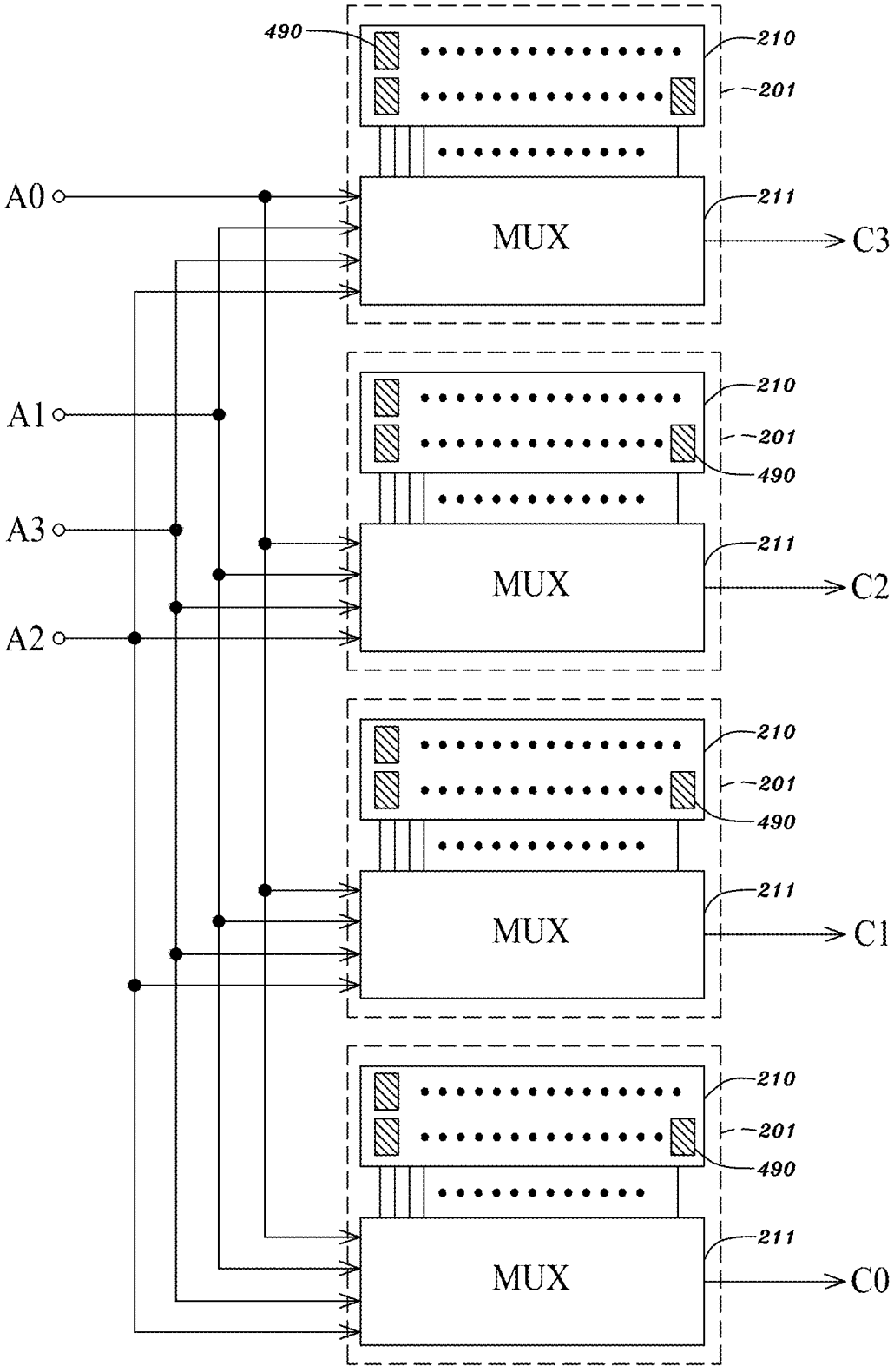

490
210
201
A0
211
MUX
C3
A1
210
201
490
A3
211
MUX
C2
A2
210
201
490
211
MUX
C1
210
201
490
211
MUX
C0

Fig. 6H

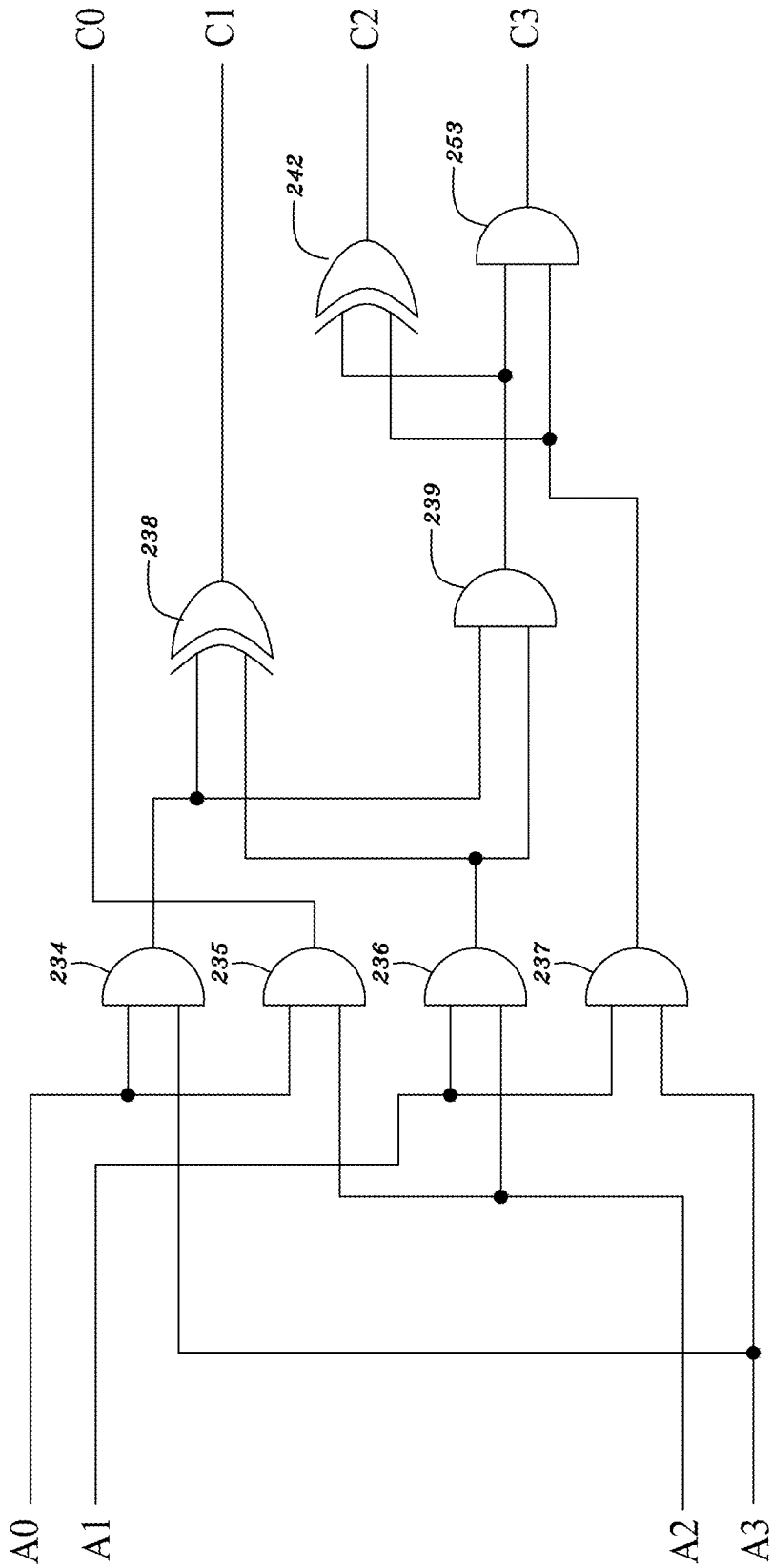


Fig. 6J

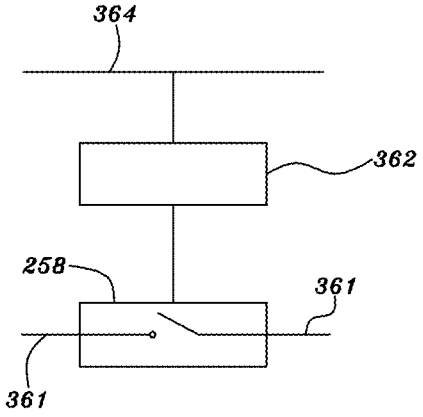

364
362
258
361
361

Fig. 7A

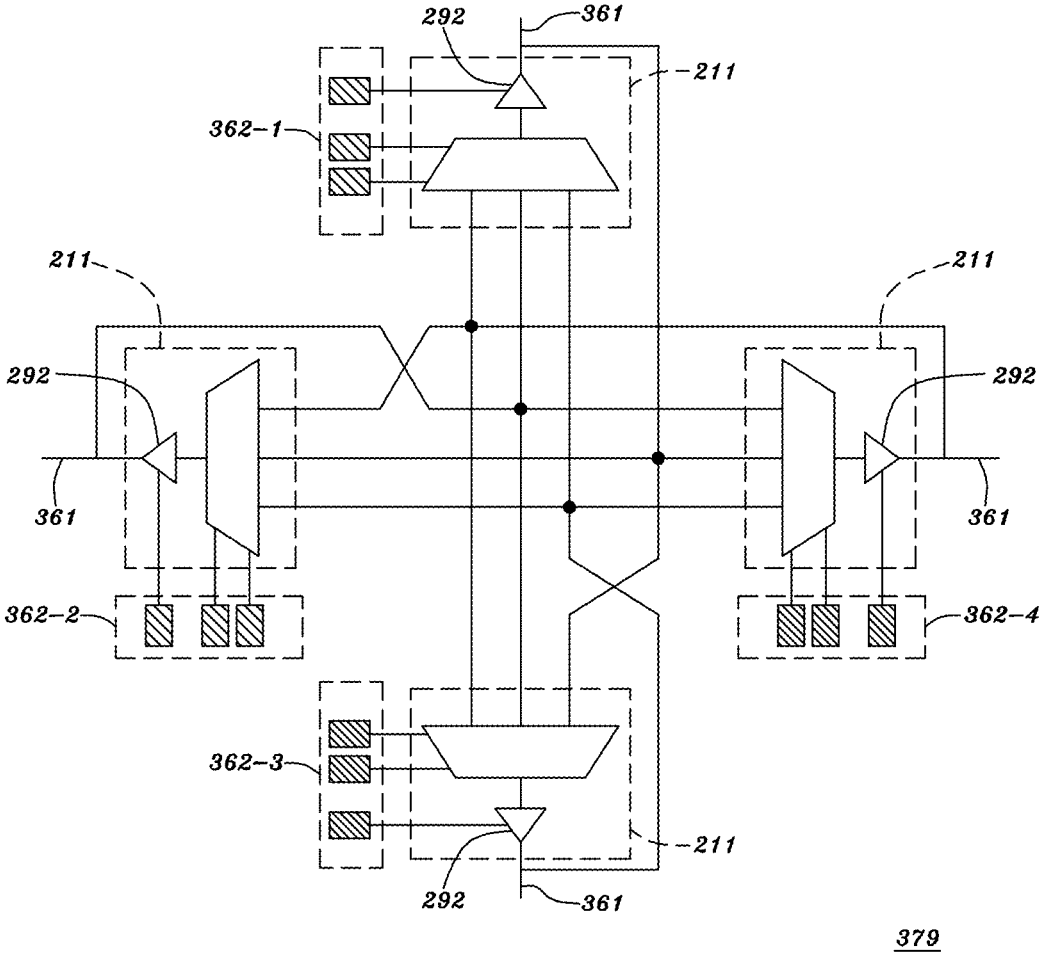

292
361
211
362-1
211
211
292
292
361
361
362-2
362-4
362-3
211
292
361
379

Fig. 7B

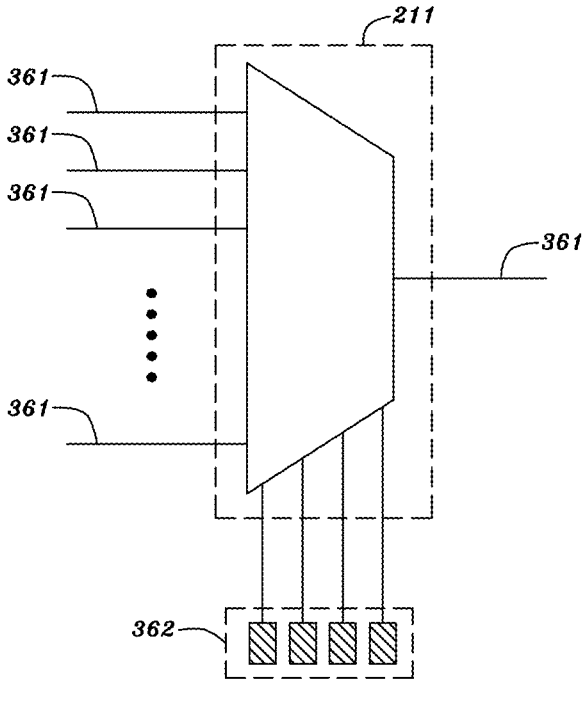


Fig. 7C

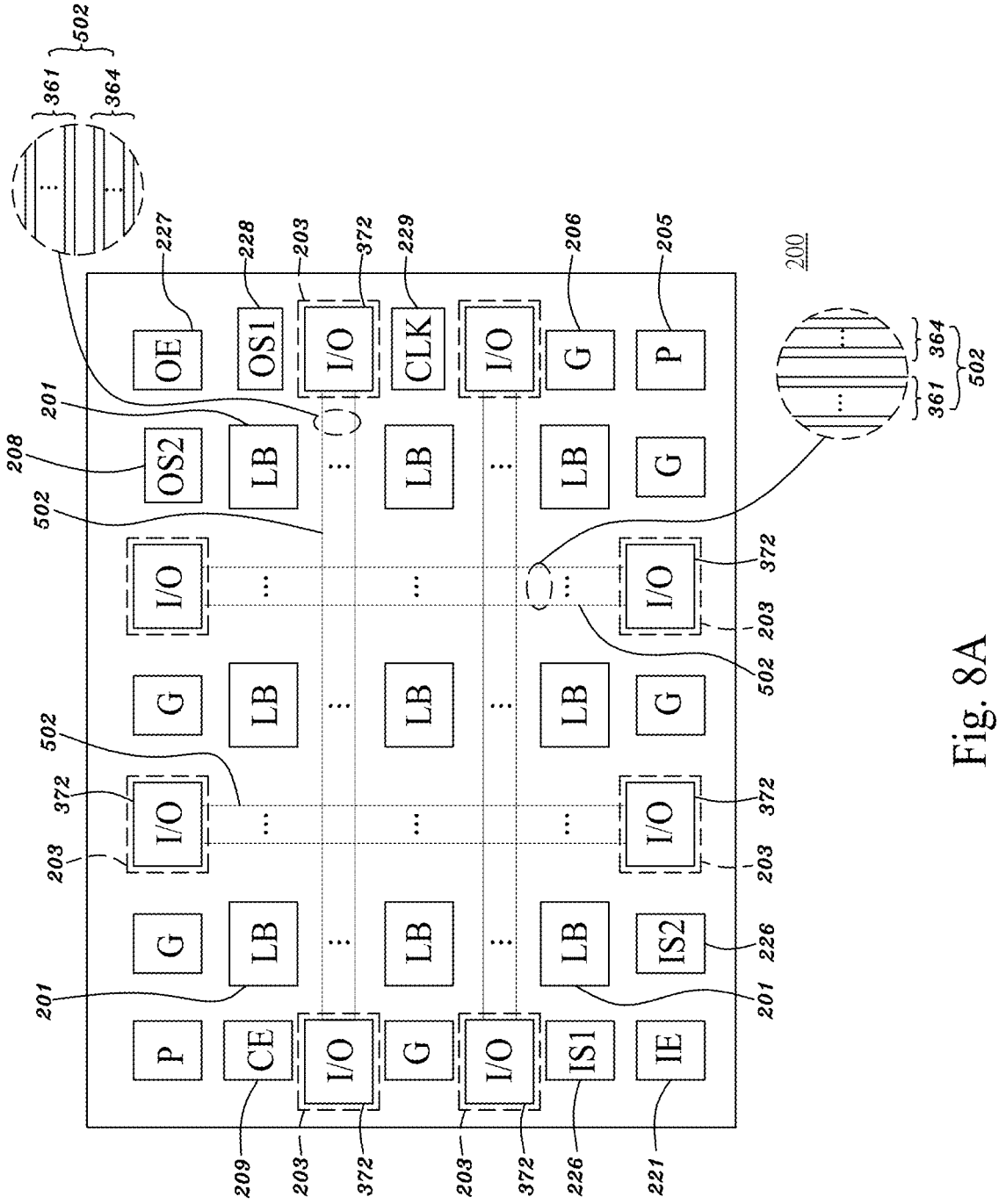

200
OE
OS1
I/O
CLK
I/O
G
P
OS2
LB
G
CE
IS2
IS1
IE
227
228
203
372
229
206
205
201
208
502
361
364
209
226
221

Fig. 8A

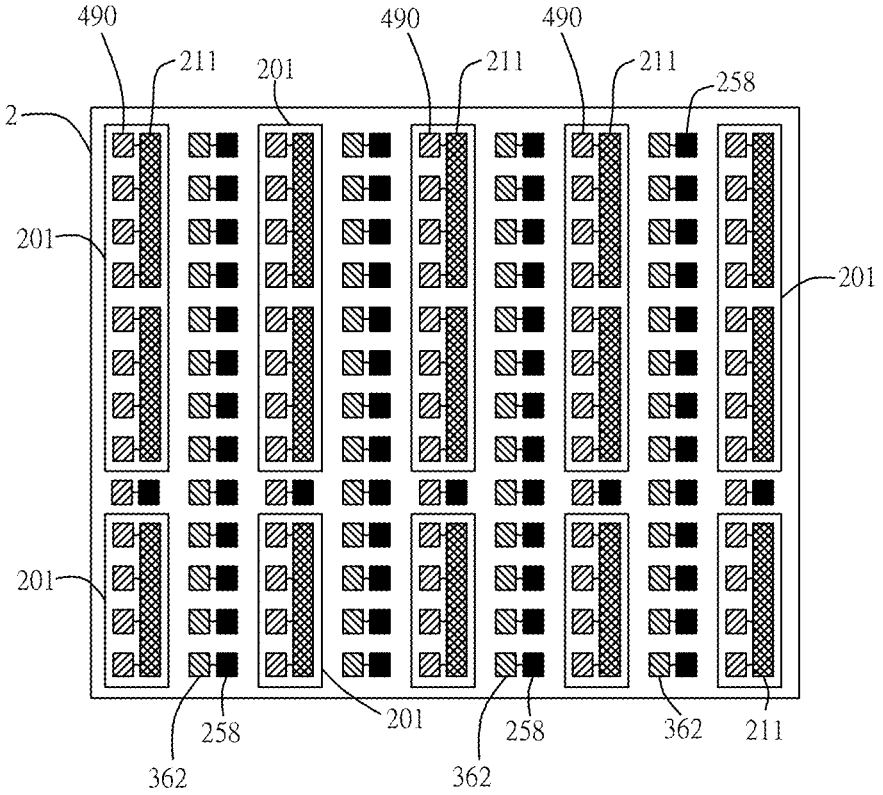

490
211
201
490
211
490
211
258
2
201
201
201
258
362
201
258
362
362
211

Fig. 8B

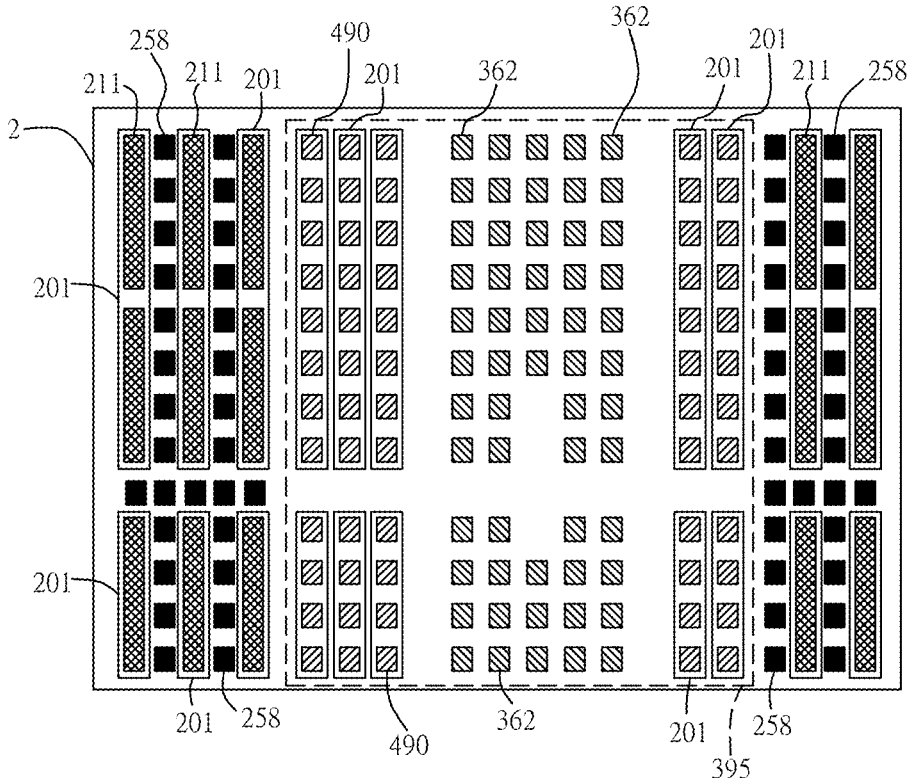

258
490
362
211
211
201
201
362
201
211
258
2
201
201
201
258
490
362
201
258
395

Fig. 8C

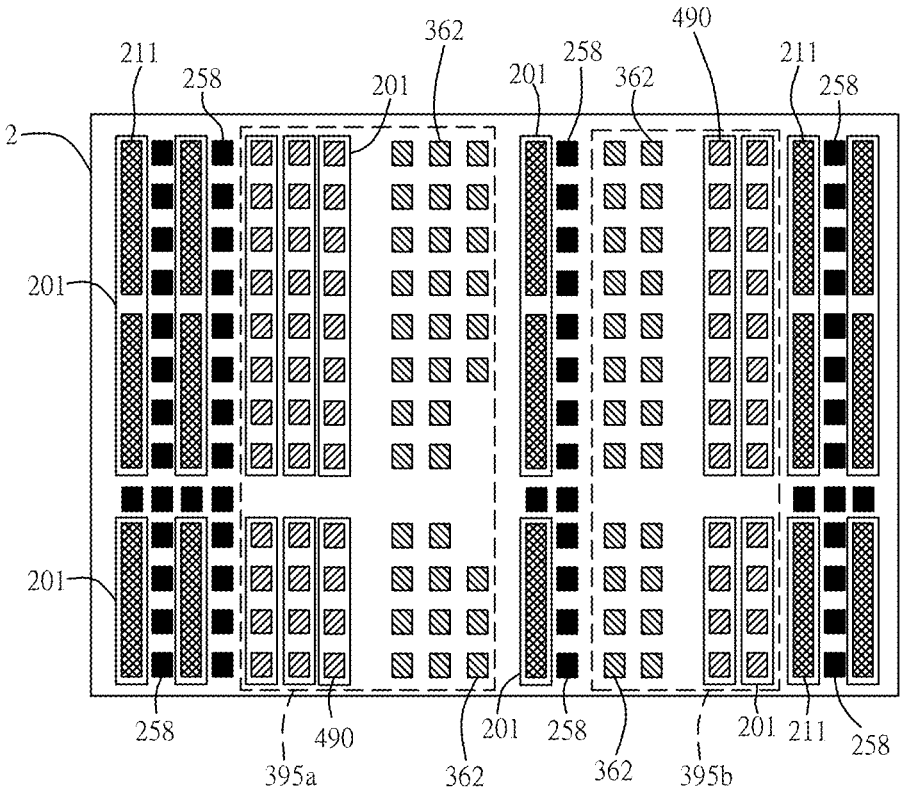

211
258
362
201
201
258
362
490
211
258
2
201
201
258
490
395a
362
201
258
362
395b
201
211
258

Fig. 8D

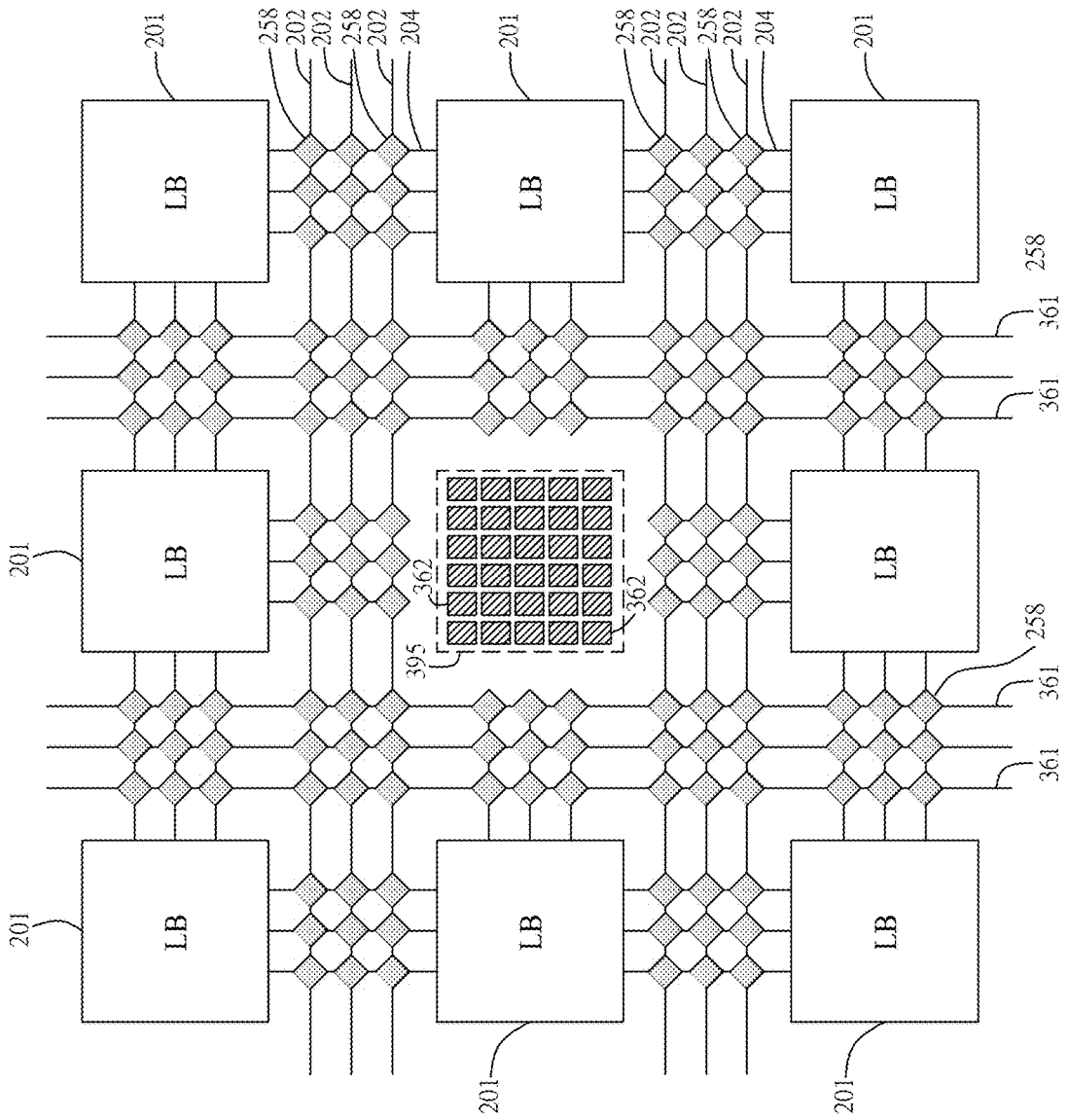


Fig. 8E

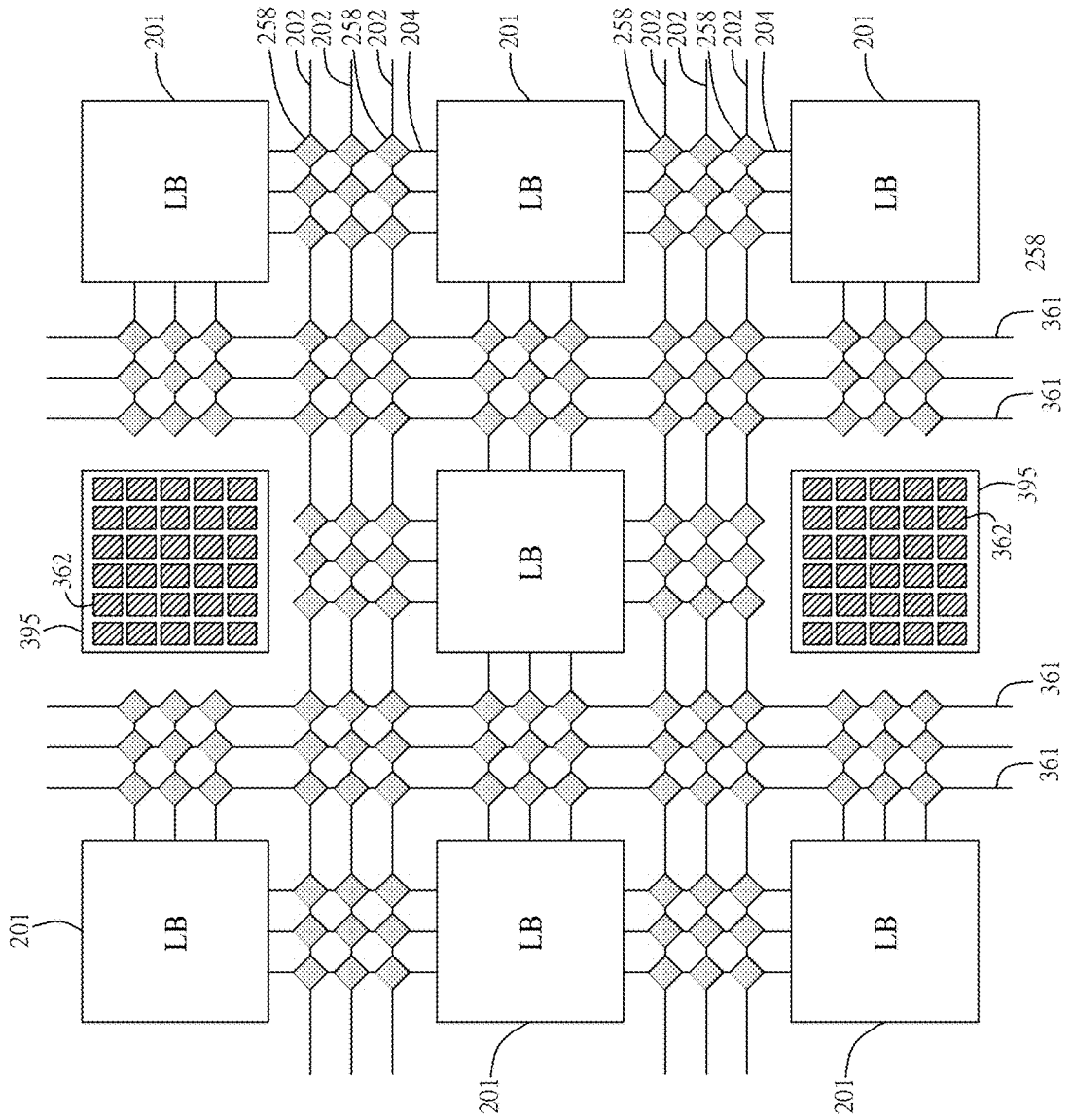


Fig. 8F

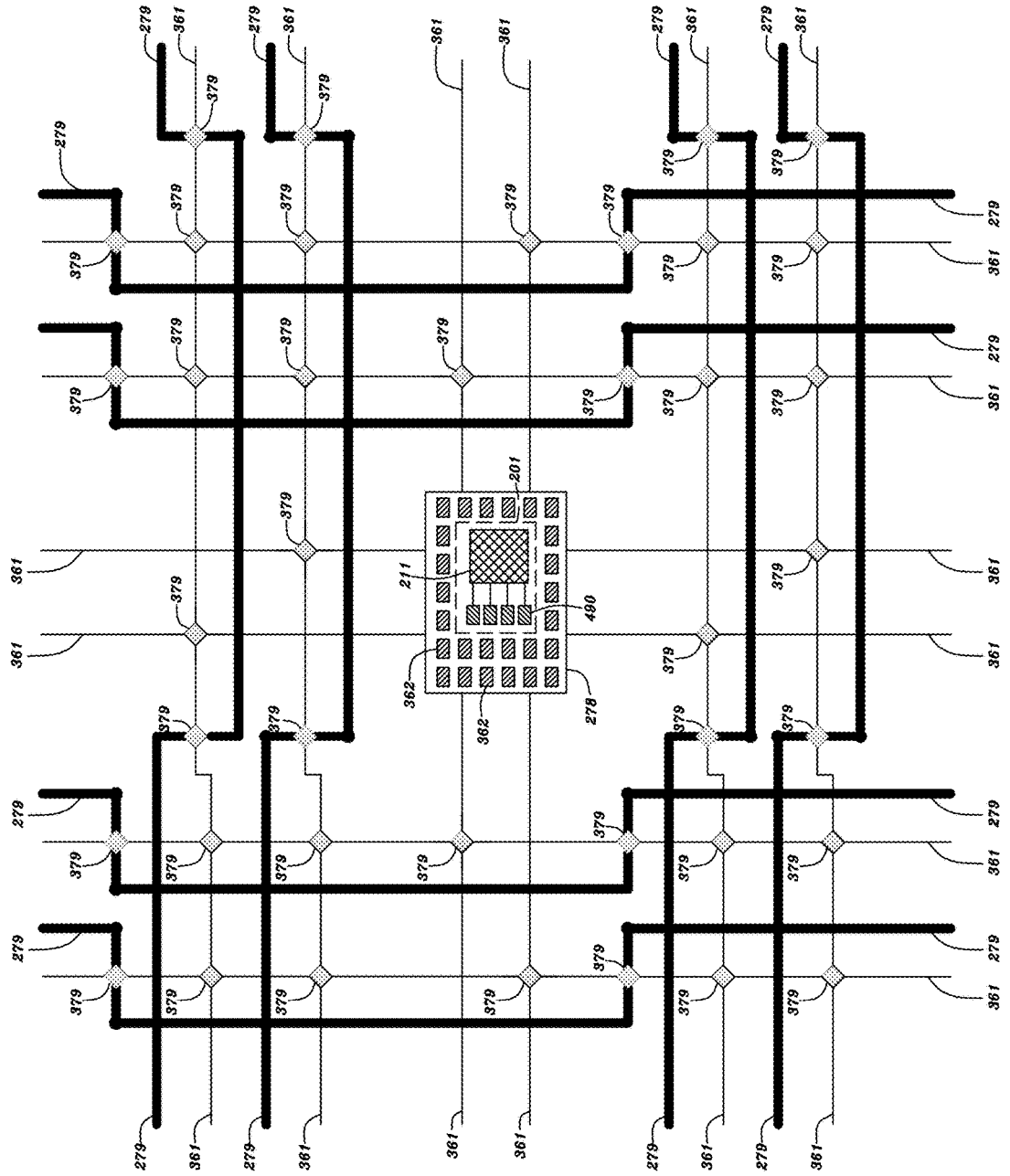


Fig. 8G

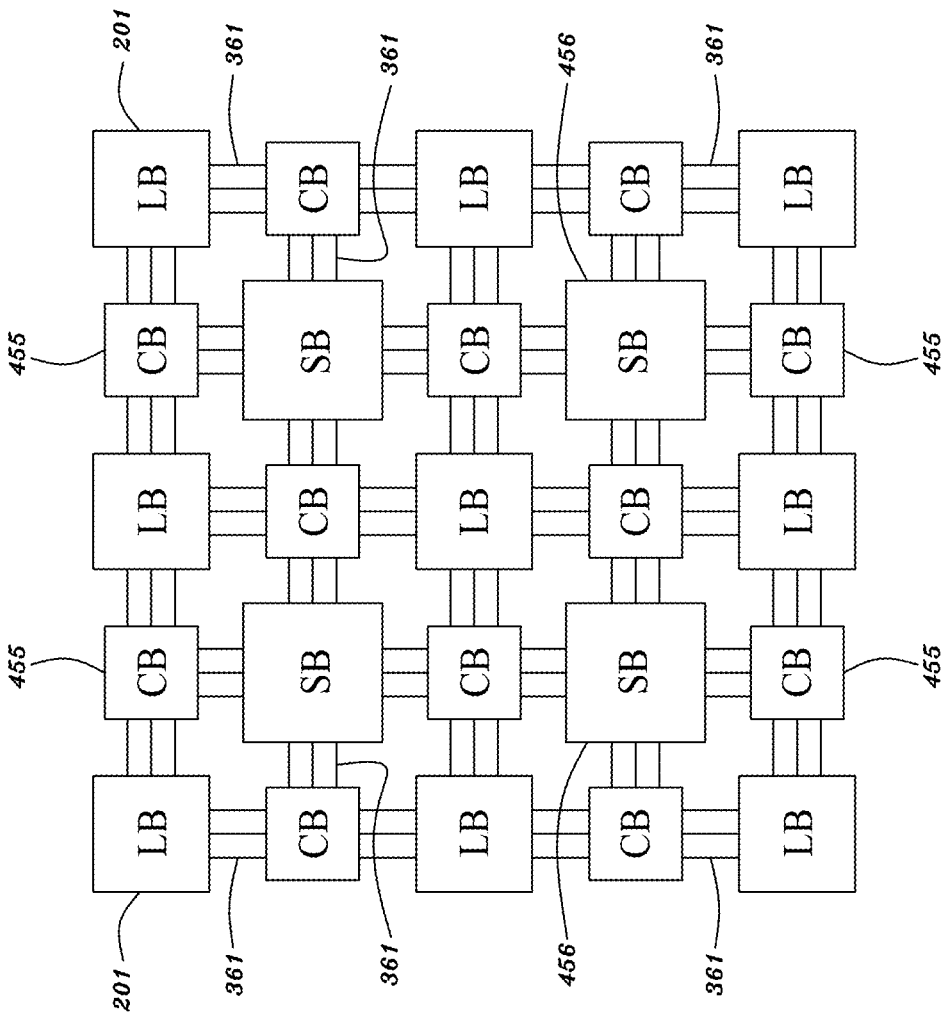


Fig. 8H

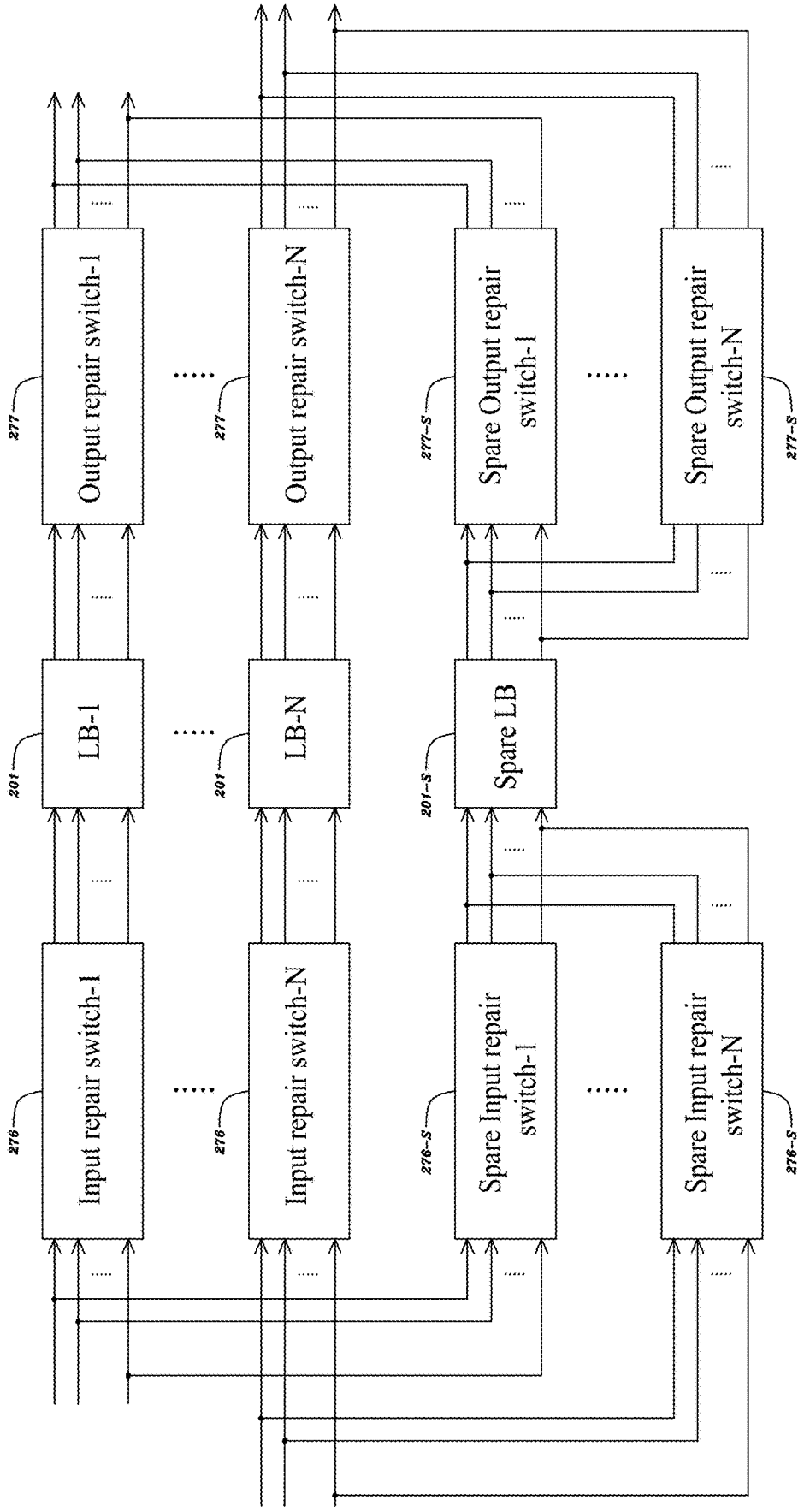

Output repair switch-1
Output repair switch-N
Spare Output repair switch-1
Spare Output repair switch-N
LB-1
LB-N
Spare LB
Input repair switch-1
Input repair switch-N
Spare Input repair switch-1
Spare Input repair switch-N
277
277
277-S
277-S
201
201
201-S
276
276
276-S
276-S

Fig. 8I

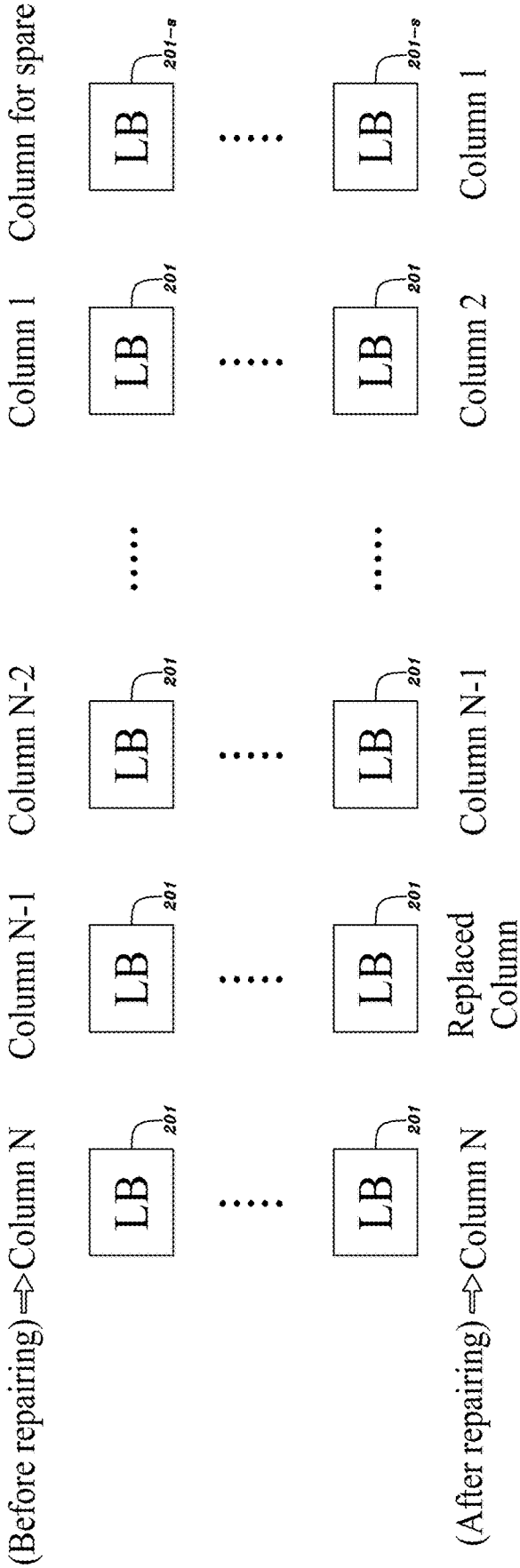

(Before repairing) ⇒ Column N
Column N-1
Column N-2
Column 1
Column for spare
LB
201
201-s
(After repairing) ⇒ Column N
Replaced Column
Column N-1
Column 2
Column 1

Fig. 8J

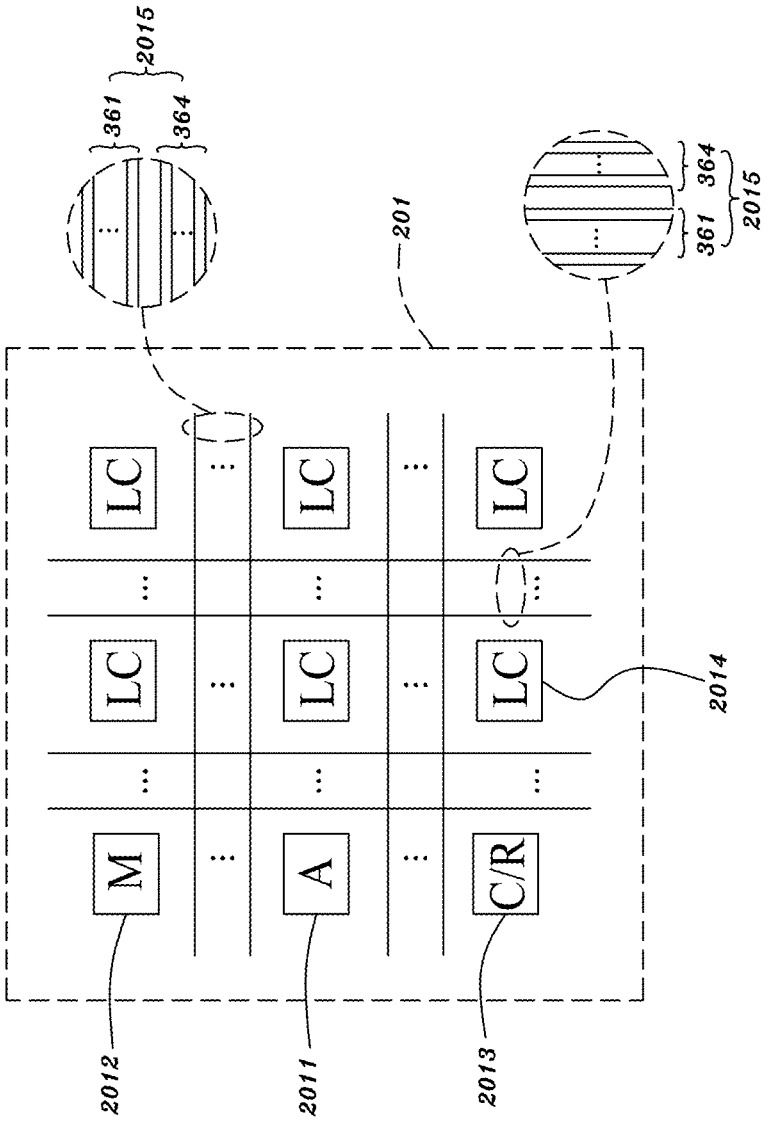


Fig. 8K

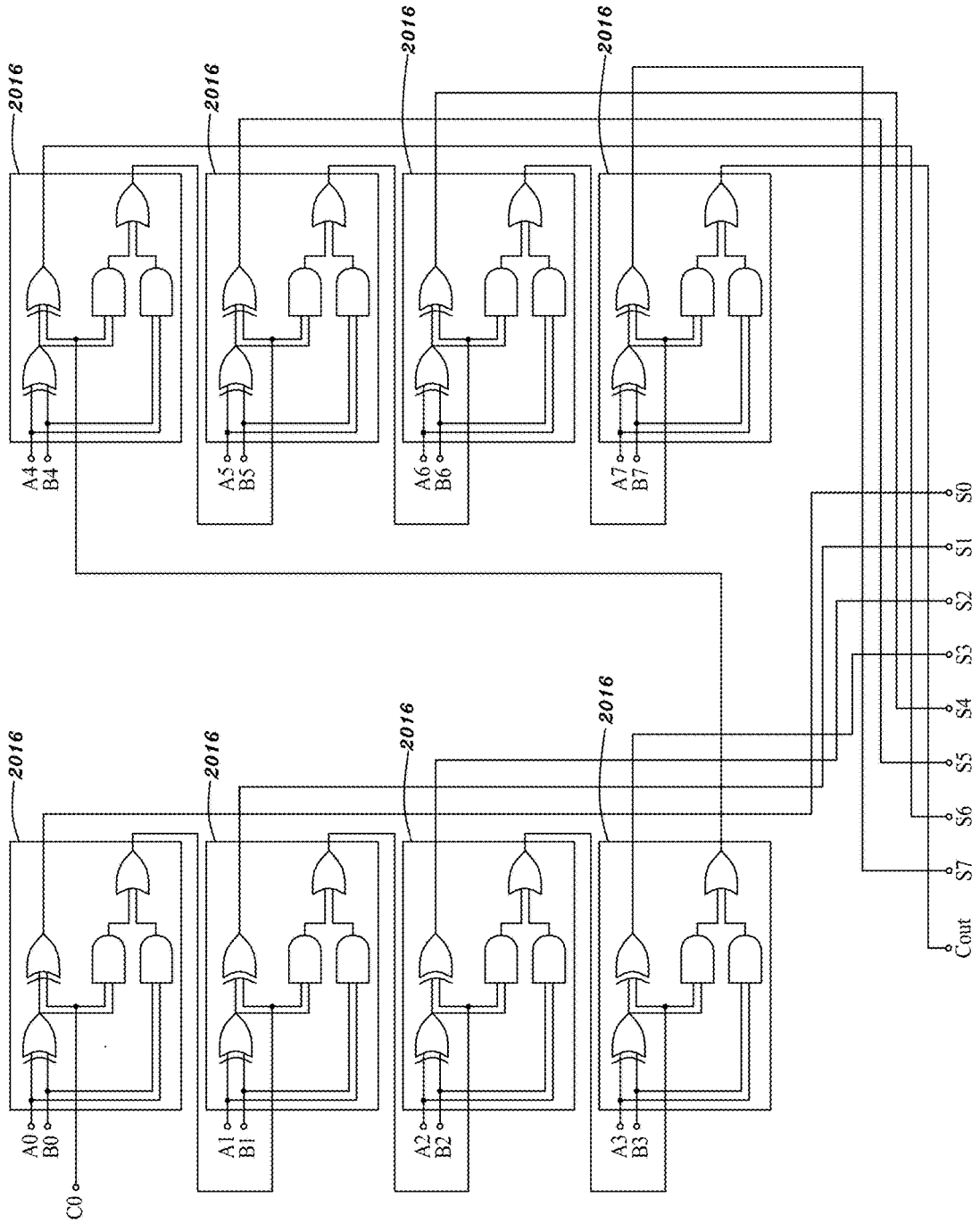

2016
2016
2016
2016
A4
B4
A5
B5
A6
B6
A7
B7
S0
S1
S2
S3
S4
S5
S6
S7
Cout
2016
2016
2016
2016
A0
B0
C0
A1
B1
A2
B2
A3
B3

Fig. 8L

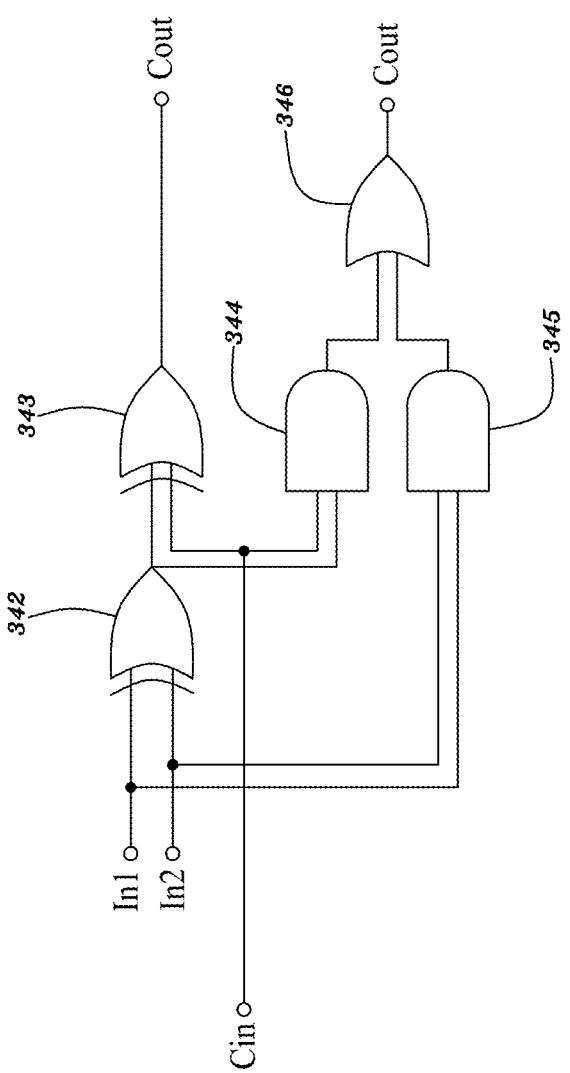


Fig. 8M

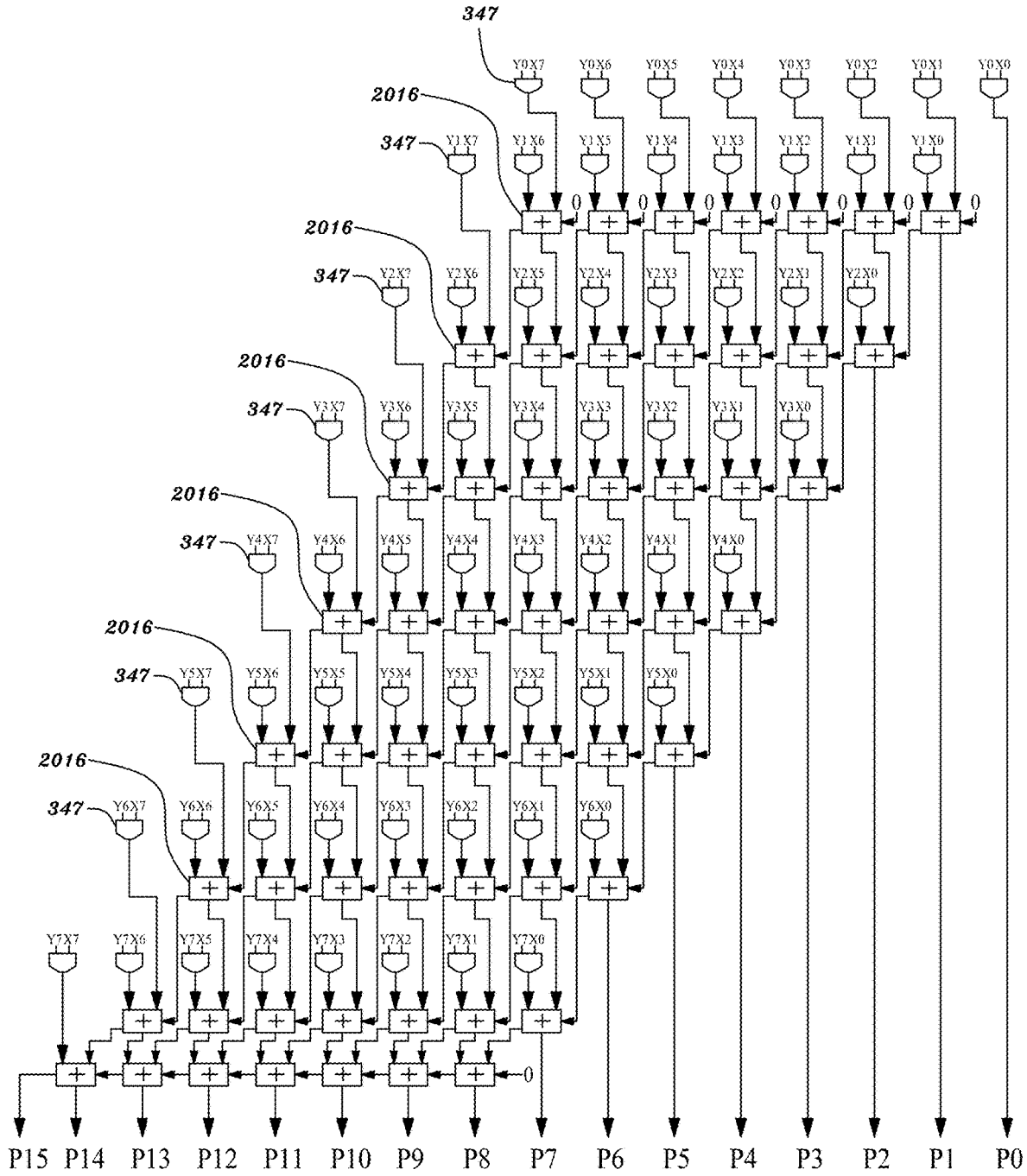

347
2016
Y0X7 Y0X6 Y0X5 Y0X4 Y0X3 Y0X2 Y0X1 Y0X0
Y1X7 Y1X6 Y1X5 Y1X4 Y1X3 Y1X2 Y1X1 Y1X0
Y2X7 Y2X6 Y2X5 Y2X4 Y2X3 Y2X2 Y2X1 Y2X0
Y3X7 Y3X6 Y3X5 Y3X4 Y3X3 Y3X2 Y3X1 Y3X0
Y4X7 Y4X6 Y4X5 Y4X4 Y4X3 Y4X2 Y4X1 Y4X0
Y5X7 Y5X6 Y5X5 Y5X4 Y5X3 Y5X2 Y5X1 Y5X0
Y6X7 Y6X6 Y6X5 Y6X4 Y6X3 Y6X2 Y6X1 Y6X0
Y7X7 Y7X6 Y7X5 Y7X4 Y7X3 Y7X2 Y7X1 Y7X0
0
P15 P14 P13 P12 P11 P10 P9 P8 P7 P6 P5 P4 P3 P2 P1 P0

Fig. 8N

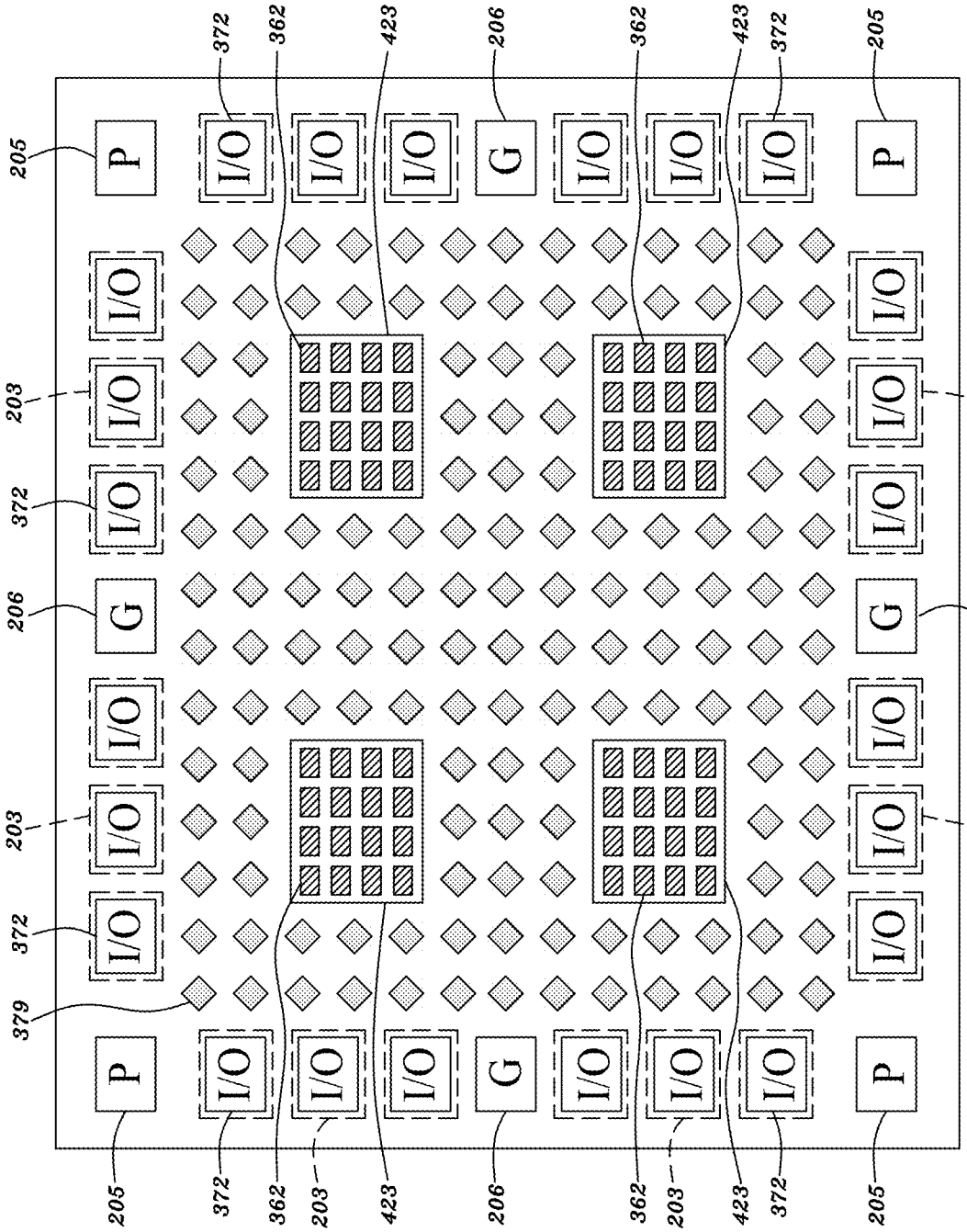


Fig. 9

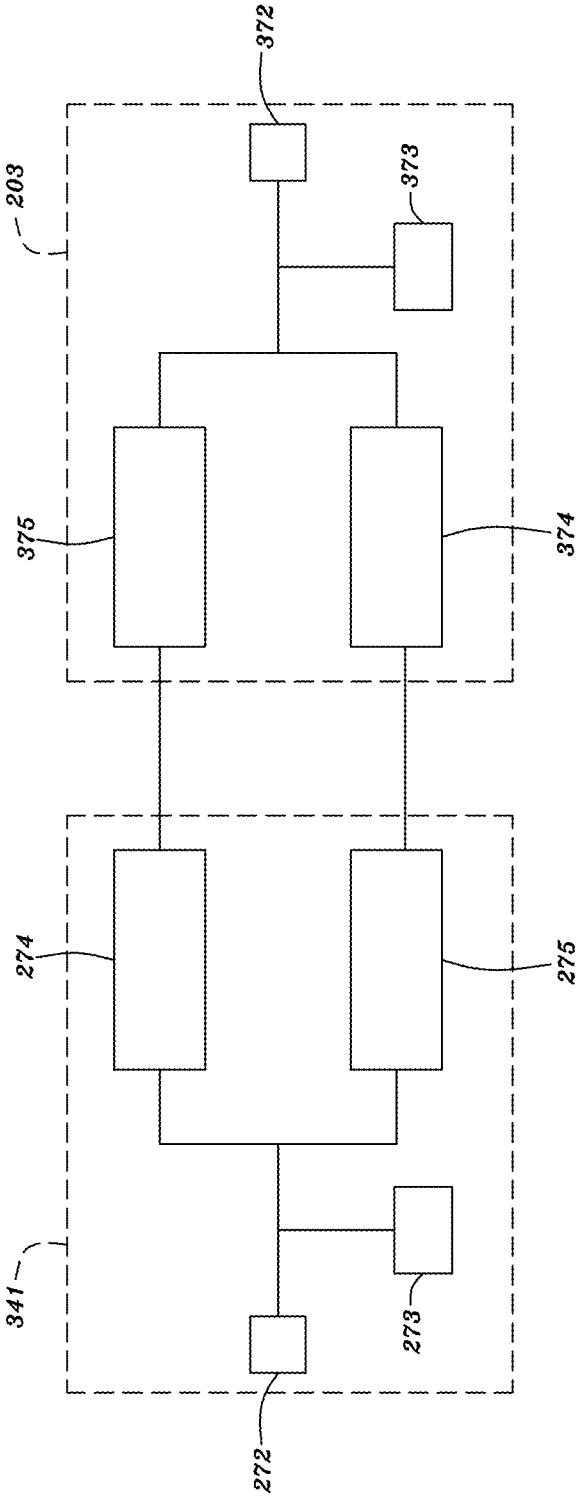


Fig. 10

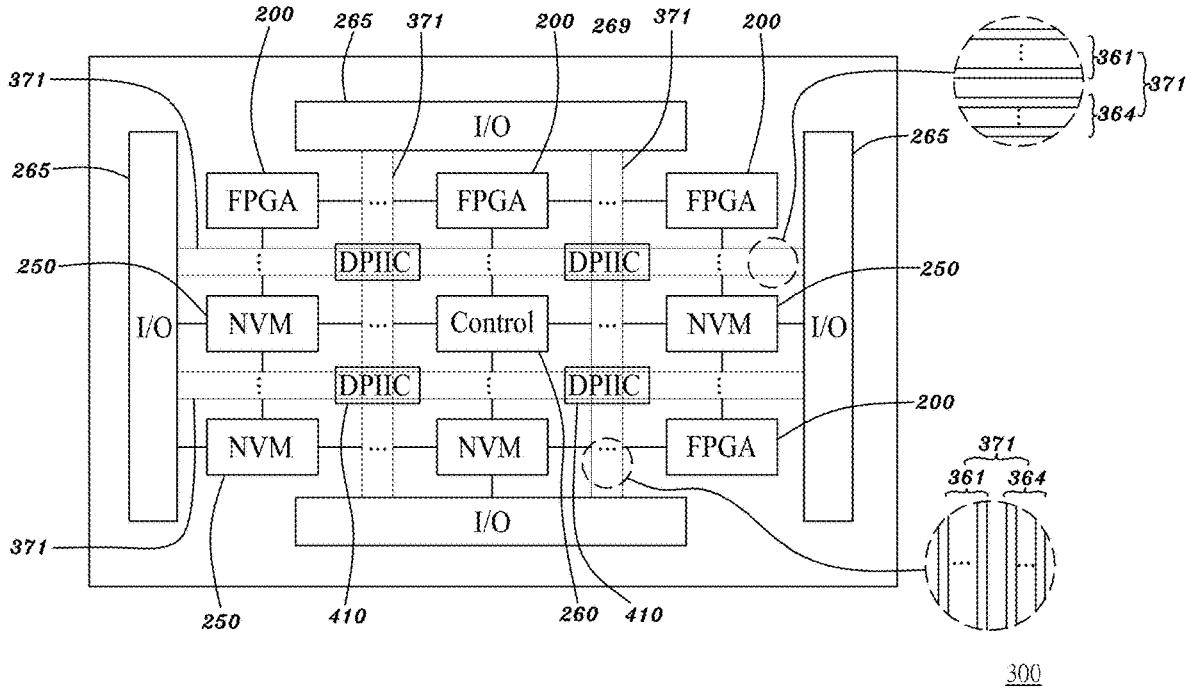


Fig. 11A

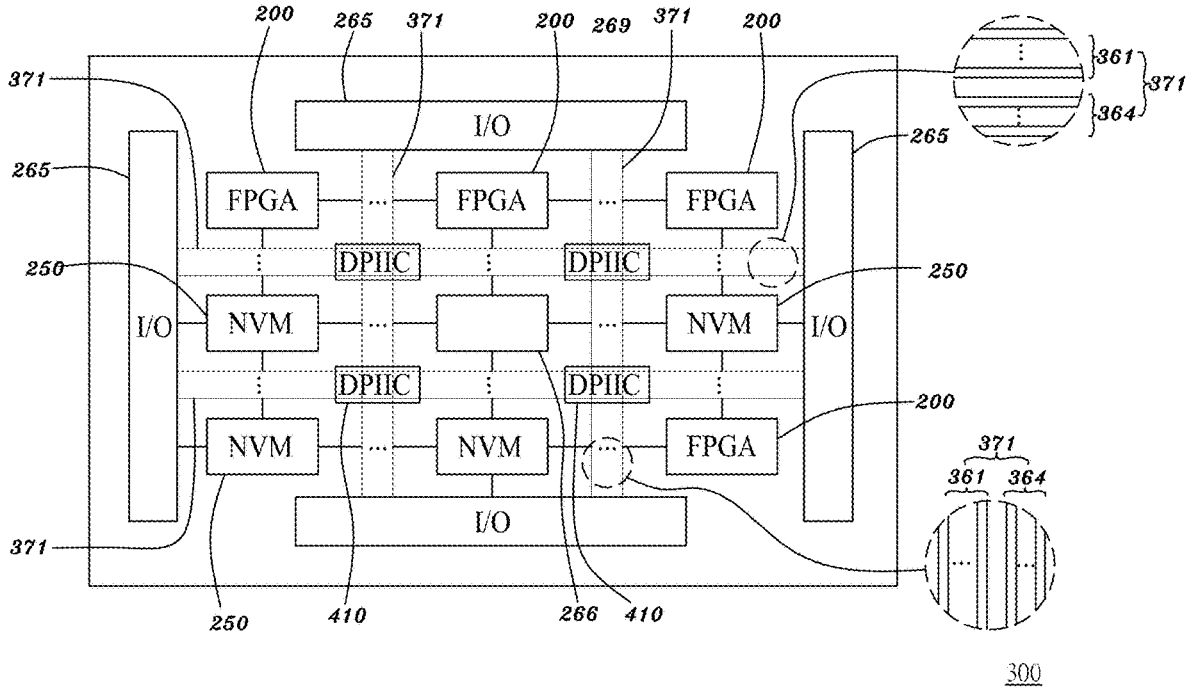


Fig. 11B

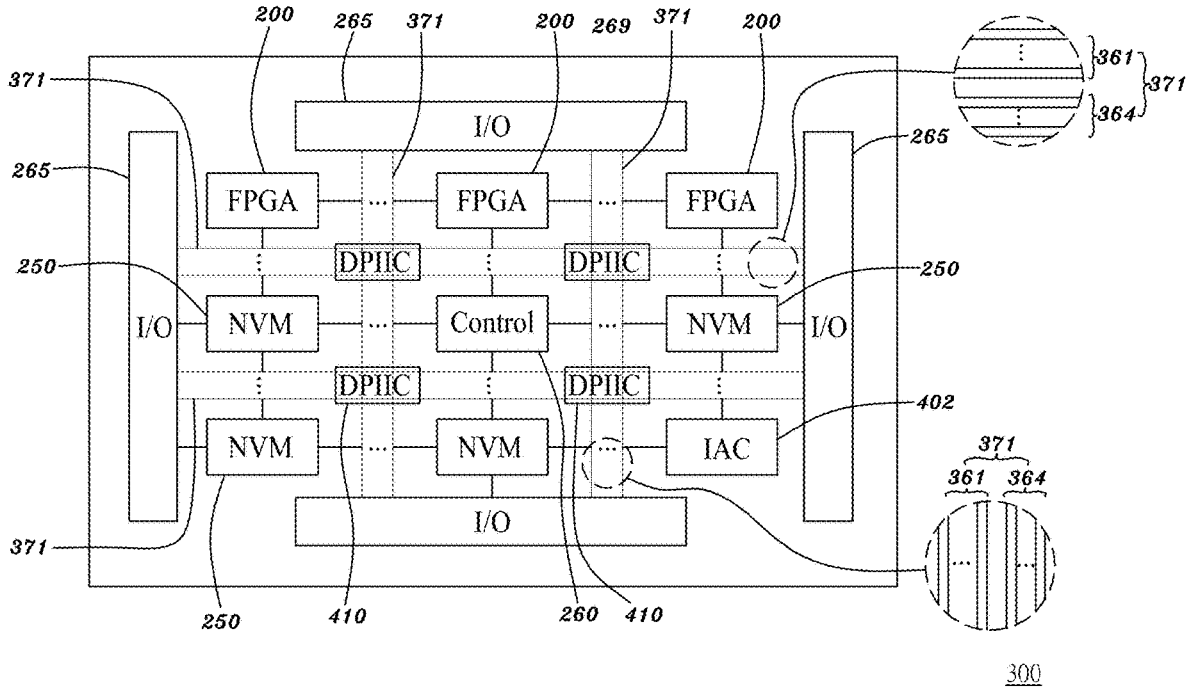


Fig. 11C

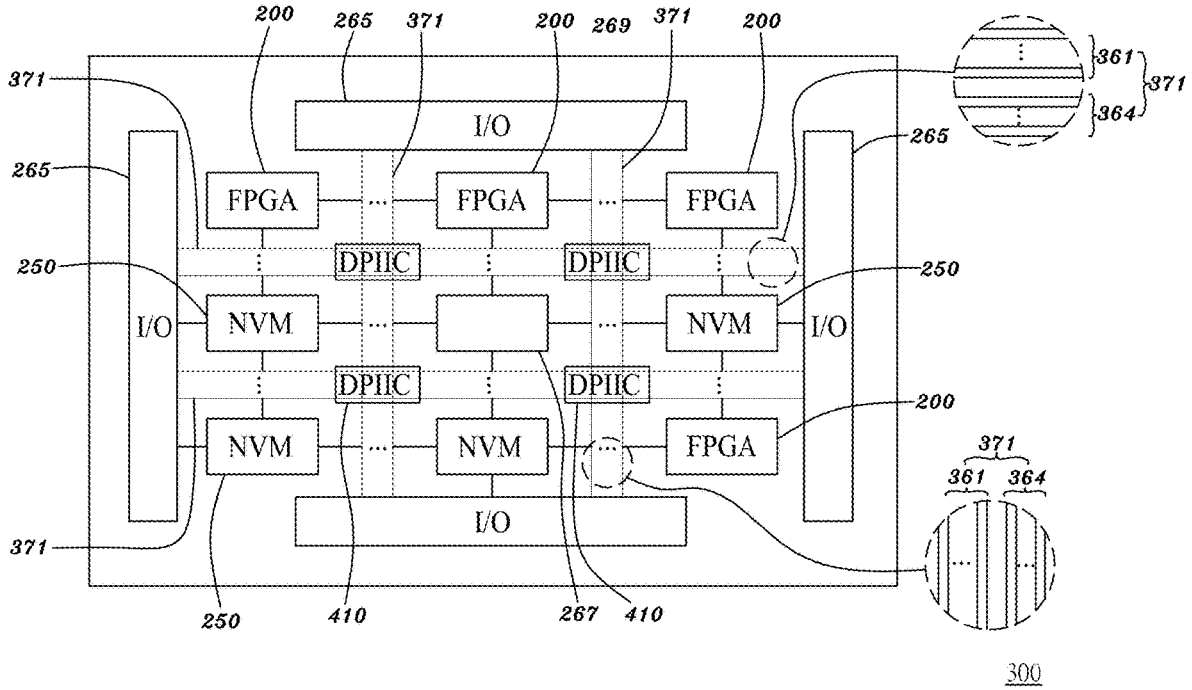


Fig. 11D

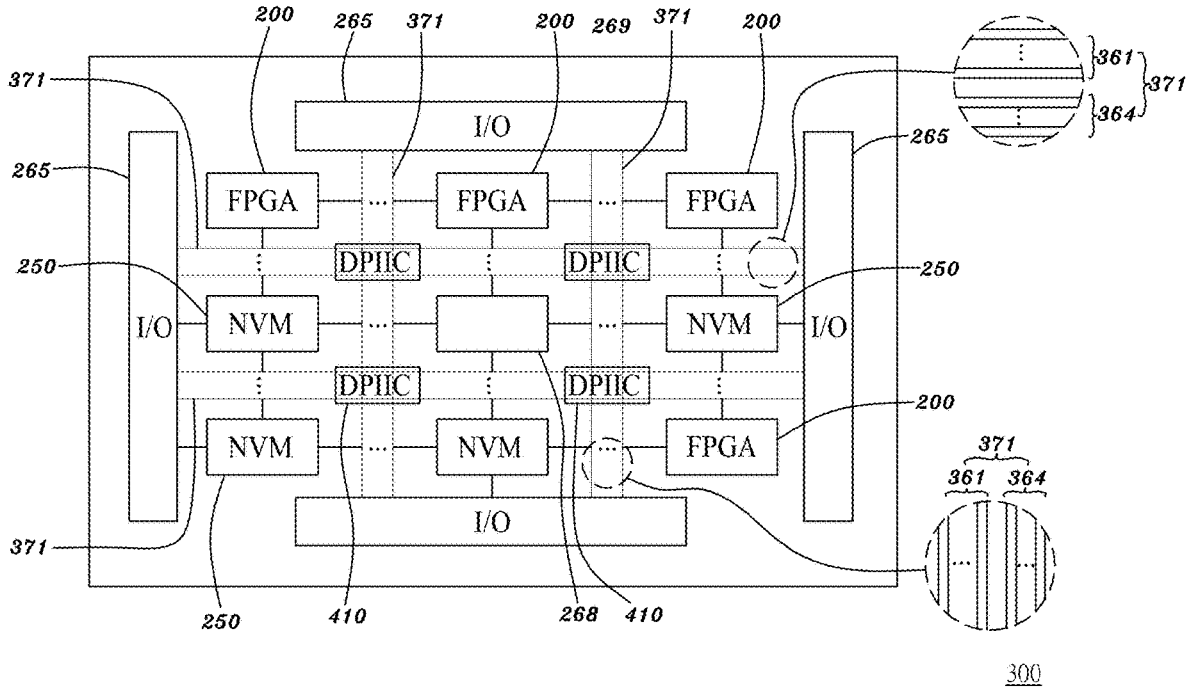


Fig. 11E

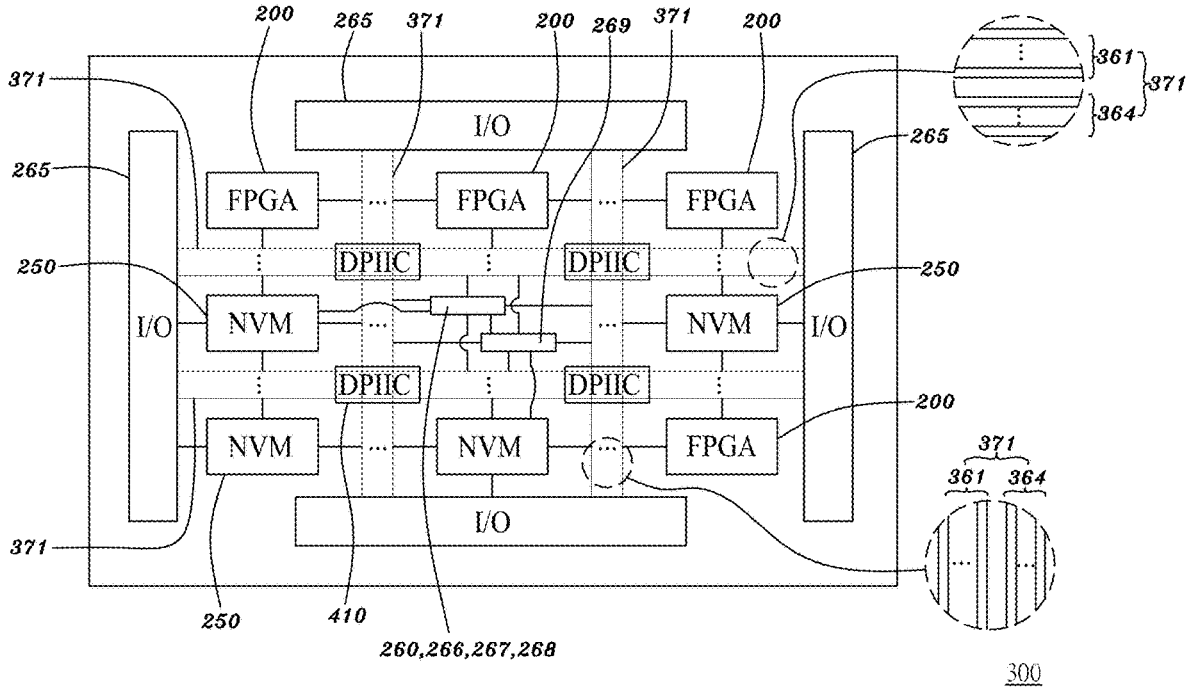


Fig. 11F

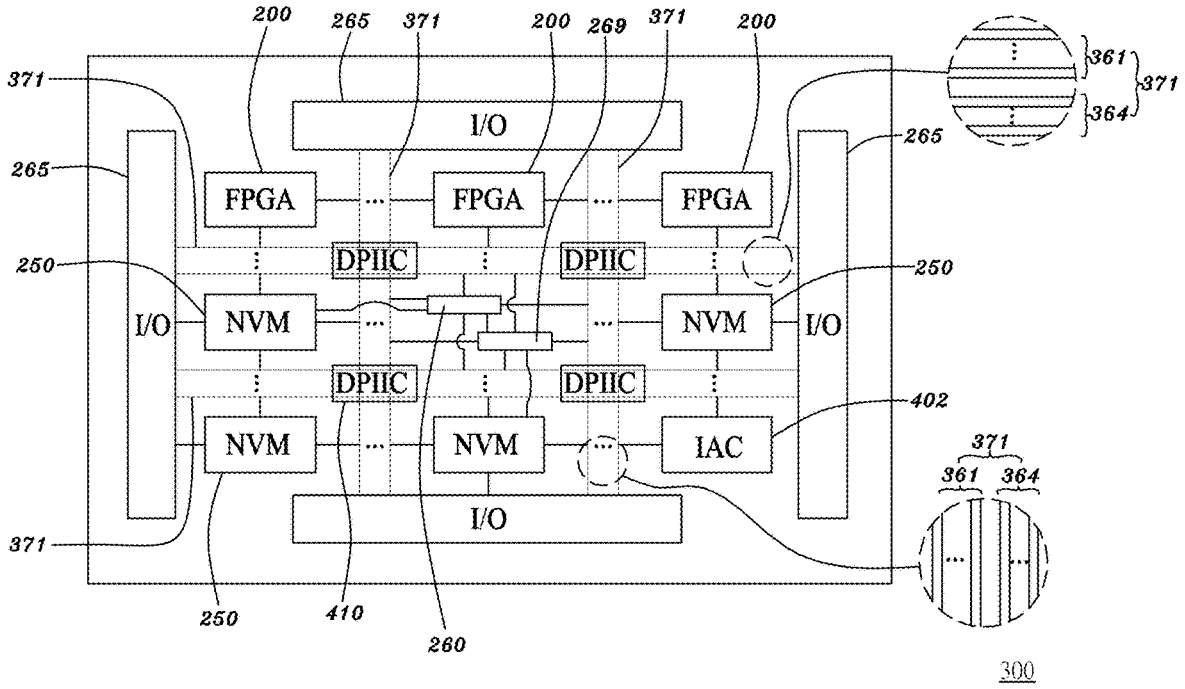


Fig. 11G

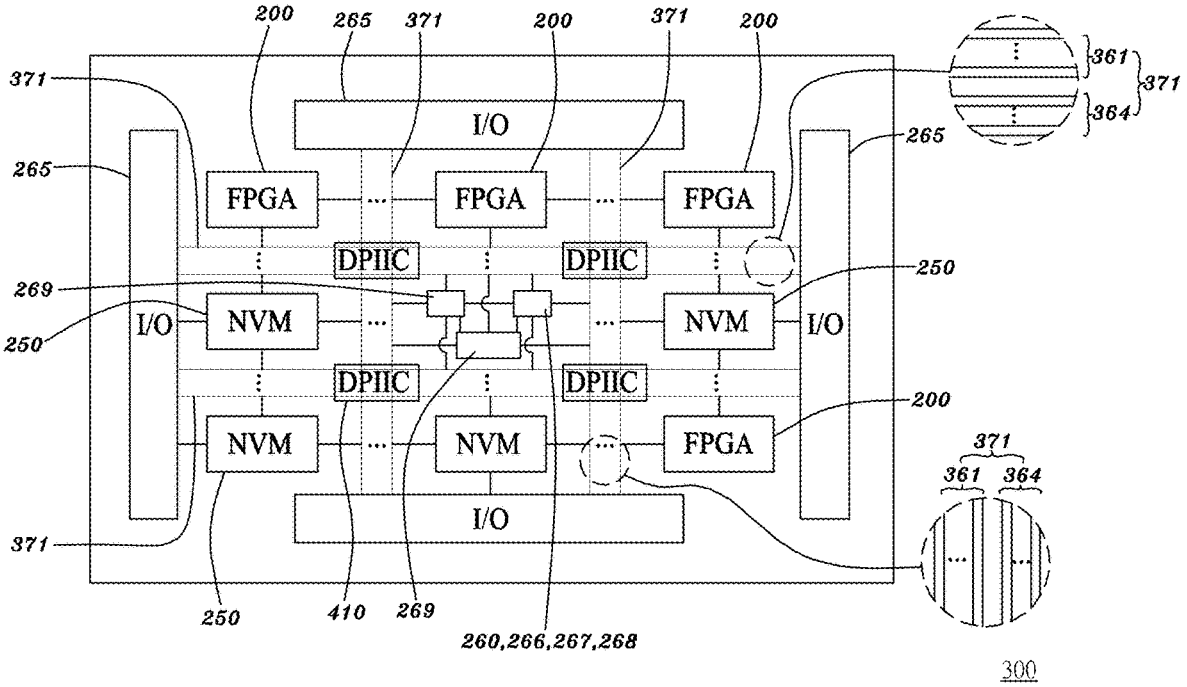


Fig. 11H

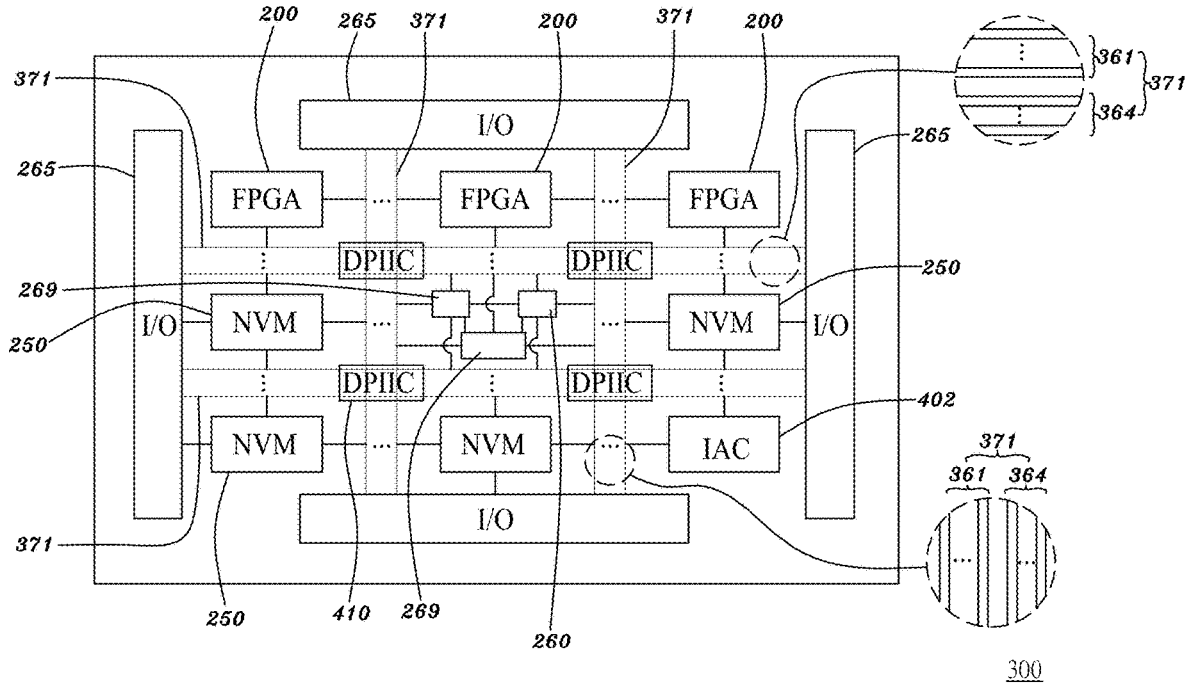


Fig. 11I

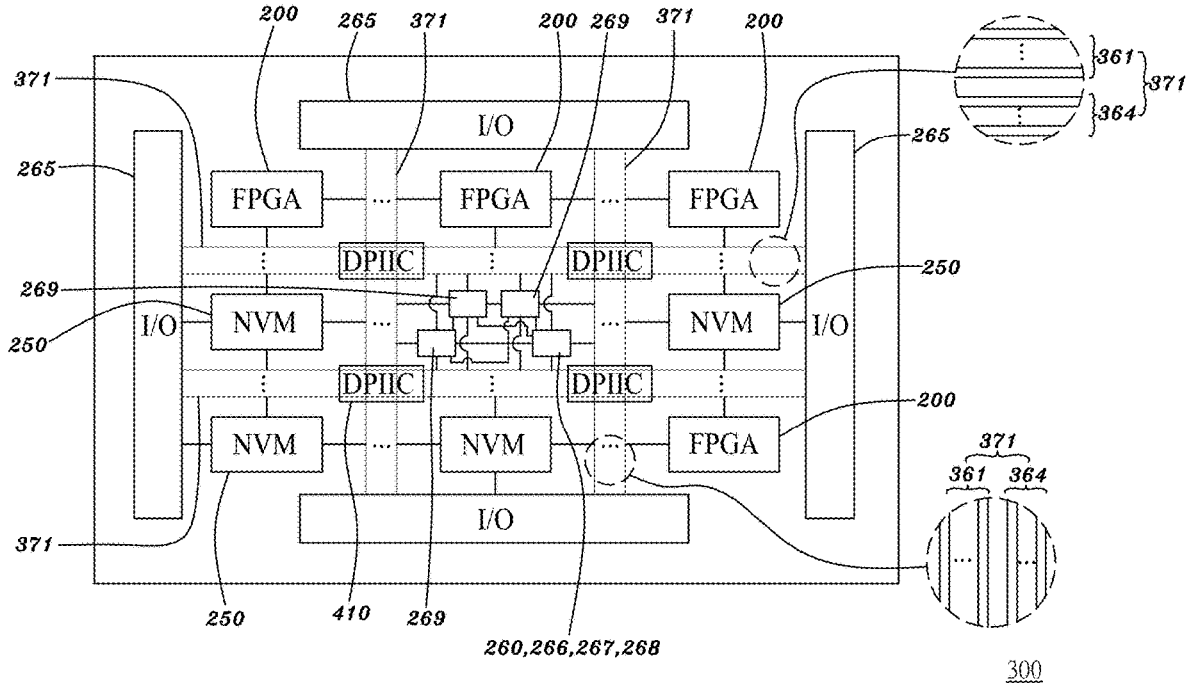


Fig. 11J

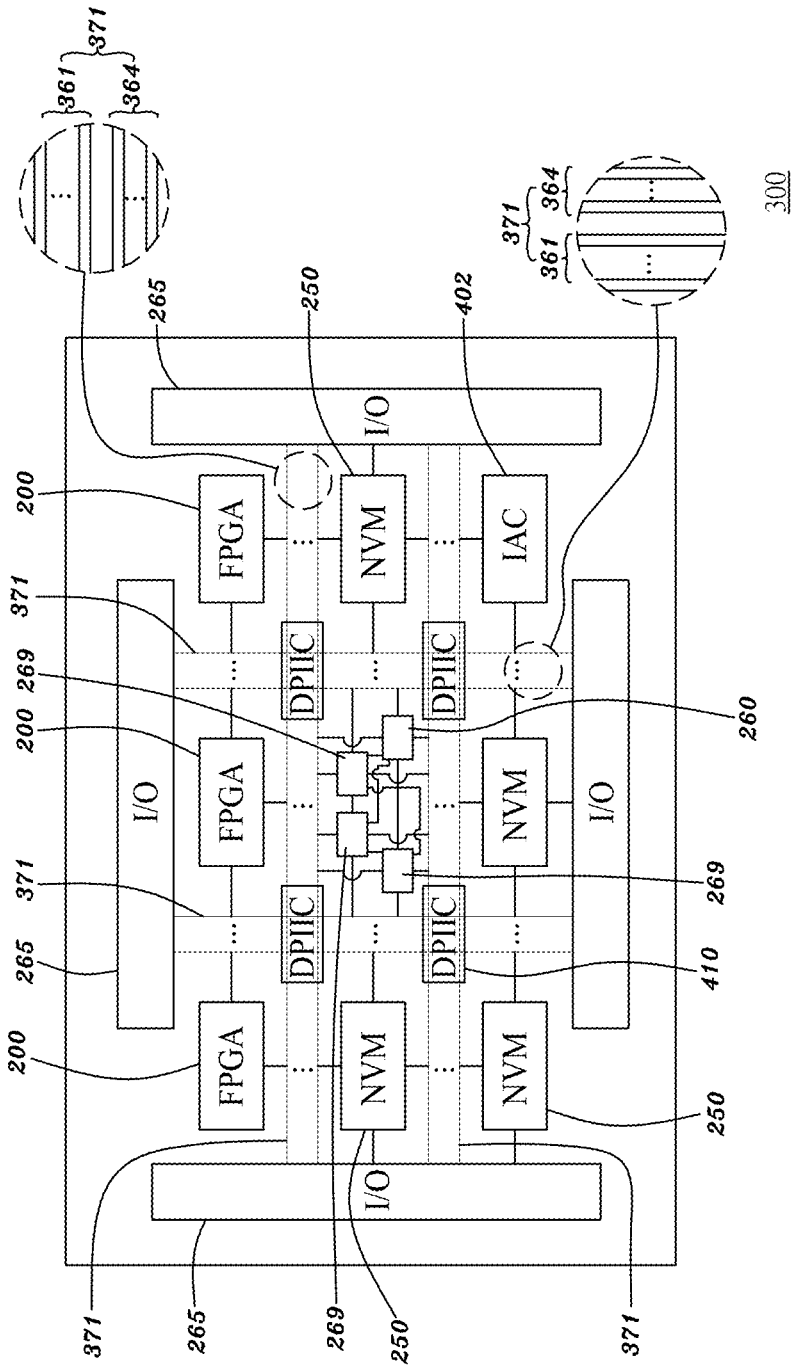

371
361
364
265
250
402
I/O
200
FPGA
NVM
IAC
DPIIC
269
260
410
300

Fig. 11K

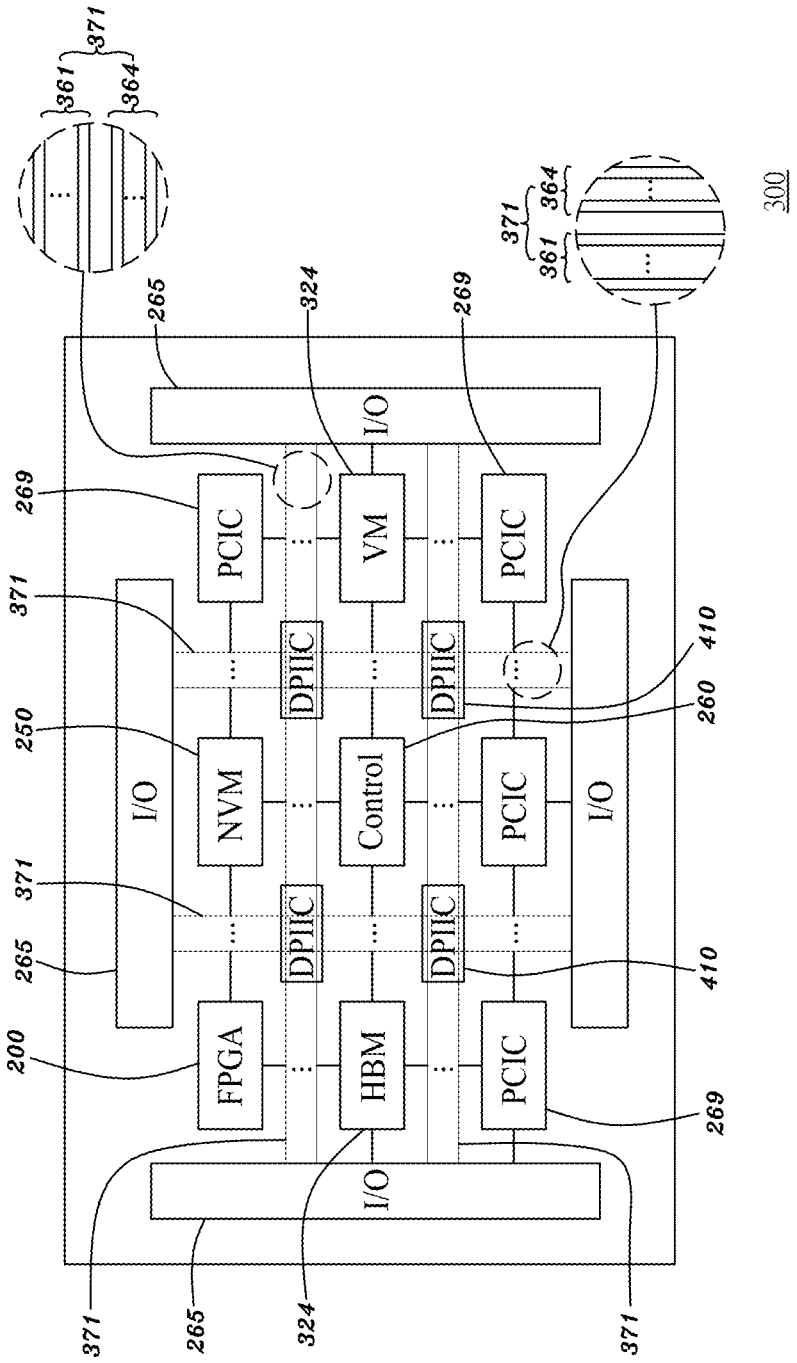

371
361
364
265
324
269
I/O
PCIC
VM
PCIC
DPIIC
DPIIC
410
260
250
I/O
NVM
Control
PCIC
I/O
DPIIC
DPIIC
410
265
200
FPGA
HBM
PCIC
269
I/O
371
265
324
371
300

Fig. 11L

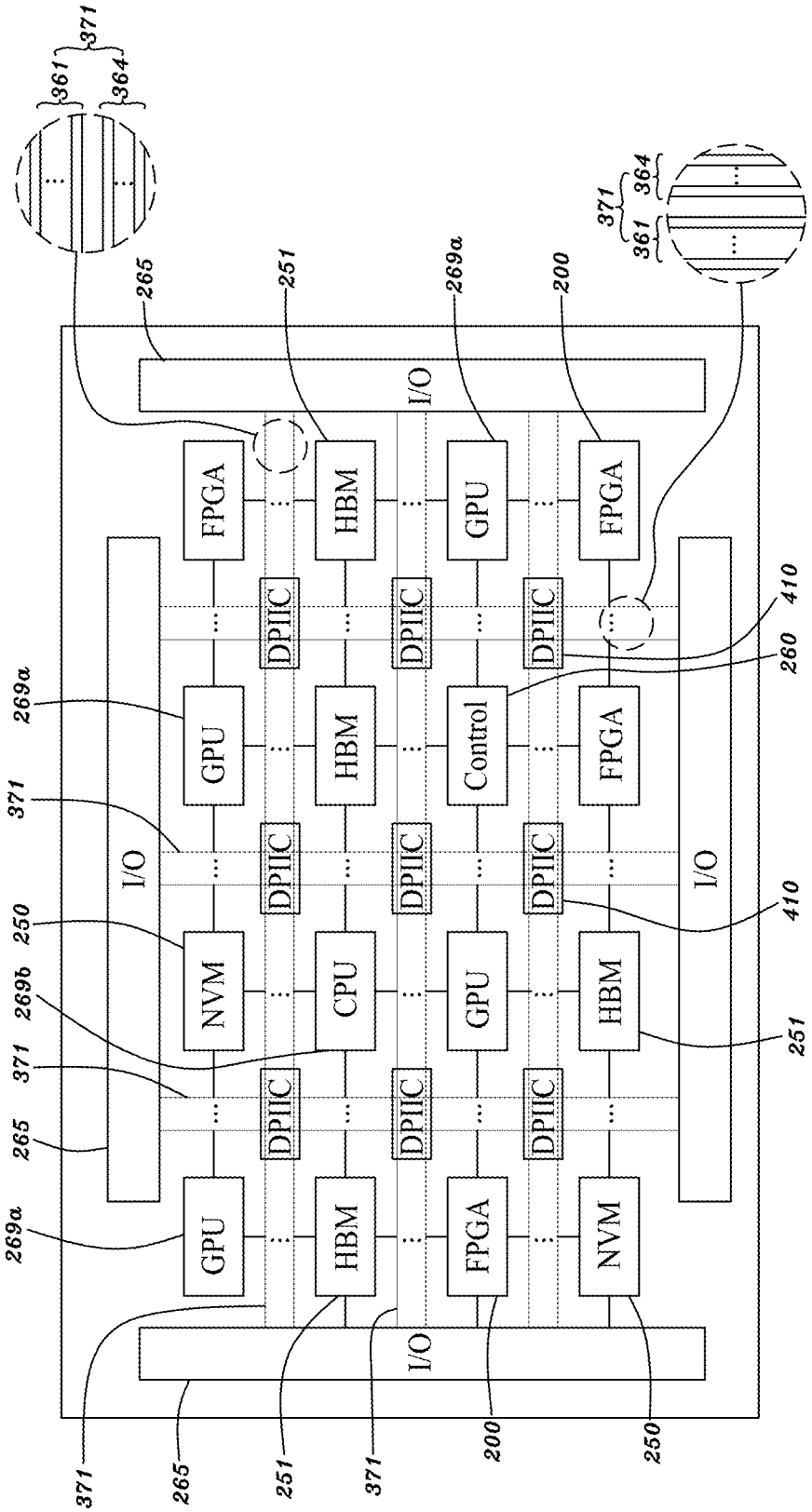

300
371
361
364
265
251
269a
200
I/O
FPGA
HBM
GPU
FPGA
DPIIC
410
260
Control
NVM
CPU
269b
250

Fig. 11M

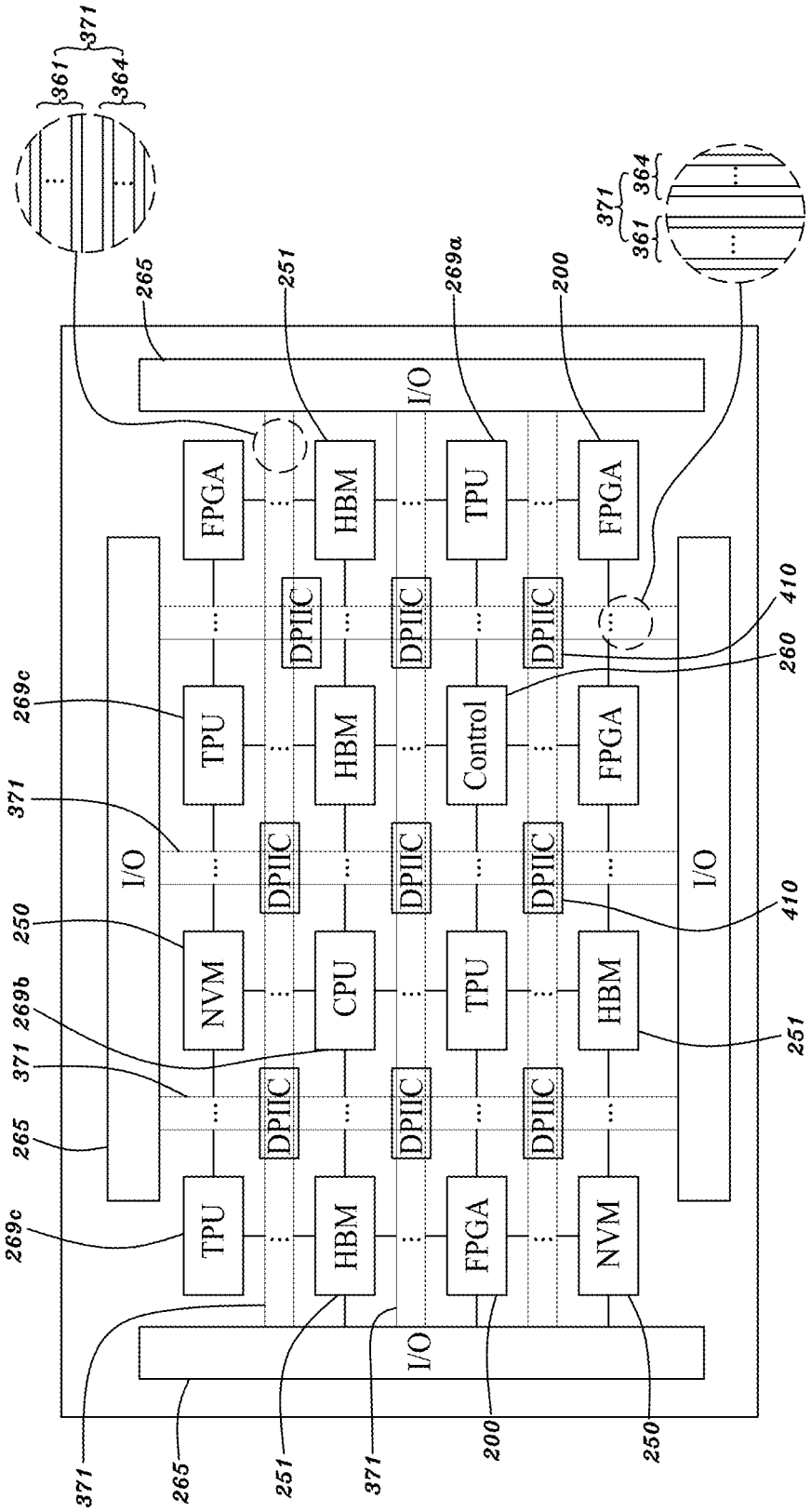

300
371
361
364
265
251
269a
200
I/O
FPGA
HBM
TPU
DPIIC
410
260
269c
Control
371
250
NVM
CPU
269b
251
265
269c
371
265
251
371
200
250

Fig. 11N

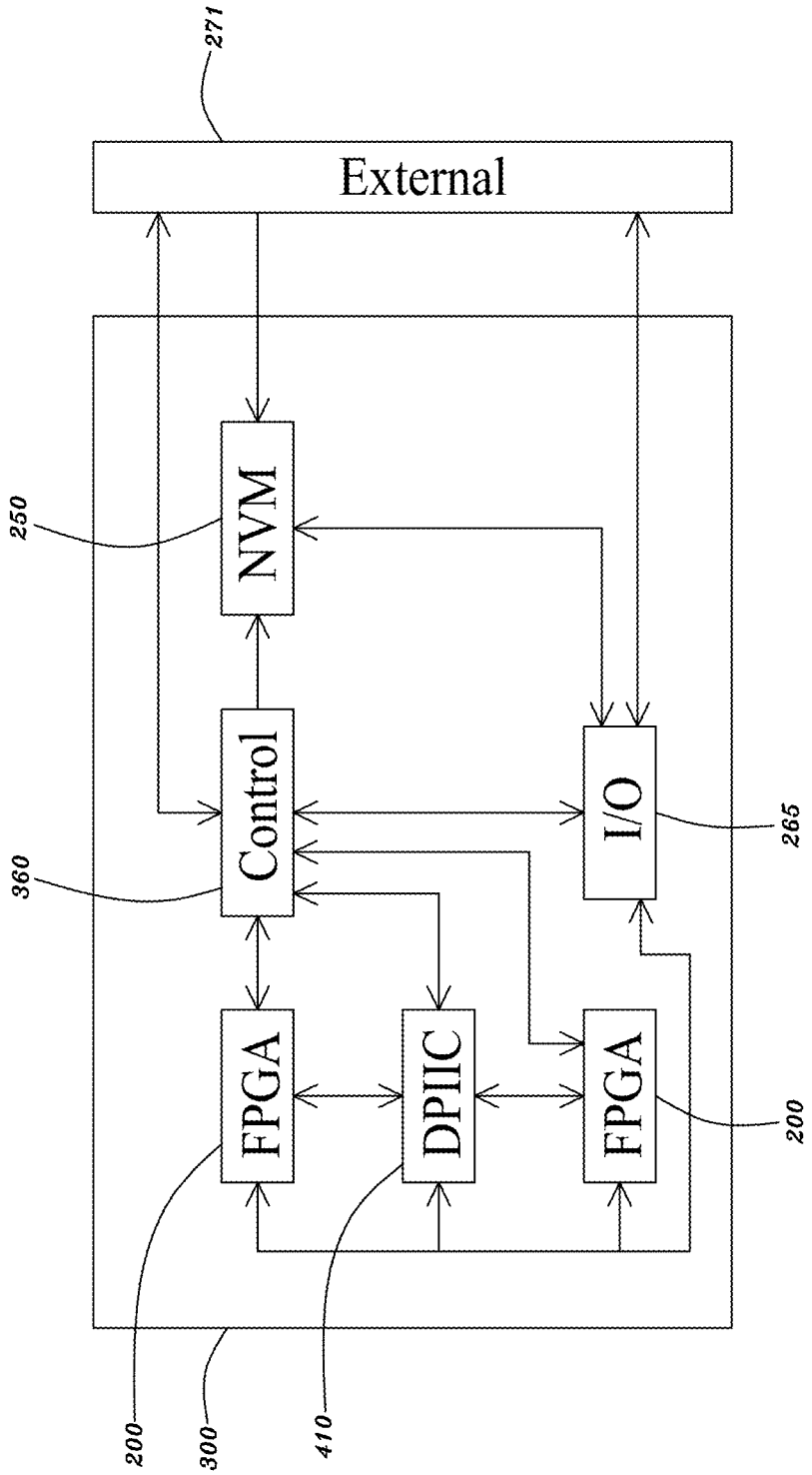

271
External
NVM
250
Control
360
I/O
265
FPGA
DPIIC
FPGA
200
200
300
410

Fig. 12A

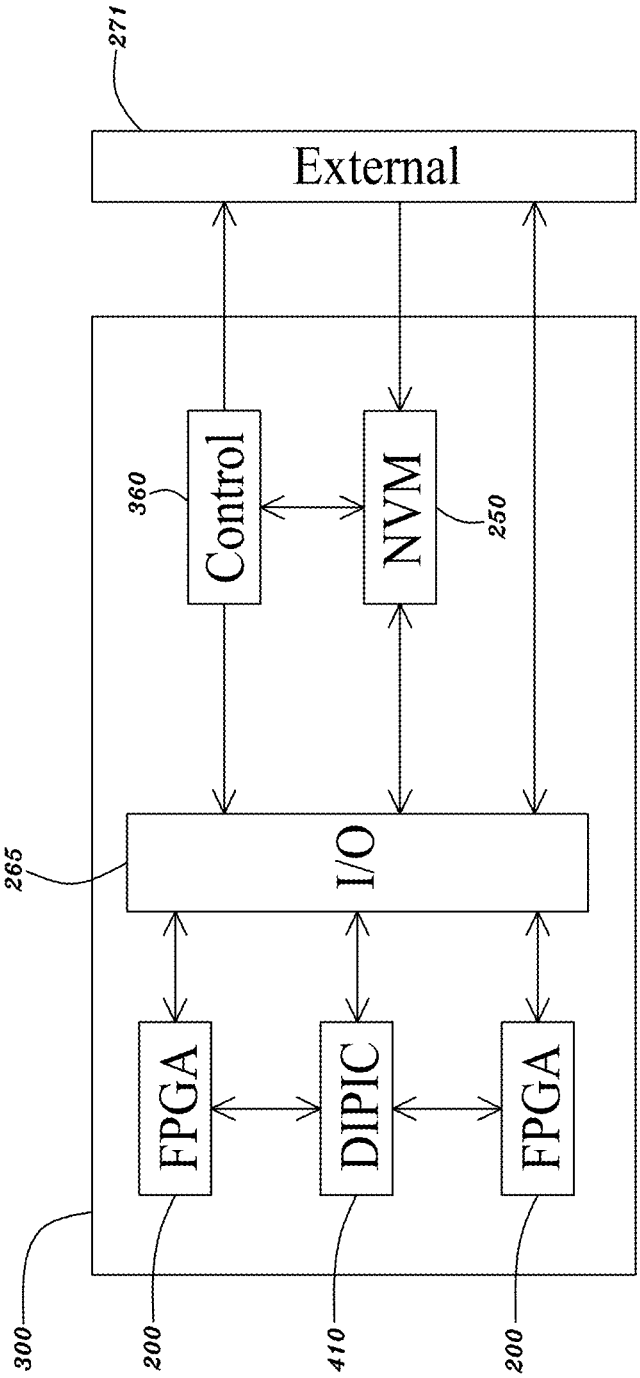

271
External
360
Control
NVM
250
265
I/O
FPGA
DIPIC
FPGA
300
200
410
200

Fig. 12B

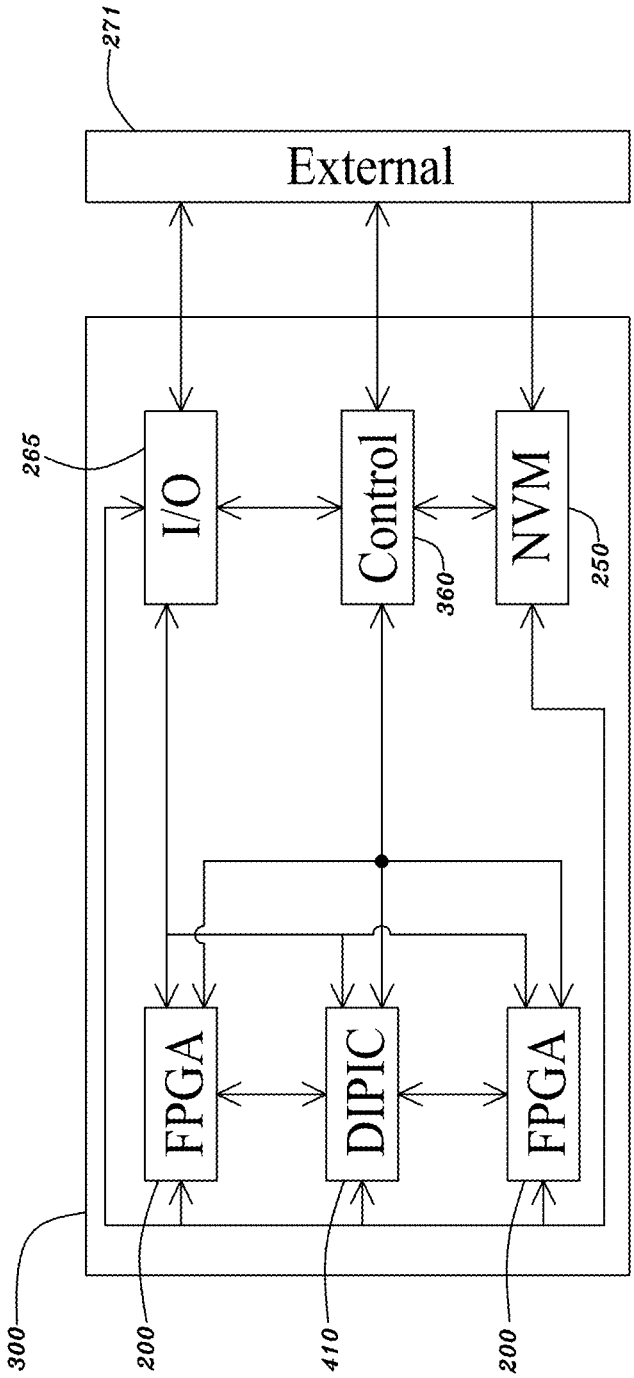

271
External
265
I/O
Control
NVM
360
250
FPGA
DIPIC
FPGA
300
200
410
200

Fig. 12C

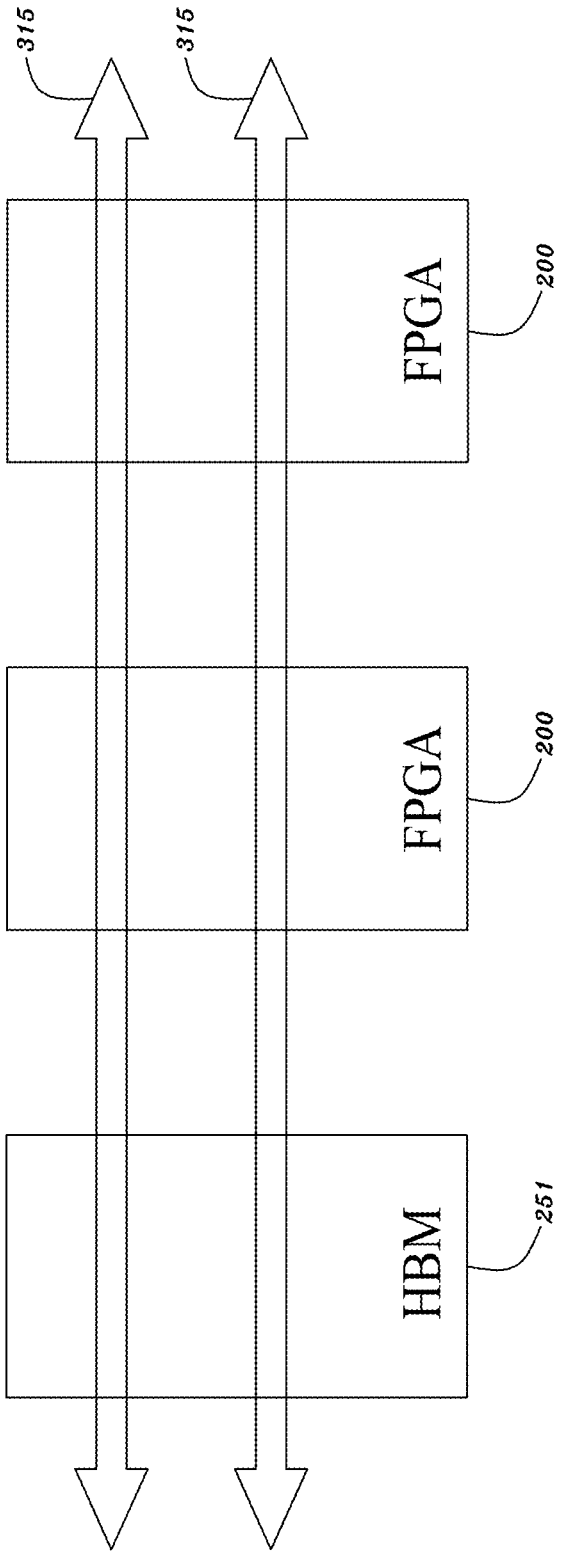


Fig. 12D

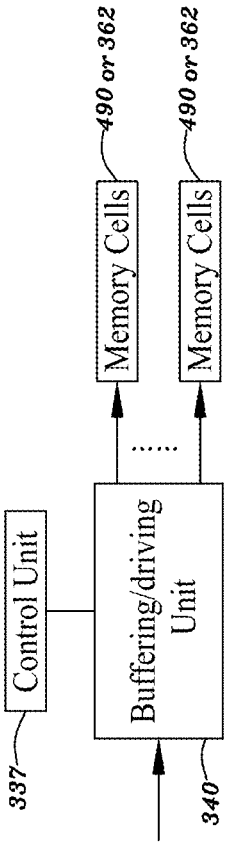

Control Unit
Buffering/driving Unit
Memory Cells
Memory Cells
490 or 362
490 or 362
337
340

Fig. 13A

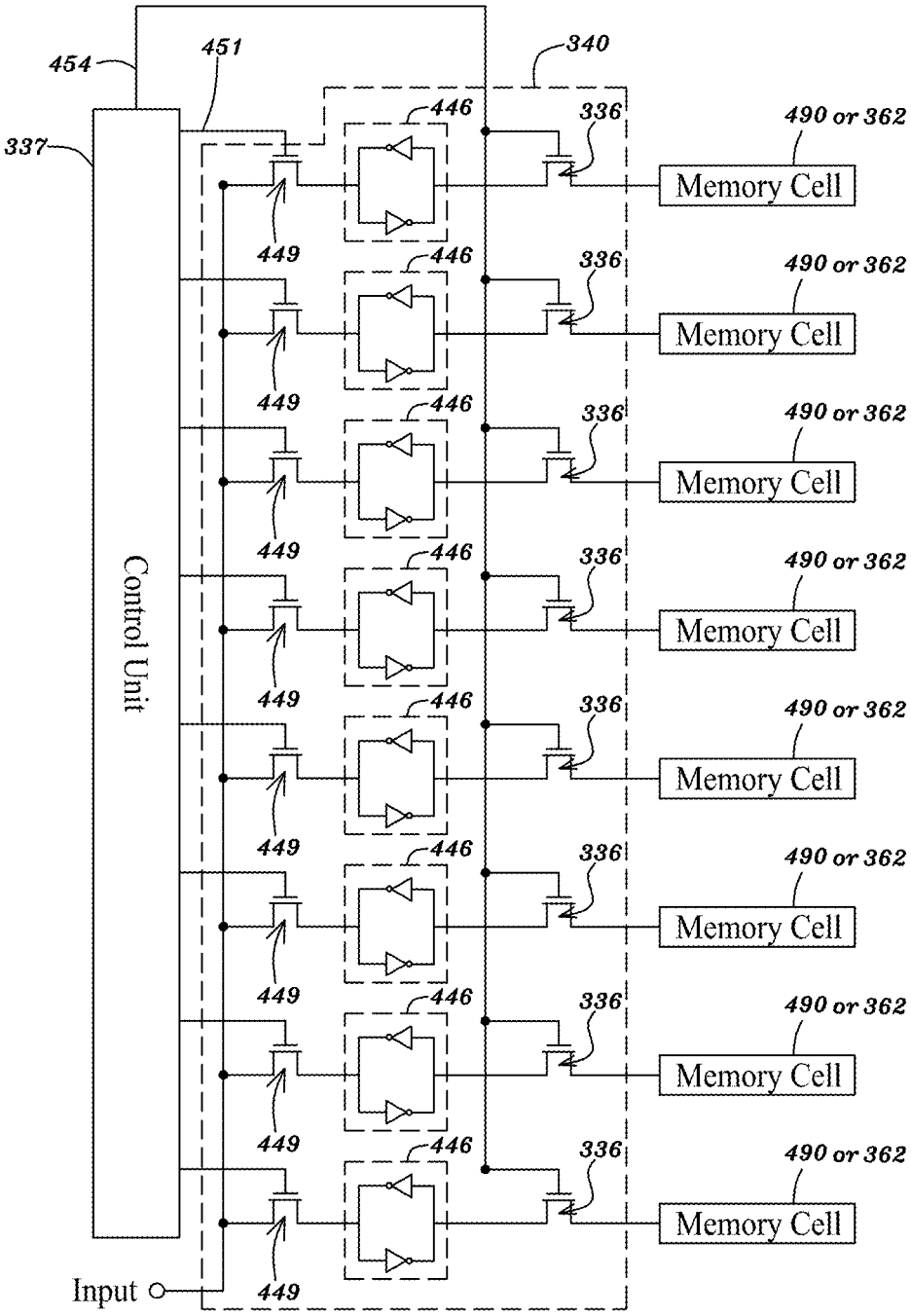

454
451
340
337
446
336
490 or 362
Memory Cell
449
Control Unit
Input

Fig. 13B

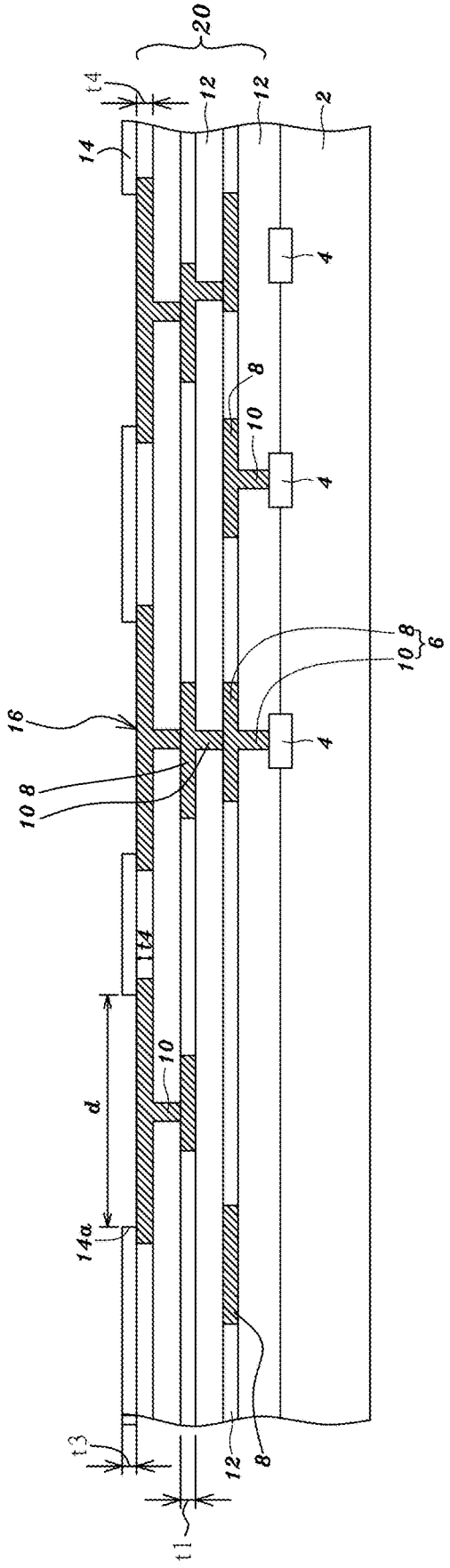


Fig. 14A

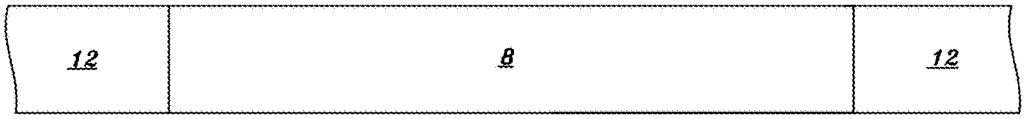


Fig. 14B

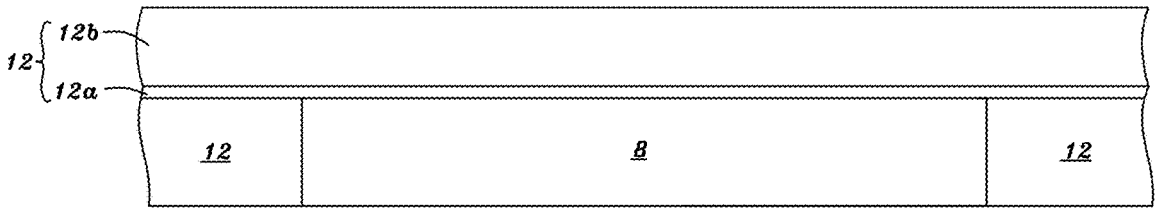


Fig. 14C

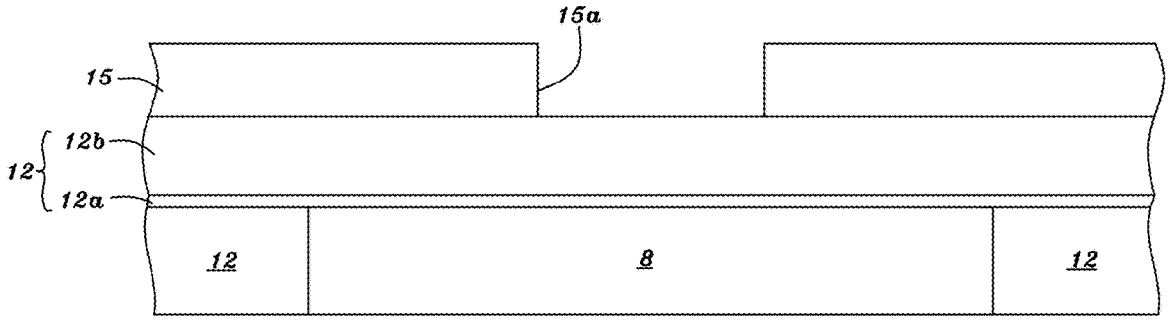


Fig. 14D

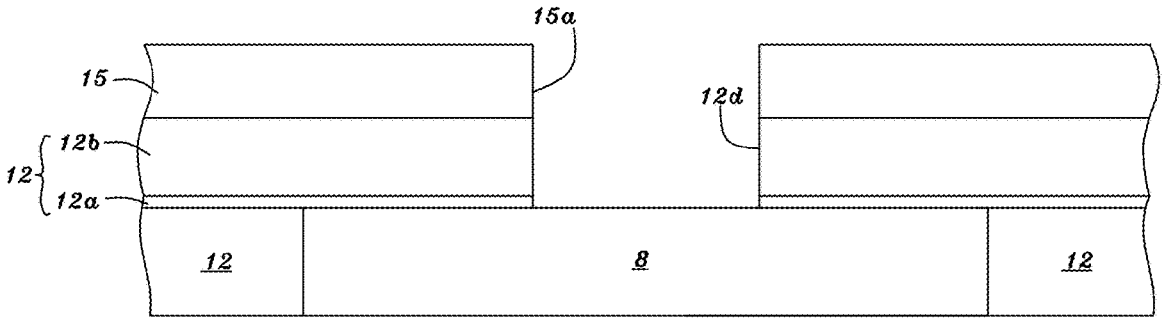


Fig. 14E

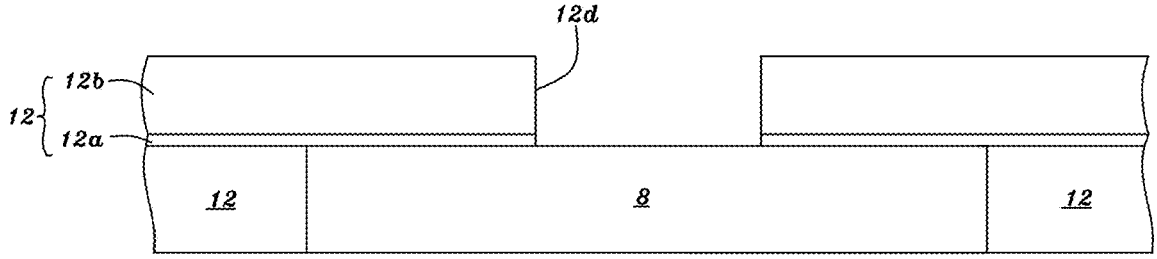


Fig. 14F

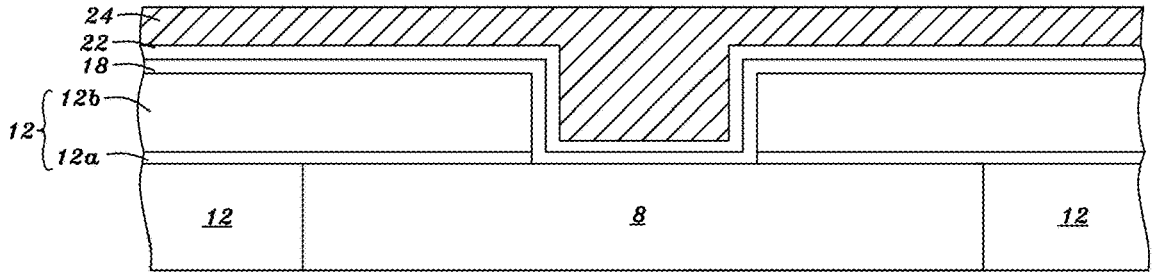


Fig. 14G

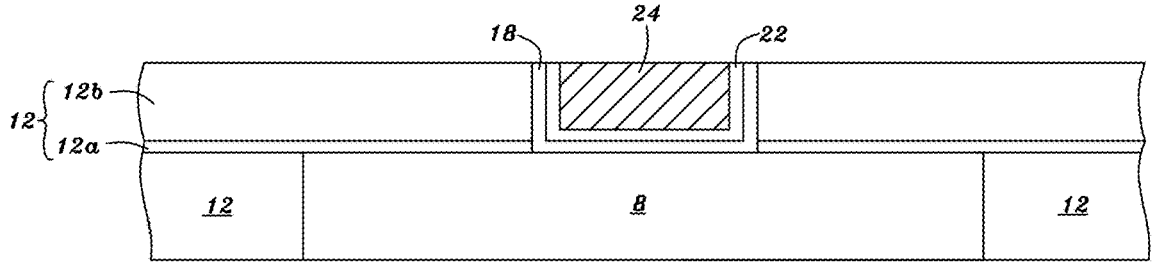


Fig. 14H

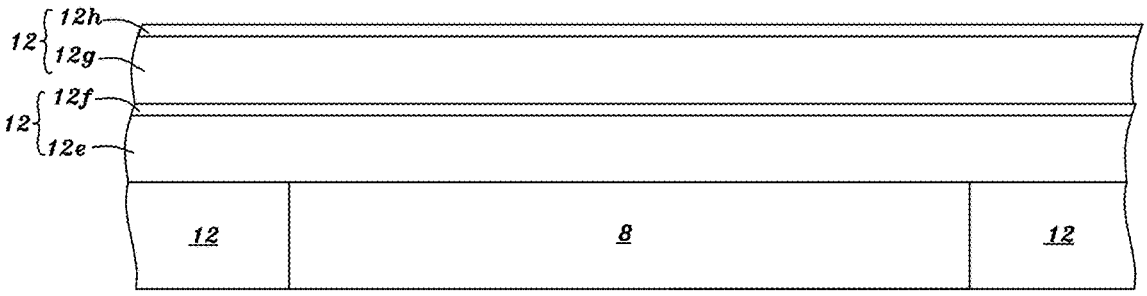


Fig. 14I

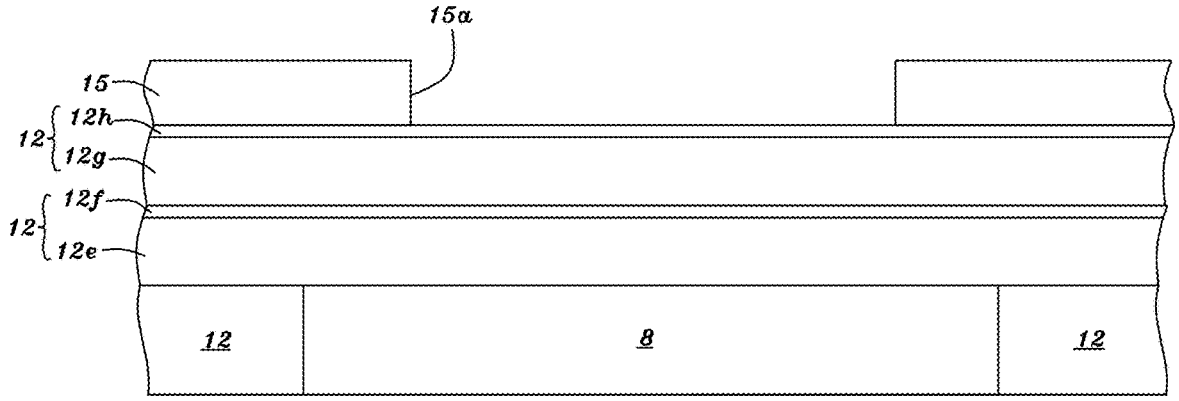


Fig. 14J

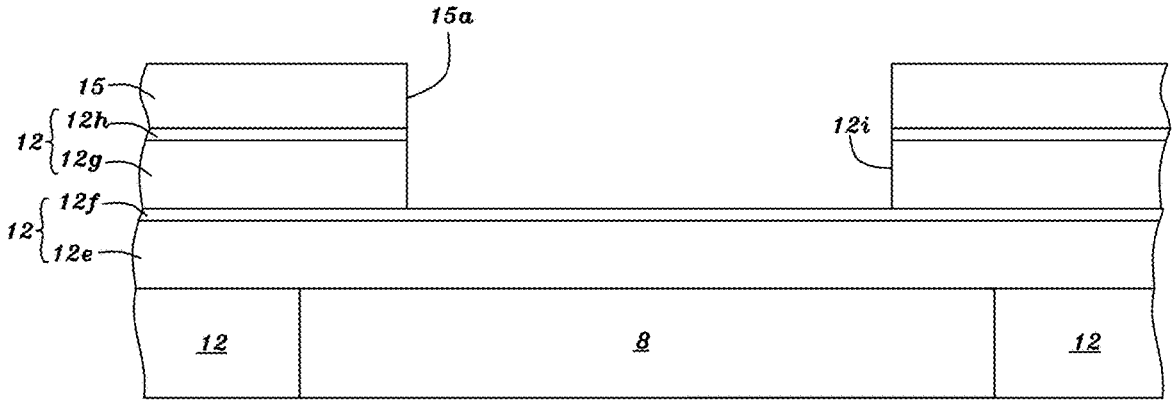


Fig. 14K

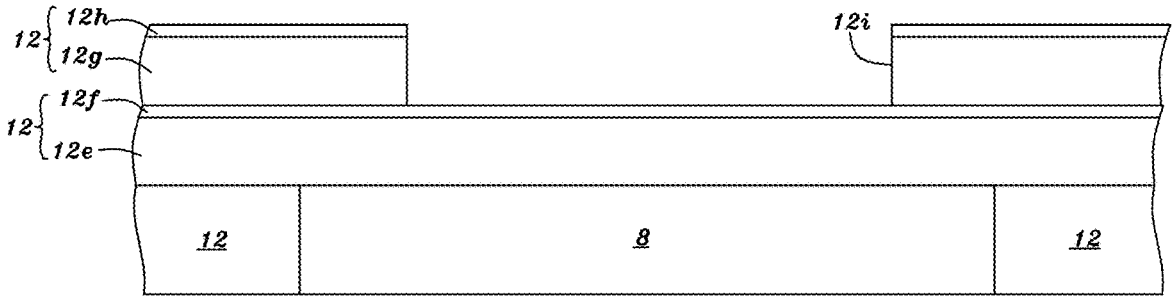


Fig. 14L

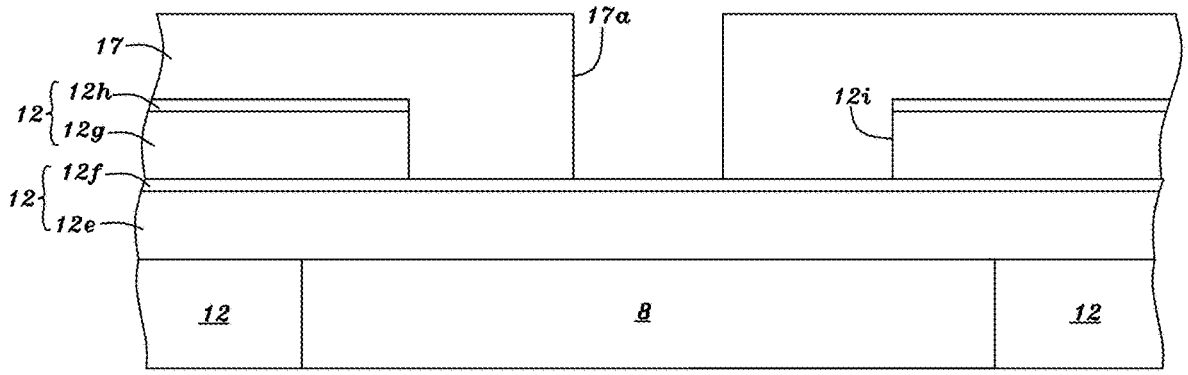


Fig. 14M

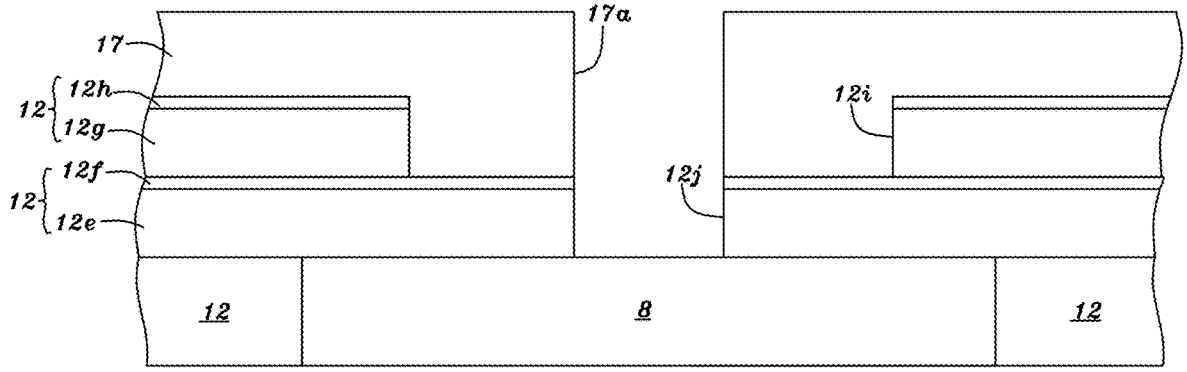


Fig. 14N

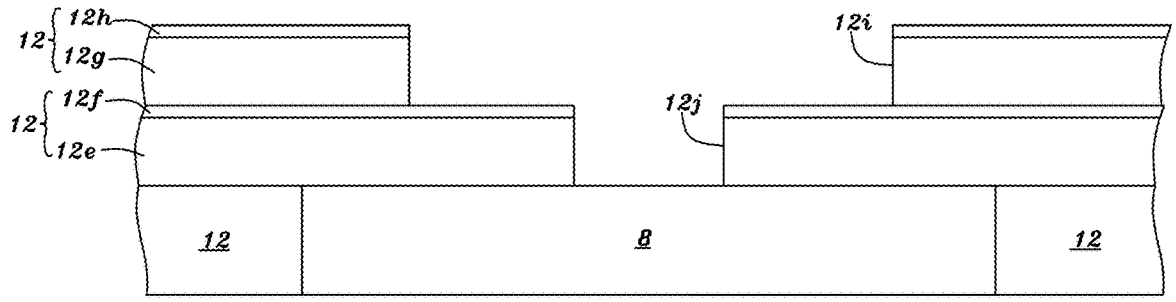


Fig. 14O

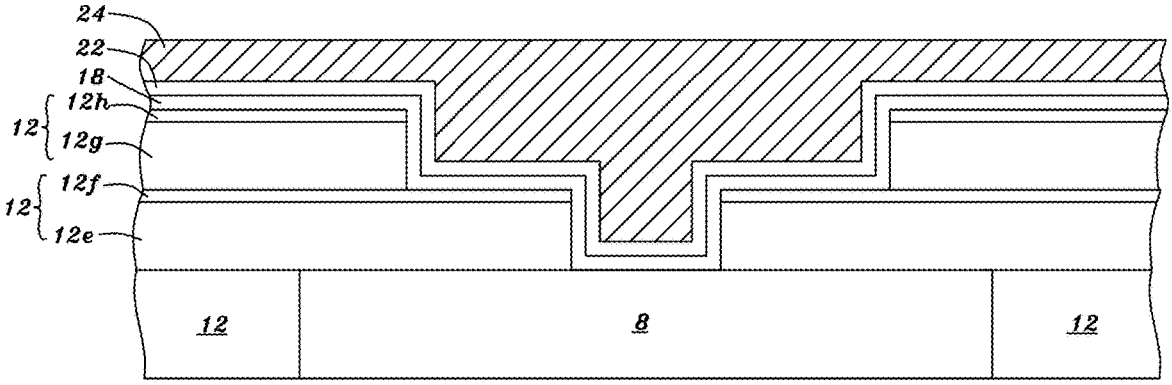


Fig. 14P

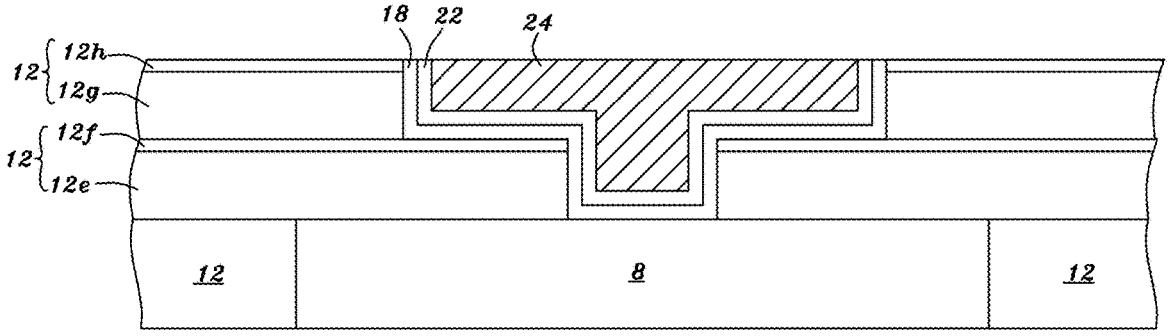


Fig. 14Q

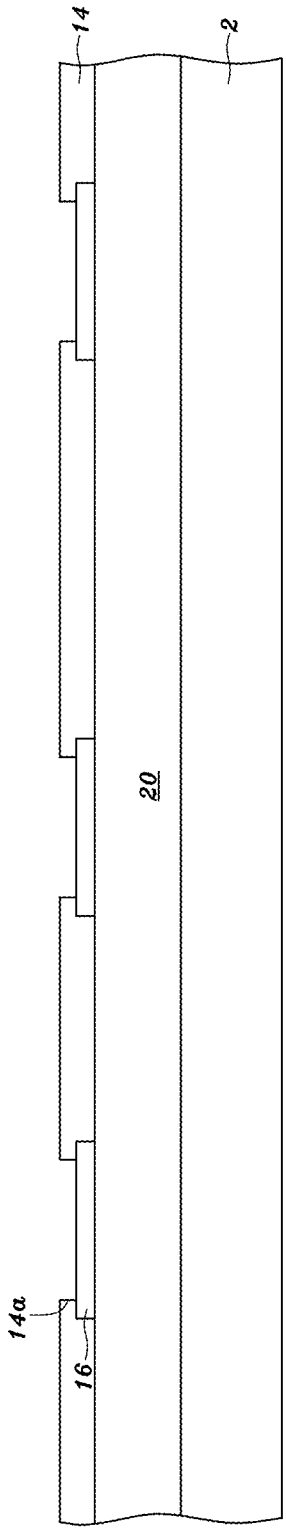


Fig. 15A

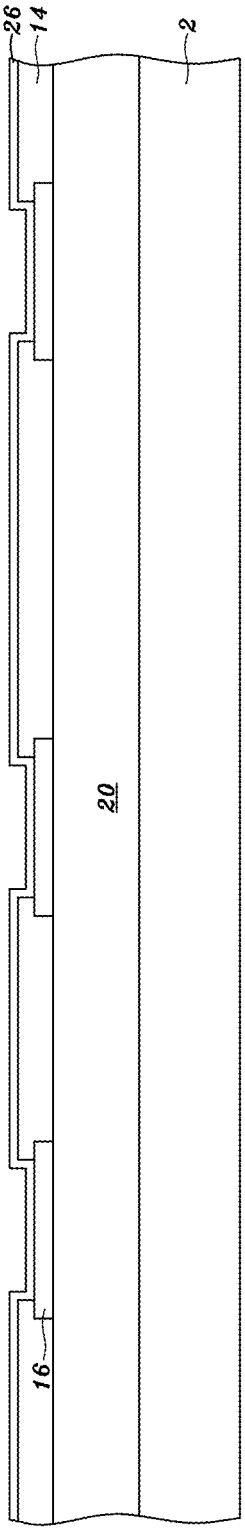


Fig. 15B

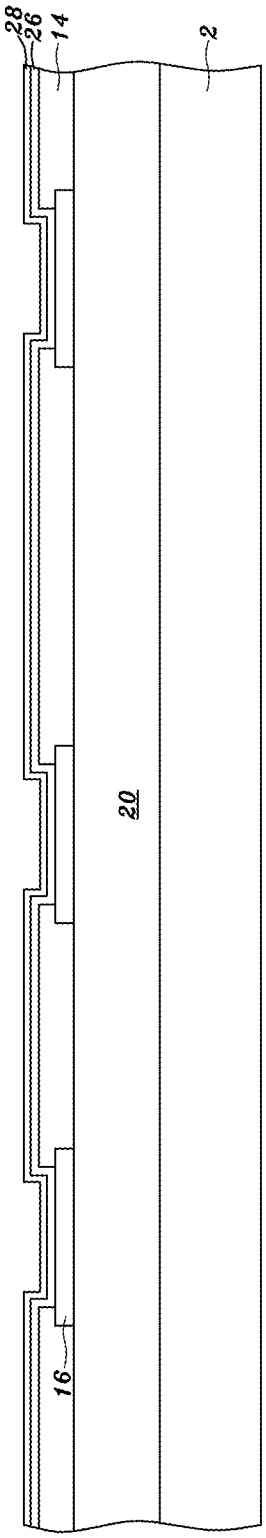


Fig. 15C

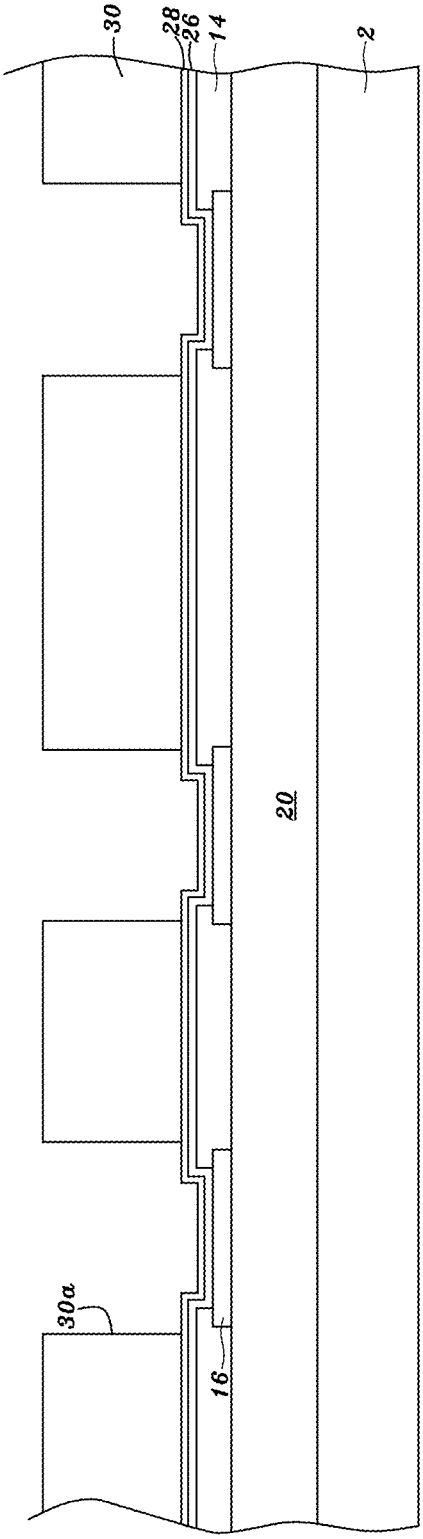


Fig. 15D

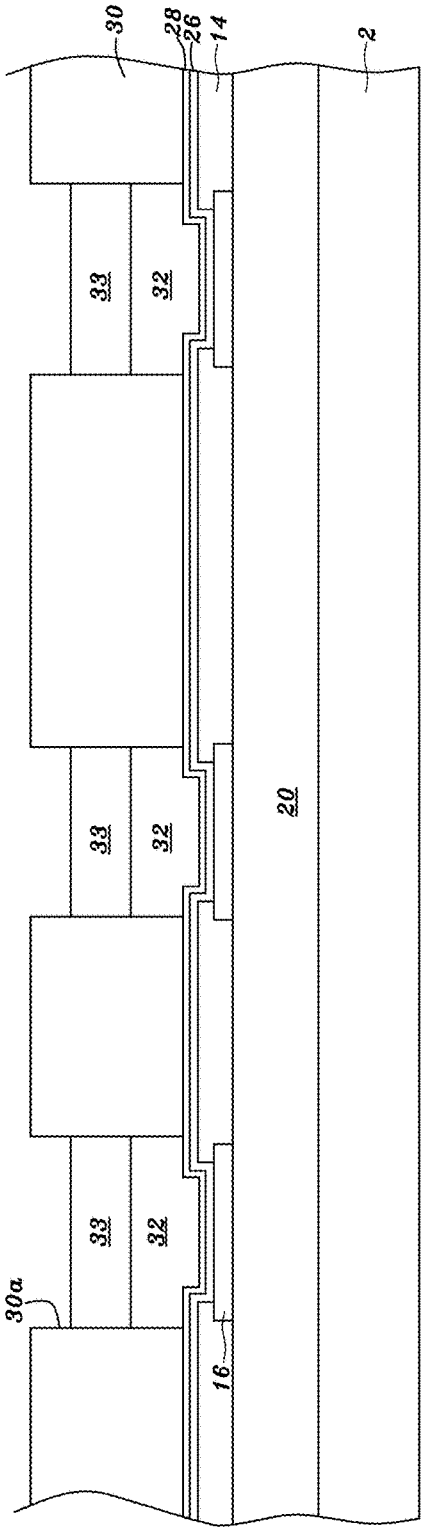


Fig. 15E

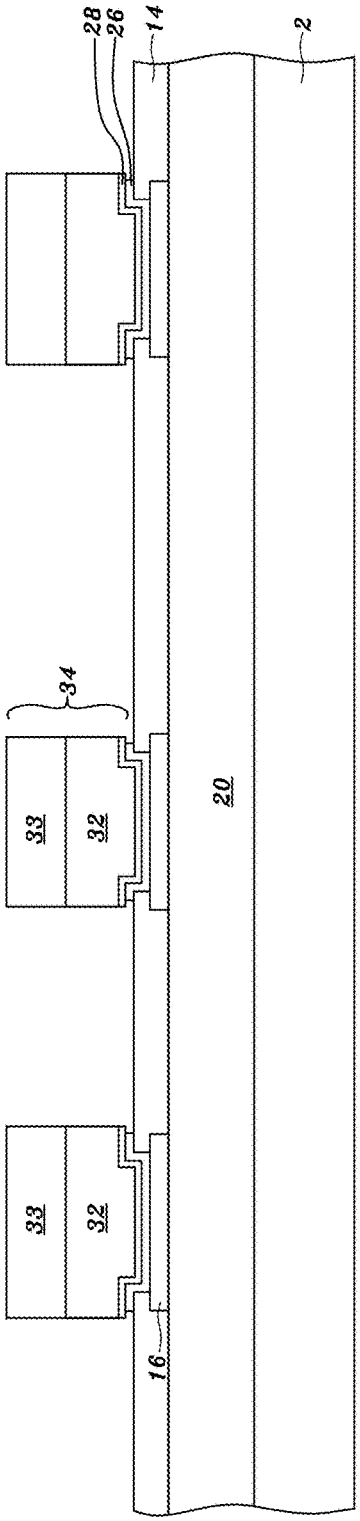


Fig. 15F

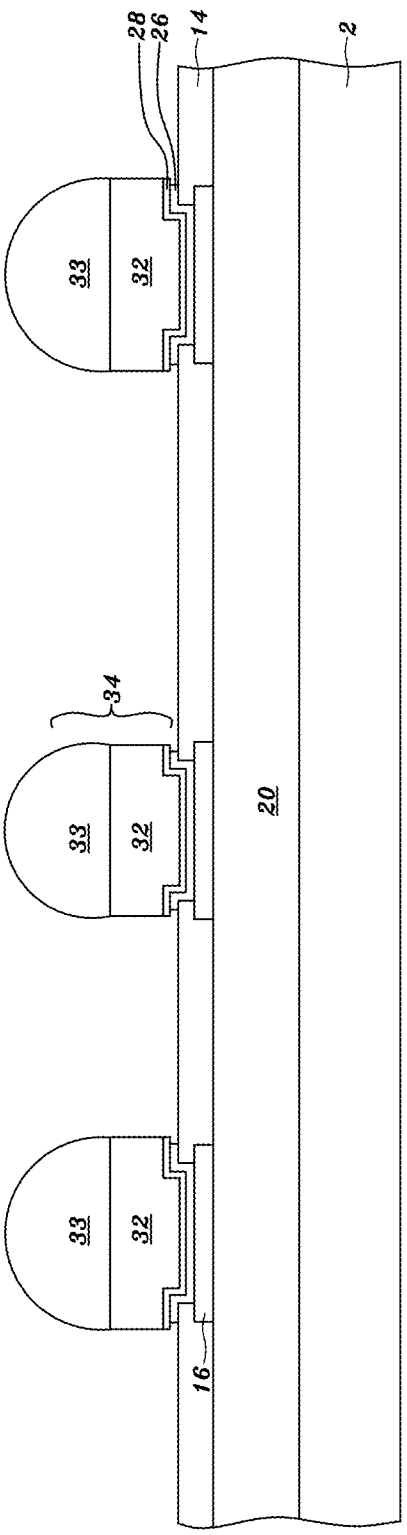


Fig. 15G

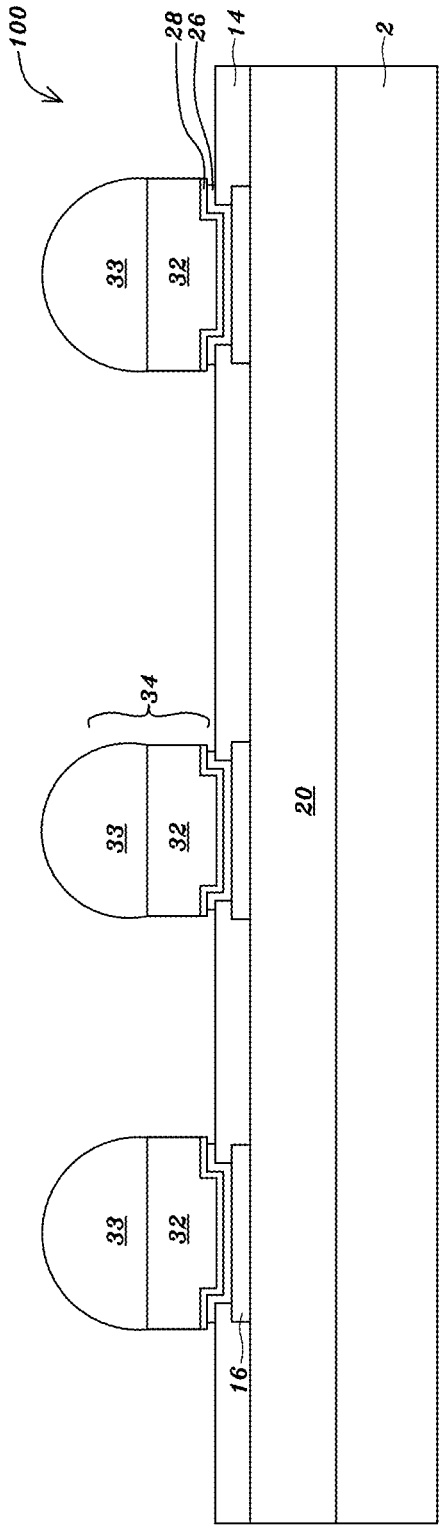


Fig. 15H

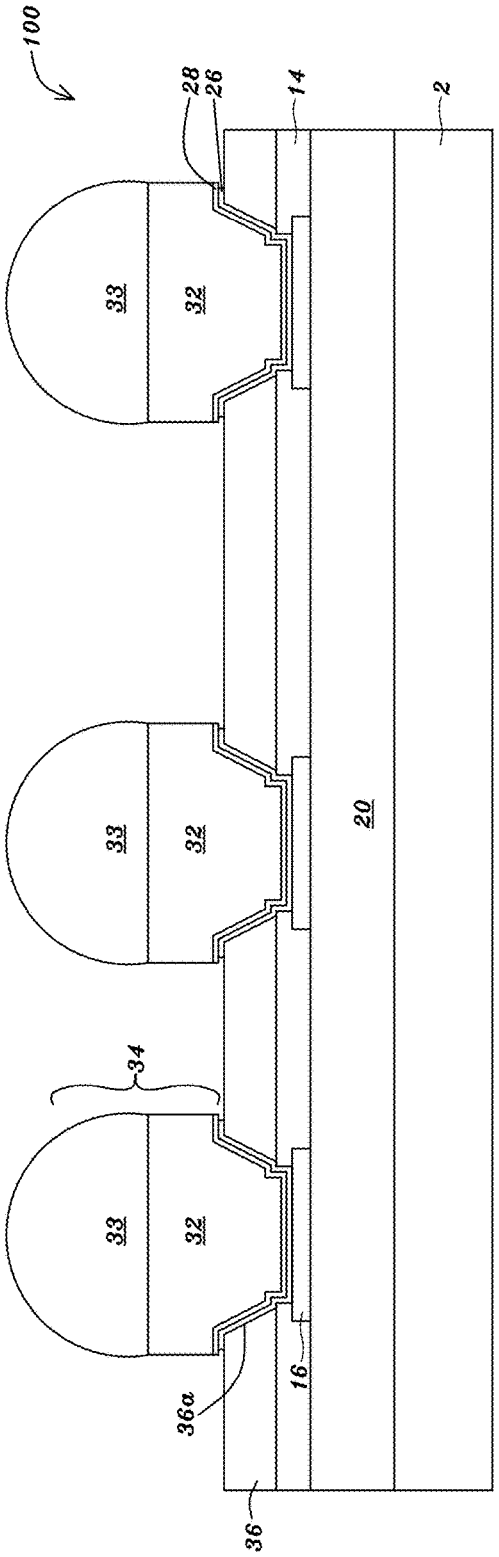


Fig. 15I

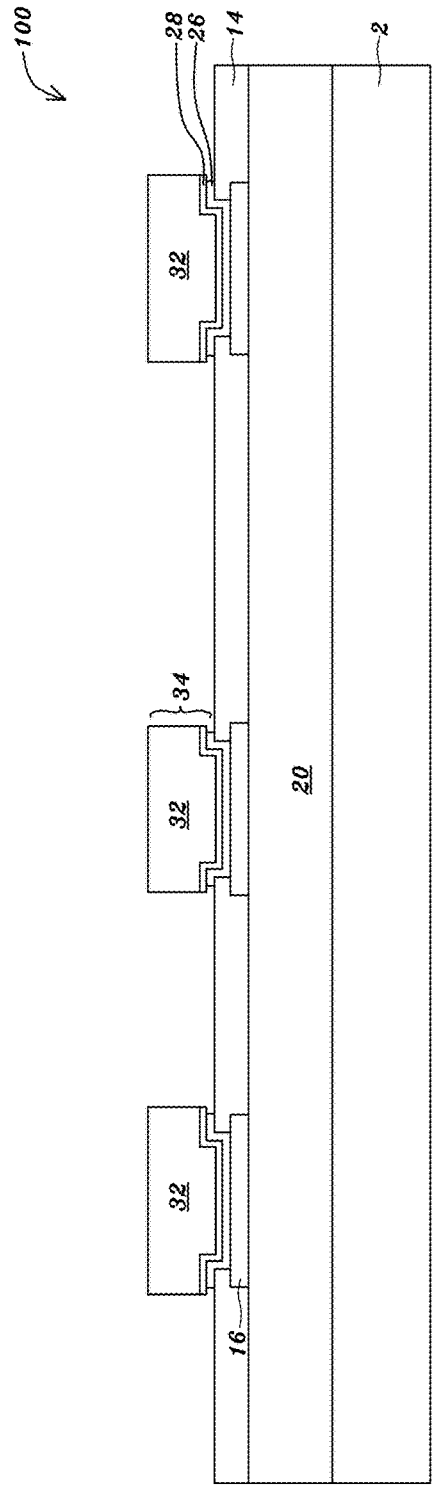


Fig. 15J

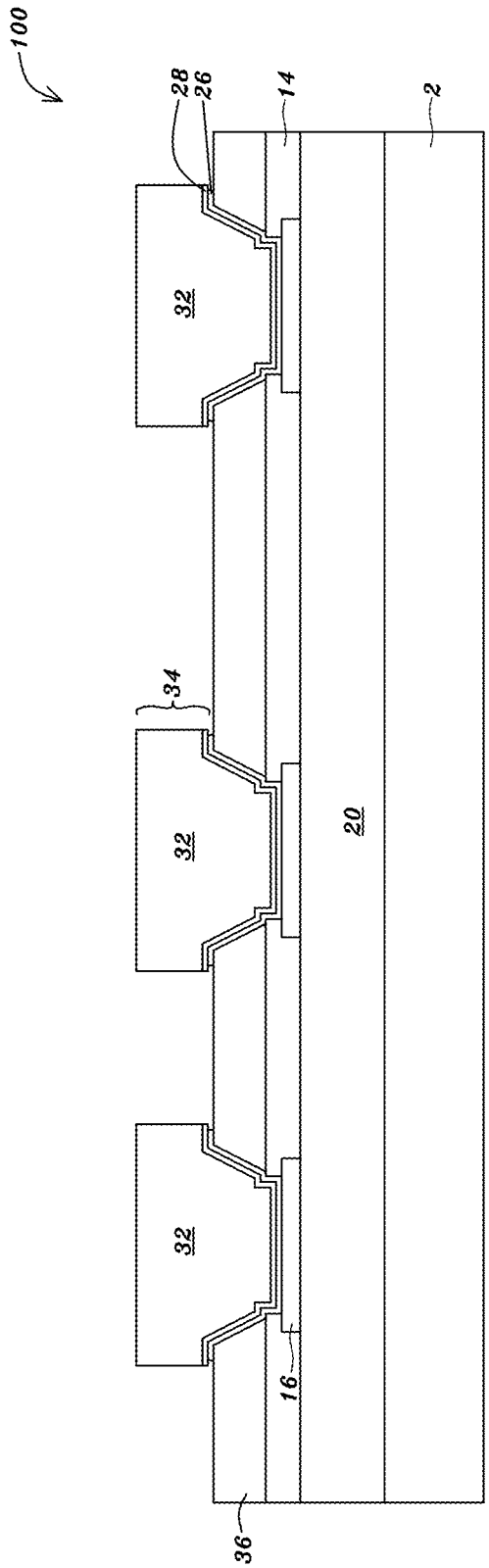


Fig. 15K

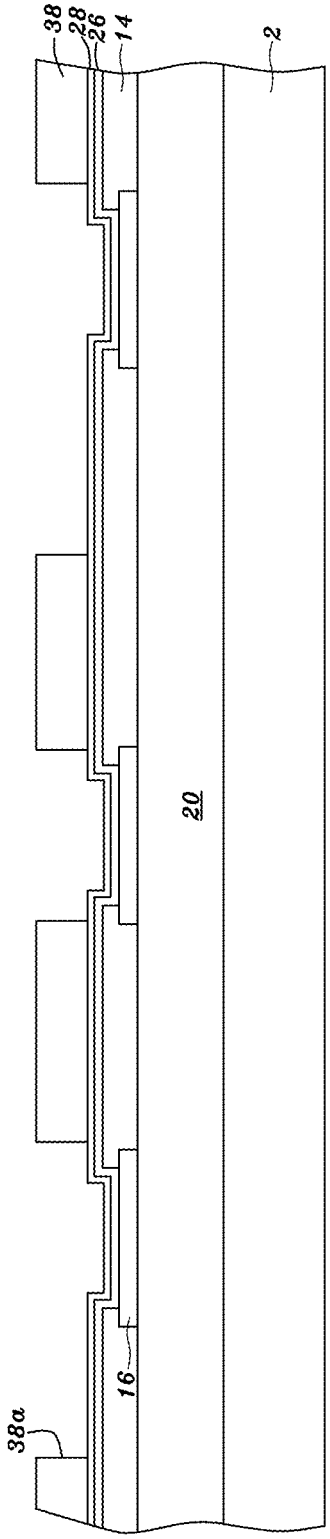


Fig. 16A

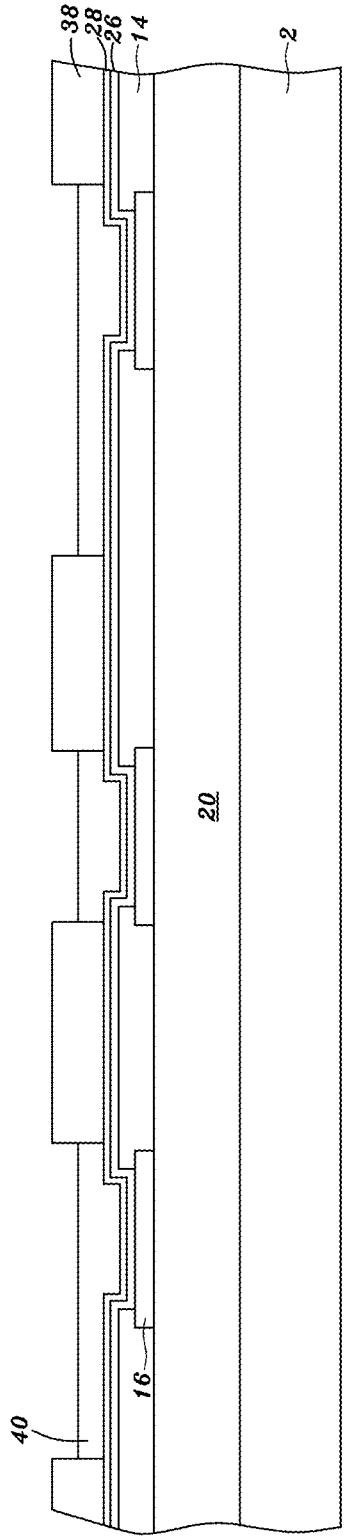


Fig. 16B

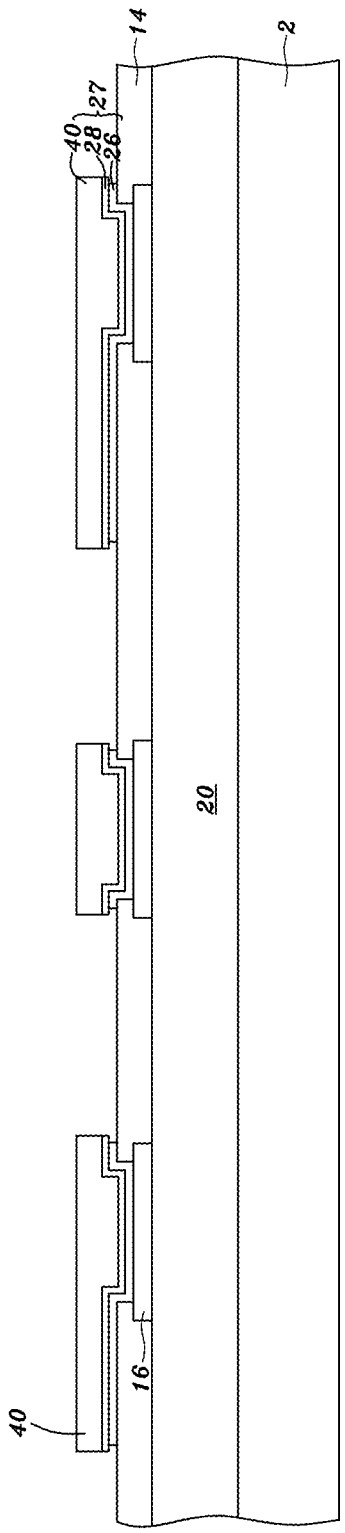


Fig. 16C

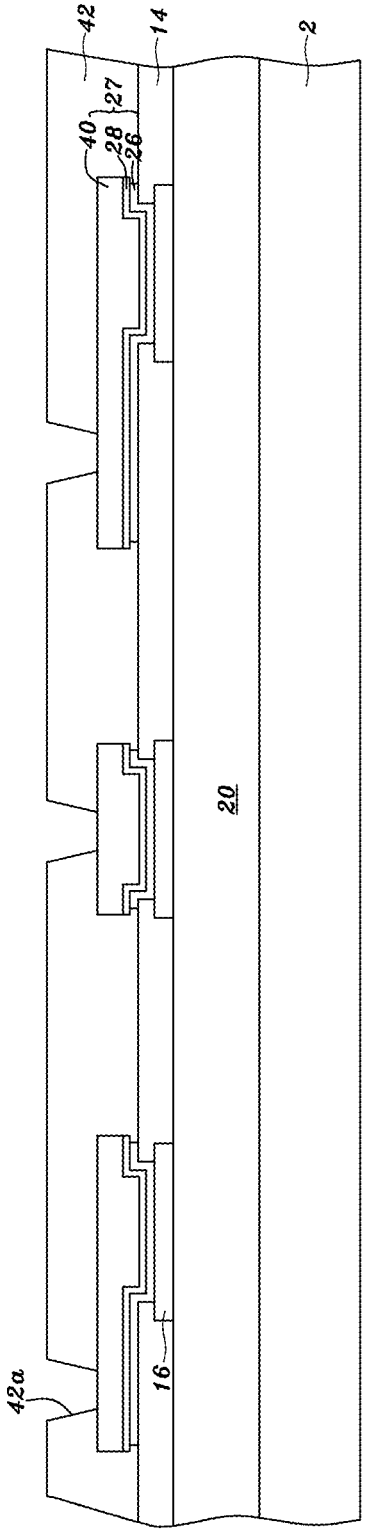


Fig. 16D

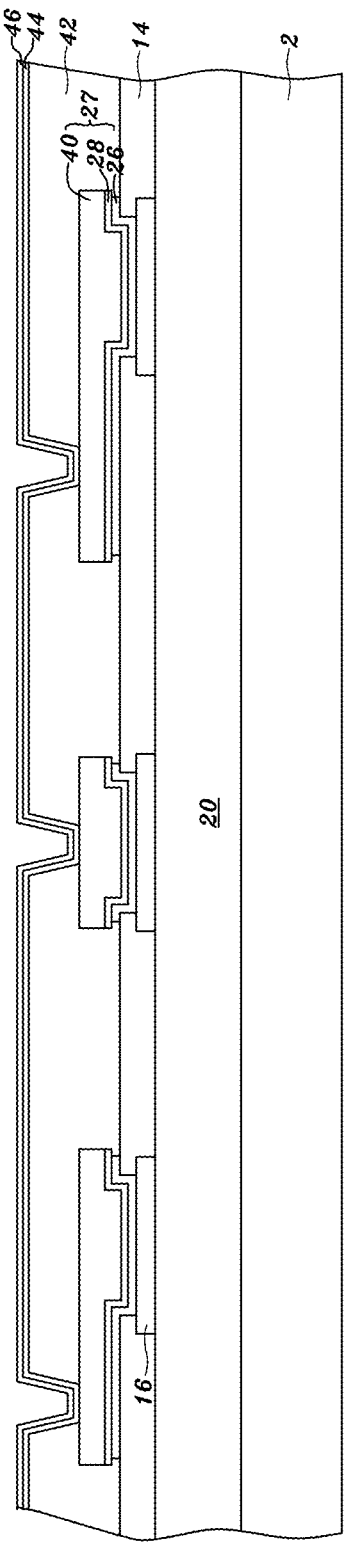


Fig. 16E

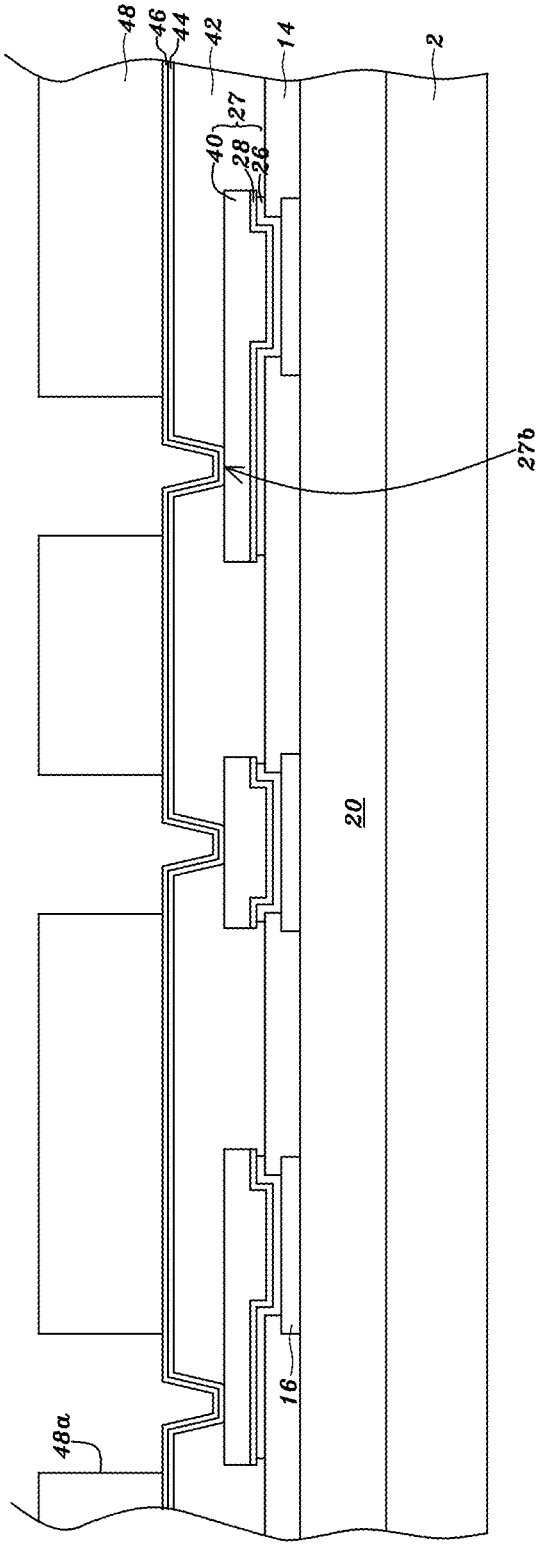


Fig. 16F

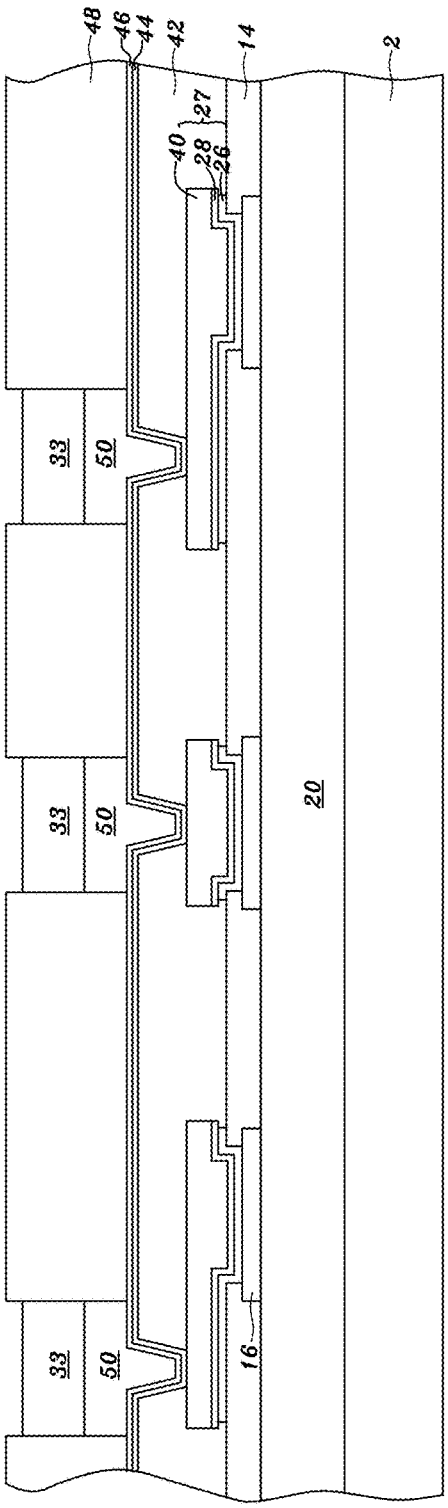


Fig. 16G

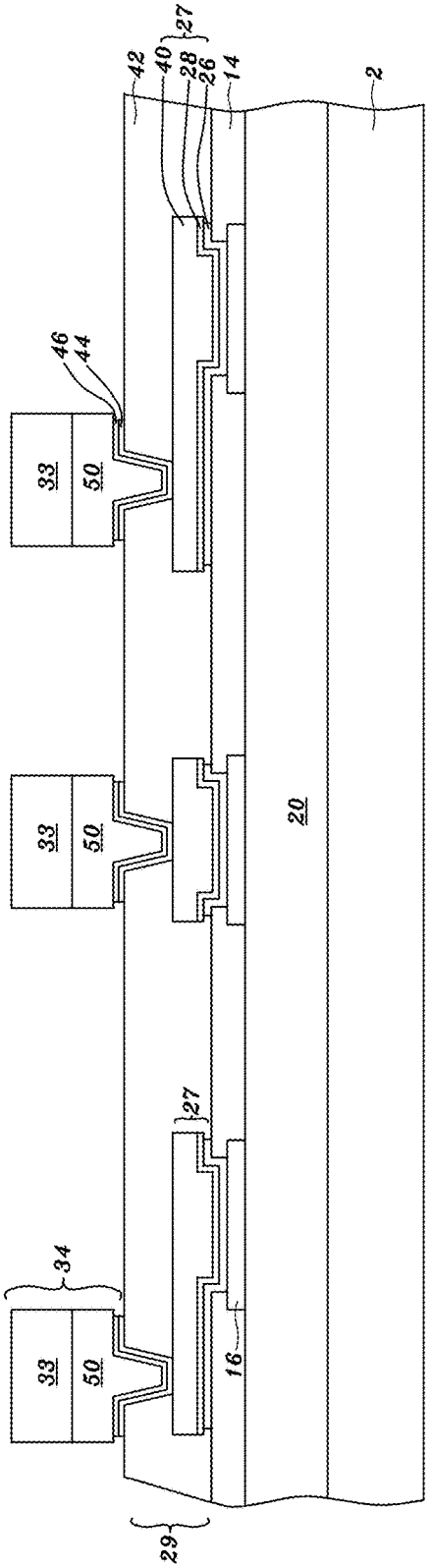


Fig. 16H

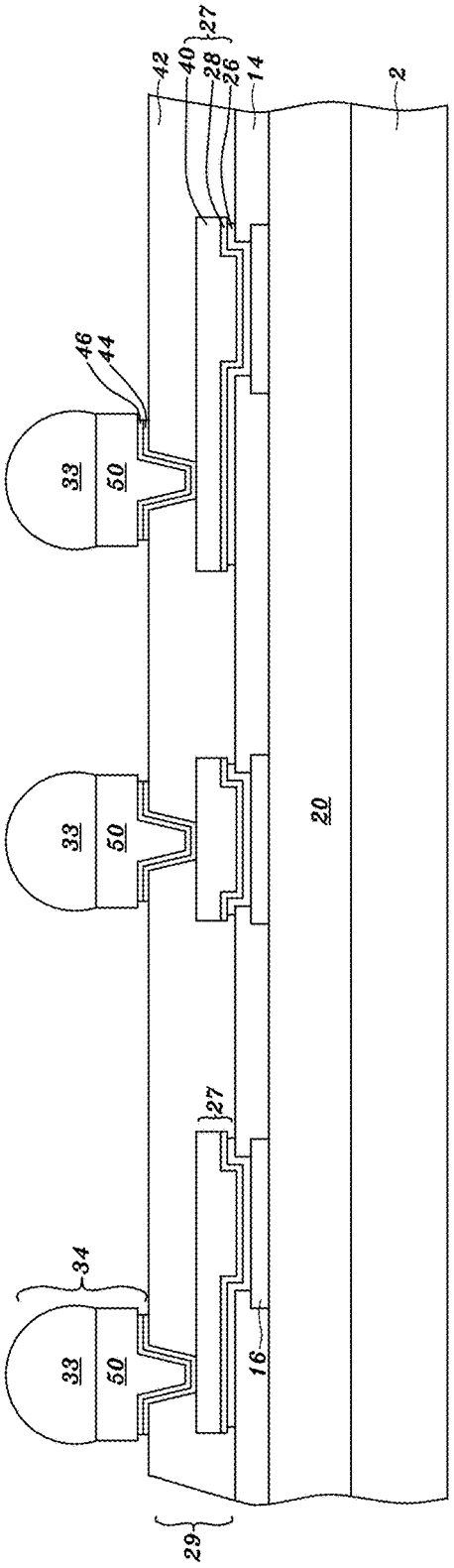


Fig. 16I

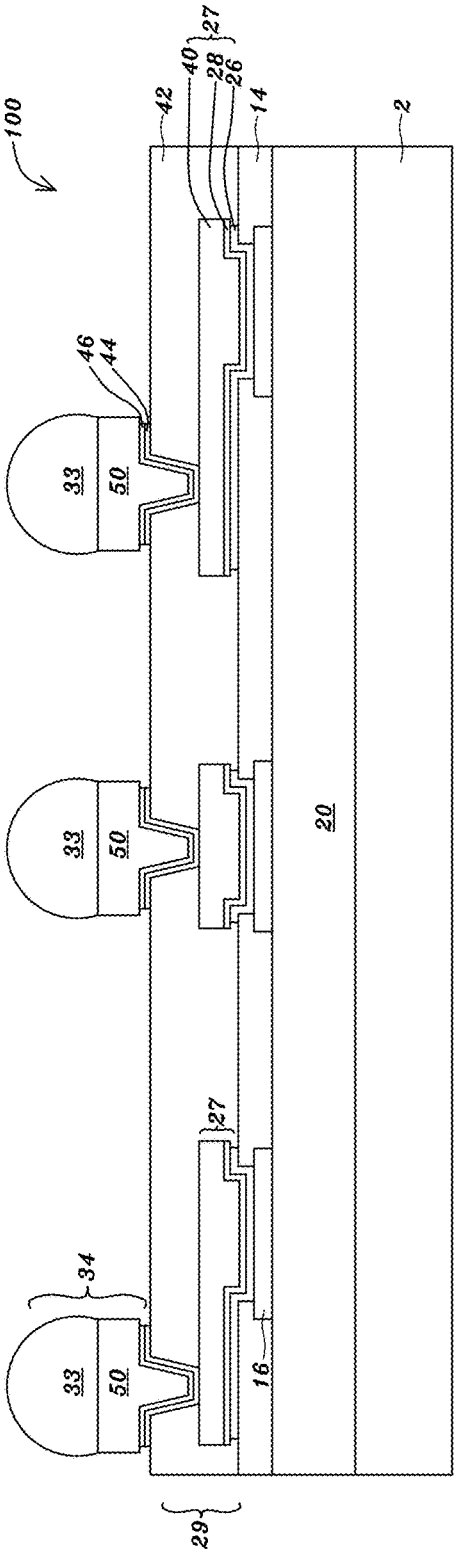


Fig. 16J

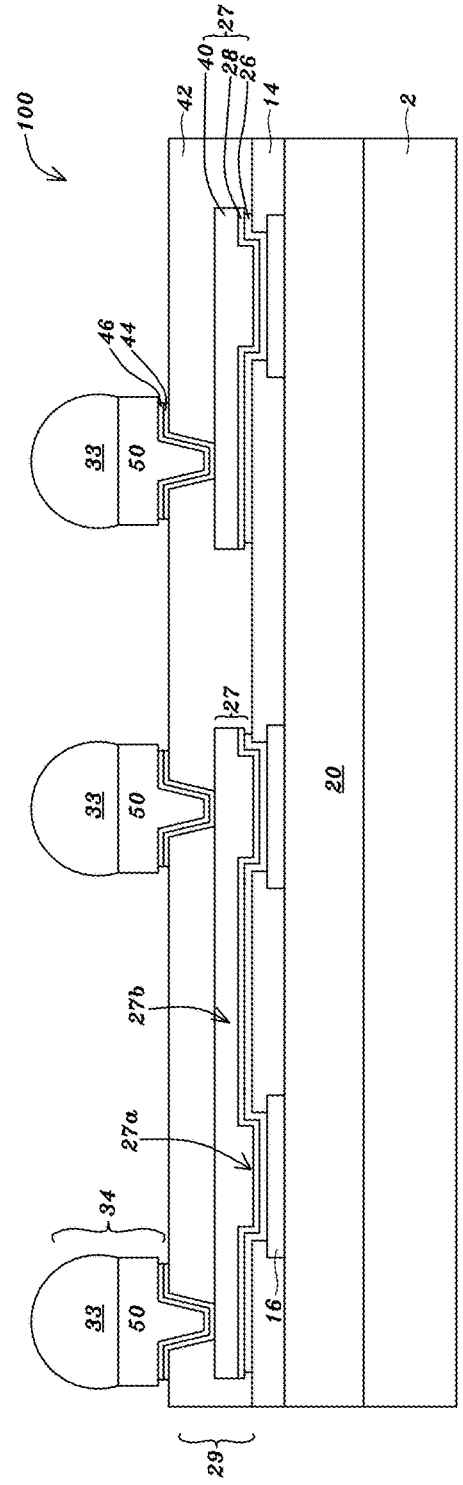


Fig. 16K

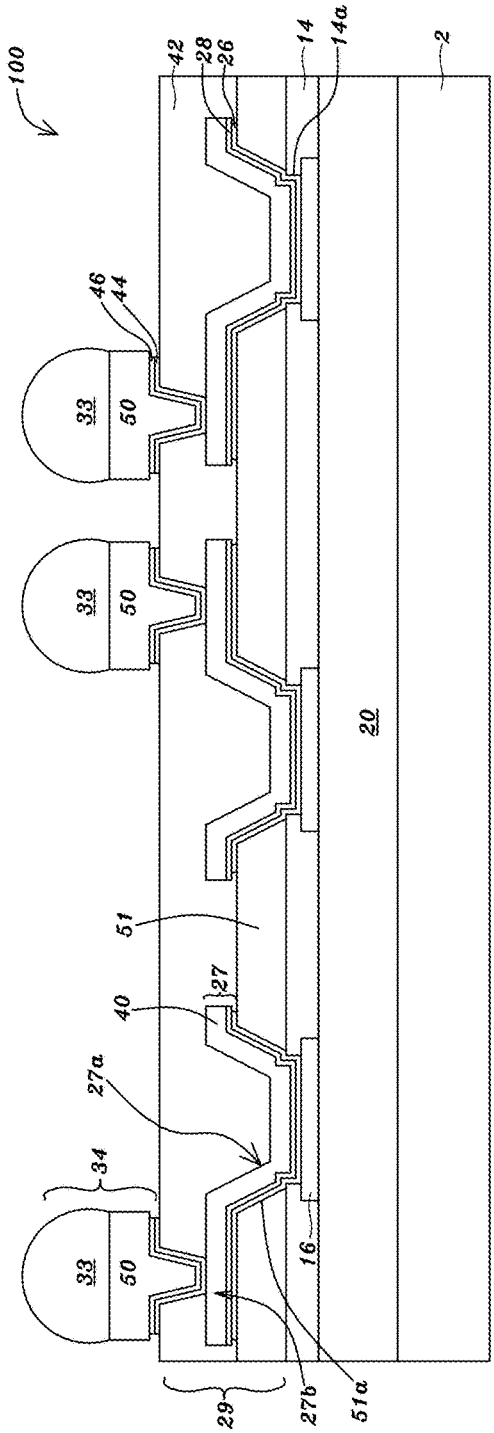


Fig. 16L

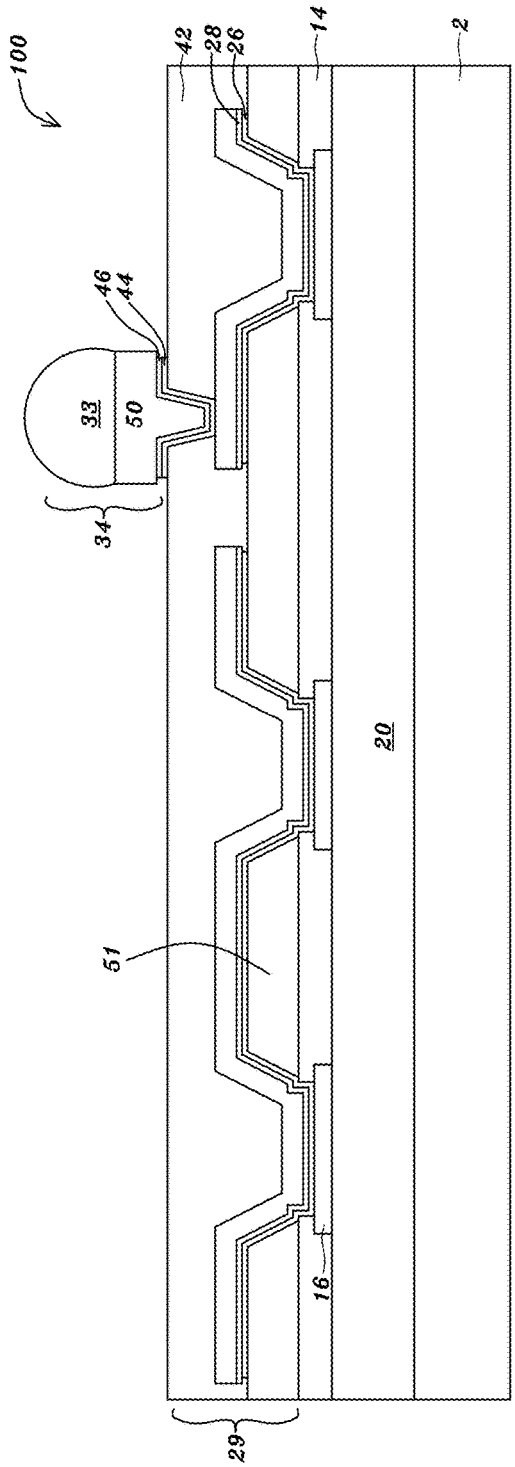


Fig. 16M

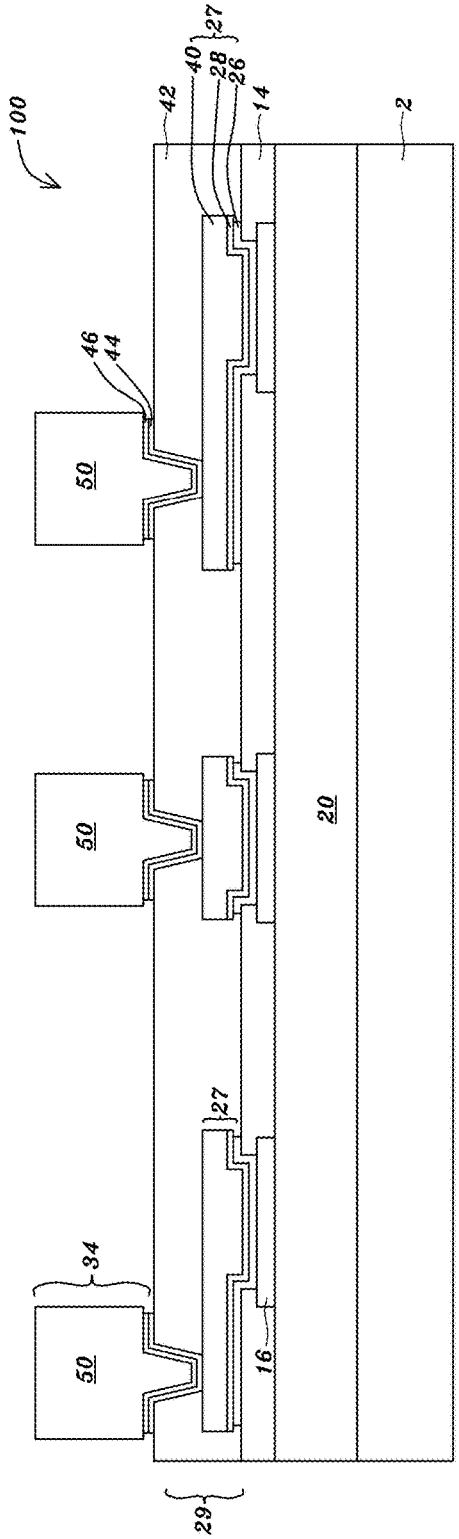


Fig. 16N

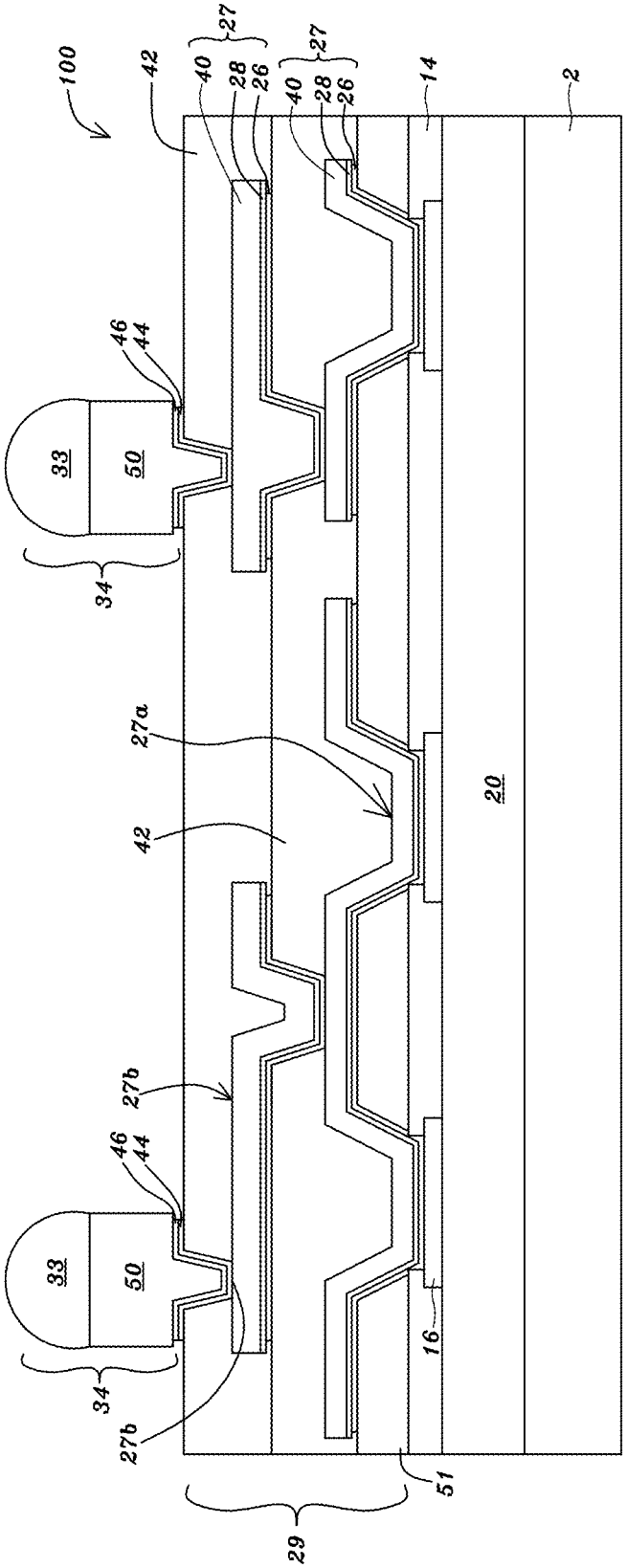


Fig. 17

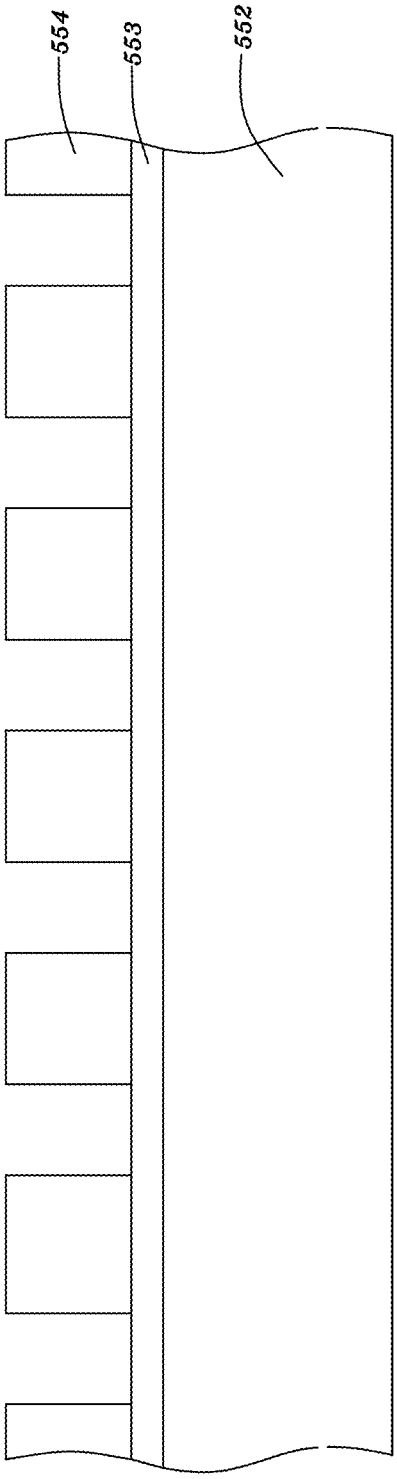


Fig. 18A

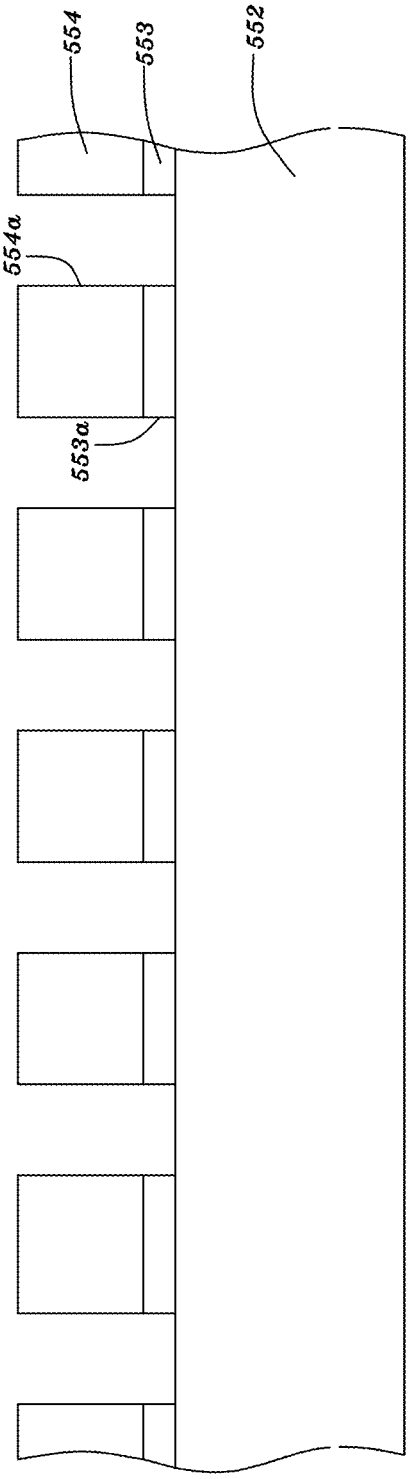


Fig. 18B

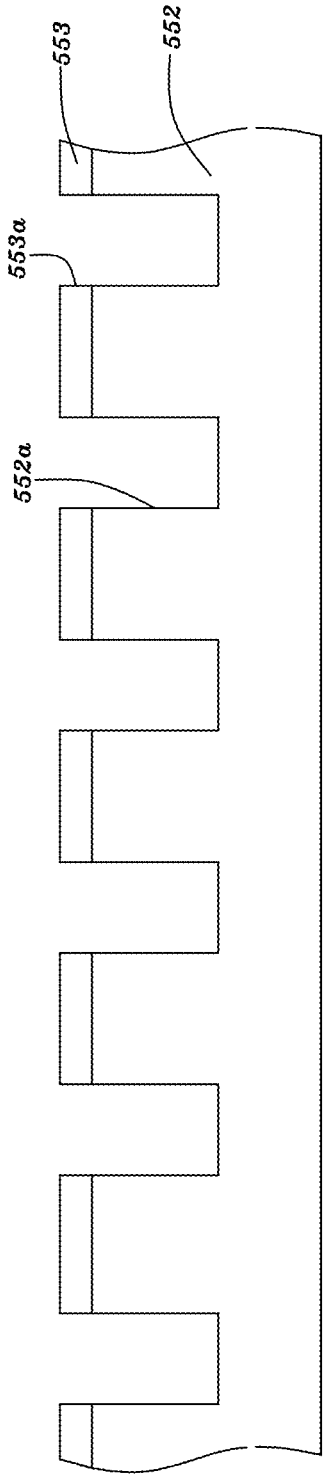


Fig. 18C

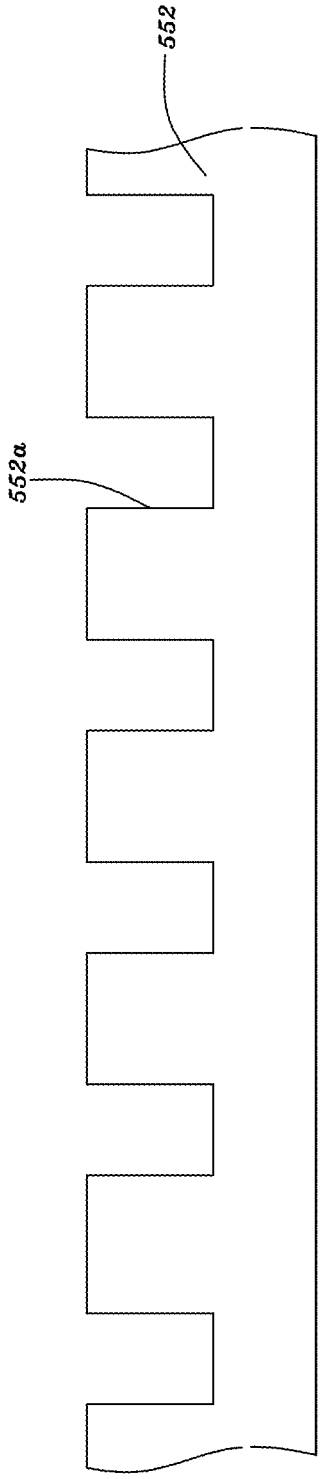


Fig. 18D

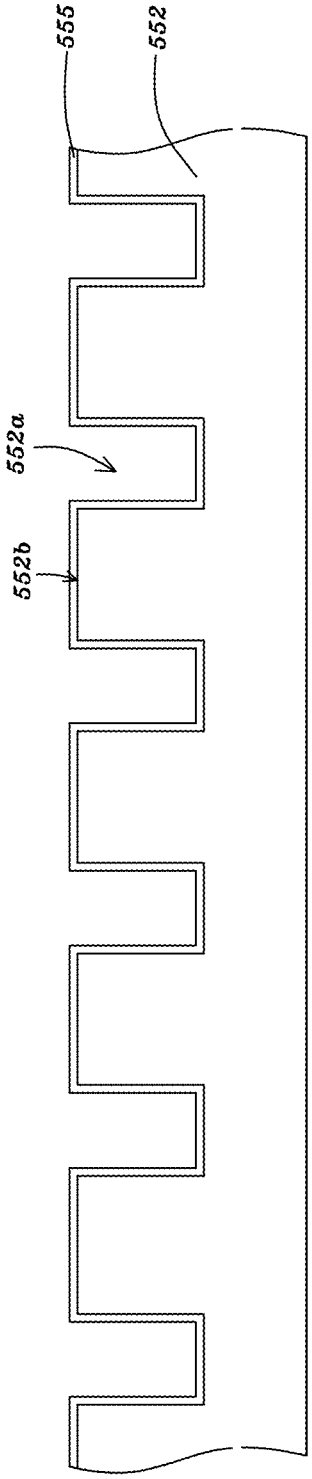


Fig. 18E

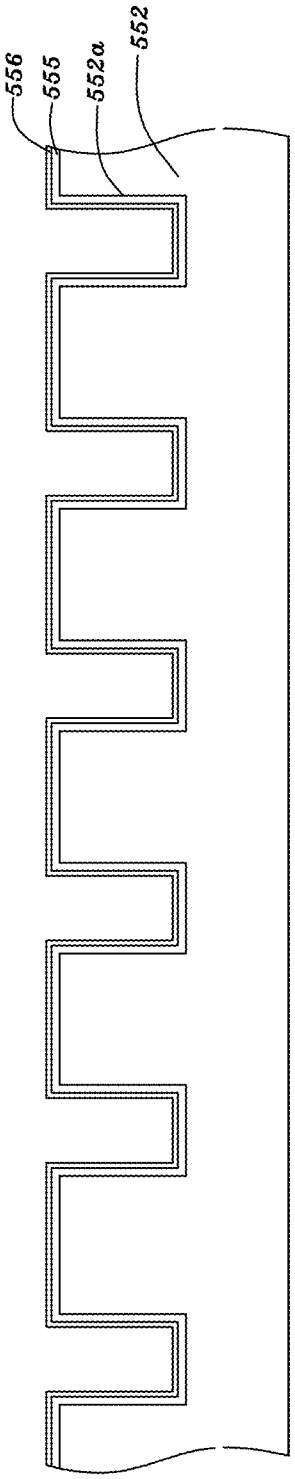


Fig. 18F

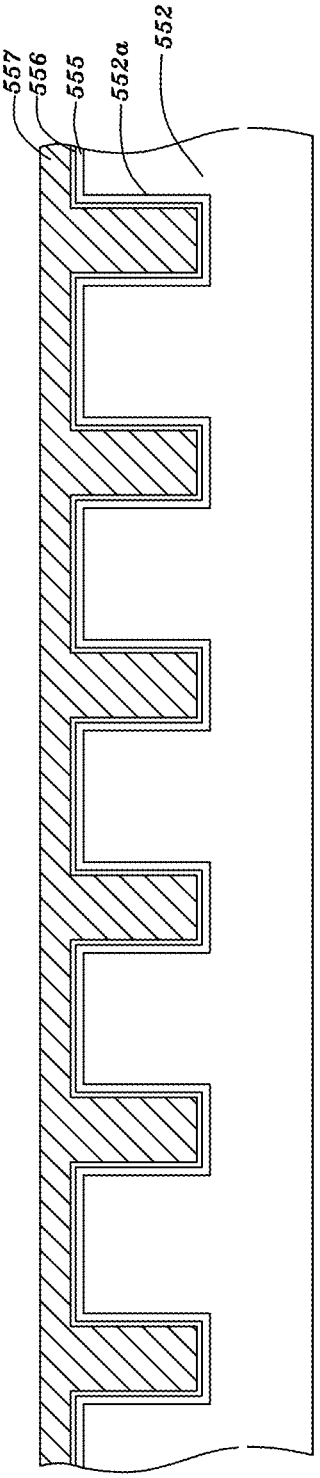


Fig. 18G

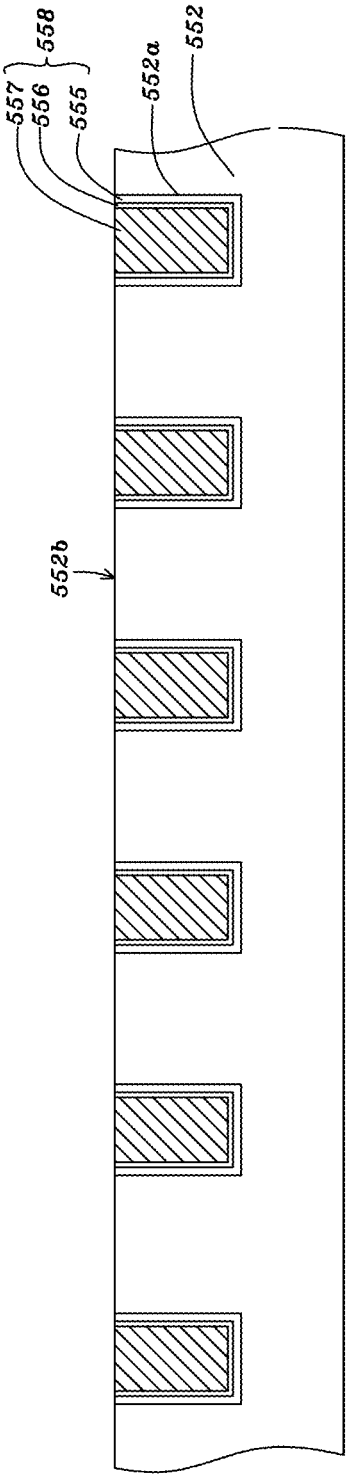


Fig. 18H

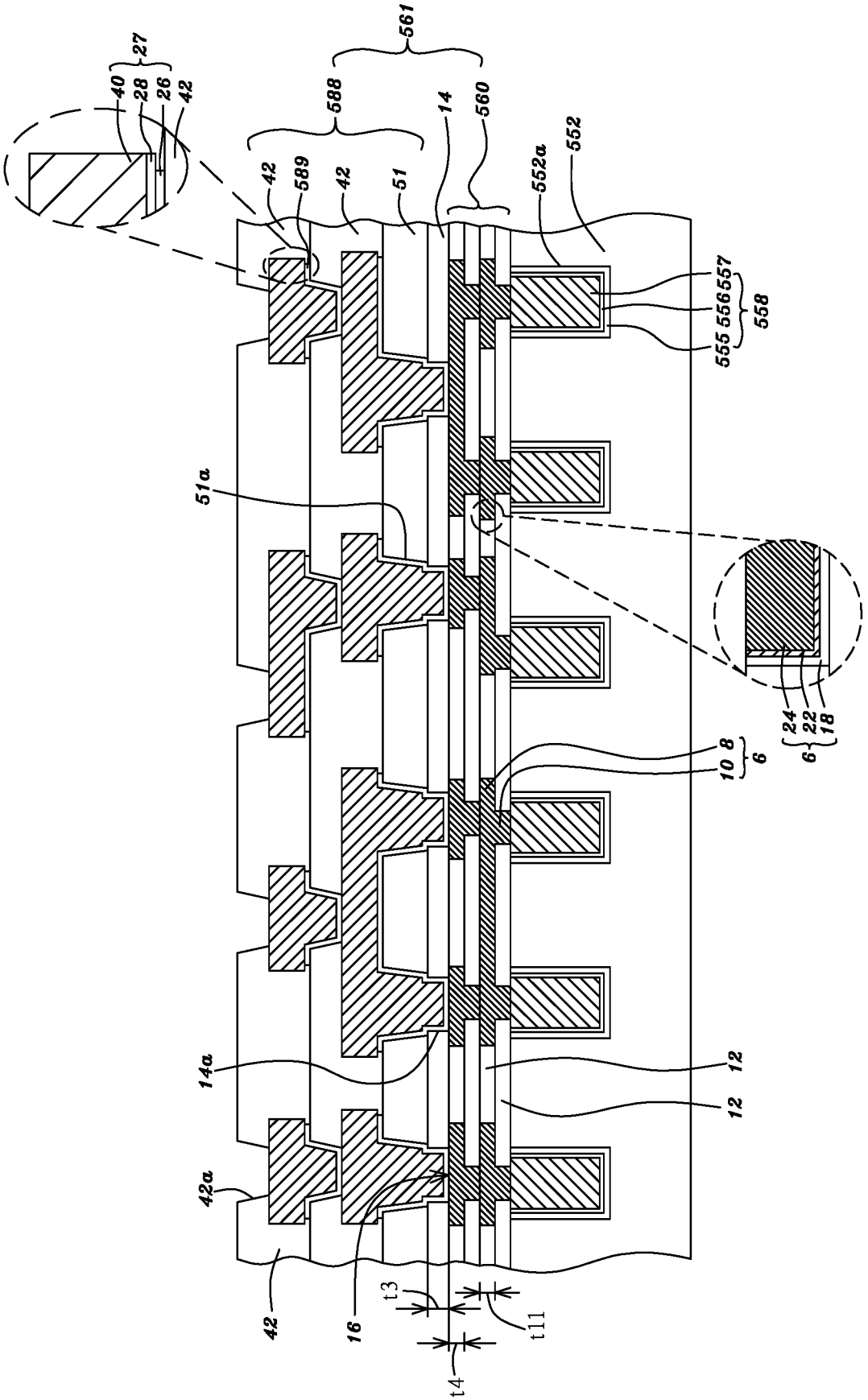

561
27
40
28
26
42
588
14
560
552
552a
42
589
42
51
557
556
555
558
51a
24
22
18
6
10
8
6
14a
12
12
42a
42
16
t3
t11
t4

Fig. 18I

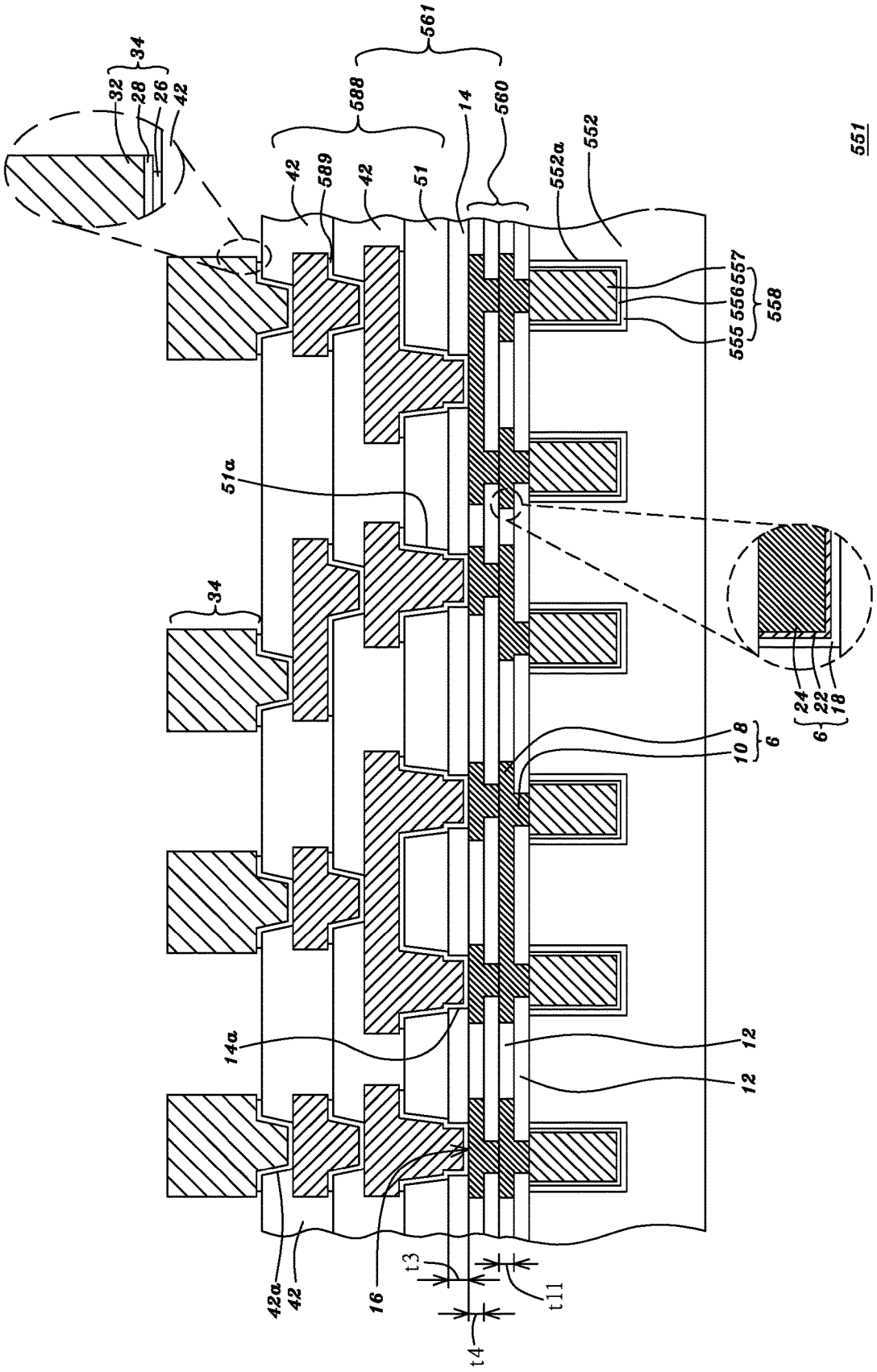

561
34
32
28
26
42
588
14
560
552
42
589
42
51
552a
551
557
556
555
558
51a
34
24
22
18
6
10 8
6
14a
12
12
42a
42
16
t3
t11
t4

Fig. 18J

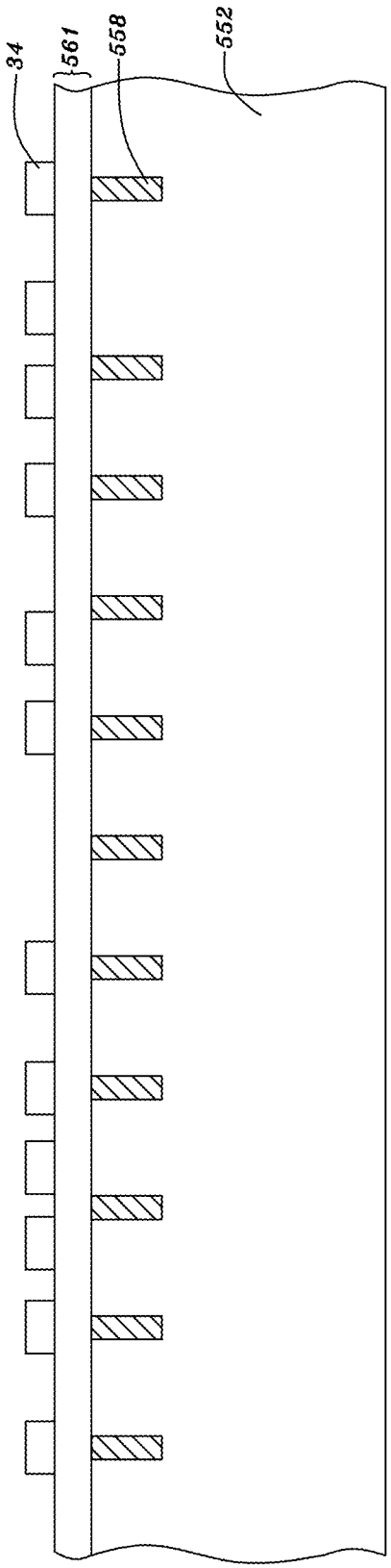


Fig. 18K

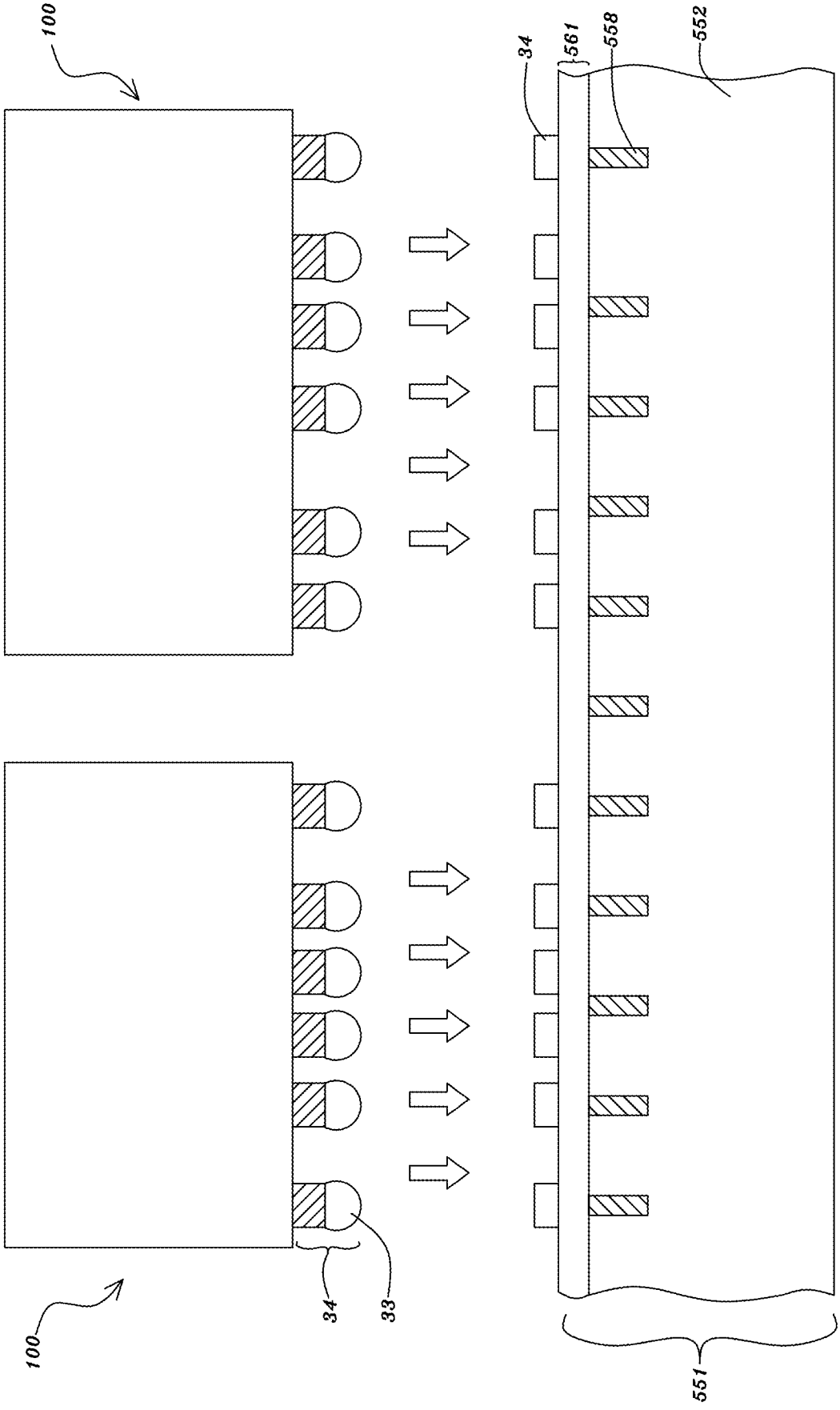


Fig. 18L

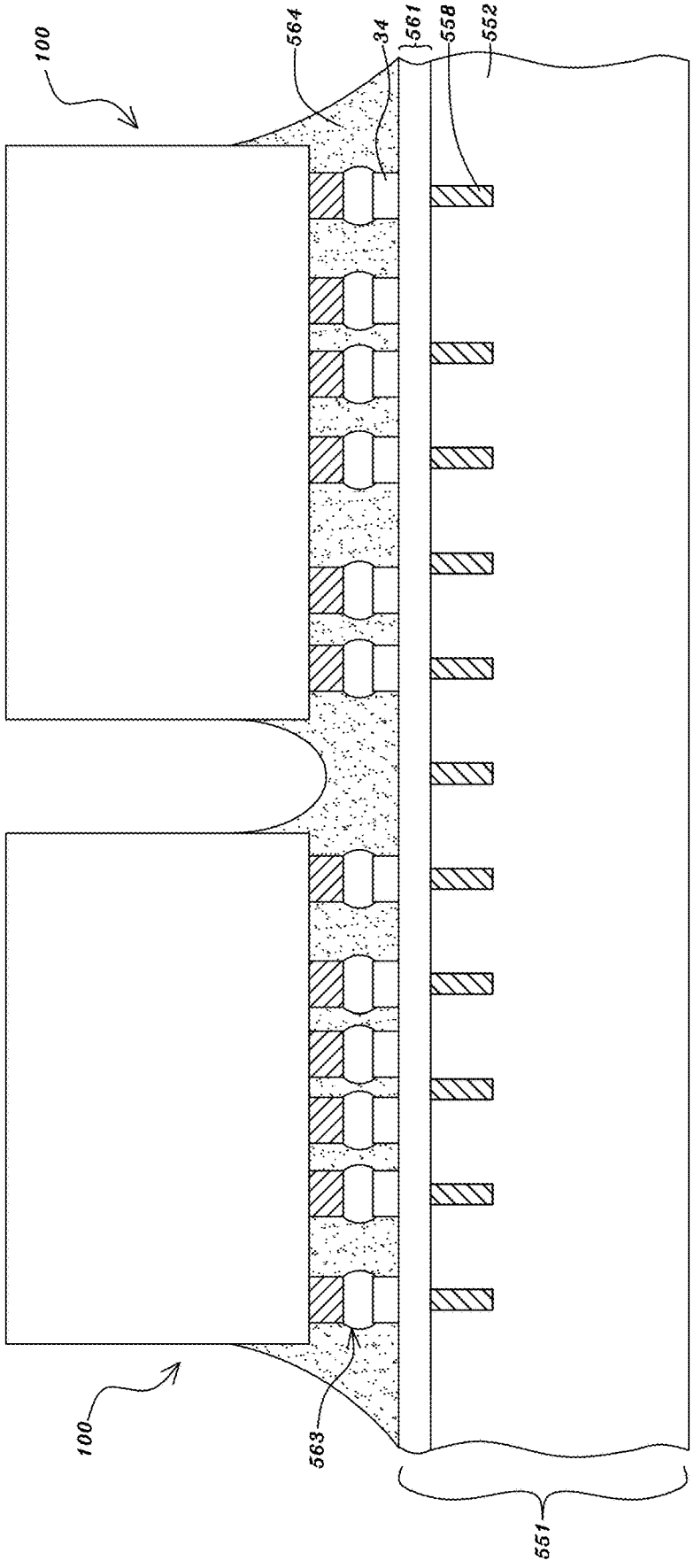


Fig. 18M

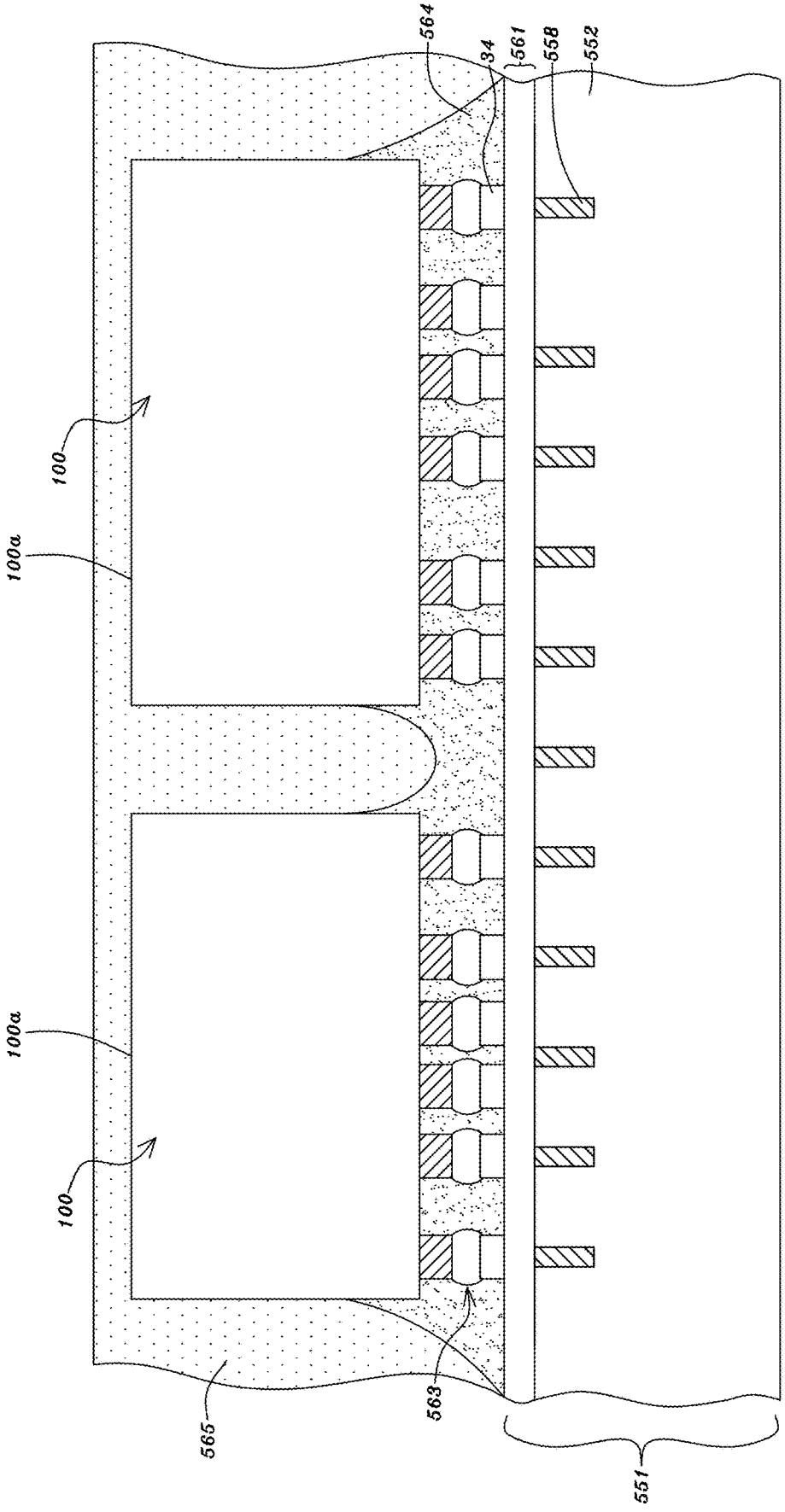


Fig. 18N

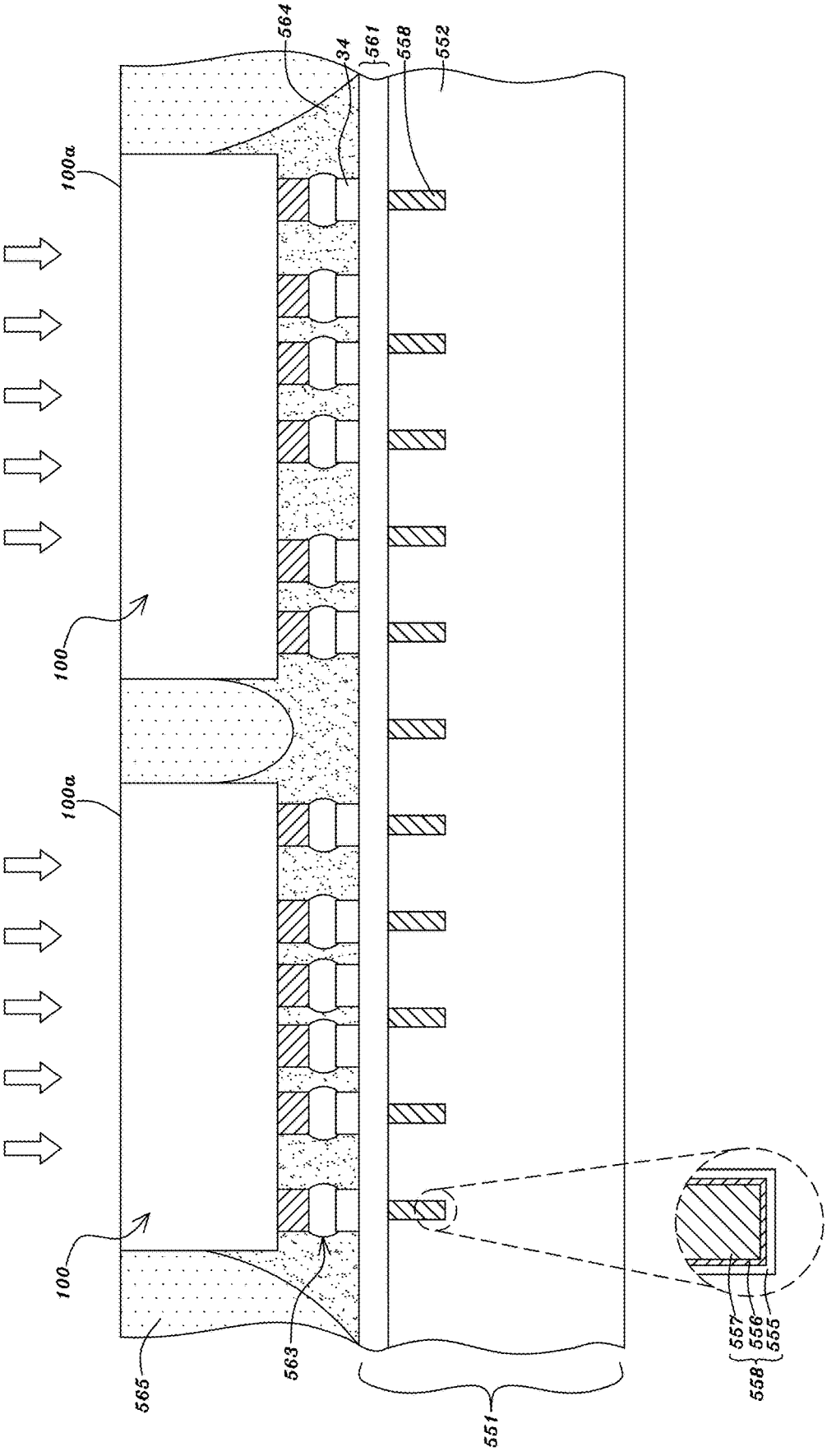


Fig. 180

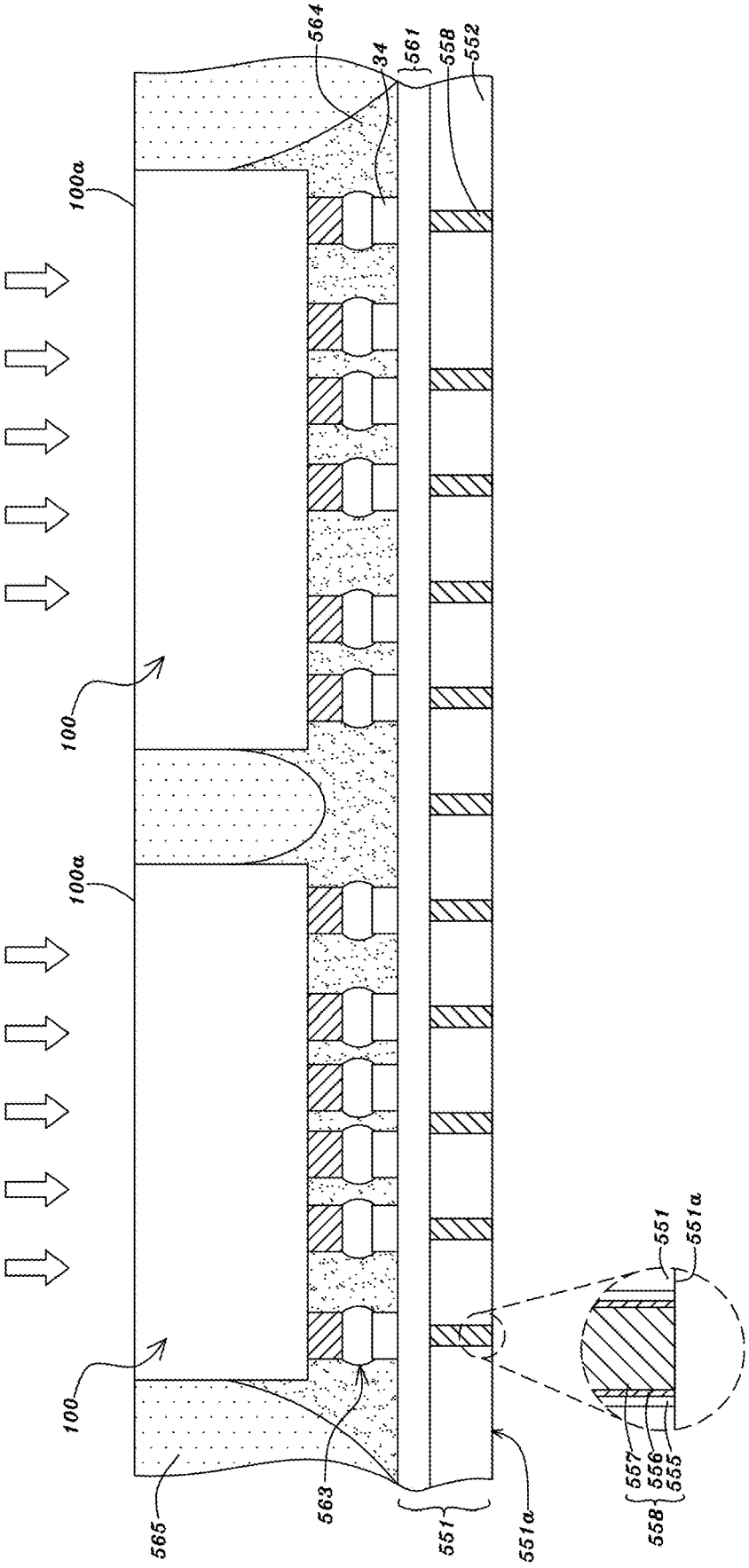

564
34
561
558
552
100a
100
100a
100
563
565
551
551a
551
551a
557
556
555
558

Fig. 18P

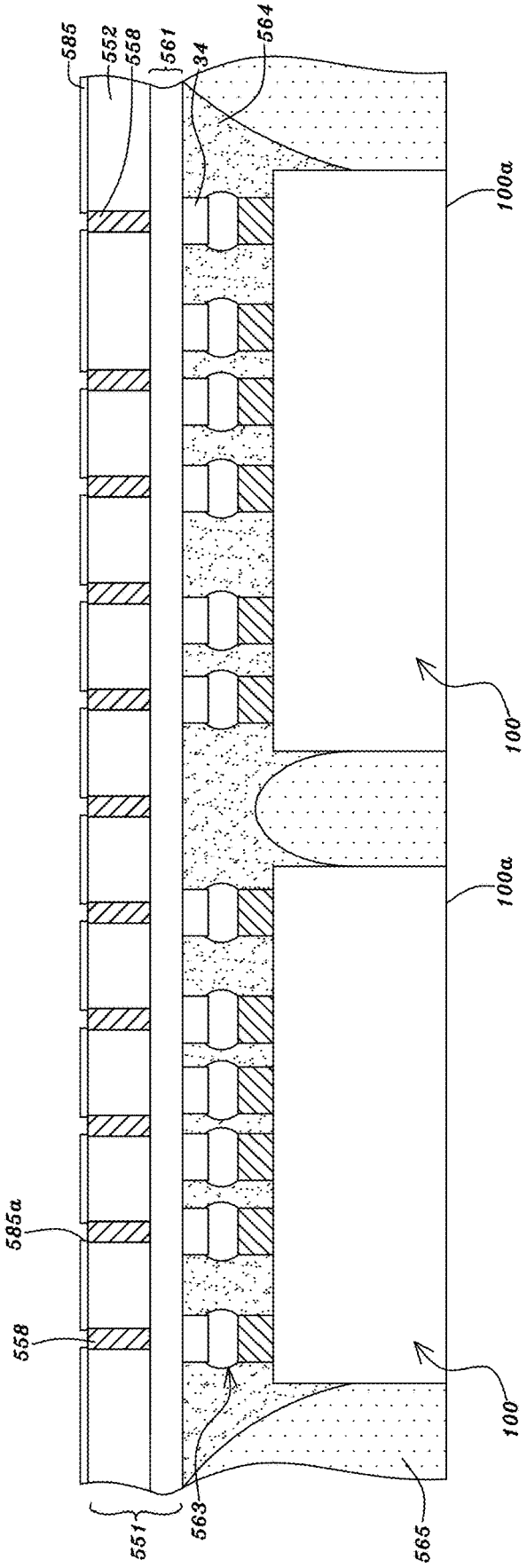


Fig. 18Q

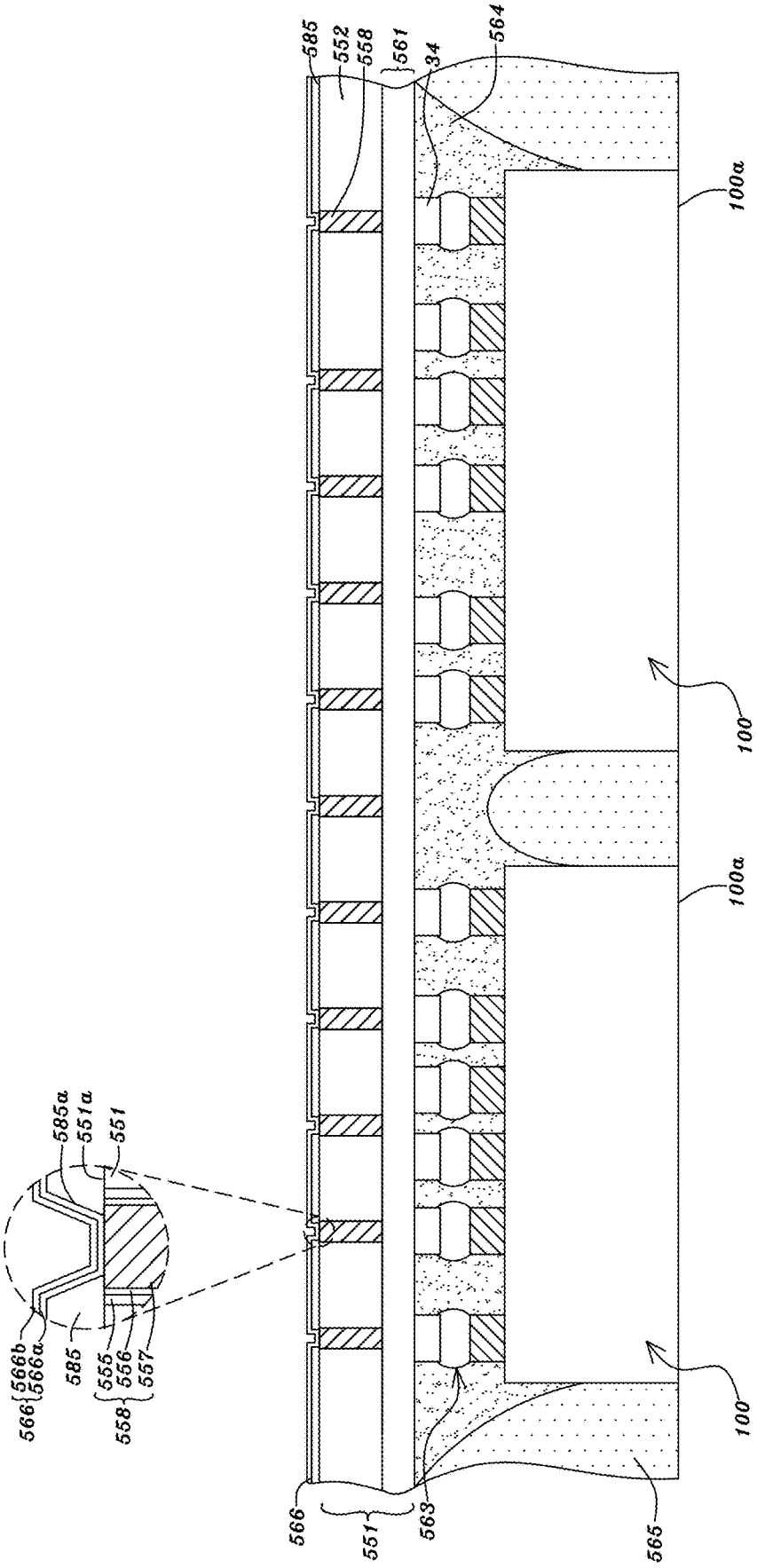

585
552
558
561
34
564
100a
100
100a
100
566
551
563
565
585a
551a
551
566b
566a
566
585
555
556
557
558

Fig. 18R

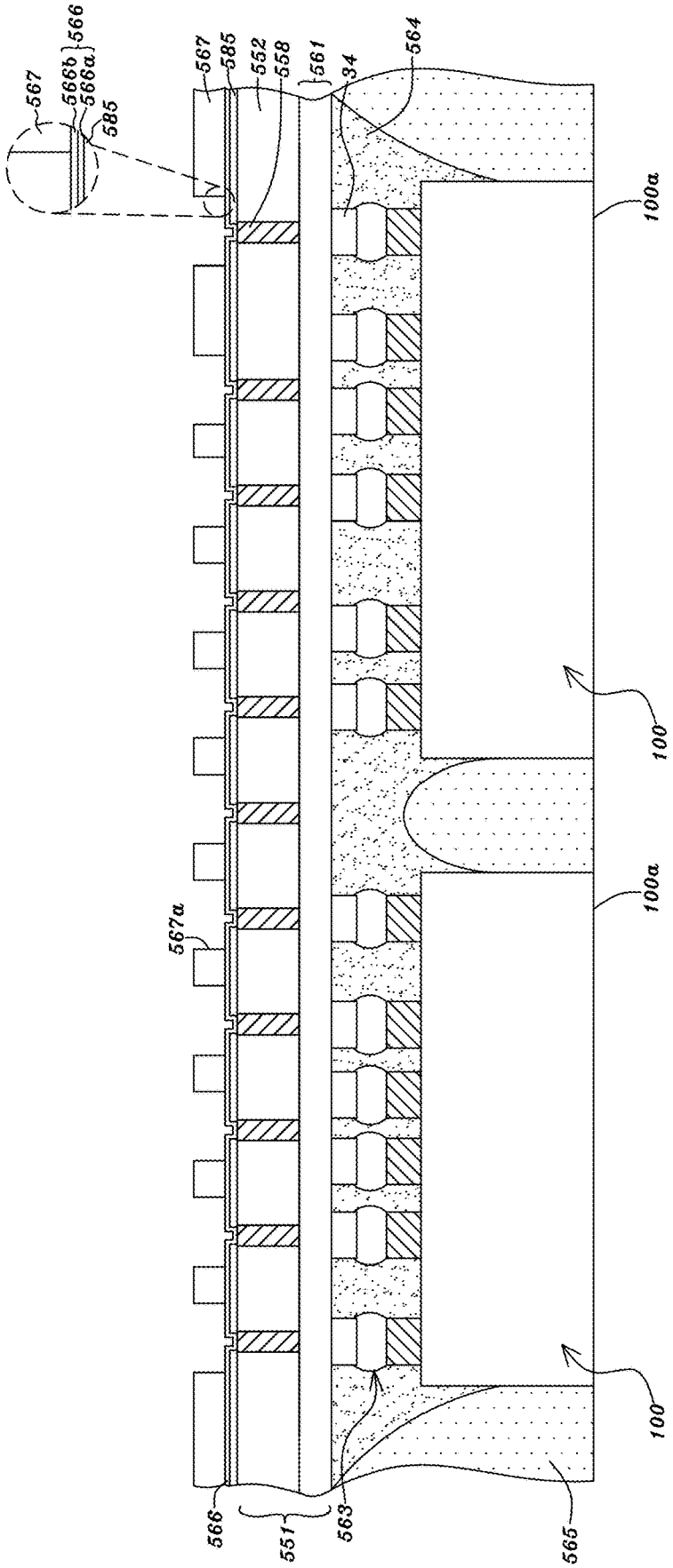

567
566b
566a
566
585
567
585
552
558
561
34
564
100a
100
100a
100
567a
566
551
563
565

Fig. 18S

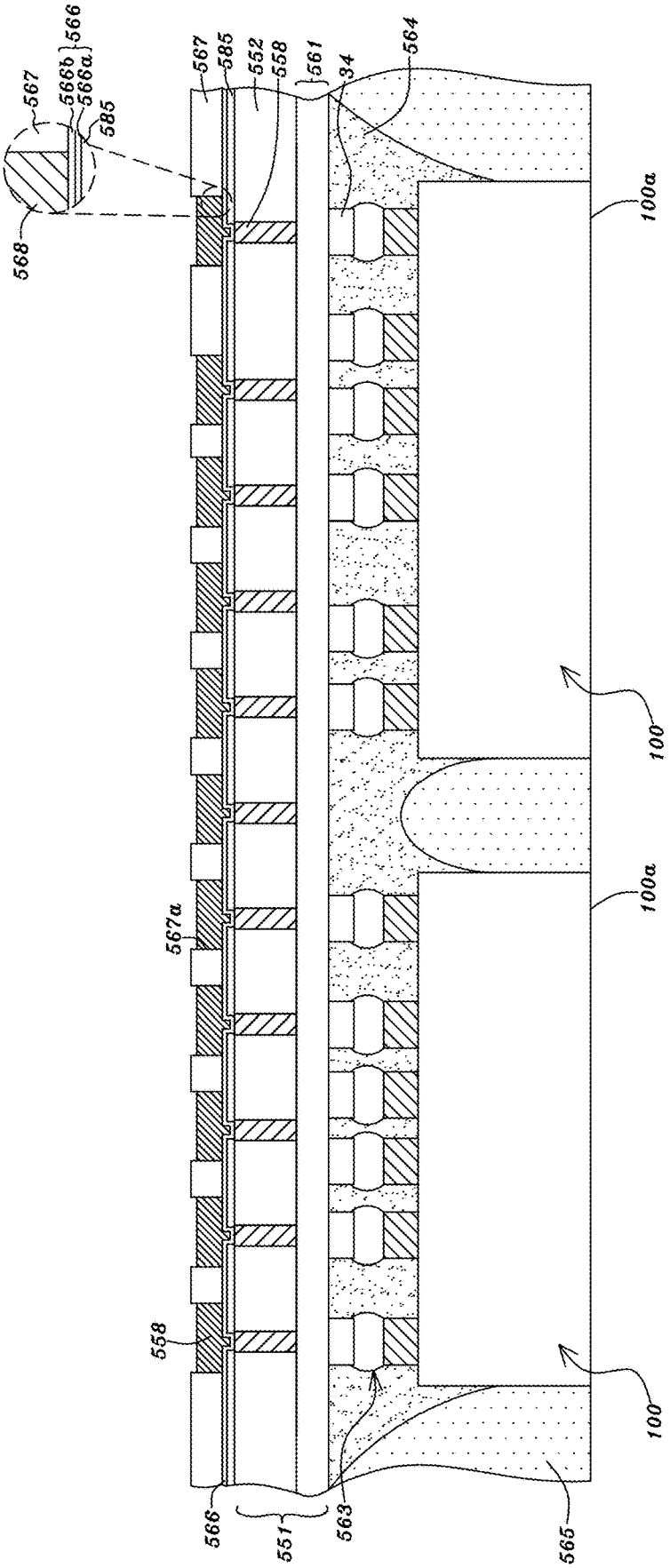

567
566b
566a
566
585
568
567
585
552
558
561
34
564
100a
100
100a
100
567a
558
566
551
563
565

Fig. 18T

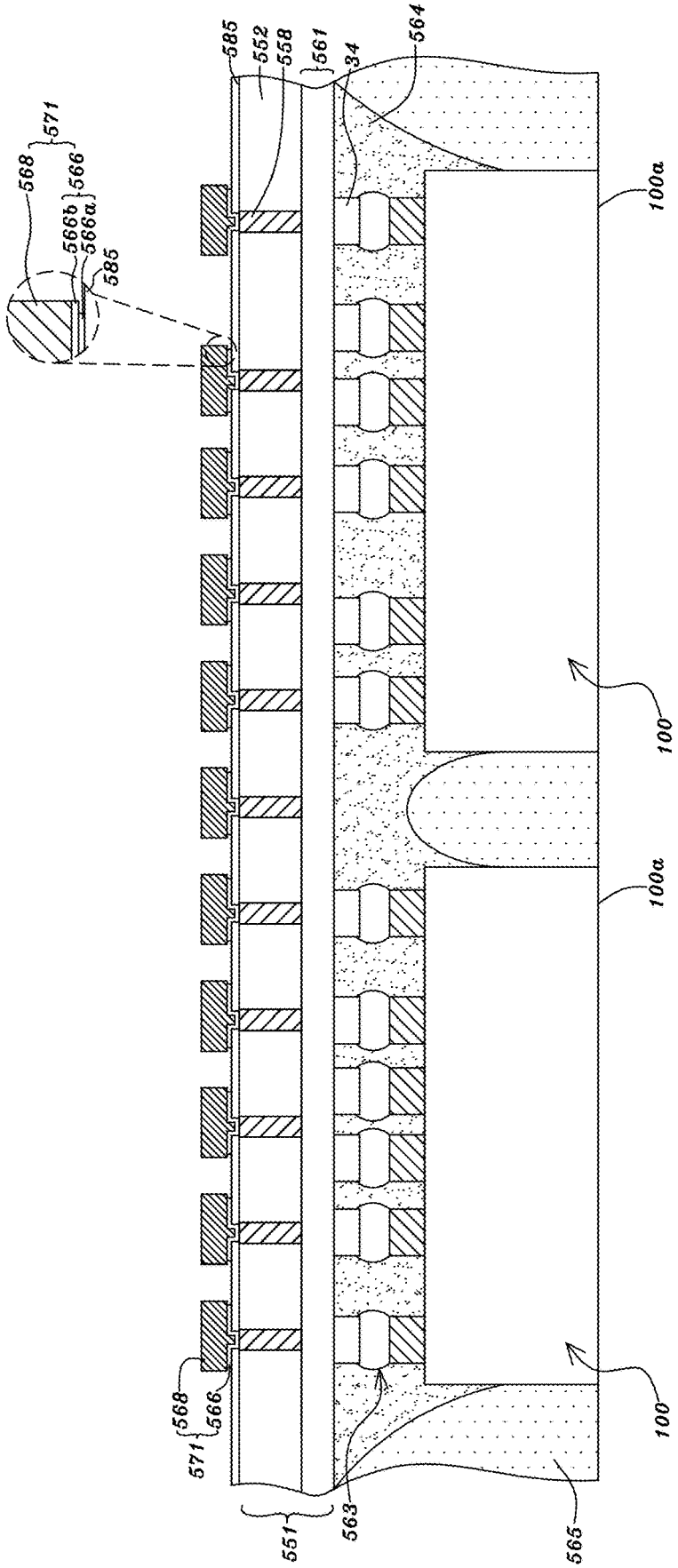

585
552
558
561
34
564
571
568
566
566b
566a
585
100a
100
100a
100
568
566
571
563
551
565

Fig. 18U

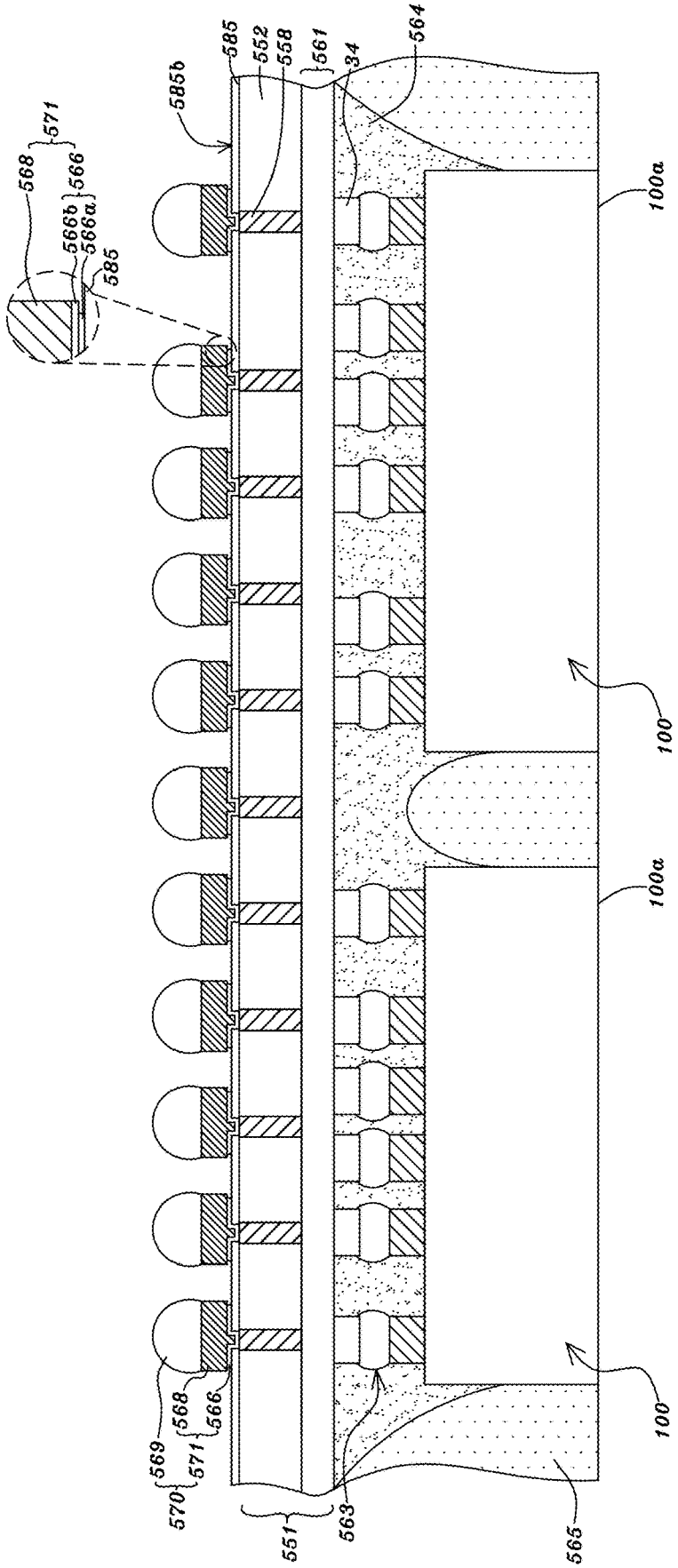

585
552
558
561
34
564
585b
571
568
566
566b
566a
585
100a
100
100a
100
569
571
568
566
570
551
563
565

Fig. 18V

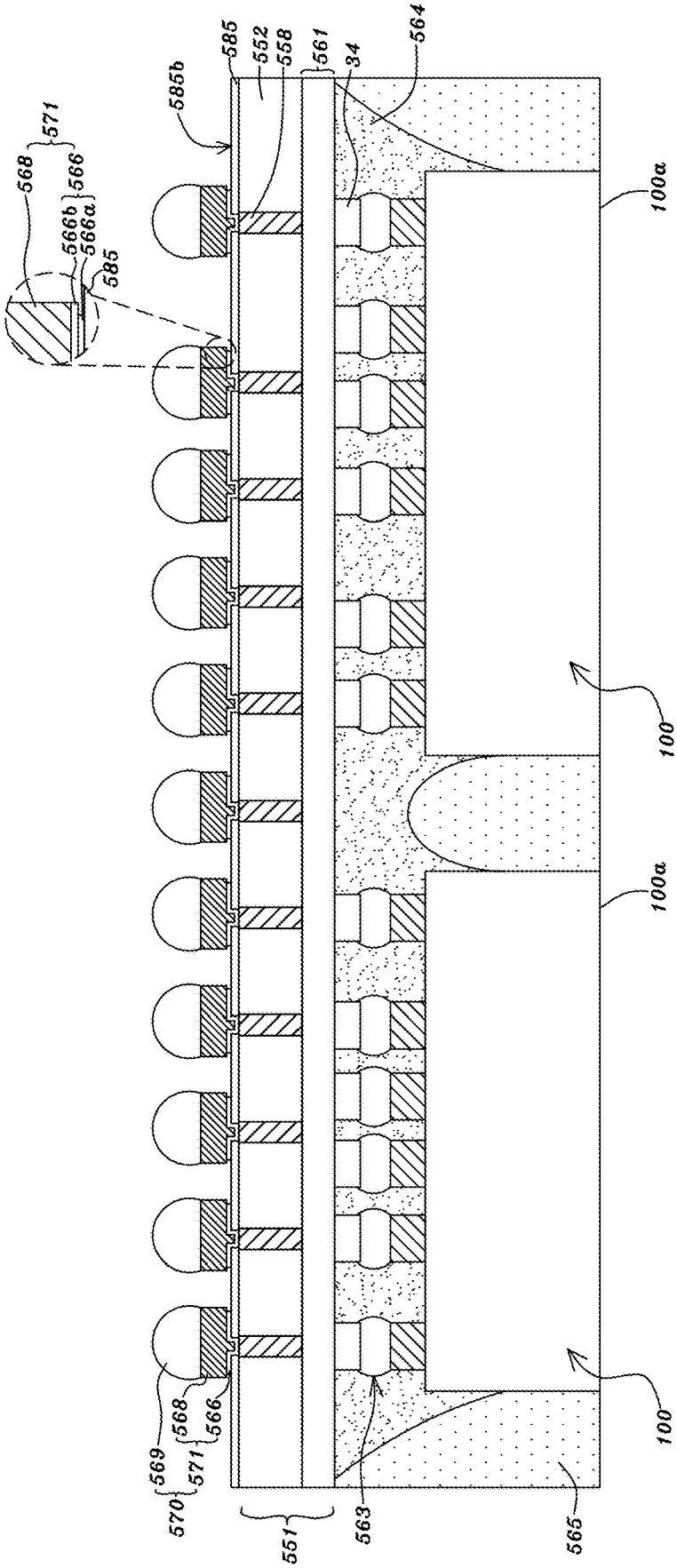

300
585
552
558
561
34
564
585b
571
568
566
566b
566a
585
100a
100
100a
100
569
568
566
571
570
551
563
565

Fig. 18W

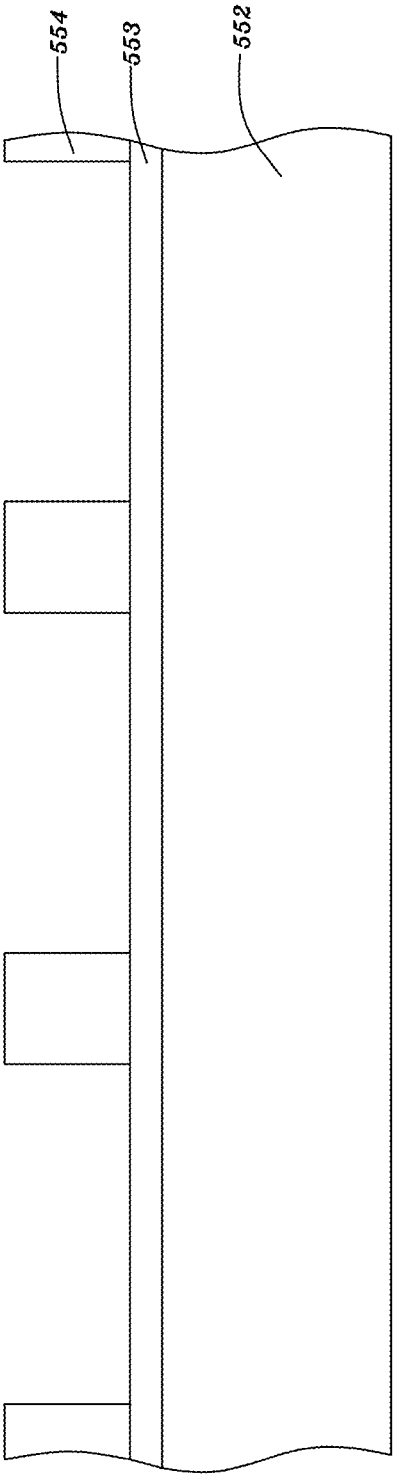


Fig. 19A

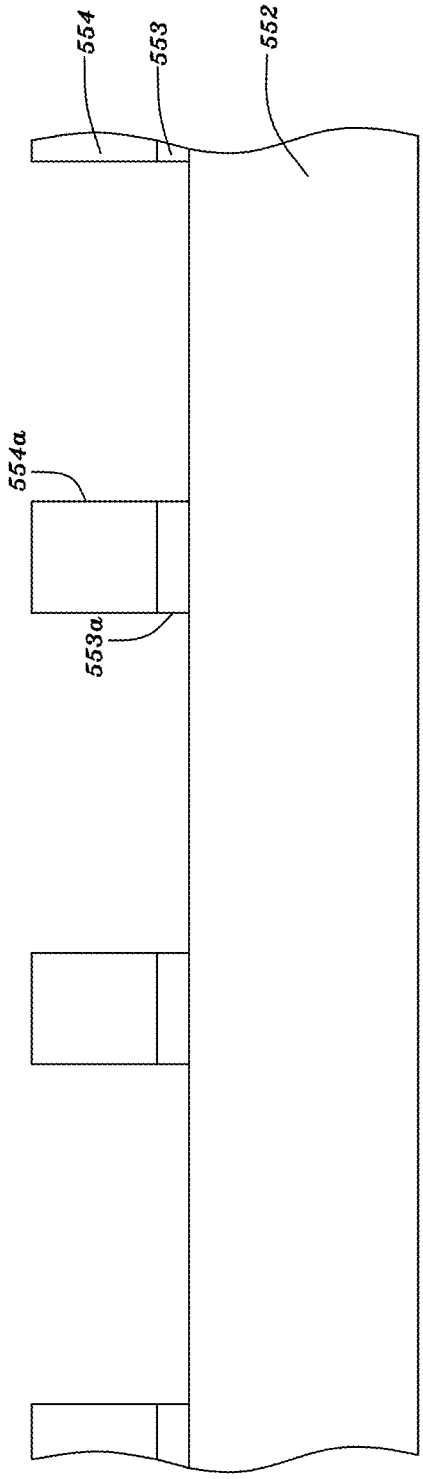


Fig. 19B

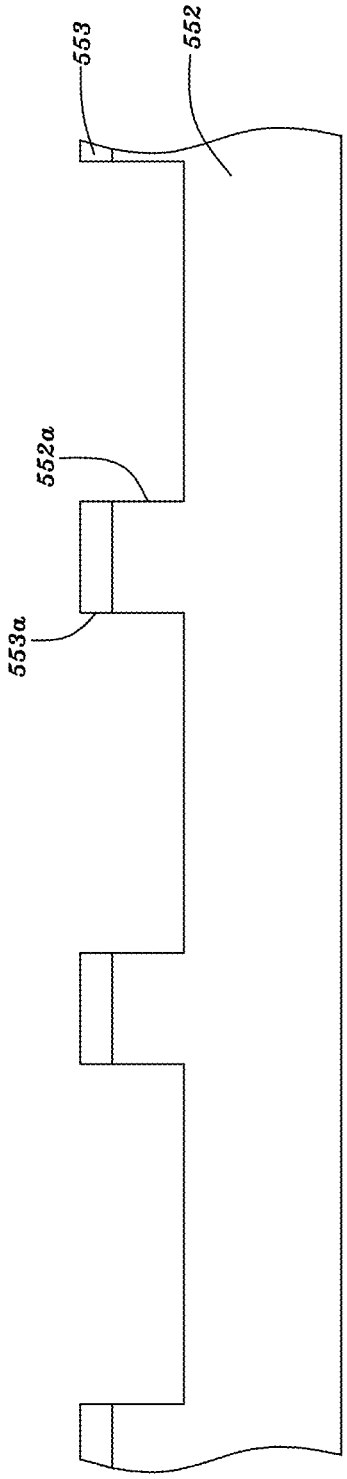


Fig. 19C

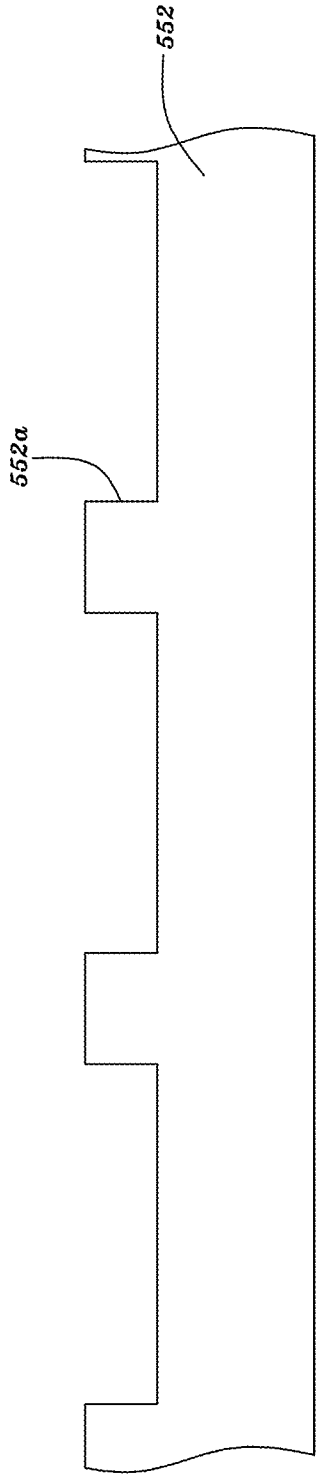


Fig. 19D

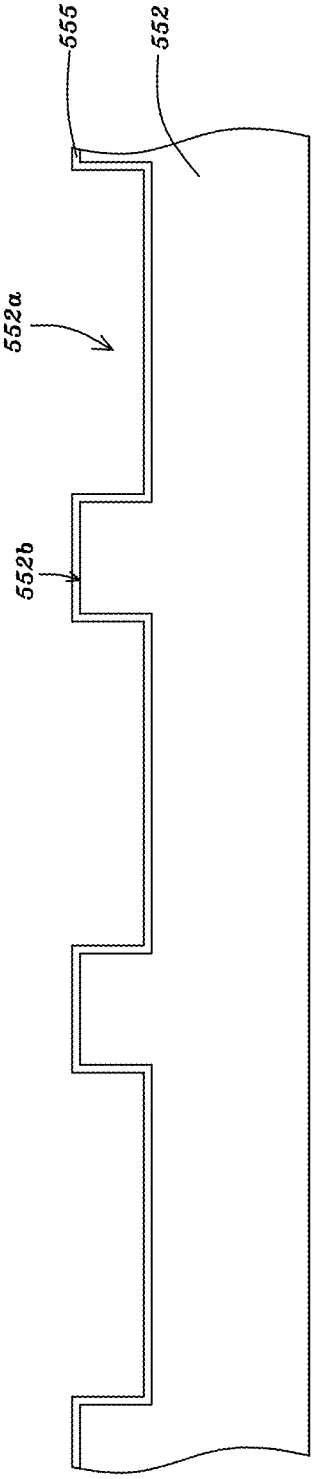


Fig. 19E

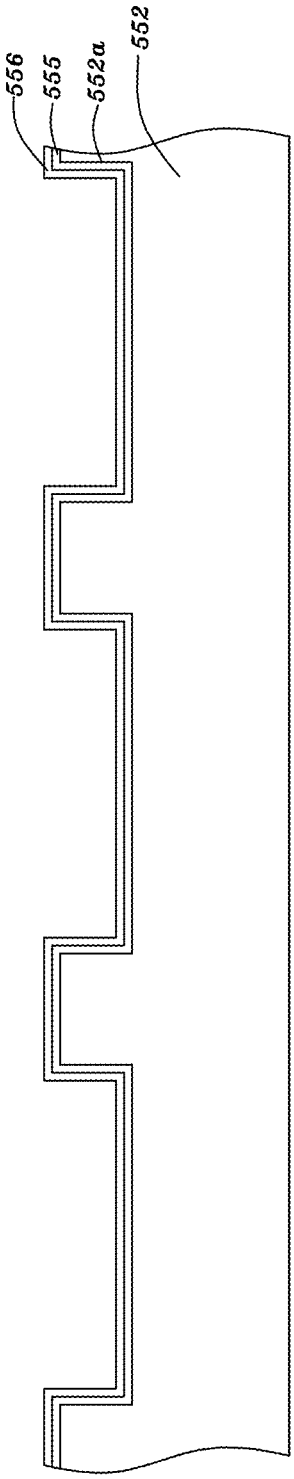


Fig. 19F

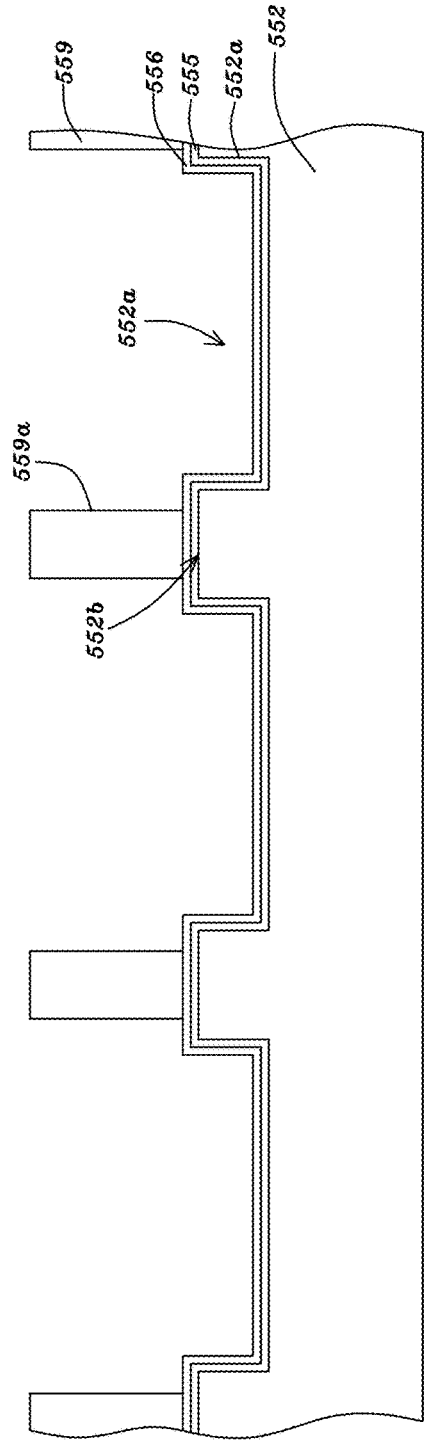


Fig. 19G

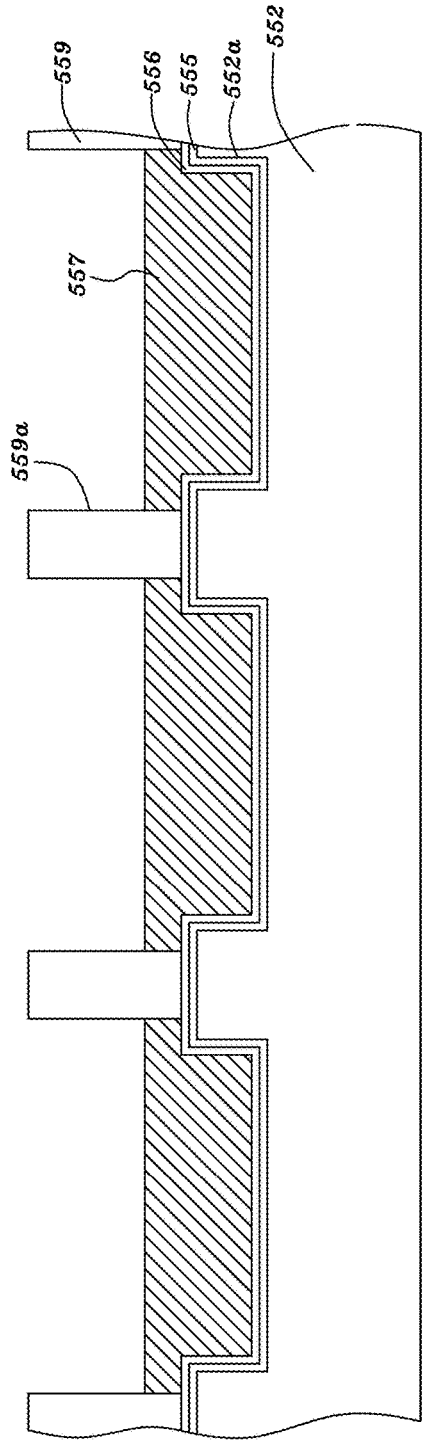


Fig. 19H

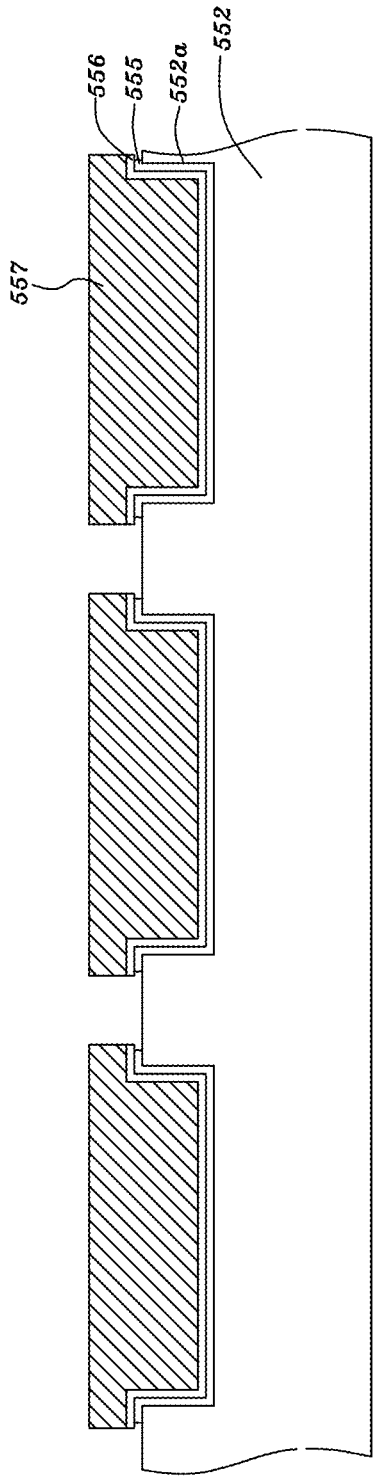


Fig. 19I

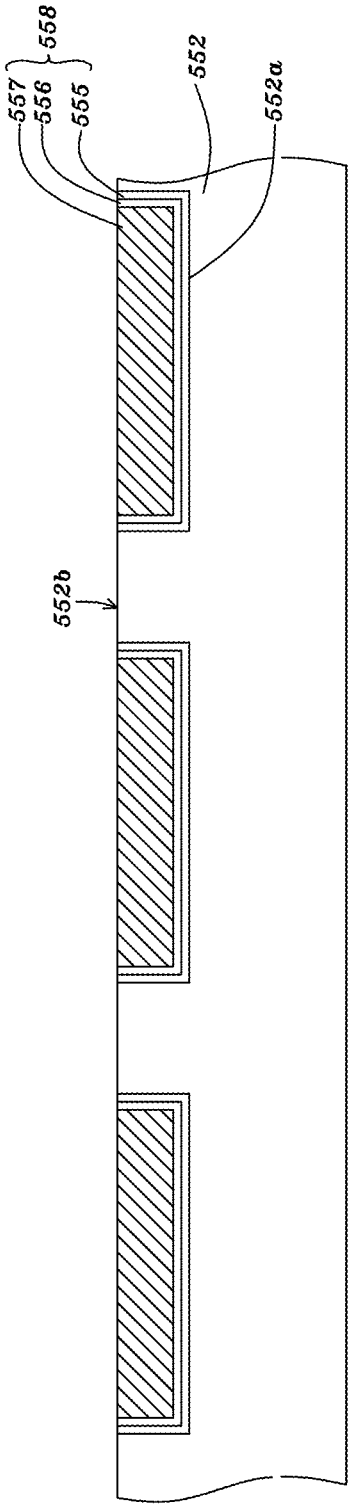


Fig. 19J

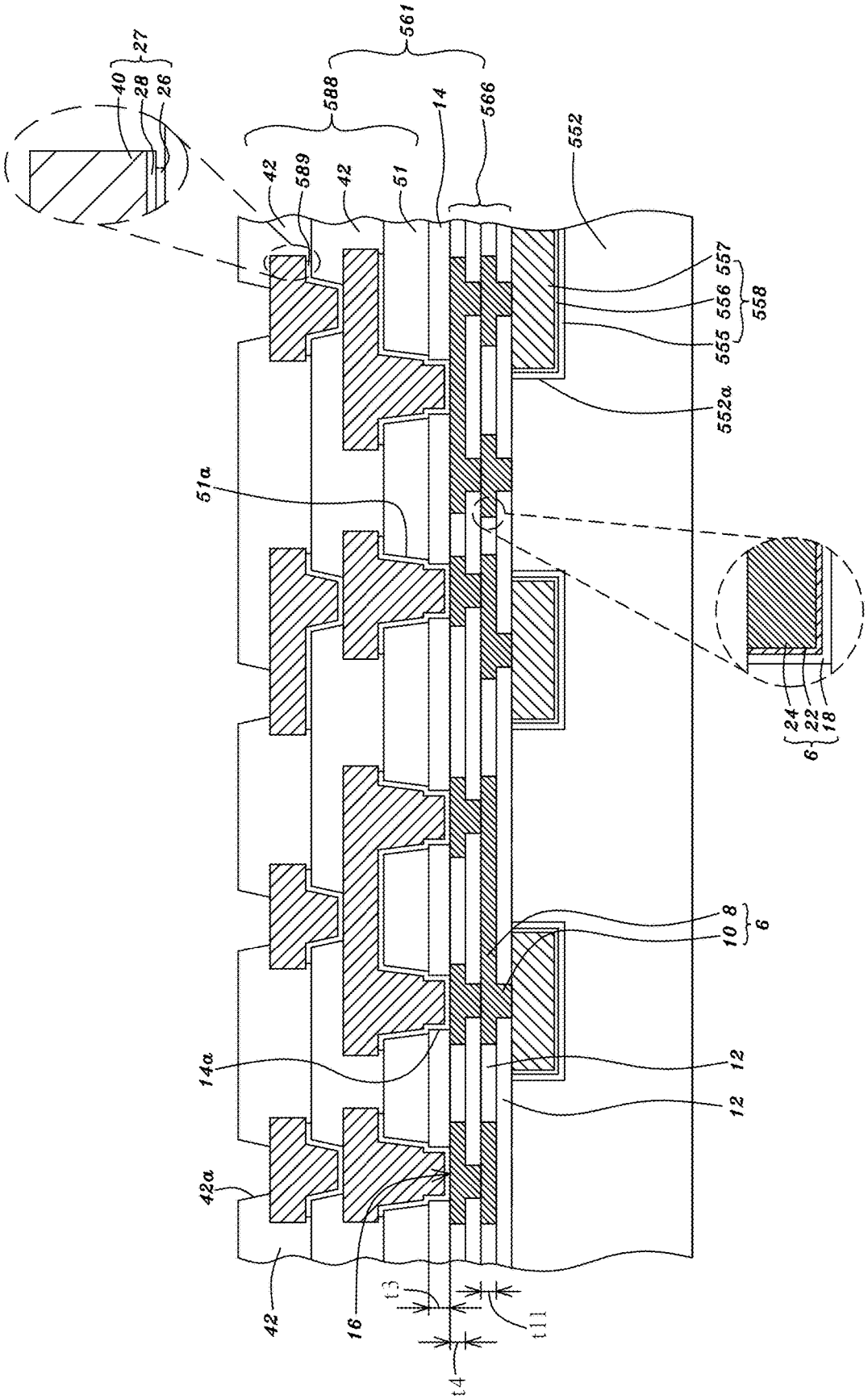

561
588
14
566
552
27
40
28
26
42
589
42
51
557
556
555
558
552a
51a
24
22
18
6
10
8
6
14a
12
12
42a
42
16
t3
t11
t4

Fig. 19K

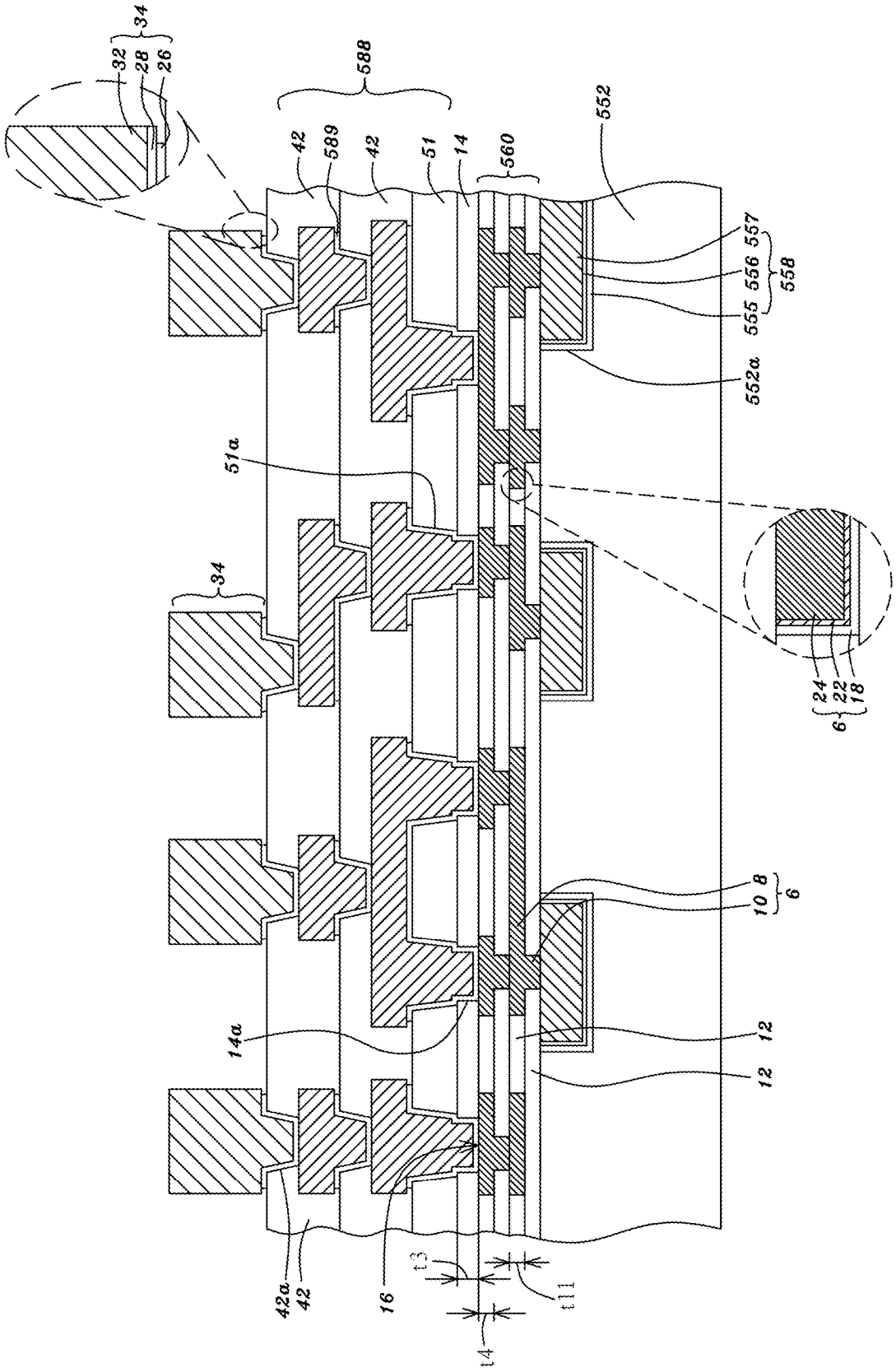

34
32
28
26
588
42
589
42
51
14
560
552
557
556
555
558
552a
51a
34
24
22
18
6
10
8
6
14a
12
12
42a
42
16
t3
t11
t4

Fig. 19L

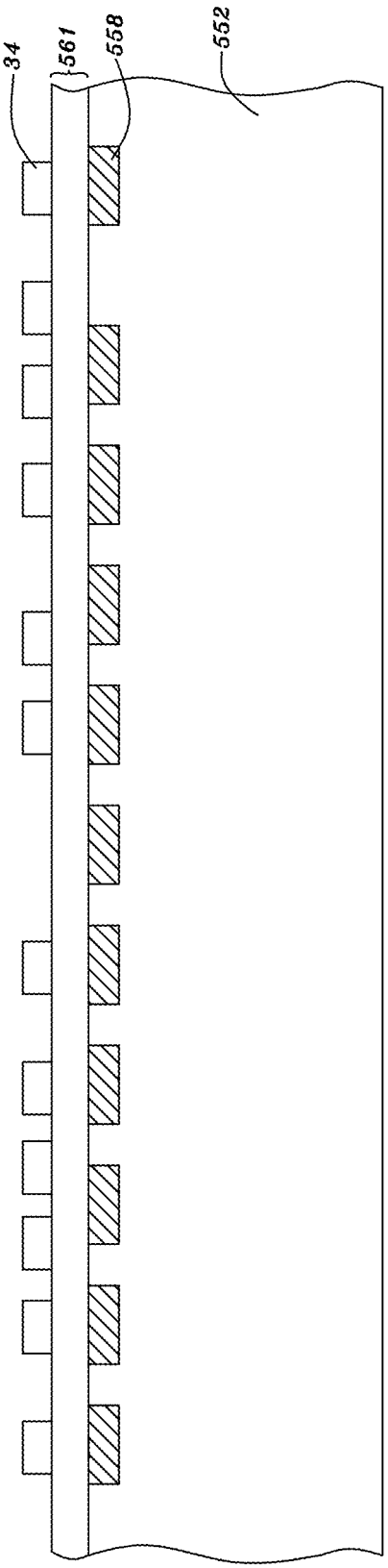


Fig. 19M

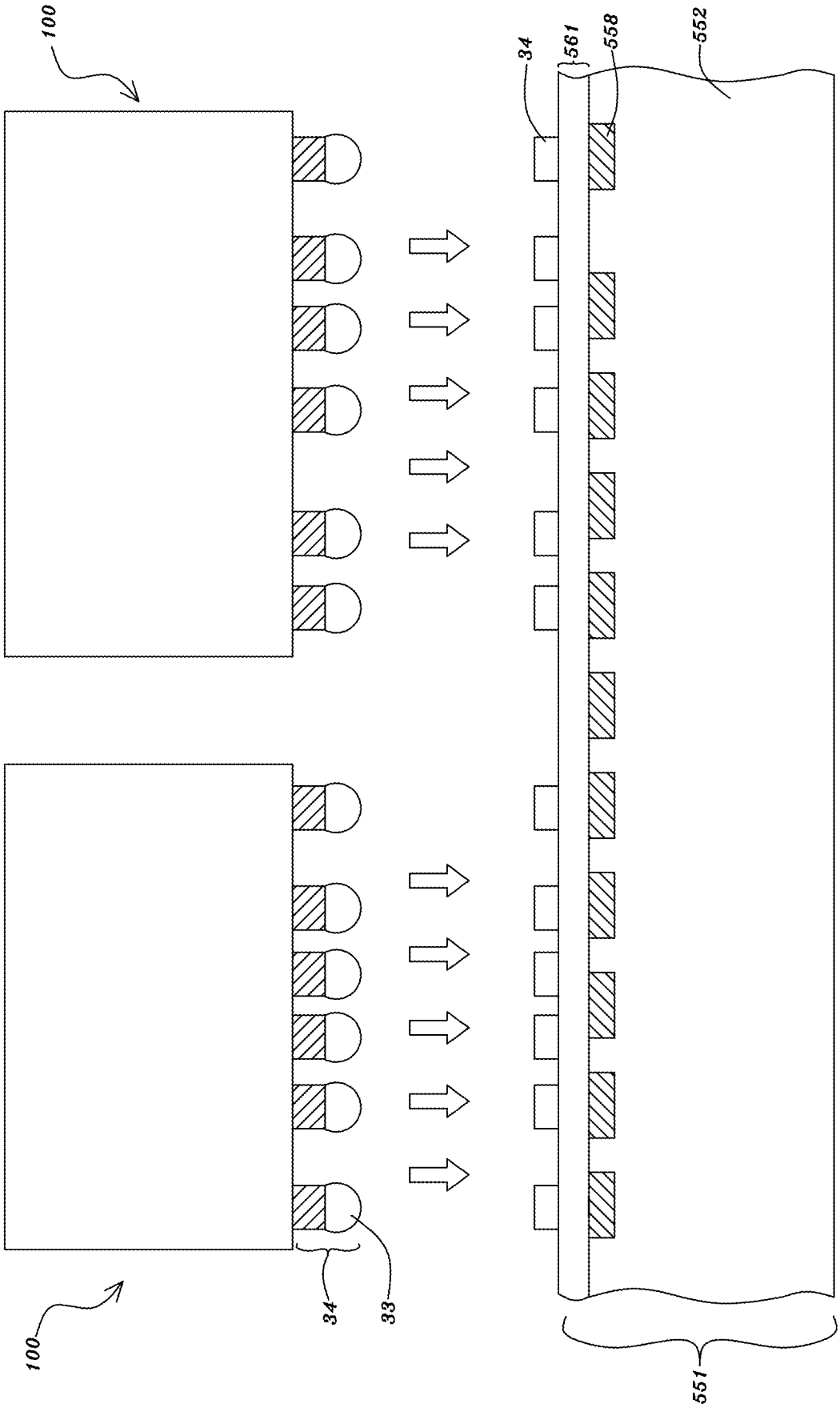


Fig. 19N

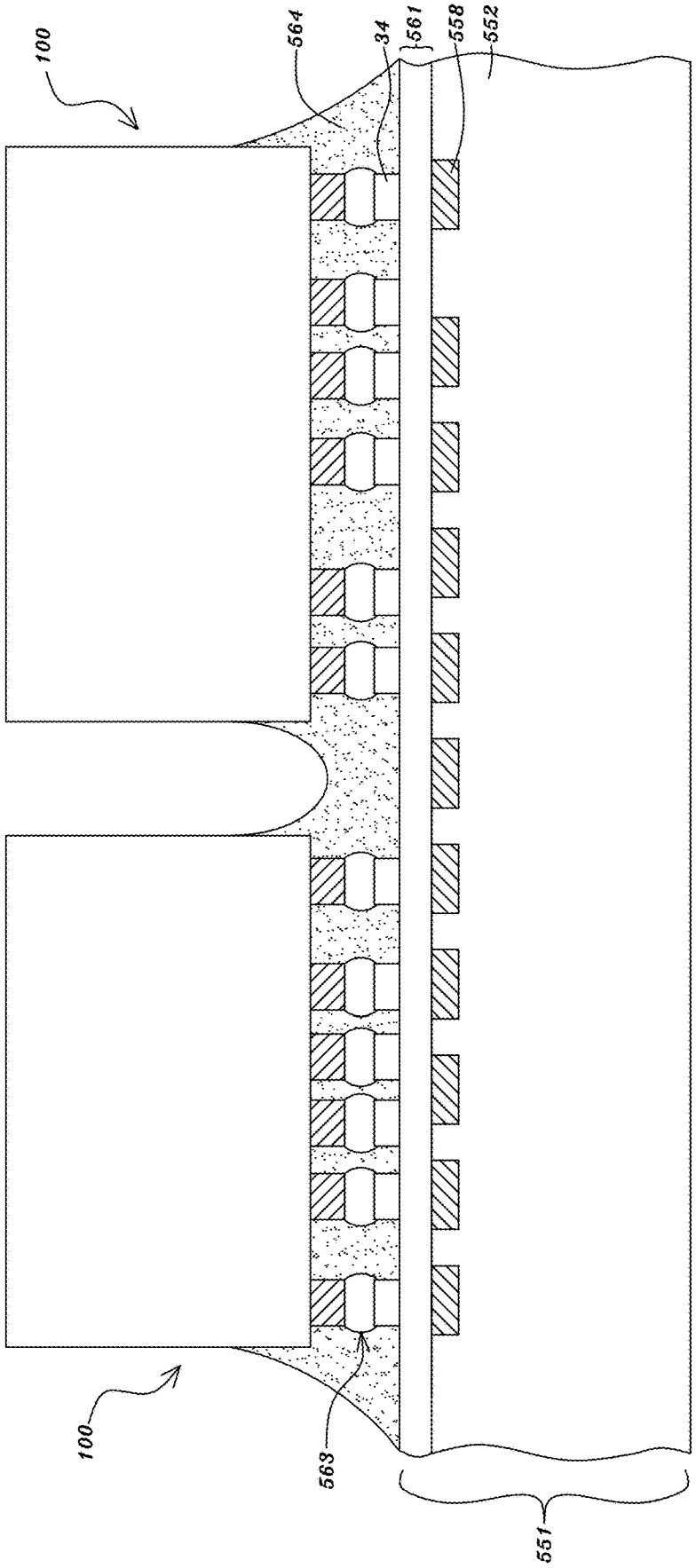


Fig. 19O

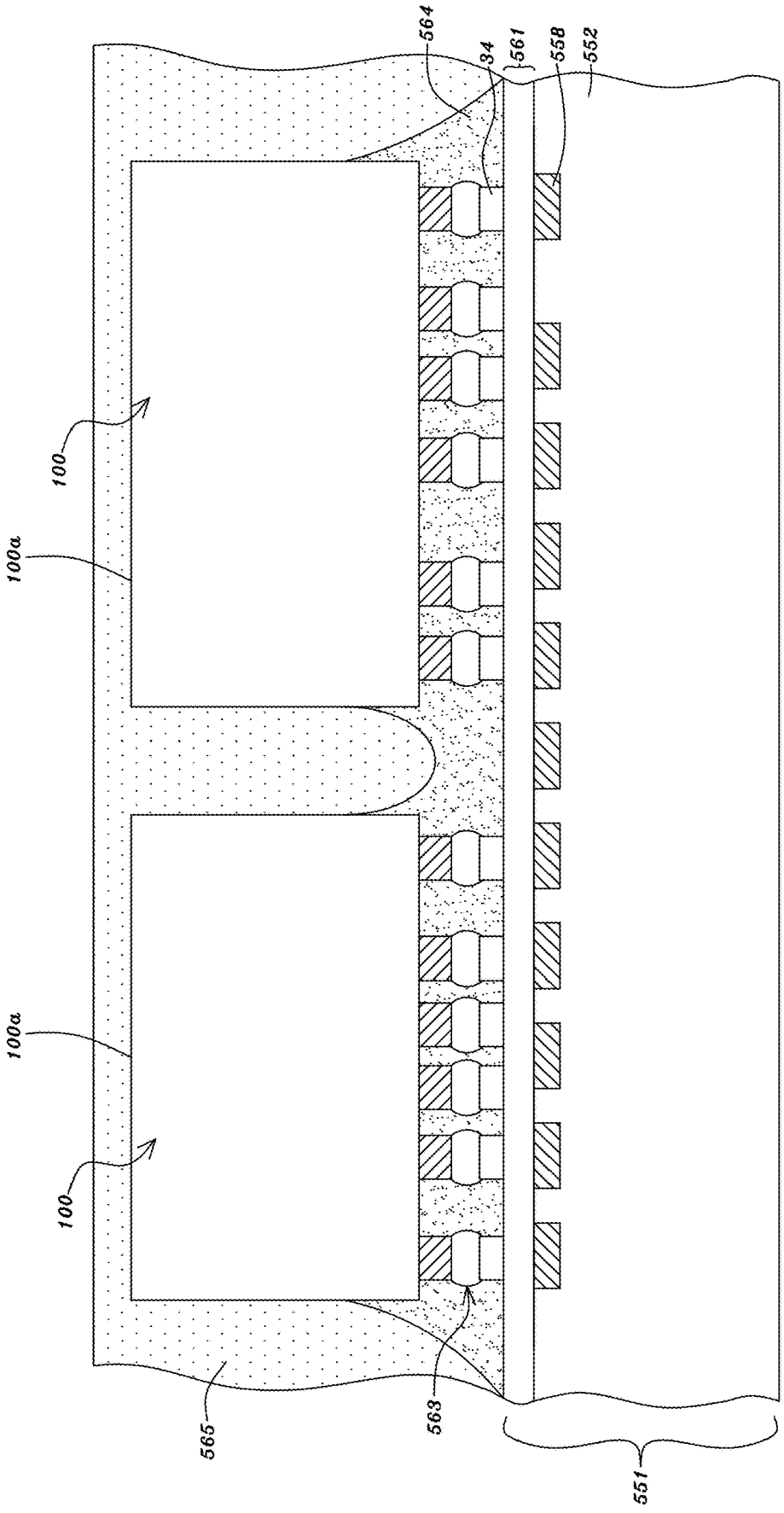


Fig. 19P

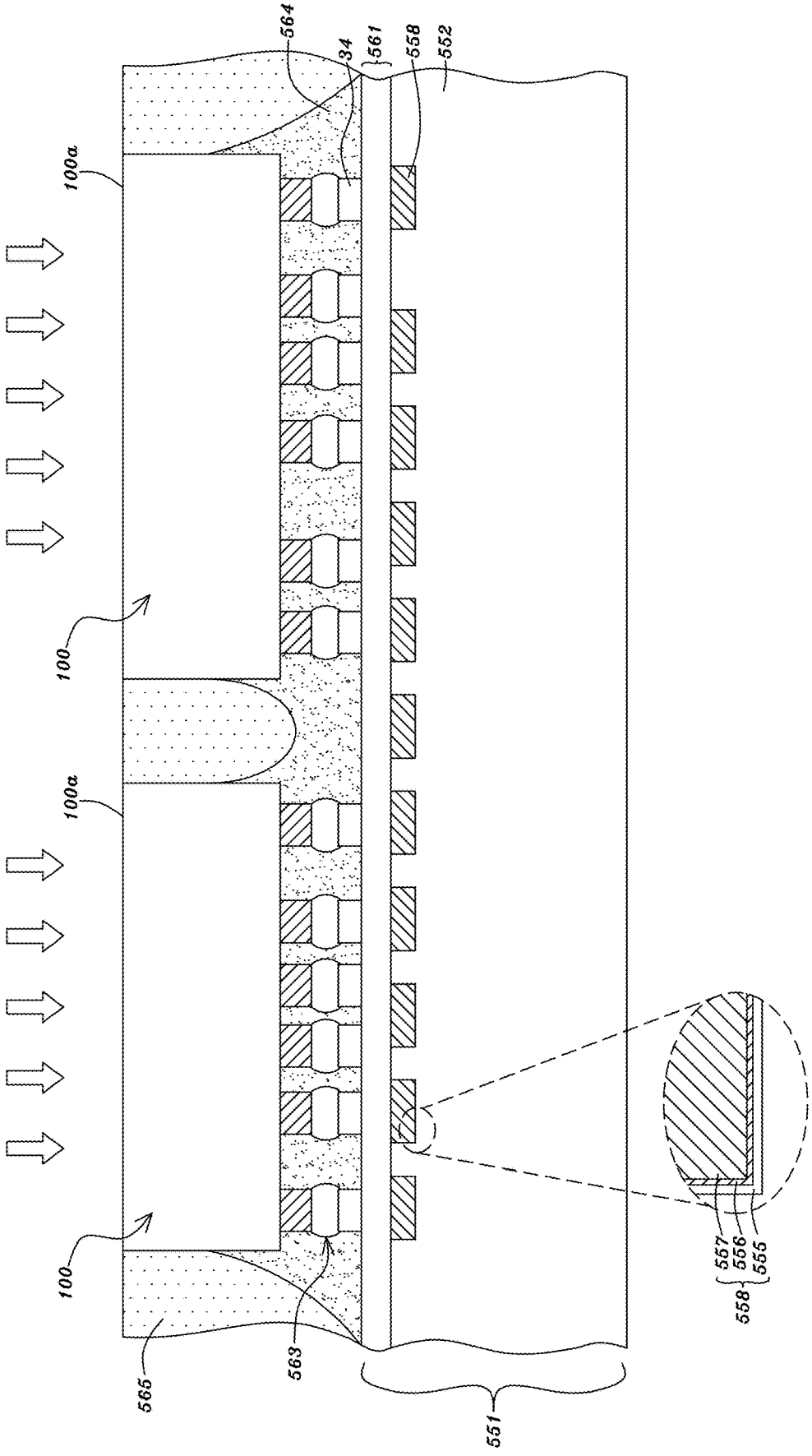


Fig. 19Q

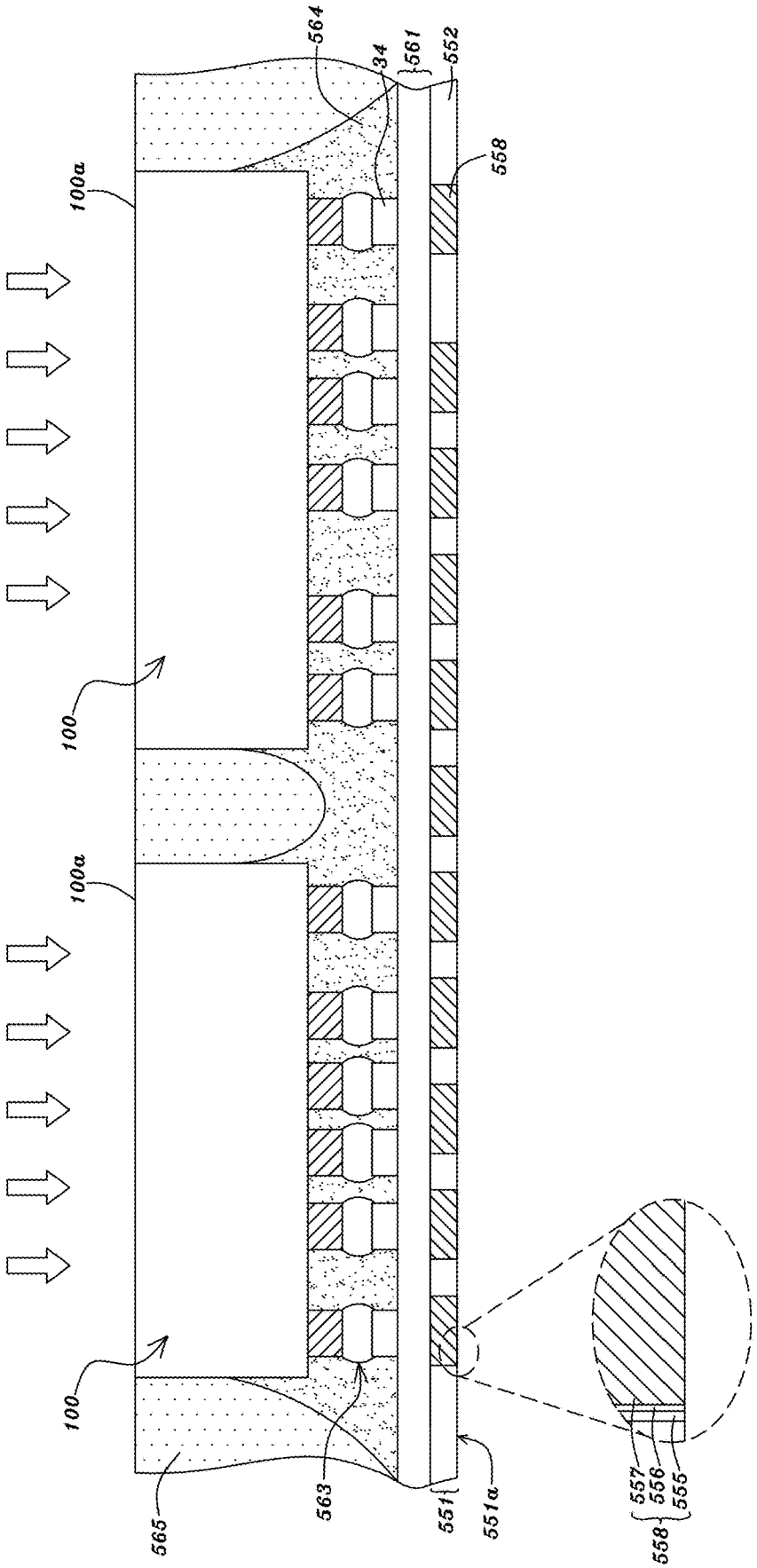

564
34
561
552
558
100a
100
100a
100
563
565
551
551a
557
556
555
558

Fig. 19R

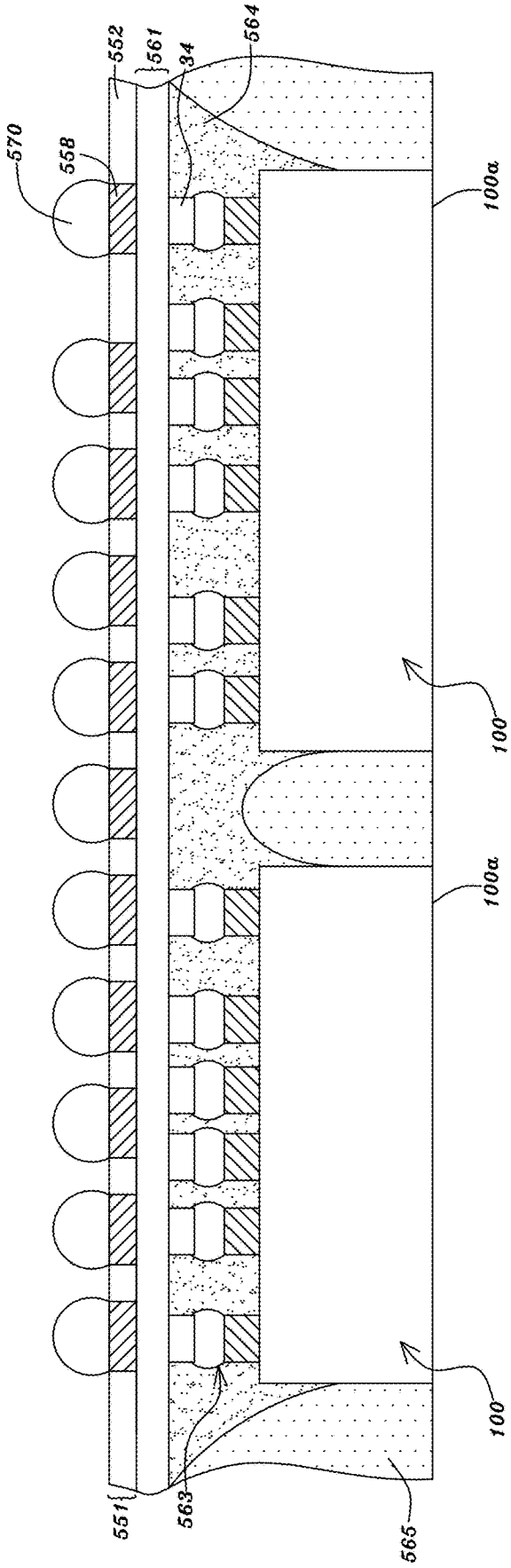


Fig. 19S

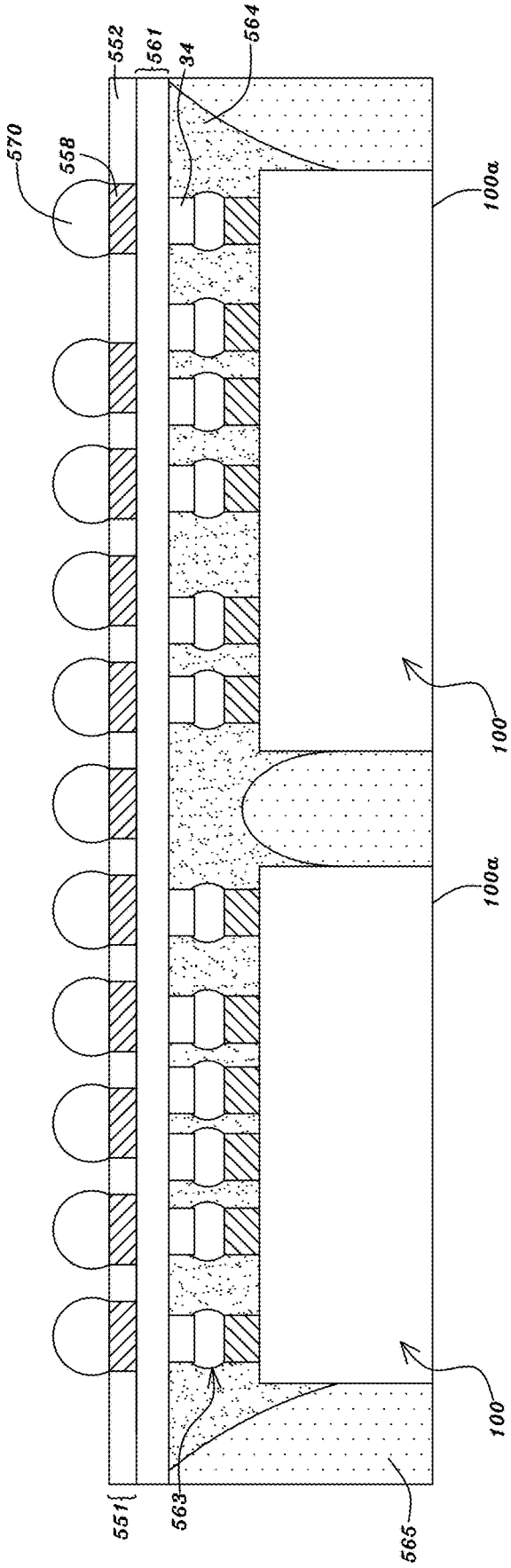


Fig. 19T

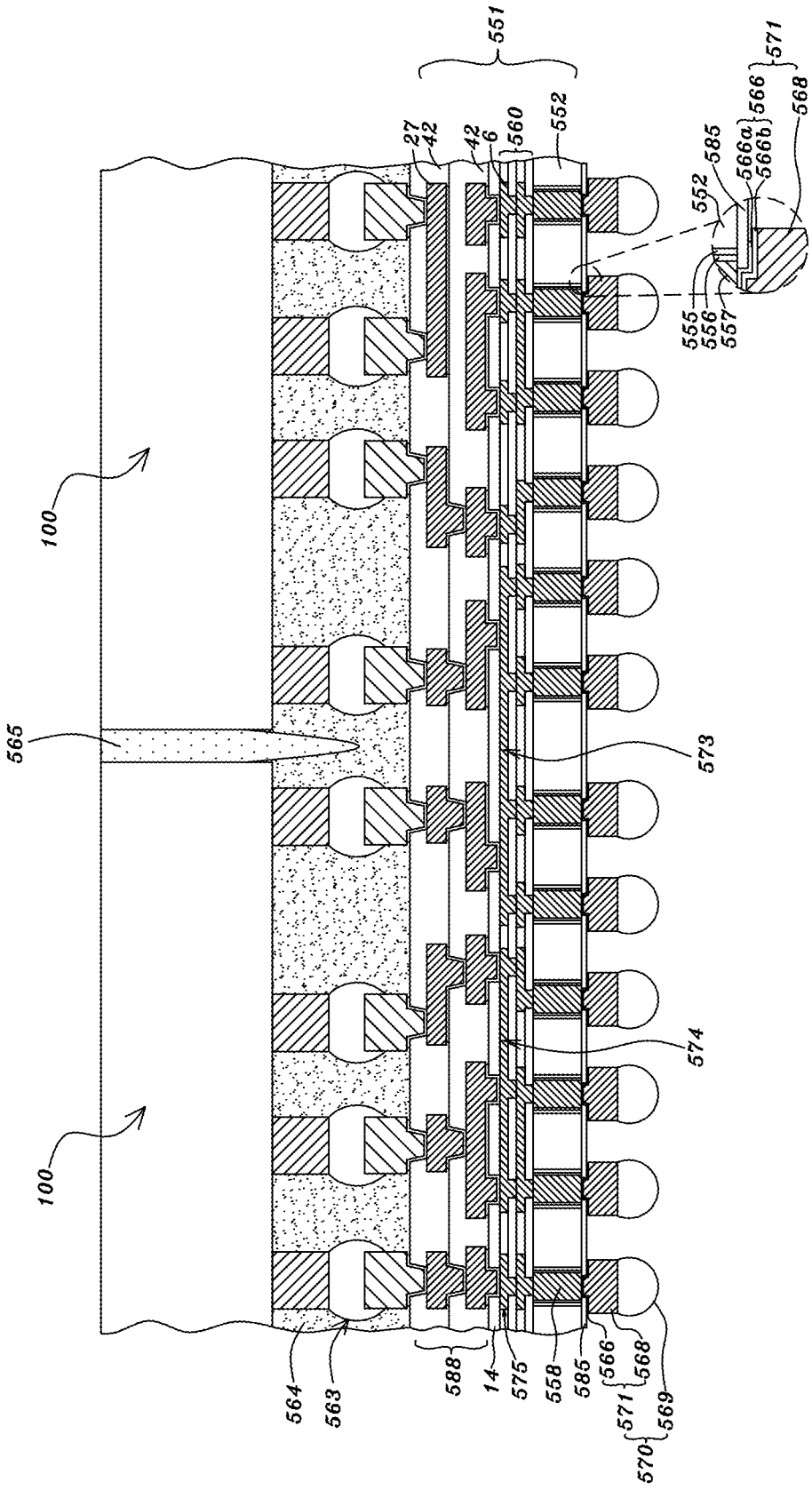

551
571
566
568
27
42
42
6
560
552
585
566a
566b
552
555
556
557
100
565
573
574
100
564
563
588
14
575
558
585
566
568
571
569
570

Fig. 20A

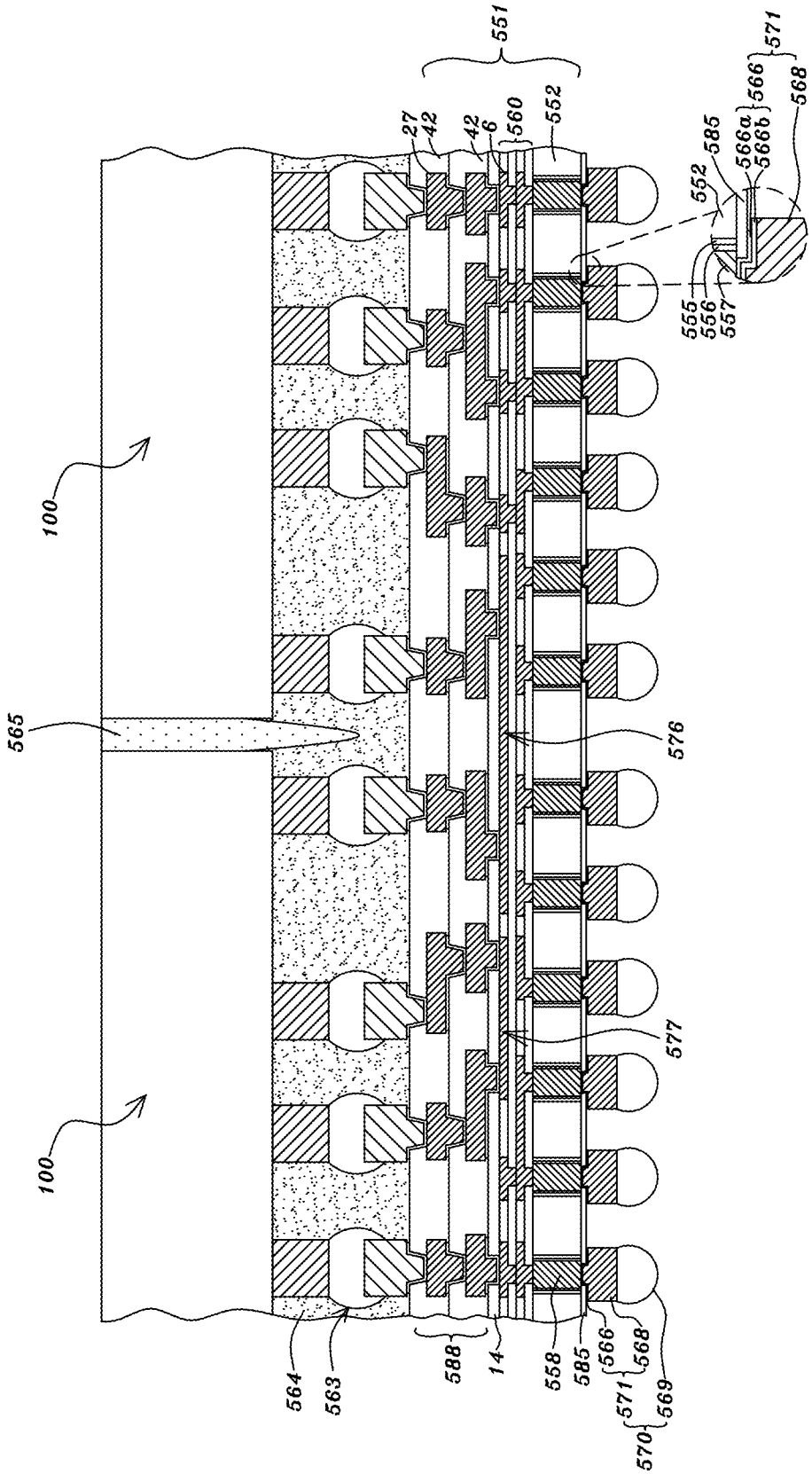

551
571
566
568
27
42
42
6
560
552
585
566a
566b
552
555
556
557
100
565
576
577
100
564
563
588
14
558
585
566
568
571
569
570

Fig. 20B

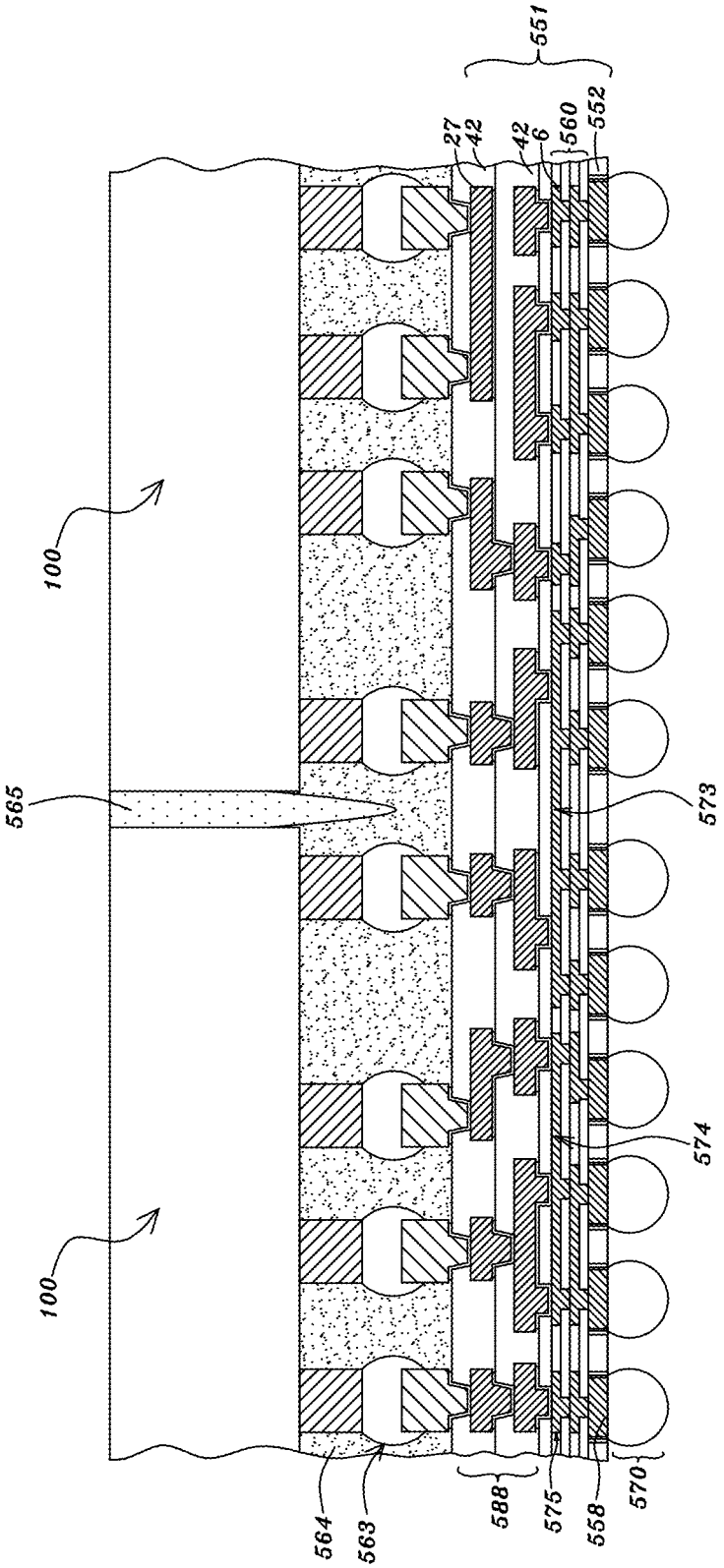


Fig. 21A

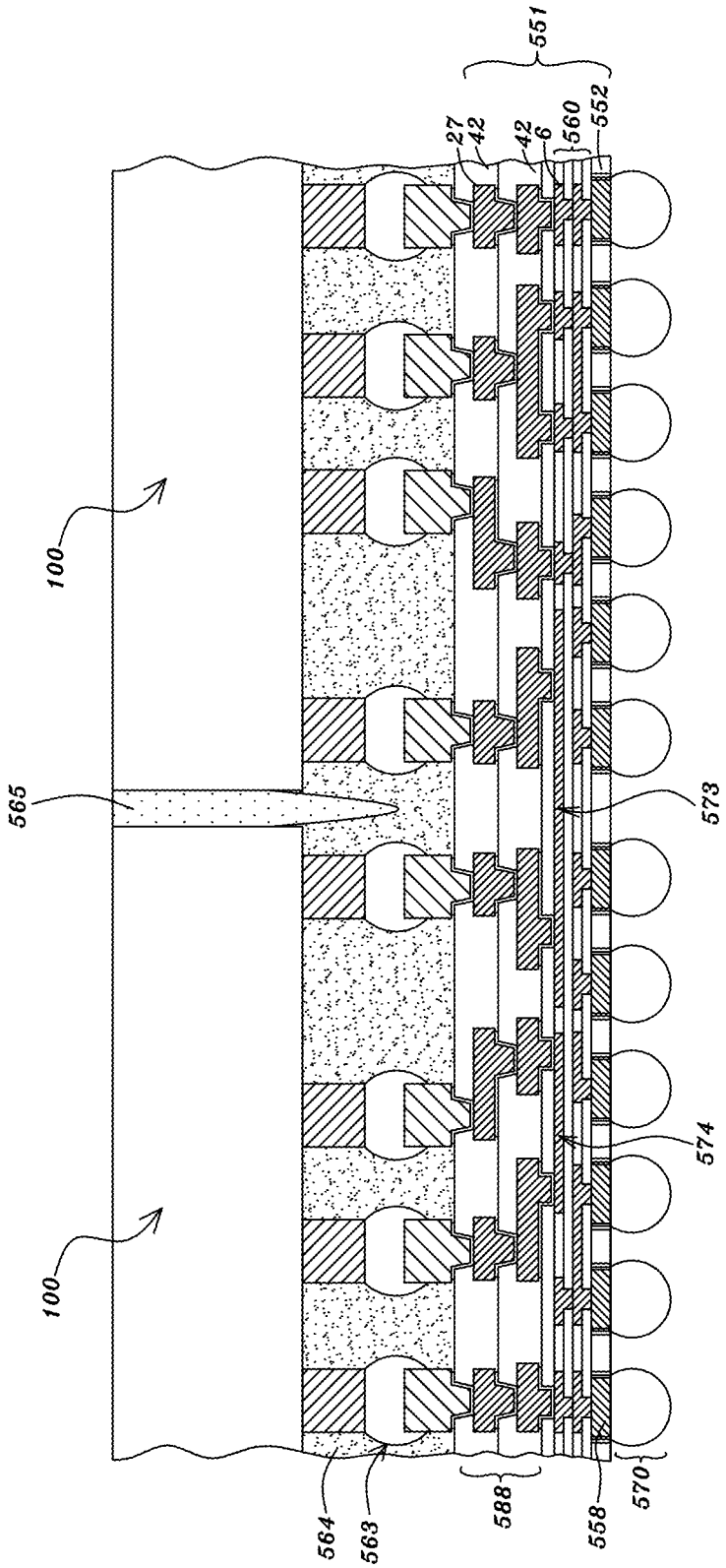


Fig. 21B

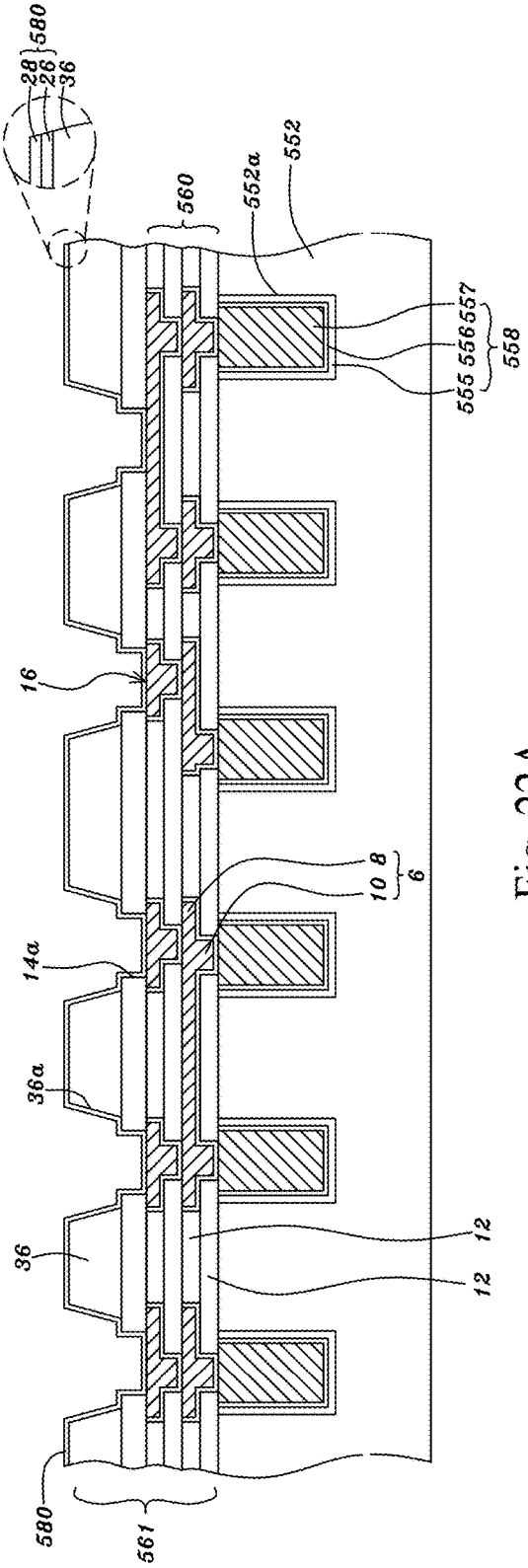


Fig. 22A

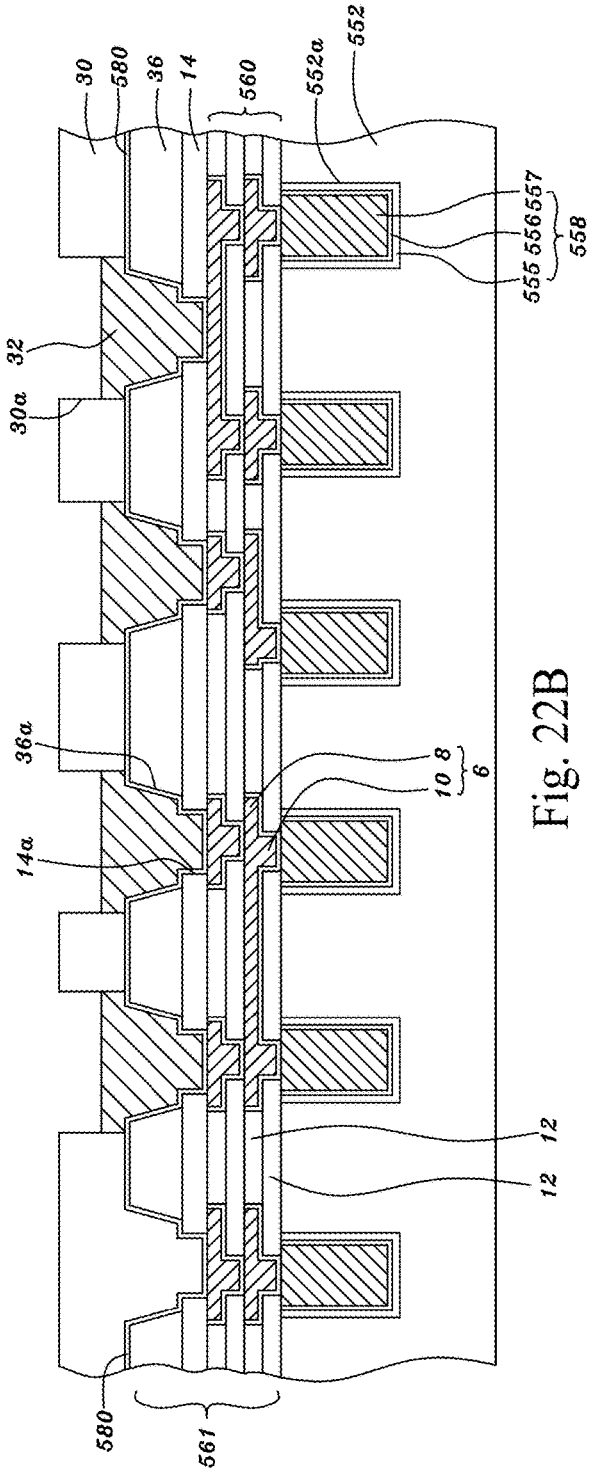


Fig. 22B

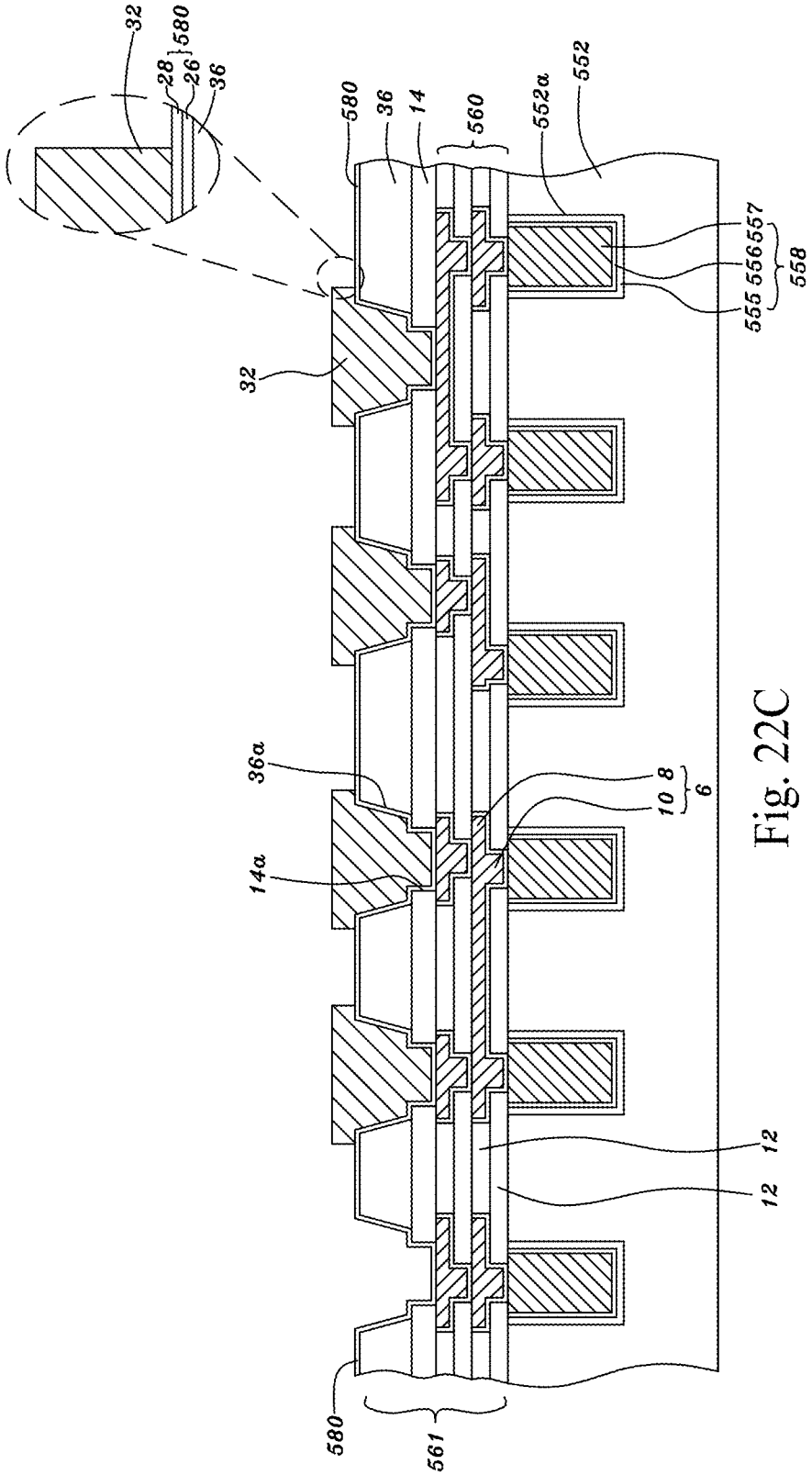

32
580
28
26
36
580
36
14
560
552a
552
557
556
555
558
32
36a
8
10
6
14a
12
12
580
561

Fig. 22C

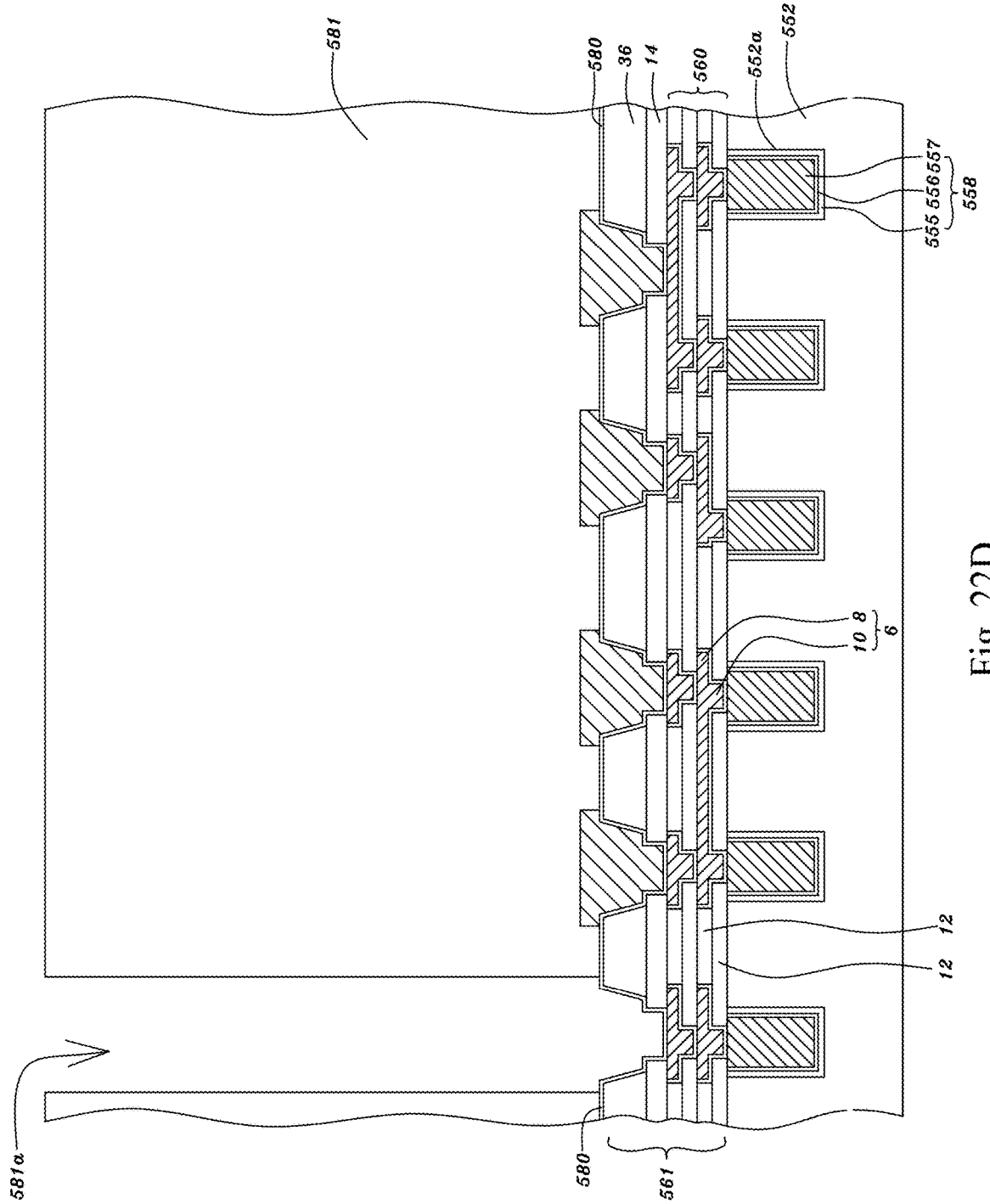

581
580
36
14
560
552a
552
555 556 557
558
10 8
6
12
12
581a
580
561

Fig. 22D

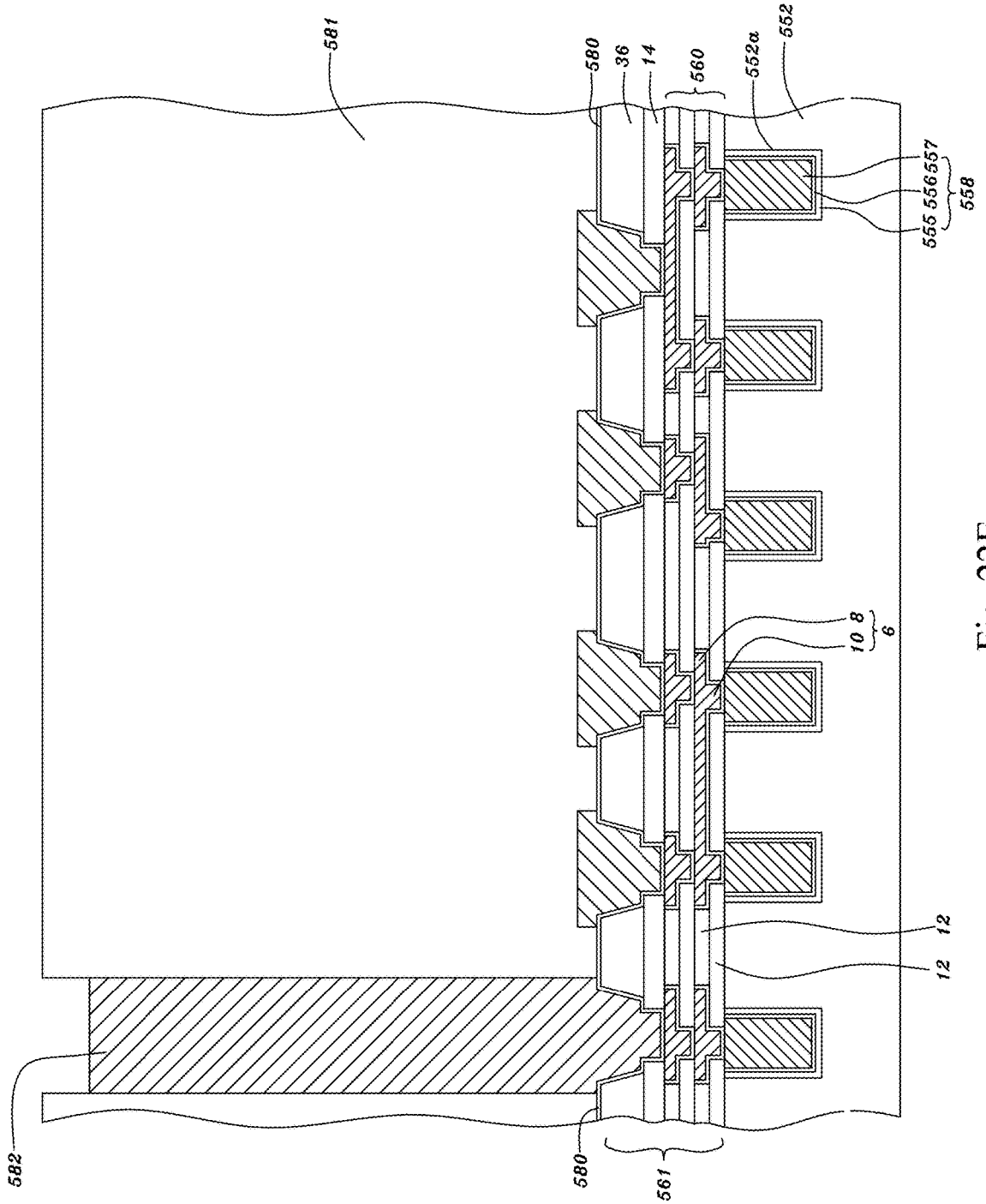


Fig. 22E

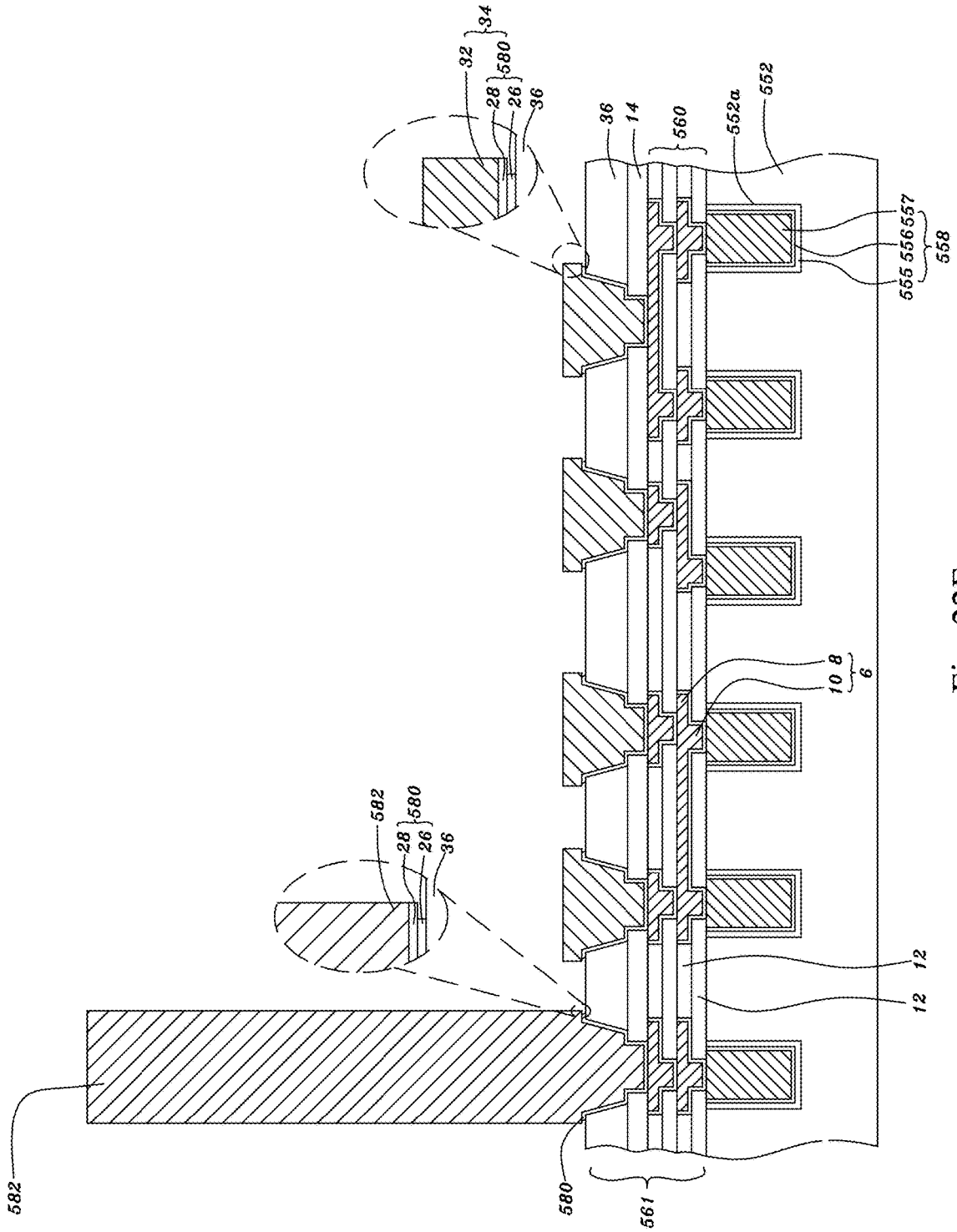

582
580
561
582
28
26
36
580
32
34
28
26
36
36
14
560
552a
552
555 556 557
558
10 8
6
12
12

Fig. 22F

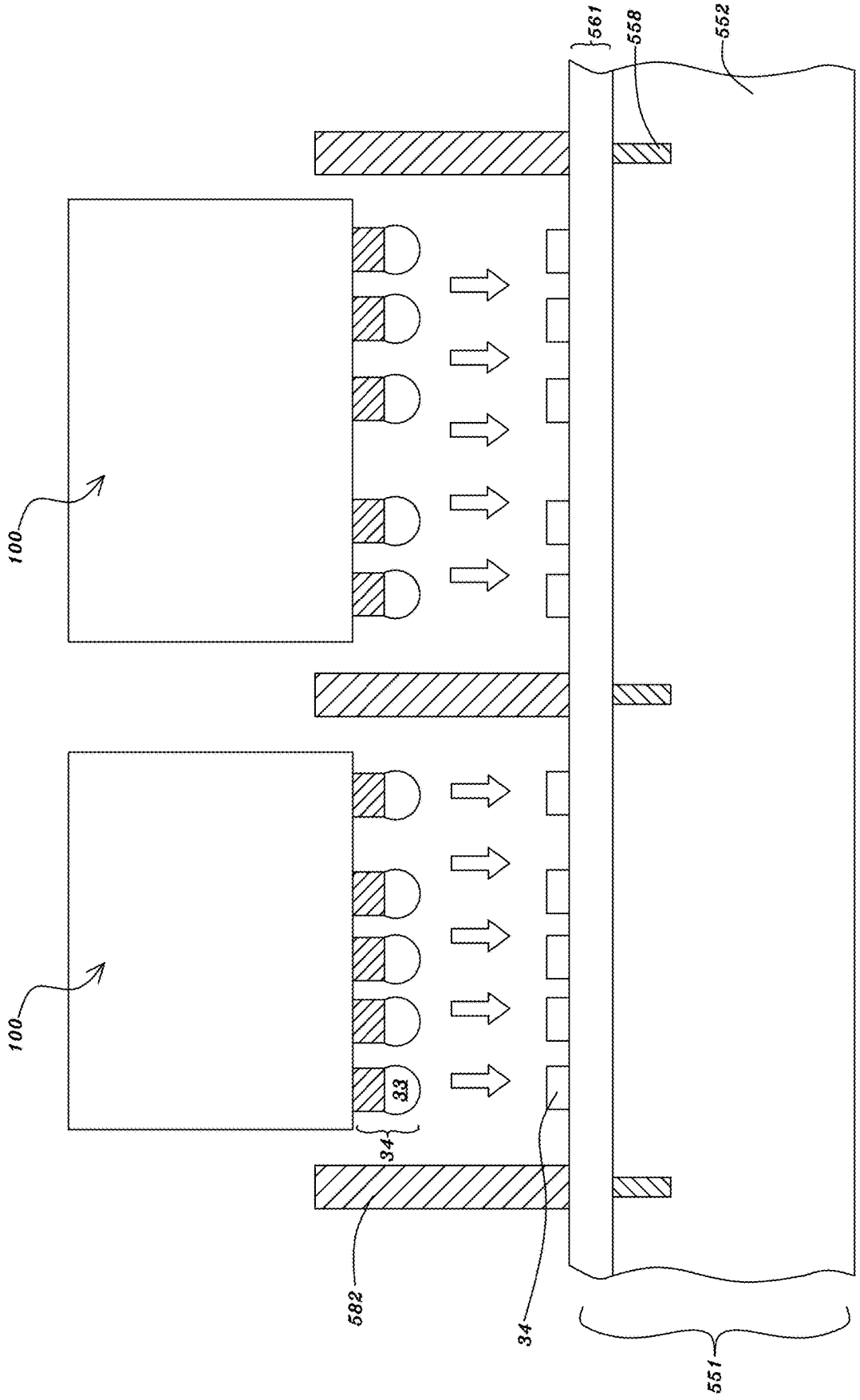


Fig. 22G

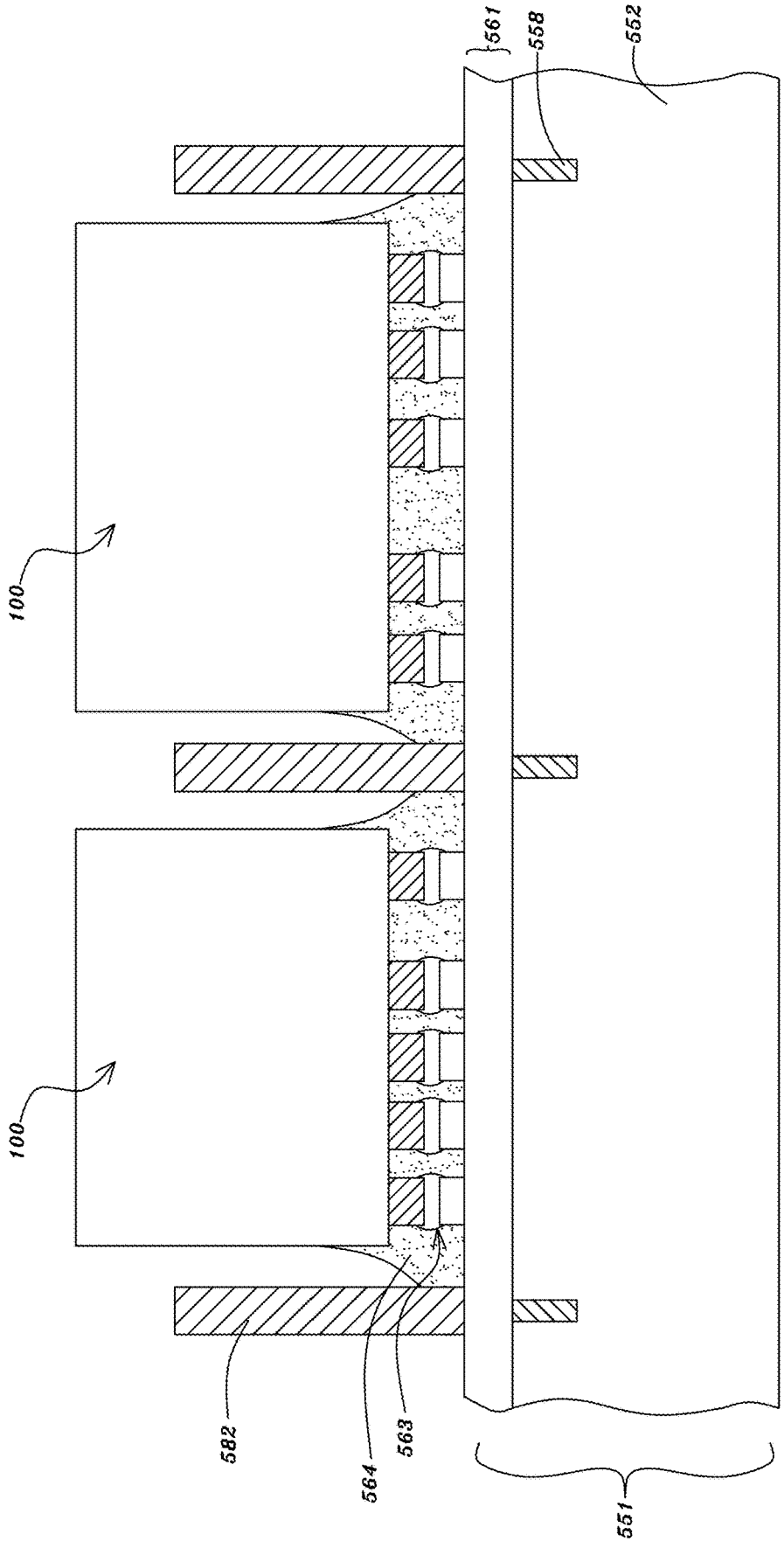


Fig. 22H

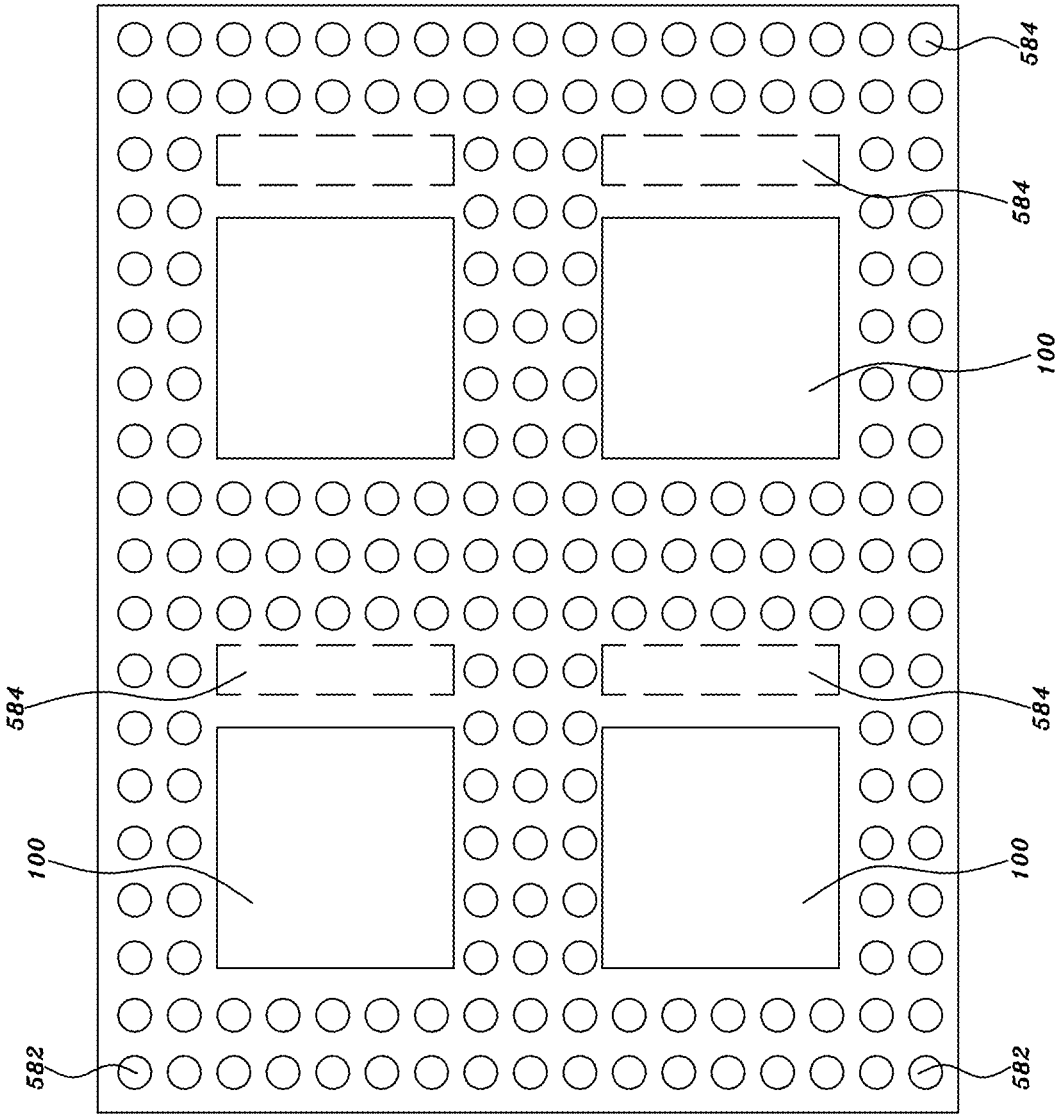


Fig. 22I

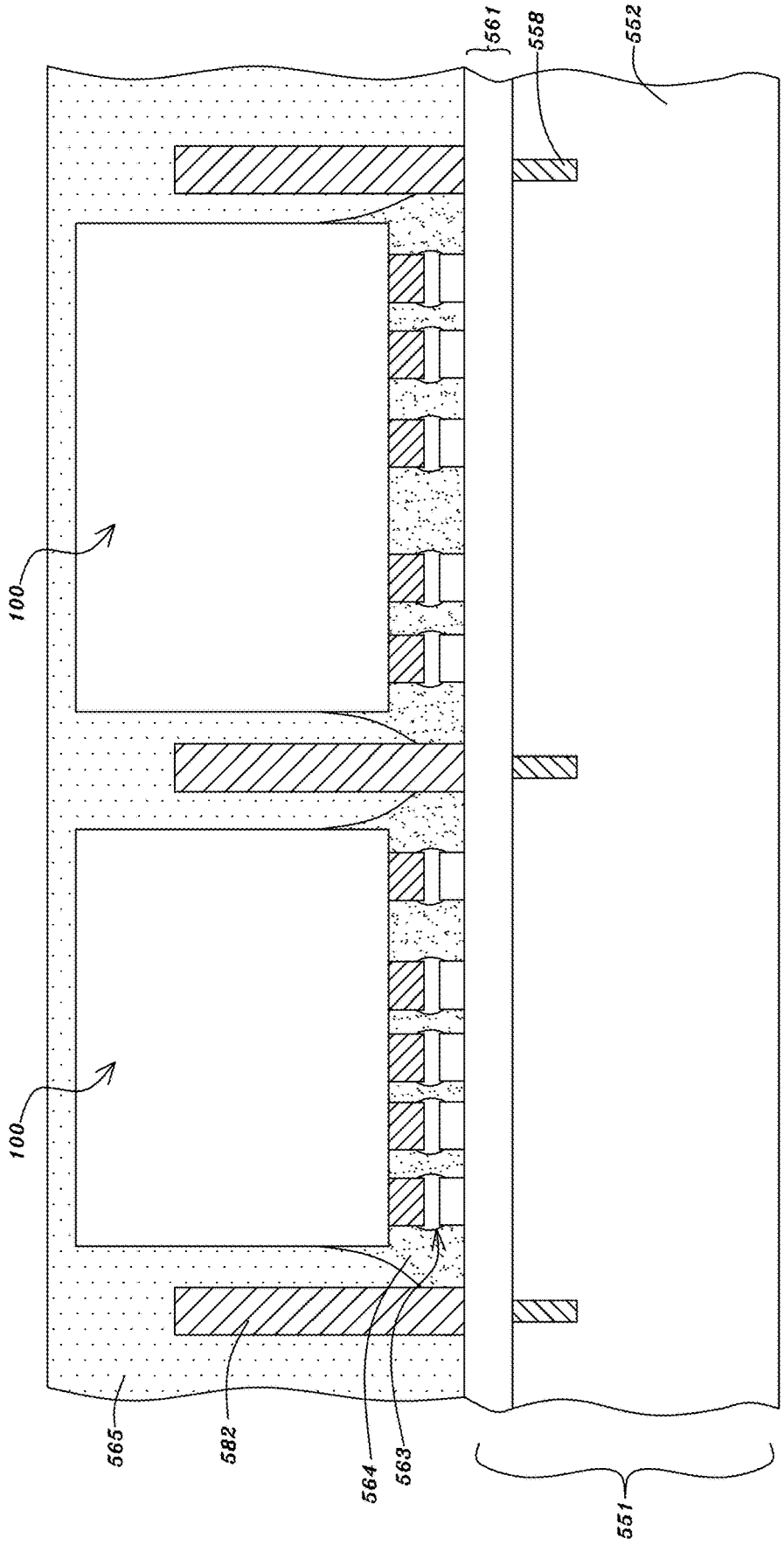


Fig. 22J

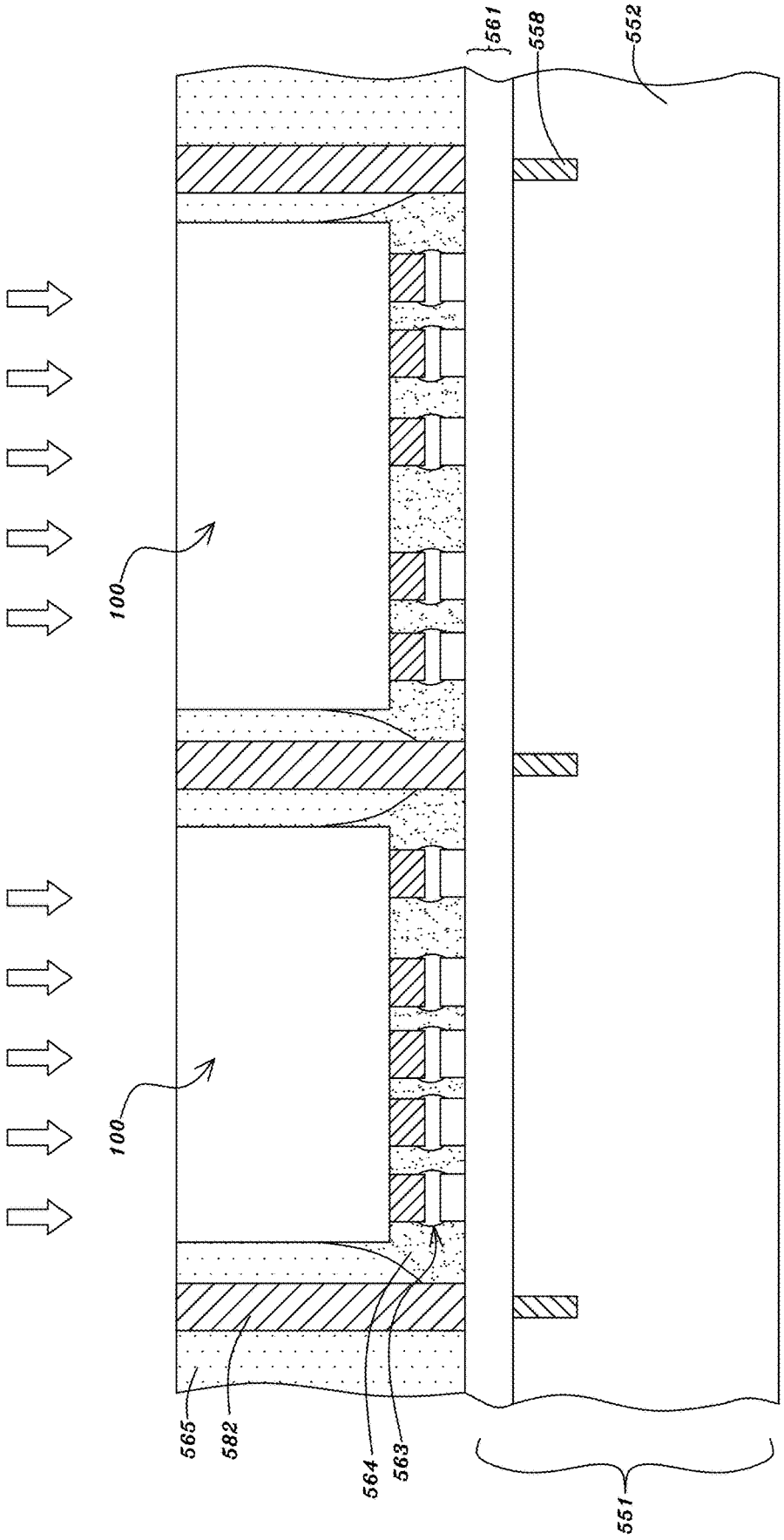


Fig. 22K

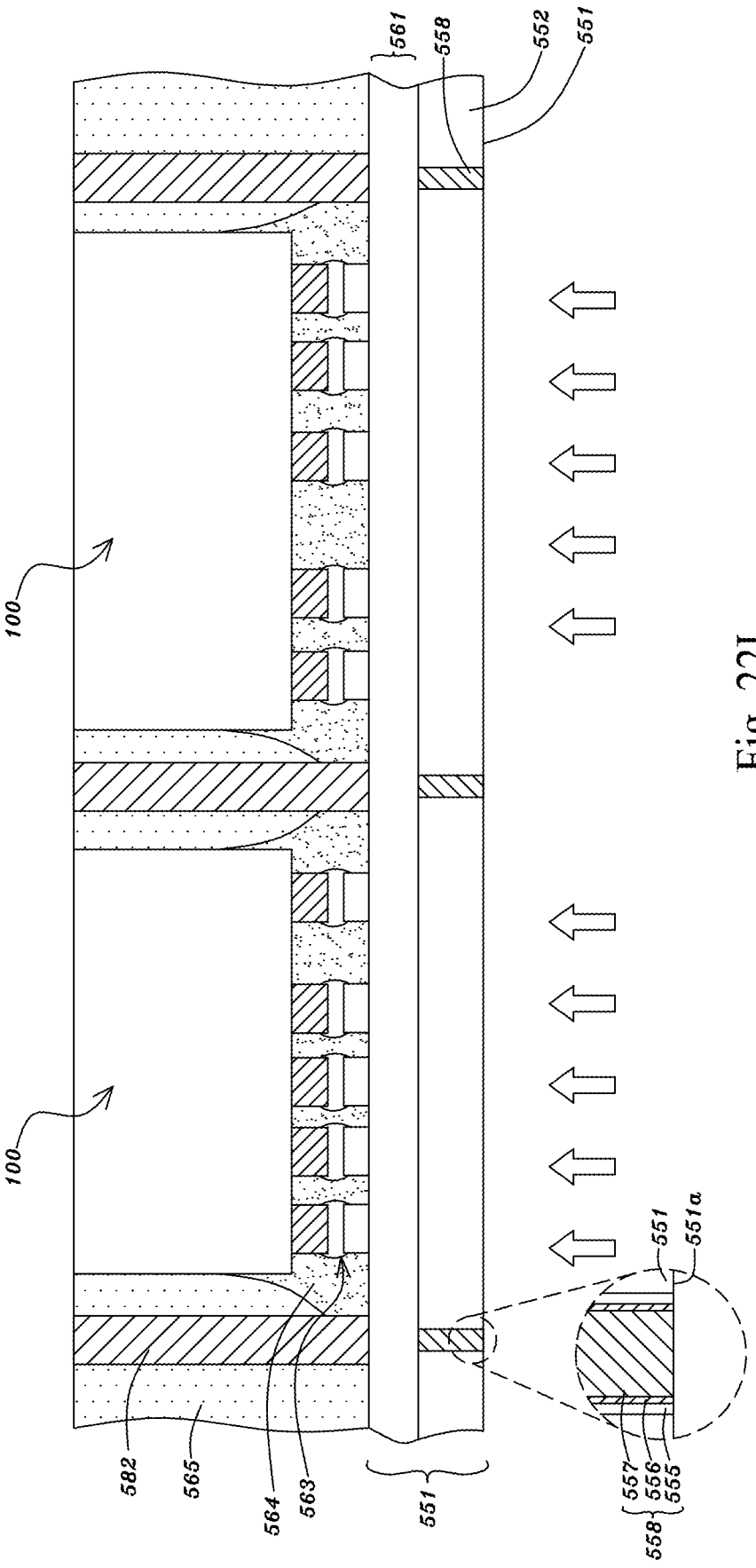

561
558
552
551
100
100
582
565
564
563
551
551
551a
557
556
555
558

Fig. 22L

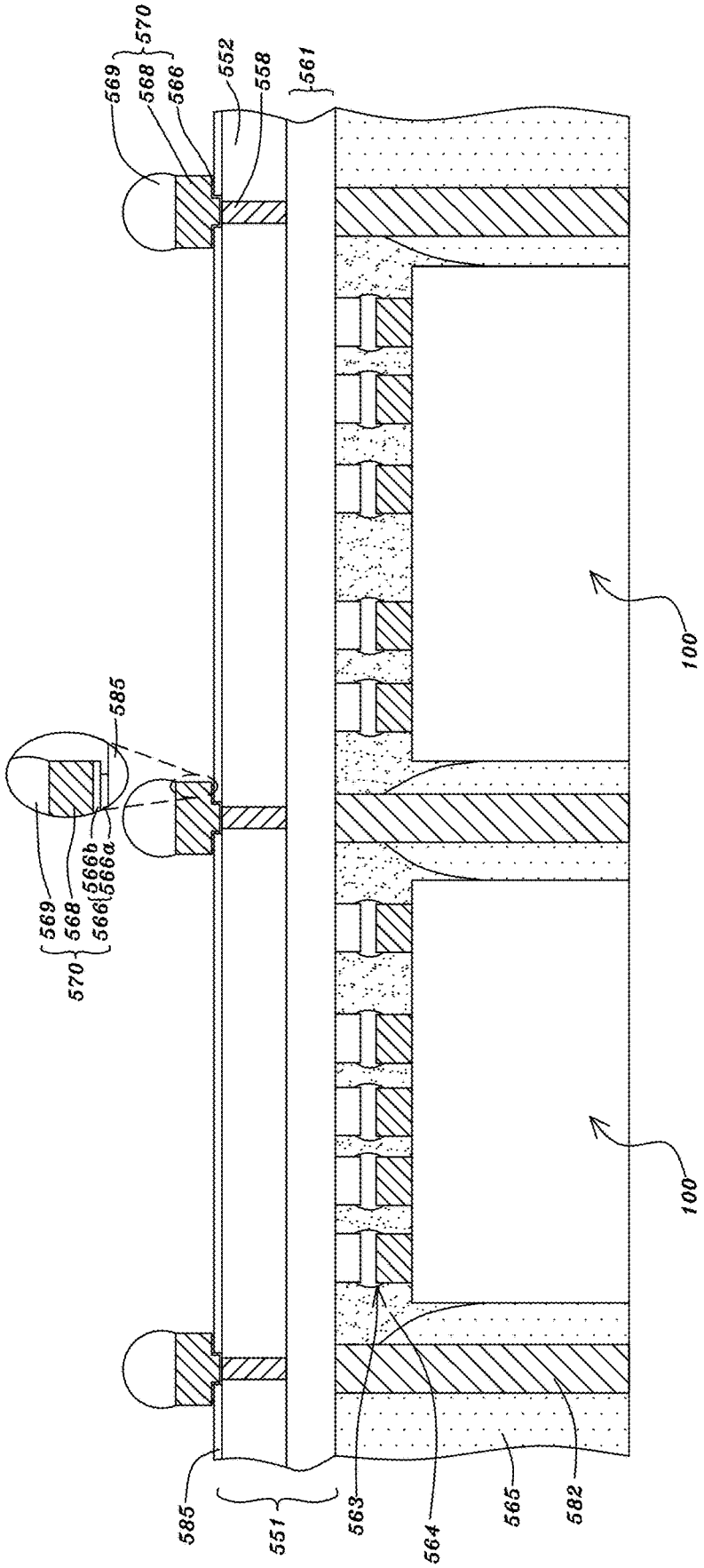

570
569
568
566
552
558
561
585
566b
566a
566
568
569
570
100
100
585
551
563
564
565
582

Fig. 22M

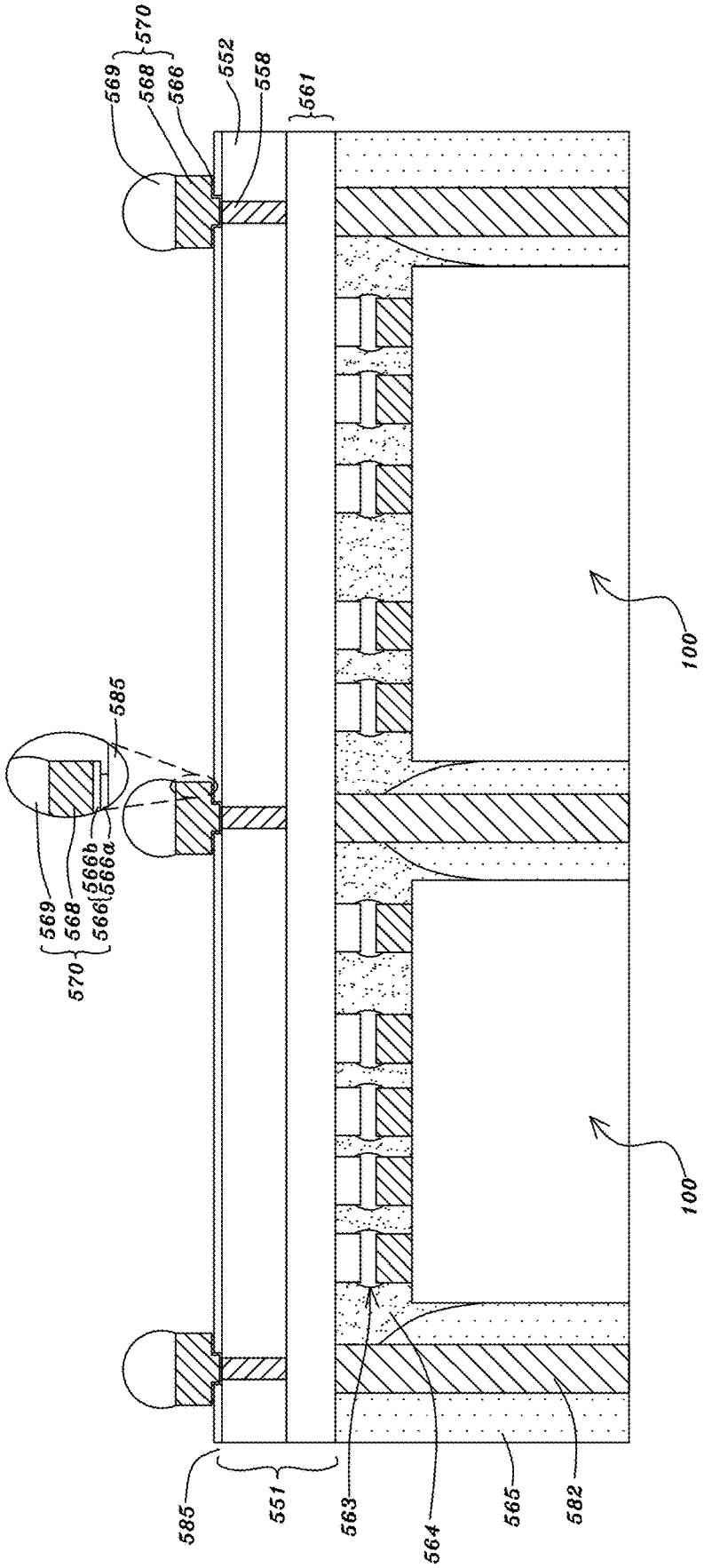

570
569
568
566
552
558
561
585
566b
566a
100
100
585
551
563
564
565
582

Fig. 22N

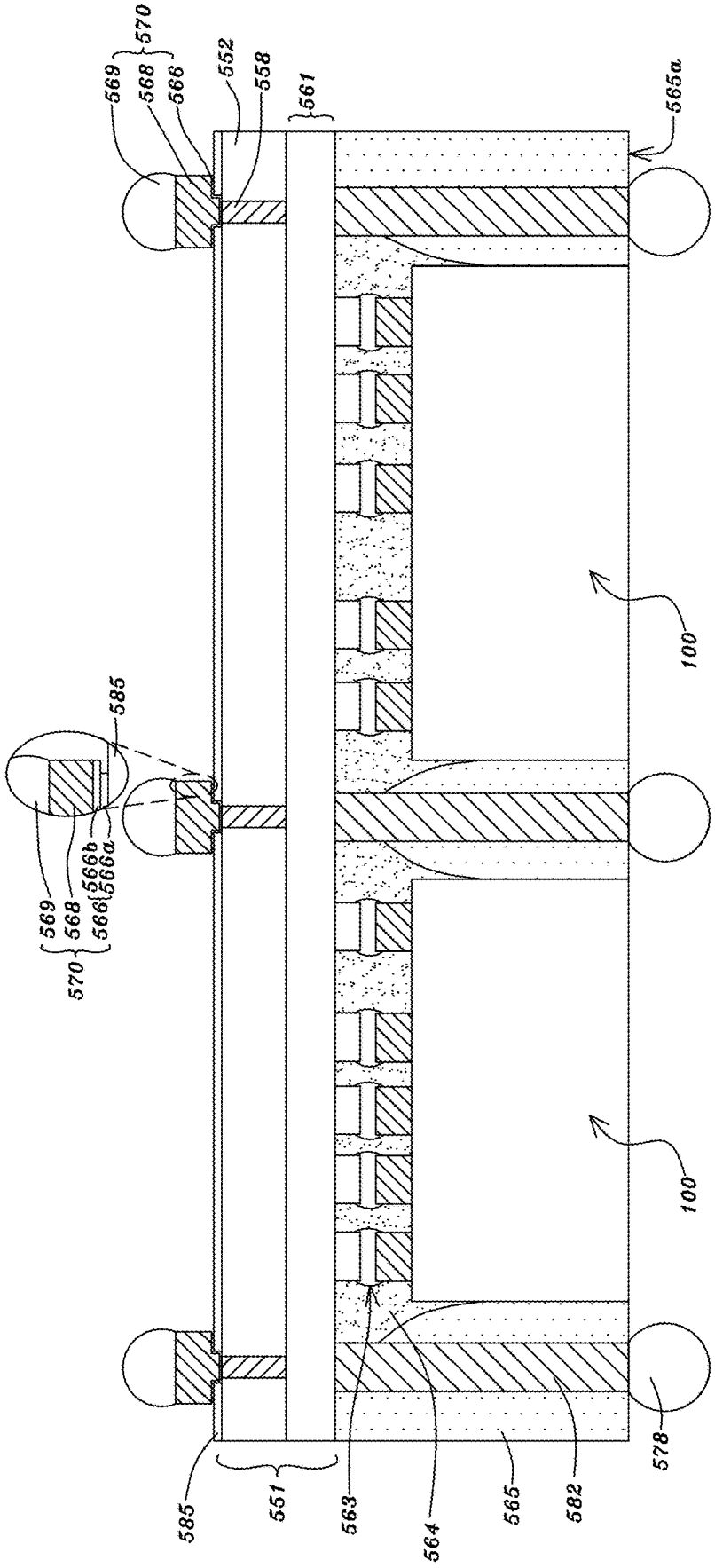

570
569
568
566
552
558
561
565a
100
585
566b
566a
569
568
566
570
100
585
551
563
564
565
582
578

Fig. 220

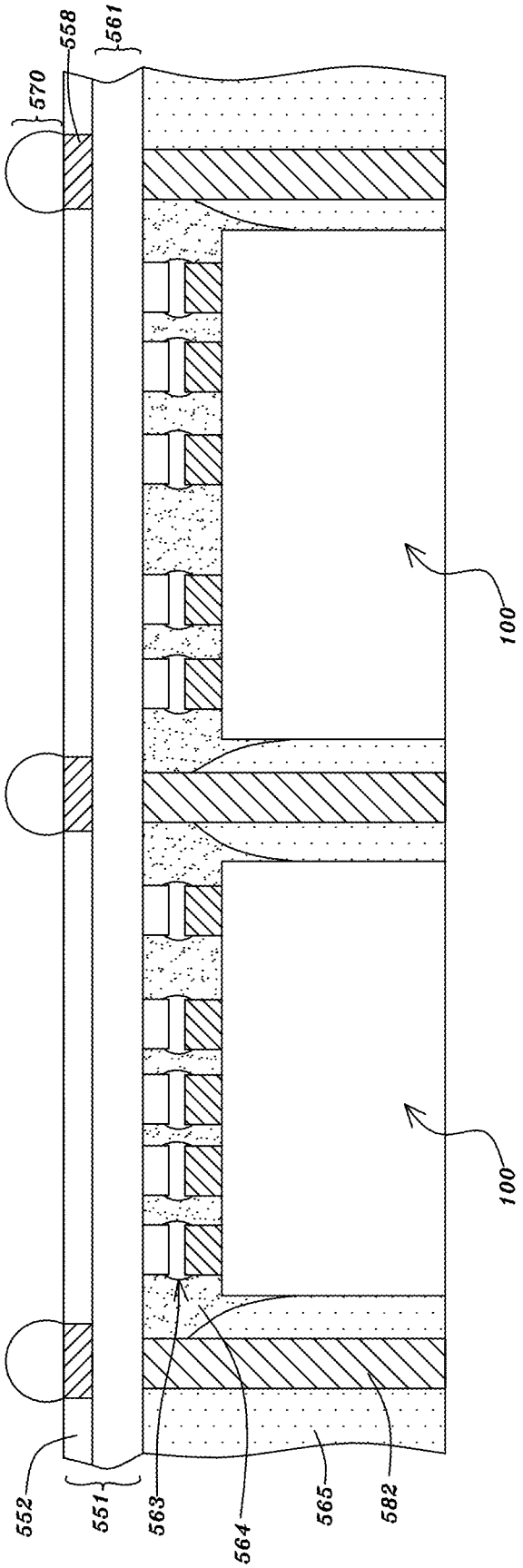


Fig. 23A

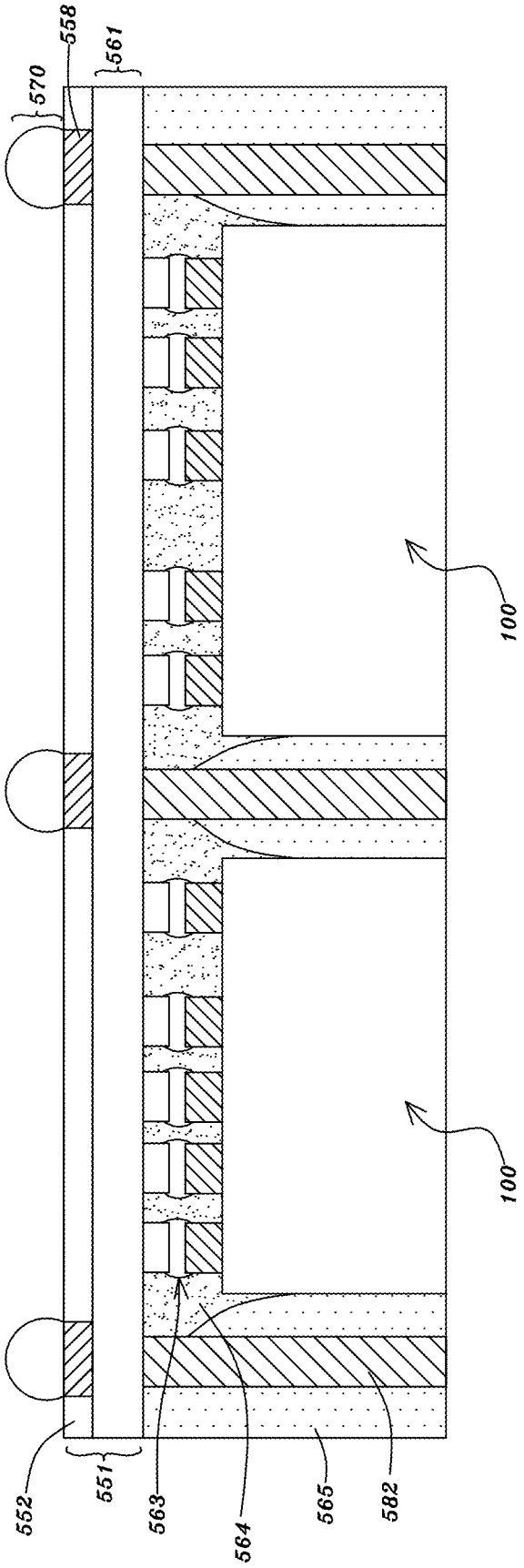


Fig. 23B

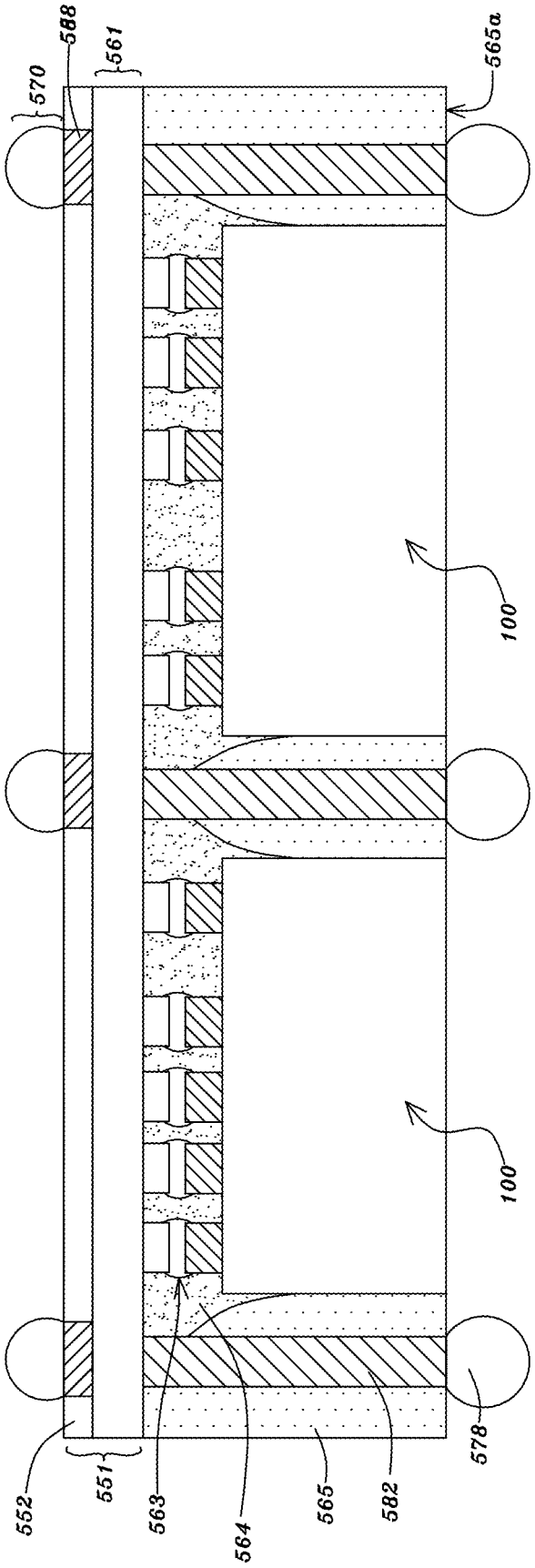


Fig. 23C

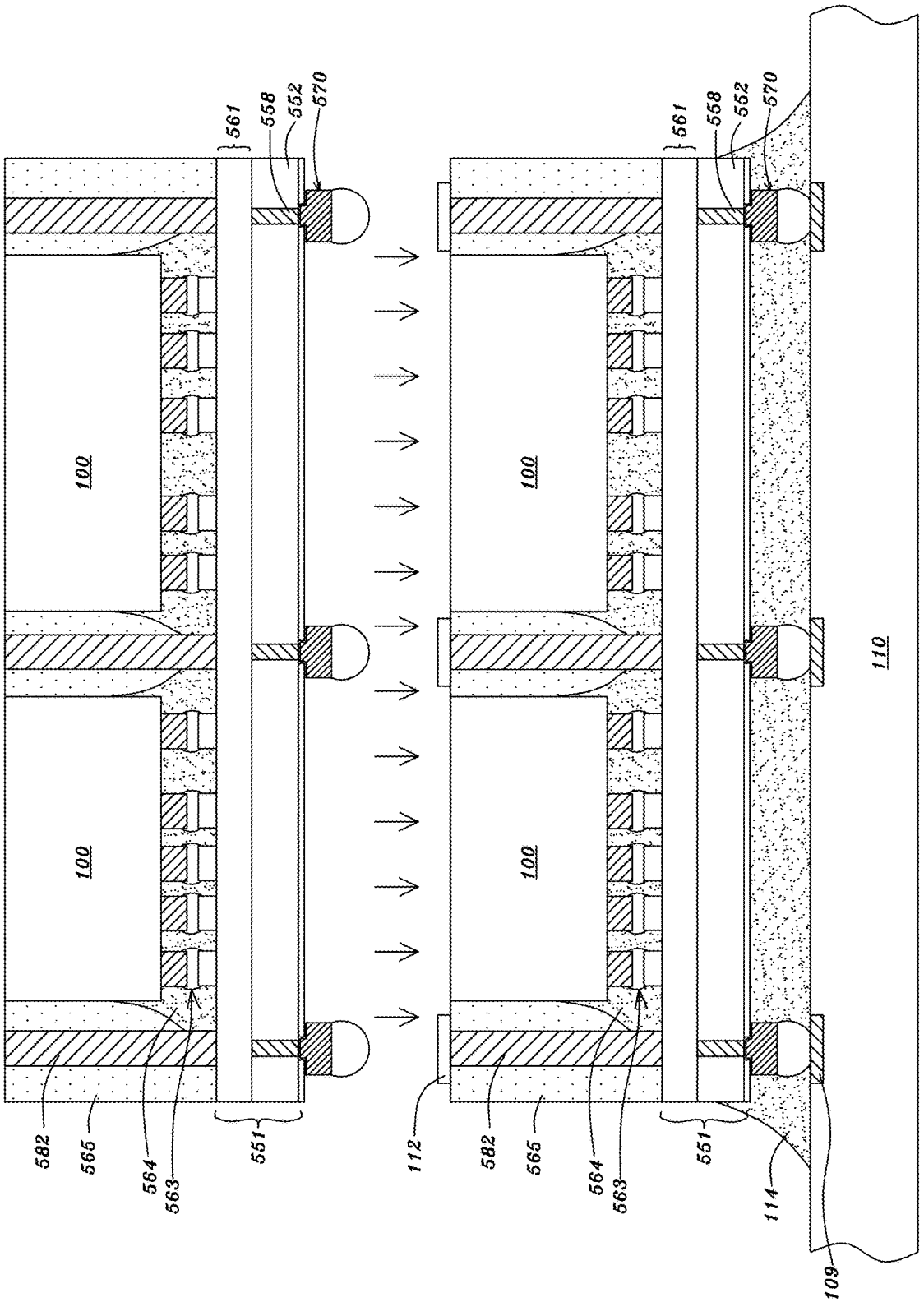

561
558
552
570
100
100
100
582
565
564
563
551
112
582
565
564
563
551
114
109
110

Fig. 24A

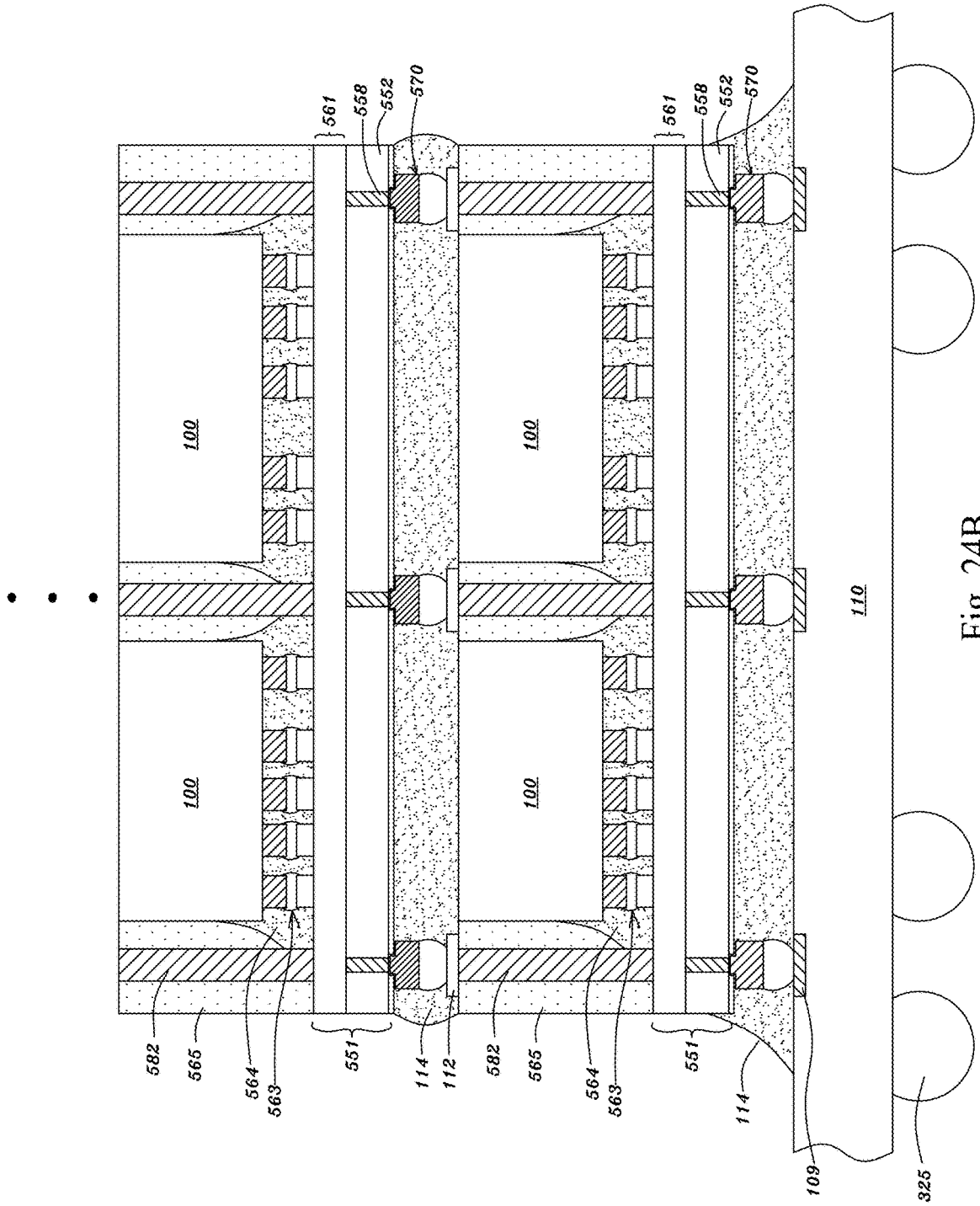


Fig. 24B

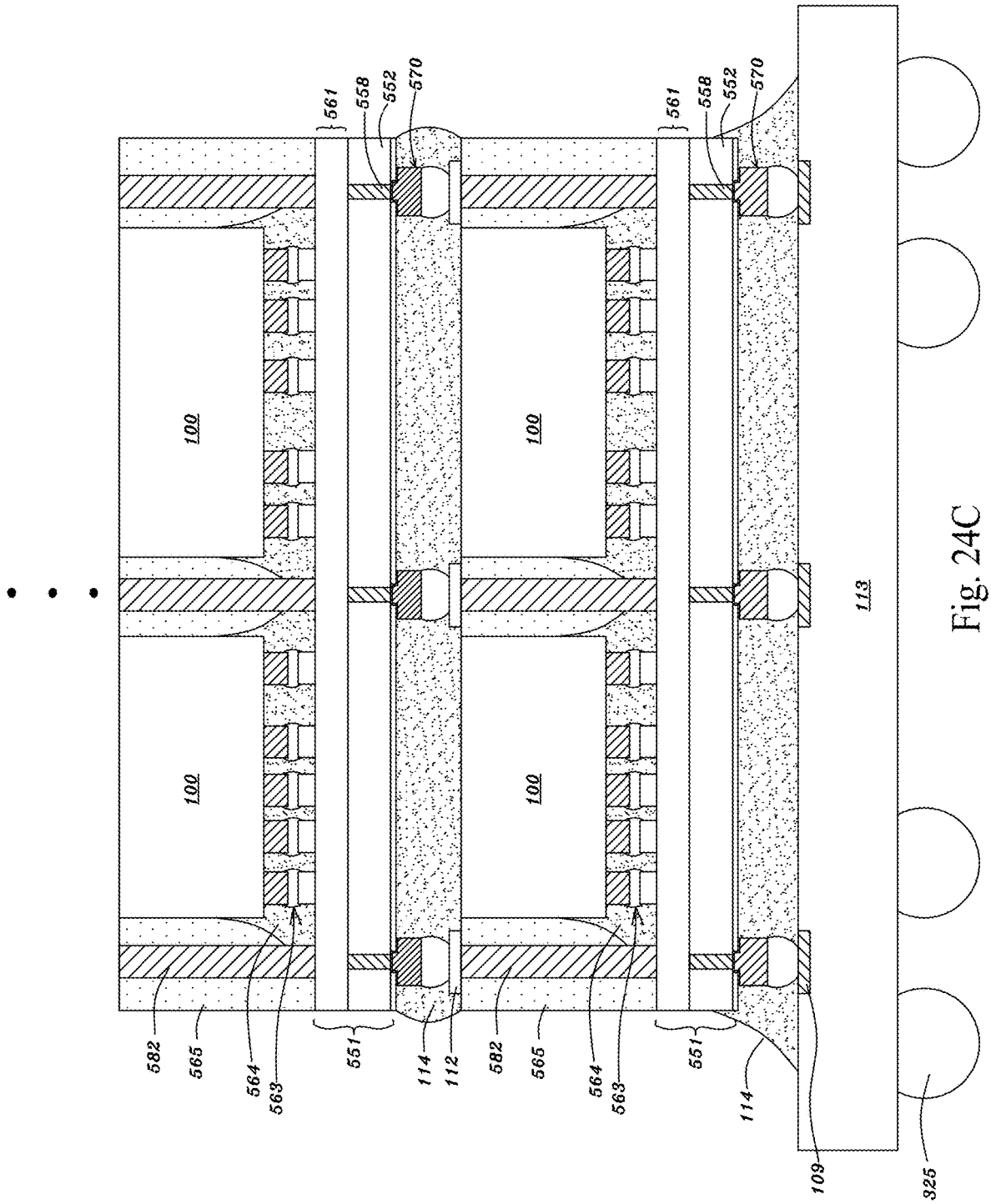

561
558
552
570
561
558
552
570
100
100
100
100
113
582
565
564
563
551
114
112
582
565
564
563
551
114
109
325

Fig. 24C

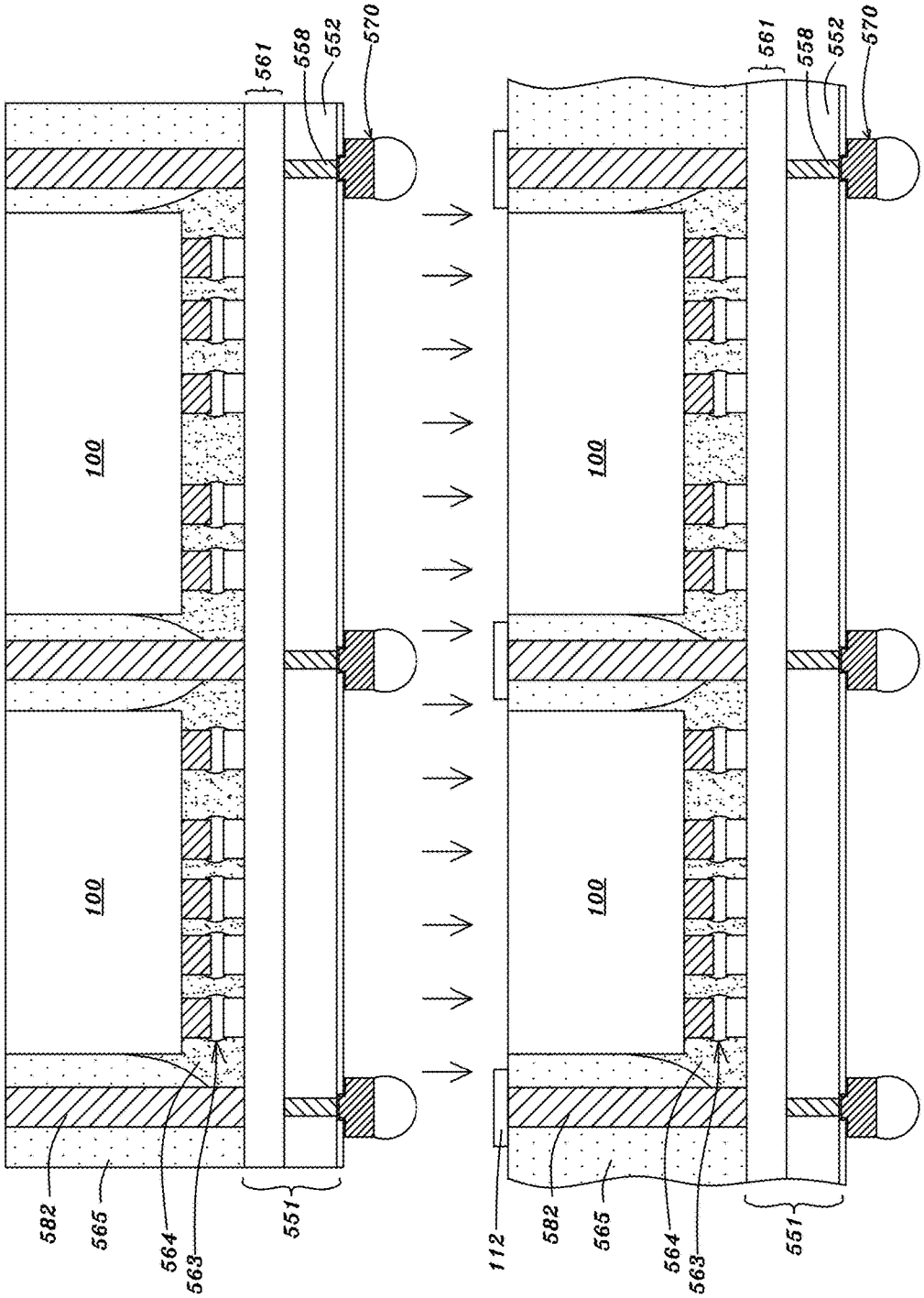


Fig. 24D

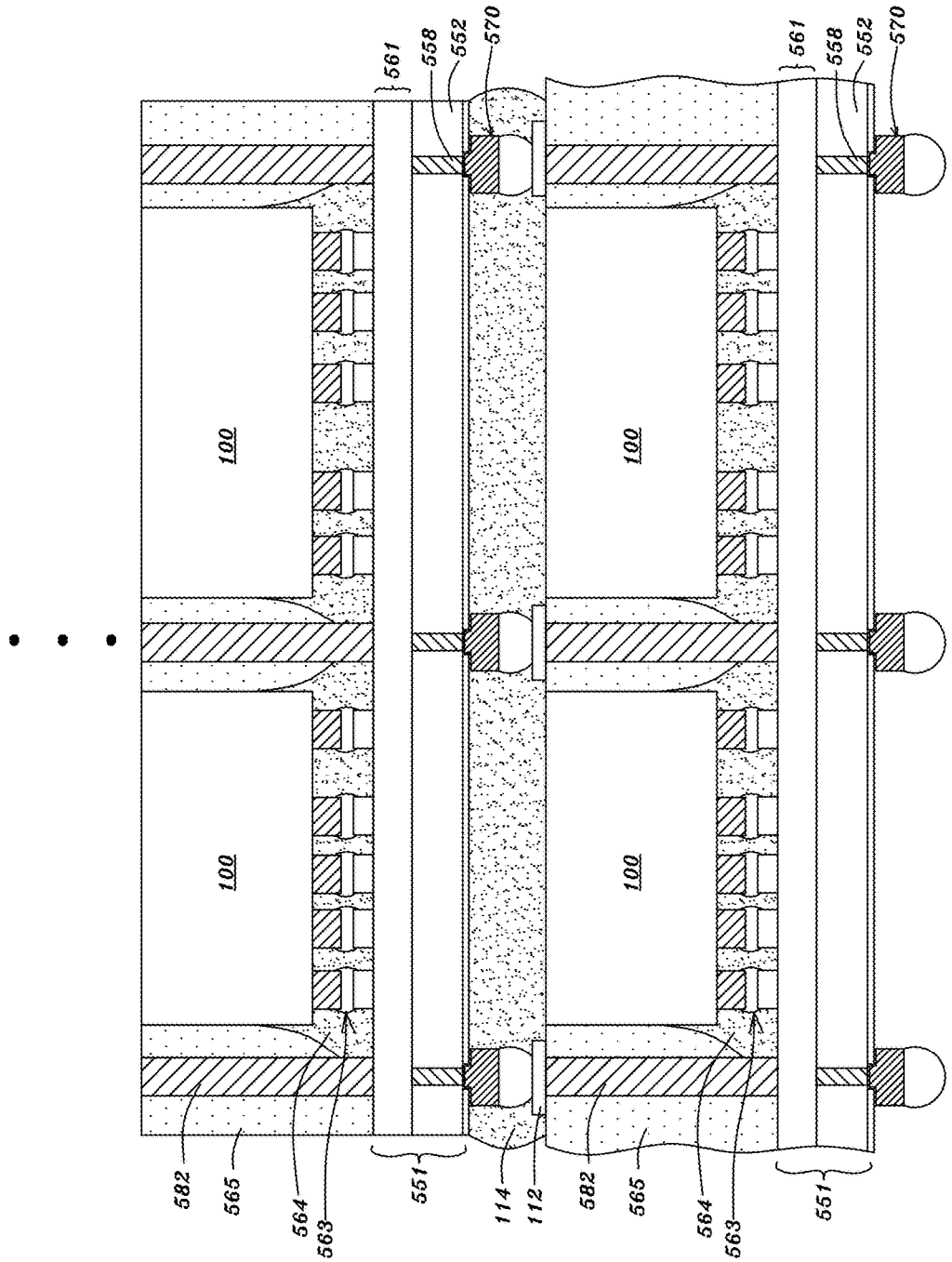


Fig. 24E

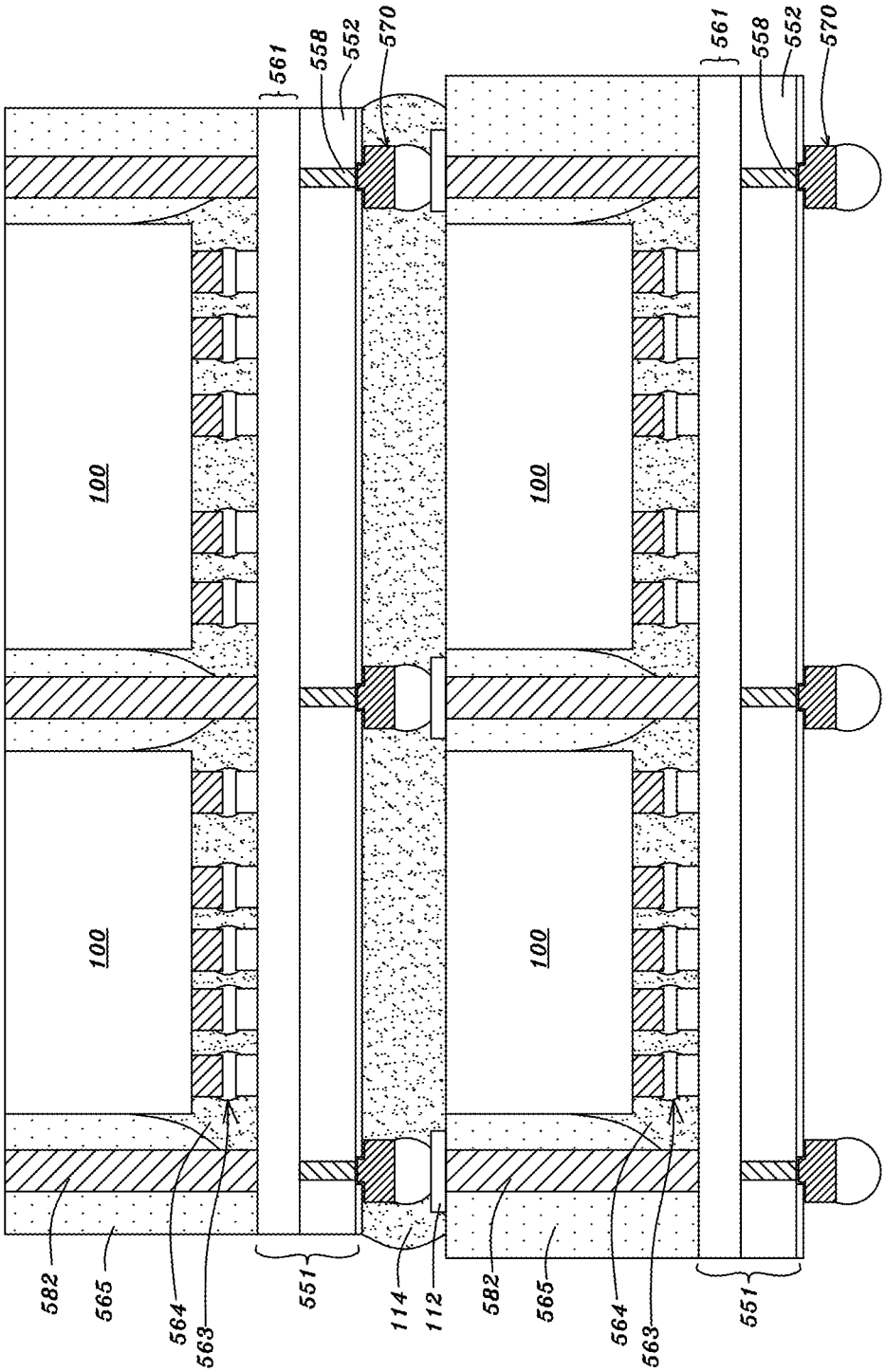

561
558
552
570
561
558
552
570
100
100
100
100
582
565
564
563
551
114
112
582
565
564
563
551

Fig. 24F

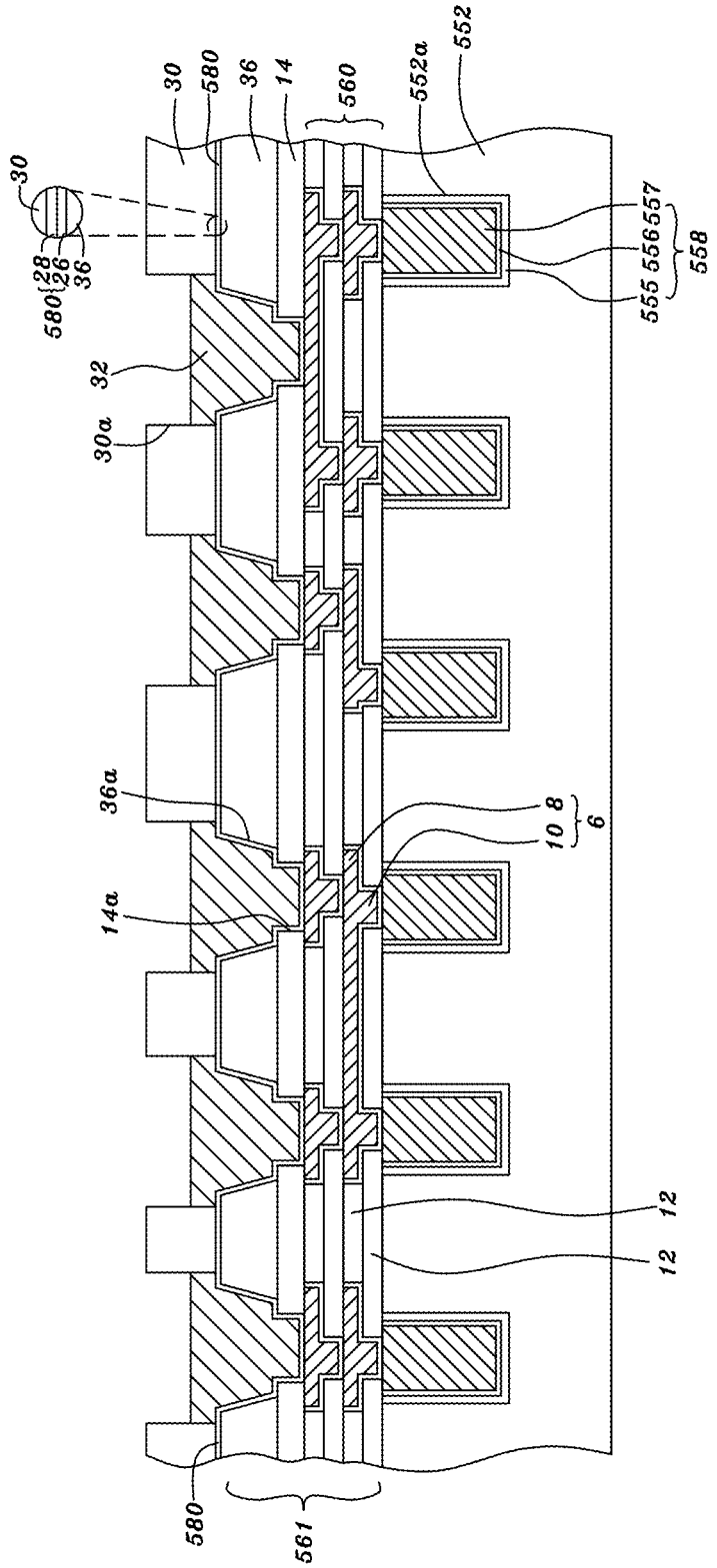

30
580
36
14
560
552a
552
30
28
26
36
580
557
556
555
558
32
30a
36a
10
8
6
14a
12
12
580
561

Fig. 25A

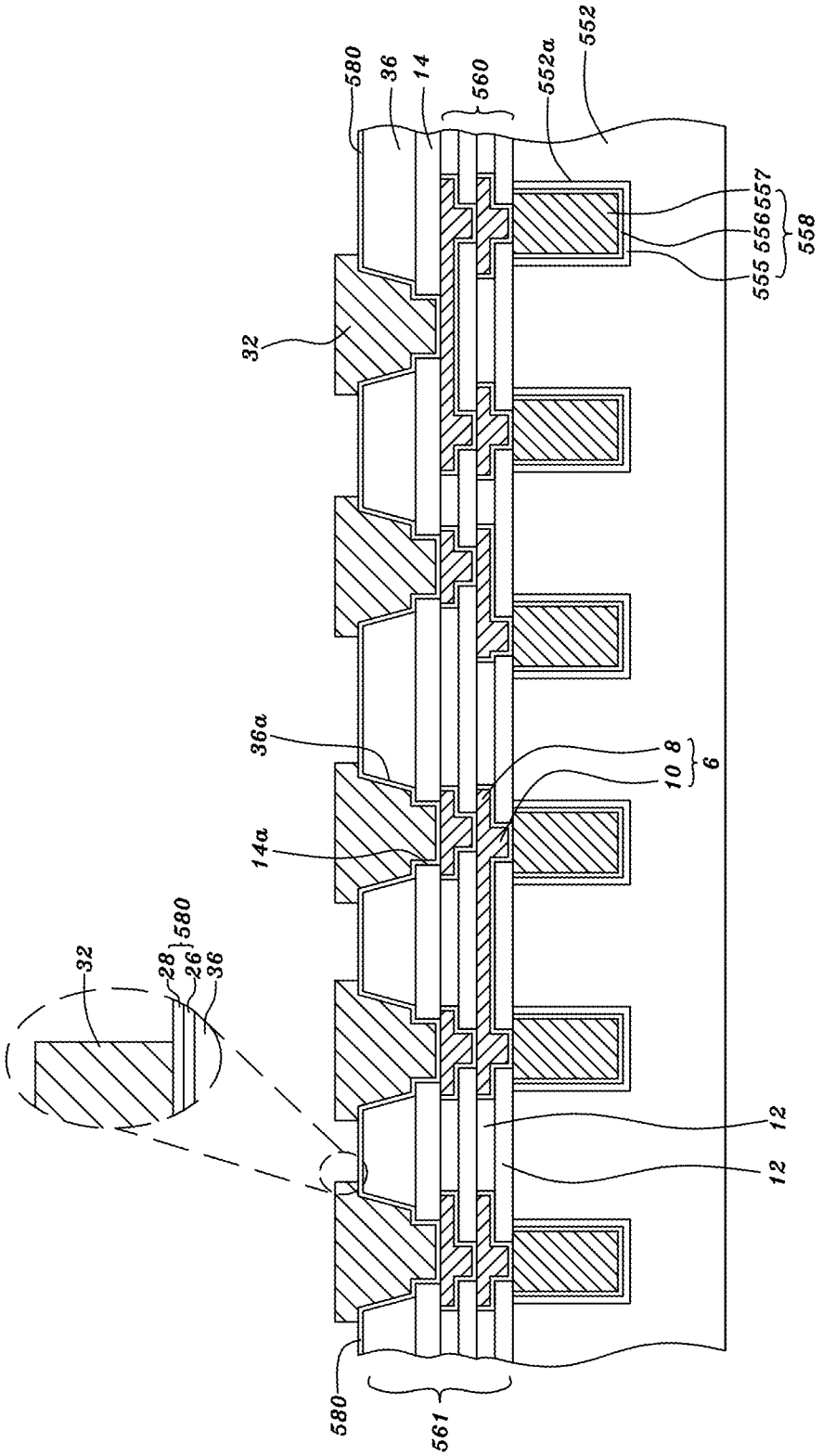

580
36
14
560
552a
552
555 556 557
558
32
36a
10 8
6
14a
580
28
26
36
32
12
12
580
561

Fig. 25B

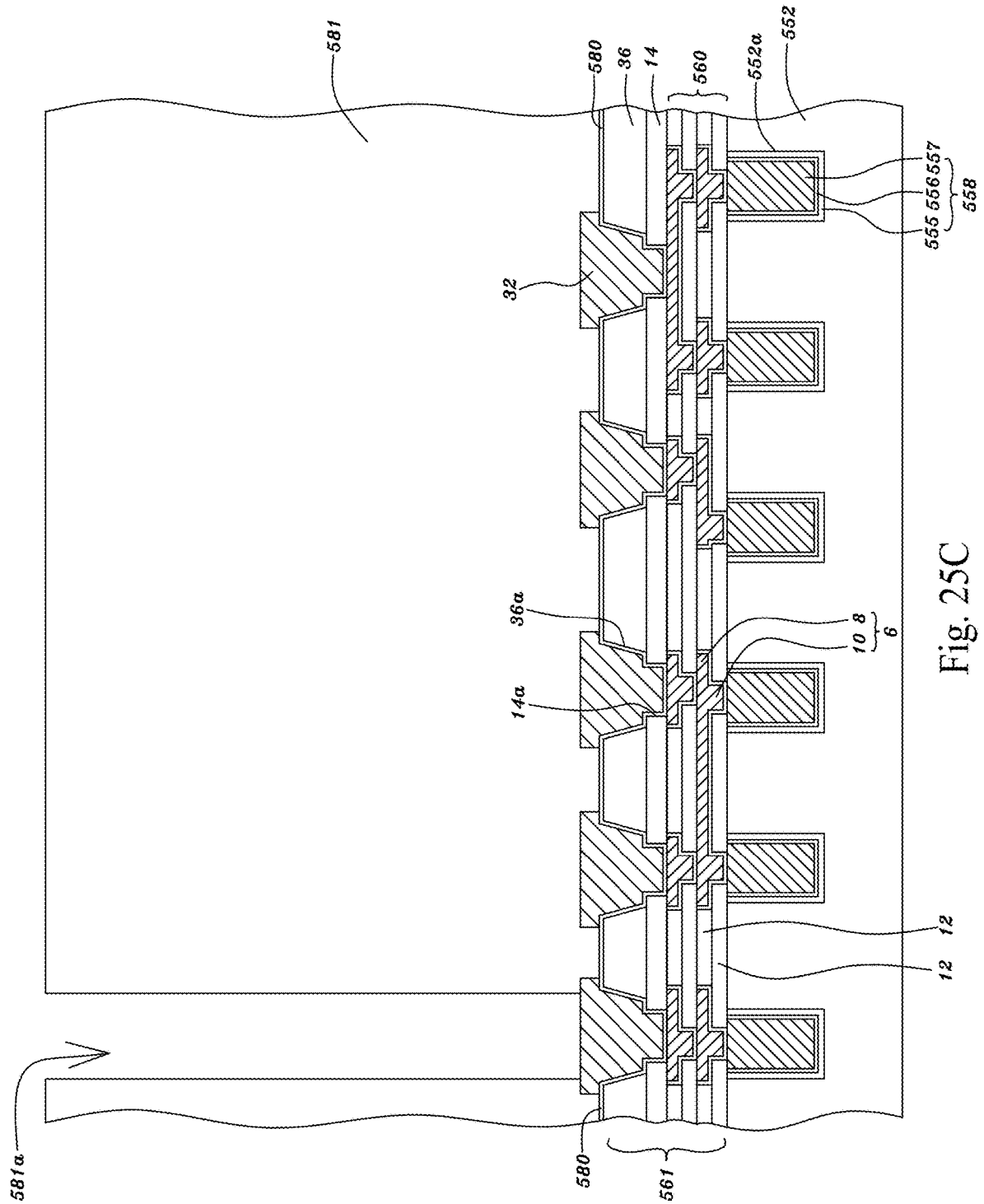

581
580
36
14
560
552a
552
555 556 557
558
32
36a
10 8
6
14a
12
12
581a
580
561

Fig. 25C

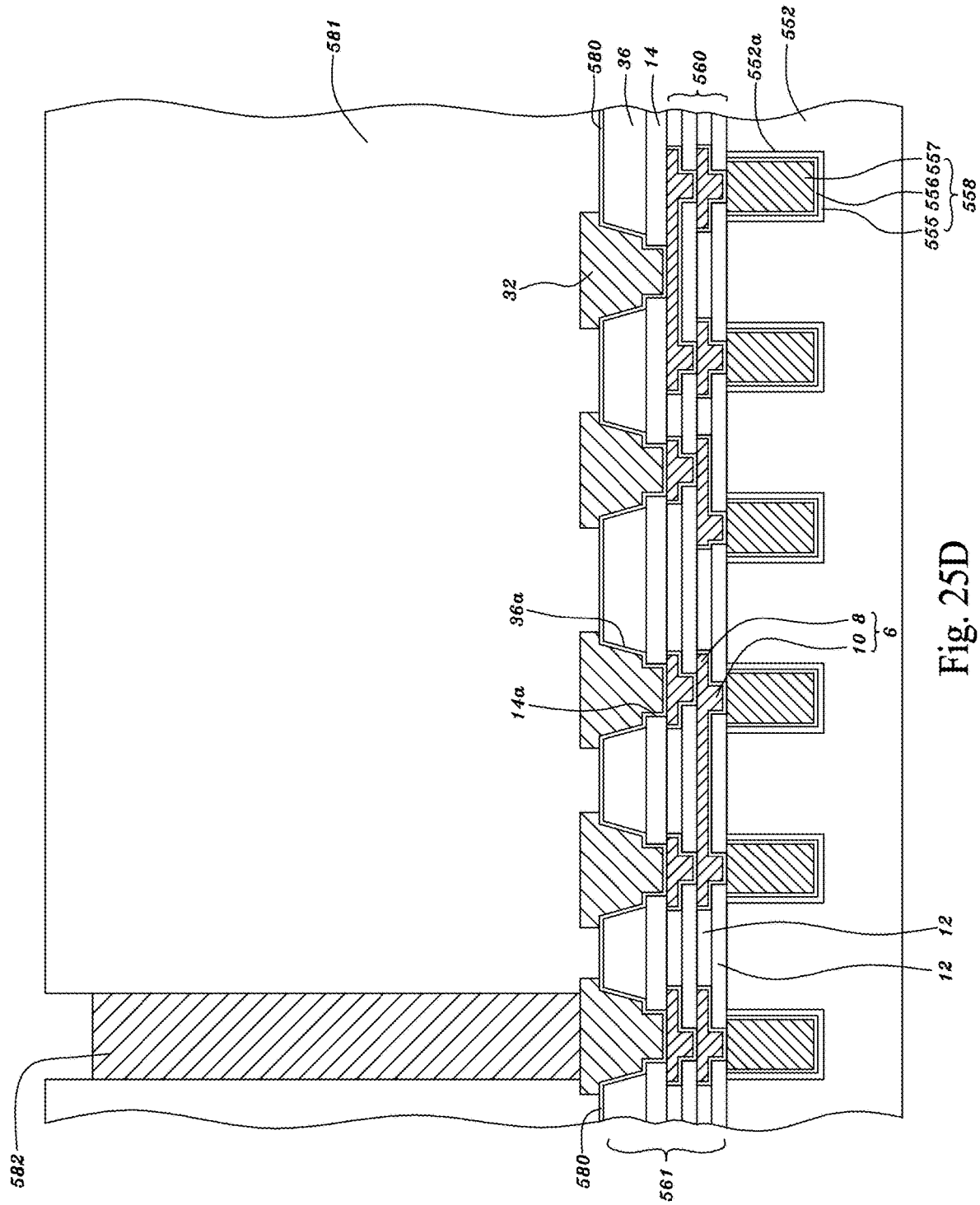

581
580
36
14
560
552a
552
555 556 557
558
32
96a
10 8
6
14a
12
12
582
580
561

Fig. 25D

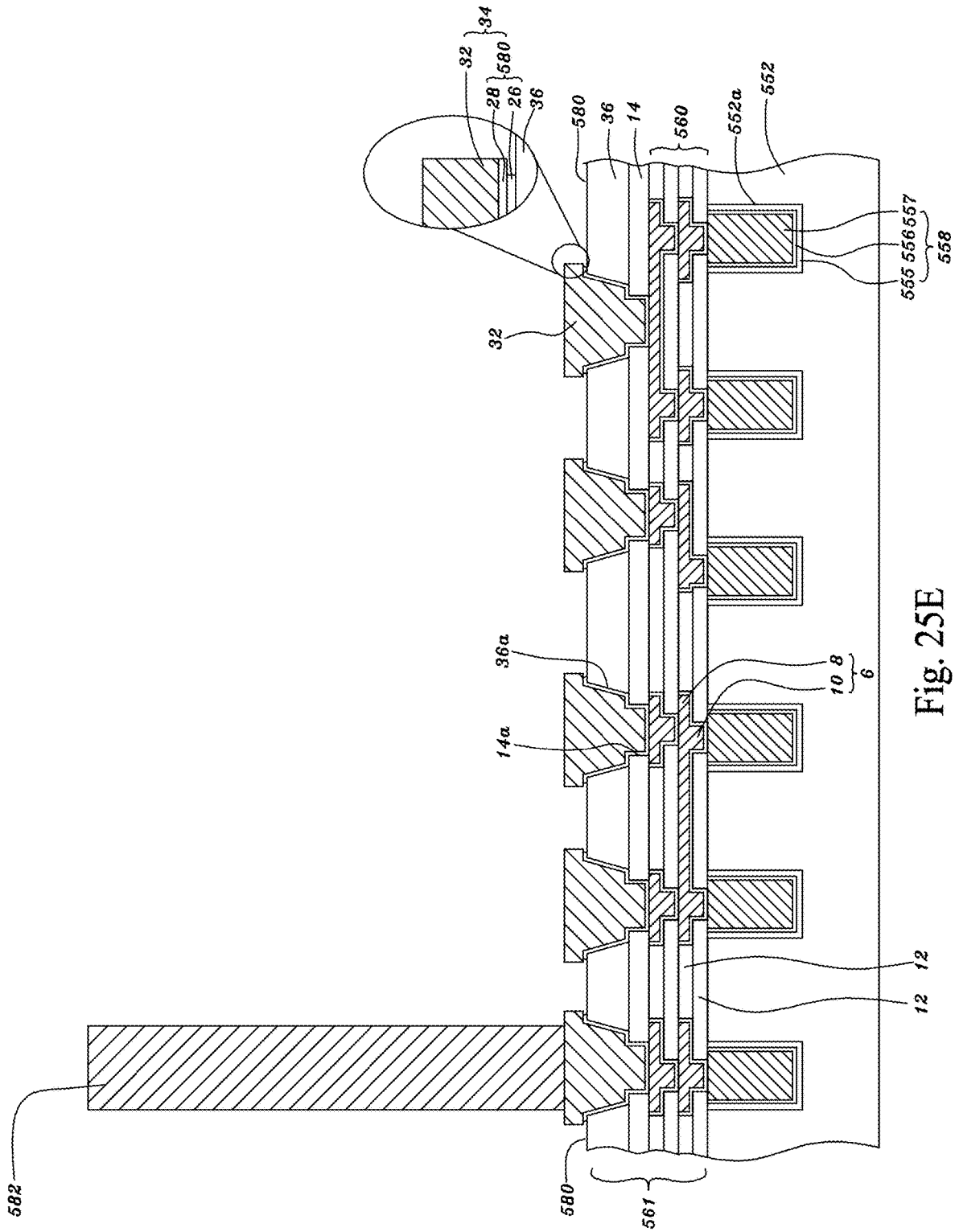

34
32
580
28
26
36
580
36
14
560
552a
552
557
556
555
558
32
36a
10 8
6
14a
12
12
582
580
561

Fig. 25E

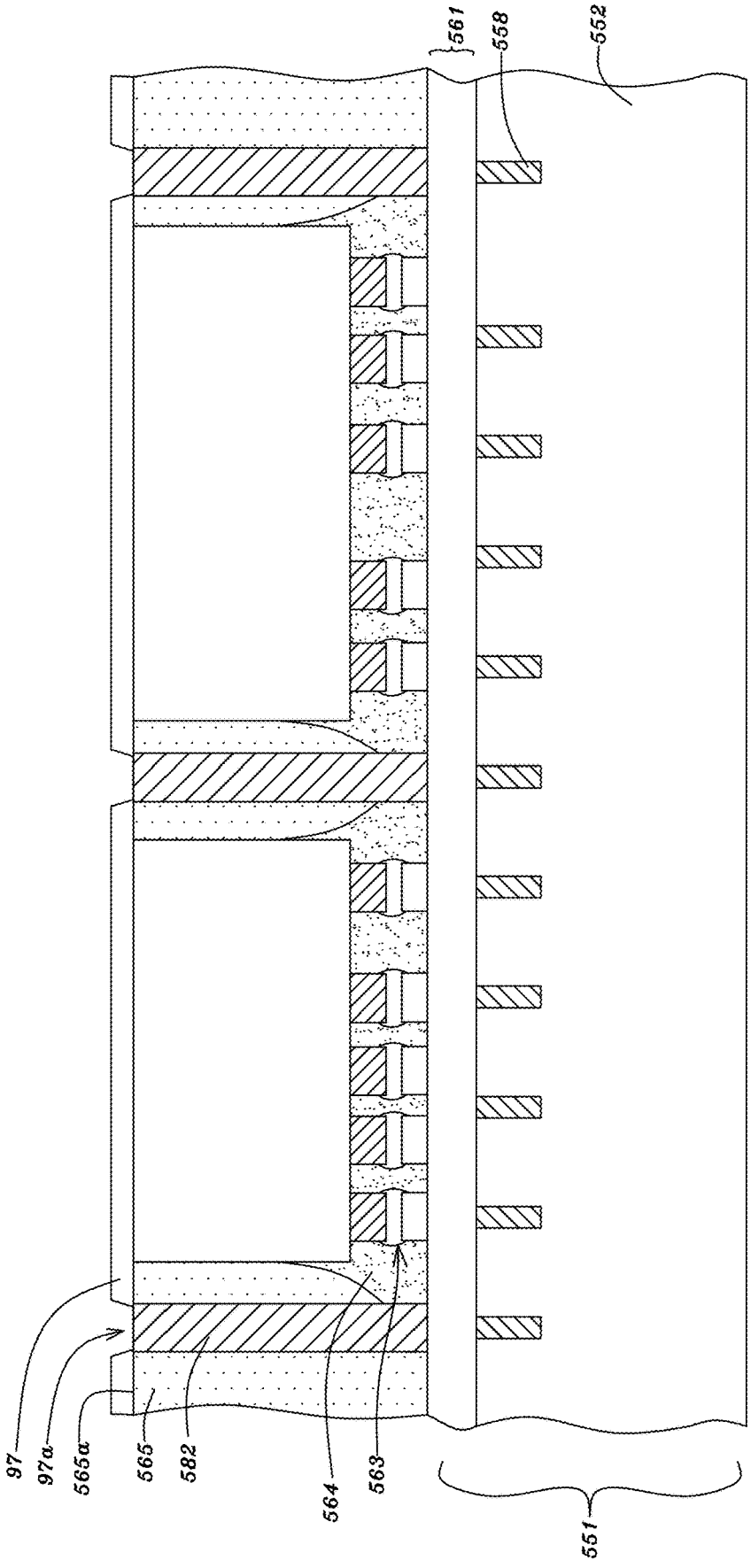


Fig. 26A

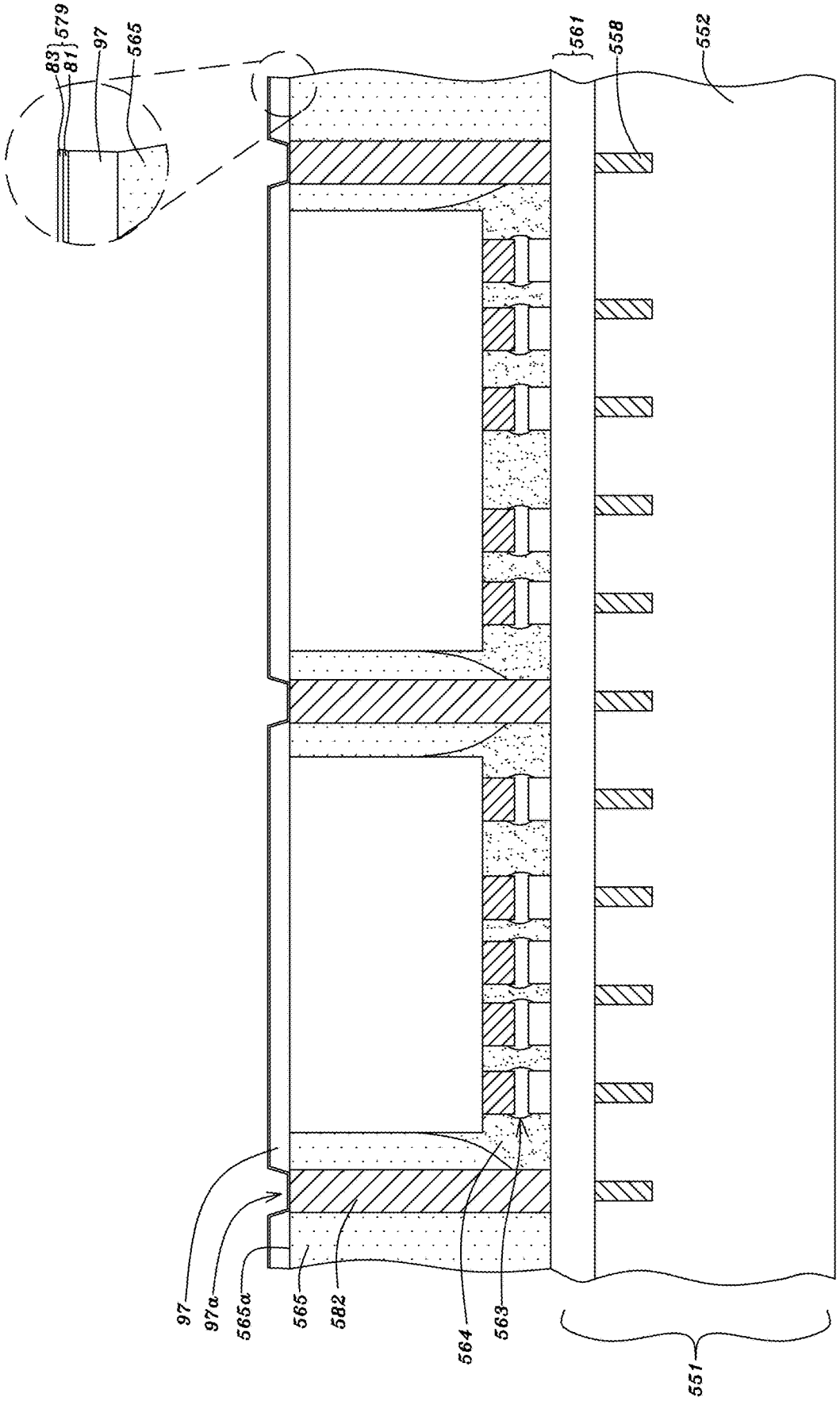


Fig. 26B

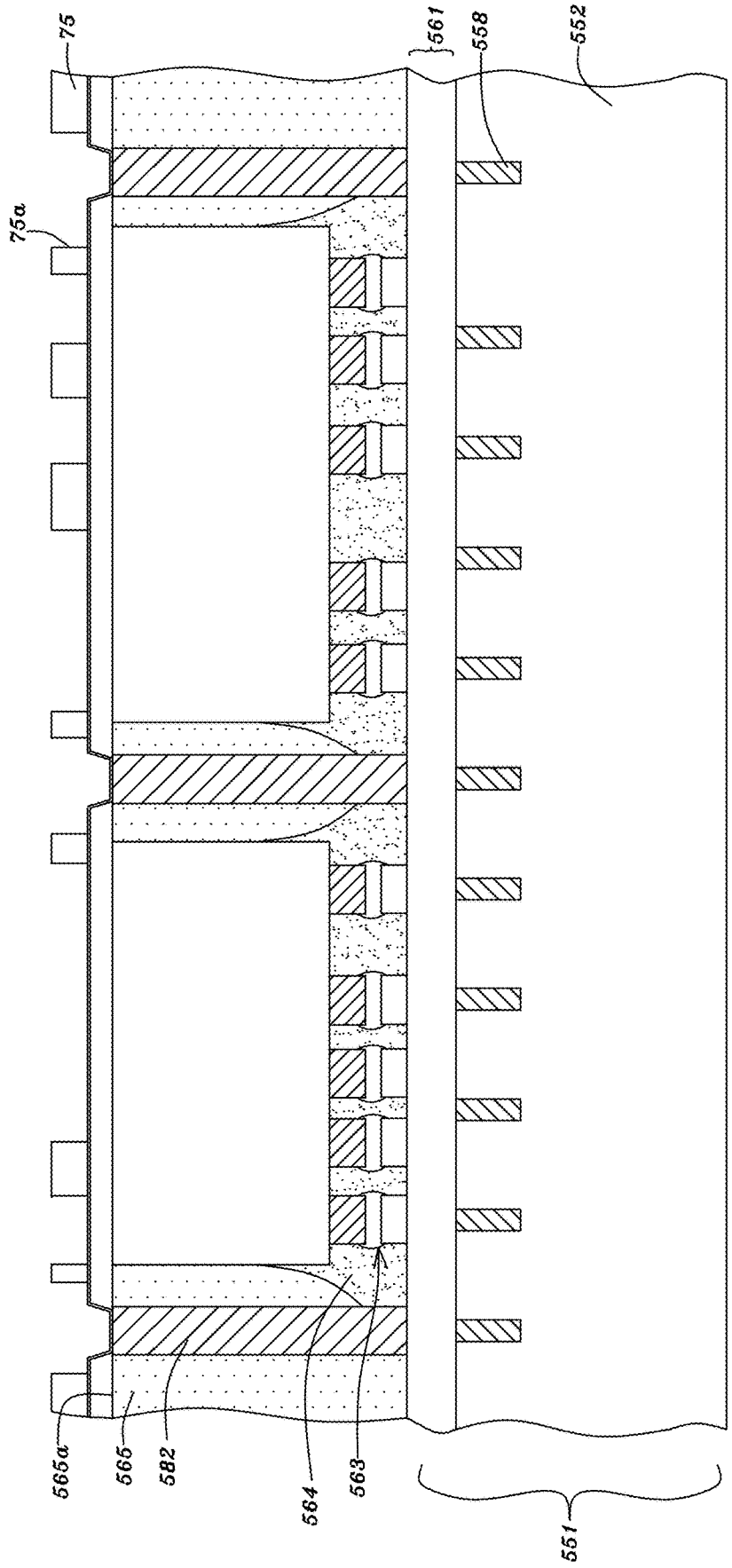


Fig. 26C

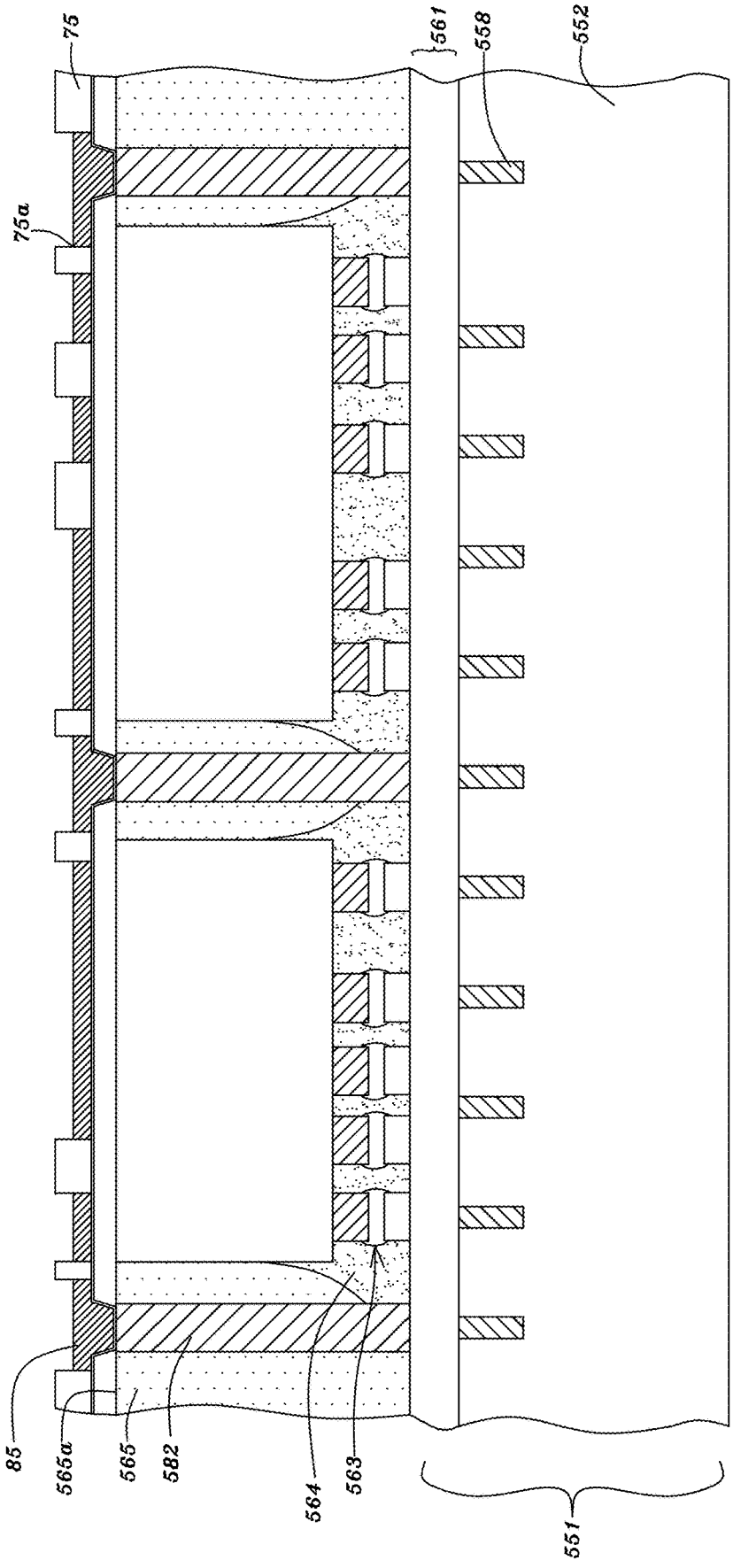


Fig. 26D

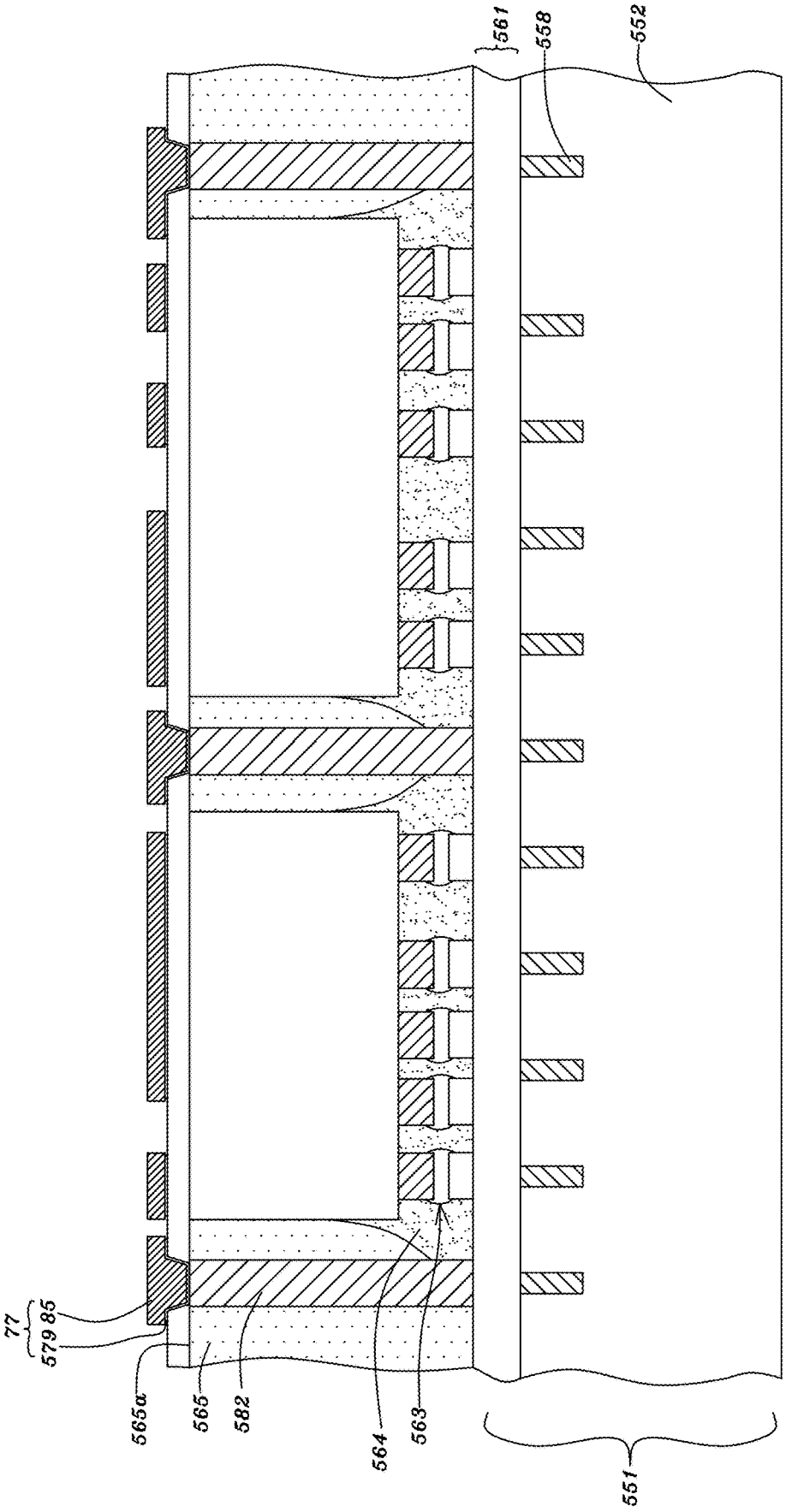


Fig. 26E

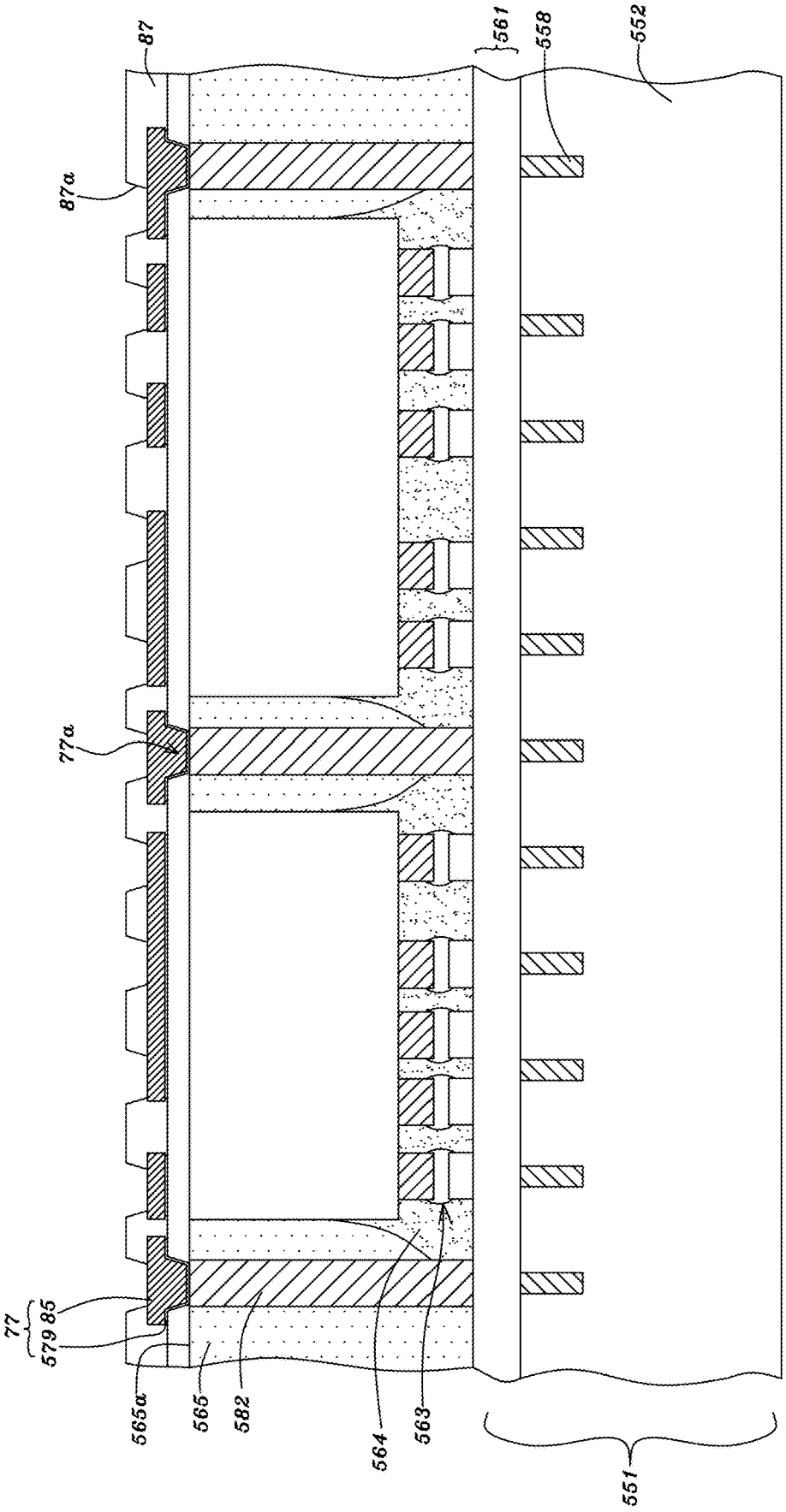


Fig. 26F

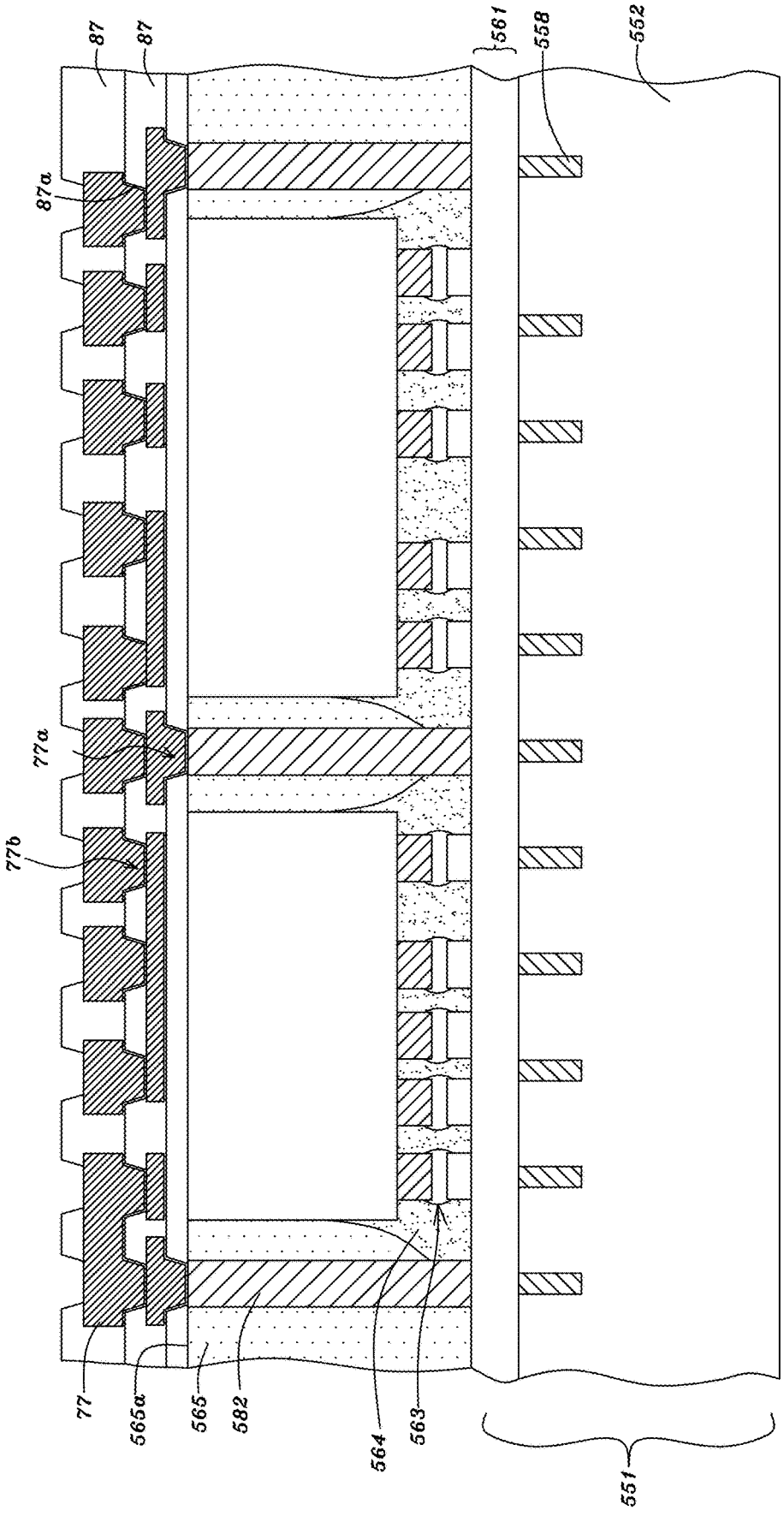


Fig. 26G

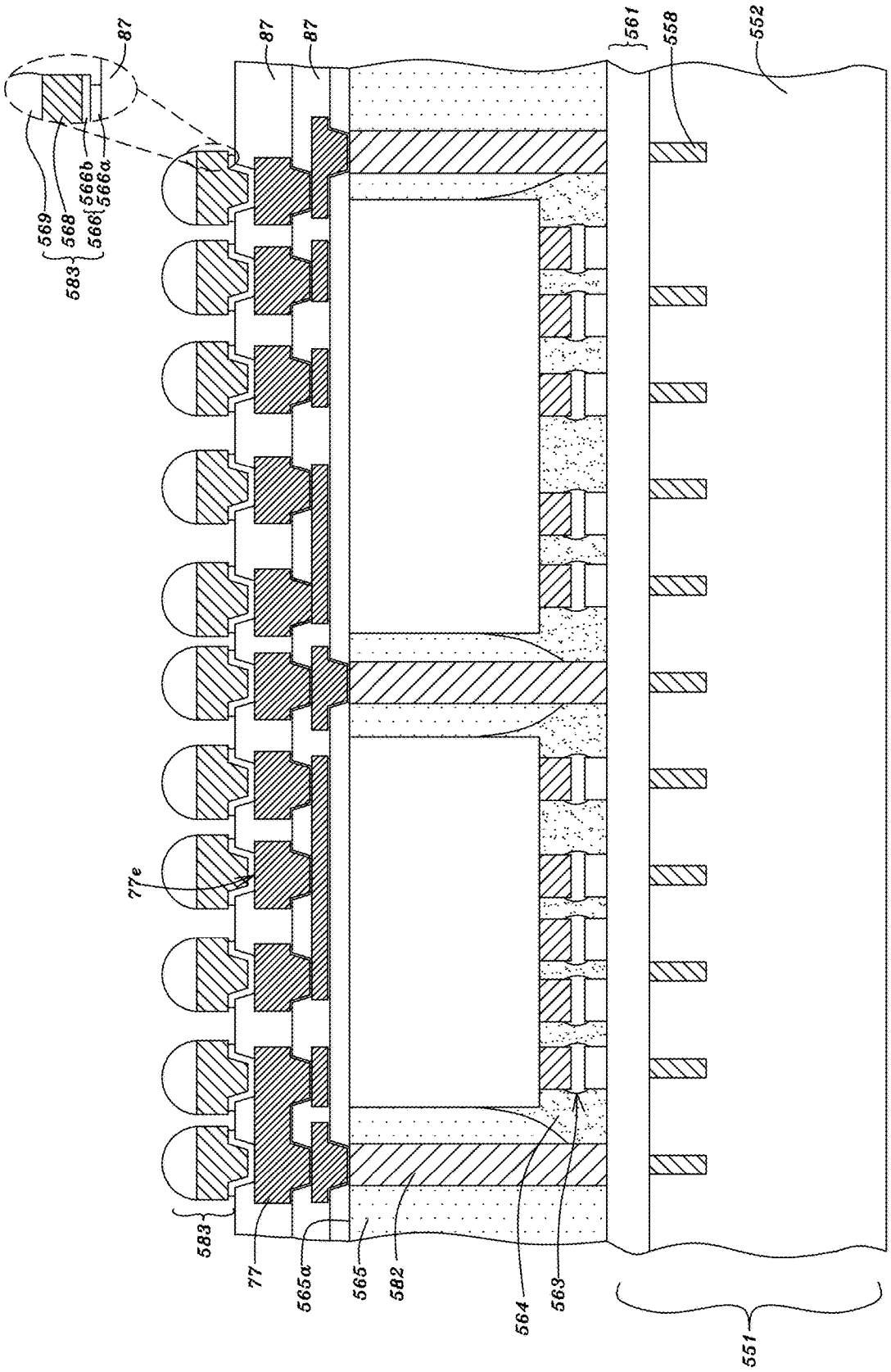

87
87
87
561
558
552
569
568
566
566b
566a
583
77e
583
77
565a
565
582
564
563
551

Fig. 26H

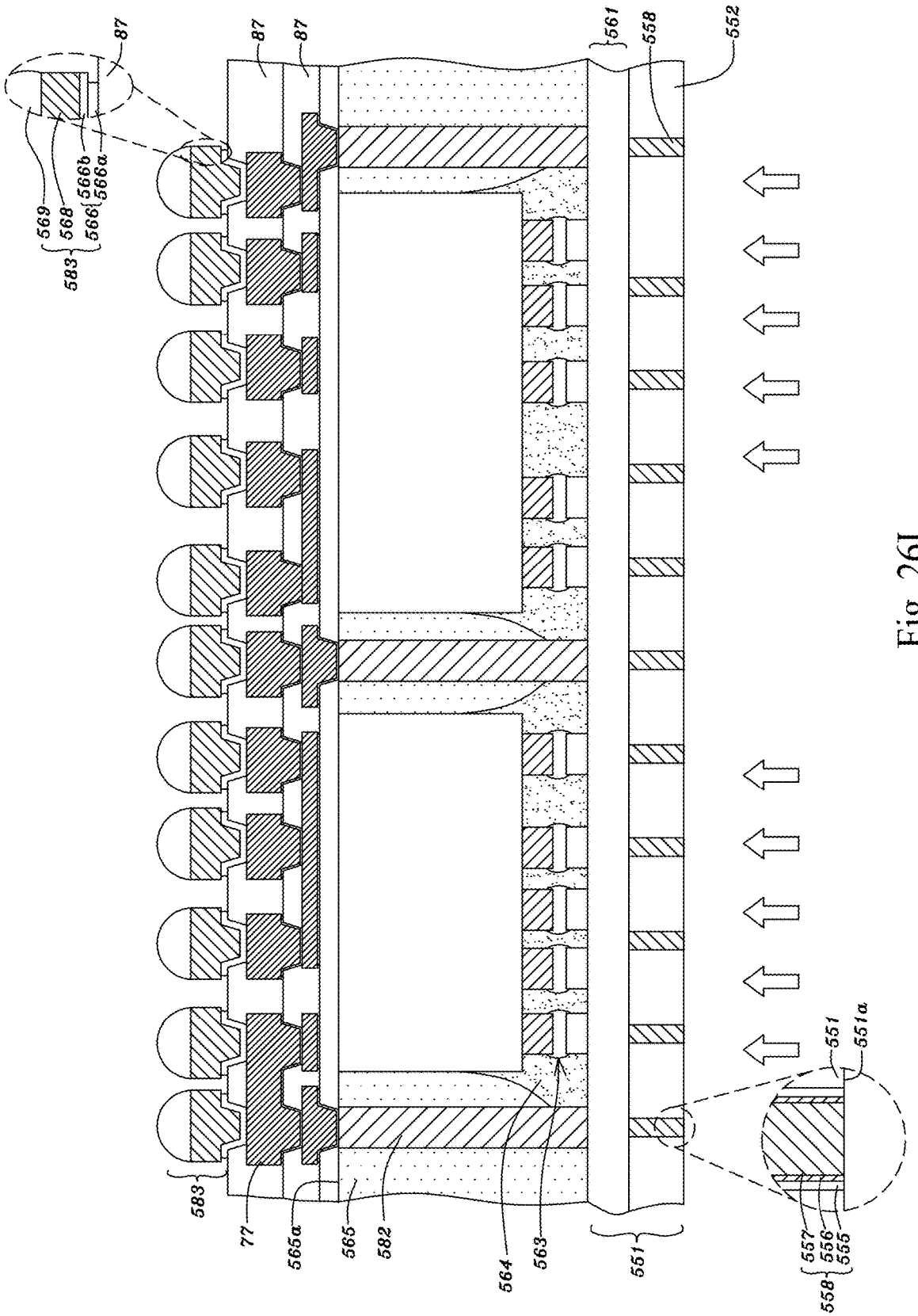

87
87
87
561
558
552
569
568
566
566b
566a
583
583
77
565a
565
582
564
563
551
557
556
555
558
551
551a

Fig. 26I

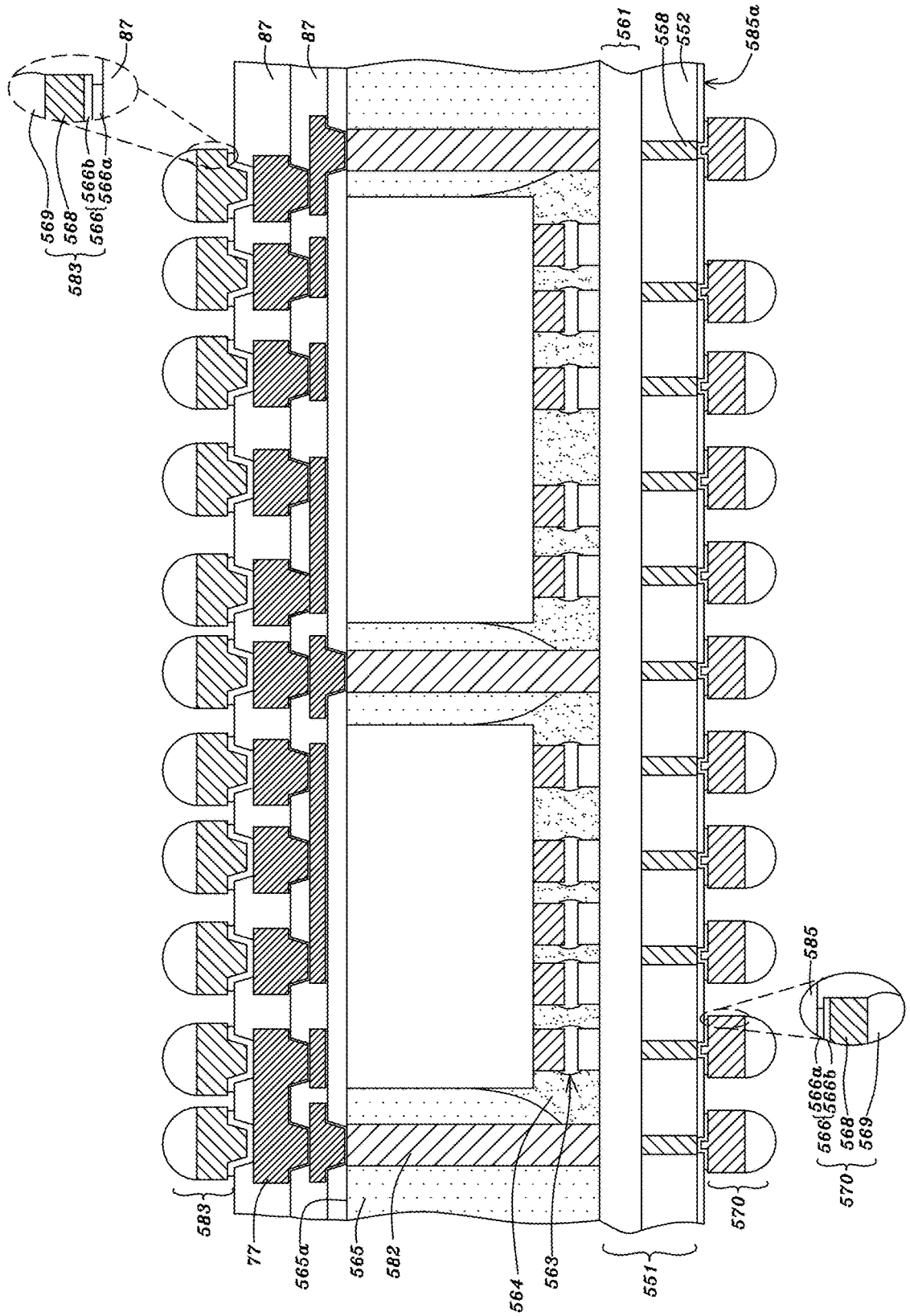

87
87
87
561
558
552
585a
569
568
566b
566a
566
583
585
566a
566b
566
568
569
570
583
77
565a
565
582
564
563
551
570

Fig. 26J

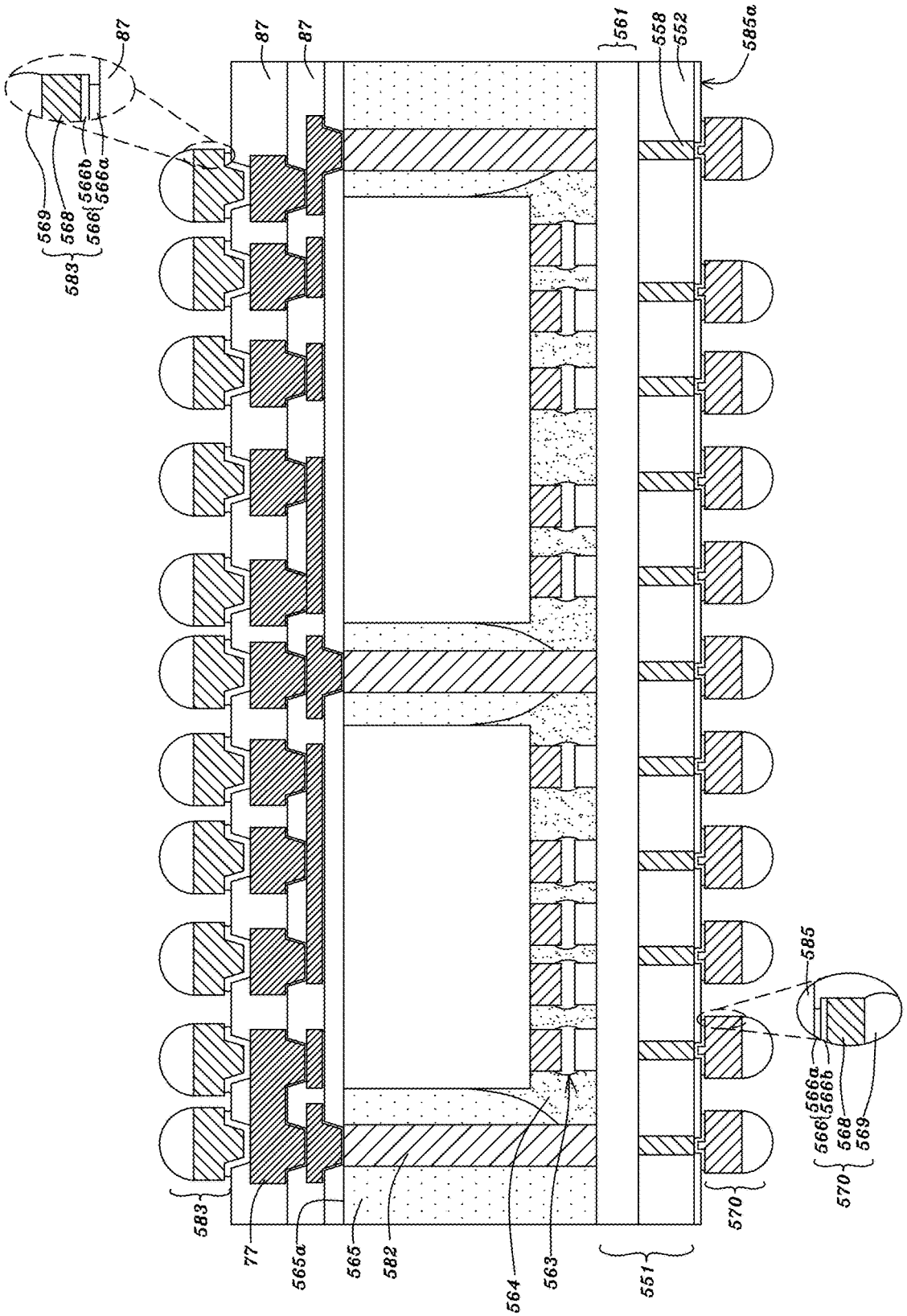

87
87
87
561
558
552
585a
569
568
566b
566a
566
583
585
566a
566b
566
568
569
570
583
77
565a
565
582
564
563
551
570

Fig. 26K

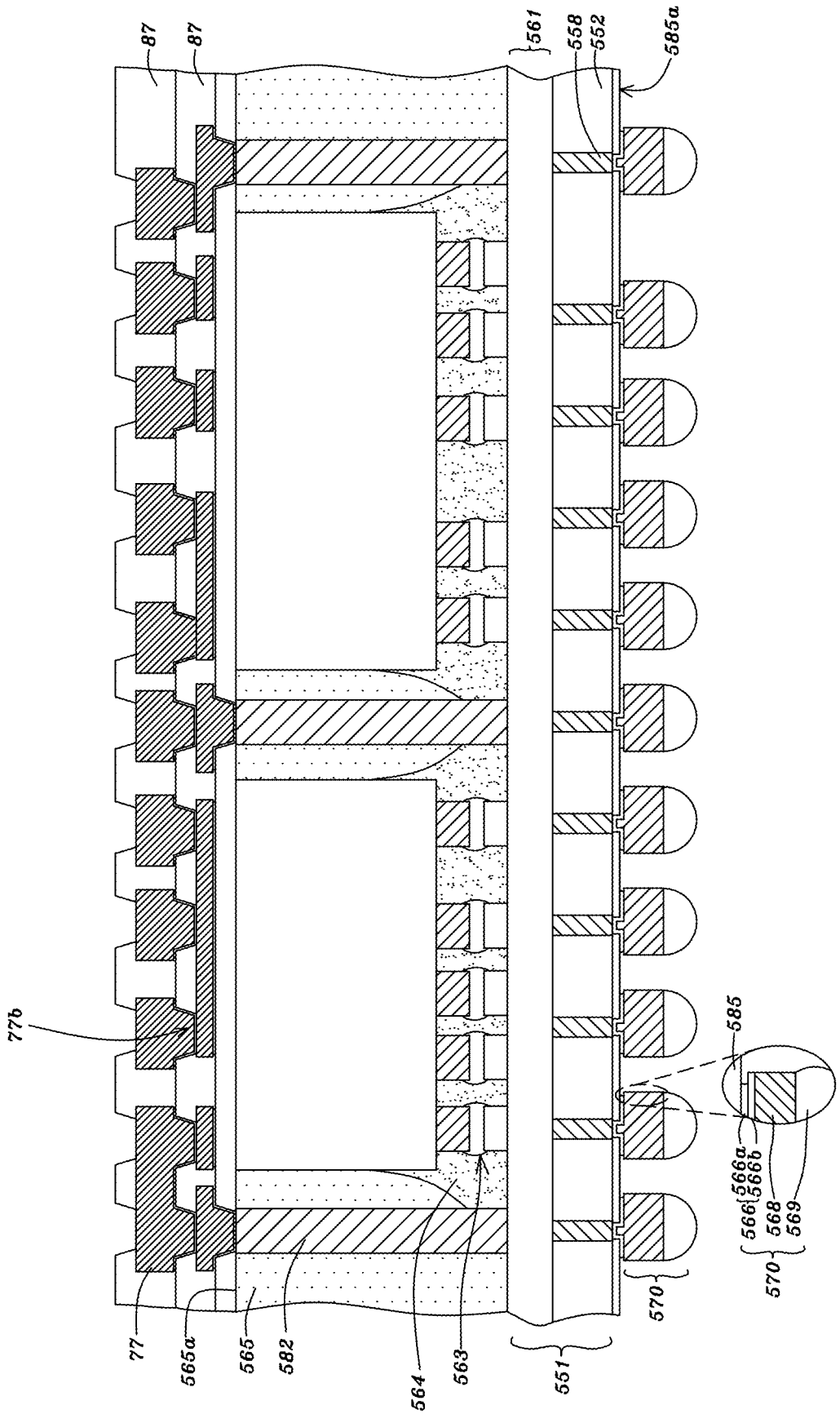

87
87
561
558
552
585a
776
585
566a
566b
566
568
569
570
570
77
565a
565
582
564
563
551

Fig. 26L

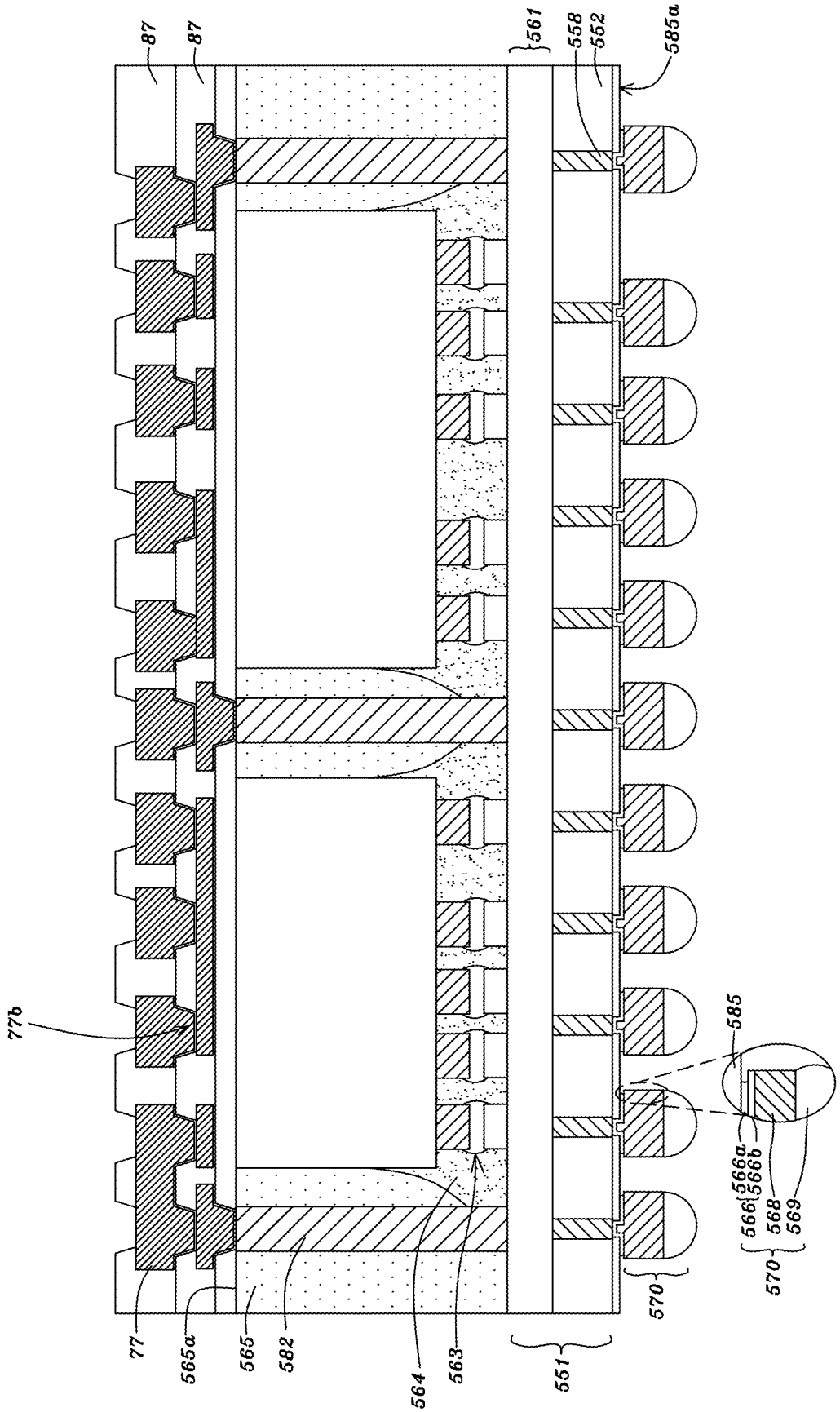

87
87
561
558
552
585a
776
585
566a
566b
566
568
569
570
570
77
565a
565
582
564
563
551

Fig. 26M

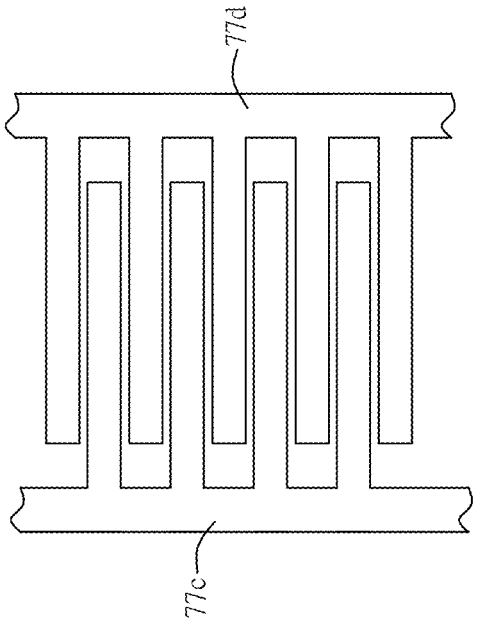


Fig. 26N

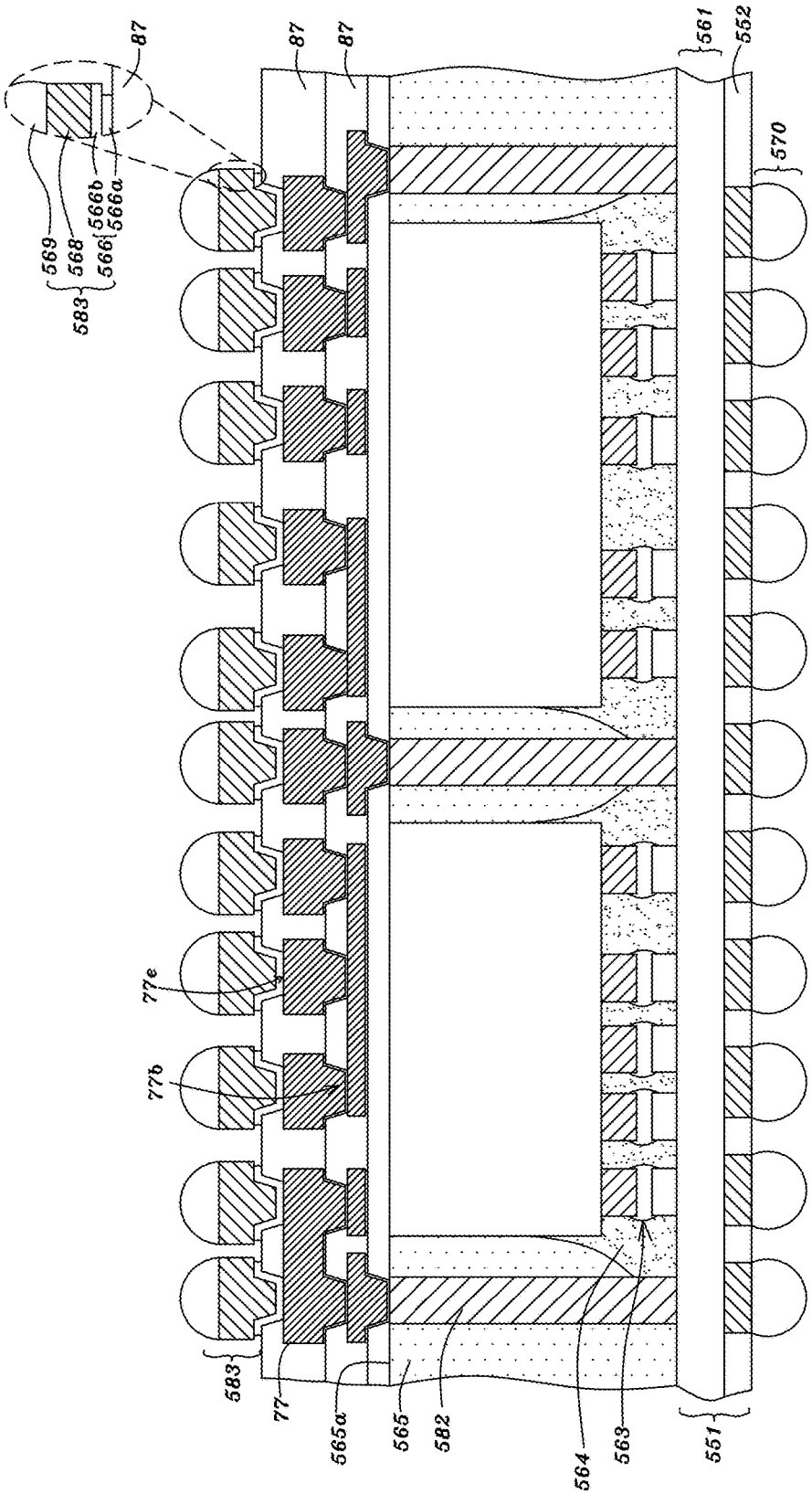

87
87
87
561
552
570
569
568
566
566b
566a
583
77e
77b
583
77
565a
565
582
564
563
551

Fig. 27A

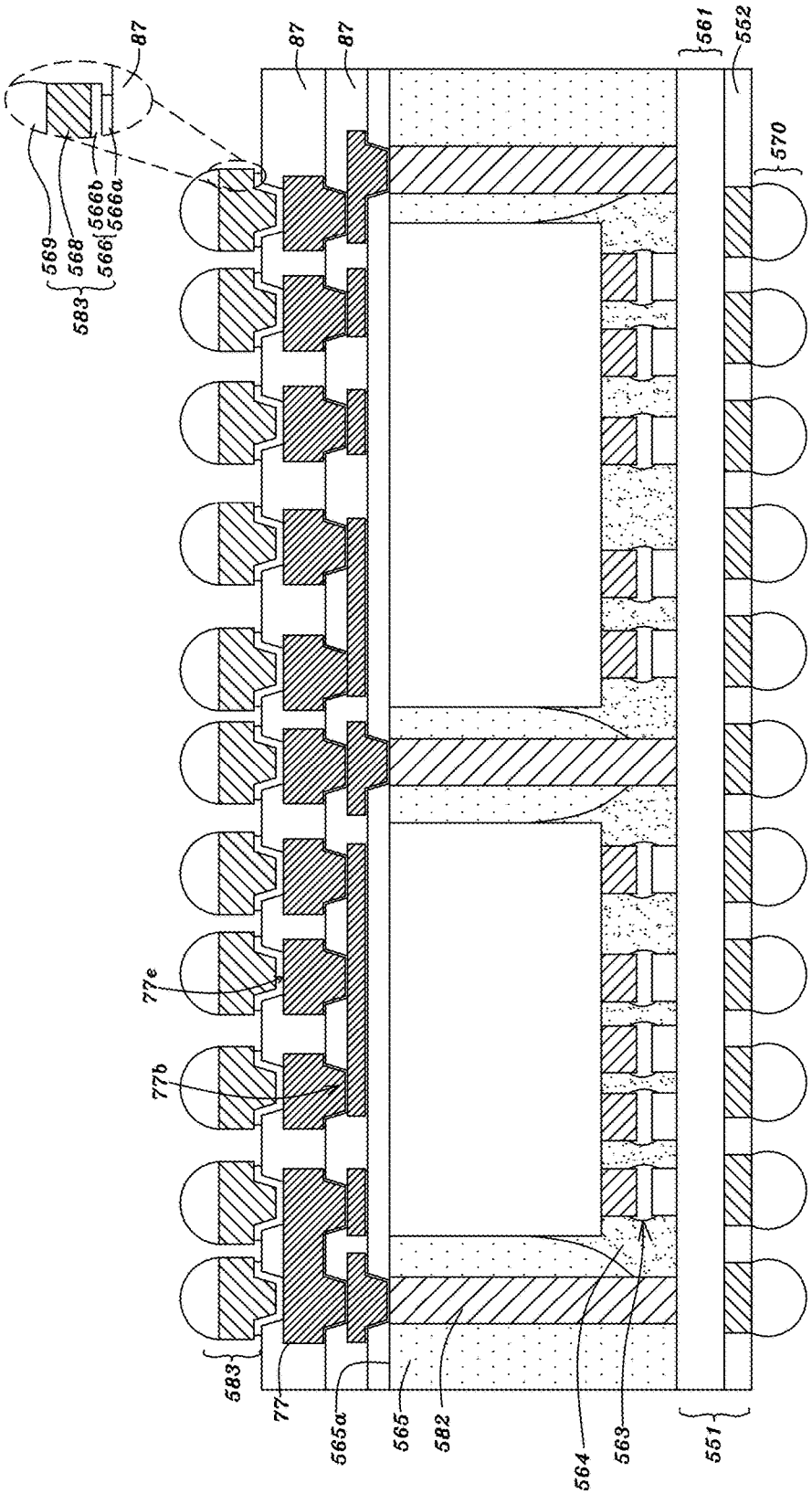

87
87
87
561
552
570
569
568
566
566b
566a
583
77e
77b
583
77
565a
565
582
564
563
551

Fig. 27B

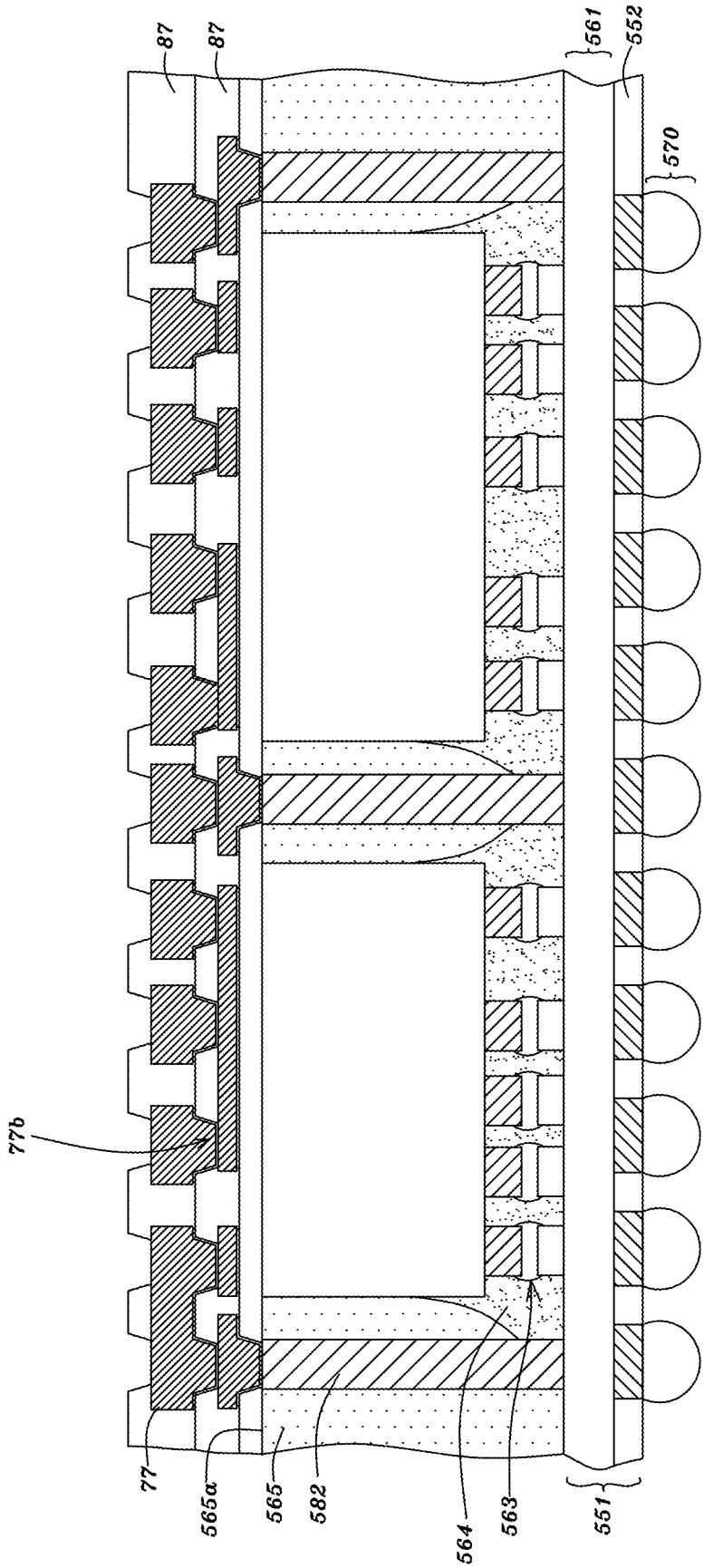


Fig. 27C

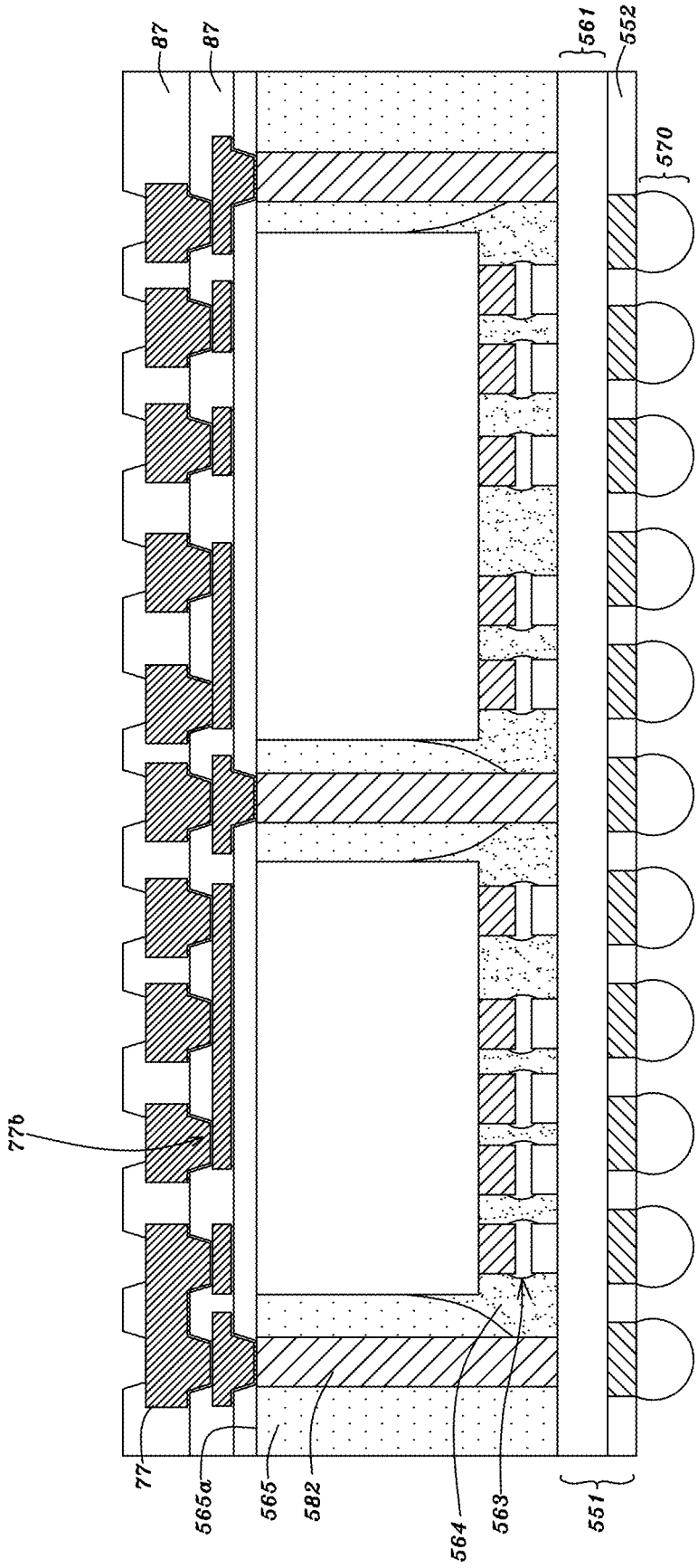


Fig. 27D

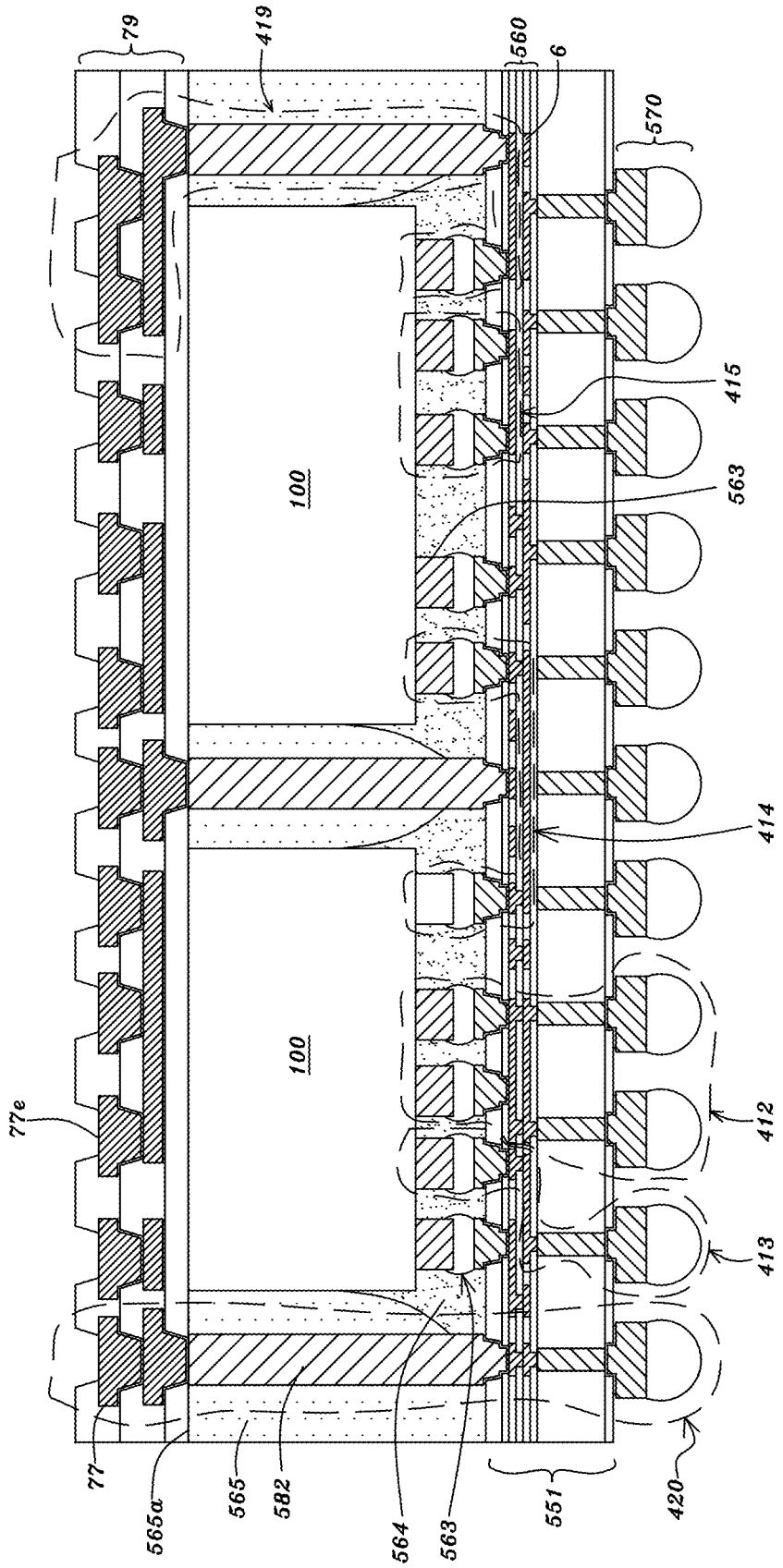

79
419
560
6
570
415
563
100
414
100
77e
412
413
77
565a
565
582
564
563
551
420

Fig. 28A

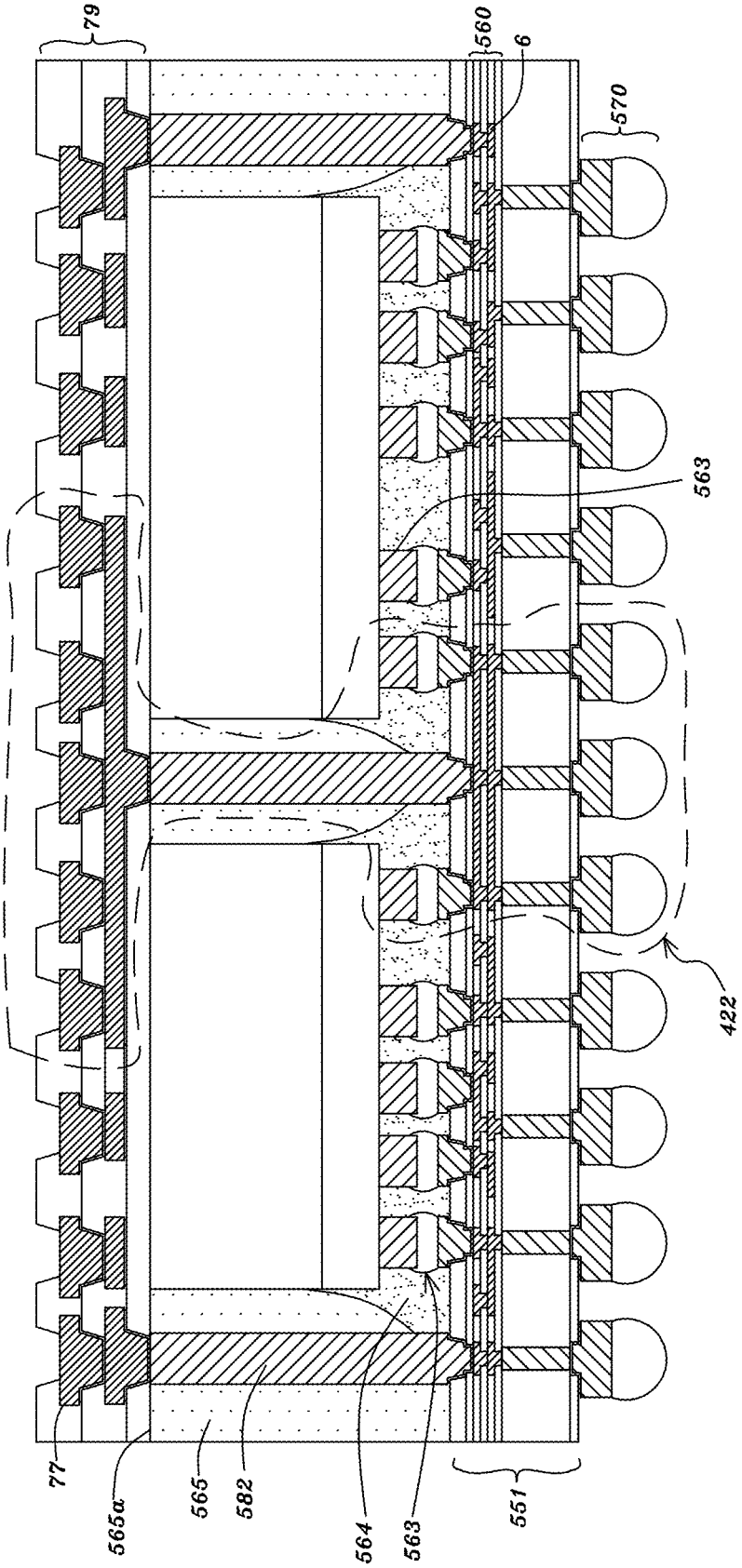


Fig. 28B

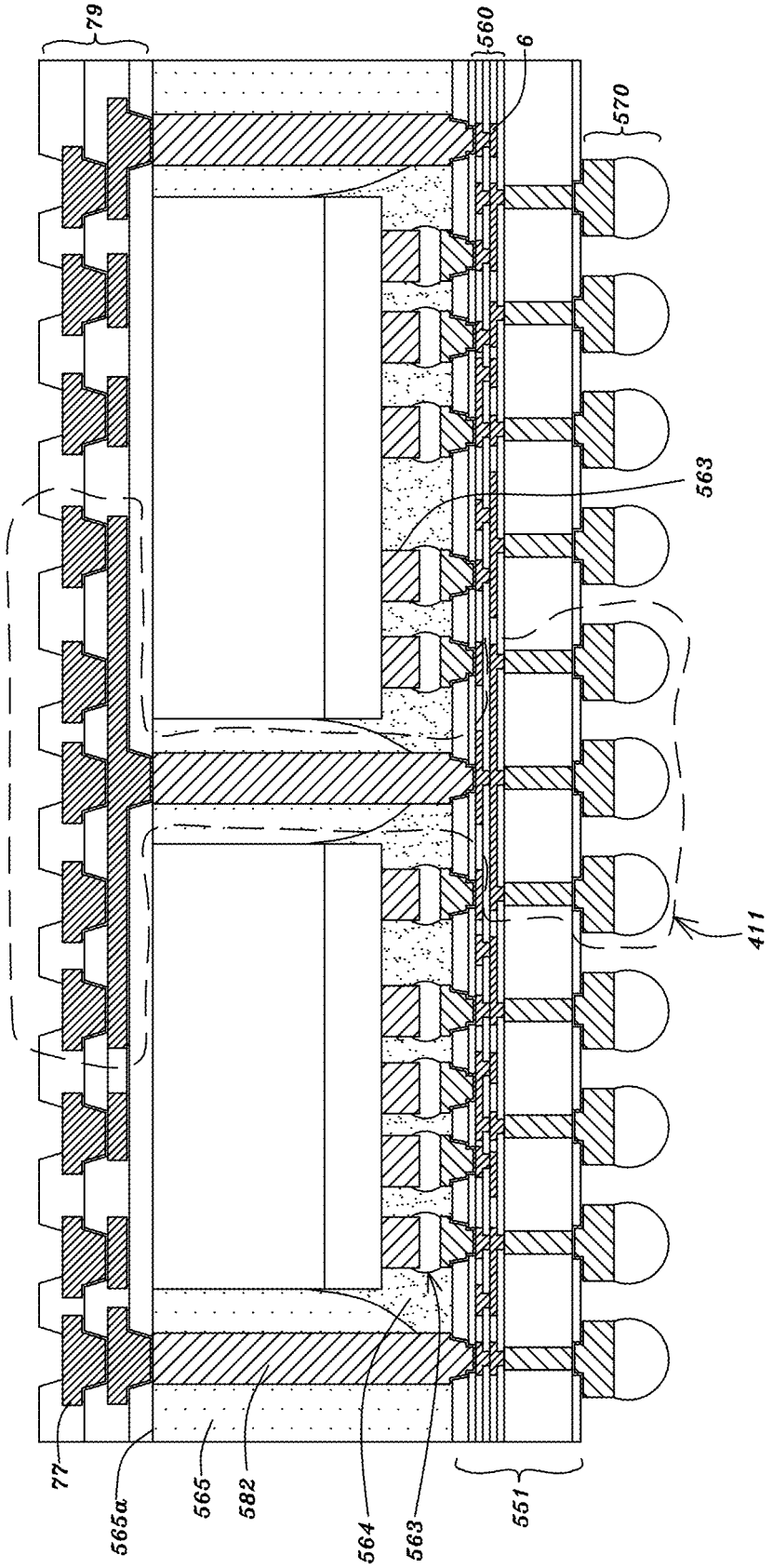


Fig. 28C

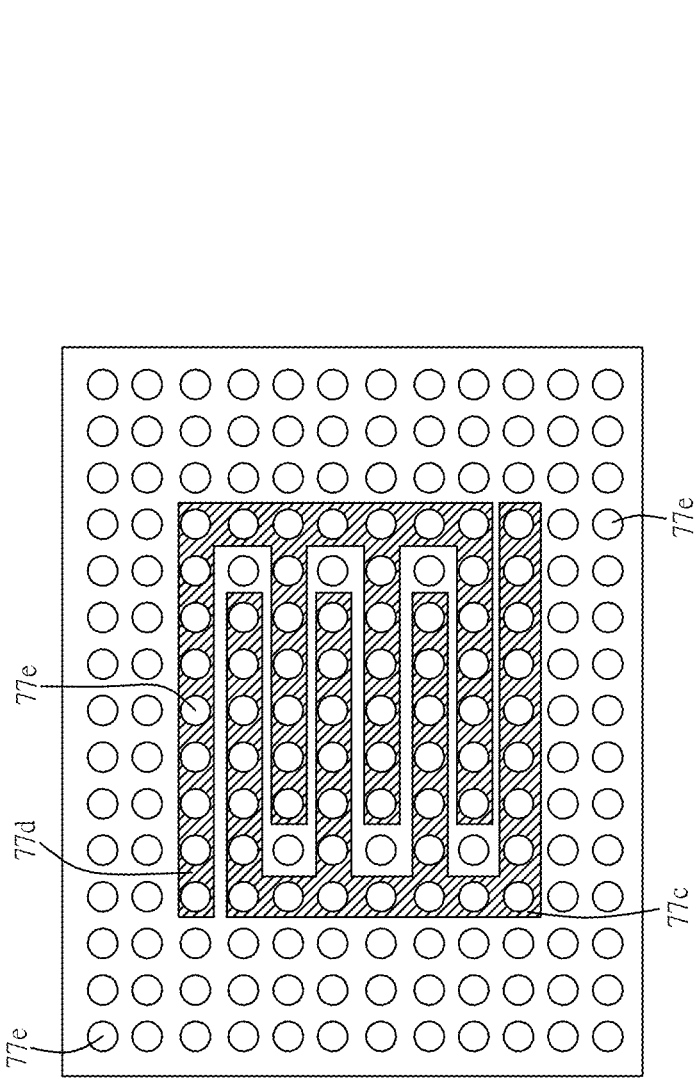


Fig. 28D

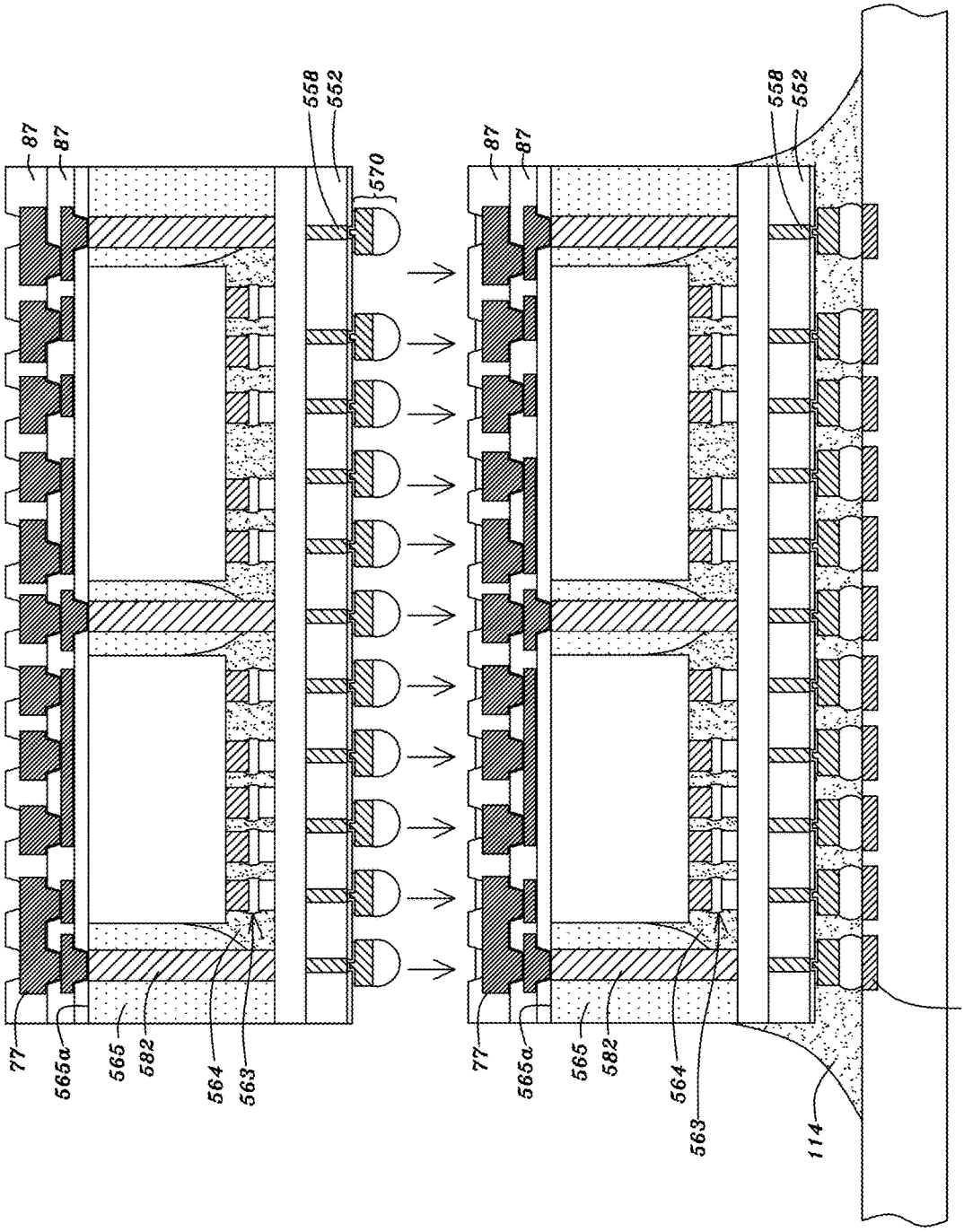


Fig. 29A

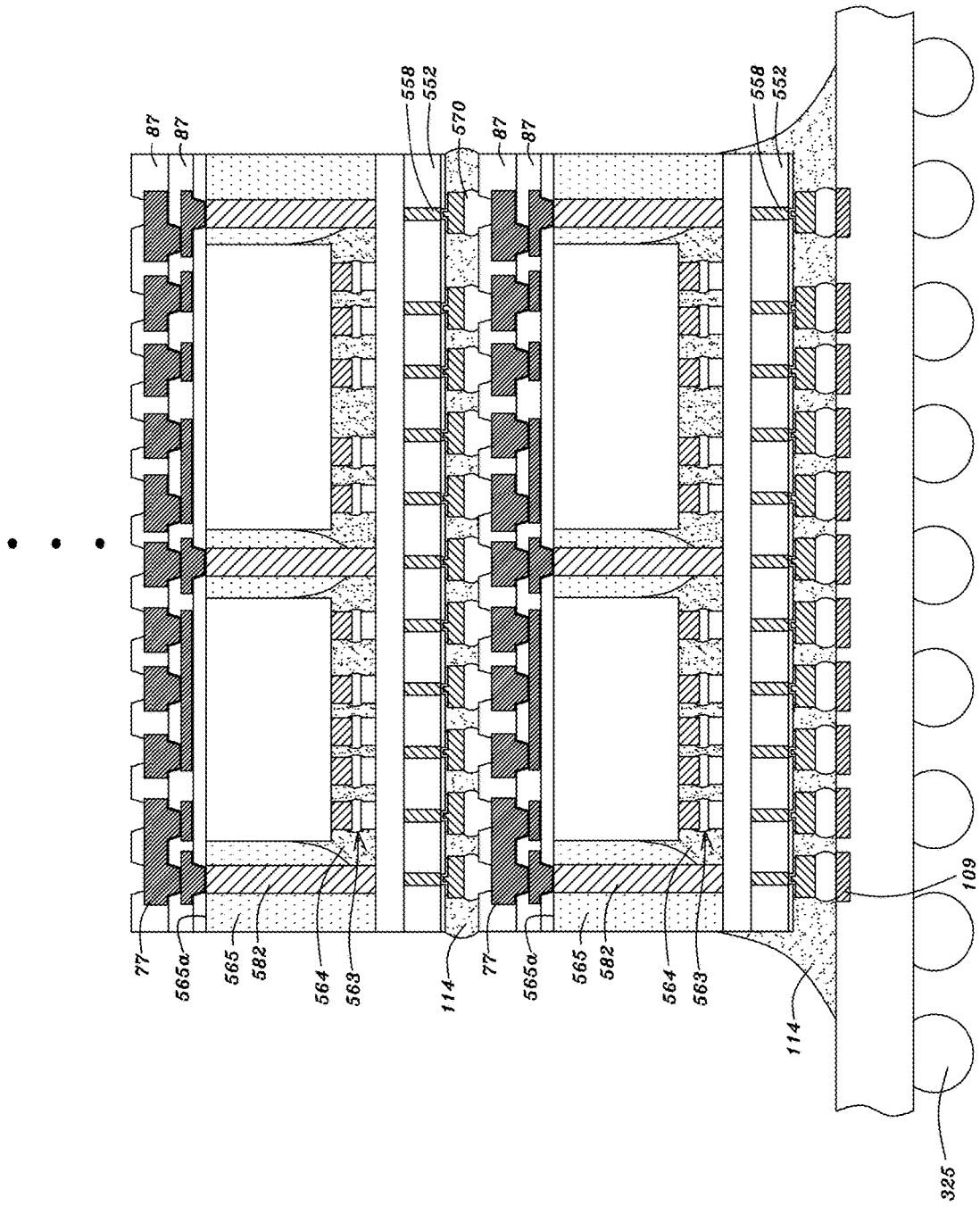

87
87
558
552
570
87
87
558
552
77
565a
565
582
564
563
114
77
565a
565
582
564
563
114
109
325

Fig. 29B

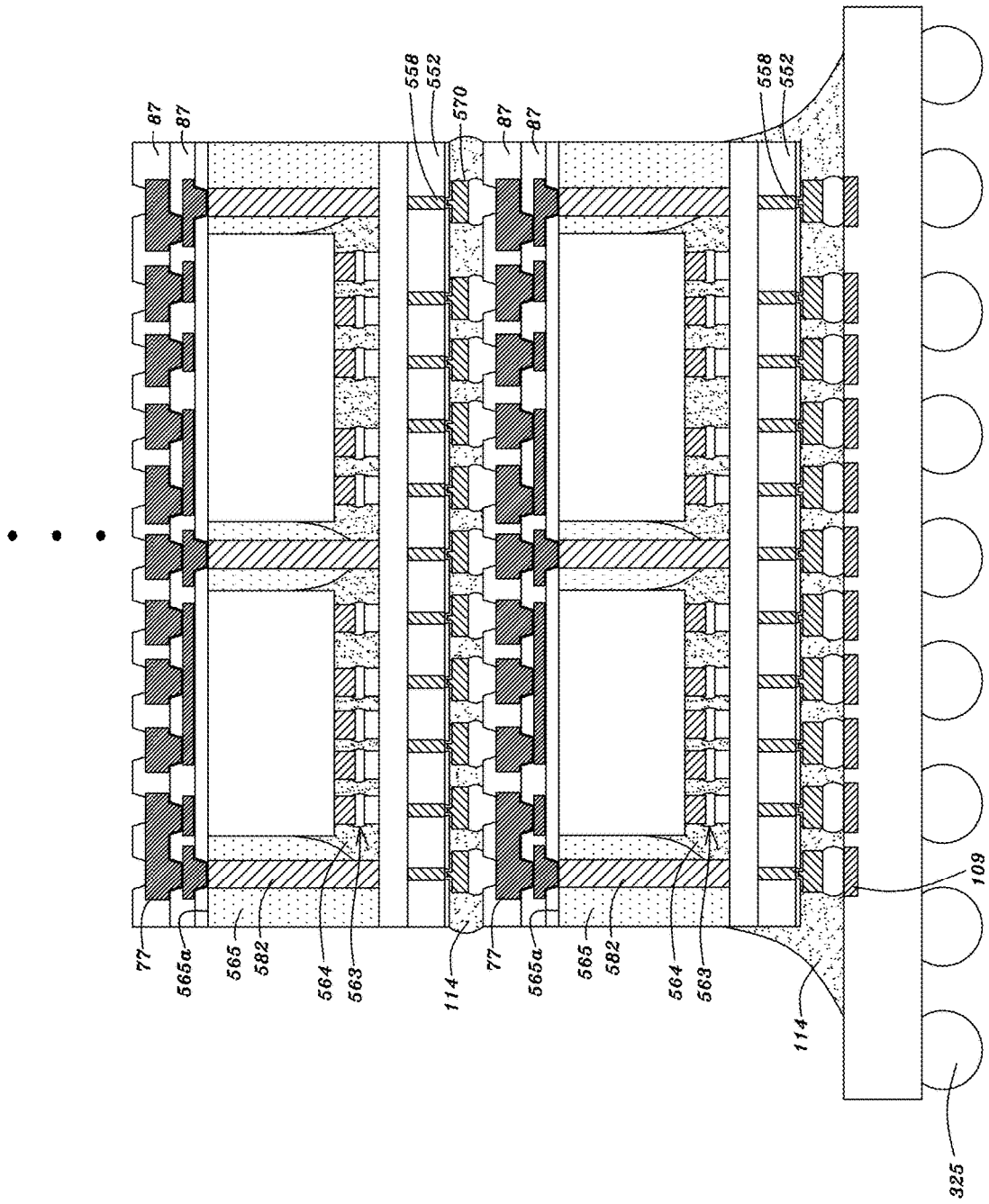

87
87
558
552
570
87
87
558
552
77
565a
565
582
564
563
114
77
565a
565
582
564
563
114
109
325

Fig. 29C

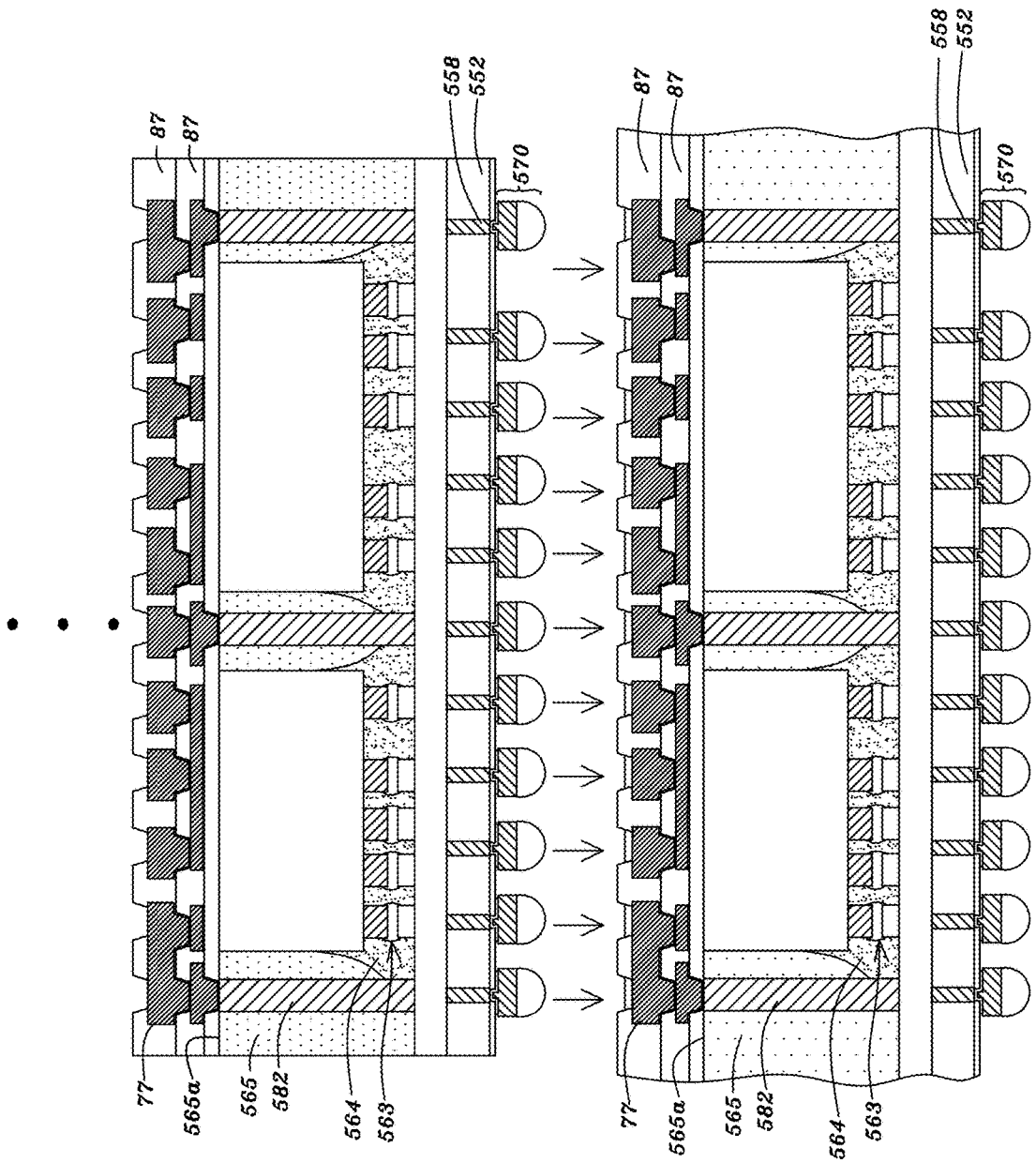


Fig. 29D

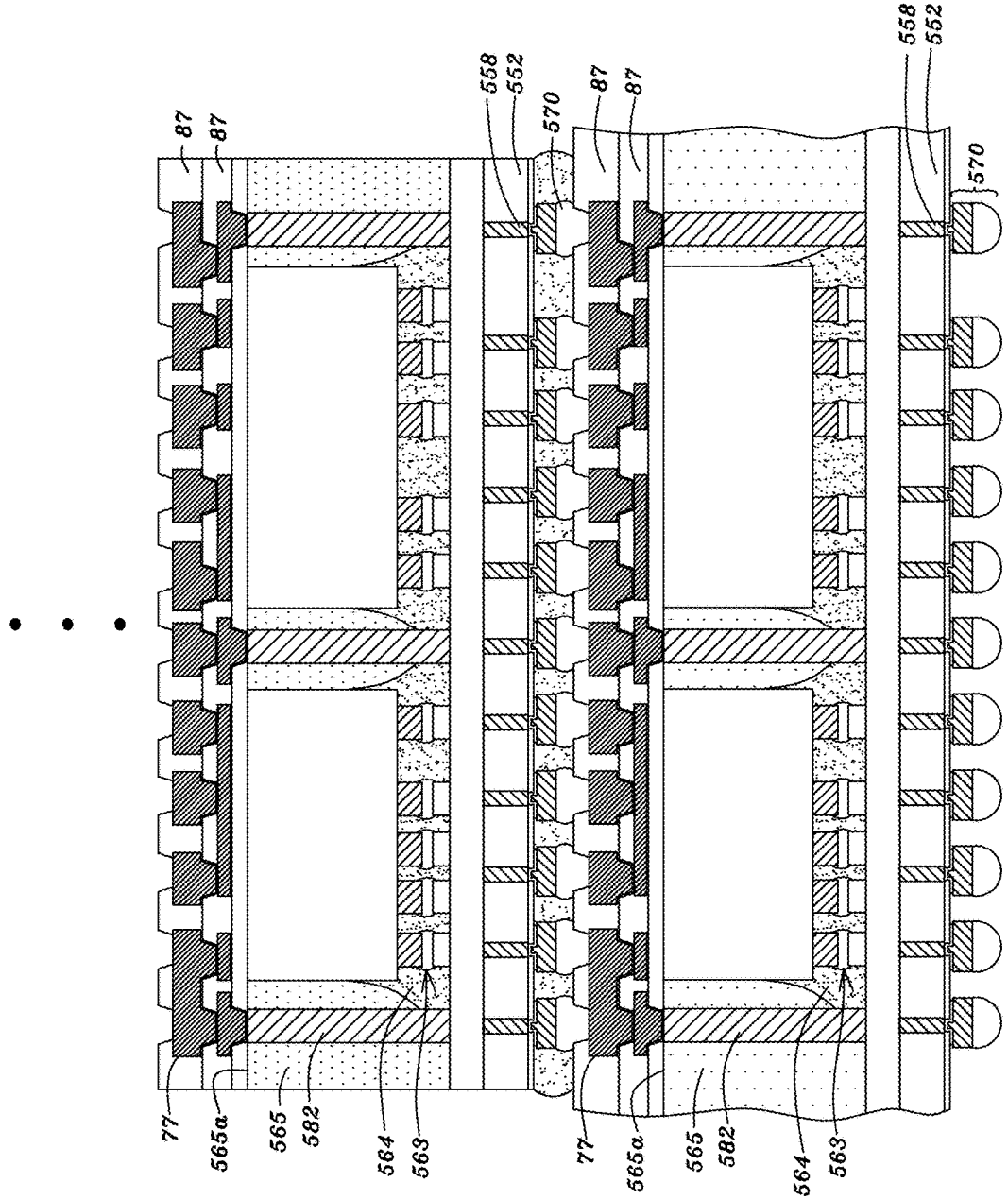

87
87
558
552
570
87
87
558
552
570
77
565a
565
582
564
563
77
565a
565
582
564
563

Fig. 29E

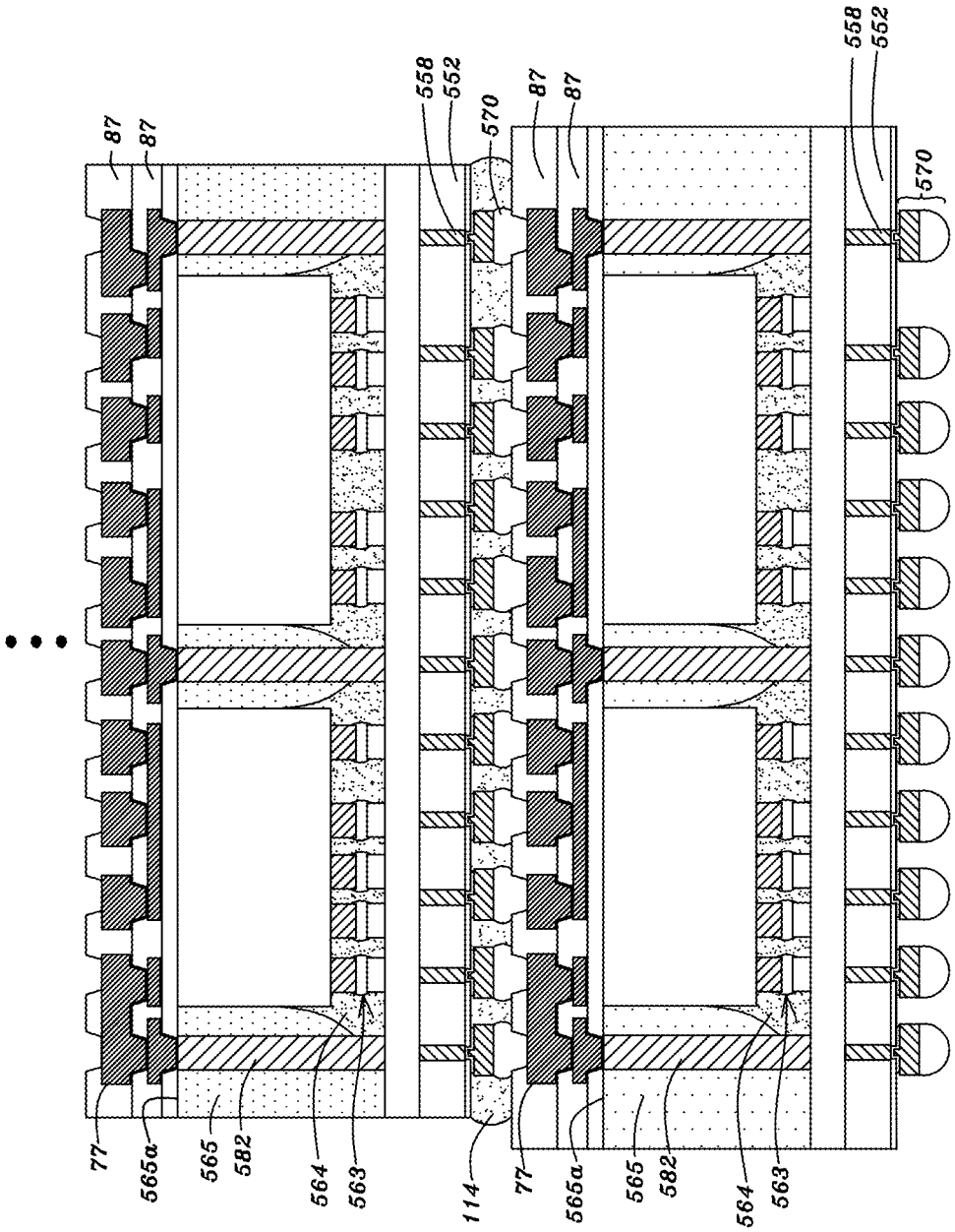

87
87
558
552
570
87
87
558
552
570
77
565a
565
582
564
563
114
77
565a
565
582
564
563

Fig. 29F

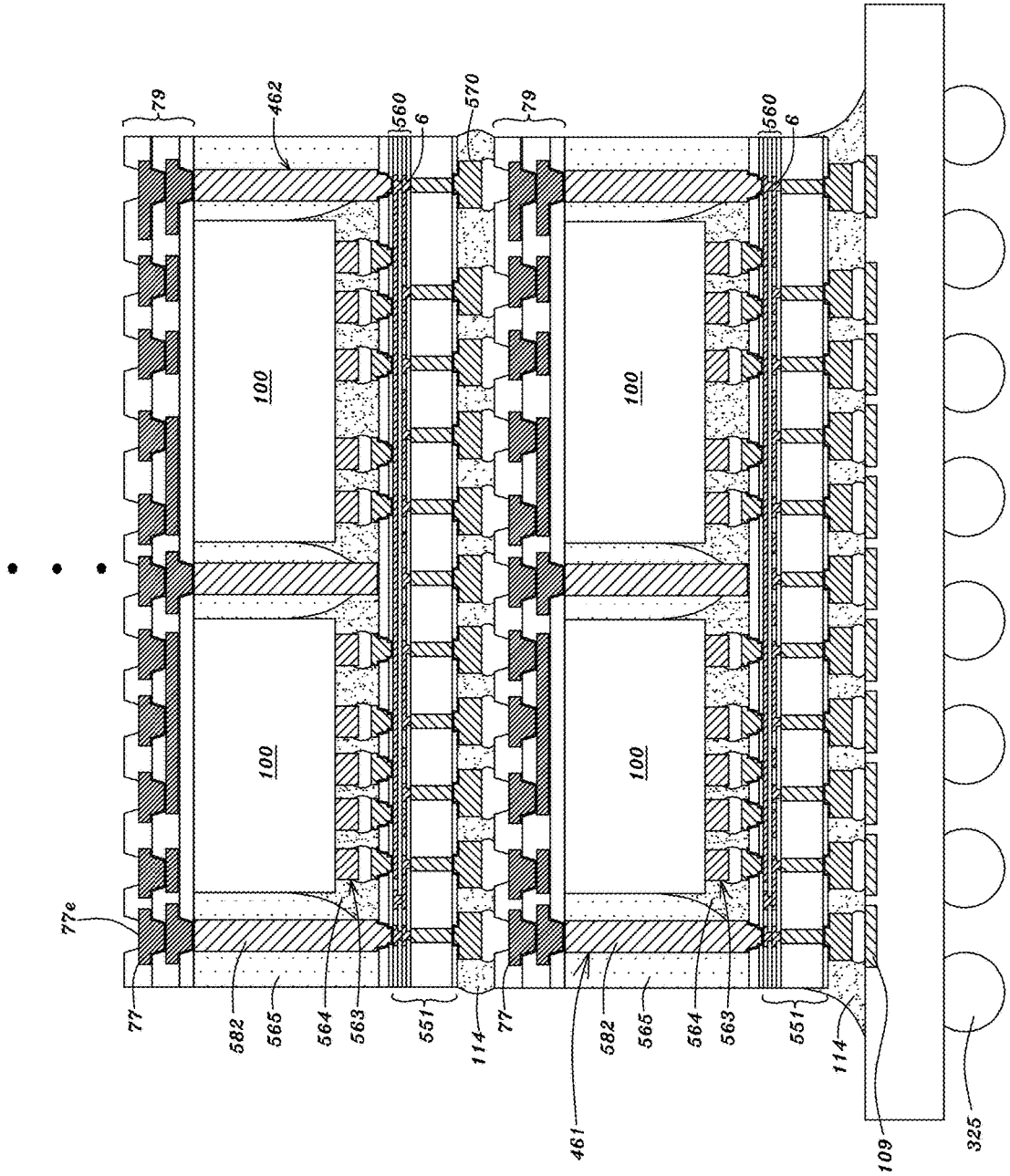

79
462
560
6
570
79
560
6
100
100
100
100
77e
77
582
565
564
563
551
114
77
461
582
565
564
563
551
114
109
325

Fig. 30A

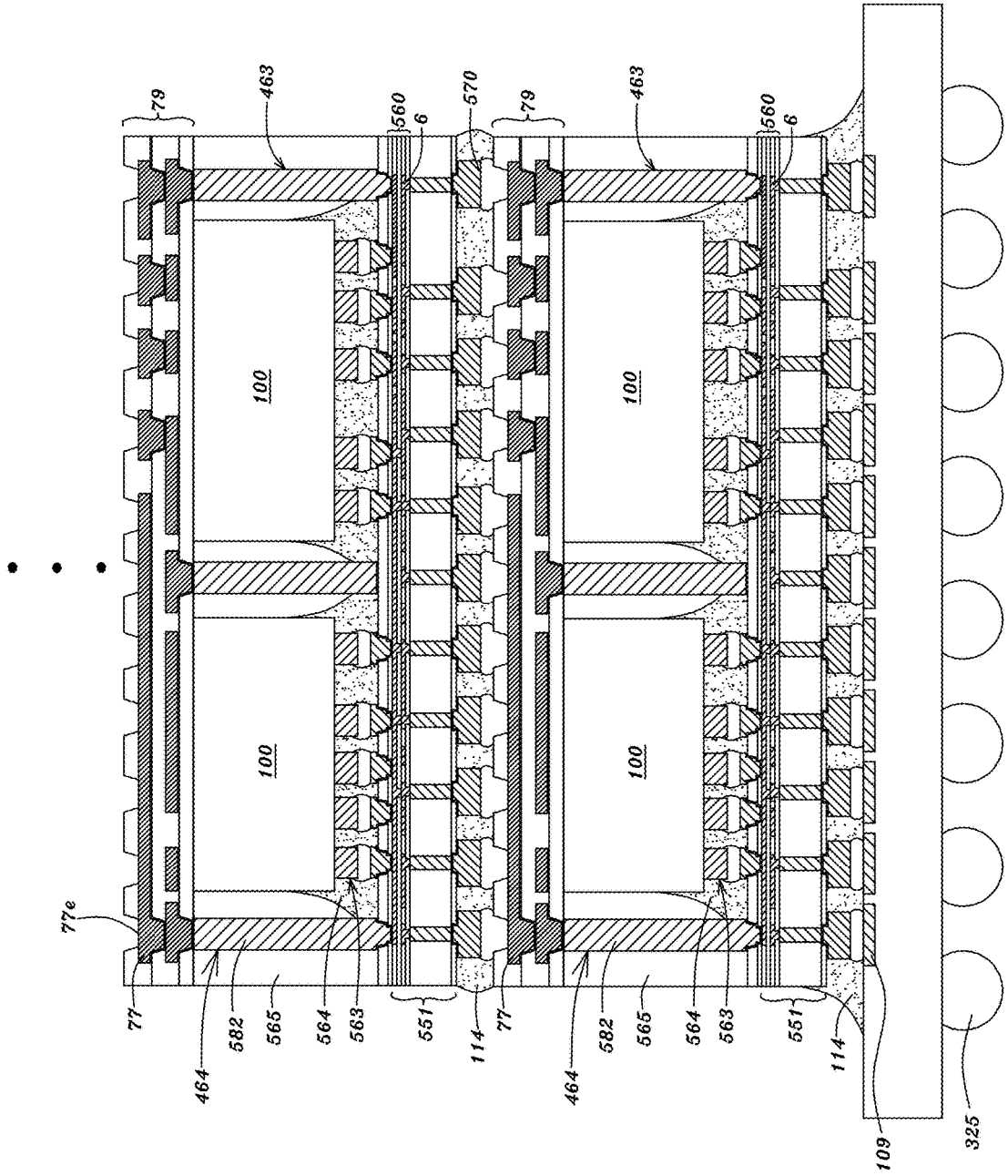

79
463
560
6
570
79
463
560
6
100
100
100
100
77e
77
464
582
565
564
563
551
114
77
464
582
565
564
563
551
114
109
325

Fig. 30B

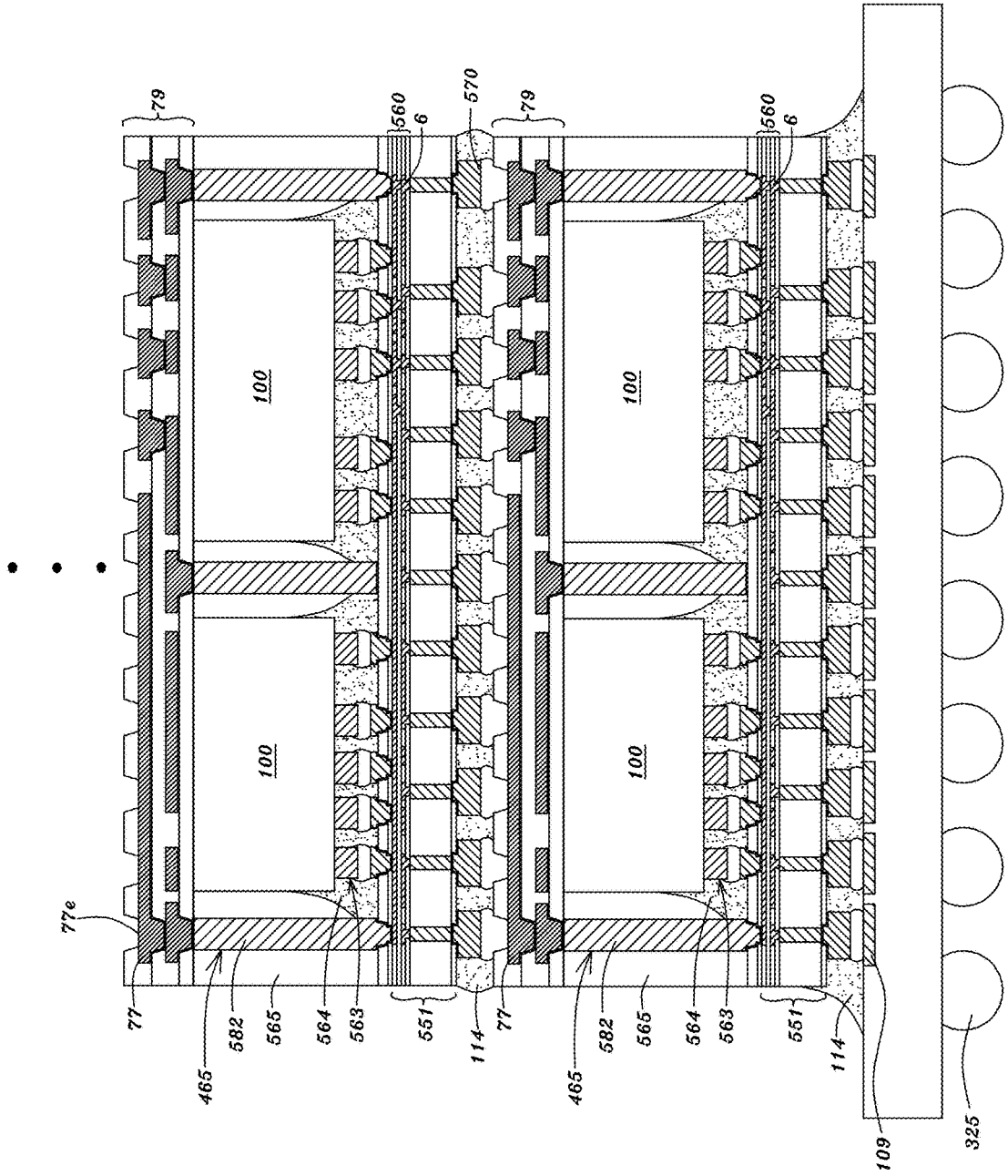

79
560
6
570
79
560
6
100
100
100
100
77e
77
582
565
564
563
551
114
77
465
582
565
564
563
551
114
109
325

Fig. 30C

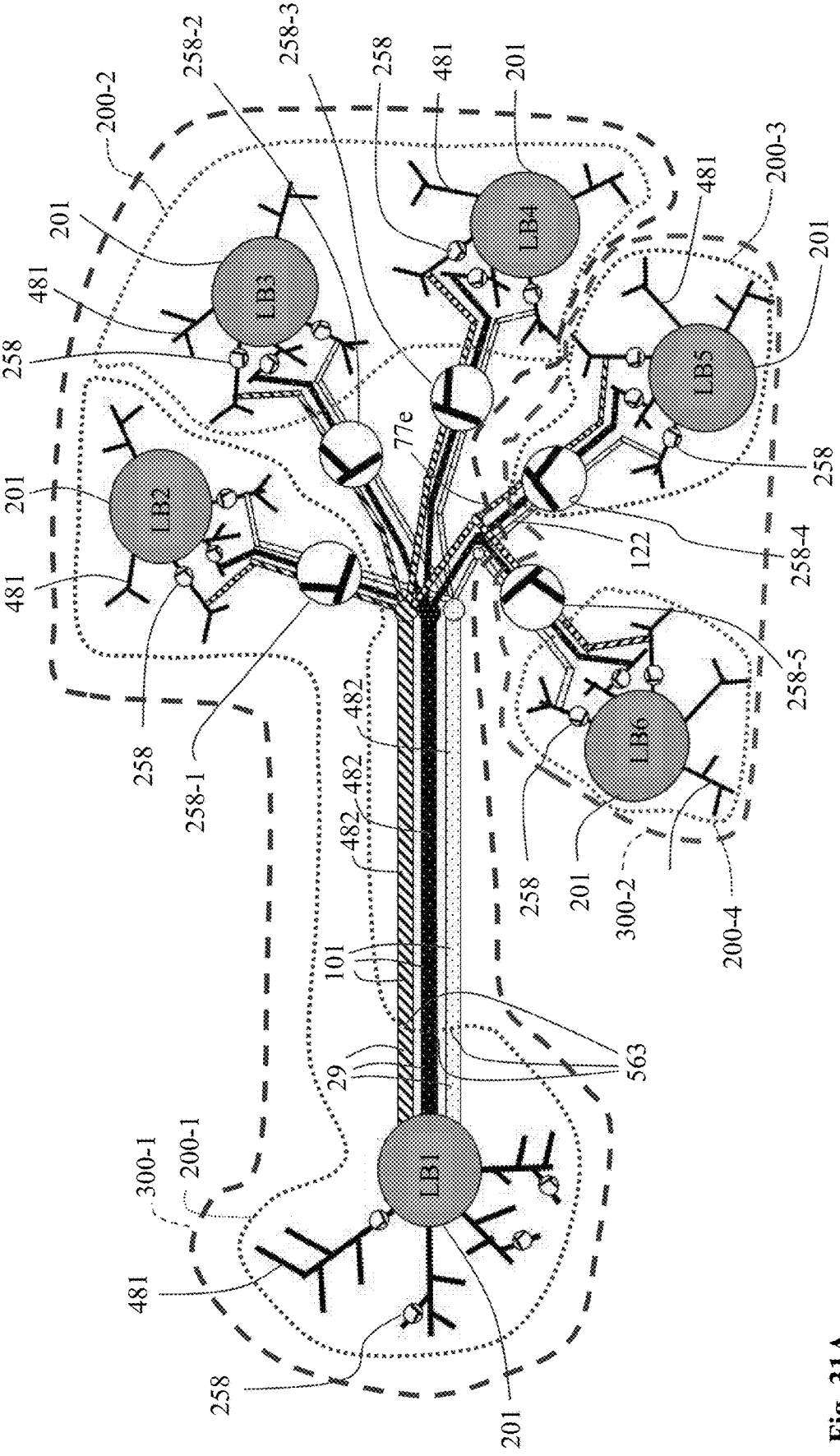

LB1
LB2
LB3
LB4
LB5
LB6
200-1
200-2
200-3
200-4
300-1
300-2
201
258
258-1
258-2
258-3
258-4
258-5
481
482
101
29
563
77e
122

Fig. 31A

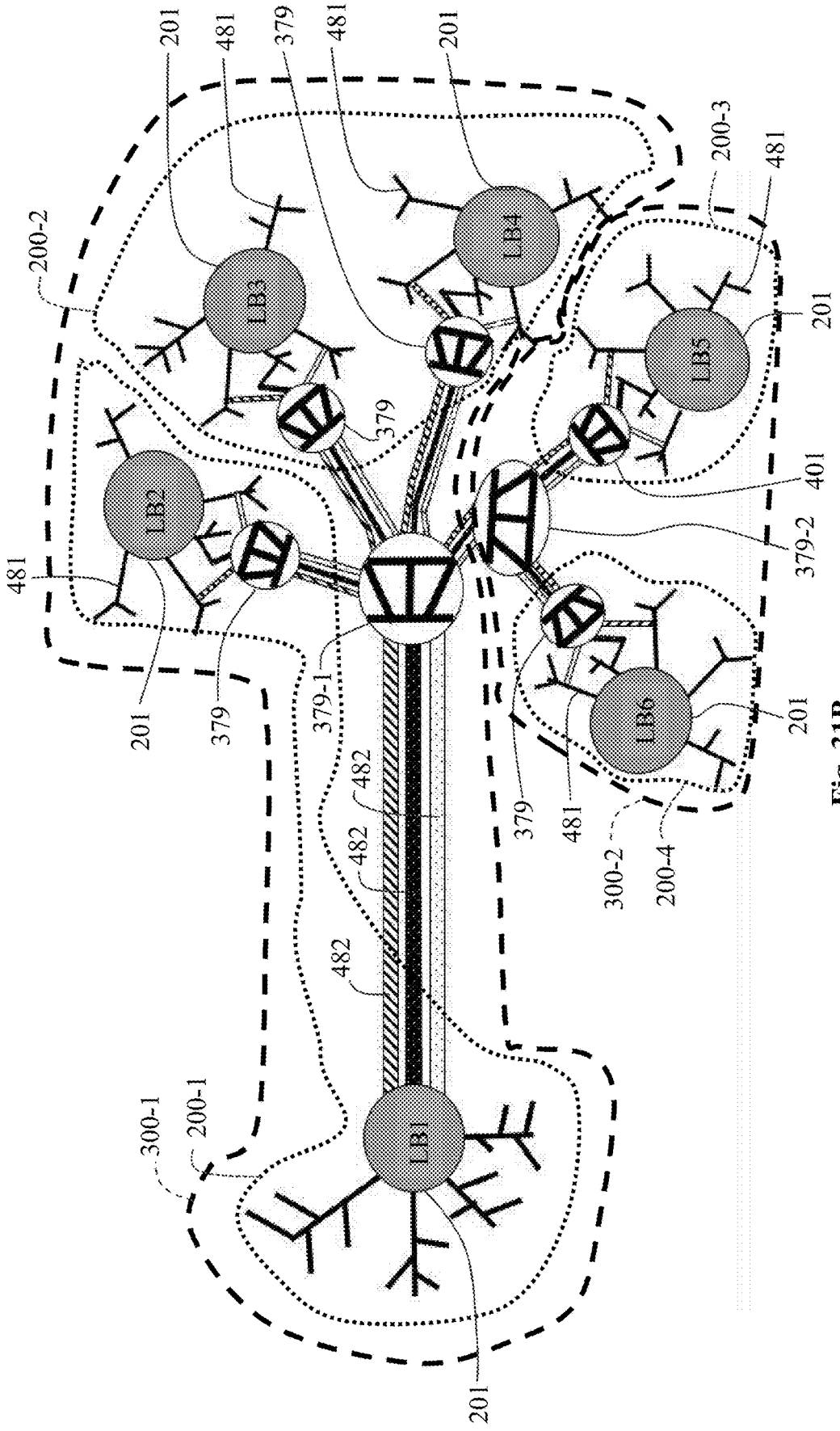

201
481
379
481
201
200-3
481
200-2
LB4
LB3
LB5
201
379
LB2
401
379-2
481
379-1
201
379
482
482
379
481
LB6
201
300-2
200-4
482
300-1
200-1
LB1
201

Fig. 31B

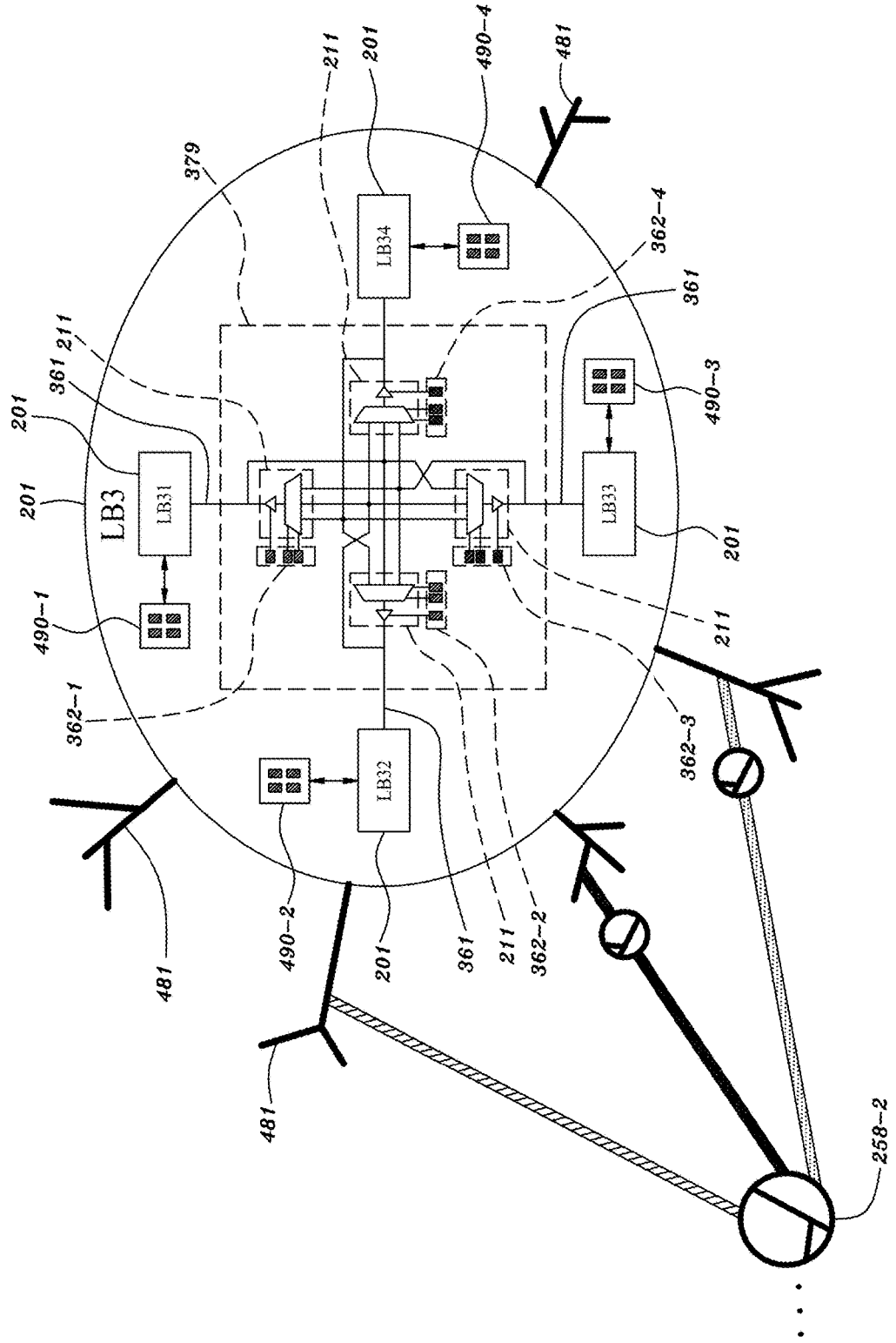

LB3
LB31
LB32
LB33
LB34
379
211
201
490-4
481
362-4
361
490-3
201
211
361
201
490-1
362-1
481
490-2
201
361
211
362-2
481
211
362-3
258-2

Fig. 31C

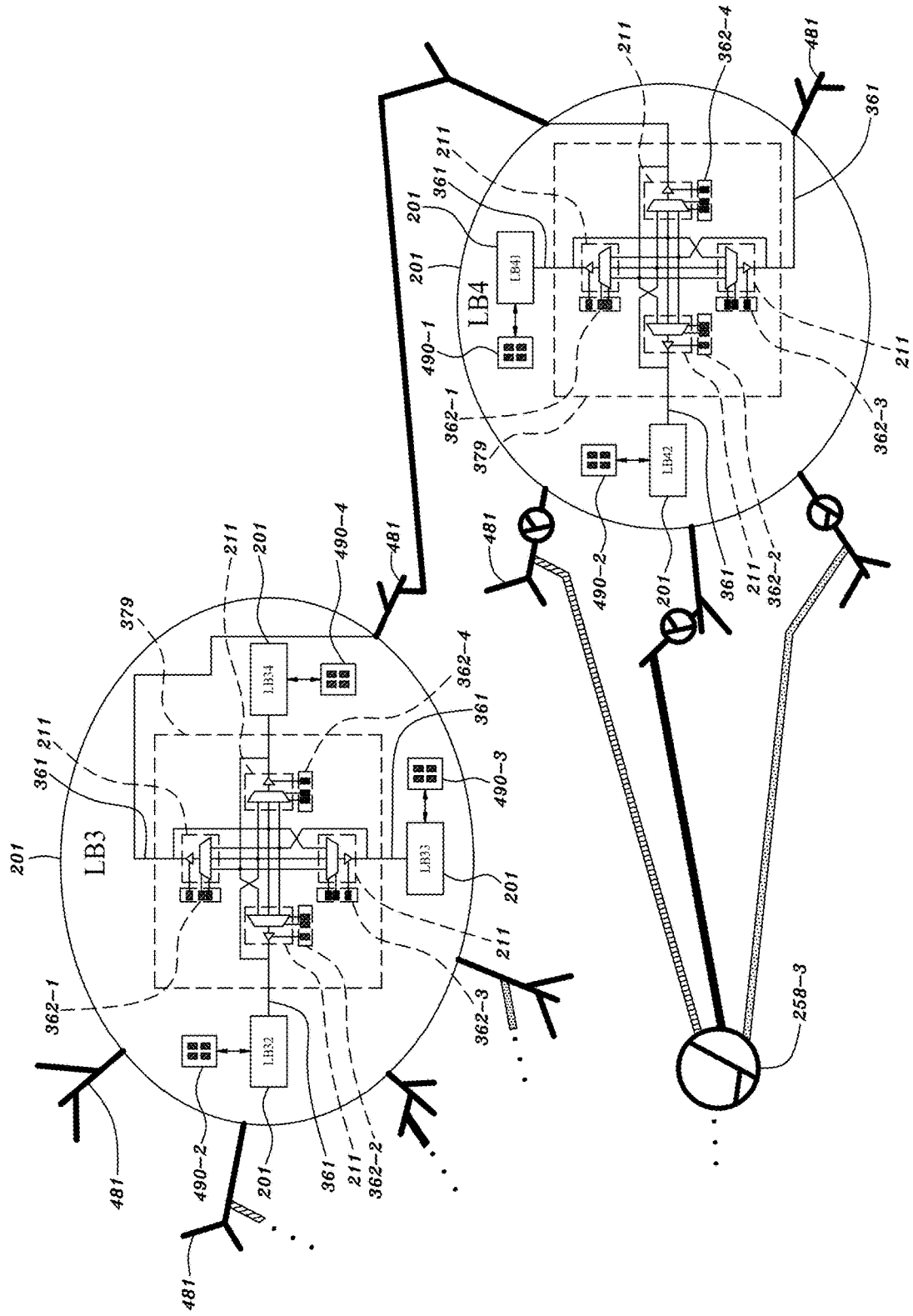

LB3
LB4
LB34
LB33
LB32
LB41
LB42
379
211
201
490-4
481
362-4
361
361 211
490-3
362-1
362-3
490-2
362-2
490-1
258-3

Fig. 31D

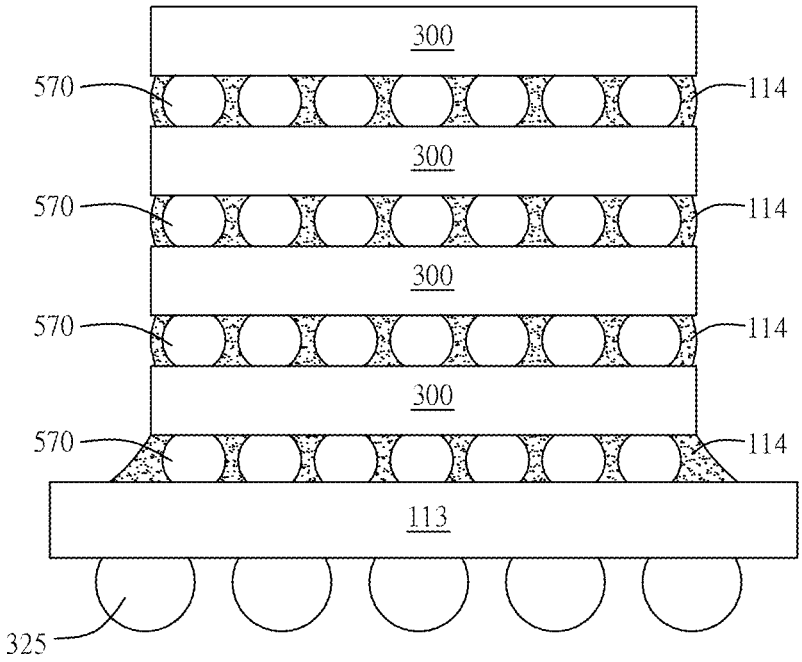


Fig. 32A

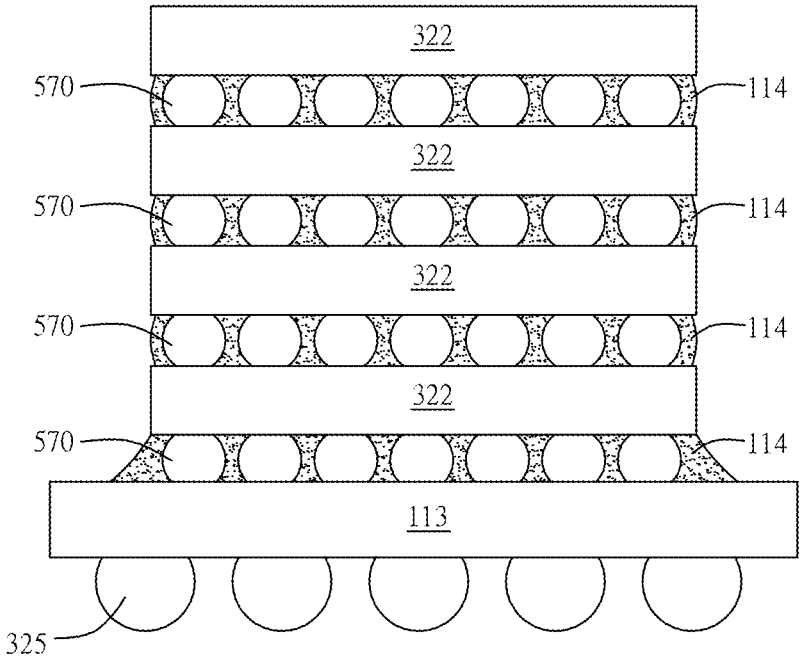


Fig. 32B

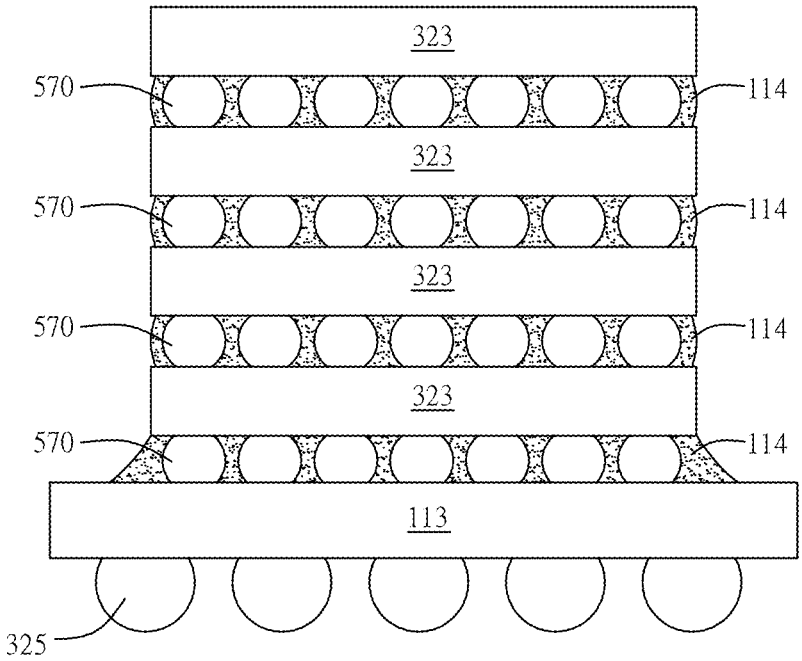


Fig. 32C

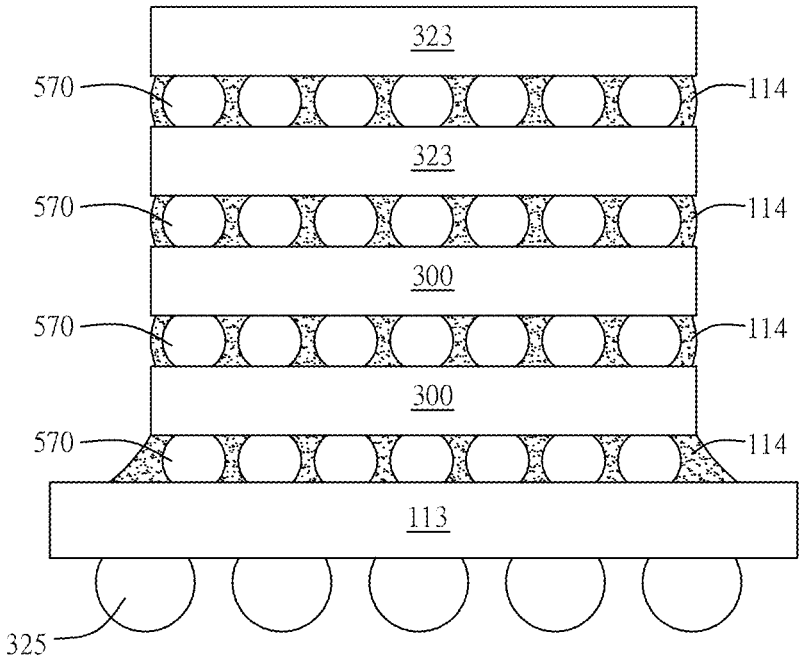


Fig. 32D

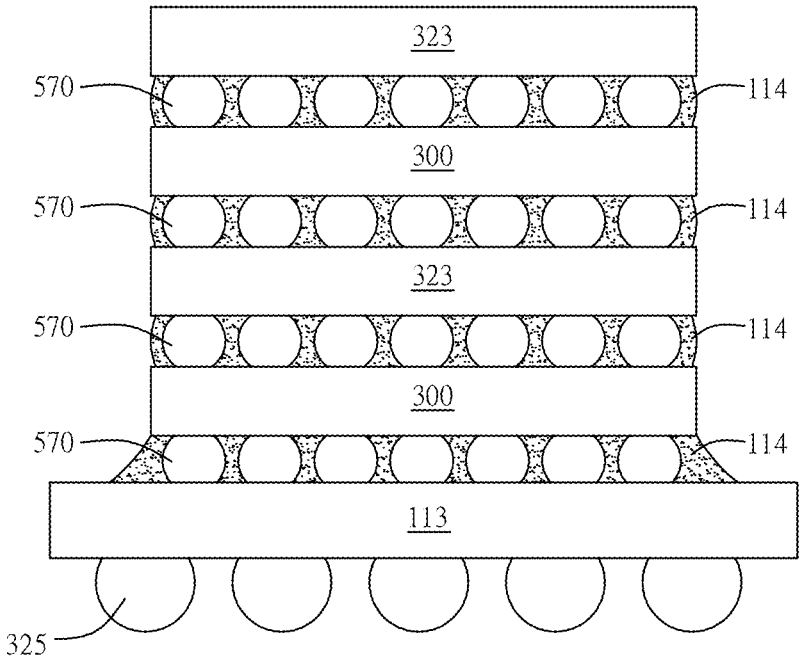


Fig. 32E

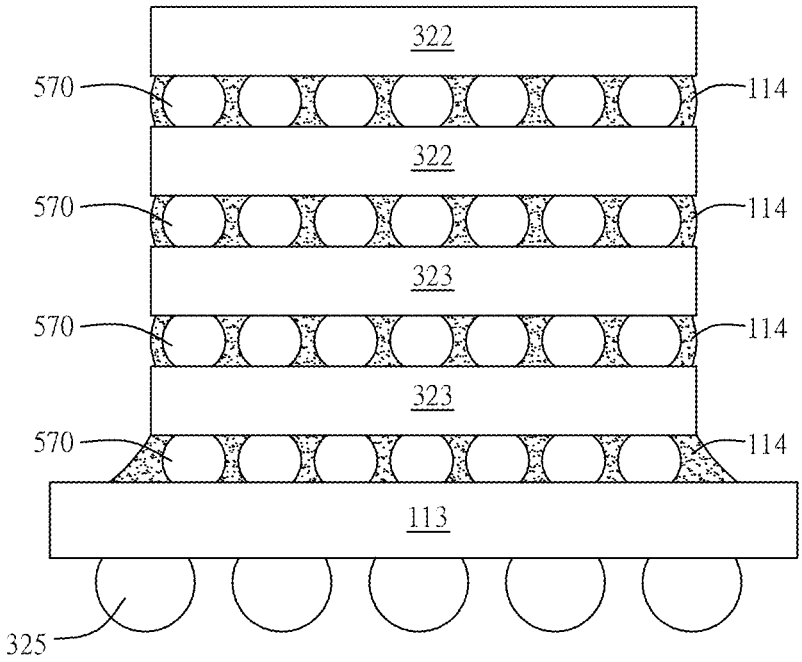


Fig. 32F

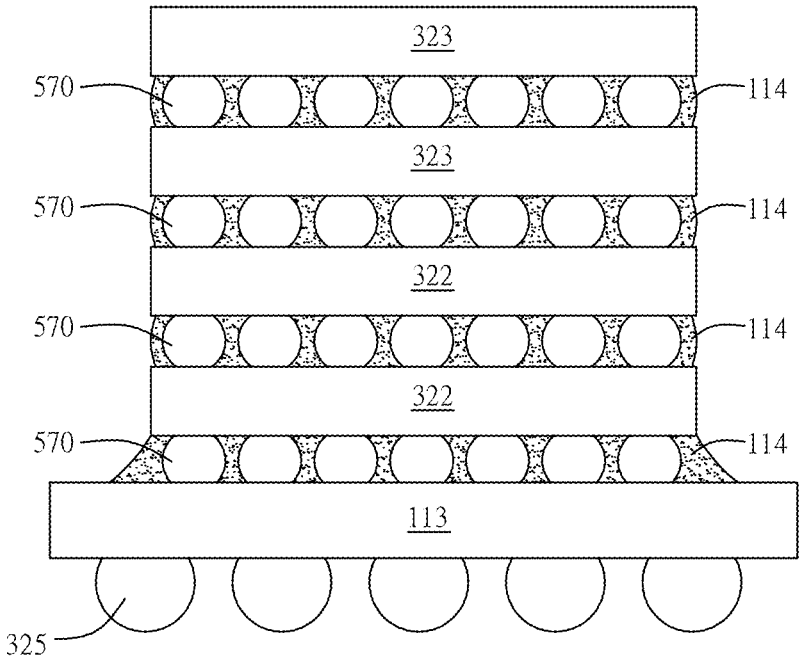


Fig. 32G

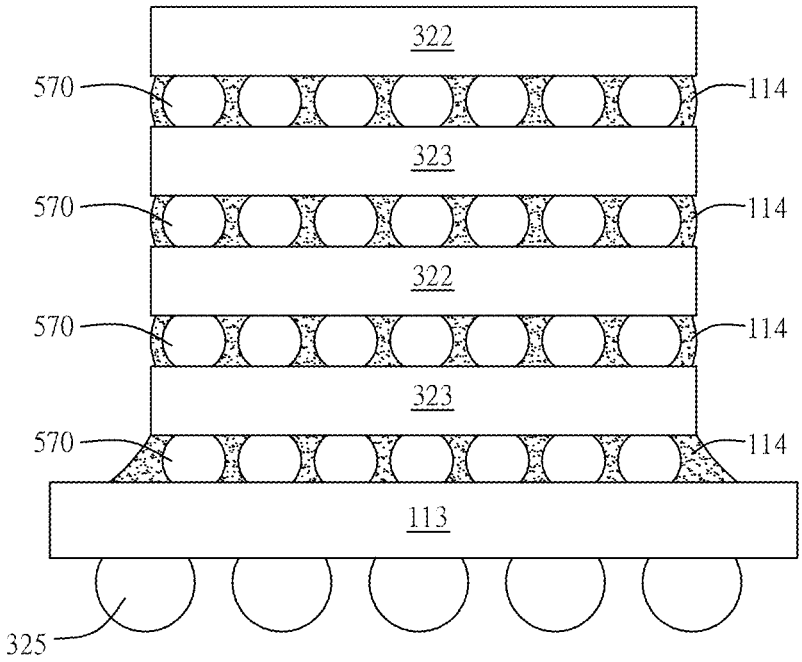


Fig. 32H

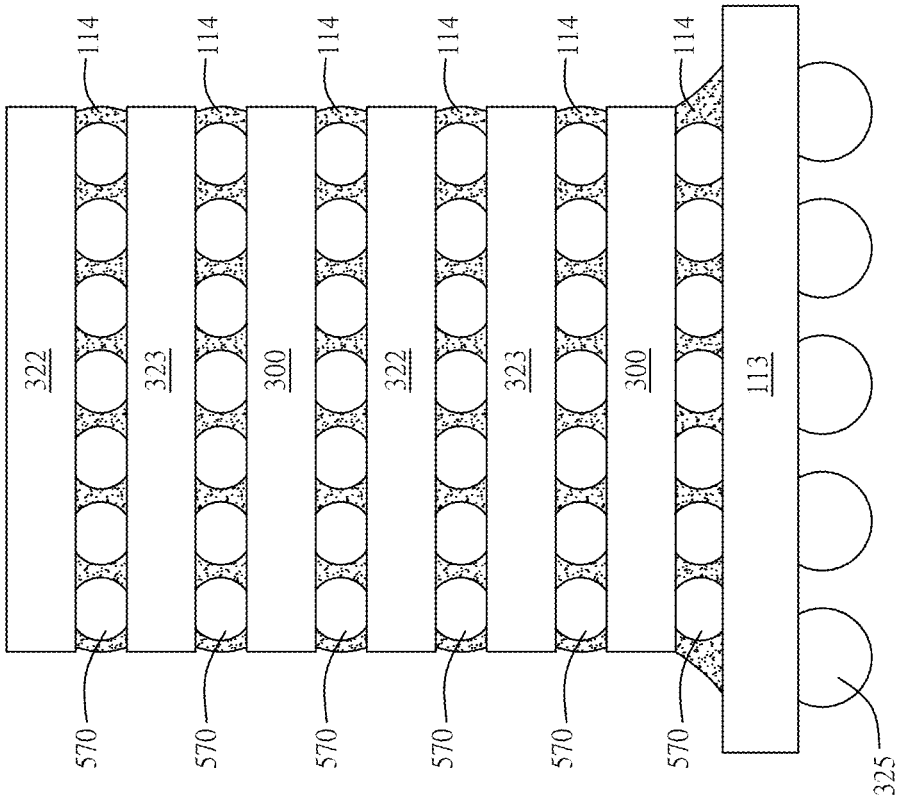


Fig. 32J

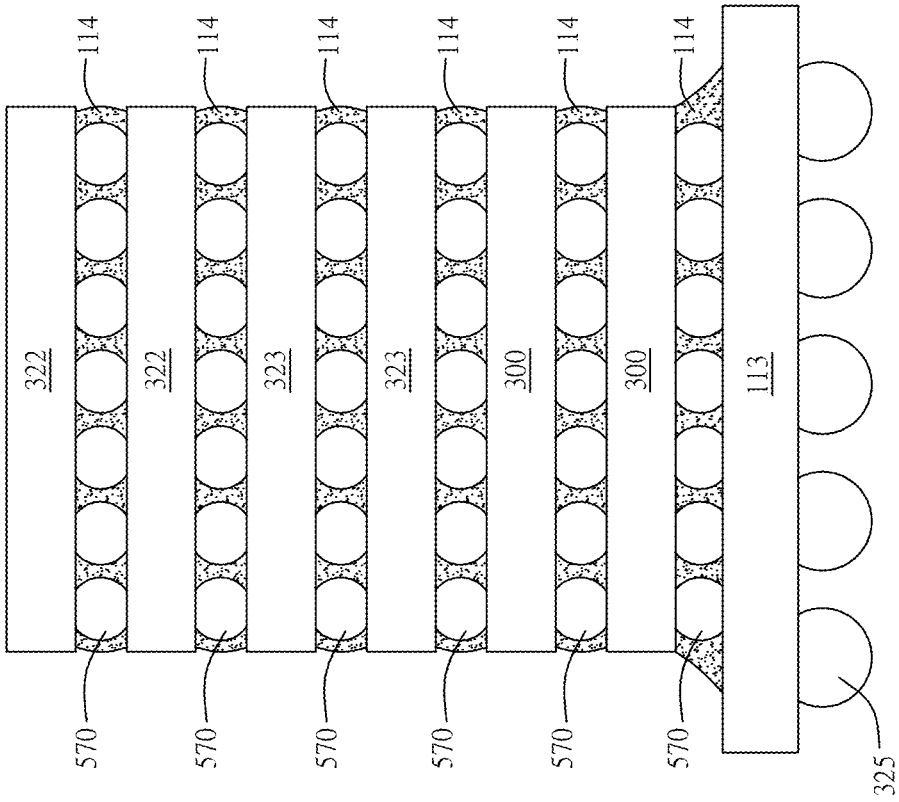


Fig. 32I

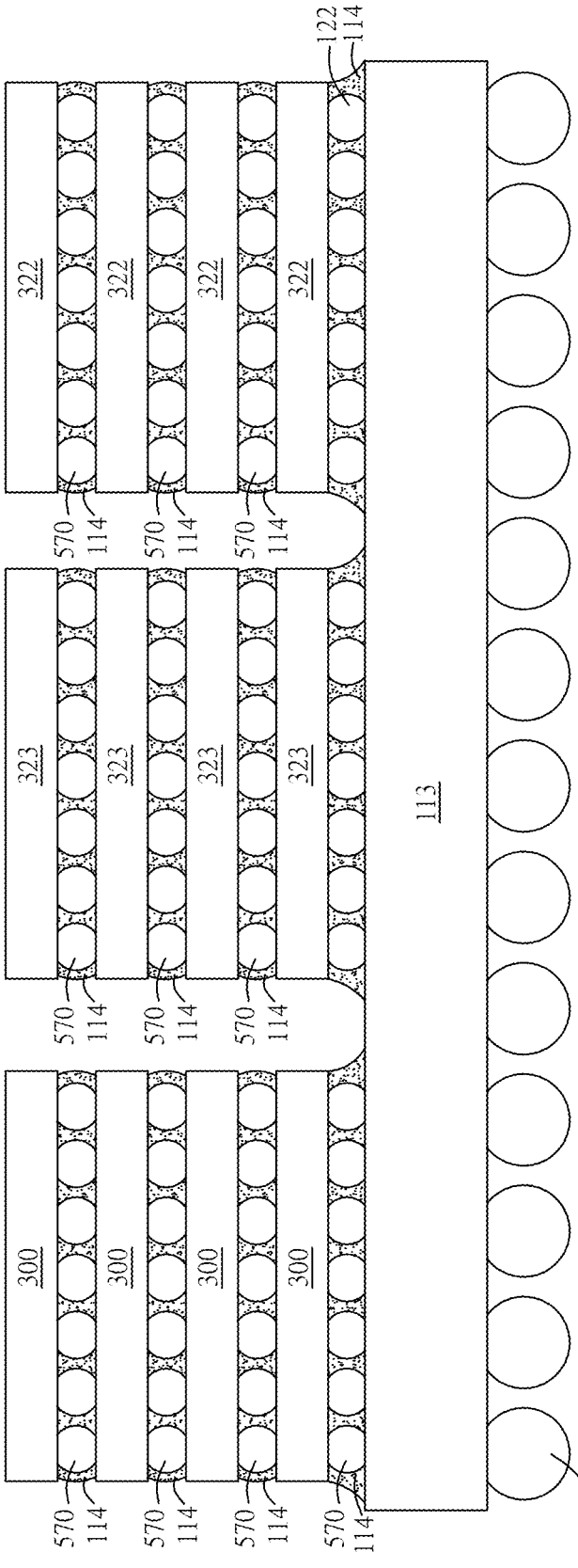

122
114
322
322
322
322
570
114
570
114
570
114
323
323
323
323
570
114
570
114
570
114
113
300
300
300
300
570
114
570
114
570
114
570
114
325

Fig. 32K

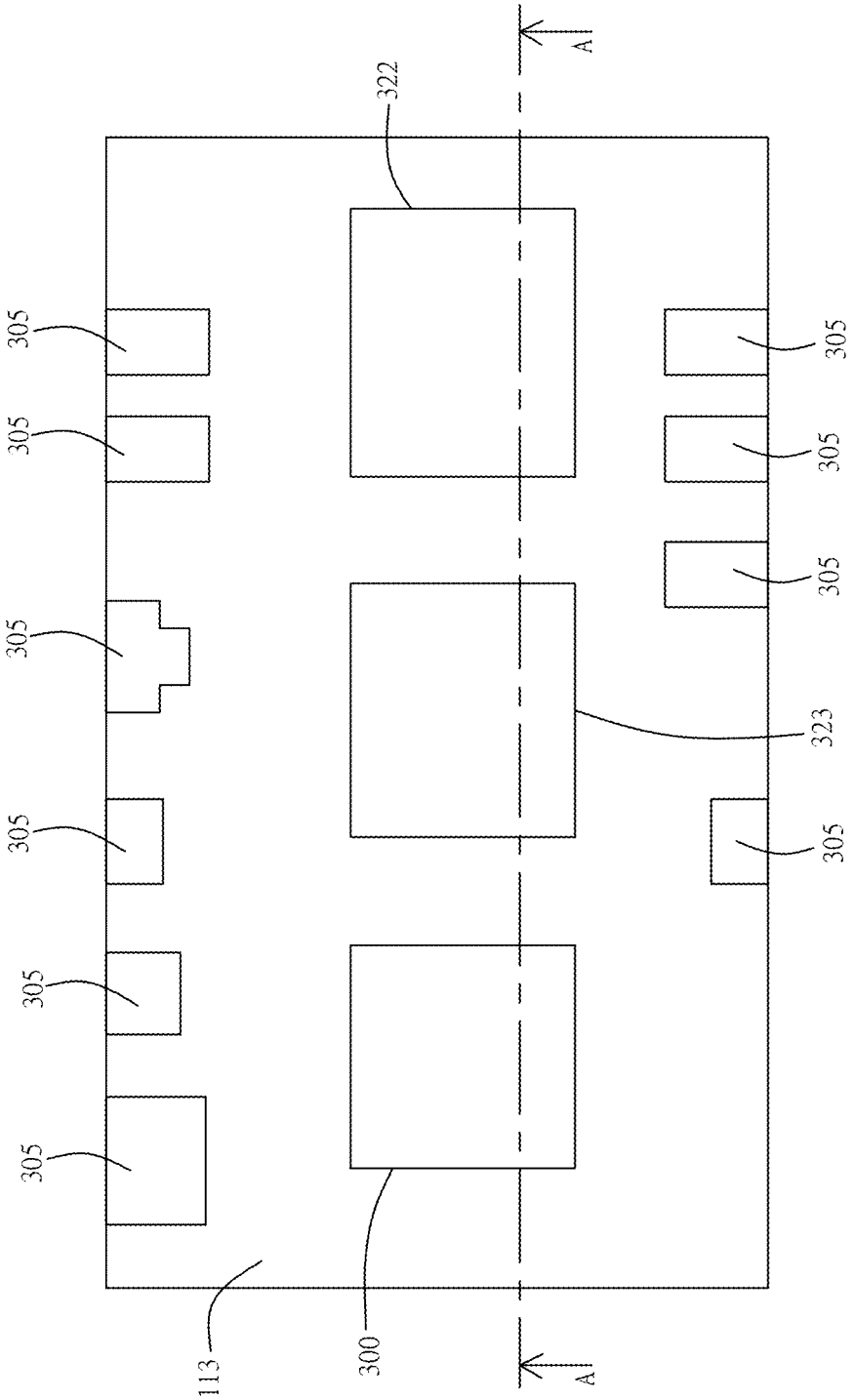


Fig. 32L

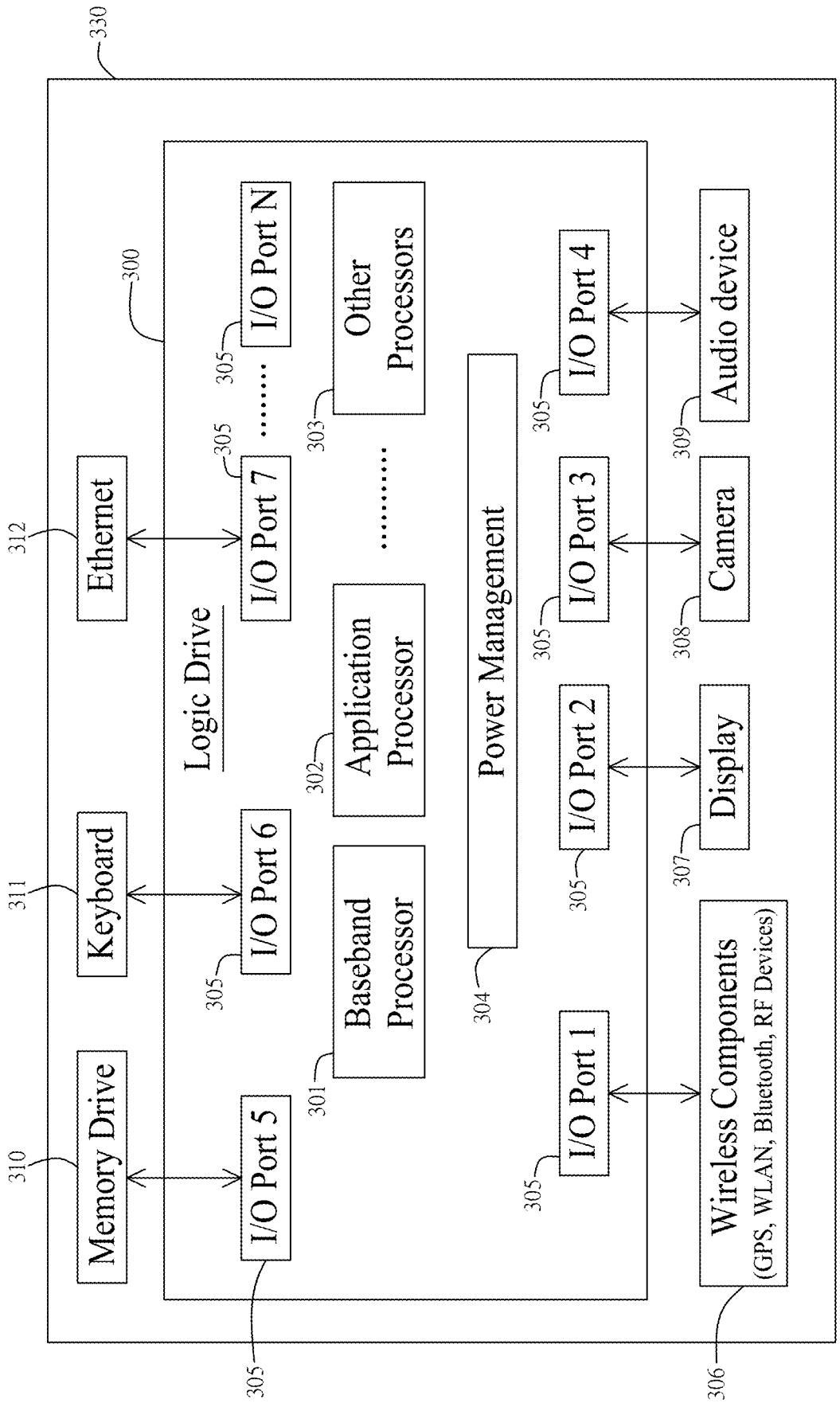

330
300
Logic Drive
Ethernet
312
Keyboard
311
Memory Drive
310
I/O Port 5
I/O Port 6
I/O Port 7
I/O Port N
305
Baseband Processor
301
Application Processor
302
Other Processors
303
Power Management
304
I/O Port 1
I/O Port 2
I/O Port 3
I/O Port 4
Display
307
Camera
308
Audio device
309
Wireless Components
(GPS, WLAN, Bluetooth, RF Devices)
306

Fig. 33A

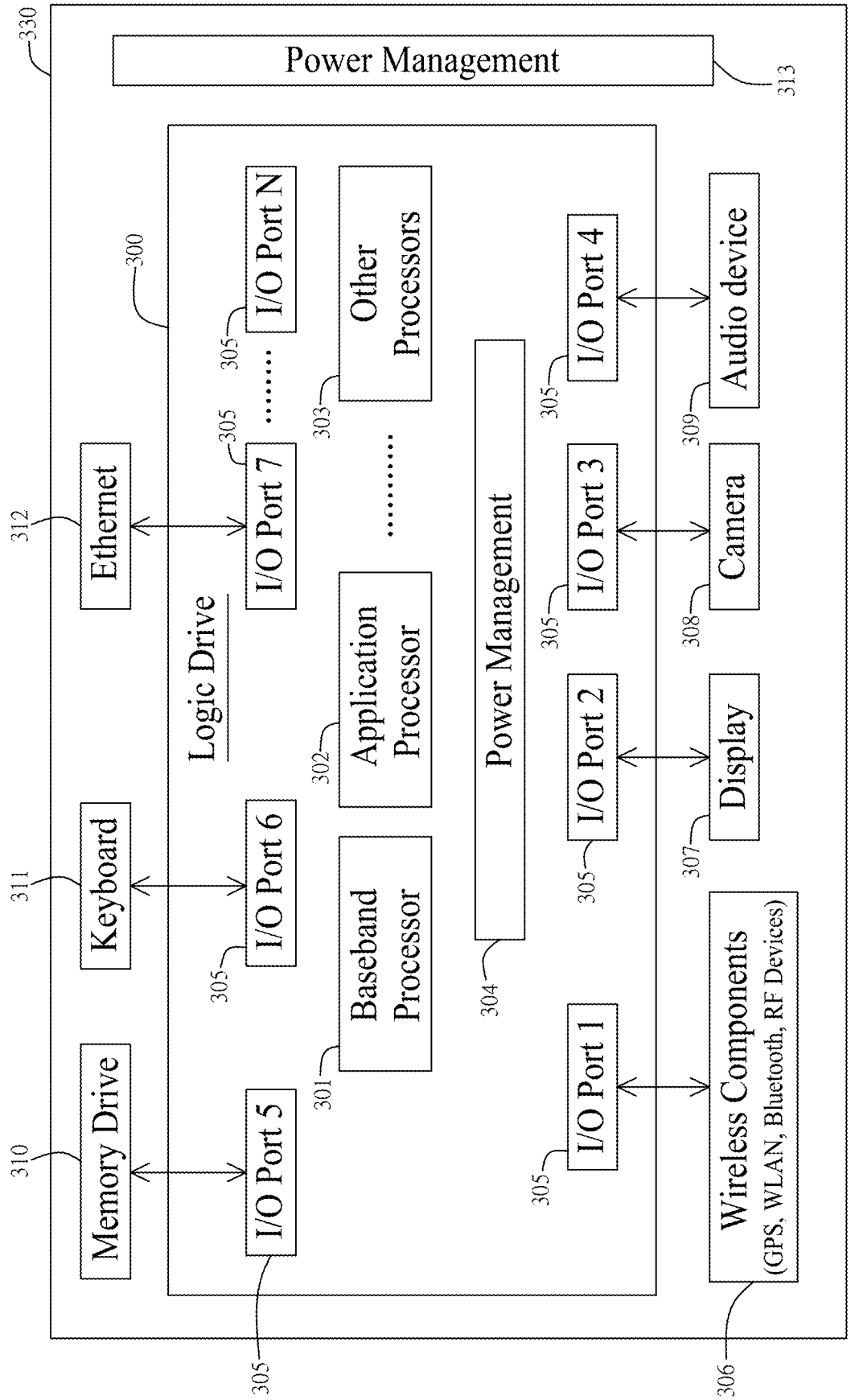

330
Power Management
313
300
Logic Drive
Ethernet
312
I/O Port 7
305
I/O Port N
305
Other Processors
303
Application Processor
302
Power Management
304
Baseband Processor
301
I/O Port 6
305
Keyboard
311
Memory Drive
310
I/O Port 5
305
305
I/O Port 1
I/O Port 2
305
I/O Port 3
305
I/O Port 4
305
Audio device
309
Camera
308
Display
307
Wireless Components
(GPS, WLAN, Bluetooth, RF Devices)
306

Fig. 33B

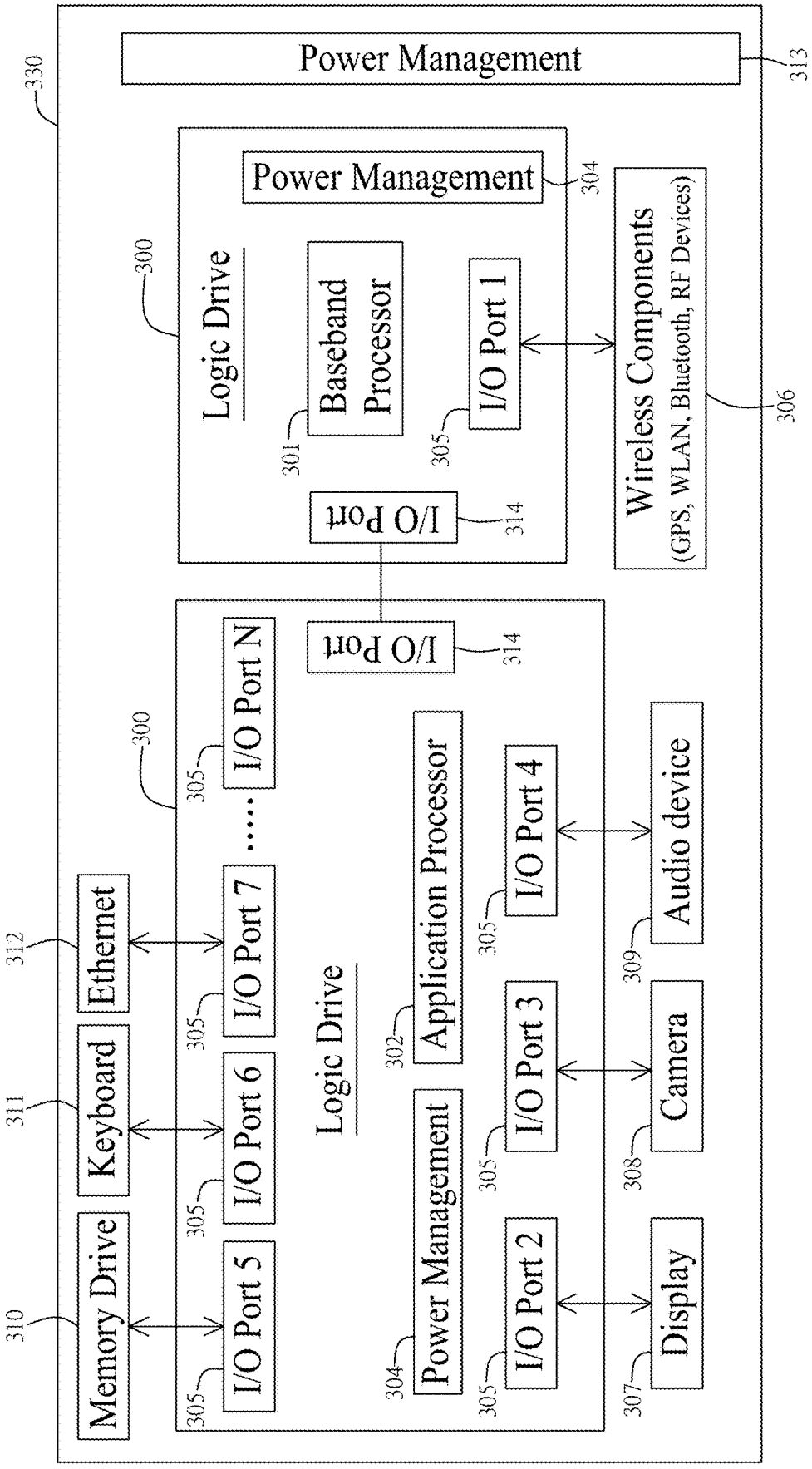

330
Power Management
313
Logic Drive
300
Power Management
304
Baseband Processor
301
I/O Port 1
305
I/O Port
314
Wireless Components
(GPS, WLAN, Bluetooth, RF Devices)
306
I/O Port
314
I/O Port N
305
I/O Port 7
305
I/O Port 6
305
I/O Port 5
305
Ethernet
312
Keyboard
311
Memory Drive
310
Logic Drive
300
Application Processor
302
Power Management
304
I/O Port 4
305
I/O Port 3
305
I/O Port 2
305
Audio device
309
Camera
308
Display
307

Fig. 33C

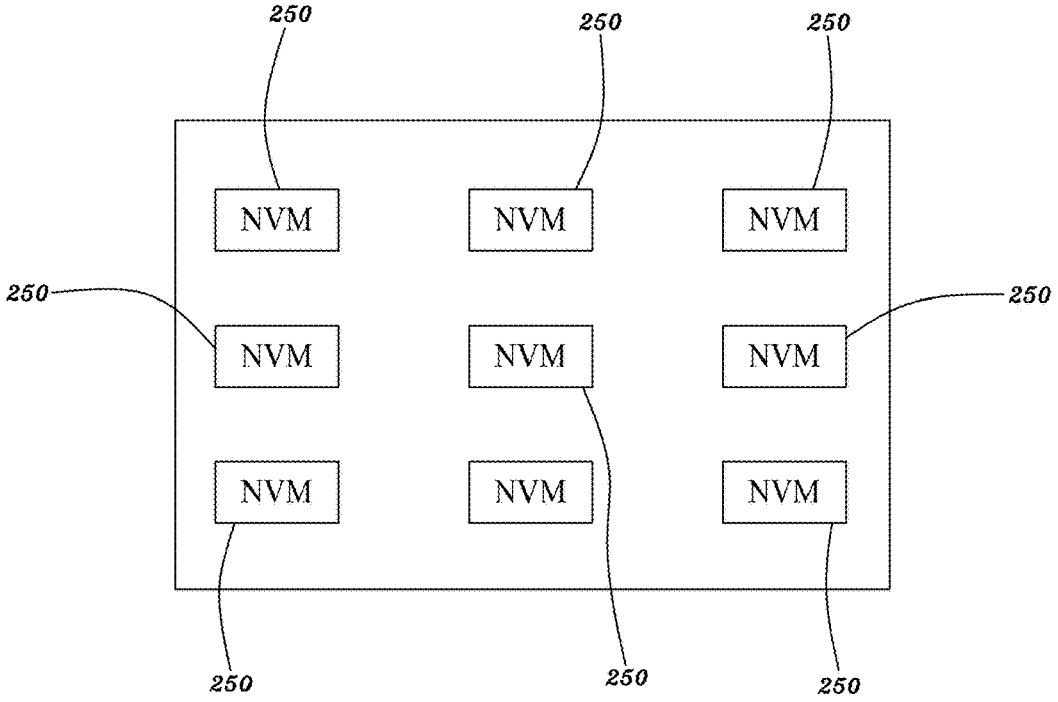


Fig. 34A

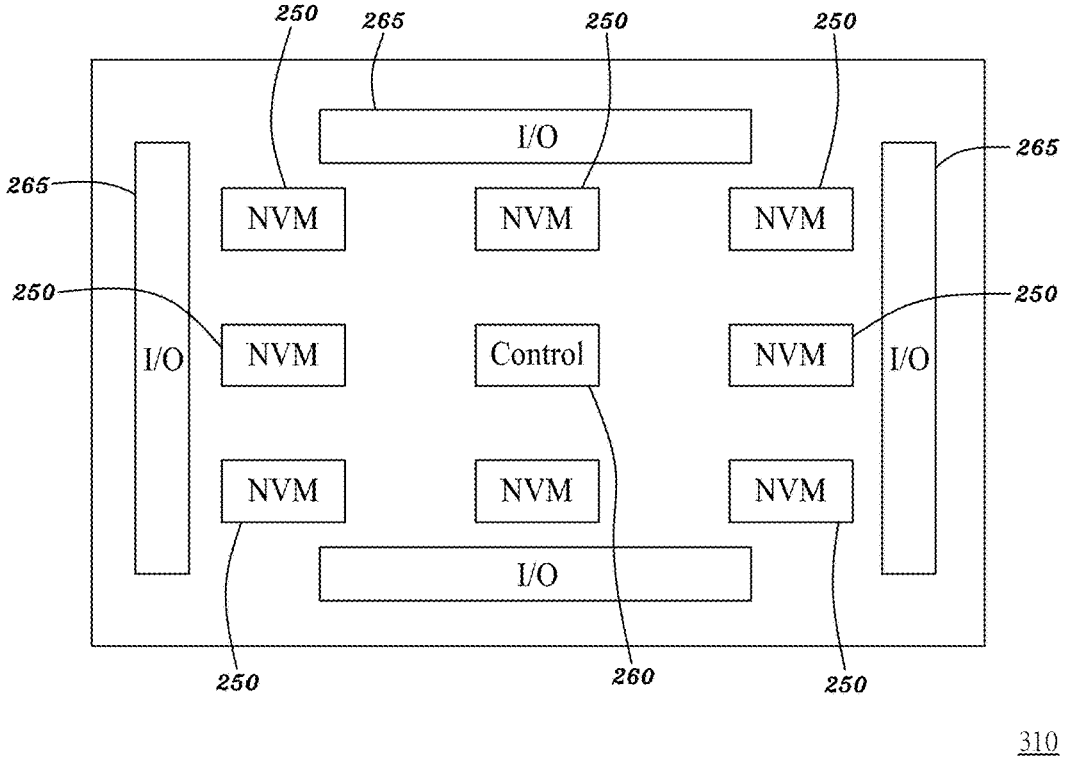


Fig. 34B

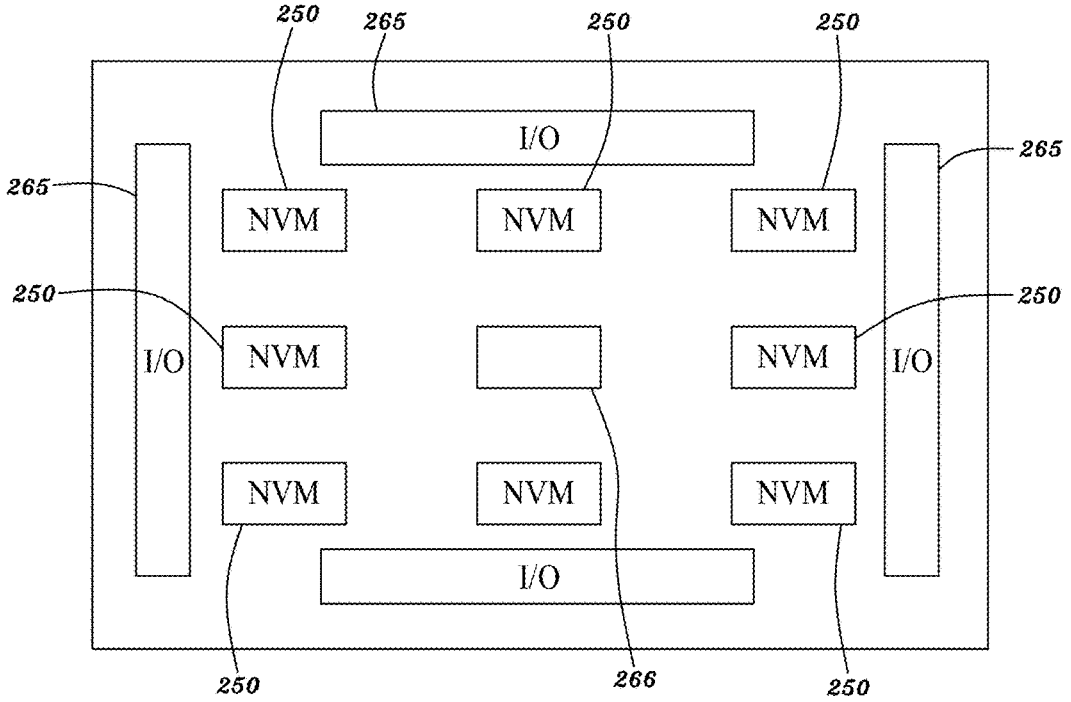


Fig. 34C

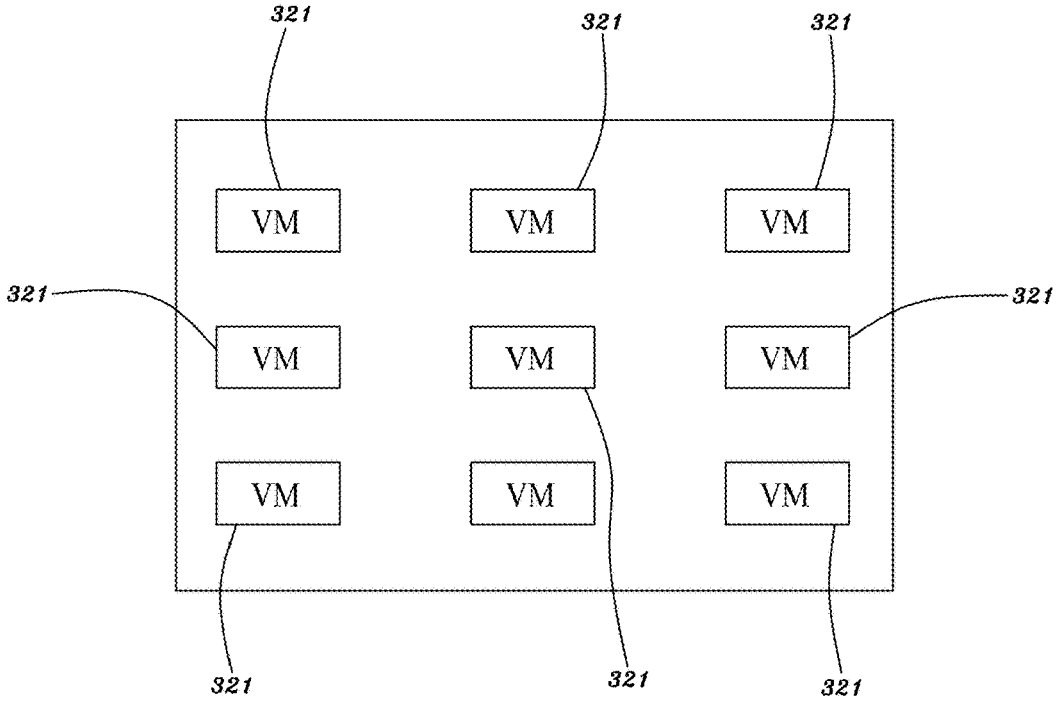


Fig. 34D

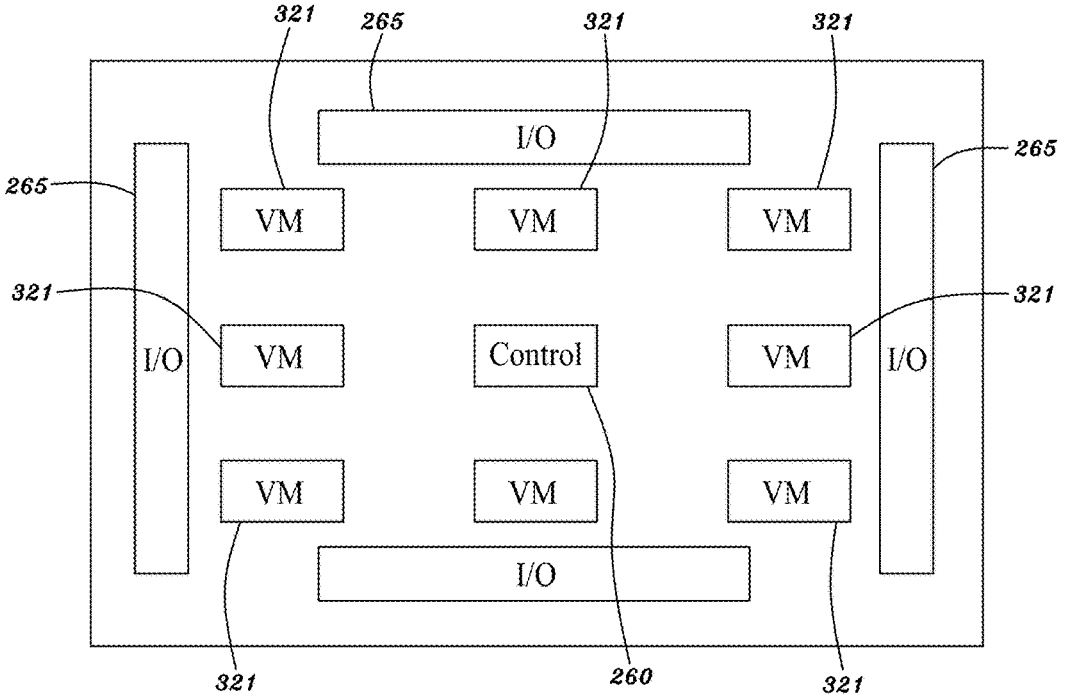


Fig. 34E

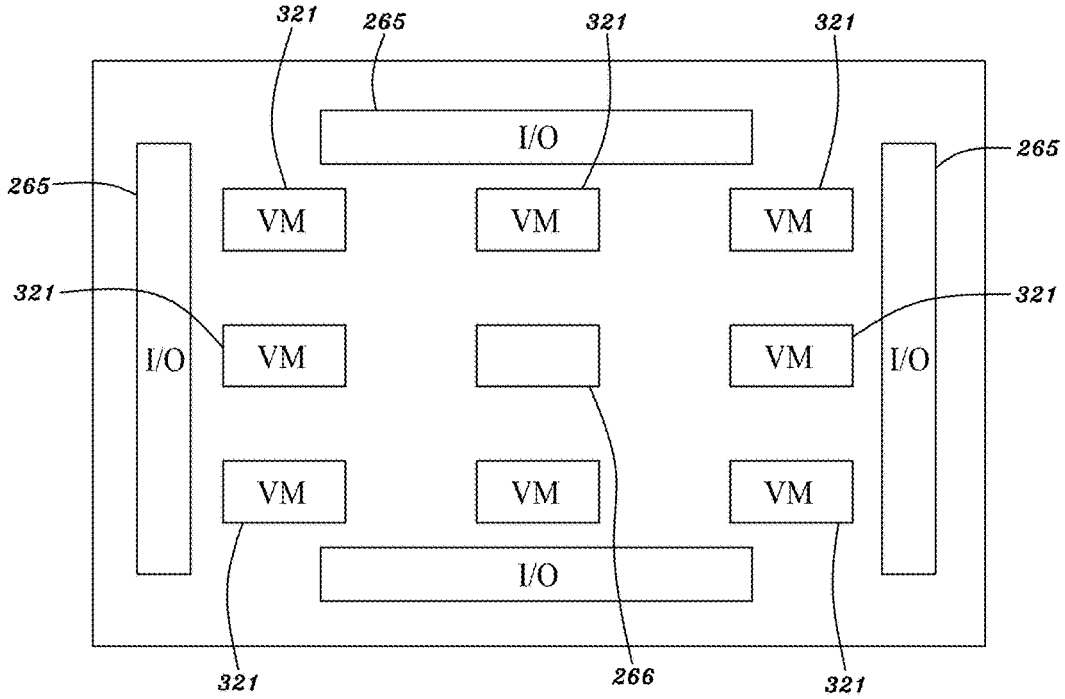


Fig. 34F

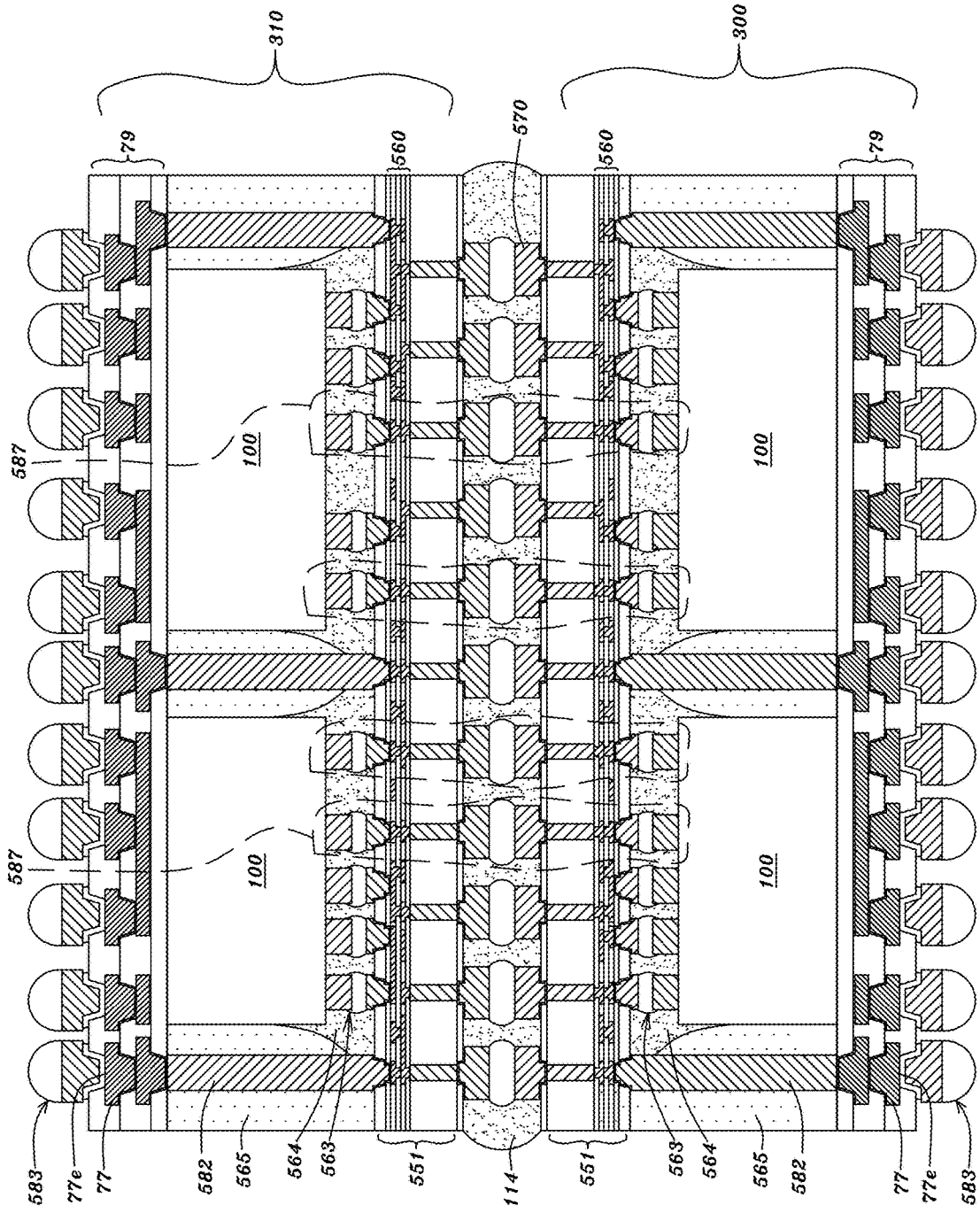

310
300
79
560
570
560
79
587
100
100
587
100
100
583
77e
77
582
565
564
563
551
114
551
563
564
565
582
77
77e
583

Fig. 35A

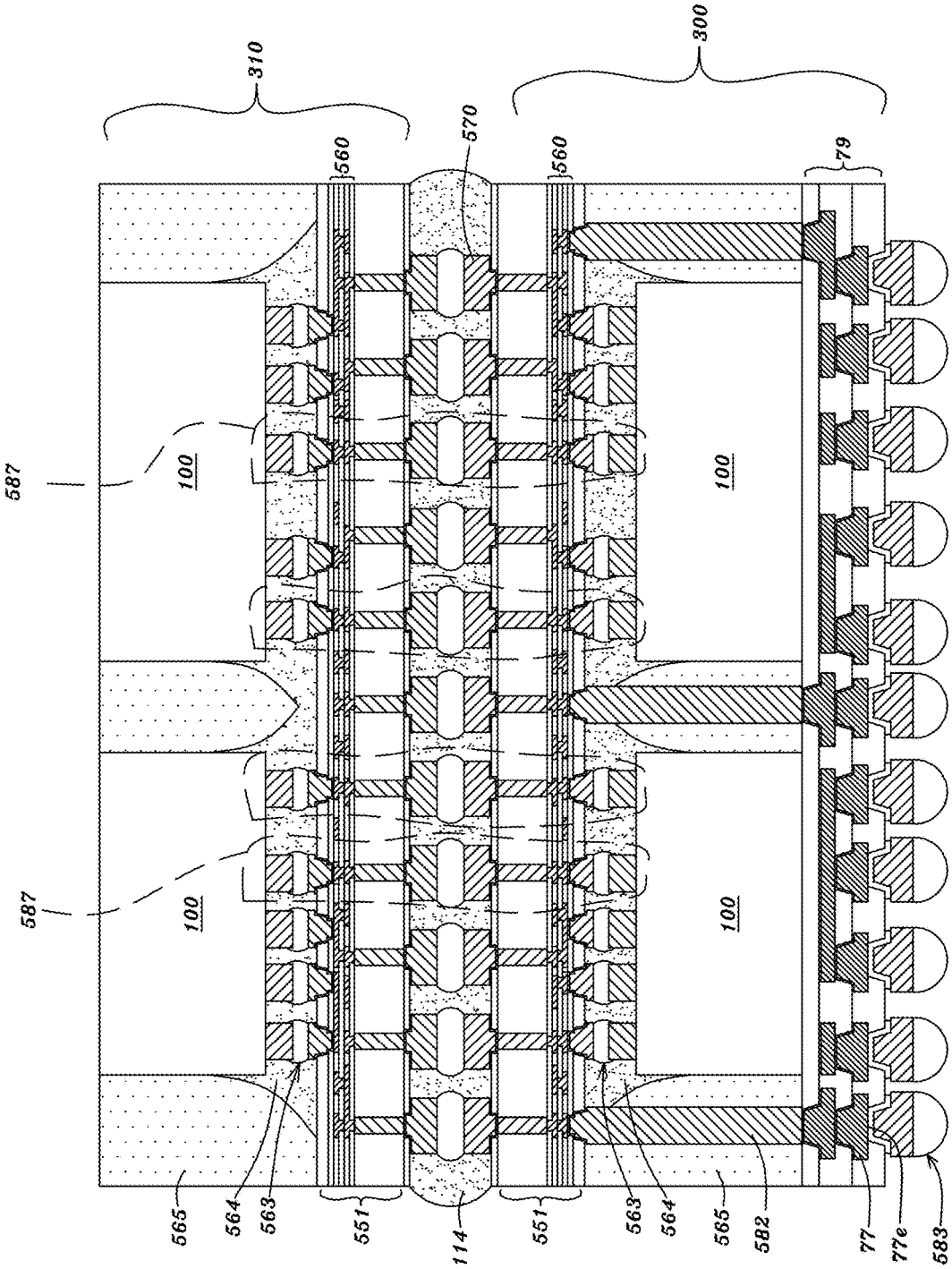

310
300
560
570
560
79
587
100
100
587
100
100
565
564
563
551
114
551
563
564
565
582
77
77e
583

Fig. 35B

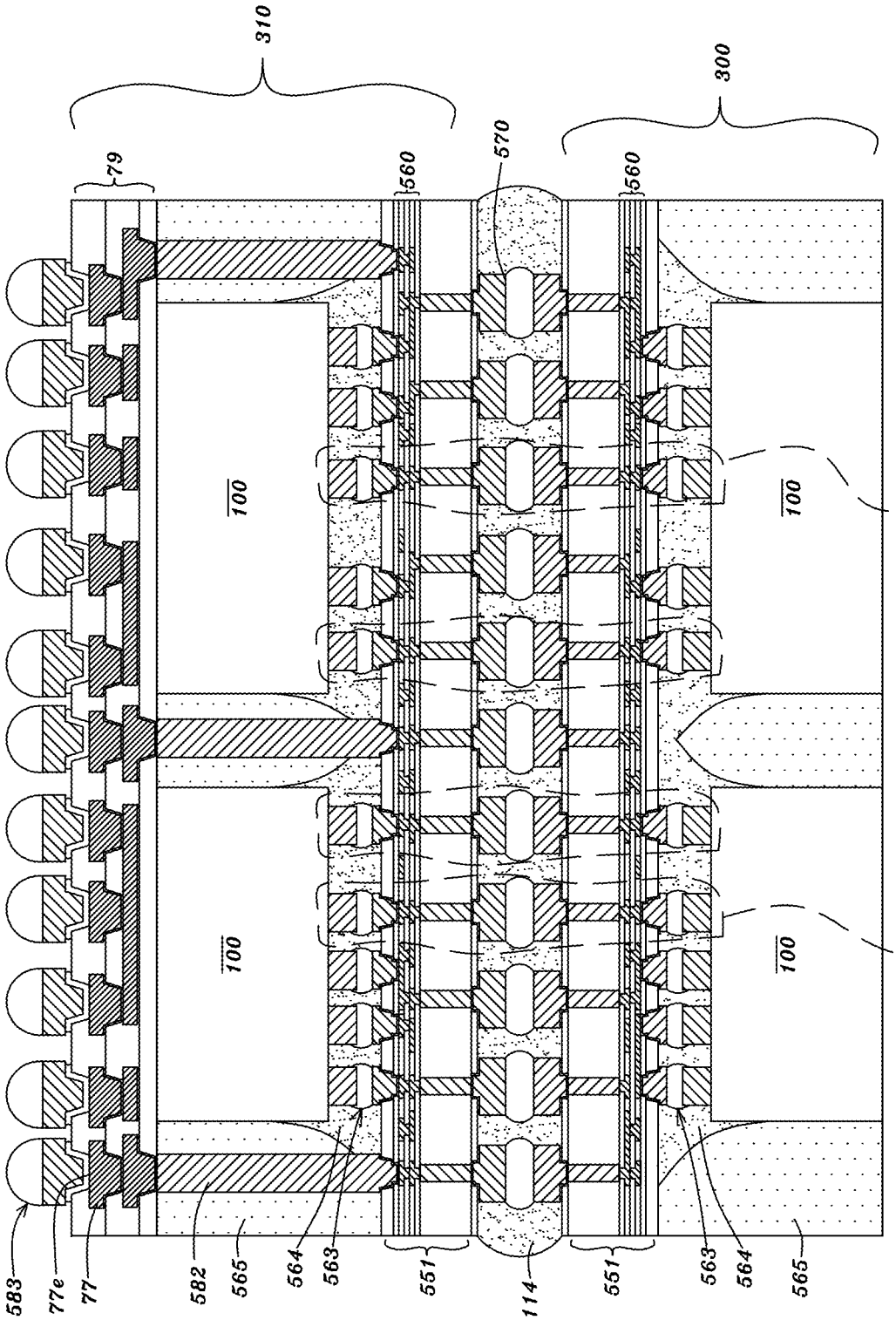

310
300
79
560
570
560
100
100
100
100
587
587
583
77e
77
582
565
564
563
551
114
551
563
564
565

Fig. 35C

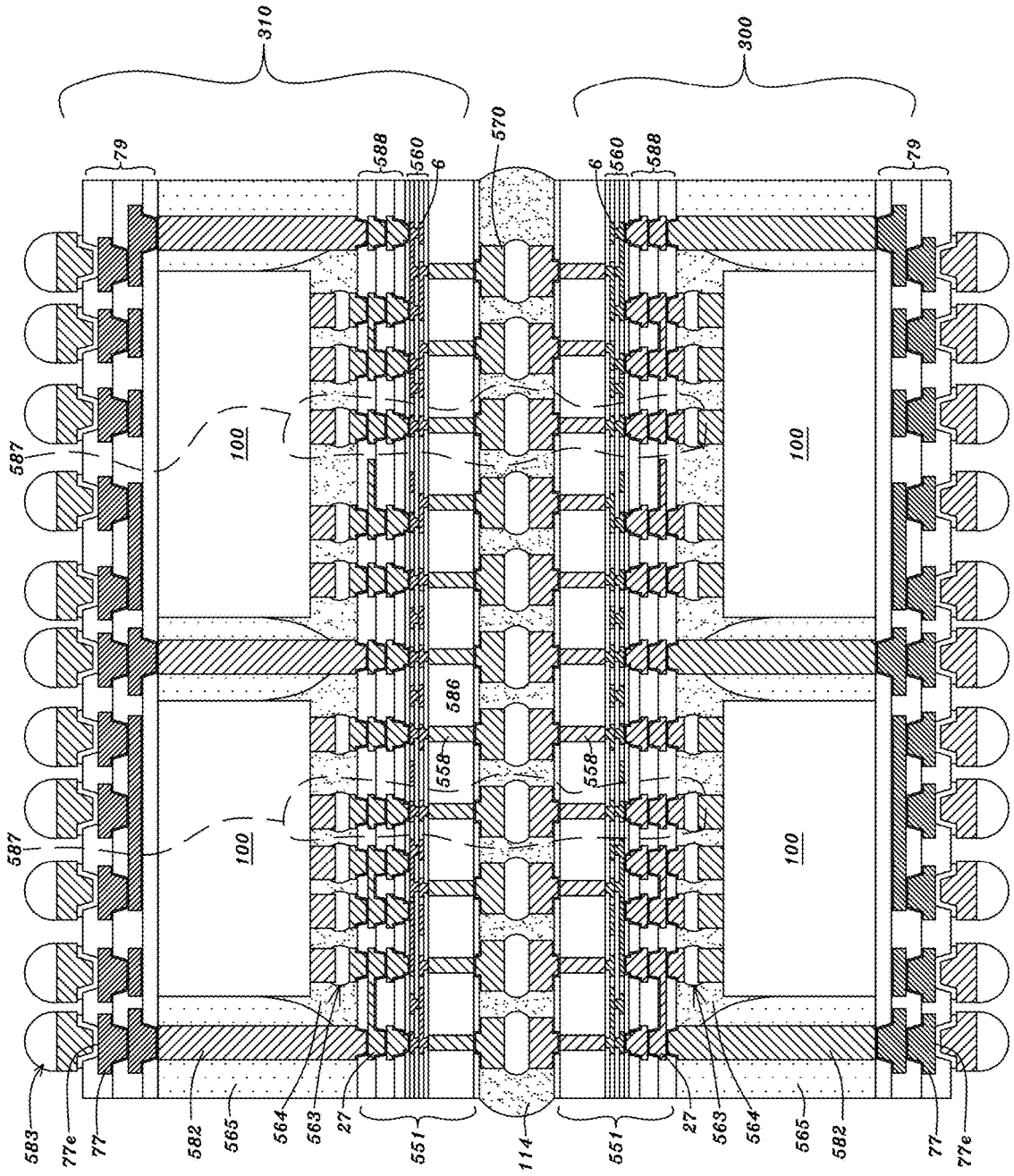

310
300
79
588
560
6
570
587
100
586
558
583
77e
77
582
565
564
563
27
551
114

Fig. 35D

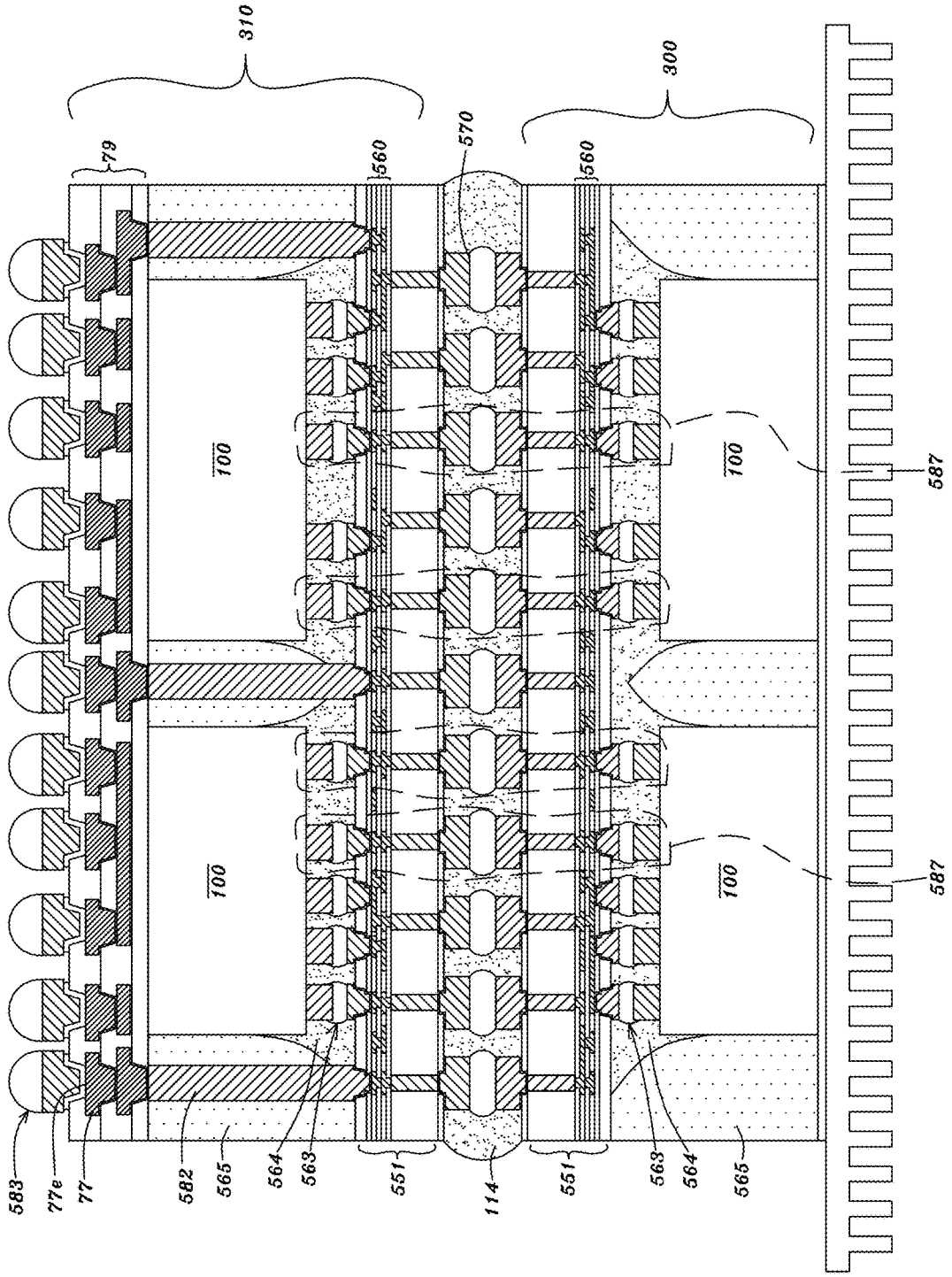

310
300
79
560
570
560
100
100
100
100
587
587
583
77e
77
582
565
564
563
551
114
551
563
564
565

Fig. 35E

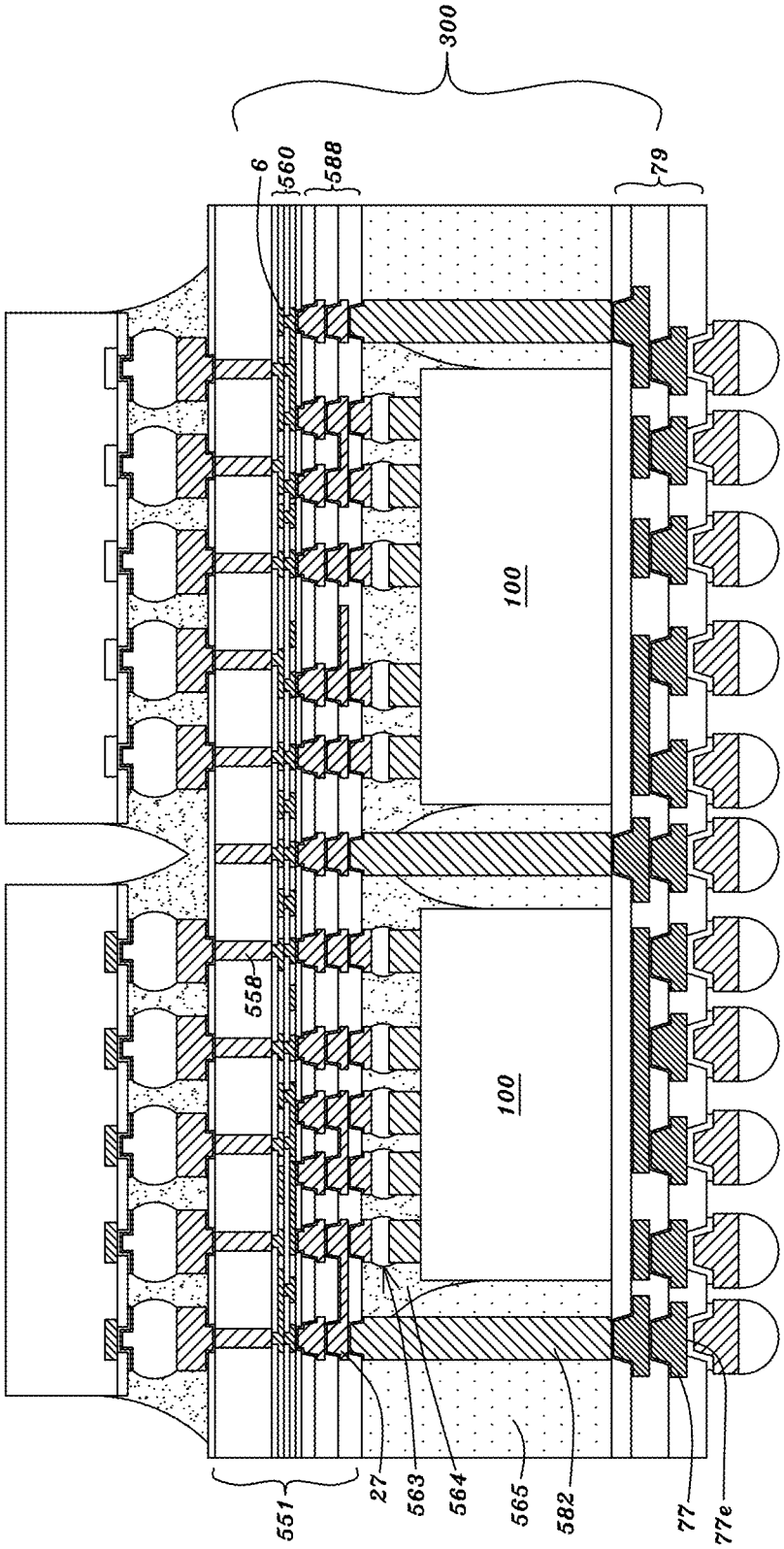


Fig. 35F

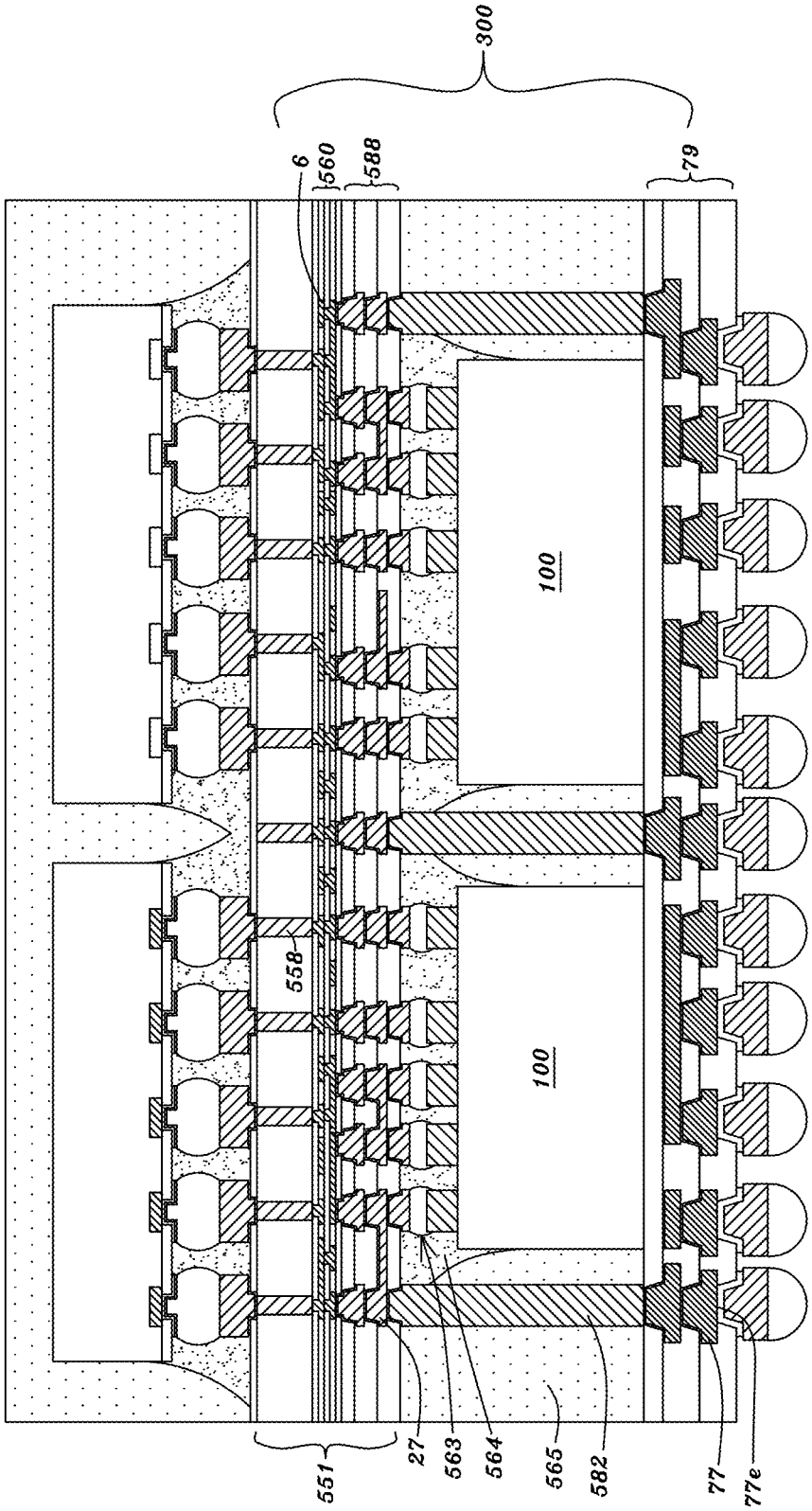


Fig. 35G

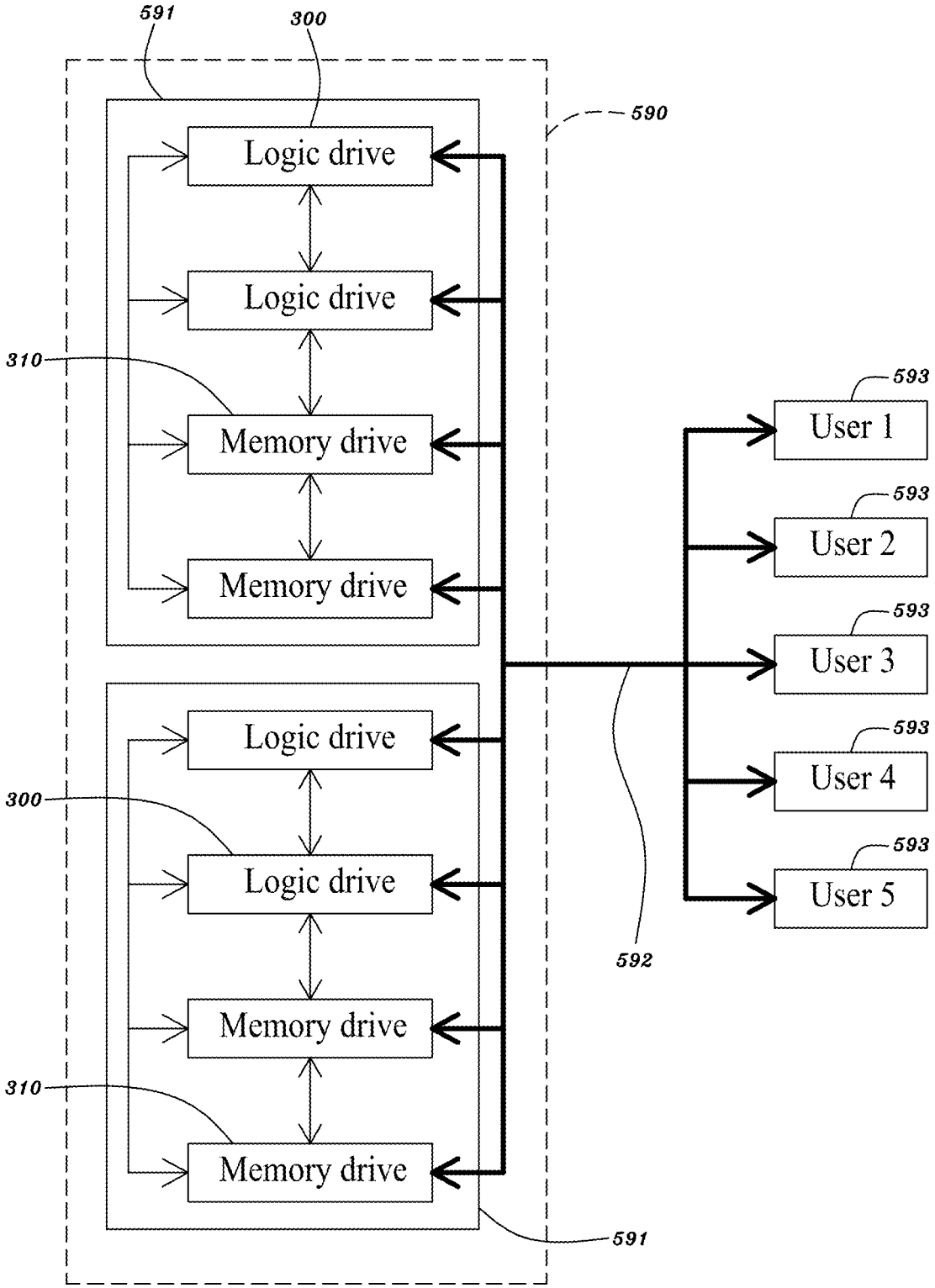

591
300
590
Logic drive
Logic drive
310
Memory drive
Memory drive
593
User 1
593
User 2
593
User 3
593
User 4
593
User 5
Logic drive
300
Logic drive
Memory drive
310
Memory drive
592
591

Fig. 36

LOGIC DRIVE BASED ON STANDARDIZED COMMODITY PROGRAMMABLE LOGIC SEMICONDUCTOR IC CHIPS

PRIORITY CLAIM

This application claims priority benefits from U.S. provisional application No. 62/542,793, filed on Aug. 8, 2017 and entitled "LOGIC DRIVE BASED ON STANDARD COMMODITY FPGA IC CHIPS"; U.S. provisional application No. 62/630,369, filed on Feb. 14, 2018 and entitled "LOGIC DRIVE WITH BRAIN-LIKE PLASTICITY AND INTEGRALITY"; and U.S. provisional application No. 62/675,785, filed on May 24, 2018 and entitled "LOGIC DRIVE WITH BRAIN-LIKE ELASTICITY AND INTEGRALITY". The present application incorporates the foregoing disclosures herein by reference.

BACKGROUND OF THE DISCLOSURE

Field of the Disclosure

The present invention relates to a logic package, logic package drive, logic device, logic module, logic drive, logic disk, logic disk drive, logic solid-state disk, logic solid-state drive, Field Programmable Gate Array (FPGA) logic disk, FPGA logic drive, or programmable logic drive (to be abbreviated as "logic drive" below, that is when "logic drive" is mentioned below, it means and reads as "logic package, logic package drive, logic device, logic module, logic drive, logic disk, logic disk drive, logic solid-state disk, logic solid-state drive, FPGA logic disk, FPGA logic drive, or programmable logic drive") comprising plural programmable logic semiconductor IC chips such as FPGA IC chips, and one or plural non-volatile IC chips for field programming purposes, and more particularly to a standardized commodity logic drive formed by using plural standardized commodity FPGA IC chips and one or plural non-volatile IC chip or chips, and to be used for different specific applications when field programmed or user programmed.

Brief Description of the Related Art

The Field Programmable Gate Array (FPGA) semiconductor integrated circuit (IC) has been used for development of new or innovated applications, or for small volume applications or business demands. When an application or business demand expands to a certain volume and extend to a certain time period, the semiconductor IC suppliers may usually implement the application in an Application Specific IC (ASIC) chip, or a Customer-Owned Tooling (COT) IC chip. The switch from the FPGA design to the ASIC or COT design is because the current FPGA IC chip, for a given application and compared with an ASIC or COT chip, (1) has a larger semiconductor chip size, lower fabrication yield, and higher fabrication cost, (2) consumes more power, (3) gives lower performance. When the semiconductor technology nodes or generations migrate, following the Moore's Law, to advanced nodes or generations (for example below 30 nm or 20 nm), the Non-Recurring Engineering (NRE) cost for designing an ASIC or COT chip increases greatly (more than US $5M or even exceeding US $10M, US $20M, US $50M or US $100M). The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation may be over US $2M, US $5M, or US $10M. The high NRE cost in implementing the innovation or application using the advanced IC technology nodes or generations slows down or even stops the innovation or application using advanced and useful semiconductor technology nodes or generations. A new approach or technology is needed to inspire the continuing innovation and to lower down the barrier for implementing the innovation in the semiconductor IC chips.

SUMMARY OF THE DISCLOSURE

One aspect of the disclosure provides a standardized commodity logic drive in a multi-chip package comprising plural FPGA IC chips and one or more non-volatile memory IC chips for use in different applications requiring logic, computing and/or processing functions by field programming. Uses of the standardized commodity logic drive is analogues to uses of a standardized commodity data storage solid-state disk (drive), data storage hard disk (drive), data storage floppy disk, Universal Serial Bus (USB) flash drive, USB drive, USB stick, flash-disk, or USB memory, and differs in that the latter has memory functions for data storage, while the former has logic functions for processing and/or computing.

Another aspect of the disclosure provides a method to reduce Non-Recurring Engineering (NRE) expenses for implementing an innovation, and to accelerate workload processing or an application in semiconductor IC chips by using the standardized commodity logic drive. A person, user, or developer with an innovation or an application concept or idea or an aim for accelerating workload processing needs to purchase the standardized commodity logic drive and develops or writes software codes or programs to load into the standardized commodity logic drive to implement his/her innovation or application concept or idea. Compared to the implementation by developing a logic ASIC or COT IC chip, the NRE cost may be reduced by a factor of larger than 2, 5, or 10. For advanced semiconductor technology nodes or generations (for example more advanced than or below 30 nm or 20 nm), the NRE cost for designing an ASIC or COT chip increases greatly, more than US $5M or even exceeding US $10M, US $20M, US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation may be over US $2M, US $5M, or US $10M. Implementing the same or similar innovation or application using the logic drive may reduce the NRE cost down to smaller than US $10M or even less than US $5M, US $3M, US $2M or US $1M. The aspect of the disclosure inspires the innovation and lowers the barrier for implementing the innovation in IC chips designed and fabricated using an advanced IC technology node or generation, for example, a technology node or generation more advanced than or below 30 nm, 20 nm or 10 nm.

Another aspect of the disclosure provides a method to change the current logic ASIC or COT IC chip business into a commodity logic IC chip business, like the current commodity DRAM, or commodity flash memory IC chip business, by using the standardized commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standardized commodity logic drive may be better or equal to that of the ASIC or COT IC chip for a same innovation, application or aim for accelerating workload processing, the standardized commodity logic drive may be used as an alternative of designing an ASIC or COT IC chip. The current logic ASIC or COT IC chip design, manufacturing and/or product companies (including fabless IC design and product companies, IC

foundry or contracted manufactures (may be product-less), and/or vertically-integrated IC design, manufacturing and product companies) may become companies like the current commodity DRAM, or flash memory IC chip design, manufacturing, and/or product companies; or like the current DRAM module design, manufacturing, and/or product companies; or like the current flash memory module, flash USB stick or drive, or flash solid-state drive or disk drive design, manufacturing, and/or product companies. The current logic ASIC or COT IC chip design and/or manufacturing companies (including fabless IC design and product companies, IC foundry or contracted manufactures (may be product-less), vertically-integrated IC design, manufacturing and product companies) may become companies in the following business models: (1) designing, manufacturing, and/or selling the standard commodity FPGA IC chips; and/or (2) designing, manufacture, and/or selling the standard commodity logic drives. A person, user, customer, or software developer, or application developer may purchase the standardized commodity logic drive and write software codes to program them for his/her desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (TOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP). The logic drive may be programed to perform functions like a graphic chip, or a baseband chip, or an Ethernet chip, or a wireless (for example, 802.11ac) chip, or an AI chip. The logic drive may be alternatively programmed to perform functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Another aspect of the disclosure provides a method to change the current logic ASIC or COT IC chip hardware business into a software business by using the standardized commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standardized commodity logic drive may be better or equal to that of the ASIC or COT IC chip for a same innovation, application or aim for accelerating workload processing, the standardized commodity logic drive may be used as an alternative of designing an ASIC or COT IC chip. The current ASIC or COT IC chip design companies or suppliers may become software developers or suppliers; they may adapt the following business models: (1) become software companies to develop and sell software for their innovation or application, and let their customers or users to install software in the customers' or users' own standard commodity logic drive; and/or (2) still hardware companies by selling hardware without performing ASIC or COT IC chip design and/or production. In the business model (2), they may install their in-house developed software for the innovation or application in the one or plural non-volatile memory IC chip or chips in the purchased standard commodity logic drive; and sell the program-installed logic drive to their customers or users. In both the business model (1) and (2), the customers/users or developers may write software codes into the standard commodity logic drive (that is, loading the software codes in the non-volatile memory IC chip or chips in or of the standardized commodity logic drive) for their desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, car electronics, Virtual Reality (VR), Augmented Reality (AR), Graphic Processing, Digital Signal Processing, micro controlling, and/or Central Processing. The logic drive may be programed to perform functions like a graphic chip, or a baseband chip, or an Ethernet chip, or a wireless (for example, 802.11ac) chip, or an AI chip. The logic drive may be alternatively programmed to perform functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, car electronics, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Another aspect of the disclosure provides a method to change the current logic ASIC or COT IC chip hardware business into a network business by using the standardized commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standardized commodity logic drive may be better or equal to that of the ASIC or COT IC chip for a same innovation, application or aim for accelerating workload processing, the standardized commodity logic drive may be used as an alternative for designing an ASIC or COT IC chip. The commodity logic drive comprising standard commodity FPGA chips may be used in a data center or cloud in networks for innovation, application or aim for accelerating workload processing. The commodity logic drive attached to the networks may serve to offload and accelerate service-oriented functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Video Streaming, Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP). The commodity logic drive used in the data center or cloud in the networks offers FPGAs as an IaaS (Infrastructure as a Service) resource to cloud users. Using the commodity logic drive in the data center or cloud, users can rent FPGAs of the logic drive, similarly to renting Virtual Memories (VMs) in the cloud. The commodity logic drive used in the data center or cloud is the Virtual Logics (VLs) just like Virtual Memories (VMs).

Another aspect of the disclosure provides a development kit comprising a hardware (the logic drive) and a software (tool) for users or software developers, in addition to current hardware developers, to easily develop their innovated or specific applications by using the standardized commodity logic drive. The software tool provides capabilities for users or software developers to write software using popular, common, or easy-to-learn programming languages, for example, C, Java, C++, C#, Scala, Swift, Matlab, Assembly Language, Pascal, Python, Visual Basic, PL/SQL or JavaScript languages. The users, or software developers may write software codes into the standard commodity logic drive (that is, loading the software codes in the non-volatile memory cells in the one or more non-volatile IC chips in or of the standardized commodity logic drive) for their desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (JOT), industry computing, car electronics, Virtual Reality (VR), Augmented Reality (AR), Graphic Processing, Digital Signal Processing, micro controlling, and/or Central Processing. The logic drive may be programed to perform functions like a graphic chip, or a baseband chip, or an Ethernet chip, or a wireless (for

example, 802.11ac) chip, or an AI chip. The logic drive may be alternatively programmed to perform functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, car electronics, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Another aspect of the disclosure provides a method to change the current system design, manufactures and/or product business into a commodity system/product business, like current commodity DRAM, or flash memory business, by using the standardized commodity logic drive. The system, computer, processor, smart-phone, or electronic equipment or device may become a standard commodity hardware working on hardware comprises mainly a memory drive and a logic drive. The memory drive may be a hard disk drive, a flash drive, a solid-state drive, or a memory drive packaged in a multichip package as disclosed in this invention. The logic drive in the aspect of the disclosure may have big enough or adequate number of inputs/outputs (I/Os) to support I/O ports for used for programming all or most applications. The logic drive may have I/Os to support required I/O ports for programming, for example, to perform all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP), and etc. The logic drive may comprise (1) programing or configuration I/Os for software or application developers to load application software or program codes to program or configure the logic drive, through I/O ports or connectors connecting or coupling to the I/Os of the logic drive; and (2) execution or user I/Os for the users to execute and perform their instructions, through I/O ports or connectors connecting or coupling to the I/Os of the logic drive; for example, generating a Microsoft Word file, or a PowerPoint presentation file, or an Excel file. The I/O ports or connectors connecting or coupling to the corresponding I/Os of the logic drive may comprise one or multiple (2, 3, 4, or more than 4) Universal Serial Bus (USB) ports, one or more IEEE 1394 ports, one or more Ethernet ports, one or more audio ports or serial ports, for example, RS-232 or COM (communication) ports, wireless transceiver I/Os, and/or Bluetooth transceiver I/Os, and etc. The I/O ports or connectors connecting or coupling to the corresponding I/Os of the logic drive may also comprise Serial Advanced Technology Attachment (SATA) ports, or Peripheral Components Interconnect express (PCIe) ports for communicating, connecting or coupling with or to the memory drive. The I/O ports or connectors may be placed, located, assembled, or connected on or to a substrate, film or board; for example, a Printed Circuit Board (PCB), a silicon substrate with interconnection schemes, a metal substrate with interconnection schemes, a glass substrate with interconnection schemes, a ceramic substrate with interconnection schemes, a flexible film with interconnection schemes. The logic drive is assembled on the substrate, film or board using solder bumps, copper pillars or bumps, or gold bumps, on or of the logic drive, similar to the flip-chip assembly of the chip packaging technology, or the Chip-On-Film (COF) assembly technology used in the LCD driver packaging technology. The system, computer, processor, smart-phone, or electronic equipment or device design, manufacturing, and/or product companies may become companies to (1) design, manufacturing and/or sell the standard commodity hardware comprising mainly memory drives and logic drives; in this case, the companies are still hardware companies; (2) develop system and application software for users to install in the users' own standard commodity hardware; in this case, the companies become software companies; (3) install the third party's developed system and application software or programs in the standard commodity hardware and sell the software-loaded hardware; and in this case, the companies are still hardware companies.

Another aspect of the disclosure provides a "public innovation platform" for innovators to easily and cheaply implement or realize their innovation in semiconductor IC chips using advanced IC technology nodes more advanced than 28 nm, for example, 20 nm, 16 nm, 10 nm, 7 nm, 5 nm or 3 nm IC technology nodes. In early days, 1990's, innovators could implement their innovation by designing IC chips and fabricate the IC chips in a semiconductor foundry fab using technology nodes at 1 nm, 0.8 nm, 0.5 nm, 0.35 nm, 0.18 nm or 0.13 nm, at a (NRE) cost of about several hundred thousands of US dollars. The IC foundry fab was then the "public innovation platform". However, when IC technology nodes migrate to a technology node more advanced than 28 nm, for example, 20 nm, 16 nm, 10 nm, 7 nm, 5 nm or 3 nm IC technology nodes, only a few giant system or IC design companies, not the public innovators, can afford to use the semiconductor IC foundry fab. It costs about or over 10 million US dollars to develop and implement an IC chip using these advanced technology nodes. The semiconductor IC foundry fab is now not "public innovation platform" anymore, they are "club innovation platform" for very few club innovators. The concept of the disclosed logic drives, comprising standard commodity FPGA IC chips, provides "public innovation platform" back to public innovators in semiconductor IC industry again; just as in 1990's. The innovators can implement or realize their innovation by using logic drives and writing software programs in common programing languages, for example, C, Java, C++, C#, Scala, Swift, Matlab, Assembly Language, Pascal, Python, Visual Basic, PL/SQL or JavaScript languages, at cost of less than 500K or 300K US dollars. The innovators can use their own commodity logic drives or they can rent logic drives in data centers or clouds through networks.

Another aspect of the disclosure provides an innovation platform for an innovator, comprising: multiple logic drives in a data center or a cloud, wherein multiple logic drives comprise multiple standard commodity FPGA IC chips fabricated using a semiconductor IC process technology node more advanced 28 nm technology node; an innovator's device and multiple users' devices communicating with the multiple logic drives in the data center or the cloud through an internet or a network, wherein the innovator develops and writes software programs to implement his/her innovation in a common programing language to program, through the internet or the network, the multiple logic drives in the data center or the cloud, wherein the common programing language comprises Java, C++, C#, Scala, Swift, Matlab, Assembly Language, Pascal, Python, Visual Basic, PL/SQL or JavaScript language; after programming the logic drives, the innovator or the multiple users may use the programed logic drives for his/her or their applications through the internet or the network.

Another aspect of the disclosure provides a standard commodity FPGA IC chip for use in the standard commodity logic drive. The standard commodity FPGA IC chip is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm,

20 nm or 10 nm; with a chip size and manufacturing yield optimized with the minimum manufacturing cost for the used semiconductor technology node or generation. The standard commodity FPGA IC chip may have an area between 400 mm^2 and 9 mm^2, 225 mm^2 and 9 mm^2, 144 mm^2 and 16 mm^2, 100 mm^2 and 16 mm^2, 75 mm^2 and 16 mm^2, or 50 mm^2 and 16 mm^2. Transistors used in the advanced semiconductor technology node or generation may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET. The standard commodity FPGA IC chip may only communicate directly with other chips in or of the logic drive only; its I/O circuits may require only small I/O drivers or receivers, and small or none Electrostatic Discharge (ESD) devices. The driving capability, loading, output capacitance, or input capacitance of I/O drivers or receivers, or I/O circuits may be between 0.1 pF and 10 pF, 0.1 pF and 5 pF, 0.1 pF and 3 pF or 0.1 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF. The size of the ESD device may be between 0.05 pF and 10 pF, 0.05 pF and 5 pF, 0.05 pF and 2 pF or 0.05 pF and 1 pF; or smaller than 5 pF, 3 pF, 2 pF, 1 pF or 0.5 pF. For example, a bi-directional (or tri-state) I/O pad or circuit may comprise an ESD circuit, a receiver, and a driver, and has an input capacitance or output capacitance between 0.1 pF and 10 pF, 0.1 pF and 5 pF or 0.1 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF. All or most control and/or Input/Output (I/O) circuits or units (for example, the off-logic-drive I/O circuits, i.e., large I/O circuits, communicating with circuits or components external or outside of the logic drive) are outside of, or not included in, the standard commodity FPGA IC chip, but are included in another dedicated control chip, dedicated I/O chip, or dedicated control and I/O chip, packaged in the same logic drive. None or minimal area of the standard commodity FPGA IC chip is used for the control or I/O circuits, for example, less than 15%, 10%, 5%, 2%, 1%, 0.5% or 0.1% area is used for the control or I/O circuits; or, none or minimal transistors of the standard commodity FPGA IC chip are used for the control or I/O circuits, for example, less than 15%, 10%, 5%, 2%, 1%, 0.5% or 0.1% of the total number of transistors are used for the control or I/O circuits; or all or most area of the standard commodity FPGA IC chip is used for (i) logic blocks comprising logic gate arrays, computing units or operators, and/or Look-Up-Tables (LUTs) and multiplexers, and/or (ii) programmable interconnection. For example, greater than 85%, 90%, 95%, 98%, 99%, 99.5% or 99.9% area is used for logic blocks, and/or programmable interconnection; or, all or most transistors of the standard commodity FPGA IC chip are used for logic blocks, and/or programmable interconnection, for example, greater than 85%, 90%, 95%, 98%, 99%, 99.5% or 99.9% of the total number of transistors are used for logic blocks, and/or programmable interconnection.

The logic blocks comprise (i) logic gate arrays comprising Boolean logic operators, for example, NAND, NOR, AND, and/or OR circuits; (ii) computing units comprising, for examples, adder, multiplication, and/or division circuits; (iii) Look-Up-Tables (LUTs) and multiplexers. The Boolean operators, the functions of logic gates, or computing, operations or processes may be carried out using the programmable wires or lines (the programmable metal interconnection wires or lines) on the FPGA IC chip; while certain Boolean operators, logic gates, or certain computing, operations or processes may be carried out using the fixed wires or lines (the metal interconnection wires or lines) on the FPGA IC chip. For example, the adder and/or multiplier may be designed and implemented by the fixed wires or lines (the fixed metal interconnection wires or lines) on the FPGA IC chip, for interconnecting logic circuits of the adder and/or multiplier. Alternatively, the Boolean operators, the functions of logic gates, or computing, operations or processes may be carried out using, for example, Look-Up-Tables (LUTs) and/or multiplexers. The LUTs store or memorize the processing or computing results of logic gates, computing results of calculations, decisions of decision-making processes, or results of operations, events or activities. The LUTs may store or memorize data or results in, for example, SRAM cells. The SRAM cells may be distributed over all locations in the FPGA chip, and are nearby or close to their corresponding multiplexers in the logic blocks. Alternatively, the SRAM cells may be located in a SRAM array, in a certain area or location of the FPGA chip; wherein the SRAM cell array aggregates or comprises multiple of the SRAM cells of LUTs for the selection multiplexers in logic blocks in the distributed locations. Alternatively, the SRAM cells may be located in one of multiple SRAM arrays, in multiple certain areas of the FPGA chip; each of the SRAM arrays aggregates or comprises multiple of the SRAM cells of LUTs for the selection multiplexers in logic blocks in the distributed locations. The data stored or latched in each of SRAM cells are input to the multiplexer for selection. Each of the SRAM cells may comprise 6 Transistors (6T SRAM), with 2 transfer (write) transistors and 4 data-latch transistors, wherein the two transfer transistors are used for writing the data into the storage or latched nodes of the 4 data-latch transistors. Alternatively, each of the SRAM cells may comprise 5 Transistors (5T SRAM), with 1 transfer (write) transistor and 4 data-latch transistors; wherein the transfer transistor is used for writing the data into the two storage or latched nodes of the 4 data-latch transistors. One of the two latched nodes of the 4 latch transistors in the 5T or 6T SRAM cell is connected or coupled to the multiplexer. The stored data in the 5T or 6T SRAM cell is used for LUTs. When inputting a set of data, requests or conditions, a multiplexer is used to select the corresponding data (or results) stored or memorized in the LUTs, based on the inputted set of data, requests or conditions. As an example, a 4-input NAND gate may be implemented using an operator comprising LUTs and multiplexers as described below: There are 4 inputs for a 4-input NAND gate, and 16 (2^4) possible corresponding outputs (results) of the 4-input NAND gate. An operator, used to carry out the 4-input NAND operation using LUTs and multiplexers, comprises (i) 4 inputs, (ii) a LUT for storing and memorizing the 16 possible corresponding outputs (results), (iii) a multiplexer designed and used for selecting the right (corresponding) output from the 16 possible corresponding results, based on the given 4 input data set (for example, 1, 0, 0, 1), and (iv) an output. In general, an operator comprises n inputs, a LUT for storing or memorizing 2^n corresponding data or results, a multiplexer for selecting the right (corresponding) output from the 2^n possible corresponding results, based on the given n input data set, and 1 output.

The programmable interconnections of the standard commodity FPGA chip comprise cross-point switches, each in the middle of interconnection metal lines or traces. For example, n metal lines or traces are connected to the input terminals of a cross-point switch, and m metal lines or traces are connected to the output terminals of the cross-point switch, and the cross-point switch is located between the n metal lines or traces and the m metal lines and traces. The cross-point switch is designed such that each of the n metal

lines or traces may be programed to connect to anyone of the m metal lines or traces. The cross-point switch may comprise, for example, a pass/no-pass circuit comprising a n-type and a p-type transistor, in pair, wherein one of then metal lines or traces are connected to the connected source terminals of the n-type and p-type transistor pairs in the pass-no-pass circuit, while one of the m metal lines and traces are connected to the connected drain terminal of the n-type and p-type transistor pairs in the pass-no-pass circuit. The connection or disconnection (pass or no pass) of the cross-point switch is controlled by the data (1 or 0) stored or latched in a SRAM cell. The SRAM cell may be distributed over all in the FPGA chip, and is nearby or close to the corresponding switch. Alternatively, the SRAM cell may be located in a SRAM array, in a certain area or location of the FPGA chip; wherein the SRAM cell array aggregates or comprises multiple of the SRAM cells for controlling their corresponding cross-point switches in the distributed locations. Alternatively, the SRAM cell may be located in one of multiple SRAM arrays, in multiple certain areas or locations of the FPGA chip; each of the SRAM arrays aggregates or comprises multiple of the SRAM cells for controlling cross-point switches in the distributed locations. The (control) gates of both n-type and p-type transistors in the cross-point switch are connected to the two storage or latch nodes, respectively, of the SRAM cell. Each of the SRAM cells may comprise 6 Transistors (6T SRAM), with 2 transfer (write) transistors and 4 data-latch transistors, wherein the two transfer transistors are used for writing the programing code or data into the two storage nodes of the 4 data-latch transistors. Alternatively, each of the SRAM cells may comprise 5 Transistors (5T SRAM), with 1 transfer (write) transistor and 4 data-latch transistors, wherein the transfer transistor is used for writing the programing code or data into the two storage nodes of the 4 data-latch transistors. The two storage nodes of the 4 latch transistors in the 5T or 6T SRAM cell are connected to the gate of the n-type transistor and the gate of the p-type transistor, respectively, in the pass-no-pass switch circuit. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection of the two metal lines or traces connected to the terminals of the cross-point switch. When the data latched in the two storage nodes of the 5T or 6T SRAM cell is programmed at [1, 0], (may be defined as "1" for the data stored in the SRAM cell), the node of 1 is connected to the gate of the n-type transistor, and the node of 0 is connected to the gate of the p-type transistor; therefore, the pass/no-pass circuit is on, and the two metal lines or traces connected to the two terminals of the pass-no-pass switch circuit are connected. While the data latched in the two storage nodes of the 5T or 6T SRAM cell is programmed at [0, 1], (may be defined as "0" for the data stored in the SRAM cell), the node of 0 is connected to the gate of the n-type transistor, and the node of 1 is connected to the gate of the p-type transistor; therefore, the pass/no-pass switch circuit is off, and the two metal lines or traces connected to the two terminals of the pass/no-pass switch circuit are dis-connected. Since the standard commodity FPGA IC chip comprises mainly the regular and repeated gate arrays or blocks, LUTs and multiplexers, or programmable interconnection, just like standard commodity DRAM, or NAND flash IC chips, the manufacturing yield may be very high, for example, greater than 70%, 80%, 90% or 95% for a chip area greater than, for example, 50 mm^2, or 80 mm^2.

Alternatively, each of the cross-point switches may comprise, for example, a pass/no-pass circuit comprising a switching buffer, wherein the switching buffer comprises two-stages of inverters (buffer), a control N-MOS, and a control P-MOS. Wherein one of the n metal lines or traces is connected to the common (connected) gate terminal of an input-stage inverter of the buffer in the pass-no-pass circuit, while one of the m metal lines and traces is connected to the common (connected) drain terminal of output-stage inverter of buffer in the pass-no-pass circuit. The output-stage inverter is stacked with the control P-MOS at the top (between V_{cc} and the source of the P-MOS of the output-stage inverter) and the control N-MOS at the bottom (between V_{ss} and the source of the N-MOS of the output-stage inverter). The connection or disconnection (pass or no pass) of the cross-point switch is controlled by the data (0 or 1) stored in a 5T or 6T SRAM cell. The 5T or 6T SRAM cells may be distributed over all locations in the FPGA chip, and each of the 5T or 6T SRAM cells is nearby or close to its corresponding cross-point switch. Alternatively, the 5T or 6T SRAM cell may be located in a 5T or 6T SRAM cell array, in a certain area or location of the FPGA chip; wherein the 5T or 6T SRAM cell array aggregates or comprises multiple of the 5T or 6T SRAM cells for controlling their corresponding cross-point switches in the distributed locations. Alternatively, the 5T or 6T SRAM cell may be located in one of multiple 5T or 6T SRAM cell arrays, in multiple certain areas or locations of the FPGA chip; each of the 5T or 6T SRAM cell arrays aggregates or comprises multiple of the 5T or 6T SRAM cells for controlling their cross-point switches in the distributed locations. The gates of both control N-MOS and the control P-MOS transistors in the cross-point switch are connected or coupled to the two latched nodes, respectively, of the 5T or 6T SRAM cell. One latched node of the 5T or 6T SRAM cell is connected or coupled to the gate of the control N-MOS transistor in the switching buffer circuit, while the other latched node of the 5T or 6T SRAM cell is connected or coupled to the gate of the control P-MOS transistor in the switch buffer circuit. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection of the two metal lines or traces connected to the terminals of the cross-point switch. When the data stored in the 5T or 6T SRAM cell is programmed at 1, the latched node of 1 is connected to the gate of the control N-MOS transistor, and the other latched node of 0 is connected to the gate of the control P-MOS transistor; therefore, the pass/no-pass circuit (the switching buffer) passes the data from input to the output. In other words, the two metal lines or traces connected to the two terminals of the pass-no-pass switch circuit are (virtually) connected. While the data stored in the 5T or 6T SRAM cell is programmed at 0, the latched node of 0 is connected to the gate of the control N-MOS transistor, and the other latched node of 1 is connected to the gate of the control P-MOS transistor; therefore, both the control N-MOS and control P-MOS transistors are off. The data cannot be transferred from the input to the output, and the two metal lines or traces connected to the two terminals of the pass/no-pass switch circuit are dis-connected.

Alternatively, the cross-point switches may comprise, for example, multiplexers and switch buffers. A multiplexer of a cross-point switch selects one of then inputting data from the n inputting metal lines based on the data stored in the 5T or 6T SRAM cells; and outputs the selected one of inputs to a switch buffer. The switch buffer passes or does not pass the output data from the multiplexer to one metal line connected to the output of the switch buffer based on the data stored in the 5T or 6T SRAM cells. The switch buffer comprises two-stages of inverters (buffer), a control N-MOS, and a control P-MOS. Wherein the selected data from the multi-

plexer is connected to the common (connected) gate terminal of input-stage inverter of the buffer, while one of them metal lines or traces is connected to the common (connected) drain terminal of output-stage inverter of the buffer. The output-stage inverter is stacked with the control P-MOS at the top (between V_{cc} and the source of the P-MOS of the output-stage inverter) and the control N-MOS at the bottom (between V. and the source of the N-MOS of the output-stage inverter). The connection or disconnection of the switch buffer is controlled by the data (0 or 1) stored in the 5T or 6T SRAM cell. One latched node of the 5T or 6T SRAM cell is connected or coupled to the gate of the control N-MOS transistor in the switch buffer circuit, and the other latched node of the 5T or 6T SRAM cell is connected or coupled to the gate of the control P-MOS transistor in the switch buffer circuit. For example, two metal lines A and B are crossed at a point, and segmenting metal line A into two segments, A_1 and A_2, and metal line B into two segments, B_1 and B_2. The cross-point switch is located at the cross point. The cross-point switch comprises 4 pairs of multiplexers and switch buffers. Each of the multiplexer has 3 inputs and 1 output, that is, each multiplexer selects one from the 3 inputs as the output, based on 2 bits of data stored in two (the first and second) of the 5T or 6T SRAM cells. Each of the switch buffers receives the output data from the corresponding multiplexer and decides to pass or not to pass the selected data, based on the 3rd bit of data stored in the 3rd 5T or 6T SRAM cell. The cross-point switch is located between segments A_1, A_2, B_1 and B_2, and comprises 4 pairs of multiplexers/switch buffers: (1) The 3 inputs of a first multiplexer may be A_1, B_1 and B_2. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 0 for the multiplexer, the A_1 segment is selected by the first multiplexer. The A_1 segment is connected to the input of a first switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the first switch buffer, the data of A_1 segment is passing to the A_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the first switch buffer, the data of A_1 segment is not passing to the A_1 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 1 and 0 for the first multiplexer, the B_1 segment is selected by the first multiplexer. The B_1 segment is connected to the input of the first switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the first switch buffer, the data of B_1 segment is passing to the A_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the first switch buffer, the data of B_1 segment is not passing to the A_2 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 1 for the first multiplexer, the B_2 segment is selected by the first multiplexer. The B_2 segment is connected to the input of the first switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the first switch buffer, the data of B_2 segment is passing to the A_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the first switch buffer, the data of B_2 segment is not passing to the A_2 segment. (2) The 3 inputs of a second multiplexer may be A_2, B_1 and B_2. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 0 for the second multiplexer, the A_2 segment is selected by the second multiplexer. The A_2 segment is connected to the input of a second switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the second switch buffer, the data of A_2 segment is passing to the A_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the second switch buffer, the data of A_2 segment is not passing to the A_1 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 1 and 0 for the second multiplexer, the B_1 segment is selected by the second multiplexer. The B_1 segment is connected to the input of the second switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the second switch buffer, the data of B_1 segment is passing to the A_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the second switch buffer, the data of B_1 segment is not passing to the A_1 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 1 for the second multiplexer, the B_2 segment is selected by the second multiplexer. The B_2 segment is connected to the input of the second switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the second switch buffer, the data of B_2 segment is passing to the A_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the second switch buffer, the data of B_2 segment is not passing to the A_1 segment (3) The 3 inputs of a third multiplexer may be A_1, A_2 and B_2. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 0 for the third multiplexer, the A_1 segment is selected by the third multiplexer. The A_1 segment is connected to the input of a third switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the third switch buffer, the data of A_1 segment is passing to the B_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the third switch buffer, the data of A_1 segment is not passing to the B_1 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 1 and 0 for the third multiplexer, the A_2 segment is selected by the third multiplexer. The A_2 segment is connected to the input of the third switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the third switch buffer, the data of A_2 segment is passing to the B_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the third switch buffer, the data of A_2 segment is not passing to the B_1 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 1 for the third multiplexer, the B_2 segment is selected by the third multiplexer. The B_2 segment is connected to the input of the third switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the third switch buffer, the data of B_2 segment is passing to the B_1 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the third switch buffer, the data of B_2 segment is not passing to the B_1 segment. (4) The 3 inputs of a fourth multiplexer may be A_1, A_2 and B_1. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 0 for the fourth multiplexer, the A_1 segment is selected by the fourth multiplexer. The A_1 segment is connected to the input of a fourth switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the fourth switch buffer, the data of A_1 segment is passing to the B_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the fourth switch buffer, the data of A_1 segment is not passing to the B_2 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 1 and 0 for the fourth multiplexer, the A_2 segment is selected by the fourth multiplexer. The A_2 segment is connected to the input of the fourth switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the fourth switch buffer, the data of A_2 segment is passing to the B_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the fourth switch buffer, the data of A_2 segment is not passing to the B_2 segment. If the 2 bits stored in the 5T or 6T SRAM cells are 0 and 1 for the fourth multiplexer, the B_1 segment is selected by the fourth multiplexer. The B_1 segment is connected to the input of the fourth switch buffer. If the data bit stored in the 5T or 6T SRAM cell is 1 for the fourth switch buffer, the data of B_1 segment is passing to the B_2 segment. If the data bit stored in the 5T or 6T SRAM cell is 0 for the fourth switch buffer, the data of B_1 segment is not passing to the B_2 segment. In this case, the cross-point switch is bi-directional; there are 4 pairs of multiplexers/switch buffers, each pair of the multiplexers/switch buffers is controlled by three bits of the three 5T or 6T SRAM cells. Totally, 12 bits of the

twelve 5T or 6T SRAM cells are required for the cross-point switch. The 5T or 6T SRAM cell may be distributed over all locations in the FPGA chip, and each of the 5T or 6T SRAM cells is nearby or close to its corresponding multiplexers and/or cross-point switch buffers. Alternatively, the 5T or 6T SRAM cell may be located in a 5T or 6T SRAM cell array, in a certain area or location of the FPGA chip; wherein the 5T or 6T SRAM cell array aggregates or comprises multiple of the 5T or 6T SRAM cells for controlling their corresponding multiplexers and/or switch buffers of the crop-point switches in the distributed locations. Alternatively, the 5T or 6T SRAM cell may be located in one of multiple 5T or 6T SRAM cell arrays, in multiple certain areas or locations of the FPGA chip; each of the 5T or 6T SRAM cell arrays aggregates or comprises multiple of the 5T or 6T SRAM cells for controlling multiplexers and/or switch buffers of the cross-point switches in the distributed locations.

The programmable interconnections of the standard commodity FPGA chip comprise a multiplexer in the middle of interconnection metal lines or traces. The multiplexer selects from n metal interconnection lines connected to the n inputs of the multiplexer, and coupled or connected to one metal interconnection line connected to the output of the multiplexer, based on the data stored or programmed in the 5T or 6T SRAM cells. For example, n=16, 4 bits of the 5T or 6T SRAM cells are required to select any one of the 16 metal interconnection lines connected to the 16 inputs of the multiplexer, and couple or connect the selected one to one metal interconnection line connected to the output of the multiplexer. The data from the selected one of 16 inputs is therefore coupled, passed, or connected to the metal line connected to the output of the multiplexer.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising plural standard commodity FPGA IC chips and one or more non-volatile memory IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming, wherein the plural standard commodity FPGA IC chips, each is in a bare-die format or in a single-chip or multi-chip package. Each of the plural standard commodity FPGA IC chips may have standard common features or specifications; (1) the logic block count, or operator count, or gate count, or density, or capacity or size: The logic block count or operator count may be greater than or equal to 16K, 64K, 256K, 512K, 1M, 4M, 16M, 64M, 256M, 1G, or 4G logic block counts or operator counts. The logic gate count may be greater than or equal to 64K, 256K, 512K, 1M, 4M, 16M, 64M, 256M, 1G, 4G or 16G logic gate counts; (2) the number of inputs to each of the logic blocks or operators: the number of inputs to each of the logic block or operator may be greater or equal to 4, 8, 16, 32, 64, 128, or 256; (3) the power supply voltage: the voltage may be between 0.2V and 2.5V 0.2V and 2V 0.2V and 1.5V 0.1V and 1V, or 0.2V and 1V, or, smaller or lower than or equal to 2.5V 2V 1.8V, 1.5V or 1V; (4) the I/O pads, in terms of layout, location, number and function. Since the FPGA chips are standard commodity IC chips, the number of FPGA chip designs or products is reduced to a small number, therefore, the expensive photo masks or mask sets for fabricating the FPGA chips using advanced semiconductor nodes or generations are reduced to a few mask sets. For example, reduced down to between 3 and 20 mask sets, 3 and 10 mask sets, or 3 and 5 mask sets for a specific technology node or generation. The NRE and production expenses are therefore greatly reduced. With the few designs and products, the manufacturing processes may be tuned or optimized for the few chip designs or products, and resulting in very high manufacturing chip yields. This is similar to the current advanced standard commodity DRAM or NAND flash memory design and production. Furthermore, the chip inventory management becomes easy, efficient and effective; therefore, resulting in a shorter FPGA chip delivery time and becoming very cost-effective.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising the plural standard commodity FPGA IC chips and one or more non-volatile memory IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming, wherein the plural standard commodity FPGA IC chips, each is in a bare-die format or in a single-chip or multi-chip package. Each of the plural standard commodity FPGA IC chips may have standard common features or specifications as described and specified above. Similar to the standard DRAM IC chips for use in a DRAM module, the standard commodity FPGA IC chips, each chip may further comprise some additional (common, standard) I/O pins or pads, for example: (1) one chip enable pin, (2) one input enable pin, (3) one output enable pin, (4) two input selection pins and/or (5) two output selection pins. Each of the plural standard commodity FPGA IC chips may comprise a standard set of I/O ports, for example, 4 I/O ports, and each I/O port may comprise 64 bi-directional I/O circuits.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising the plural standard commodity FPGA IC chips and one or more non-volatile memory IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming, wherein the plural standard commodity FPGA IC chips, each is in a bare-die format or in a single-chip or multi-chip package. Each of the plural standard commodity FPGA IC chips may have standard common features or specifications as described and specified above. Each of the plural standard commodity FPGA IC chip may comprise multiple logic blocks, wherein each logic block may comprise, for example, (1) 1 to 16 of 8-by-8 adders, (2) 1 to 16 of 8-by-8 multipliers, (3) 256 to 2K of logic cells, wherein each logic cell comprises 1 register and 1 to 4 of LUTs (Look-Up-Tables), wherein each LUT comprises 4 to 256 bits of data or information. The above 1 to 16 of 8-by-8 adders and/or 1 to 16 of 8-by-8 multipliers may be designed and formed by fixed metal wires or lines (metal interconnection wires or lines) on each of the FPGA IC chips.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising plural standard commodity FPGA IC chips and one or more non-volatile memory IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming, wherein the plural standard commodity FPGA IC chips, each is in a bare-die format or in a single-chip or multi-chip package format. The standard commodity logic drive may have standard common features or specifications; (1) the logic block count, or operator count, or gate count, or density, or capacity or size of the standard commodity logic drive: The logic block count or operator count may be greater than or equal to 32K, 64K, 256K, 512K, 1M, 4M, 16M, 64M, 256M, 1G, 4G, 8G or 16G logic block counts or operator counts. The logic gate count may be greater than or equal to 128K, 256K, 512K, 1M, 4M, 16M, 64M, 256M, 1G, 4G, 8G, 16G, 32G or 64G logic gate counts; (2) the power supply voltage: the voltage may be between 0.2V and 12V, 0.2V and 10V, 0.2V and 7V 0.2V and 5V 0.2V and 3V 0.2V and 2V 0.2V and 1.5V, or

0.2V and 1V; (3) the I/O pads in the multi-chip package of the standard commodity logic drive in terms of layout, location, number and function of I/O pads: the logic drive may comprise the I/O pads, metal pillars or bumps connecting or coupling to one or multiple (2, 3, 4, or more than 4) Universal Serial Bus (USB) ports, one or more IEEE 1394 ports, one or more Ethernet ports, one or more audio ports or serial ports, for example, RS-232 or COM (communication) ports, wireless transceiver I/Os, and/or Bluetooth transceiver I/Os, and/or etc. The logic drive may also comprise the I/O pads, metal pillars or bumps connecting or coupling to Serial Advanced Technology Attachment (SATA) ports, or Peripheral Components Interconnect express (PCIe) ports for communicating, connecting or coupling with the memory drive. Since the logic drives are standard commodity products, the product inventory management becomes easy, efficient and effective, therefore resulting in a shorter logic drive delivery time and becoming cost-effective.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package further comprising a dedicated control chip. The dedicated control chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm. Alternatively, advanced semiconductor technology nodes or generations may be used for the dedicated control chip; for example, a semiconductor node or generation more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm. The semiconductor technology node or generation used in the dedicated control chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the dedicated control chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the dedicated control chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the dedicated control chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the dedicated control chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. The dedicated control chip provides control functions of: (1) downloading programing codes from outside (of the logic drive) to the non-volatile IC chips in the logic drive; (2) downloading the programing codes from the non-volatile IC chips in the logic drive to the 5T or 6T SRAM cells of the programmable interconnection on the standard commodity FPGA chips. Alternatively, the programming codes from the non-volatile IC chips in the logic drive may go through a buffer or driver in or of the dedicated control chip before getting into the 5T or 6T SRAM cells of the programmable interconnection on the standard commodity FPGA chips. The buffer in or of the dedicated control chip may latch the data from the non-volatile chips and increase the bit-width of the data. For example, the data bit-width (in a SATA standard) from the non-volatile chips is 1 bit, the buffer may latch the 1 bit data in each of the multiple SRAM cells in the buffer, and output the data stored or latched in the multiple SRAM cells in parallel and simultaneously to increase the data bit-width; for example, equal to or greater than 4, 8, 16, 32, or 64 data bit-width. For another example, the data bit-width (in a PCIe standard) from the non-volatile chips is 32 bit, the buffer may increase the data bit-width to equal to or greater than 64, 128, or 256 data bit-width. The driver in or of the dedicated control chip may amplify the data signals from the non-volatile chips; (3) inputting/outputting signals for a user application; (4) power management; (5) downloading data from the non-volatile IC chips in the logic drive to the 5T or 6T SRAM cells of the LUTs on the standard commodity FPGA chips. Alternatively, the data from the non-volatile IC chips in the logic drive may go through a buffer or driver in or of the dedicated control chip before getting into the 5T or 6T SRAM cells of LUTs on the standard commodity FPGA chips. The buffer in or of the dedicated control chip may latch the data from the non-volatile chips and increase the bit-width of the data. For example, the data bit-width (in a SATA standard) from the non-volatile chips is 1 bit, the buffer may latch the 1 bit data in each of the multiple SRAM cells in the buffer, and output the data stored or latched in the multiple SRAM cells in parallel and simultaneously to increase the data bit-width; for example, equal to or greater than 4, 8, 16, 32, or 64 data bit-width. For another example, the data bit-width (in a PCIe standard) from the non-volatile chips is 32 bit, the buffer may increase the data bit-width to equal to or greater than 64, 128, or 256 data bit-width. The driver in or of the dedicated control chip may amplify the data signals from the non-volatile chips.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package further comprising a dedicated I/O chip. The dedicated I/O chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm. The semiconductor technology node or generation used in the dedicated I/O chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the dedicated I/O chip may be a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the dedicated I/O chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the dedicated I/O chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the dedicated I/O chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. The power supply voltage used in the dedicated I/O chip may be greater than or equal to 1.5V, 2.0 V 2.5V, 3 V, 3.5V, 4V, or 5V, while the power supply voltage used in the standard commodity FPGA IC chips packaged in the same logic drive may be smaller than or equal to 2.5V, 2V, 1.8V, 1.5V, or 1 V. The power supply voltage used in the dedicated I/O chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the dedicated I/O chip may use a power supply of 4V, while the standard commodity FPGA IC chips packaged in the same logic drive may use a power supply voltage of 1.5V; or the dedicated I/O chip may use a power supply of 2.5V, while the standard commodity FPGA IC chips packaged in the same logic drive may use a power supply of 0.75V. The gate oxide (physical)

thickness of the Field-Effect-Transistors (FETs) may be thicker than or equal to 5 nm, 6 nm, 7.5 nm, 10 nm, 12.5 nm, or 15 nm, while the gate oxide (physical) thickness of FETs used in the standard commodity FPGA IC chips packaged in the same logic drive may be thinner than 4.5 nm, 4 nm, 3 nm or 2 nm. The gate oxide (physical) thickness of FETs used in the dedicated I/O chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the dedicated I/O chip may use a gate oxide (physical) thickness of FETs of 10 nm, while the standard commodity FPGA IC chips packaged in the same logic drive may use a gate oxide (physical) thickness of FETs of 3 nm; or the dedicated I/O chip may use a gate oxide (physical) thickness of FETs of 7.5 nm, while the standard commodity FPGA IC chips packaged in the same logic drive may use a gate oxide (physical) thickness of FETs of 2 nm. The dedicated I/O chip provides inputs and outputs, and ESD protection for the logic drive. The dedicated I/O chip provides (i) large drivers or receivers, or I/O circuits for communicating with external or outside (of the logic drive), and (ii) small drivers or receivers, or I/O circuits for communicating with chips in or of the logic drive. The large drivers or receivers, or I/O circuits for communicating with external or outside (of the logic drive) have driving capability, loading, output capacitance or input capacitance lager or bigger than that of the small drivers or receivers, or I/O circuits for communicating with chips in or of the logic drive. The driving capability, loading, output capacitance, or input capacitance of the large I/O drivers or receivers, or I/O circuits for communicating with external or outside (of the logic drive) may be between 2 pF and 100 pF, 2 pF and 50 pF, 2 pF and 30 pF, 2 pF and 20 pF, 2 pF and 15 pF, 2 pF and 10 pF, or 2 pF and 5 pF; or larger than 2 pF, 5 pF, 10 pF, 15 pF or 20 pF. The driving capability, loading, output capacitance, or input capacitance of the small I/O drivers or receivers, or I/O circuits for communicating with chips in or of the logic drive may be between 0.1 pF and 10 pF, 0.1 pF and 5 pF or 0.1 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF. The size of ESD protection device on the dedicated I/O chip is larger than that on other standard commodity FPGA IC chips in the same logic drive. The size of the ESD device in the large I/O circuits may be between 0.5 pF and 20 pF, 0.5 pF and 15 pF, 0.5 pF and 10 pF 0.5 pF and 5 pF or 0.5 pF and 2 pF; or larger than 0.5 pF, 1 pF, 2 pF, 3 pF, 5 pF or 10 pF. For example, a bi-directional (or tri-state) I/O pad or circuit may be used for the large I/O drivers or receivers, or I/O circuits for communicating with external or outside (of the logic drive), and may comprise an ESD circuit, a receiver, and a driver, and may have an input capacitance or output capacitance between 2 pF and 100 pF, 2 pF and 50 pF, 2 pF and 30 pF, 2 pF and 20 pF, 2 pF and 15 pF, 2 pF and 10 pF, or 2 pF and 5 pF; or larger than 2 pF, 5 pF, 10 pF, 15 pF or 20 pF. For example, a bi-directional (or tri-state) I/O pad or circuit may be used for the small I/O drivers or receivers, or I/O circuits for communicating with chips in or of the logic drive, and may comprise an ESD circuit, a receiver, and a driver, and may have an input capacitance or output capacitance between 0.1 pF and 10 pF, 0.1 pF and 5 pF or 0.1 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF.

The dedicated I/O chip (or chips) in the multi-chip package of the standard commodity logic drive may comprise a buffer and/or driver circuits for (1) downloading the programing codes from the non-volatile IC chips in the logic drive to the 5T or 6T SRAM cells of the programmable interconnection on the standard commodity FPGA chips. The programming codes from the non-volatile IC chips in the logic drive may go through a buffer or driver in or of the dedicated I/O chip before getting into the 5T or 6T SRAM cells of the programmable interconnection on the standard commodity FPGA chips. The buffer in or of the dedicated I/O chip may latch the data from the non-volatile chips and increase the bit-width of the data. For example, the data bit-width (in a SATA standard) from the non-volatile chips is 1 bit, the buffer may latch the 1 bit data in each of the multiple SRAM cells in the buffer, and output the data stored or latched in the multiple SRAM cells in parallel and simultaneously to increase the data bit-width; for example, equal to or greater than 4, 8, 16, 32, or 64 data bit-width. For another example, the data bit-width (in a PCIe standard) from the non-volatile chips is 32 bit, the buffer may increase the data bit-width to equal to or greater than 64, 128, or 256 data bit-width. The driver in or of the dedicated I/O chip may amplify the data signals from the non-volatile chips; (2) downloading data from the non-volatile IC chips in the logic drive to the 5T or 6T SRAM cells of the LUTs on the standard commodity FPGA chips. The data from the non-volatile IC chips in the logic drive may go through a buffer or driver in or of the dedicated I/O chip before getting into the 5T or 6T SRAM cells of LUTs on the standard commodity FPGA chips. The buffer in or of the dedicated I/O chip may latch the data from the non-volatile chips and increase the bit-width of the data. For example, the data bit-width (in a SATA standard) from the non-volatile chips is 1 bit, the buffer may latch the 1 bit data in each of the multiple SRAM cells in the buffer, and output the data stored or latched in the multiple SRAM cells in parallel and simultaneously to increase the data bit-width; for example, equal to or greater than 4, 8, 16, 32, or 64 data bit-width. For another example, the data bit-width (in a PCIe standard) from the non-volatile chips is 32 bit, the buffer may increase the data bit-width to equal to or greater than 64, 128, or 256 data bit-width. The driver in or of the dedicated I/O chip may amplify the data signals from the non-volatile chips.

The dedicated I/O chip (or chips) in the multi-chip package of the standard commodity logic drive may comprise I/O circuits or pads (or micro copper pillars or bumps) for connecting or coupling to one or multiple (2, 3, 4, or more than 4) Universal Serial Bus (USB) ports, one or more IEEE 1394 ports, one or more Ethernet ports, one or more audio ports or serial ports, for example, RS-232 or COM (communication) ports, wireless transceiver I/Os, and/or Bluetooth transceiver I/Os, and etc. The dedicated I/O chip may also comprise I/O circuits or pads (or micro copper pillars or bumps) for connecting or coupling to Serial Advanced Technology Attachment (SATA) ports, or Peripheral Components Interconnect express (PCIe) ports for communicating, connecting or coupling with the memory drive.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising plural standard commodity FPGA IC chips and one or more non-volatile IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming; wherein the one or more non-volatile memory IC chips comprises a NAND flash chip or chips, in a bare-die format or in a multi-chip flash package format. Each of the one or more NAND flash chips may has a standard memory density, capacity or size of greater than or equal to 64 Mb, 512 Mb, 1 Gb, 4 Gb, 16 Gb, 64 Gb, 128 Gb, 256 Gb, or 512 Gb, wherein "b" is bits. The NAND flash chip may be designed and fabricated using advanced NAND flash technology nodes or generations, for example, more advanced than or equal to 45 nm, 28 nm, 20 nm, 16 nm, and/or 10 nm, wherein the advanced NAND flash technol-

ogy may comprise Single Level Cells (SLC) or multiple level cells (MLC) (for example, Double Level Cells DLC, or triple Level cells TLC), and in a 2D-NAND or a 3D NAND structure. The 3D NAND structures may comprise multiple stacked layers or levels of NAND cells, for example, greater than or equal to 4, 8, 16, 32 stacked layers or levels of NAND cells.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising plural standard commodity FPGA IC chips and one or more non-volatile IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming; wherein the one or more non-volatile memory IC chips comprises a NAND flash chip or chips, in a bare-die format or in a multi-chip flash package format. The standard commodity logic drive may have a standard non-volatile memory density, capacity or size of greater than or equal to 8 MB, 64 MB, 128 GB, 512 GB, 1 GB, 4 GB, 16 GB, 64 GB, 256 GB, or 512 GB, wherein "B" is bytes, each byte has 8 bits.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package comprising the plural standard commodity FPGA IC chips, the dedicated I/O chip, the dedicated control chip and the one or more non-volatile memory IC chips, for use in different applications requiring logic, computing and/or processing functions by field programming. The communication between the chips of the logic drive and the communication between each chip of the logic drive and the external or outside (of the logic drive) are described as follows: (1) the dedicated I/O chip communicates directly with the other chip or chips of the logic drive, and also communicates directly with the external or outside (circuits) (of the logic drive). The dedicated I/O chip comprises two types of I/O circuits; one type having large driving capability, loading, output capacitance or input capacitance for communicating directly with the external or outside of the logic drive, and the other type having small driving capability, loading, output capacitance or input capacitance for communicating directly with the other chip or chips of the logic drive; (2) each of the plural FPGA IC chips only communicates directly with the other chip or chips of the logic drive, but does not communicate directly and/or does not communicate with the external or outside (of the logic drive); wherein an I/O circuit of one of the plural FPGA IC chips may communicate indirectly with the external or outside (of the logic drive) by going through an I/O circuit of the dedicated I/O chip; wherein the driving capability, loading, output capacitance or input capacitance of the I/O circuit of the dedicated I/O chip is significantly larger or bigger than that of the I/O circuit of the one of the plural FPGA IC chips, wherein the I/O circuit (for example, the input or output capacitance is smaller than 2 pF) of the one of the plural FPGA IC chips is connected or coupled to the large or big I/O circuit (for example, the input or output capacitance is larger than 3 pF) of the dedicated I/O chip for communicating with the external or outside circuits of the logic drive; (3) the dedicated control chip only communicates directly with the other chip or chips of the logic drive, but does not communicate directly and/or does not communicate with the external or outside (of the logic drive); wherein an I/O circuit of the dedicated control chip may communicate indirectly with the external or outside (of the logic drive) by going through an I/O circuit of the dedicated I/O chip; wherein the driving capability, loading, output capacitance or input capacitance of the I/O circuit of the dedicated I/O chip is significantly larger or bigger than that of the I/O circuit of the dedicated control chip. Alternatively, wherein the dedicated control chip may communicate directly with the other chip or chips of the logic drive, and may also communicate directly with the external or outside (of the logic drive), wherein the dedicated control chip comprises both small and large I/O circuits for these two types of communication, respectively; (4) each of the one or more non-volatile memory IC chips only communicates directly with the other chip or chips of the logic drive, but does not communicates directly and/or does not communicate with the external or outside (of the logic drive); wherein an I/O circuit of the one or more non-volatile memory IC chips may communicate indirectly with the external or outside (of the logic drive) by going through an I/O circuit of the dedicated I/O chip; wherein the driving capability, loading, output capacitance or input capacitance of the I/O circuit of the dedicated I/O chip is significantly larger or bigger than that of the I/O circuit of the one or more non-volatile memory IC chips. Alternatively, wherein the one or more non-volatile memory IC chips may communicate directly with the other chip or chips of the logic drive, and may also communicate directly with the external or outside (of the logic drive), wherein the one or more non-volatile memory IC chips comprises both small and large I/O circuits for these two types of communication, respectively. In the above, "Object X communicates directly with Object Y" means the Object X (for example, a first chip of the logic drive) communicates or couples electrically and directly with the Object Y without going through or passing through any other chip or chips of the logic drive. In the above, "Object X does not communicate directly with Object Y" means the Object X (for example, a first chip of or in the logic drive) may communicate or couple electrically but indirectly with the Object Y by going through or passing through any other chip or chips of the logic drive. "Object X does not communicate with Object Y" means the Object X (for example, a first chip of the logic drive) does not communicate or couple electrically and directly, and does not communicate or couple electrically and indirectly with the Object Y.

Another aspect of the disclosure provides the standard commodity logic drive in a multi-chip package further comprising a dedicated control and I/O chip. The dedicated control and I/O chip provides the functions of the dedicated control chip and the dedicated I/O chip, as described in the above paragraphs, in one chip. The dedicated control and I/O chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 30 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm. The semiconductor technology node or generation used in the dedicated control and I/O chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the dedicated control and I/O chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the dedicated control and I/O chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the dedicated control and I/O chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the dedicated control and I/O chip may use the Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, while the

standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. The above-mentioned specification for the small I/O circuits, i.e., small driver or receiver, and the large I/O circuits, i.e., large driver or receiver, in the I/O chip may be applied to that in the dedicated control and I/O chip.

The communication between the chips of the logic drive and the communication between each chip of the logic drive and the external or outside (of the logic drive) are described as follows: (1) the dedicated control and I/O chip communicates directly with the other chip or chips of the logic drive, and also communicates directly with the external or outside (circuits) (of the logic drive). The dedicated control and I/O chip comprises two types of I/O circuits; one type having large driving capability, loading, output capacitance or input capacitance for communicating with the external or outside of the logic drive, and the other type having small driving capability, loading, output capacitance or input capacitance for communicating directly with the other chip or chips of the logic drive; (2) each of the plural FPGA IC chips only communicates directly with the other chip or chips of the logic drive, but does not communicate directly and/or does not communicate with the external or outside (of the logic drive); wherein an I/O circuit of one of the plural FPGA IC chips may communicate indirectly with the external or outside (of the logic drive) by going through an I/O circuit of the dedicated control and I/O chip; wherein the driving capability, loading, output capacitance or input capacitance of the I/O circuit of the dedicated control and I/O chip is significantly larger or bigger than that of the I/O circuit of the one of the plural FPGA IC chips; (3) each of the one or more non-volatile memory IC chips only communicates directly with the other chip or chips in or of the logic drive, but does not communicates directly or does not communicate with the external or outside (of the logic drive); wherein an I/O circuit of the one or more non-volatile memory IC chips may communicate indirectly with the external or outside (of the logic drive) by going through an I/O circuit of the dedicated control and I/O chip, wherein the driving capability, loading, output capacitance or input capacitance of the I/O circuit of the dedicated control and I/O chip is significantly larger or bigger than that of the I/O circuit of the one or more non-volatile memory IC chips. Alternatively, wherein the one or more non-volatile memory IC chips communicates directly with the other chip or chips in the logic drive, and also communicates directly with the external or outside (of the logic drive), wherein the one or more non-volatile memory IC chips comprises small and large I/O circuits for both these two types of communication, respectively. The wordings "Object X communicates directly with Object Y", "Object X does not communicate directly with Object Y", and "Object X does not communicate with Object Y" have the same meanings as defined in the previous paragraph.

Another aspect of the disclosure provides a development kit or tool for a user or developer to implement an innovation or an application using the standard commodity logic drive. The user or developer with innovation or application concept or idea may purchase the standard commodity logic drive and use the corresponding development kit or tool to develop or to write software codes or programs to load into the non-volatile memory of the standard commodity logic drive for implementing his/her innovation or application concept or idea.

Another aspect of the disclosure provides a logic drive in a multi-chip package format further comprising an Innovated ASIC or COT (abbreviated as IAC below) chip for Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, etc. The IAC chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Alternatively, the advanced semiconductor technology nodes or generations, such as more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm, may be used for the IAC chip. The semiconductor technology node or generation used in the IAC chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the IAC chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FD-SOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the IAC chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the IAC chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the IAC chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. Since the IAC chip in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing a current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 μm or 10 mm, may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 μm technology node or generation is over US $2M, US $5M, or US $10M. Implementing the same or similar innovation or application using the logic drive including the IAC chip designed and fabricated using older or less advanced technology nodes or generations may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing the current conventional logic ASIC or COT IC chip, the NRE cost of developing the IAC chip for the same or similar innovation or application may be reduced by a factor of larger than 2, 5, 10, 20, or 30.

Another aspect of the disclosure provides the logic drive in a multi-chip package format may comprises a dedicated control and IAC (abbreviated as DCIAC below) chip by combining the functions of the dedicated control chip and the IAC chip, as described in the above paragraphs, in one single chip. The DCIAC chip now comprises the control circuits, Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, and/or etc. The DCIAC chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for

example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Alternatively, the advanced semiconductor technology nodes or generations, such as more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm, may be used for the DCIAC chip. The semiconductor technology node or generation used in the DCIAC chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the DCIAC chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the DCIAC chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the DCIAC chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the DCIAC chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. Since the DCIAC chip in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing a current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 mm, may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation is over US $2M, US $5M or US $10M. Implementing the same or similar innovation or application using the logic drive including the DCIAC chip designed and fabricated using older or less advanced technology nodes or generations, may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing a logic ASIC or COT IC chip, the NRE cost of developing the DCIAC chip for the same or similar innovation or application may be reduced by a factor of larger than 2, 5, 10, 20, or 30.

Another aspect of the disclosure provides the logic drive in a multi-chip package further comprising a dedicated control, dedicated I/O, and IAC (abbreviated as DCDI/OIAC below) chip by combining the functions of the dedicated control chip, the dedicated I/O chip and the IAC chip, as described in the above paragraphs, in one single chip. The DCDI/OIAC chip comprises the control circuits, I/O circuits, Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, and/or etc. The DCDI/OIAC chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 30 nm, 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, or 500 nm. The semiconductor technology node or generation used in the DCDI/OIAC chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the DCDI/OIAC chip may be a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the DCDI/OIAC chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the DCDI/OIAC chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the DCDI/OIAC chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET. Since the DCDI/OIAC chip in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing a current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation is over US$2M, US $5M or US $10M. Implementing the same or similar innovation or application using the logic drive including the DCDI/OIAC chip designed and fabricated using older or less advanced technology nodes or generations, may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing a logic ASIC or COT IC chip, the NRE cost of developing the DCDI/OIAC chip for the same or similar innovation or application may be reduced by a factor of larger than 2, 5, 10, 20, or 30.

Another aspect of the disclosure provides a method to change the logic ASIC or COT IC chip hardware business into a mainly software business by using the logic drive. Since the performance, power consumption and engineering and manufacturing costs of the logic drive may be better or equal to the current conventional ASIC or COT IC chip for a same or similar innovation or application, the current ASIC or COT IC chip design companies or suppliers may become mainly software developers, while only designing the IAC chip, the DCIAC chip, or the DCDI/OIAC chip, as described above, using older or less advanced semiconductor technology nodes or generations. In this aspect of disclosure, they may (1) design and own the IAC chip, the DCIAC chip, or the DCDI/OIAC chip; (2) purchase from a third party the standard commodity FPGA chips and standard commodity non-volatile memory chips in the bare-die or packaged format; (3) design and fabricate (may outsource the manufacturing to a third party of the manufacturing provider) the logic drive including their own IAC, DCIAC, or DCI/OIAC chip, and the purchased third party's standard commodity FPGA chips and standard commodity non-volatile memory chips; (3) install in-house developed software for the innovation or application in the non-volatile memory IC chip or chips in the logic drive; and/or (4) sell the program-installed logic drive to their customers. In this case, they still sell hardware without performing the expensive ASIC or COT IC chip design and production using advanced semiconduc-

tor technology nodes, for example, nodes or generations more advanced than or below 30 nm, 20 nm or 10 nm. They may write software codes to program the logic drive comprising the plural of standard commodity FPGA chips for their desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Another aspect of the disclosure provides the logic drive in a multi-chip package comprising plural standard commodity FPGA IC chips and one or more non-volatile IC chips, further comprising processing and/or computing IC chips, for example, one or more Central Processing Unit (CPU) chips, one or more Graphic Processing Unit (GPU) chips, one or more Digital Signal Processing (DSP) chips, one or more Tensor Processing Unit (TPU) chips, and/or one or more Application Processing Unit (APU) chips, designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm, which may be the same as, one generation or node less advanced than, or one generation or node more advanced than that used for the FPGA IC chips in the same logic drive. Alternatively, the processing and/or computing IC chip may be a System-On-a-Chip (SOC) chip, comprising: (1) CPU and DSP unit, (2) CPU and GPU, (3) DSP and GPU or (4) CPU, GPU and DSP unit. Transistors used in the processing and/or computing IC chip may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET. Alternatively, a plurality of the processing and/or computing IC chips may be included, packaged, or incorporated in the logic drive. Alternatively, two processing and/or computing IC chips are included, packaged or incorporated in the logic drive, the combination for the two processing and/or computing IC chips is as below: (1) one of the two processing and/or computing IC chips may be a Central Processing Unit (CPU) chip, and the other one of the two processing and/or computing IC chips may be a Graphic Processing unit (GPU); (2) one of the two processing and/or computing IC chips may be a Central Processing Unit (CPU), and the other one of the two processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit; (3) one of the two processing and/or computing IC chips may be a Central Processing Unit (CPU), and the other one of the two processing and/or computing IC chips may be a Tensor Processing Unit (TPU); (4) one of the two processing and/or computing IC chips may be a Graphic Processing Unit (GPU), and the other one of the two processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit; (5) one of the two processing and/or computing IC chips may be a Graphic Processing Unit (GPU), and the other one of the two processing and/or computing IC chips may be a Tensor Processing Unit (TPU); (6) one of the two processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit, and the other one of the two processing and/or computing IC chips may be a Tensor Processing Unit (TPU). Alternatively, three processing and/or computing IC chips are incorporated in the logic drive, the combination for the three processing and/or computing IC chips is as below: (1) one of the three processing and/or computing IC chips may be a Central Processing Unit (CPU), another one of the three processing and/or computing IC chips may be a graphic Processing Unit (GPU), and the other one of the three processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit; (2) one of the three processing and/or computing IC chips may be a Central Processing Unit (CPU), another one of the three processing and/or computing IC chips may be a Graphic Processing Unit (GPU), and the other one of the three processing and/or computing IC chips may be a Tensor Processing Unit (TPU); (3) one of the three processing and/or computing IC chips may be a Central Processing Unit (CPU), another one of the three processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit, and the other one of the three processing and/or computing IC chips may be a Tensor Processing Unit (TPU); (4) one of the three processing and/or computing IC chips may be a Graphic processing unit (GPU), another one of the three processing and/or computing IC chips may be a Digital Signal Processing (DSP) unit, and the other one of the three processing and/or computing IC chips may be a Tensor Processing Unit (TPU). Alternatively, the combination for the multiple processing and/or computing IC chips may comprise: (1) multiple GPU chips, for example 2, 3, 4 or more than 4 GPU chips, (2) one or more CPU chips and/or one or more GPU chips, (3) one or more CPU chips and/or one or more DSP chips, (3) one or more CPU chips, one or more GPU chips and/or one or more DSP chips, (4) one or more CPU chips and/or one or more TPU chips, or, (5) one or more CPU chips, one or more DSP chips and/or one or more TPU chips. In all of the above alternatives, the logic drive may comprise one or more of the processing and/or computing IC chips, and one or more high speed, wide bit-width and high bandwidth cache SRAM chips or DRAM IC chips for high speed parallel processing and/or computing. For example, the logic drive may comprise multiple GPU chips, for example 2, 3, 4 or more than 4 GPU chips, and multiple high speed, wide bit-width and high bandwidth cache SRAM chips or DRAM IC chips. The communication between one of GPU chips and one of SRAM or DRAM IC chips may be with data bit-width of equal or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. For another example, the logic drive may comprise multiple TPU chips, for example 2, 3, 4 or more than 4 TPU chips, and multiple high speed, wide bit-width and high bandwidth cache SRAM chips or DRAM IC chips. The communication between one of TPU chips and one of SRAM or DRAM IC chips may be with data bit-width of equal or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

The communication, connection, or coupling between one of logic, processing and/or computing chips (for example, FPGA, CPU, GPU, DSP, APU, TPU, and/or ASIC chips) and one of high speed, wide bit-width and high bandwidth SRAM, DRAM or NVM RAM (for example, MRAM, RRAM) chips through the FISIP and/or SISIP of the interposer to be described and specified below, may be the same or similar as that between internal circuits in a same chip. Alternatively, the communication, connection, or coupling between one of logic, processing and/or computing chips (for example, FPGA, CPU, GPU, DSP, APU, TPU, and/or ASIC chips) and one of high speed, wide bit-width and high bandwidth SRAM, DRAM or NVM RAM chips through the FISIP and/or SISIP of the interposer, may be using small I/O drivers and/or receivers on both logic, processing and/or computing chips and SRAM, DRAM or NVM RAM chips. The driving capability, loading, output capacitance, or input capacitance of the small I/O drivers or receivers, or I/O circuits may be between 0.01 pF and 10 pF, 0.05 pF and 5

pF, or 0.01 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, 0.5 pF or 0.1 pF. For example, a bi-directional (or tri-state) I/O pad or circuit may be used for the small I/O drivers or receivers, or I/O circuits for communicating between high speed, wide bit-width and high bandwidth logic and memory chips in the logic drive, and may comprise an ESD circuit, a receiver, and a driver, and may have an input capacitance or output capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, or 0.01 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, or 0.5 pF or 0.1 pF.

The processing and/or computing IC chip or chips in the logic drive provide fixed-metal-line (non-field-programmable) interconnects for (non-field-programmable) functions, processors and operations. The standard commodity FPGA IC chips provide (1) programmable-metal-line (field-programmable) interconnects for (field-programmable) logic functions, processors and operations and (2) fixed-metal-line (non-field-programmable) interconnects for (non-field-programmable) logic functions, processors and operations. Once the programmable-metal-line interconnects in or of the FPGA IC chips are programmed, the programmed interconnects together with the fixed interconnects in or of the FPGA chips provide some specific functions for some given applications. The operational FPGA chips may operate together with the processing and/or computing IC chip or chips in the same logic drive to provide powerful functions and operations in applications, for example, Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), driverless car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Another aspect of the disclosure provides the standard commodity FPGA IC chip for use in the logic drive. The standard commodity FPGA chip is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm. The standard commodity FPGA IC chips are fabricated by the process steps described in the following paragraphs:

(1) Providing a semiconductor substrate (for example, a silicon substrate), or a Silicon-On-Insulator (SOI) substrate, with the substrate in the wafer form, and with a wafer size, for example 8", 12" or 18" in the diameter. Transistors are formed in the substrate, and/or on or at the surface of the substrate by a wafer process. Transistors formed in the advanced semiconductor technology node or generation may be a FINFET, a FINFET on Silicon-on-insulator (FINFET SOI), a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET.

(2) Forming a First Interconnection Scheme in, on or of the Chip (FISC) over the substrate and on or over a layer comprising transistors, by a wafer process. The FISC comprises multiple interconnection metal layers, with an inter-metal dielectric layer between each of the multiple interconnection metal layers. The FISC structure may be formed by performing a single damascene copper process and/or a double damascene copper process. As an example, the metal lines and traces of an interconnection metal layer in the multiple interconnection metal layers may be formed by the single damascene copper process as follows: (i) providing a first insulating dielectric layer (may be an inter-metal dielectric layer with the top surfaces of vias or metal pads, lines or traces exposed and formed therein). The top-most layer of the first insulting dielectric layer may be, for example, a low k dielectric layer, for an example, a SiOC layer; (ii) depositing, for example, by Chemical Vapor Deposition (CVD) methods, a second insulting dielectric layer on or over the whole wafer, including on or over the first insulating dielectric layer, and on or over the exposed vias or metal pads, lines or traces in the first insulating dielectric layer. The second insulting dielectric layer is formed by (a) depositing a bottom differentiate etch-stop layer, for example, a Silicon Carbon Nitride layer (SiCN), on or over the top-most layer of the first insulting dielectric layer and on the exposed top surfaces of the vias or metal pads, lines or traces in the first insulating dielectric layer; (b) then depositing a low k dielectric layer, for example, a SiOC layer, on or over the bottom differentiate etch-stop layer. The low k dielectric material has a dielectric constant smaller than that of the SiO2 material. The SiCN and SiOC layers may be deposited by CVD methods. The material used for the first and second insulating dielectric layers of the FISC comprises inorganic material, or material compounds comprising silicon, nitrogen, carbon, and/or oxygen; (iii) then forming trenches or openings in the second insulting dielectric layer by (a) coating, exposing, developing a photoresist layer to form trenches or openings in the photoresist layer, and then (b) forming trenches or openings in the second insulating dielectric layer by etching methods, and then removing the photoresist layer; (iv) followed by depositing an adhesion layer on or over the whole wafer including in the trenches or openings in the second insulating dielectric layer, for example, sputtering or Chemical Vapor Depositing (CVD) a titanium (Ti) or titanium nitride (TiN) layer (with thickness for example, between 1 nm and 50 nm); (v) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 200 nm); (vi) then electroplating a copper layer (with a thickness, for example, between 10 nm and 3,000 nm, 10 nm and 1,000 nm or 10 nm and 500 nm) on or over the copper seed layer; (vii) then applying a Chemical-Mechanical Process (CMP) to remove the un-wanted metals (Ti or TiN)/Seed Cu/electroplated Cu) outside the trenches or openings in the second insulating dielectric layer, until the top surface of the second insulating dielectric layer is exposed. The metals left or remained in trenches or openings in or of the second insulating dielectric layer are used as metal pads, lines or traces, or metal vias for the interconnection metal layer of the FISC.

As another example, the metal lines and traces of an interconnection metal layer of the FISC, and the vias in an inter-metal dielectric layer of the FISC may be form by a double damascene copper process as follows: (i) providing a first insulating dielectric layer with top surfaces of metal lines or traces or metal pads (in the first insulating dielectric layer) exposed. The top-most layer of the first insulting dielectric layer may be, for example, a Silicon Carbon Nitride layer (SiCN) or Silicon Nitride (SiN) layer; (ii) depositing a dielectric stack layer comprising multiple insulating dielectric layers on the top-most layer of the first insulting dielectric layer and the exposed top surfaces of metal lines and traces in the first insulating dielectric layer. The dielectric stack layer comprises, from bottom to top, (a) a bottom low k dielectric layer, for example, a SiOC layer (to be used as the via layer or the inter-metal dielectric layer), (b) a middle differentiate etch-stop layer, for example, a Silicon Carbon Nitride layer (SiCN) or Silicon Nitride layer (SiN), (c) a top low k SiOC layer (to be used as the insulating dielectrics between metal lines or traces in or of the same interconnection metal layer), and (d) a top differ-

entiate etch-stop layer, for example, a Silicon Carbon Nitride layer (SiCN) or Silicon Nitride (SiN) layer. All insulating dielectric layers, (SiCN, SiN, SiOC) may be deposited by CVD methods; (iii) forming trenches, openings or holes in the dielectric stack: (a) coating, exposing and developing a first photoresist layer to form trenches or openings in the first photoresist layer; and then (b) etching the exposed top differentiate etch-stop layer (SiCN or SiN), and the top low k SiOC layer, and stopping at the middle differentiate etch-stop layer, (SiCN or SiN), forming trenches or top openings in the top portion of the dielectric stack layer for the later double-damascene copper process to from metal lines or traces of the interconnection metal layer; (c) then coating, exposing and developing a second photoresist layer to form openings or holes in the second photoresist layer; (d) etching the exposed middle differentiate etch-stop layer (SiCN or SiN), and the bottom low k SiOC layer, and stopping at the metal lines and traces in the first insulating dielectric layer, forming bottom openings or holes in the bottom portion of the dielectric stack layer for the later double-damascene copper process to form the vias in the inter-metal dielectric layer. The trenches or top openings in the top portion of the dielectric stack layer overlap the bottom openings or holes in the bottom portion of the dielectric stack layer, and have a size larger than that of the bottom openings or holes. In other words, the bottom openings or holes in the bottom portion of the dielectric stack layer, are inside or enclosed by the trenches or top openings in the top portion of the dielectric stack layer from a top view; (iv) forming metal lines or traces and vias: (a) depositing an adhesion layer on or over the whole wafer, including on or over the dielectric stack layer, and in the etched trenches or top openings in the top portion of the dielectric stack layer, and in the bottom openings or holes in the bottom portion of the dielectric stack layer. For example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 50 nm), (b) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 200 nm); (c) then electroplating a copper layer (with a thickness, for example, between 20 nm and 6,000 nm, 10 nm and 3,000 nm, or between 10 nm and 1,000 nm) on or over the copper seed layer; (d) then applying a Chemical-Mechanical Process (CMP) to remove the un-wanted metals (Ti (or TiN)/Seed Cu/electroplated Cu) outside the trenches or top openings, and the bottom openings or holes in the dielectric stack layer, until the top surface of the dielectric stack layer is exposed. The metals left or remained in the trenches or top openings are used as metal lines or traces for the interconnection metal layer, and the metals left or remained in the bottom openings or holes are used as vias in the inter-metal dielectric layer for coupling the metal lines or traces below and above the vias. In the single-damascene process, the copper electroplating process step and the CMP process step are performed for the metal lines or traces of an interconnection metal layer, and are then performed sequentially again for vias in an inter-metal dielectric layer on the interconnection metal layer. In other words, in the single damascene copper process, the copper electroplating process step and the CMP process step are performed two times for forming the metal lines or traces of an interconnection metal layer, and vias in an inter-metal dielectric layer on the interconnection metal layer. In the double-damascene process, the copper electroplating process step and the CMP process step are performed only one time for forming the metal lines or traces of an interconnection metal layer, and vias in an inter-metal dielectric layer under the interconnection metal layer. The processes for forming metal lines or traces of the interconnection metal layer and vias in the inter-metal dielectric layer using the single damascene copper process or the double damascene copper process may be repeated multiple times to form metal lines or traces of multiple interconnection metal layers and vias in inter-metal dielectric layers of the FISC. The FISC may comprise 4 to 15 layers, or 6 to 12 layers of interconnection metal layers.

The metal lines or traces in the FISC are coupled or connected to the underlying transistors. The thickness of the metal lines or traces of the FISC, either formed by the single-damascene process or by the double-damascene process, is, for example, between 3 nm and 500 nm, or between 10 nm and 1,000 nm, or, thinner than or equal to 5 nm, 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, or 1,000 nm. The width of the metal lines or traces of the FISC is, for example, between 3 nm and 500 nm, or between 10 nm and 1,000 nm, or, narrower than 5 nm, 10 nm, 20 nm, 30 nm, 70 nm, 100 nm, 300 nm, 500 nm or 1,000 nm. The thickness of the inter-metal dielectric layer has a thickness, for example, between 3 nm and 500 nm, or between 10 nm and 1,000 nm, or thinner than 5 nm, 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 nm or 1,000 nm. The metal lines or traces of the FISC may be used for the programmable interconnection.

(3) Depositing a passivation layer on or over the whole wafer and on or over the FISC structure. The passivation is used for protecting the transistors and the FISC stricture from water moisture or contamination from the external environment, for example, sodium mobile ions. The passivation comprises a mobile ion-catching layer or layers, for example, SiN, SiON, and/or SiCN layer or layers. The total thickness of the mobile ion catching layer or layers is thicker than or equal to 100 nm, 150 nm, 200 nm, 300 nm, 450 nm, or 500 nm. Openings in the passivation layer may be formed to expose the top surface of the top-most interconnection metal layer of the FISC, and for forming vias in the passivation openings in the following processes later.

(4) Forming a Second Interconnection Scheme in, on or of the Chip (SISC) on or over the FISC structure. The SISC comprises multiple interconnection metal layers, with an inter-metal dielectric layer between each of the multiple interconnection metal layers, and may optionally comprise an insulating dielectric layer on or over the passivation layer, and between the bottom-most interconnection metal layer of the SISC and the passivation layer. The insulating dielectric layer is then deposited on or over the whole wafer, including passivation layer and in the passivation openings. The insulating dielectric layer may have planarization function. A polymer material may be used for the insulating dielectric layer, for example, polyimide, BenzoCycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer or silicone. The material used for the insulating dielectric layer of SISC comprises organic material, for example, a polymer, or material compounds comprising carbon. The polymer layer may be deposited by methods of spin-on coating, screen-printing, dispensing, or molding. The polymer material may be photosensitive, and may be used as photoresist as well for patterning openings in it for forming metal vias in it by following processes to be performed later; that is, the photosensitive polymer layer is coated, and exposed to light through a photomask, and then developed and etched to form openings in it. The opening in the photosensitive insulating dielectric layer overlaps the opening in the passivation layer, exposing the

top surfaces of the top-most metal layer of the FISC. In some applications or designs, the size of opening in the polymer layer is larger than that of the opening in the passivation layer, and the top surface of the passivation layer is exposed in the opening of the polymer layer. The photosensitive polymer layer (the insulating dielectric layer) is then cured at a temperature, for example, equal to or higher than 100T° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. An emboss copper process is then performed on or over the cured polymer layer and on or over the exposed top surfaces of the top-most interconnection metal layer of the FISC in openings in the cured polymer layer, or, on or over the exposed surface of the passivation layer in the openings of the cured polymer layer for some cases: (a) first depositing the whole wafer an adhesion layer on or over the cured polymer layer and on or over the exposed top surfaces of the top-most interconnection metal layer of the FISC in openings in the cured polymer layer, or, on or over the exposed surface of the passivation layer in the openings of the cured polymer layer for some cases, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 50 nm); (b) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 200 nm); (c) coating, exposing and developing a photoresist layer on or over the copper seed layer; forming trenches or openings in the photoresist layer for forming metal lines or traces of the interconnection metal layer of SISC by following processes to be performed later, wherein portion of the trench (opening) in the photoresist layer may overlap the whole area of opening in the cured polymer layer, (the metal vias will be formed in the openings of the cured polymer layer by following processes to be performed later); exposing the copper seed layer at the bottom of the trenches or openings; (d) then electroplating a copper layer (with a thickness, for example, between 0.3 μm and 20 μm, 0.5 μm and 5 μm, 1 μm and 10 μm, or 2 μm and 10 μm) on or over the copper seed layer at the bottom of the patterned trenches or openings in the photoresist layer; (e) removing the remained photoresist; (f) removing or etching the copper seed layer and the adhesion layer not under the electroplated copper. The emboss metals (Ti (or TiN)/seed Cu/electroplated Cu) left or remained in the openings of the cured polymer layer are used for vias in the insulating dielectric layer and vias in the passivation layer; and the emboss metals (Ti (or TiN)/seed Cu/electroplated Cu) left or remained in the locations of trenches or openings in the photoresist, (noted: the photoresist is removed after copper electroplating) are used for the metal lines or traces of the interconnection metal layer. The processes of forming the insulating dielectric layer and openings in it, and the emboss copper processes for forming the vias in the insulting dielectric layer and the metal lines or traces of the interconnection metal layer, may be repeated to form multiple interconnection metal layers in or of the SISC; wherein the insulating dielectric layer is used as the inter-metal dielectric layer between two interconnection metal layers of the SISC, and the vias in the insulating dielectric layer (now in the inter-metal dielectric layer) are used for connecting or coupling metal lines or traces of the two interconnection metal layers. The top-most interconnection metal layer of the SISC is covered with a top-most insulating dielectric layer of SISC. The top-most insulating dielectric layer has openings in it to expose top surface of the top-most interconnection metal layer. The SISC may comprise 2 to 6, or 3 to 5 layers of interconnection metal layers. The metal lines or traces of the interconnection metal layers of the SISC have the adhesion layer (Ti or TiN, for example) and the copper seed layer only at the bottom, but not at the sidewalls of the metal lines or traces. The metal lines or traces of the interconnection metal layers of FISC have the adhesion layer (Ti or TiN, for example) and the copper seed layer at both the bottom and the sidewalls of the metal lines or traces.

The SISC interconnection metal lines or traces are coupled or connected to the FSIC interconnection metal lines or traces, or to transistors in the chip, through vias in openings of the passivation layer. The thickness of the metal lines or traces of SISC is between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm, or 2 μm and 10 μm; or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The width of the metal lines or traces of SISC is between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm, or 2 μm and 10 μm; or wider than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The thickness of the inter-metal dielectric layer has a thickness between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, or 1 μm and 10 μm; or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The metal lines or traces of SISC may be used for the programmable interconnection.

(5) Forming micro copper pillars or bumps with solder caps (i) on the top surface of the top-most interconnection metal layer of SISC, exposed in openings in the insulating dielectric layer of the SISC, and/or (ii) on or over the top-most insulating dielectric layer of the SISC. An emboss metal electroplating process, as described in above paragraphs, is performed to form the micro copper pillars or bumps with solder caps as follows: (a) depositing whole wafer an adhesion layer on or over the top-most dielectric layer of the SISC structure, and in the openings of the top-most insulating dielectric layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with thickness for example, between 1 nm and 50 nm); (b) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness between, for example, 3 nm and 300 nm, or 3 nm and 200 nm); (c) coating, exposing and developing a photoresist layer; forming openings or holes in the photoresist layer for forming the micro pillars or bumps in later processes, exposing (i) a top surface of the top-most interconnection metal layer at the bottom of the openings in the top-most insulating layer of the SISC, and (ii) exposing an area or a ring of the top-most insulating dielectric layer (of the SISC) around the opening in the top-most insulating dielectric layer; (d) then electroplating a copper layer (with a thickness, for example, between 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, or 5 μm and 15 μm) on or over the copper seed layer in the patterned openings or holes in the photoresist layer; (e) then electroplating a solder layer (with a thickness, for example, between 1 μm and 50 μm, 1 μm and 30 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 5 μm and 10 μm, 5 μm and 10 μm, 1 μm and 10 μm, or 1 μm and 3 μm) on or over the electroplated copper layer in the openings of the photoresist; optionally, a nickel layer may be electroplated before electroplating the solder cap or layer and after electroplating the copper layer. The nickel layer may have a thickness, for example, between 1 μm and 10 μm, 3 μm and 10 μm, 3 μm and 5 μm, 1 μm and 5 μm, or 1 μm and 3 μm); (f) removing the remained photoresist; (g) removing or etching the copper seed layer

and the adhesion layer not under the electroplated copper layer and the electroplated solder layer; (h) reflowing solder to form the solder-capped copper bumps. The metals (Ti (or TiN)/seed Cu/electroplated Cu/electroplated solder) left or remained and reflowed-solder are used as the solder-capped copper bumps. The solder material used may be a lead-free solder. Lead-free solders in commercial use may contain tin, copper, silver, bismuth, indium, zinc, antimony, or traces of other metals. For example, the lead-free solder may be Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn Ag Cu Zn solder. The micro copper pillars or bumps with solder caps are coupled or connected to the SISC and FISC interconnection metal lines or traces, and to transistors in or of the chip, through vias in openings in the top-most insulating dielectric layer of the SISC. The height of the micro pillars or bumps is between, for example, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or greater than or equal to 30 μm, 20 μm, 15 μm, 5 μm or 3 μm. The largest dimension in a cross-section of the micro pillars or bumps (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) is between, for example, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm. The space between a micro pillar or bump to its nearest neighboring pillar or bump is between, for example, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

(6) Cutting or dicing the wafer to obtain separated standard commodity FPGA chips. The standard commodity FPGA chips comprise, from bottom to top: (i) a layer comprising transistors, (ii) the FISC, (iii) a passivation layer, (iv) the SISC and (v) micro copper pillars or bumps, above a level of the top surface of the top-most insulating dielectric layer of the SISC by a height of, for example, between 3 μm and 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or greater than or equal to 30 μm, 20 μm, 15 μm, 5 μm or 3 μm.

Another aspect of the disclosure provides an interposer for flip-chip assembly or packaging in forming the multi-chip package of the logic drive. The multi-chip package is based on multiple-Chips-On-an-Interposer (COIP) flip-chip packaging method. The interposer or substrate in the COIP multi-chip package comprises: (1) high density interconnects for fan-out and interconnection between IC chips flip-chip-assembled, bonded or packaged on or over the interposer, (2) micro metal pads, bumps or pillars on or over the high density interconnects, (3) deep vias or shallow vias in the interposer. The IC chips or packages to be flip-chip assembled, bonded or packaged, to the interposer include the chips or packages mentioned, described and specified above: the standard commodity FPGA chips, the non-volatile chips or packages, the dedicated control chip, the dedicated I/O chip, the dedicated control and I/O chip, IAC, DCIAC, DCDI/OIAC chip, and/or processing and/or computing IC chip, for example CPU, GPU, DSP, TPU, or APU chip. The process steps for forming the interposer of the logic drive are as follows:

(1) Providing a substrate. The substrate may be in a wafer format (with 8", 12" or 18" in diameter), or, in a panel format in the square or rectangle format (with a width or a length greater than or equal to 20 cm, 30 cm, 50 cm, 75 cm, 100 cm, 150 cm, 200 cm or 300 cm). The material of the substrate may be silicon, metal, ceramics, glass, steel, plastics, polymer, epoxy-based polymer, or epoxy-based compound. As an example, a silicon wafer may be used as a substrate in forming a silicon interposer.

(2) forming through vias in the substrate. Silicon wafer is used as an example in forming the metal vias in the substrate. The bottom surface metal vias in the silicon wafer are exposed in the final product of the logic drive, therefore, the metal vias become through vias, and the through vias are the Trough-Silicon-Vias (TSVs). The metal vias in the substrate are formed by the following process steps: (a) depositing a masking insulting layer on the silicon wafer, for example, a thermally grown silicon oxide SiO2 and/or a CVD silicon nitride Si3N4; (b) photoresist depositing, patterning and then etching the masking insulating layer to form holes or openings in it; (c) using the masking insulting layer as an etching mask to etch the silicon wafer and forming holes or openings in the silicon wafer at the locations of holes or openings in the masking insulating layer. Two types of holes are formed. One type is a deep hole with the depth of hole between 30 μm and 150 μm, or 50 μm and 100 μm; and with a diameter or size of the hole between 5 μm and 50 μm, or 5 μm and 15 μm. The other type is a shallow hole with the depth of via between 5 μm and 50 μm, or 5 μm and 30 μm; and with a diameter or size of the hole between 20 μm and 150 μm, or 30 μm and 80 μm; (d) removing the remaining masking insulating layer, then forming an insulating lining layer on the sidewall of the hole. The insulating lining layer may be, for example, a thermally grown silicon oxide SiO2 and/or a CVD silicon nitride Si3N4; (e) forming metal via by filling the hole with metal. The damascene copper process, as mentioned above, is used to form the deep via in the deep hole, while the embossing copper process, as mentioned above, is used to form the shallow via in the shallow hole. In the damascene copper process for forming the deep vias, an adhesion metal layer is deposited, followed by depositing an electroplating seed layer, and then electroplating a copper layer. The electroplating copper process is performed on the whole wafer until the deep hole is completely filled. The un-wanted metal stack of electroplating copper, seed layer and adhesion layer outside the via is then removed by a CMP process. The processes and materials in the damascene process for forming the deep vias are the same as described and specified in the above. In the emboss copper process for forming the shallow vias, an adhesion metal layer is deposited, followed by depositing an electroplating seed layer, and then coating and patterning a photoresist layer on or over the electroplating seed layer, forming holes in the photoresist layer to expose the seed layer on the sidewall and bottom of the shallow hole and/or a ring of area along the edge of the hole. Then the electroplating copper process is performed in the holes in the photoresist layer until the shallow hole in the silicon substrate is completely filled. The remained photoresist is then removed. The metals stack of seed layer and adhesion layer outside the via is then removed by a dry or wet etching process or by a CMP process. The process and materials in the embossing process for forming the shallow vias are the same as described and specified in the above.

(3) Forming a First Interconnection Scheme on or of the Interposer (FISIP). The metal lines or traces and the metal vias of the FISIP are formed by the single damascene copper processes or the double damascene copper processes as described or specified above in forming the metal lines or traces and metal vias in the FISC of FPGA IC chips. The processes and materials for forming (a) metal lines or traces of the interconnection metal layer, (b) the inter-metal dielectric layer and (c) metal vias in the inter-metal dielectric layer

in or of the FISIP are the same as described and specified in forming the FISC of FPGA IC chips. The processes for forming metal lines or traces of the interconnection metal layer and vias in the inter-metal dielectric layer using the single damascene copper process or the double damascene copper process may be repeated multiple times to form metal lines or traces of multiple interconnection metal layers and vias in inter-metal dielectric layers of the FISIP. The FISIP may comprise 2 to 10 layers, or 3 to 6 layers of interconnection metal layers. The metal lines or traces of the interconnection metal layers of FISIP have the adhesion layer (Ti or TiN, for example) and the copper seed layer at both the bottom and the sidewalls of the metal lines or traces.

The metal lines or traces in the FISIP are coupled or connected to the micro copper bumps or pillars of the IC chips in or of the logic drive, and coupled or connected to the TSVs in the substrate of the interposer. The thickness of the metal lines or traces of the FISIP, either formed by the single-damascene process or by the double-damascene process, is, for example, between 3 nm and 500 nm, between 10 nm and 1,000 nm, or between 10 nm and 2,000 nm, or, thinner than or equal to 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm. The minimum width of the metal lines or traces of the FISIP is, for example, equal to or smaller than 50 nm, 100 nm, 150 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm. The minimum space between two neighboring metal lines or traces of the FISIP is, for example, equal to or smaller than 50 nm, 100 nm, 150 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm. The minimum pitch of the metal lines or traces of the FISIP is, for example, equal to or smaller than 100 nm, 200 nm, 300 nm, 400 nm, 600 nm, 1,000 nm, 3,000 nm or 4,000 nm. The thickness of the inter-metal dielectric layer has a thickness, for example, between 3 nm and 500 nm, between 10 nm and 1,000 nm, or between 10 nm and 2,000 nm, or, thinner than or equal to 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, 1,000 nm or 2,000 nm. The metal lines or traces of the FISIP may be used as the programmable interconnection.

(4) Forming a Second Interconnection Scheme of the Interposer (SISIP) on or over the FISIP structure. The SISIP comprises multiple interconnection metal layers, with an inter-metal dielectric layer between each of the multiple interconnection metal layers. The metal lines or traces and the metal vias are formed by the emboss copper processes as described or specified above in forming the metal lines or traces and metal vias in the SISC of FPGA IC chips. The processes and materials for forming (a) metal lines or traces of the interconnection metal layer, (b) the inter-metal dielectric layer and (c) metal vias in the inter-metal dielectric layer are the same as described and specified in forming the SISC of FPGA IC chips. The processes for forming metal lines or traces of the interconnection metal layer and vias in the inter-metal dielectric layer using the emboss copper process may be repeated multiple times to form metal lines or traces of multiple interconnection metal layers and vias in inter-metal dielectric layers of the SISIP. The SISIP may comprise 1 to 5 layers, or 1 to 3 layers of interconnection metal layers. Alternatively, the SISIP on or of the interposer may be omitted, and the COIP only has FISIP interconnection scheme on the substrate of the interposer. Alternatively, the FISIP on or of the interposer may be omitted, and the COIP only has SISIP interconnection scheme on the substrate of the interposer.

The thickness of the metal lines or traces of SISIP is between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm, or 2 μm and 10 μm; or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The width of the metal lines or traces of SISIP is between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm, or 2 μm and 10 μm; or wider than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The thickness of the inter-metal dielectric layer has a thickness between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, or 1 μm and 10 μm; or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The metal lines or traces of SISIP may be used as the programmable interconnection.

(5) Forming micro copper pads, pillars or bumps (i) on the top surface of the top-most interconnection metal layer of SISIP, exposed in openings in the topmost insulating dielectric layer of the SISIP, or (ii) on the top surface of the top-most interconnection metal layer of FISIP, exposed in openings in the topmost insulating dielectric layer of the FISIP in the case wherein the SISIP is omitted. An emboss copper process, as described and specified in above paragraphs, is performed to form the micro copper pillars or bumps on or over the interposer.

The height of the micro pads, pillars or bumps on or over the interposer is between, for example, 1 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The largest dimension in a cross-section of the micro pillars or bumps (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) is between, for example, 1 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space between a micro pillar or bump to its nearest neighboring pillar or bump is between, for example, 1 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Another aspect of the disclosure provides a method for forming the logic drive in a COIP multi-chip package using an interposer comprising the FISP, the SISIP, micro copper bumps or pillars and TSVs based on a flip-chip assembled multi-chip packaging technology and process. The process steps for forming the COIP multi-chip packaged logic drive are described as below:

(1) Performing flip-chip assembling, bonding or packaging: (a) First providing the interposer comprising the FISIP, the SISIP, micro copper bumps or pillars and TSVs, and IC chips or packages; then flip-chip assembling, bonding or packaging the IC chips or packages to and on the interposer. The interposer is formed as described and specified above. The IC chips or packages to be assembled, bonded or packaged to the interposer include the chips or packages mentioned, described and specified above: the standard commodity FPGA chips, the non-volatile chips or packages, the dedicated control chip, the dedicated I/O chip, the dedicated control and I/O chip, IAC, DCIAC, DCDI/OIAC chip and/or computing and/or processing IC chips, for example, CPU, GPU, DSP, TPU. APU chips. All chips to be flip-chip packaged in the logic drives comprise micro copper pillars or bumps with solder caps on the top surface of the chips. The top surfaces of micro copper pillars or bumps with solder caps are at a level above the level of the top surface of the top-most insulating dielectric layer of the chips with a height of, for example, between 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5

μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or greater than or equal to 30 μm, 20 μm, 15 μm, 5 μm or 3 μm; (b) The chips are flip-chip assembled, bonded or packaged on or to corresponding micro copper pads, bumps or pillar on or of the interposer with the side or surface of the chip with transistors faced down. The backside of the silicon substrate of the chips (the side or surface without transistors) is faced up; (c) Filling the gaps between the interposer and the IC chips (and between micro copper bumps or pillars of the IC chips and the interposer) with an underfill material by, for example, a dispensing method using a dispenser. The underfill material comprises epoxy resins or compounds, and can be cured at temperature equal to or above 100° C., 120° C., or 150° C.

(2) Applying a material, resin, or compound to fill the gaps between chips and cover the backside surfaces of chips by methods, for example, spin-on coating, screen-printing, dispensing or molding in the wafer or panel format. The molding method includes the compress molding (using top and bottom pieces of molds) or the casting molding (using a dispenser). The material, resin, or compound used may be a polymer material includes, for example, polyimide, BenzoCycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer, or silicone. The polymer may be, for example, photosensitive polyimide/PBO PIMEL™ supplied by Asahi Kasei Corporation, Japan; or epoxy-based molding compounds, resins or sealants provided by Nagase ChemteX Corporation, Japan. The material, resin or compound is applied (by coating, printing, dispensing or molding) on or over the interposer and on or over the backside of the chips to a level to: (i) fill gaps between chips, (ii) cover the top-most backside surface of the chips. The material, resin or compound may be cured or cross-linked by raising a temperature to a certain temperature degree, for example, equal to or higher than or equal to 50° C., 70° C., 90° C., 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. The material may be polymer or molding compound. Applying a CMP, polishing or grinding process to planarize the surface of the applied material, resin or compound. Optionally, the CMP, or grinding process is performed until a level where the backside surfaces of all IC chips are fully exposed.

(3) Thinning the interposer to expose the surfaces of the metal through vias (TSVs) at the backside of the interposer. A wafer or panel thinning process, for example, a CMP process, a polishing process or a wafer backside grinding process, may be performed to remove portion of the wafer or panel to make the wafer or panel thinner, in a wafer or panel process, to expose the surfaces of the metal through vias (TSVs) at the backside of the interposer.

The interconnection metal lines or traces of the FISIP and/or SISIP of the interposer for the logic drive may: (a) comprise an interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP of the logic drive for connecting or coupling the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of an FPGA IC chip of the logic drive to the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of another FPGA IC chip packaged in the same logic drive. This interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be connected to the circuits or components outside or external to the logic drive through TSVs in the substrate of the interposer. This interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be a net or scheme for signals, or the power or ground supply; (b) comprise an interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP of the logic drive connecting to multiple micro copper pillars or bumps of an IC chip in or of the logic drive. This interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be connected to the circuits or components outside or external to the logic drive through the TSVs in the substrate of the interposer. This interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be a net or scheme for signals, or the power or ground supply; (c) comprise interconnection metal lines or traces in or of the FISIP and/or SISIP of the logic drive for connecting or coupling to the circuits or components outside or external to the logic drive, through one or more of the TSVs in the substrate of the interposer. The interconnection metal lines or traces in or of the FISIP and/or SISIP may be used for signals, power or ground supplies. In this case, for example, the one or more of the TSVs in the substrate of the interposer may be connected to the I/O circuits of, for example, the dedicated I/O chip of the logic drive. The I/O circuits in this case may be a large 110 circuit, for example, a bi-directional (or tri-state) I/O pad or circuit, comprising an ESD circuit, a receiver, and a driver, and may have an input capacitance or output capacitance between 2 pF and 100 pF, 2 pF and 50 pF, 2 pF and 30 pF, 2 pF and 20 pF, 2 pF and 15 pF, 2 pF and 10 pF, or 2 pF and 5 pF; or larger than 2 pF, 5 pF, 10 pF, 15 pF or 20 pF; (d) comprise an interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP of the logic drive used for connecting the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of an FPGA IC chip of the logic drive to the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of another FPGA IC chip packaged in the logic drive; but not connected to the circuits or components outside or external to the logic drive. That is, no TSV in the substrate of the interposer of the logic drive is connected to the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP. In this case, the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be connected or coupled to the off-chip I/O circuits of the FPGA chips packaged in the logic drive. The I/O circuit in this case may be a small I/O circuit, for example, a bi-directional (or tri-state) I/O pad or circuit, comprising an ESD circuit, a receiver, and/or a driver, and may have an input capacitance or output capacitance between 0.1 pF and 10 pF, 0.1 pF and 5 pF or 0.1 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF; (e) comprise an interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP of the logic drive used for connecting or coupling to multiple micro copper pillars or bumps of an IC chip in or of the logic drive; but not connecting to the circuits or components outside or external to the logic drive. That is, no TSV in the substrate of the interposer of the logic drive is connected to the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP. In this case, the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP may be connected or coupled to the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of the FPGA IC chip of the logic drive, without going through any I/O circuit of the FPGA IC chip.

(4) Forming solder bumps on or under the exposed bottom surfaces of the TSVs. For the shallow TSVs, the areas of the exposed bottom surfaces are large enough for use as bases to form solder bumps on or under the exposed copper surfaces. For the deep TSVs, the areas of the exposed bottom surfaces may not be large enough for use as bases to form solder bumps on or under the exposed copper surfaces; therefore, an emboss copper process may be performed to

form copper pads as bases for forming the solder bumps on or under them. For the description purpose, the wafer or panel for the interposer is turned upside down, with the interposer at the top and the IC chips at the bottom. The frontside (the side with the transistors) of IC chips are now facing up, the molding compound and the backside of the IC chips are now at the bottom. The base copper pads are formed by performing an emboss copper process in the following process steps: (a) depositing and patterning an insulating layer, for example, a polymer layer, on the whole wafer or panel, and exposing the surfaces of the TSVs in the openings or holes of the insulating layer; (b) depositing an adhesion layer on or over the insulating layer, and the exposed surfaces of the TSVs in openings or holes of the insulating layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm, or 5 nm and 50 nm); (c) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 400 nm, or 10 nm and 200 nm); (d) patterning openings or holes in a photoresist layer for forming the copper pads later, by coating, exposing and developing the photoresist layer, exposing the copper seed layer at the bottom of the openings or holes in the photoresist layer. The opening or hole in the photoresist layer overlaps the opening in the insulating layer; and extends out of the opening of the insulating layer, to an area (where the copper pads are to be formed) around the opening in the insulating layer; (e) then electroplating a copper layer (with a thickness, for example, between 1 μm and 50 nm, 1 μm and 40 μm, 1 μm and 30 μm, 1 μm and 20 μm, 1 μm and 10 μm, 1 μm and 5 μm, or 1 μm and 3 μm) on or over the copper seed layer in the openings of the photoresist layer; (f) removing the remained photoresist; (g) removing or etching the copper seed layer and the adhesion layer not under the electroplated copper layer. The remained stacks of adhesion layer/seed layer/electroplated copper layer are used as the copper pads. The solder bumps may be formed by screen printing methods or by solder ball mounting methods, and then followed by the solder reflow process on either the exposed surfaces of TSVs for shallow TSVs, or, the electroplated copper pads. The material used for forming the solder bumps may be lead free solder. The lead-free solders in commercial use may contain tin, copper, silver, bismuth, indium, zinc, antimony, and traces of other metals. For example, the lead-free solder may be Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn Ag Cu Zn solder. The solder bumps are used for connecting or coupling the IC chips, for example, the dedicated I/O chip, of the logic drive to the external circuits or components external or outside of the logic drive, through micro copper pillars or bumps of the IC chips and through the FISIP, the SISIP and TSVs of the interposer or substrate. The height of the solder bumps is, for example, between 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 nm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater or taller than or equal to 75 μm, 50 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The largest dimension in cross-sections of the solder bumps (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape) is, for example, between 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between a solder bump and its nearest neighboring solder bump is, for example, between 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm. The solder bumps may be used for flip-package assembling the logic drive on or to a substrate, film or board, similar to the flip-chip assembly of the chip packaging technology, or the Chip-On-Film (COF) assembly technology used in the LCD driver packaging technology. The solder bump assembly process may comprise a solder flow or reflow process using solder flux or without using solder flux. The substrate, film or board used may be, for example, a Printed Circuit Board (PCB), a silicon substrate with interconnection schemes, a metal substrate with interconnection schemes, a glass substrate with interconnection schemes, a ceramic substrate with interconnection schemes, or a flexible film with interconnection schemes. The solder bumps may be located at the frontside (top) surface of the logic drive package with a layout in a Ball-Grid-Array (BGA) with the solder bumps at the peripheral area used for the signal I/Os, and the solder bumps at or near the central area used for the Power/Ground (P/G) I/Os. The signal bumps at the peripheral area may form ring or rings at the peripheral area near the edges of the logic drive package, with 1 ring, or 2, 3, 4, 5, 6 rings. The pitches of the signal I/Os at the peripheral area may be smaller than that of the P/G I/Os at or near the central area of the logic drive package.

Alternatively, copper pillars or bumps may be formed on or under the exposed bottom surfaces of the TSVs. For the description purpose, the wafer or panel is turned upside down, with the interposer at the top and the IC chips at the bottom. The frontside (the side with the transistors) of IC chips are now facing up, the molding compound and the backside of the IC chips are now at the bottom. The copper pillars or bumps are formed by performing an emboss copper process in the following process steps: (a) depositing and patterning an insulating layer, for example, a polymer layer, on the whole wafer or panel, and exposing the surfaces of the TSVs in the openings or holes of the insulating layer; (b) depositing an adhesion layer on or over the insulating layer, and the exposed surfaces of the TSVs in openings or holes of the insulating layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm, or 5 nm and 50 nm); (c) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 400 nm, or 10 nm and 200 nm); (d) patterning openings or holes in a photoresist layer for forming the copper pillars or bumps later, by coating, exposing and developing the photoresist layer, exposing the copper seed layer at the bottom of the openings or holes in the photoresist layer. The opening or hole in the photoresist layer overlaps the opening or hole in the insulating layer; and extends out of the opening or hole of the insulating layer, to an area (where the copper pillars or bumps are to be formed) around the opening or hole in the insulating layer; (e) then electroplating a copper layer (with a thickness, for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm) on or over the copper seed layer in the patterned openings or holes in the photoresist layer; (f) removing the remained photoresist; (g) removing or etching the copper seed layer and the adhesion layer not under the electroplated copper. The metals left or remained are used as the copper pillars or bumps. The copper pillars or bumps are used for connecting or coupling the chips, for example the dedicated I/O chip, of the logic drive to the external circuits or

components external or outside of the logic drive. The height of the copper pillars or bumps is, for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater or taller than or equal to 50 μm, 30 μm, 20 μm, 15 μm, or 5 μm. The largest dimension in a cross-section of the copper pillars or bumps (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape) is, for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between a copper pillar or bump and its nearest neighboring copper pillar or bump is, for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm. The copper bumps or pillars may be used for flip-package assembling the logic drive on or to a substrate, film or board, similar to the flip-chip assembly of the chip packaging technology, or similar to the Chip-On-Film (COF) assembly technology used in the LCD driver packaging technology. The substrate, film or board used may be, for example, a Printed Circuit Board (PCB), a silicon substrate with interconnection schemes, a metal substrate with interconnection schemes, a glass substrate with interconnection schemes, a ceramic substrate with interconnection schemes, or a flexible film with interconnection schemes. The substrate, film or board may comprise metal bonding pads or bumps at its surface; and the metal bonding pads or bumps may have a layer of solder on their top surface for use in the solder reflow or thermal compressing bonding process for bonding to the copper pillars or bumps on or of the logic drive package. The copper pillars or bumps may be located at the frontside (top) surface of the logic drive package with a layout of Bump or Pillar Grid-Array, with the copper pillars or bumps at the peripheral area used for the signal I/Os, and the pillars or bumps at or near the central area used for the Power/Ground (P/G) I/Os. The signal pillars or bumps at the peripheral area may form 1 ring, or 2, 3, 4, 5, or 6 rings along the edges of the logic drive package. The pitches of the signal I/Os at the peripheral area may be smaller than that of the P/G I/Os at or near the central area of the logic drive package.

Alternatively, gold bumps may be formed on or under the exposed bottom surfaces of the TSVs. For the description purpose, the wafer or panel is turned upside down, with the interposer or substrate at the top and the IC chips at the bottom. The frontside (the side with transistors) of IC chips are now facing up, and the molding compound and the backside of the IC chips are now at the bottom. The copper pillars or bumps are formed by performing an emboss copper process in the following process steps: (a) depositing and patterning an insulating layer, for example, a polymer layer, on the whole wafer or panel, and exposing the surfaces of the TSVs in the openings or holes of the insulating layer; (b) depositing an adhesion layer on or over the insulating layer, and the exposed surfaces of the TSVs in openings or holes of the insulating layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm, or 5 nm and 50 nm); (c) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a gold seed layer (with a thickness, for example, between 1 nm and 300 nm, or 1 nm and 50 nm); (d) patterning openings or holes in a photoresist layer for forming gold bumps in later processes, by coating, exposing and developing the photoresist layer, exposing the gold seed layer at the bottom of the openings or holes in the photoresist layer. The opening or hole in the photoresist layer overlaps the opening or holes in the insulating layer, and extends out of the opening or hole of the insulating layer, to an area (where the gold bumps are to be formed) around the opening or hole in the insulating layer; (e) then electroplating a gold layer (with a thickness, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm) on or over the gold seed layer in the patterned openings or holes of the photoresist layer; (f) removing the remained photoresist; (g) removing or etching the gold seed layer and the adhesion layer not under the electroplated gold layer. The metals (Ti (or TiN)/seed Au/Electroplated Au) left or remained are used as the gold bumps. The gold bumps are used for connecting or coupling the chips, for example, the dedicated I/O chip, of the logic drive to the external circuits or components external or outside of the logic drive. The height of the gold bumps is, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller or shorter than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The largest dimension in cross-sections of the gold bumps (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape) is, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between a gold bump and its nearest neighboring gold bump is, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The gold bumps may be used for flip-package assembling the logic drive on or to the substrate, film or board, similar to the flip-chip assembly of the chip packaging technology, or similar to the Chip-On-Film (COF) assembly technology used in the LCD driver packaging technology. The substrate, film or board used may be, for example, a Printed Circuit Board (PCB), a silicon substrate with interconnection schemes, a metal substrate with interconnection schemes, a glass substrate with interconnection schemes, a ceramic substrate with interconnection schemes, or a flexible film or tape with interconnection schemes. When the gold bumps are used for the COF technology, the gold bumps are thermal compress bonded to a flexible circuit film or tape. The COF assembly using gold bumps may provide very high I/Os in a small area. The current COF assembly technology using gold bumps may provide gold bumps with pitches smaller than 20 μm. The number of I/Os or gold bumps used for signal inputs or outputs at the peripheral area along 4 edges of a logic drive package, for example, for a square shaped logic drive package with 10 mm width and having two rings (or two rows) along the 4 edges, may be, for example, greater or equal to 5,000 (with 15 μm gold bump pitch), 4,000 (with 20 μm gold bump pitch), or 2,500 (with 15 μm gold bump pitch). The reason that 2 rings or rows are designed along the edges is for the easy fan-out from the logic drive package when a single-layer film with one-sided metal lines or traces is used. The metal pads on the flexible circuit film or tape have a gold layer or a solder layer at the top-most surfaces of the metal pads. The gold-to-gold thermal compressing bonding method is used for the COF assembly technology when the metal pad on the flexible circuit film or tape has a gold layer at its top surface; while the gold-to-solder thermal compressing bonding method is used for the COF assembly technology when the metal pad on the flexible circuit film or tape has a solder layer at its top surface. The gold bumps

may be located at the frontside (top) surface of the logic drive package with a layout in a Ball-Grid-Array (BGA), having the gold bumps at the peripheral area used for the signal I/Os, and the gold bumps at or near the central area used for the Power/Ground (P/G) I/Os. The signal bumps at the peripheral area may form ring or rings along the edges of the logic drive package, with 1 ring, or 2, 3, 4, 5, 6 rings. The pitches of the signal I/Os in the peripheral area may be smaller than that of the P/G I/Os at or near the central area of the logic drive package.

(5) Separating, cutting or dicing the finished wafer or panel, including separating, cutting or dicing through materials or structures between two neighboring logic drives. The material (for example, polymer) filling gaps between chips of two neighboring logic drives is separated, cut or diced to from individual unit of logic drives.

Another aspect of the disclosure provides the standard commodity COIP multi-chips packaged logic drive. The standard commodity COIP logic drive may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the logic drive. For example, the standard shape of the COIP-multi-chip packaged logic drive may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the COIP-multi-chip packaged logic drive may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Furthermore, the metal bumps or pillars on or under the interposer in the logic drive may be in a standard footprint, for example, in an area array of M×N with a standard dimension of pitch and space between neighboring two metal bumps or pillars. The location of each metal bumps or pillars is also at a standard location.

Another aspect of the disclosure provides the logic drive comprising plural single-layer-packaged logic drives; and each of single-layer-packaged logic drives in a multiple-chip package is as described and specified above. The multiple single-layer-packaged logic drives, for example, 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged logic drives, may be, for example, (1) flip-package assembled on a printed circuit board (PCB), high-density fine-line PCB, Ball-Grid-Array (BGA) substrate, or flexible circuit film or tape; or (2) stack assembled using the Package-on-Package (POP) assembling technology; that is assembling one single-layer-packaged logic drive on top of the other single-layer-packaged logic drive. The POP assembling technology may apply, for example, the Surface Mount Technology (SMT).

Another aspect of the disclosure provides a method for a single-layer-packaged logic drive suitable for the stacked POP assembling technology. The single-layer-packaged logic drive for use in the POP package assembling is fabricated as the same as the process steps and specifications of the COIP multi-chip packaged logic drive as described in the above paragraphs, except for forming Through-Package-Vias, or Through Polymer Vias (TPVs) in the gaps between chips in or of the logic drive, and/or in the peripheral area of the logic drive package and outside the edges of chips in or of the logic drive. The TPVs are used for connecting or coupling circuits or components at the frontside (top) of the logic drive to that at the backside (bottom) of the logic drive package, the frontside (top) is the side with the interposer or substrate, wherein the chips with the side having transistors are faced up. The single-layer-packaged logic drive with TPVs for use in the stacked logic drive may be in a standard format or having standard sizes. For example, the single-layer-packaged logic drive may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the single-layer-packaged logic drive. For example, the standard shape of the single-layer-packaged logic drive may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the single-layer-packaged logic drive may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. The logic drive with TPVs is formed by forming another set of copper pillars or bumps on or of the interposer, with the height of copper bump or pillar taller than that of the micro copper pad, bump or pillar on the SISIP and/or FISIP used for the flip-chip assembly (flip-chip micro copper pads, pillars or bumps) on or of the interposer. The process steps of forming the flip-chip micro copper pads, bumps or pillars are described or specified above. Here, the process steps of forming the flip-chip micro copper pads, bumps or pillars are described again, and followed by process steps of forming the TPVs (a) on or over the top surfaces of the top-most interconnection metal layer of SISIP, exposed in openings in the top-most insulating dielectric layer of the SISIP, or (b) on or over the top surfaces of the top-most interconnection metal layer of FISIP, exposed in openings in the top-most insulating dielectric layer of the FISIP, in the case when the SISIP is omitted. Performing a double emboss copper process to form (a) the micro copper pads, pillars or bumps for use in the flip-chip (IC chips) assembly, and (b) TPVs on or of the interposer as described below: (i) depositing whole wafer or panel an adhesion layer on or over the top-most insulting dielectric layer (of SISIP or FISIP) and the exposed top surfaces of the top-most interconnection layer of SISIP or FISIP at the bottom of the openings in top-most insulating layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm, or 5 nm and 50 nm); (ii) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 300 nm, or 10 nm and 120 nm); (iii) depositing a first photoresist layer and patterning openings or holes in the first photoresist layer, for forming the flip-chip micro copper pads, pillars or bumps later, by coating, exposing and developing the first photoresist layer, exposing the copper seed layer at the bottom of the openings or holes in the first photoresist layer. The first photoresist layer has a thickness, for example, between 1 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 2 μm and 15 μm, or 1 μm and 10 μm, or smaller than or equal to 60 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The opening or hole in the first photoresist layer

overlaps the opening or hole in the top-most insulating layer; and may extend out of the opening or hole of the insulating dielectric layer, to an area or a ring of the insulating dielectric layer around the opening or hole in the insulating dielectric layer; (iv) then electroplating a copper layer (with a thickness, for example, between 1 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, or 1 μm and 10 μm, or smaller than or equal to 60 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm) on or over the copper seed layer in the patterned openings or holes of the first photoresist layer; (v) removing the remained first photoresist, and exposed the surfaces of electroplated copper seed layer; (vi) depositing a second photoresist layer and patterning openings or holes in the second photoresist layer for forming the TPVs later by coating, exposing and developing the second photoresist layer, exposing the copper seed layer at the bottom of the openings or holes in the second photoresist layer. The second photoresist layer has a thickness, for example, between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm). The locations of the openings or holes in the second photoresist layer are in the gaps between chips in or of the logic drive, and/or in peripheral area of the logic drive package and outside the edges of chips in or of the logic drive, (the chips are to be flip-chip bonded to the flip-chip micro copper pads, pillars or bumps in latter processes); (vii) then electroplating a copper layer (with a thickness, for example, between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm) on or over the copper seed layer in the patterned openings or holes of the second photoresist layer; (viii) removing the remained second photoresist to expose the copper seed layer; (ix) removing or etching the copper seed layer and the adhesion layer not under the electroplated coppers for both TPVs and flip-chip micro copper pads, pillars or bumps. Alternatively, the micro copper pads, pillars or bumps may also be formed at the locations of TPVs while forming the flip-chip micro copper pads, pillars or bumps, process steps (i) to (v). In this case, in the process step (vi), in depositing a second photoresist layer and patterning openings or holes in the second photoresist layer for forming the TPVs later by coating, exposing and developing the second photoresist layer, the top surfaces of the micro copper pads, pillars or bumps at the locations of TPVs are exposed, and the top surfaces of the flip-chip micro copper pads, pillars or bumps are not exposed; and, in the process step (vii), electroplating a copper layer starts from the top surfaces of the micro copper pads, pillars or bumps on the exposed top surfaces of flip-chip micro copper pads, pillars or bumps in the openings or holes in the second photoresist layer. The height of TPVs (from the level of top surface of the top-most insulating layer to the level of the top surface of the copper pillars or bumps) is between, for example, 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater than or taller than or equal to 50 μm, 30 μm, 20 μm, 15 μm, or 5 μm. The largest dimension in a cross-section of the TPVs (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape) is between, for example, 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 150 μm, 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between a TPV and its nearest neighboring TPV is between, for example, 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm; or greater than or equal to 150 μm, 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm.

The wafer or panel of the interposer, with the FISP, SISIP, flip-chip micro copper pads, pillars and the tall copper pillars or bumps (TPVs), are then used for flip-chip assembling or bonding the IC chips to the flip-chip micro copper pads, pillars or bumps on or of the interposer for forming a logic drive. The process steps for forming the logic drive with TPVs are the same as described and specified above, including the process steps of flip-chip assembly or bonding, underfill, molding, molding compound planarization, silicon interposer thinning and formation of metal pads, pillars or bumps on or under the interposer. Some process steps are mentioned again below. In the Process Step (1) for forming the logic drive described above: Since there are TPVs between IC chips, a clearness of space is needed for the dispenser to perform the underfill dispensing. That is there are no TPVs in the path for dispensing underfill. In the Process Step (2) for forming the logic drive described above: A material, resin, or compound is applied to (i) fill gaps between chips, (ii) cover the backside surfaces of chips (with IC chips faced down), (iii) filling gaps between copper pillars or bumps (TPVs) on, over or of the interposer, (iv) cover the top surfaces of the copper pillars or bumps (TPVs) on or over the wafer or panel. Applying a CMP process, polishing process or grinding process to planarize the surface of the applied material, resin or compound to a level where (i) all top surfaces of copper pillars or bumps (TPVs) on or over the wafer or panel, are fully exposed. The exposed top surfaces of the TPVs may be used as metal pads for bonding other electronic components (on the top side of the logic drive, the IC chips are facing down) on the logic drive using the POP packaging method. Alternatively, solder bumps may be formed on the exposed top surfaces of the TPVs by the methods of screen printing or solder ball mounting. The solder bumps are used for connecting or assembly the logic drive to other electronic components on the top side of the logic drive (IC chips are facing down).

Another aspect of the disclosure provides a method for forming a stacked logic drive, for an example, by the following process steps: (i) providing a first single-layer-packaged logic drive, either separated or still in the wafer or panel format, with its copper pillars or bumps, solder bumps, or gold bumps faced down, and with the exposed copper pads of TPVs faced up (IC chips are facing down); (ii) Package-On-Package (POP) stacking assembling, by surface-mounting and/or flip-package methods, a second separated single-layer-packaged logic drive on top of the provided first single-layer-packaged logic drive. The surface-mounting process is similar to the Surface-Mount Technology (SMT) used in the assembly of components on or to the Printed Circuit Boards (PCB), by first printing solder or solder cream, or flux on the copper pads (top surfaces) of the TPVs, and then flip-package assembling, connecting or coupling the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive to the solder or solder cream or flux printed copper pads of TPVs of the first single-layer-packaged logic drive. The flip-package process is performed, similar to the Package-On-Package technology (POP) used in the IC stacking-package technology, by flip-package assembling, connecting or coupling the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive to the

copper pads of TPVs of the first single-layer-packaged logic drive. An underfill material may be filled in the gaps between the first and second single-layer-packaged logic drives. A third separated single-layer-packaged logic drive may be flip-package assembled, connected or coupled to the exposed copper pads of TPVs of the second single-layer-packaged logic drive. The Package-On-Package stacking assembling process may be repeated for assembling more separated single-layer-packaged logic drives (for example, up to more than or equal to a nth separated single-layer-packaged logic drive, wherein n is greater than or equal to 2, 3, 4, 5, 6, 7, 8) to form the finished stacking logic drive. When the first single-layer-packaged logic drives are in the separated format, they may be first flip-package assembled to a carrier or substrate, for example a PCB, or a BGA (Ball-Grid-Army) substrate, and then performing the POP processes, in the carrier or substrate format, to form stacked logic drives, and then cutting, dicing the carrier or substrate to obtain the separated finished stacked logic drives. When the first single-layer-packaged logic drives are still in the wafer or panel format, the wafer or panel may be used directly as the carrier or substrate for performing POP stacking processes, in the wafer or panel format, for forming the stacked logic drives. The wafer or panel is then cut or diced to obtain the separated stacked finished logic drives.

Another aspect of the disclosure provides a method for a single-layer-packaged logic drive suitable for the stacked POP assembling technology. The single-layer-packaged logic drive for use in the POP package assembling is fabricated as the same process steps and specifications of the COIP multi-chip packages described in the above paragraphs, except for forming a Backside metal Interconnection Scheme at the backside of the single-layer-packaged logic drive (abbreviated as BISD in below) and Through-Package-Vias, or Through Polymer Vias (TPVs) in the gaps between chips in or of the logic drive, and/or in the peripheral area of the logic drive package and outside the edges of chips in or of the logic drive (the side with transistors of the IC chips are facing down). The BISD may comprise metal lines, traces, or planes in multiple interconnection metal layers, and is formed on or over the backside of the IC chips (the side of IC chips with the transistors are facing down), the molding compound after the process step of planarization of the molding compound, and the exposed top surfaces of the TPVs. The BISD provides additional interconnection metal layer or layers at the backside of the logic drive package, and provides copper pads, copper pillars or solder bumps in an area array at the backside of the single-layer-packaged logic drive, including at locations directly and vertically over the IC chips of the logic drive (IC chips with the transistors side faced down). The TPVs are used for connecting or coupling circuits or components (for example, the FISIP and/or SISIP) of the interposer of the logic drive to that (for example, the BISD) at the backside of the logic drive package. The single-layer-packaged logic drive with TPVs and BISD for use in the stacked logic drive may be in a standard format or having standard sizes. For example, the single-layer-packaged logic drive may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses; and/or with a standard layout of the locations of the copper pads, copper pillars or solder bumps on or over the BISD. An industry standard may be set for the shape and dimensions of the single-layer-packaged logic drive. For example, the standard shape of the single-layer-packaged logic drive may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the single-layer-packaged logic drive may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. The logic drive with the BISD is formed by forming metal lines, traces, or planes on multiple interconnection metal layers on or over the backside of the IC chips (the side of IC chips with the transistors are faced down), the molding compound, and the exposed top surfaces of the TPVs, after the process step of planarization of the molding compound. The process steps for forming the BISD are: (a) depositing a bottom-most insulting dielectric layer, whole wafer or panel, on or over the exposed backside of the IC chips, molding compound and the exposed top surfaces of the TPVs. The bottom-most insulting dielectric layer may be a polymer material includes, for example, polyimide, Benzo-CycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer, or silicone. The bottom-most polymer insulating dielectric layer may be deposited by methods of spin-on coating, screen-printing, dispensing, or molding. The polymer material may be photosensitive, and may be used as photoresist as well for patterning openings in it for forming metal vias in it by following processes to be performed later; that is, the photosensitive polymer layer is coated, and exposed to light through a photomask, and then developed and etched to form openings in it. The openings in the bottom-most insulating dielectric layer expose the top surfaces of the TPVs. The bottom-most polymer layer (the insulating dielectric layer) is then cured at a temperature, for example, equal to or higher than 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. The thickness of the cured bottom-most polymer is between, for example, 3 μm and 50 μm, 3 μm and 30 μm, 3 μm and 20 or 3 μm and 15 μm; or thicker than or equal to 3 μm, 5 μm, 10 μm, 20 μm, or 30 μm; (b) performing an emboss copper process to form the metal vias in the openings of the cured bottom-most polymer insulating dielectric layer, and to form metal lines, traces or planes of a bottom-most interconnection metal layer of the BISD: (i) depositing whole wafer or panel an adhesion layer on or over the bottom-most insulting dielectric layer and the exposed top surfaces of TPVs at the bottom of the openings in the cured bottom-most polymer layer, for example, sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm, or 5 nm and 50 nm); (ii) then depositing an electroplating seed layer on or over the adhesion layer, for example, sputtering or CVD depositing a copper seed layer (with a thickness, for example, between 3 nm and 300 nm, or 10 nm and 120 nm); (iii) patterning trenches, openings or holes in a photoresist layer for forming metal lines, traces or planes of the bottom-most interconnection metal layer later by coating, exposing and developing the photoresist layer, exposing the copper seed layer at the bottom of the trenches, openings or holes in the photoresist layer. The trench, opening or hole in the photoresist layer overlaps the opening in the bottom-most insulating dielectric layer; and may extend out of the opening of the bottom-most insulating dielectric layer; (iv) then electroplating a copper layer (with a thickness, for example, between 5 μm and 80 μm, 5 μm and 50 μm, 5 μm and 40 μm,

5 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm) on or over the copper seed layer in the patterned trenches, openings or holes of the photoresist layer; (v) removing the remained photoresist; (vi) removing or etching the copper seed layer and the adhesion layer not under the electroplated copper. The metals (Ti (or TiN)/seed Cu/electroplated Cu) left or remained in the locations of trenches, openings or holes in the photoresist layer (note that the photoresist is removed now) are used as the metal lines, traces or planes of the bottom-most interconnection metal layer of the BISD; and the metals (Ti (or TiN)/seed Cu/electroplated Cu) left or remained in the openings of the bottom-most insulting dielectric layer are used as the metal vias in the bottom-most insulating dielectric layer of the BISD. The processes of forming the bottom-most insulating dielectric layer and openings in it; and the emboss copper processes for forming the metal vias in the bottom-most insulting dielectric layer and the metal lines, traces, or planes of the bottom-most interconnection metal layer, may be repeated to form a metal layer of multiple interconnection metal layers in or of the BISD; wherein the repeated bottom-most insulating dielectric layer is used as the inter-metal dielectric layer between two interconnection metal layers of the BISD, and the metal vias in the bottom-most insulating dielectric layer (now in the inter-metal dielectric layer) are used for connecting or coupling metal lines, traces, or planes of the two interconnection metal layers, above and below the metal vias, of the BISD. The top-most interconnection metal layer of the BISD is covered with a top-most insulating dielectric layer of the BISD. Forming copper pads, solder bumps, copper pillars on or over the top-most metal layer of BISD exposed in openings in the top-most insulating dielectric layer of BISD using emboss copper process as described and specifies in above. The locations of the copper pads, copper pillars or solder bumps are on or over: (a) the gaps between chips in or of the logic drive; (b) peripheral area of the logic drive package and outside the edges of chips in or of the logic drive; (c) and/or directly and vertically over the backside of the IC chips. The BISD may comprise 1 to 6 layers, or 2 to 5 layers of interconnection metal layers. The interconnection metal lines, traces or planes of the BISD have the adhesion layer (Ti or TiN, for example) and the copper seed layer only at the bottom, but not at the sidewalls of the metal lines or traces. The interconnection metal lines or traces of FISC and FISIP have the adhesion layer (Ti or TiN, for example) and the copper seed layer at both the bottom and the sidewalls of the metal lines or traces.

The thickness of the metal lines, traces or planes of the BISD is between, for example, 0.3 μm and 40 μm, 0.5 μm and 30 μm, 1 μm and 20 μm, 1 μm and 15 μm, 1 μm and 10 μm, or 0.5 μm to 5 μm, or thicker than or equal to 0.3 μm, 0.7 μm, 1 μm, 2 μm, 3 μm, 5 μm, 7 μm or 10 μm. The width of the metal lines or traces of the BISD is between, for example, 0.3 μm and 40 μm, 0.5 μm and 30 μm, 1 μm and 20 μm, 1 μm and 15 μm, 1 μm and 10 μm, or 0.5 μm to 5 μm, or wider than or equal to 0.3 μm, 0.7 μm, 1 μm, 2 μm, 3 μm, 5 μm, 7 μm or 10 μm. The thickness of the inter-metal dielectric layer of the BISD is between, for example, 0.3 μm and 50 μm, 0.3 μm and 30 μm, 0.5 μm and 20 μm, 1 μm and 10 μm, or 0.5 μm and 5 μm, or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm, 3 μm or 5 μm. The planes in a metal layer of interconnection metal layers of the BISD may be used for the power, ground planes of a power supply, and/or used as heat dissipaters or spreaders for the heat dissipation or spreading; wherein the metal thickness may be thicker, for example, between 5 μm and 50 μm, 5 μm and 30 μm, 5 μm and 20 μm, or 5 μm and 15 μm; or thicker than or equal to 5 μm, 10 μm, 20 μm, or 30 μm. The power, ground plane, and/or heat dissipater or spreader may be layout as interlaced or interleaved shaped structures in a plane of an interconnection metal layer of the BISD; or may be layout in a fork shape.

The BISD interconnection metal lines or traces of the single-layer-packaged logic drive are used: (a) for connecting or coupling the copper pads, copper pillars or solder bumps at the backside (top side, with the side having transistors of IC chips faced down) surface of the single-layer-packaged logic drive to their corresponding TPVs; and through the corresponding TPVs, the copper pads, copper pillars or solder bumps at the backside surface of the single-layer-packaged logic drive are connected or coupled to the metal lines or traces of the FISIP and/or SISIP of the interposer; and further through the micro copper pillars or bumps, the SISC, and the FISC of the IC chips for connecting or coupling to the transistors; (b) for connecting or coupling the copper pads, copper pillars or solder bumps at the backside (top side, with the side having transistors of IC chips faced down) surface of the single-layer-packaged logic drive to their corresponding TPVs; and through the corresponding TPVs, the copper pads, copper pillars or solder bumps at the backside surface of the single-layer-packaged logic drive are connected or coupled to the metal lines or traces of the FISIP and/or SISIP of the interposer, and are further through TSVs for connecting or coupling to copper pads, metal bumps or pillars, for example, solder bumps, copper pillars or gold bumps at the frontside (bottom side, with the side having transistors of IC chips faced down) surface of the single-layer-packaged logic drive. Therefore, the copper pads, copper pillars or solder bumps at the backside (top side, with the side having transistors of IC chips faced down) of the single-layer-packaged logic drive are connected or coupled to the copper pads, metal pillars or bumps at the frontside (bottom side, with the side having transistors of IC chips faced down) of the single-layer-packaged logic drive; (c) for connecting or coupling copper pads, copper pillars or solder bumps directly and vertically over a backside of a first FPGA chip (top side, with the side having transistors of the first FPGA chip faced down) of the single-layer-packaged logic drive to copper pads, copper pillars or solder bumps directly and vertically over a second FPGA chip (top side, with the side having transistors of the second FPGA chip faced down) of the single-layer-packaged logic drive by using an interconnection net or scheme of metal lines or traces in or of the BISD. The interconnection net or scheme may be connected or coupled to TPVs of the single-layer-packaged logic drive; (d) for connecting or coupling a copper pad, copper pillars or solder bumps directly and vertically over a FPGA chip of the single-layer-packaged logic drive to another copper pad, copper pillars or solder bumps, or multiple other copper pads, copper pillars or solder bumps directly and vertically over the same FPGA chip by using an interconnection net or scheme of metal lines or traces in or of the BISD. The interconnection net or scheme may be connected or coupled to the TPVs of the single-layer-packaged logic drive; (e) for the power or ground planes and/or heat dissipaters or spreaders.

Another aspect of the disclosure provides a method for forming a stacked logic drive using the single-layer-packaged logic drive with the BISD and TPVs. The stacked logic drive may be formed using the same or similar process steps, as described and specified above; for an example, by the following process steps: (i) providing a first single-layer-packaged logic drive with both TPVs and the BISD, either separated or still in the wafer or panel format, and with its

copper pillars or bumps, solder bumps, or gold bumps, on or under the TSVs, faced down, and with the exposed copper pads, copper pillars, or solder bumps, on or over the BISD, on its upside; (ii) Package-On-Package (POP) stacking assembling, by surface-mounting and/or flip-package methods, a second separated single-layer-packaged logic drive (also with both TPVs and the BISD) on top of the provided first single-layer-packaged logic drive. The surface-mounting process is similar to the Surface-Mount Technology (SMT) used in the assembly of components on or to the Printed Circuit Boards (PCB), by, for example, first printing solder or solder cream, or flux on the surfaces of the exposed copper pads, and then flip-package assembling, connecting or coupling the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive to the solder or solder cream or flux printed surfaces of the exposed copper pads of the first single-layer-packaged logic drive. The flip-package process is performed, similar to the Package-On-Package technology (POP) used in the IC stacking-package technology, by flip-package assembling, connecting or coupling the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive to the surfaces of copper pads of the first single-layer-packaged logic drive. Note that the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive bonded to the surfaces of copper pads of the first single-layer-packaged logic drive may be located directly and vertically over or above locations where IC chips are placed in the first single-layer-packaged logic drive; and that the copper pillars or bumps, solder bumps, or gold bumps on or of the second separated single-layer-packaged logic drive bonded to the surfaces of copper pads of the first single-layer-packaged logic drive may be located directly and vertically under or below locations where IC chips are placed in the second single-layer-packaged logic drive. An underfill material may be filled in the gaps between the first and the second single-layer-packaged logic drives. A third separated single-layer-packaged logic drive (also with both TPVs and the BISD) may be flip-package assembled, connected or coupled to the copper pads (on or over the BISD) of the second single-layer-packaged logic drive. The Package-On-Package stacking assembling process may be repeated for assembling more separated single-layer-packaged logic drives (for example, up to more than or equal to a nth separated single-layer-packaged logic drive, wherein n is greater than or equal to 2, 3, 4, 5, 6, 7, 8) to form the finished stacking logic drive. When the first single-layer-packaged logic drives are in the separated format, they may be first flip-package assembled to a carrier or substrate, for example a PCB, or a BGA (Ball-Grid-Army) substrate, and then performing the POP processes, in the carrier or substrate format, to form stacked logic drives, and then cutting, dicing the carrier or substrate to obtain the separated finished stacked logic drives. When the first single-layer-packaged logic drives are still in the wafer or panel format, the wafer or panel may be used directly as the carrier or substrate for performing POP stacking processes, in the wafer or panel format, for forming the stacked logic drives. The wafer or panel is then cut or diced to obtain the separated stacked finished logic drives.

Another aspect of the disclosure provides varieties of interconnection alternatives for the TPVs of a single-layer-packaged logic drive: (a) the TPV may be designed and formed as a through via by stacking the TPV directly over the stacked metal layers/vias of SISIP and/or FISIP and directly over the TSV in the interposer or substrate. The TSV is now used as a through via for connecting a single-layer-packaged logic drive above the single-layer-packaged logic drive, and a single-layer-packaged logic drive below the single-layer-packaged logic drive; without connecting or coupled to the FISIP, the SISIP or micro copper pillars or bumps on or of any IC chip of the single-layer-packaged logic drive. In this case, a stacked structure is formed, from top to bottom: (i) copper pad, copper pillar or solder bump; (ii) stacked interconnection layers and metal vias in the dielectric layer of the BISD; (iii) the TPV; (iv) stacked interconnection layers and metal vias in the dielectric layer of the FISIP and/or SISIP; (v) TSV in the interposer or substrate; (vi) copper pad, metal bump, solder bump, copper pillar, or gold bump on or under bottom surface of the TSV. Alternatively, the stacked TPV/metal layers and vias/TSV may be used as a thermal conduction via; (b) the TPV is stacked as a through TPV as in (a), but is connected or coupled to the FISP, the SISIP and/or micro copper pillars or bumps on or of one or more IC chips of the single-layer-packaged logic drive, through the metal lines or traces of the FISIP and/or FISIP; (c) the TPV is only stacked at the top portion, but not at the bottom portion. In this case, a structure for the TPV connection is formed, from top to bottom: (i) copper pad, copper pillar or solder bump; (ii) stacked interconnection layers and metal vias in the dielectric layer of the BISD; (iii) the TPV; (iv) the bottom of the TPV is connected or coupled to the FISP, the SISIP or micro copper pillars or bumps on or of one or more IC chips of the single-layer-packaged logic drive, through the interconnection metal layers and metal vias in the dielectric layer of the SISIP and/or FISIP. Wherein (1) a copper pad, metal bump, solder bumps, copper pillar or gold bump, directly under the bottom of the TPV, is not connected or coupled to the TPV; (2) a copper pad, metal bump, solder bump, copper pillar or gold bump on and under the interposer connected or coupled to the bottom of the TPV (through FISIP and/or SISIP) is at a location not directly and vertically under the bottom of the TPV; (d) a structure for the TPV connection is formed, from top to bottom: (i) a copper pad, copper pillar or solder bump (on the BISD) connected or coupled to the top surface of the TPV, and may be at a location directly and vertically over the backside of the IC chips; (ii) the copper pad, copper pillar or solder bump (on the BISD) is connected or coupled to the top surface of the TPV (which is located between the gaps of chips or at the peripheral area where no chip is placed) through the interconnection metal layers and metal vias in the dielectric layer of the BISD; (iii) the TPV; (iv) the bottom of the TPV is connected or coupled to the FISIP, the SISIP, or the micro copper pillars or bumps on or of one or more IC chips of the single-layer-packaged logic drive through the interconnection metal layers and metal vias in the dielectric layer of the SISIP and/or FISIP; (v) TSV (in the interposer or substrate) and a metal pad, pillar or bump (on or under the TSV) connected or coupled to the bottom of the TPV, wherein the TSV or the metal pad, bump or pillar may be at a location not directly under the bottom of the TPV; (e) a structure for the TPV connection is formed, from top to bottom: (i) a copper pad, copper pillar or solder bump (on the BISD) directly or vertically over the backside of an IC chip of the single-layer-packaged logic drive; (ii) the copper pad, copper pillar or solder bump on the BISD is connected or coupled to the top surface of the TPV (which is located between the gaps of chips or at the peripheral area where no chip is placed) through the interconnection metal layers and metal vias in the dielectric layer of the BISD; (iii) the TPV; (iv) the bottom of the TPV is connected or coupled to the

FISIP, the SISIP of interposer; and/or micro copper pillars or bumps, SISC, or FISC on or of one or more IC chips of the single-layer-packaged logic drive through the interconnection metal layers and metal vias in the dielectric layer of the CISIP and/or FISIP. Wherein no TSV (in the interposer or substrate) and no metal pad, pillar or bump (on or under the TSV) are connected or coupled to the bottom of the TPV.

Another aspect of the disclosure provides an interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP of the single-layer-packaged logic drive used for connecting or coupling the transistors, the FISC, the SISC and/or the micro copper pillars or bumps of an FPGA IC chip or multiple FPGA IC chips packaged in the single-layer-packaged logic drive, but the interconnection net or scheme is not connected or coupled to the circuits or components outside or external to the single-layer-packaged logic drive. That is, no metal pads, pillars or bumps (copper pads, pillars or bumps, solder bumps, or gold bumps) on or under the interposer of the single-layer-packaged logic drive is connected to the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP, and no copper pads, copper pillars or solder bumps on or over the BISD is connected or coupled to the interconnection net or scheme of metal lines or traces in or of the FISIP and/or SISIP.

Another aspect of the disclosure provides the logic drive in a multi-chip package format further comprising one or plural Dedicated Programmable Interconnection (DPI) chip or chips. The DPI chip comprises 5T or 6T SRAM cells and cross-point switches, and is used for programming the interconnection between circuits or interconnections of the standard commodity FPGA chips. The programmable interconnections comprise interconnection metal lines or traces on, over or of the interposer (the FISIP and/or SISIP) between the standard commodity FPGA chips, with cross-point switch circuits in the middle of interconnection metal lines or traces of the FISIP and/or SISIP. For example, n metal lines or traces of the FISIP and/or SISIP are input to a cross-point switch circuit, and m metal lines or traces of the FISIP and/or SISIP are output from the switch circuit. The cross-point switch circuit is designed such that each of the n metal lines or traces of the FISIP and/or SISIP can be programed to connect to anyone of them metal lines or traces of the FISIP and/or SISIP. The cross-point switch circuit may be controlled by the programming code stored in, for example, an SRAM cell in or of the DPI chip. The SRAM cell may comprise 6-Transistors (6T), with two transfer (write) transistors and 4 data-latch transistors. The two transfer (write) transistors are used for writing the programing code or data into the two storage or latch nodes of the 4 data-latch transistors. Alternatively, the SRAM cell may comprise 5-Transistors (5T), with a transfer (write) transistor and 4 data-latch transistors. The transfer (write) transistor is used for writing the programing code or data into the two storage or latch nodes of the 4 data-latch transistors. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection of metal lines or traces of the FISIP and/or SISIP. The cross-point switches are the same as that described in the standard commodity FPGA IC chips. The details of various types of cross-point switches are as specified or described in the paragraphs of FPGA IC chips. The cross-point switches may comprise: (1) n-type and p-type transistor pair circuits; or (2) multiplexers and switch buffers. In (1), when the data latched in the 5T or 6T SRAM cell is programmed at 1, a pass/no-pass circuit comprising a n-type and p-type transistor pair is on, and the two metal lines or traces of the FISIP and/or SISIP connected to two terminals of the pass-no-pass circuit (the source and drain of the transistor pair, respectively), are connected; while the data latched in the 5T or 6T SRAM cell is programmed at 0, a pass/no-pass circuit comprising a n-type and p-type transistor pair circuit is off, and the two metal lines or traces of the FISIP and/or SISIP connected to two terminals of the pass/no-pass circuit (the source and drain of the transistor pair, respectively), are die-connected. In (2), the multiplexer selects one from n inputs as its output, and then input its output to the switch buffer. When the data latched in the 5T or 6T SRAM cell is programmed at 1, the control N-MOS transistor and the control P-MOS transistor in the switch buffer are on, the data on the input metal line is passing to the output metal line of the cross-point switch, and the two metal lines or traces of the FISIP and/or SISIP connected to two terminals of the cross-point switch are coupled or connected; while the data latched in the 5T or 6T SRAM cell is programmed at 0, the control N-MOS transistor and the control P-MOS transistor in the switch buffer are off, the data on the input metal line is not passing to the output metal line of the cross-point switch, and the two metal lines or traces of the FISIP and/or SISIP connected to two terminals of the cross-point switch are not coupled or dis-connected. The DPI chip comprises 5T or 6T SRAM cells and cross-point switches used for programmable interconnection of metal lines or traces of the FISIP and/or SISIP between the standard commodity FPGA chips in the logic drive. Alternatively, the DPI chip comprising 5T or 6T SRAM cells and cross-point switches may be used for programmable interconnection of metal lines or traces of the FISIP and/or SISIP between the standard commodity FPGA chips and the TPVs (for example, the bottom surfaces of the TPVs) in the logic drive, in the same or similar method as described above. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection between (i) a first metal line, trace, or net of the FISIP and/or SISIP, connecting to one or more micro copper pillars or bumps on or over one or more the IC chips of the logic drive, and/or to one or more metal pads, pillars or bumps on or under the TSVs of the interposer, and (ii) a second metal line, trace or net of the FISIP and/or SISIP, connecting or coupling to a TPV (for example, the bottom surface of the TPV), in a same or similar method described above. With this aspect of disclosure, TPVs are programmable; in other words, this aspect of disclosure provides programmable TPVs. The programmable TPVs may, alternatively, use the programmable interconnection, comprising 5T or 6T SRAM cells and cross-point switches, on or of the FPGA chips in or of the logic drive. The programmable TPV may be, by (software) programming, (i) connected or coupled to one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) of the logic drive, and/or (ii) connected or coupled to one or more metal pads, pillars or bumps on or under TSVs of the interposer of the logic drive. When a metal pad, bump or pillar (on or over the BISD) at the backside of the logic drive is connected to the programmable TPV, the copper pad, copper pillar or solder bump (on or over the BISD) becomes a programmable metal bump or pillar (on or over the BISD). The programmable metal pad, bump or pillar (on or over the BISD) at the backside of the logic drive may be connected or coupled to, by programming and through the programmable TPV, (i) one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) at the frontside (the side with the transistors) of the one or more IC chips of the logic drive,

and/or (ii) one or more metal pads, pillars or bumps on or under the TSVs of the interposer of the logic drive. Alternatively, the DPI chip comprises 5T or 6T SRAM cells and cross-point switches may be used for programmable interconnection of metal lines or traces of the FISIP and/or SISIP between the metal pads, pillars or bumps (copper pads, copper pillars or bumps, solder bumps or gold bumps) on or under TSVs of the interposer of the logic drive and one or more micro copper pillars or bumps on or of one or more IC chips of the logic drive, in a same or similar method as described above. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection between (i) a first metal line, trace or net of the FISIP and/or SISIP, connecting to one or more micro copper pillars or bumps on or of one or more IC chips of the logic drive, and/or to the metal pads, pillars or bumps on or under (the TSVs of) the interposer, and (ii) a second metal line, trace or net of the FISIP and/or SISIP, connecting or coupling to the metal pad, pillar or bump on or under the interposer, in a same or similar method described above. With this aspect of disclosure, metal pads, pillars or bumps on or under the interposer are programmable; in other words, this aspect of disclosure provides programmable metal pads, pillars or bumps on or under the interposer. The programmable metal pad, pillar or bump on or under the interposer may, alternatively, use the programmable interconnection, comprising 5T or 6T SRAM cells and cross-point switches, on or of the FPGA chips in or of the logic drive. The programmable metal pad, pillar or bump on or under the interposer may be connected or coupled, by programming, to one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) of the logic drive.

The DPI chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 35 nm, 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, 500 nm, or alternatively including advanced semiconductor technology nodes or generations, for example, a semiconductor node or generation more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm. The semiconductor technology node or generation used in the DPI chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the DPI chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the DPI chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the DPI chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the DPI chip may use the Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET.

Another aspect of the disclosure provides the logic drive in a multi-chip package format further comprising one or plural dedicated programmable interconnection and Cache SRAM (DPICSRAM) chip or chips. The DPICSRAM chip comprises (i) 5T or 6T SRAM cells and cross-point switches used for programming interconnection of the metal lines or traces of the FISIP and/or SISIP on, over or of the interposer, and therefore programming the interconnection between circuits or interconnections of the standard commodity FPGA chips in or of the logic drive, and (ii) the conventional 6T SRAM cells used for cache memory. The programmable interconnections of the 5T or 6T cells and cross-point switches are described and specified above. Alternatively, the DPICSRAM chip comprising 5T or 6T SRAM cells and cross-point switches may be used for programmable interconnection of metal lines or traces of the FISIP and/or SISIP between the standard commodity FPGA chips and the TPVs (for example, the bottom surfaces of the TPVs) in the logic drive, in the same or similar method as described above. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection between (i) a first metal line, trace, or net of the FISIP and/or SISIP, connecting to one or more micro copper pillars or bumps on or over one or more the IC chips of the logic drive, and/or to one or more metal pads, pillars or bumps on or under (the TSVs of) the interposer of the logic drive, and (ii) a second metal line, trace or net of the FISIP and/or SISIP, connecting or coupling to TPV (for example, the bottom surface of the TPV), in a same or similar method described above. With this aspect of disclosure, TPVs are programmable; in other words, this aspect of disclosure provides programmable TPVs. The programmable TPVs may, alternatively, use the programmable interconnection, comprising 5T or 6T SRAM cells and cross-point switches, on or of the FPGA chips in or of the logic drive. The programmable TPV may be, by (software) programming, (i) connected or coupled to one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) of the logic drive, and/or (ii) connected or coupled to one or more metal pads, pillars or bumps on or over the BISD of the logic drive. When a metal pad, pillar or bump on or over the BISD at the backside of the logic drive is connected to the programmable TPV, the metal pad, pillar or bump on or over the BISD becomes a programmable metal pad, pillar or bump on or over the BISD. The programmable metal pad, pillar or bump on or over the BISD at the backside of the logic drive may be connected or coupled to, by programming and through the programmable TPV, (i) one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) at the frontside (the bottom side of the IC chips, here the IC chips are faced down) of the logic drive, and/or (ii) one or more metal pads, pillars or bumps on or under the TSVs of the interposer of the logic drive. Alternatively, the DPICSRAM chip comprises 5T or 6T SRAM cells and cross-point switches may be used for programmable interconnection of metal lines or traces of the FISIP and/or SISIP between the metal pads, pillars or bumps (copper pads, pillars or bumps, solder bumps or gold bumps) on or under the interposer of the logic drive and one or more micro copper pillars or bumps on or of one or more IC chips of the logic drive, in a same or similar method as described above. The stored (programming) data in the 5T or 6T SRAM cell is used to program the connection or not-connection between (i) a first metal line, trace or net of the FISIP and/or SISIP, connecting to one or more micro copper pillars or bumps on or of one or more IC chips of the logic drive, and/or to the metal pads, pillars or bumps on or under the interposer, and (ii) a second metal line, trace or net of the FISIP and/or SISIP, connecting or coupling to the metal pad, pillar or bump on or under the interposer, in a same or similar method described above. With this aspect of disclosure, metal pads, pillars or bumps on or under the interposer are programmable; in other words, this aspect of disclosure

provides programmable metal pads, pillars or bumps on or under the interposer. The programmable metal pads, pillars or bumps on or under the interposer may, alternatively, use the programmable interconnection, comprising 5T or 6T SRAM cells and cross-point switches, on or of the FPGA chips in or of the logic drive. The programmable metal pads, pillars or bumps on or under the interposer may be connected or coupled, by programming, to one or more micro copper pillars or bumps of one or more IC chips (therefor to the metal lines or traces of the SISC and/or the FISC, and/or the transistors) of the logic drive.

The 6T SRAM cell used as cache memory for data latch or storage comprises 2 transistors for bit and bit-bar data transfer, and 4 data-latch transistors for a data latch or storage nodes. The 6T SRAM cache memory cells provide the 2 transfer transistors for writing data into them and reading data stored in them. A sense amplifier is required for reading (amplifying or detecting) data from the cache memory cells. In comparison, the 5T or 6T SRAM cells used for the programmable interconnection or for the LUTs may not require the reading step, and no sense amplifier is required for sensing the data from the SRAM cell. The DPICSRAM chip comprises 6T SRAM cells for use as cache memory to store data during the processing or computing of the chips of the logic drive. The DPICSRAM chip is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 35 nm, 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, 500 nm, or alternatively including advanced semiconductor technology nodes or generations, for example, a semiconductor node or generation more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm. The semiconductor technology node or generation used in the DPICSRAM chip is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in the standard commodity FPGA IC chips packaged in the same logic drive. Transistors used in the DPICSRAM chip may be a FINFET, a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Transistors used in the DPICSRAM chip may be different from that used in the standard commodity FPGA IC chips packaged in the same logic drive; for example, the DPICSRAM chip may use the conventional MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET; or the DPICSRAM chip may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while the standard commodity FPGA IC chips packaged in the same logic drive may use the FINFET.

Another aspect of the disclosure provides a standardized interposer, in the wafer form or panel form in the stock or in the inventory for use in the later processing in forming the standard commodity logic drive, as described and specified above. The standardized interposer comprises a fixed physical layout or design of the TSVs in the interposer; and a fixed design and layout of the TPVs on or over the interposer if included in the interposer. The locations or coordinates of the TSVs and the TPVs in or on the interposer are the same or of certain types of standards of layouts and designs for the standard interposers. For example, connection schemes between TSVs and the TPVs, are the same for each of the standard commodity interposers. Furthermore, the design or interconnection of the FISIP and/or SISIP, and the layout or coordinates of the micro copper pads, pillars or bumps on or over the SISIP and/or FISIP are the same or of certain types of standards of layouts and designs for the standard interposers. The standard commodity interposer in the stock or inventory is then used for forming the standard commodity logic drive by the process described and specified above, including process steps: (1) flip-chip assembling or bonding the IC chips on or to the standard interposer with the side or surface of the chip with transistors faced down; (2) Applying a material, resin, or compound to fill the gaps between chips and cover the backside surfaces of IC chips by methods, for example, spin-on coating, screen-printing, dispensing or molding in the wafer or panel format. Applying a CMP process, polishing process, or backside grinding process to planarize the surface of the applied material, resin or compound to a level where the top surfaces of all bumps or pillars (TPVs) on or of the interposers and the backside of IC chips are fully exposed; (3) forming the BISD; and (4) forming the metal pads, pillars or bumps on or over the BISD. The standard commodity interposer or substrates with a fixed layout or design may be used and customized, by software coding or programming, using the programmable TPVs, and/or programmable metal pads, pillars or bumps on or under the interposer (programmable TSVs) as described and specified above, for different applications. As described above, the data installed or programed in the 5T or 6T SRAM cells of the DPI or DPICSRAM chips may be used for programmable TPVs and/or programmable metal pads, pillars or bumps under the TSVs of the interposer (programmable TSVs). The data installed or programed in the 5T or 6T SRAM cells of the FPGA chips may be alternatively used for programmable TPVs and/or programmable metal pads, pillars or bumps on or under the interposer (programmable TSVs).

Another aspect of the disclosure provides the standardized commodity logic drive (for example, the single-layer-packaged logic drive) with a fixed design, layout or footprint of (i) the metal pads, pillars or bumps (copper pillars or bumps, solder bumps or gold bumps) on or under the TSVs of the interposer, and (ii) copper pads, copper pillars or solder bumps (on or over the BISD) on the backside (top side, the side with the transistors of IC chips are faced down) of the standard commodity logic drive. The standardized commodity logic drive may be used, customized for different applications by software coding or programming, using the programmable metal pads, pillars or bumps on or under the TSVs of the interposer, and/or using programmable copper pads, copper pillars or bumps, or solder bumps on or over the BISD (through programmable TPVs), as described and specified above, for different applications. As described above, the codes of the software programs are loaded, installed or programed in the 5T or 6T SRAM cells of the DPI or DPICSRAM chip for controlling cross-point switches of the same DPI or DPICSRAM chip in or of the standard commodity logic drive for different varieties of applications. Alternatively, the codes of the software programs are loaded, installed or programed in the 5T or 6T SRAM cells of one of the FPGA IC chips, in or of the logic drive in or of the standard commodity logic drive, for controlling cross-point switches of the same one FPGA IC chip for different varieties of applications. Each of the standard commodity logic drives with the same design, layout or footprint of the metal pads, pillars or bumps on or under the TSVs of the interposer, and the copper pads, copper pillars or bumps, or solder bumps on or over the BISD may be used for different applications, purposes or functions, by software coding or programming, using the programmable metal pads, pillars or bumps on or under the

TSVs of the interposer, and/or programmable copper pads, copper pillars or bumps, or solder bumps on or over the BISD (through programmable TPVs) of the logic drive.

Another aspect of the disclosure provides the logic drive, either in the single-layer-packaged or in a stacked format, comprising IC chips, logic blocks (comprising LUTs, cross-point switches, multiplexers, switch buffers, logic circuits, switch buffers, logic gates, and/or computing circuits) and/or memory cells or arrays, immersing in a super-rich interconnection scheme or environment. The logic blocks (comprising LUTs, cross-point switches, multiplexers, logic circuits, logic gates, and/or computing circuits) and/or memory cells or arrays of each of the multiple standard commodity FPGA IC chips (and/or other IC chips in the single-layer-packaged or in a stacked logic drive) are immersed in a programmable 3D Immersive IC Interconnection Environment (DIE). The programmable 3D ME on, in, or of the logic drive package provides the super-rich interconnection scheme or environment, comprising (1) the FISC, the SISC and micro copper pillars or bumps on, in or of the IC chips, (2) the FISIP and/or SISIP, TPVs, micro copper pillars or bumps, and TSVs of the interposer or substrate, (3) metal pads, pillars or bumps on or under the TSVs of the interposer, (4) the BISD, and (5) copper pads, copper pillars or bumps, or solder bumps on or over the BISD. The programmable 3D IIIE provides a programmable 3-Dimension (3D) super-rich interconnection scheme or system: (1) the FISC, the SISC, the FISIP and/or SISIP, and/or the BISD provide the interconnection scheme or system in the x-y directions for interconnecting or coupling the logic blocks and/or memory cells or arrays in or of a same FPGA IC chip, or in or of different FPGA chips in or of the single-layer-packaged logic drive. The interconnection of metal lines or traces in the interconnection scheme or system in the x-y directions is programmable; (2) The metal structures including (i) metal vias in the FISC and SISC, (ii) micro pillars or bumps on the SISC, (i) metal vias in the FISIP and SISIP, (iv) micro pillars or bumps on the SISIP, (v) TSVs, (vi) metal pads, pillars or bumps on or under the TSVs of the interposer, (vii) TPVs, (viii) metal vias in the BISD, and/or (ix) copper pads, copper pillars or bumps, or solder bumps on or over the BISD, provide the interconnection scheme or system in the z direction for interconnecting or coupling the logic blocks, and/or memory cells or arrays in or of different FPGA chips in or of different single-layer-packaged logic drives stacking-packaged in the stacked logic drive. The interconnection of the metal structures in the interconnection scheme or system in the z direction is also programmable. The programmable 3D IIIE provides an almost unlimited number of the transistors or logic blocks, interconnection metal lines or traces, and memory cells/switches at an extremely low cost. The programmable 3D ME similar or analogous to the human brain: (i) transistors and/or logic blocks (comprising logic gates, logic circuits, computing operators, computing circuits, LUTs, and/or cross-point switches) are similar or analogous to the neurons (cell bodies) or the nerve cells; (ii) the metal lines or traces of the FISC and/or the SISC are similar or analogous to the dendrites connecting to the neurons (cell bodies) or nerve cells. The micro pillars or bumps connecting to the receivers for the inputs of the logic blocks (comprising, for example, logic gates, logic circuits, computing operators, computing circuits, LUTs, and/or cross-point switches) in or of the FPGA IC chips are similar or analogous to the post-synaptic cells at the ends of the dendrites; (iii) the long distance connects formed by metal lines or traces of the FISC, the SISC, the FISIP and/or SISIP, and/or the BISD, and the metal vias, metal pads, pillars or bumps, including the micro copper pillars or bumps on the SISC, TSVs, metal pads, pillars or bumps on or under the TSVs of the interposer, TPVs, and/or copper pads, copper pads, pillars or bumps, or solder bumps on or over the BISD, are similar or analogous to the axons connecting to the neurons (cell bodies) or nerve cells. The micro pillars or bumps connecting the drivers or transmitters for the outputs of the logic blocks (comprising, for example, logic gates, logic circuits, computing operators, computing circuits, LUTs, and/or cross-point switches) in or of the FPGA IC chips are similar or analogous to the pre-synaptic cells at the axons' terminals.

Another aspect of the disclosure provides the programmable 3D IIIE with similar or analogous connections, interconnection and/or functions of a human brain: (1) transistors and/or logic blocks (comprising, for example, logic gates, logic circuits, computing operators, computing circuits, LUTs, and/or cross-point switches) are similar or analogous to the neurons (cell bodies) or the nerve cells; (2) The interconnection schemes and/or structures of the logic drives are similar or analogous to the axons or dendrites connecting or coupling to the neurons (cell bodies) or the nerve cells. The interconnection schemes and/or structures of the logic drives comprise (i) metal lines or traces of the FISC, the SISC, the FISIP and/or SISIP, and/or BISD and/or (ii) the micro copper pillars or bumps on the SISC, TSVs, metal pads, pillars or bumps on or under the TSVs of the interposer or substrate, TPVs, and/or copper pads, copper pillars or bumps, or solder bumps on or over the BISD. An axon-like interconnection scheme and/or structure of the logic drive is connected to the driving or transmitting output (a driver) of a logic unit or operator; and having a scheme or structure like a tree, comprising: (i) a trunk or stem connecting to the logic unit or operator; (ii) multiple branches branching from the stem, and the terminal of each branch may be connected or coupled to other logic units or operators. Programmable cross-point switches (5T or 6T SRAM cells/switches of the FPGA IC chips and/or of the DPLs or DPICSRAMs) are used to control the connection or not-connection between the stem and each of the branches; (iii) sub-branches branching form the branches, and the terminal of each sub-branch may be connected or coupled to other logic units or operators. Programmable cross-point switches (5T or 6T SRAM cells/switches of the FPGA IC chips and/or of the DPIs or DPICSRAMs) are used to control the connection or not-connection between a branch and each of its sub-branches. A dendrite-like interconnection scheme and/or structure of the logic drive is connected to the receiving or sensing input (a receiver) of a logic unit or operator; and having a scheme or structure like a shrub or bush comprising: (i) a short stem connecting to the logic unit or operator; (ii) multiple branches branching from the stem. Programmable switches (5T or 6T SRAM cells/switches of the FPGA IC chips and/or of the DPIs or DPICSRAMs) are used to control the connection or not-connection between the stem and each of its branches. There are multiple dendrite-like interconnection scheme or structures connecting or coupling to the logic unit or operator. The end of each branch of the dendrite-like interconnection scheme or structure is connected or coupled to the terminal of a branch or sub-branch of the axon-like interconnection scheme or structure. The dendrite-like interconnection scheme and/or structure of the logic drive may comprise the FISCs and SISCs of the FPGA IC chips.

Another aspect of the disclosure provides a reconfigurable plastic (elastic) and/or integral architecture for system/machine computing or processing using integral and alterable memory units and logic units, in addition to the sequential,

parallel, pipelined or Von Neumann computing or processing system architecture and/or algorithm. The disclosure provides a programmable logic device (the logic drive) with plasticity (or elasticity) and integrality, comprising integral and alterable memory units and logic units, to alter or reconfigure logic functions and/or computing (or processing) architecture (or algorithm), and/or the memories (data or information) in the memory units. The properties of the plasticity (or elasticity) and integrality of the logic drive is similar or analogous to that of a human brain. The brain or nerves have plasticity (or elasticity) and integrality. Many aspects of brain or nerves can be altered (or are "plastic" or "elastic") and reconfigured through adulthood. The logic drives (or FPGA IC chips) described and specified above provide capabilities to alter or reconfigure the logic functions and/or computing (or processing) architecture (or algorithm) for a given fixed hardware using the memories (data or information) stored in the near-by Programing Memory cells (PM). In the logic drive (or FPGA IC chips), the memories (data or information) stored in the memory cells of PM are used for altering or reconfiguring the logic functions and/or computing/processing architecture (or algorithm), while some other memories stored in the memory cells are just used for data or information (Data Memory cells, DM).

The plasticity (or elasticity) and integrality of the logic drive are based on events. For the nth Event (E_n), the nth state (S_n) of the nth integral unit (IU_n) after the nth Event of the logic drive comprises the logic, PM and DM at the nth states, L_n, PM_n and DM_n, wherein n is a positive integer, 1, 2, 3, ... S_n is a function of IU_n, L_n, PM_n and DM_n, that is S_n (IU_n, L_n, PM_n, DM_n). The nth integral unit IU_n may comprise various logic blocks, various PM memory cells (in terms of number, quantity and address/location) with various memories (in terms of content, data or information), and various DM memory cells (in terms of number, quantity and address/location) with various memories (in terms of content, data or information) for a specific logic function, a specific set of PM and DM, different from other integral units. The nth state (S_n) and the nth integral unit (IU_n) are generated based on previous events occurred before the nth event (E_n).

Some events may be with great magnitude of impact and are categorized as Grand Events (GE). If the nth event is characterized as a GE, the nth state S_n (IU_n, L_n, PM_n, DM_n) may be reconfigured into a new state S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}), just like the human brain reconfigures the brain during the deep sleep. The newly generated states may become long term memories. The new $(n+1)^{th}$ state (S_{n+1}) for a new $(n+1)^{th}$ integral unit (IU_{n+1}) are generated based on algorithm and criteria for a grand reconfiguration after a Grand Event. As an example, the algorithm and criteria are described as follows: When the Event n (E_n) is quite different in magnitude from previous n−1 events, the E_n is categorized as a Grand Event, and resulted in a $(n+1)^{th}$ state S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}) from the nth state S_n (IU_n, L_n, PM_n, DM_n). After the Grand Event E_n, the machine/system perform a Grand Reconfiguration with some certain given criteria. The Grand Reconfiguration comprises condense or concise processes and learning processes:

I. Condense or Concise Processes:

A) DM reconfiguration: (1) The machine/system checks the DM_n to find identical memories, and then keeping only one memory of all identical memories, deleting all other identical memories; and (2) The machine/system checks the DM_n to find similar memories (similarity within a given percentage x %, for example, is equal to or smaller than 2%, 3%, 5% or 10%), and keeping only one or two memories of all similar memories, deleting all other similar memories; alternatively, a representative memory (data or information, having a specific range) of all similar memories may be generated and kept, while deleting all similar memories.

(B) Logic reconfiguration: (1) The machine/system checks the PM_n for corresponding logic functions to find identical logics (PMs), and keeping only one logic (PMs) of all identical logics (PMs), deleting all other identical logics (PMs); (2) The machine/system checks the PM_n for corresponding logic functions to find similar logics (PMs) (similarity with a given percentage x %, for example, x is equal to or smaller than 2%, 3%, 5% or 10%), and keeping only one or two logics (PMs) of all similar logics (PMs), deleting all other similar logics (PMs). Alternatively, a representative logic (PMs) (data or information in PM for the corresponding representative logic, having a specific range) of all similar logics (PMs) may be generated and kept, while deleting all similar logics (PMs).

II. Learning Processes:

Based on S_n (IU_n, L_n, PM_n, DM_n), performing a logarithm to select or screen (memorize) useful, significant and important integral units, logics, PMs and DMs, and delete (forget) non-useful, non-significant or non-important integral units, logics, PMs or DMs. The selection or screening algorithm may be based on a given statistical method, for example, based on the frequency of use of integral units, logics, PMs and or DMs in the previous n events. Another example, the Bayesian inference may be used for generating S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}).

The algorithm and criteria provide learning processes for the system/machine states after events. The plasticity (or elasticity) and integrality of the logic drive provide capabilities suitable for applications in machine learning and artificial intelligence.

Another aspect of the disclosure provides a standard commodity memory drive, package, package drive, device, module, disk, disk drive, solid-state disk, or solid-state drive (to be abbreviated as "drive" below, that is when "drive" is mentioned below, it means and reads as "drive, package, package drive, device, module, disk, disk drive, solid-state disk, or solid-state drive"), in a multi-chip package comprising plural standard commodity non-volatile memory IC chips for use in data storage. The data stored in the standard commodity non-volatile memory drive are kept even if the power supply of the drive is turned off. The plural non-volatile memory IC chips comprise NAND flash chips, in a bare-die format or in a package format. Alternatively, the plural non-volatile memory IC chips may comprise Non-Volatile Radom-Access-Memory (NVRAM) IC chips, in a bare-die format or in a package format. The NVRAM may be a Ferroelectric RAM (FRAM), Magnetoresistive RAM (MRAM), Resistive RAM (RRAM), or Phase-change RAM (PRAM). The standard commodity memory drive is formed by the COIP packaging, using same or similar process steps of the COIP packaging in forming the standard commodity logic drive, as described and specified in the above paragraphs. The process steps of the COIP packaging are highlighted below: (1) Providing non-volatile memory IC chips, for example, standard commodity NAND flash IC chips, and an interposer; and then flip-chip assembling or bonding the IC chips to and on the interposer. Each of the plural NAND flash chips may have a standard memory density, capacity or size of greater than or equal to 64 Mb, 512 Mb, 1 Gb, 4 Gb, 16 Gb, 64 Gb, 128 Gb, 256 Gb, or 512 Gb, wherein "b" is bits. The NAND flash chip may be designed and fabricated using advanced NAND flash technology nodes or genera-

tions, for example, more advanced than or equal to 45 nm, 28 nm, 20 nm, 16 nm, and/or 10 nm, wherein the advanced NAND flash technology may comprise Single Level Cells (SLC) or multiple level cells (MLC) (for example, Double Level Cells DLC, or triple Level cells TLC), and in a 2D-NAND or a 3D NAND structure. The 3D NAND structures may comprise multiple stacked layers or levels of NAND cells, for example, greater than or equal to 4, 8, 16, 32 stacked layers or levels of NAND cells. Each of the plural NAND flash chips to be packaged in the memory drives may comprise micro copper pillars or bumps on the top surfaces of the chips. The top surfaces of micro copper pillars or bumps are at a level above the level of the top surface of the top-most insulating dielectric layer of the chips with a height of, for example, between 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or greater than or equal to 30 μm, 20 μm, 15 μm, 5 μm or 3 μm. The chips are flip-chip assembled or bonded on or to the interposer with the side or surface of the chip with transistors faced down; (2) Applying a material, resin, or compound to fill the gaps between chips and cover the backside surfaces of chips, and the top surfaces of the TPVs, if exist, by methods, for example, spin-on coating, screen-printing, dispensing or molding in the wafer or panel format. Applying a CMP, polishing or grinding process to planarize the surface of the applied material, resin or compound to a level where the top surfaces of all backsides of the IC chips and top surfaces of TPVs are fully exposed; (3) Forming a Backside Interconnection Scheme in, on or of the memory drive (BISD) on or over the planarized material, resin or compound and on or over the exposed top surfaces of the TPVs by a wafer or panel processing; (4) Forming copper pads, pillars or bumps, or solder bumps on or over the BISD, (5) Forming copper pads, pillars or bumps, or solder bumps on or under the TSVs of the interposer; (6) Separating, cutting or dicing the finished wafer or panel, including separating, cutting or dicing through the material, resin or compound between two neighboring memory drives. The material, resin or compound (for example, polymer) filling gaps between chips of two neighboring memory drives is separated, cut or diced to from individual unit of memory drives.

Another aspect of the disclosure provides a standard commodity memory drive in a multi-chip package comprising plural standard commodity non-volatile memory IC chips may be further comprising the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip; for use in data storage. The data stored in the standard commodity non-volatile memory drive are kept even if the power supply of the drive is turned off. The plural non-volatile memory IC chips comprise NAND flash chips, in a bare-die format or in a package format. Alternatively, the plural non-volatile memory IC chips may comprise Non-Volatile Radom-Access-Memory (NVRAM) IC chips, in a bare-die format or in a package format. The NVRAM may be a Ferroelectric RAM (FRAM), Magnetoresistive RAM (MRAM), Resistive RAM (RRAM), or Phase-change RAM (PRAM). The functions of the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip are for the memory control and/or inputs/outputs, and are the same or similar to that described and specified in the above paragraphs for the logic drive. The communication, connection or coupling between the non-volatile memory IC chips, for example the NAND flash chips, and the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip in a same memory drive is the same or similar to that described and specified in the above paragraphs for the logic drive. The standard commodity NAND flash IC chips may be fabricated using an IC manufacturing technology node or generation different from that used for manufacturing the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip used in the same memory drive. The standard commodity NAND flash IC chips comprise small I/O circuits, while the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip used in the memory drive may comprise large I/O circuits, as descried and specified for the logic drive. The standard commodity memory drive comprising the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip is formed by the COIP, using same or similar process steps of the COIP in forming the logic drive, as described and specified in the above paragraphs.

Another aspect of the disclosure provides the stacked non-volatile (for example, NAND flash) memory drive comprising plural single-layer-packaged non-volatile memory drives, as described and specified above, each in a multiple-chip package. The single-layer-packaged non-volatile memory drive with TPVs and/or BISD for use in the stacked non-volatile memory drive may be in a standard format or having standard sizes. For example, the single-layer-packaged non-volatile memory drive may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the single-layer-packaged non-volatile memory drive. For example, the standard shape of the single-layer-packaged non-volatile memory drive may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the non-volatile memory drive may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. The stacked non-volatile memory drive may comprise, for example 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged non-volatile memory drives, and may be formed by the similar or the same process steps as described and specified in forming the stacked logic drive. The single-layer-packaged non-volatile memory drives comprise TPVs and/or BISD for the stacking assembly purpose. The process steps for forming TPVs and/or BISD, and the specifications of TPVs and/or BISD are as described and specified in the above paragraphs for use in the stacked logic drive. The stacking methods (for example, POP) using TPVs and/or BISD are as described and specified in above paragraphs for the stacked logic drive.

Another aspect of the disclosure provides a standard commodity memory drive in a multi-chip package comprising plural standard commodity volatile memory IC chips for use in data storage; wherein the plural volatile memory IC chips comprise DRAM IC chips, in a bare-die format or in a package format. The standard commodity DRAM memory drive is formed by the COIP packaging, using same or similar process steps of the COIP packaging in forming the logic drive, as described and specified in the above paragraphs. The process steps are highlighted below: (1) Providing standard commodity DRAM IC chips, and an interposer; and then flip-chip assembling or bonding the IC chips to and on the interposer. Each of the plural DRAM IC chips

may have a standard memory density, capacity or size of greater than or equal to 64 Mb, 512 Mb, 1 Gb, 4 Gb, 16 Gb, 64 Gb, 128 Gb, 256 Gb, or 512 Gb, wherein "b" is bits. The DRAM IC chip may be designed and fabricated using advanced DRAM technology nodes or generations, for example, more advanced than or equal to 45 nm, 28 nm, 20 nm, 16 nm, and/or 10 nm. All DRAM IC chips to be packaged in the memory drives may comprise micro copper pillars or bumps on the top surfaces of the chips. The top surfaces of micro copper pillars or bumps are at a level above the level of the top surface of the top-most insulating dielectric layer of the chips with a height of, for example, between 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, or 3 μm and 10 μm, or greater than or equal to 30 μm, 20 μm, 15 μm, 5 μm or 3 μm. The chips are flip-chip assembled or bonded on or to the interposer with the side or surface of the chip with transistors faced down; (2) Applying a material, resin, or compound to fill the gaps between chips and cover the backside surfaces of chips and the top surfaces of the TPVs, if exist, by methods, for example, spin-on coating, screen-printing, dispensing or molding in the wafer or panel format. Applying a CMP, polishing or grinding process to planarize the surface of the applied material, resin or compound to a level where the backside surfaces of all the chips and the top surfaces of the all TPVs are fully exposed; (3) Forming a Backside Interconnection Scheme in, on or of the memory drive (BISD) on or over the planarized material, resin or compound and on or over the exposed top surfaces of the TPVs by a wafer or panel processing; (4) Forming copper pads, pillars or bumps, or solder bumps on or over the BISD, (5) Forming copper pads, pillars or bumps, or solder bumps on or under the TSVs of the interposer; (6) Separating, cutting or dicing the finished wafer or panel, including separating, cutting or dicing through the material, resin or compound between two neighboring memory drives. The material, resin or compound (for example, polymer) filling gaps between chips of two neighboring memory drives is separated, cut or diced to from individual unit of memory drives.

Another aspect of the disclosure provides a standard commodity memory drive in a multi-chip package comprising plural standard commodity volatile IC chips may further comprise the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip; for use in data storage; wherein the plural volatile memory IC chips comprise DRAM IC chips, in a bare-die format or in a DRAM package format. The functions of the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip used in the memory driver are for the memory control and/or inputs/outputs, and are the same or similar to that described and specified in the above paragraphs for the logic drive. The communication, connection or coupling between the DRAM IC chips and the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip in a same memory drive is the same or similar to that described and specified in the above paragraphs for the logic drive. The standard commodity DRAM IC chips may be fabricated using an IC manufacturing technology node or generation different from that used for manufacturing the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip. The standard commodity DRAM IC chips comprise small I/O circuits, while the dedicated control chip, the dedicated I/O chip, or the dedicated control and I/O chip used in the memory drive may comprise large I/O circuits, as descried and specified above for the logic drive. The standard commodity memory drive is formed by the same or similar process steps as that in forming the logic drive, as described and specified in the above paragraphs.

Another aspect of the disclosure provides the stacked volatile (for example, DRAM) memory drive comprising plural single-layer-packaged volatile memory drives, as described and specified above, each in a multiple-chip package. The single-layer-packaged volatile memory drive with TPVs and/or BISD for use in the stacked volatile memory drive may be in a standard format or having standard sizes. For example, the single-layer-packaged volatile memory drive may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the single-layer-packaged volatile memory drive. For example, the standard shape of the single-layer-packaged volatile memory drive may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the volatile memory drive may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. The stacked volatile memory drive may comprise, for example 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged volatile memory drives, and may be formed by the similar or the same process steps as described and specified in forming the stacked logic drive. The single-layer-packaged volatile memory drives may comprise TPVs and/or BISD for the stacking assembly purpose. The process steps for forming TPVs and/or BISD, and the specifications of TPVs and/or BISD are described and specified in the above paragraphs for use in the stacked logic drive. The stacking methods (for example, POP) using TPVs and/or BISD are as described and specified in above paragraphs for the stacked logic drive.

Another aspect of the disclosure provides the stacked logic and volatile (for example, DRAM) memory drive comprising plural single-layer-packaged logic drives and plural single-layer-packaged volatile memory drives, each in a multiple-chip package, as described and specified above. Each of plural single-layer-packaged logic drives and each of plural single-layer-packaged volatile memory drives may be in a same standard format or having a same standard shape, size and dimension, may have the same standard footprints of the metal pads, pillars or bumps on the top surface, and the same standard footprints of the metal pads, pillars or bumps at the bottom surface, as described and specified in above. The stacked logic and volatile-memory drive may comprise, for example 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged logic drives or volatile-memory drives (in total), and may be formed by the similar or the same process steps as described and specified in forming the stacked logic drive. The stacking sequence, from bottom to top, may be: (a) all single-layer-packaged logic drives at the bottom and all single-layer-packaged volatile memory drives at the top, or (b) single-layer-packaged logic drives and single-layer-packaged volatile drives are stacked interlaced or interleaved layer over layer, from bottom to top, in sequence: (i) single-layer-packaged logic drive, (ii) single-layer-packaged volatile memory drive, (iii) single-layer-packaged logic drive, (iv) single-

layer-packaged volatile memory, and so on. The single-layer-packaged logic drives and single-layer-packaged volatile memory drives used in the stacked logic and volatile-memory drives, each comprises TPVs and/or BISD for the stacking assembly purpose. The process steps for forming TPVs and/or BISD, and the specifications of TPVs and/or BISD are described and specified in the above paragraphs. The stacking methods (POP) using TPVs and/or BISD are as described and specified in above paragraphs.

Another aspect of the disclosure provides the stacked non-volatile (for example, NAND flash) and volatile (for example, DRAM) memory drive comprising plural single-layer-packaged non-volatile drives and plural single-layer-packaged volatile memory drives, each in a multiple-chip package, as described and specified in above paragraphs. Each of plural single-layer-packaged non-volatile drives and each of plural single-layer-packaged volatile memory drives may be in a same standard format or having a same standard shape, size and dimension, and have standard footprints of metal pads, pillars or bumps on the top surface and at the bottom surface, as described and specified above. The stacked non-volatile and volatile-memory drive may comprise, for example 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged non-volatile memory drives or single-layer-packaged volatile-memory drives (in total), and may be formed by the similar or the same process steps as described and specified in forming the stacked logic drive. The stacking sequence, from bottom to top, may be: (a) all single-layer-packaged volatile memory drives at the bottom and all single-layer-packaged non-volatile memory drives at the top, (b) all single-layer-packaged non-volatile memory drives at the bottom and all single-layer-packaged volatile memory drives at the top, or (c) single-layer-packaged non-volatile memory drives and single-layer-packaged volatile drives are stacked interlaced or interleaved layer over layer, from bottom to top, in sequence: (i) single-layer-packaged volatile memory drive, (ii) single-layer-packaged non-volatile memory drive, (iii) single-layer-packaged volatile memory drive, (iv) single-layer-packaged non-volatile memory, and so on. The single-layer-packaged non-volatile drives and single-layer-packaged volatile memory drives used in the stacked non-volatile and volatile-memory drives, each comprises TPVs and/or BISD for the stacking assembly purpose. The process steps for forming TPVs and/or BISD, and the specifications of TPVs and/or BISD are described and specified in the above paragraphs for use in the stacked logic drive. The stacking methods (POP) using TPVs and/or BISD are as described and specified in above paragraphs for forming the stacked logic drive.

Another aspect of the disclosure provides the stacked logic, non-volatile (for example, NAND flash) memory and volatile (for example, DRAM) memory drive comprising plural single-layer-packaged logic drives, plural single-layer-packaged non-volatile memory drives and plural single-layer-packaged volatile memory drives, each in a multiple-chip package, as described and specified above. Each of plural single-layer-packaged logic drives, each of plural single-layer-packaged non-volatile memory drives and each of plural single-layer-packaged volatile memory drives may be in a same standard format or having a same standard shape, size and dimension, and have standard footprints of metal pads, pillars or bumps on the top surface and at the bottom surface, as described and specified above. The stacked logic, non-volatile (flash) memory and volatile (DRAM) memory drive may comprise, for example 2, 3, 4, 5, 6, 7, 8 or greater than 8 single-layer-packaged logic drives, single-layer-packaged non-volatile-memory drives or single-layer-packaged volatile-memory drives (in total), and may be formed by the similar or the same process steps as described and specified in forming the stacked logic drive. The stacking sequence is, from bottom to top, for example: (a) all single-layer-packaged logic drives at the bottom, all single-layer-packaged volatile memory drives in the middle, and all single-layer-packaged non-volatile memory drives at the top, or, (b) single-layer-packaged logic drives, single-layer-packaged volatile memory drives, and single-layer-packaged non-volatile memory drives are stacked interlaced or interleaved layer over layer, from bottom to top, in sequence: (i) single-layer-packaged logic drive, (ii) single-layer-packaged volatile memory drive, (iii) single-layer-packaged non-volatile memory drive, (iv) single-layer-packaged logic drive, (v) single-layer-packaged volatile memory, (vi) single-layer-packaged non-volatile memory drive, and so on. The single-layer-packaged logic drives, single-layer-packaged volatile memory drives, and single-layer-packaged volatile memory drives used in the stacked logic, non-volatile-memory and volatile-memory drives, each comprises TPVs and/or BISD for the stacking assembly purpose. The process steps for forming TPVs and/or BISD, and the specifications of TPVs and/or BISD are described and specified in the above paragraphs for use in the stacked logic drive. The stacking methods (POP) using TPVs and/or BISD are as described and specified in above paragraphs for forming the stacked logic drive.

Another aspect of the disclosure provides a system, hardware, electronic device, computer, processor, mobile phone, communication equipment, and/or robot comprising the logic drive, the non-volatile (for example, NAND flash) memory drive, and/or the volatile (for example, DRAM) memory drive. The logic drive may be the single-layer-packaged logic drive or the stacked logic drive, as described and specified above; the non-volatile flash memory drive may be the single-layer-packaged non-volatile flash memory drive or the stacked non-volatile flash memory drive as described and specified above; and the volatile DRAM memory drive may be the single-layer-packaged DRAM memory drive or the stacked volatile DRAM memory drive as described and specified above. The logic drive, the non-volatile flash memory drive, and/or the volatile DRAM memory drive are flip-package assembled on a Printed Circuit Board (PCB), a Ball-Grid-Array (BGA) substrate, a flexible circuit film or tape, or a ceramic circuit substrate.

Another aspect of the disclosure provides a stacked package or device comprising the single-layer-packaged logic drive and the single-layer-packaged memory drive. The single-layer-packaged logic drive is as described and specified above, and is comprising one or more FPGA chips, one or more NAND flash chips, the DPIs or DPICSRAMs, dedicated control chip, the dedicated I/O chip, and/or the dedicated control and I/O chip. The single-layer-packaged logic drive may be further comprising one or more of the processing and/or computing IC chips, for example, one or more CPU chips, GPU chips, DSP chips, and/or TPU chips. The single-layer-packaged memory drive is as described and specified above, and is comprising one or more high speed, high bandwidth and wide bitwidth cache SRAM chips, DRAM IC chips, or NVM chips for high speed parallel processing and/or computing. The one or more high speed, high bandwidth and wide bitwidth NVMs may comprise MRAM or RRAM. The single-layer-packaged logic drive, as described and specified above, is formed using the interposer comprising FISIP and/or SISIP, TPVs, TSVs and metal pads, pillars or bumps on or under the TSVs. For high speed, high bandwidth and wide bitwidth communications

with the memory chips of the single-layer-packaged memory drive, stacked vias (in or of the FISIP and/or SISIP) directly and vertically on or over the TSVs are formed, and micro copper pads, pillars or bumps on or over the SISIP and/or FISIP are formed directly and vertically on or over the stacked vias. Multiple stacked structures, each for a bit data of the high speed, wide bit-width buses, are formed, from top to the bottom, comprise, (1) micro copper pads, pillars or bumps on or of the SISIP and/or FISIP; (2) stacked vias by stacking metal vias and metal layers of the SISIP and/or FISIP; (3) TSVs; and (4) copper pads, metal pillars or bumps on or under the TSVs. The micro copper/solder pillars or bumps on or of the IC chips are then flip-chip assembled or bonded on or to the micro copper pads, pillars or bumps (on or over the SISIP and/or FISIP) of the stacked structures. The number of stacked structures for each IC chip (that is the data bit-width between each logic chip and each high speed, high bandwidth and wide bitwidth memory chip) is equal or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K for high speed, high bandwidth and wide bitwidth parallel processing and/or computing. Similarly, multiple stacked structures are formed in the single-layer-packaged memory drive. The single-layer-packaged logic drive (with the stacked vias) is then flip-package assembled or packaged on or to the single-layer-packaged memory drive (also with the stacked vias), with the side with transistor of IC chips in the logic drive faced down, and the side with transistor of IC chips in the memory drive faced up. Therefore, a micro copper/solder pillar or bump on or of a FPGA, CPU, GPU, DSP and/or TPU chip can be connected or coupled, with the shortest distance, to a micro copper/solder pillar or bump on a memory chip, for example, DRAM, SRAM or NVM, through: (1) micro copper pads, pillars or bumps on or of the SISIP and/or FISIP of the logic drive; (2) stacked vias by stacking metal vias and metal layers of the SISIP and/or FISIP of the logic drive; (3) TSVs of the logic drive; and (4) copper pads, metal pillars or bumps on or under the TSVs of the logic drive; (5) copper pads, metal pillars or bumps on or over the TSVs of the memory drive; (6) TSVs of the memory drive; (7) stacked vias by stacking metal vias and metal layers of the SISIP and/or FISIP of the memory drive; (8) micro copper pads, pillars or bumps on or under the SISIP and/or FISIP of the memory drive. With the TPVs and/or BISD for both the single-layer-packaged logic drive and the single-layer-packaged memory drive, the stacked logic and memory drive or device can communicate, connect or couple to the external circuits or components from the top side (the backside of the single-layer-packaged logic drive, with the side with transistor of IC chips in the logic drive faced down,) and the bottom side (the backside of the single-layer-packaged memory drive, the side with transistor of IC chips in the memory drive faced up) of the stacked logic and memory drive or device. Alternatively, the TPVs and/or BISD for the single-layer-packaged logic drive may be omitted; and the stacked logic and memory drive or device can communicate, connect or couple to the external circuits or components from the bottom side (the backside of the single-layer-packaged memory drive, the side with transistor of IC chips in the memory drive faced up) of the stacked the stacked logic and memory drive or device, through the TPVs and/or BISD of the memory drive. Alternatively, the TPVs and/or BISD for the single-layer-packaged memory drive may be omitted; and the stacked logic and memory drive or device can communicate, connect or couple to the external circuits or components from the top side (the backside of the single-layer-packaged logic drive, the side with transistor of IC chips in the logic drive faced up) of the stacked logic and memory drive or device, through the TPVs and/or BISD of the logic drive.

In all of the above alternatives for the logic and memory drive or device, the single-layer-packaged logic drive may comprise one or more of the processing and/or computing IC chips, and the single-layer-packaged memory drive may comprise one or more high speed, high bandwidth and wide bitwidth cache SRAM chips, DRAM IC chips, or NVM chips (for example, MRAM or RAM) for high speed parallel processing and/or computing. For example, the single-layer-packaged logic drive may comprise multiple GPU chips, for example 2, 3, 4 or more than 4 GPU chips, and the single-layer-packaged memory drive may comprise multiple high speed, high bandwidth and wide bitwidth cache SRAM chips, DRAM IC chips, or NVM chips. The communication between one of GPU chips and one of SRAM, DRAM or NVM chips, through the stacked structures described and specified above, may be with data bit-width equal or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. For another example, the logic drive may comprise multiple TPU chips, for example 2, 3, 4 or more than 4 TPU chips, and the single-layer-packaged memory drive may comprise multiple high speed, high bandwidth and wide bitwidth cache SRAM chips, DRAM IC chips or NVM chips. The communication between one of TPU chips and one of SRAM or DRAM IC chips, through the stacked structures described and specified above, may be with data bit-width equal or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

The communication, connection, or coupling between one of logic, processing and/or computing chips (for example, FPGA, CPU, GPU, DSP, APU, TPU, and/or ASIC chips) and one of high speed, high bandwidth SRAM, DRAM or NVM chips, through the stacked structures described and specified above, may be the same or similar as that between internal circuits in a same chip. Alternatively, the communication, connection, or coupling between one of logic, processing and/or computing chips (for example, FPGA, CPU, GPU, DSP, APU, TPU, and/or ASIC chips) and one of high speed, high bandwidth SRAM, DRAM or NVM chips, through the stacked structures described and specified above, may be using small I/O drivers and/or receivers. The driving capability, loading, output capacitance, or input capacitance of the small I/O drivers or receivers, or I/O circuits may be between 0.01 pF and 10 pF, 0.05 pF and 5 pF, or 0.01 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, 0.5 pF or 0.1 pF. For example, a bi-directional (or tri-state) I/O pad or circuit may be used for the small I/O drivers or receivers, or I/O circuits for communicating between high speed, high bandwidth logic and memory chips in the logic and memory stacked drive, and may comprise an ESD circuit, a receiver, and a driver, and may have an input capacitance or output capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, or 0.01 pF and 2 pF; or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, 0.5 pF or 0.1 pF.

These, as well as other components, steps, features, benefits, and advantages of the present application, will now become clear from a review of the following detailed description of illustrative embodiments, the accompanying drawings, and the claims.

BRIEF DESCRIPTION OF THE DRAWINGS

The drawings disclose illustrative embodiments of the present application. They do not set forth all embodiments. Other embodiments may be used in addition or instead.

Details that may be apparent or unnecessary may be omitted to save space or for more effective illustration. Conversely, some embodiments may be practiced without all of the details that are disclosed. When the same reference number or reference indicator appears in different drawings, it may refer to the same or like components or steps.

Aspects of the disclosure may be more fully understood from the following description when read together with the accompanying drawings, which are to be regarded as illustrative in nature, and not as limiting. The drawings are not necessarily to scale, emphasis instead being placed on the principles of the disclosure. In the drawings:

FIGS. **1**A and **1**B are circuit diagrams illustrating various types of memory cells in accordance with an embodiment of the present application.

FIGS. **2**A-**2**F are circuit diagrams illustrating various types of pass/no-pass switch in accordance with an embodiment of the present application.

FIGS. **3**A-**3**D are block diagrams illustrating various types of cross-point switches in accordance with an embodiment of the present application.

FIGS. **4**A and **4**C-**4**L are circuit diagrams illustrating various types of multiplexers in accordance with an embodiment of the present application.

FIG. **4**B is a circuit diagram illustrating a tri-state buffer of a multiplexer in accordance with an embodiment of the present application.

FIG. **5**A is a circuit diagram of a large I/O circuit in accordance with an embodiment of the present application.

FIG. **5**B is a circuit diagram of a small I/O circuit in accordance with an embodiment of the present application.

FIG. **6**A is a schematic view showing a block diagram of a programmable logic block in accordance with an embodiment of the present application.

FIG. **6**B shows an OR gate in accordance with the present application.

FIG. **6**C shows a look-up table configured for achieving an OR gate in accordance with the present application.

FIG. **6**D shows an AND gate in accordance with the present application.

FIG. **6**E shows a look-up table configured for achieving an AND gate in accordance with the present application.

FIG. **6**F is a circuit diagram of a logic operator in accordance with an embodiment of the present application.

FIG. **6**G shows a look-up table for a logic operator in FIG. **6**F.

FIG. **6**H is a block diagram illustrating a computation operator in accordance with an embodiment of the present application.

FIG. **6**I shows a look-up table for a computation operator in FIG. **6**J.

FIG. **6**J is a circuit diagram of a computation operator in accordance with an embodiment of the present application.

FIGS. **7**A-**7**C are block diagrams illustrating programmable interconnects programmed by a pass/no-pass switch or cross-point switch in accordance with an embodiment of the present application.

FIGS. **8**A-**8**H are schematically top views showing various arrangements for a standard commodity FPGA IC chip in accordance with an embodiment of the present application.

FIGS. **8**I and **8**J are block diagrams showing various repair algorithms in accordance with an embodiment of the present application.

FIG. **8**K is a block diagram illustrating a programmable logic block for a standard commodity FPGA IC chip in accordance with an embodiment of the present application.

FIG. **8**L is a circuit diagram illustrating a cell of an adder in accordance with an embodiment of the present application.

FIG. **8**M is a circuit diagram illustrating an adding unit for a cell of an adder in accordance with an embodiment of the present application.

FIG. **8**N is a circuit diagram illustrating a cell of a multiplier in accordance with an embodiment of the present application.

FIG. **9** is a schematically top view showing a block diagram of a dedicated programmable interconnection (DPI) integrated-circuit (IC) chip in accordance with an embodiment of the present application.

FIG. **10** is a schematically top view showing a block diagram of a dedicated input/output (I/O) chip in accordance with an embodiment of the present application.

FIGS. **11**A-**11**N are schematically top views showing various arrangement for a logic drive in accordance with an embodiment of the present application.

FIGS. **12**A-**12**C are various block diagrams showing various connections between chips in a logic drive in accordance with an embodiment of the present application.

FIG. **12**D is a block diagram illustrating multiple data buses for one or more standard commodity FPGA IC chips and high bandwidth memory (HBM) IC chips in accordance with the present application.

FIGS. **13**A and **13**B are block diagrams showing an algorithm for data loading to memory cells in accordance with an embodiment of the present application.

FIG. **14**A is a cross-sectional view of a semiconductor wafer in accordance with an embodiment of the present application.

FIGS. **14**B-**14**H are cross-sectional views showing a single damascene process is performed to form a first interconnection scheme in accordance with an embodiment of the present application.

FIGS. **14**I-**14**Q are cross-sectional views showing a double damascene process is performed to form a first interconnection scheme in accordance with an embodiment of the present application.

FIGS. **15**A-**15**K are schematically cross-sectional views showing a process for forming a chip with a micro-bump or micro-pillar thereon in accordance with an embodiment of the present application.

FIGS. **16**A-**16**N and **17** are schematically cross-sectional views showing a process for forming a second interconnection scheme over a passivation layer and forming multiple micro-pillars or micro-bumps on the second interconnection metal layer in accordance with an embodiment of the present application.

FIGS. **18**A-**18**K are schematically cross-sectional views showing a process for forming an interposer with a first type of vias in accordance with an embodiment of the present application.

FIGS. **18**L-**18**W are schematically cross-sectional views showing a process for forming a multi-chip-on-interposer (COIP) logic drive in accordance with an embodiment of the present application.

FIGS. **19**A-**19**M are schematically cross-sectional views showing a process for forming an interposer with a second type of vias in accordance with an embodiment of the present application.

FIGS. **19**N-**19**T are schematically cross-sectional views showing a process for forming a multi-chip-on-interposer (COIP) logic drive in accordance with an embodiment of the present application.

FIGS. **20**A and **20**B are schematically cross-sectional views showing various interconnection for an interposer arranged with a first type of vias in accordance with an embodiment of the present application.

FIGS. **21**A and **21**B are schematically cross-sectional views showing various interconnection for an interposer arranged with a second type of vias in accordance with an embodiment of the present application.

FIGS. **22**A-**22**O are cross-sectional views showing a process for forming a multi-chip-on-interposer (COIP) logic drive with multiple through package vias in accordance with the present application.

FIGS. **23**A-**23**C are cross-sectional views showing a process for forming a multi-chip-on-interposer (COIP) logic drive with multiple through package vias in accordance with the present application.

FIGS. **24**A-**24**F are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application.

FIGS. **25**A-**25**E are cross-sectional views showing a process for forming TPVs and micro-bumps on an interposer in accordance with the present application.

FIGS. **26**A-**26**M are schematic views showing a process for forming a multi-chip-on-interposer (COIP) logic drive with a backside metal interconnection scheme in accordance with the present application.

FIG. **26**N is a top view showing a metal plane in accordance with an embodiment of the present application.

FIGS. **27**A-**27**D are schematic views showing a process for forming a multi-chip-on-interposer (COIP) logic drive with a backside metal interconnection scheme in accordance with the present application.

FIGS. **28**A-**28**D are cross-sectional views showing various interconnection nets in a COIP logic drive in accordance with embodiments of the present application.

FIGS. **29**A-**29**F are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application.

FIGS. **30**A-**30**C are cross-sectional views showing various connection of multiple logic drives in POP assembly in accordance with embodiment of the present application.

FIGS. **31**A and **31**B are conceptual views showing interconnection between multiple programmable logic blocks from an aspect of human's nerve system in accordance with an embodiment of the present application.

FIG. **31**C is a schematic diagram for a reconfigurable plastic, elastic and/or integral architecture in accordance with an embodiment of the present application.

FIG. **31**D is a schematic diagram for a reconfigurable plastic, elastic and/or integral architecture for the eighth event E**8** in accordance with an embodiment of the present application.

FIGS. **32**A-**32**K are schematically views showing multiple combinations of POP assemblies for logic and memory drives in accordance with embodiments of the present application.

FIG. **32**L is a schematically top view of multiple POP assemblies, which is a schematically cross-sectional view along a cut line A-A shown in FIG. **32**K.

FIGS. **33**A-**33**C are schematically views showing various applications for logic and memory drives in accordance with multiple embodiments of the present application.

FIGS. **34**A-**34**F are schematically top views showing various standard commodity memory drives in accordance with an embodiment of the present application.

FIGS. **35**A-**35**E are cross-sectional views showing various assemblies for multiple COIP logic and memory drives in accordance with an embodiment of the present application.

FIGS. **35**F and **35**G are cross-sectional views showing a COIP logic drive assembled with one or more memory IC chips in accordance with an embodiment of the present application.

FIG. **36** is a block diagram illustrating networks between multiple data centers and multiple users in accordance with an embodiment of the present application.

While certain embodiments are depicted in the drawings, one skilled in the art will appreciate that the embodiments depicted are illustrative and that variations of those shown, as well as other embodiments described herein, may be envisioned and practiced within the scope of the present application.

DETAILED DESCRIPTION OF THE DISCLOSURE

Illustrative embodiments are now described. Other embodiments may be used in addition or instead. Details that may be apparent or unnecessary may be omitted to save space or for a more effective presentation. Conversely, some embodiments may be practiced without all of the details that are disclosed.

Specification for Static Random-Access Memory (SRAM) Cells

(1) First Type of SRAM Cell (6T SRAM Cell)

FIG. **1**A is a circuit diagram illustrating a 6T SRAM cell in accordance with an embodiment of the present application.

Referring to FIG. **1**A, a first type of static random-access memory (SRAM) cell **398**, i.e., 6T SRAM cell, may have a memory unit **446** composed of 4 data-latch transistors **447** and **448**, that is, two pairs of a P-type MOS transistor **447** and N-type MOS transistor **448** both having respective drain terminals coupled to each other, respective gate terminals coupled to each other and respective source terminals coupled to the voltage Vcc of power supply and to the voltage Vss of ground reference. The gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair are coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair, acting as an output Out**1** of the memory unit **446**. The gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair are coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair, acting as an output Out**2** of the memory unit **446**.

Referring to FIG. **1**A, the first type of SRAM cell **398** may further include two switches or transfer (write) transistor **449**, such as N-type or P-type MOS transistors, a first one of which has a gate terminal coupled to a word line **451** and a channel having a terminal coupled to a bit line **452** and another terminal coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair, and a second one of which has a gate terminal coupled to the word line **451** and a channel having a terminal coupled to a bit-bar line **453** and another terminal coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair. A logic level on the bit line **452** is opposite a logic level on the bit-bar line **453**. The switch **449** may be considered as a programming transistor for writing

a programing code or data into storage nodes of the 4 data-latch transistors **447** and **448**, i.e., at the drains and gates of the 4 data-latch transistors **447** and **448**. The switches **449** may be controlled via the word line **451** to turn on connection from the bit line **452** to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair via the channel of the first one of the switches **449**, and thereby the logic level on the bit line **452** may be reloaded into the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair. Further, the bit-bar line **453** may be coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair via the channel of the second one of the switches **449**, and thereby the logic level on the bit line **453** may be reloaded into the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair. Thus, the logic level on the bit line **452** may be registered or latched in the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and in the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair; a logic level on the bit line **453** may be registered or latched in the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and in the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair.

(2) Second Type of SRAM Cell (5T SRAM Cell)

FIG. **1**B is a circuit diagram illustrating a 5T SRAM cell in accordance with an embodiment of the present application. Referring to FIG. **1**B, a second type of static random-access memory (SRAM) cell **398**, i.e., 5T SRAM cell, may have the memory unit **446** as illustrated in FIG. **1**A. The second type of static random-access memory (SRAM) cell **398** may further have a switch or transfer (write) transistor **449**, such as N-type or P-type MOS transistor, having a gate terminal coupled to a word line **451** and a channel having a terminal coupled to a bit line **452** and another terminal coupled to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair. The switch **449** may be considered as a programming transistor for writing a programing code or data into storage nodes of the 4 data-latch transistors **447** and **448**, i.e., at the drains and gates of the 4 data-latch transistors **447** and **448**. The switch **449** may be controlled via the word line **451** to turn on connection from the bit line **452** to the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair via the channel of the switch **449**, and thereby a logic level on the bit line **452** may be reloaded into the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair. Thus, the logic level on the bit line **452** may be registered or latched in the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair and in the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair; a logic level, opposite to the logic level on the bit line **452**, may be registered or latched in the conductive line between the gate terminals of the P-type and N-type MOS transistors **447** and **448** in the left pair and in the conductive line between the drain terminals of the P-type and N-type MOS transistors **447** and **448** in the right pair.

Specification for Pass/No-Pass Switches

(1) First Type of Pass/No-Pass Switch

FIG. **2**A is a circuit diagram illustrating a first type of pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **2**A, a first type of pass/no-pass switch **258** may include an N-type metal-oxide-semiconductor (MOS) transistor **222** and a P-type metal-oxide-semiconductor (MOS) transistor **223** coupling in parallel to each other. Each of the N-type and P-type metal-oxide-semiconductor (MOS) transistors **222** and **223** of the pass/no-pass switch **258** of the first type may be provided with a channel having an end coupling to a node N**21** and the other opposite end coupling to a node N**22**. Thereby, the first type of pass/no-pass switch **258** may be set to turn on or off connection between the nodes N**21** and N**22**. The P-type MOS transistor **223** of the pass/no-pass switch **258** of the first type may have a gate terminal coupling to a node SC-**1**. The N-type MOS transistor **222** of the pass/no-pass switch **258** of the first type may have a gate terminal coupling to a node SC-**2**.

(2) Second Type of Pass/No-Pass Switch

FIG. **2**B is a circuit diagram illustrating a second type of pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **2**B, a second type of pass/no-pass switch **258** may include the N-type MOS transistor **222** and the P-type MOS transistor **223** that are the same as those of the pass/no-pass switch **258** of the first type as illustrated in FIG. **2**A. The second type of pass/no-pass switch **258** may further include an inverter **533** configured to invert its input coupling to a gate terminal of the N-type MOS transistor **222** and a node SC-**3** into its output coupling to a gate terminal of the P-type MOS transistor **223**.

(3) Third Type of Pass/No-Pass Switch

FIG. **2**C is a circuit diagram illustrating a third type of pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **2**C, a third type of pass/no-pass switch **258** may be a multi-stage tri-state buffer **292**, i.e., switch buffer, having a pair of a P-type MOS transistor **293** and N-type MOS transistor **294** in each stage, both having respective drain terminals coupling to each other and respective source terminals configured to couple to the voltage Vcc of power supply and to the voltage Vss of ground reference. In this case, the multi-stage tri-state buffer **292** is two-stage tri-state buffer, i.e., two-stage inverter buffer, having two pairs of the P-type MOS transistor **293** and N-type MOS transistor **294** in the two respective stages, i.e., first and second stages. A node N**21** may couple to gate terminals of the P-type MOS and N-type MOS transistors **293** and **294** in the pair in the first stage. The drain terminals of the P-type MOS and N-type MOS transistors **293** and **294** in the pair in the first stage may couple to gate terminals of the P-type MOS and N-type MOS transistors **293** and **294** in the pair in the second stage, i.e., output stage. The drain terminals of the P-type MOS and N-type MOS transistors **293** and **294** in the pair in the second stage, i.e., output stage, may couple to a node N**22**.

Referring to FIG. **2**C, the multi-stage tri-state buffer **292** may further include a switching mechanism configured to enable or disable the multi-stage tri-state buffer **292**, wherein

the switching mechanism may be composed of (1) a control P-type MOS transistor **295** having a source terminal coupling to the voltage Vcc of power supply and a drain terminal coupling to the source terminals of the P-type MOS transistors **293** in the first and second stages, (2) a control N-type MOS transistor **296** having a source terminal coupling to the voltage Vss of ground reference and a drain terminal coupling to the source terminals of the N-type MOS transistors **294** in the first and second stages and (3) an inverter **297** configured to invert its input coupling to a gate terminal of the control N-type MOS transistor **296** and a node SC-**4** into its output coupling to a gate terminal of the control P-type MOS transistor **295**.

For example, referring to FIG. **2**C, when a logic level of "1" couples to the node SC-**4** to turn on the multi-stage tri-state buffer **292**, a signal may be transmitted from the node N**21** to the node N**22**. When a logic level of "0" couples to the node SC-**4** to turn off the multi-stage tri-state buffer **292**, no signal transmission may occur between the nodes N**21** and N**22**.

(4) Fourth Type of Pass/No-Pass Switch

FIG. **2**D is a circuit diagram illustrating a fourth type of pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **2**D, a fourth type of pass/no-pass switch **258** may be a multi-stage tri-state buffer, i.e., switch buffer, that is similar to the one **292** as illustrated in FIG. **2**C. For an element indicated by the same reference number shown in FIGS. **2**C and **2**D, the specification of the element as seen in FIG. **2**D may be referred to that of the element as illustrated in FIG. **2**C. The difference between the circuits illustrated in FIG. **2**C and the circuits illustrated in FIG. **2**D is mentioned as below. Referring to FIG. **2**D, the drain terminal of the control P-type MOS transistor **295** may couple to the source terminal of the P-type MOS transistor **293** in the second stage, i.e., output stage, but does not couple to the source terminal of the P-type MOS transistor **293** in the first stage; the source terminal of the P-type MOS transistor **293** in the first stage may couple to the voltage Vcc of power supply and the source terminal of the control P-type MOS transistor **295**. The drain terminal of the control N-type MOS transistor **296** may couple to the source terminal of the N-type MOS transistor **294** in the second stage, i.e., output stage, but does not couple to the source terminal of the N-type MOS transistor **294** in the first stage; the source terminal of the N-type MOS transistor **294** in the first stage may couple to the voltage Vss of ground reference and the source terminal of the control N-type MOS transistor **296**.

(5) Fifth Type of Pass/No-Pass Switch

FIG. **2**E is a circuit diagram illustrating a fifth type of pass/no-pass switch in accordance with an embodiment of the present application. For an element indicated by the same reference number shown in FIGS. **2**C and **2**E, the specification of the element as seen in FIG. **2**E may be referred to that of the element as illustrated in FIG. **2**C. Referring to FIG. **2**E, a fifth type of pass/no-pass switch **258** may include a pair of the multi-stage tri-state buffers **292**, i.e., switch buffers, as illustrated in FIG. **2**C. The gate terminals of the P-type and N-type MOS transistors **293** and **294** in the first stage in the left one of the multi-stage tri-state buffers **292** in the pair may couple to the drain terminals of the P-type and N-type MOS transistors **293** and **294** in the second stage, i.e., output stage, in the right one of the multi-stage tri-state buffers **292** in the pair and to a node N**21**. The gate terminals of the P-type and N-type MOS transistors **293** and **294** in the first stage in the right one of the multi-stage tri-state buffers **292** in the pair may couple to the drain terminals of the P-type and N-type MOS transistors **293** and **294** in the second stage, i.e., output stage, in the left one of the multi-stage tri-state buffers **292** in the pair and to a node N**22**. For the left one of the multi-stage tri-state buffers **292** in the pair, its inverter **297** is configured to invert its input coupling to the gate terminal of its control N-type MOS transistor **296** and a node SC-**5** into its output coupling to the gate terminal of its control P-type MOS transistor **295**. For the right one of the multi-stage tri-state buffers **292** in the pair, its inverter **297** is configured to invert its input coupling to the gate terminal of its control N-type MOS transistor **296** and a node SC-**6** into its output coupling to the gate terminal of its control P-type MOS transistor **295**.

For example, referring to FIG. **2**E, when a logic level of "1" couples to the node SC-**5** to turn on the left one of the multi-stage tri-state buffers **292** in the pair and a logic level of "0" couples to the node SC-**6** to turn off the right one of the multi-stage tri-state buffers **292** in the pair, a signal may be transmitted from the node N**21** to the node N**22**. When a logic level of "0" couples to the node SC-**5** to turn off the left one of the multi-stage tri-state buffers **292** in the pair and a logic level of "1" couples to the node SC-**6** to turn on the right one of the multi-stage tri-state buffers **292** in the pair, a signal may be transmitted from the node N**22** to the node N**21**. When a logic level of "0" couples to the node SC-**5** to turn off the left one of the multi-stage tri-state buffers **292** in the pair and a logic level of "0" couples to the node SC-**6** to turn off the right one of the multi-stage tri-state buffers **292** in the pair, no signal transmission may occur between the nodes N**21** and N**22**. When a logic level of "1" couples to the node SC-**5** to turn on the left one of the multi-stage tri-state buffers **292** in the pair and a logic level of "1" couples to the node SC-**6** to turn on the right one of the multi-stage tri-state buffers **292** in the pair, signal transmission may occur in either of directions from the node N**21** to the node N**22** and from the node N**22** to the node N**21**.

(6) Sixth Type of Pass/No-Pass Switch

FIG. **2**F is a circuit diagram illustrating a sixth type of pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **2**F, a sixth type of pass/no-pass switch **258** may be composed of a pair of multi-stage tri-state buffers, i.e., switch buffers, which is similar to the ones **292** as illustrated in FIG. **2**E. For an element indicated by the same reference number shown in FIGS. **2**E and **2**F, the specification of the element as seen in FIG. **2**F may be referred to that of the element as illustrated in FIG. **2**E. The difference between the circuits illustrated in FIG. **2**E and the circuits illustrated in FIG. **2**F is mentioned as below. Referring to FIG. **2**F, for each of the multi-stage tri-state buffers **292** in the pair, the drain terminal of its control P-type MOS transistor **295** may couple to the source terminal of its P-type MOS transistor **293** in the second stage, i.e., output stage, but does not couple to the source terminal of its P-type MOS transistor **293** in the first stage; the source terminal of its P-type MOS transistor **293** in the first stage may couple to the voltage Vcc of power supply and the source terminal of its control P-type MOS transistor **295**. For each of the multi-stage tri-state buffers **292** in the pair, the drain terminal of its control N-type MOS transistor **296** may couple to the source terminal of its N-type MOS transistor **294** in the second stage, i.e., output stage, but does not couple to the source terminal of its N-type MOS transistor **294** in the first stage; the source terminal of its N-type MOS transistor **294** in the first stage may couple to the voltage Vss of ground reference and the source terminal of its control N-type MOS transistor **296**.

Specification for Cross-Point Switches Constructed from Pass/No-Pass Switches

(1) First Type of Cross-Point Switch

FIG. **3**A is a circuit diagram illustrating a first type of cross-point switch composed of six pass/no-pass switches in accordance with an embodiment of the present application. Referring to FIG. **3**A, six pass/no-pass switches **258**, each of which may be any one of the first through sixth types of pass/no-pass switches as illustrated in FIGS. **2**A-**2**F respectively, may compose a first type of cross-point switch **379**. The first type of cross-point switch **379** may have four terminals N**23**-N**26** each configured to be switched to couple to another one of its four terminals N**23**-N**26** via one of its six pass/no-pass switches **258**. One of the first through sixth types of pass/no-pass switches for said each of the pass/no-pass switches **258** may have one of its nodes N**21** and N**22** coupling to one of the four terminals N**23**-N**26** and the other one of its nodes N**21** and N**22** coupling to another one of the four terminals N**23**-N**26**. For example, the first type of cross-point switch **379** may have its terminal N**23** configured to be switched to couple to its terminal N**24** via a first one of its six pass/no-pass switches **258** between its terminals N**23** and N**24**, to its terminal N**25** via a second one of its six pass/no-pass switches **258** between its terminals N**23** and N**25** and/or to its terminal N**26** via a third one of its six pass/no-pass switches **258** between its terminals N**23** and N**26**.

(2) Second Type of Cross-Point Switch

FIG. **3**B is a circuit diagram illustrating a second type of cross-point switch composed of four pass/no-pass switches in accordance with an embodiment of the present application. Referring to FIG. **3**B, four pass/no-pass switches **258**, each of which may be any one of the first through sixth types of pass/no-pass switches as illustrated in FIGS. **2**A-**2**F respectively, may compose a second type of cross-point switch **379**. The second type of cross-point switch **379** may have four terminals N**23**-N**26** each configured to be switched to couple to another one of its four terminals N**23**-N**26** via two of its four pass/no-pass switches **258**. The second type of cross-point switch **379** may have a central node configured to couple to its four terminals N**23**-N**26** via its four respective pass/no-pass switches **258**. One of the first through sixth types of pass/no-pass switches for said each of the pass/no-pass switches **258** may have one of its nodes N**21** and N**22** coupling to one of the four terminals N**23**-N**26** and the other one of its nodes N**21** and N**22** coupling to the central node of the cross-point switch **379** of the second type. For example, the second type of cross-point switch **379** may have its terminal N**23** configured to be switched to couple to its terminal N**24** via left and top ones of its four pass/no-pass switches **258**, to its terminal N**25** via left and right ones of its four pass/no-pass switches **258** and/or to its terminal N**26** via left and bottom ones of its four pass/no-pass switches **258**.

Specification for Multiplexer (MUXER)

(1) First Type of Multiplexer

FIG. **4**A is a circuit diagram illustrating a first type of multiplexer in accordance with an embodiment of the present application. Referring to FIG. **4**A, a first type of multiplexer (MUXER) **211** may select one from its first set of inputs arranged in parallel into its output based on a combination of its second set of inputs arranged in parallel. For example, the first type of multiplexer (MUXER) **211** may have sixteen inputs D**0**-D**15** arranged in parallel to act as its first set of inputs and four inputs A**0**-A**3** arranged in parallel to act as its second set of inputs. The first type of multiplexer (MUXER) **211** may select one from its first set of sixteen inputs D**0**-D**15** into its output Dout based on a combination of its second set of four inputs A**0**-A**3**.

Referring to FIG. **4**A, the first type of multiplexer **211** may include multiple stages of tri-state buffers, e.g., four stages of tri-state buffers **215**, **216**, **217** and **218**, coupling to one another stage by stage. For more elaboration, the first type of multiplexer **211** may include sixteen tri-state buffers **215** in eight pairs in the first stage, arranged in parallel, each having a first input coupling to one of the sixteen inputs D**0**-D**15** in the first set and a second input associated with the input A**3** in the second set. Each of the sixteen tri-state buffers **215** in the first stage may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The first type of multiplexer **211** may include an inverter **219** configured to invert its input coupling to the input A**3** in the second set into its output. One of the tri-state buffers **215** in each pair in the first stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **219** to pass its first input into its output; the other one of the tri-state buffers **215** in said each pair in the first stage may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **219** not to pass its first input into its output. The outputs of the tri-state buffers **215** in said each pair in the first stage may couple to each other. For example, a top one of the tri-state buffers **215** in a topmost pair in the first stage may have its first input coupling to the input D**0** in the first set and its second input coupling to the output of the inverter **219**; a bottom one of the tri-state buffers **215** in the topmost pair in the first stage may have its first input coupling to the input D**1** in the first set and its second input coupling to the input of the inverter **219**. The top one of the tri-state buffers **215** in the topmost pair in the first stage may be switched on in accordance with its second input to pass its first input into its output; the bottom one of the tri-state buffers **215** in the topmost pair in the first stage may be switched off in accordance with its second input not to pass its first input into its output. Thereby, each of the eight pairs of tri-state buffers **215** in the first stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **219** respectively to pass one of its two first inputs into its output coupling to a first input of one of the tri-state buffers **216** in the second stage.

Referring to FIG. **4**A, the first type of multiplexer **211** may include eight tri-state buffers **216** in four pairs in the second stage, arranged in parallel, each having a fast input coupling to the output of one of the eight pairs of tri-state buffers **215** in the first stage and a second input associated with the input A**2** in the second set. Each of the eight tri-state buffers **216** in the second stage may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The first type of multiplexer **211** may include an inverter **220** configured to invert its input coupling to the input A**2** in the second set into its output. One of the tri-state buffers **216** in each pair in the second stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **220** to pass its first input into its output; the other one of the tri-state buffers **216** in said each pair in the second stage may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **220** not to pass its first input into its output. The outputs of the tri-state buffers **216** in said each pair in the second stage may couple to each other. For example, a top one of the tri-state buffers **216** in a topmost pair in the second stage may have its first input coupling to the output of a topmost one of the

eight pairs of tri-state buffers **215** in the first stage and its second input coupling to the output of the inverter **220**; a bottom one of the tri-state buffers **216** in the topmost pair in the second stage may have its first input coupling to the output of a second top one of the eight pairs of tri-state buffers **215** in the first stage and its second input coupling to the input of the inverter **220**. The top one of the tri-state buffers **216** in the topmost pair in the second stage may be switched on in accordance with its second input to pass its first input into its output; the bottom one of the tri-state buffers **216** in the topmost pair in the second stage may be switched off in accordance with its second input not to pass its first input into its output. Thereby, each of the four pairs of tri-state buffers **216** in the second stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **220** respectively to pass one of its two first inputs into its output coupling to a first input of one of the tri-state buffers **217** in the third stage.

Referring to FIG. **4**A, the first type of multiplexer **211** may include four tri-state buffers **217** in two pairs in the third stage, arranged in parallel, each having a first input coupling to the output of one of the four pairs of tri-state buffers **216** in the second stage and a second input associated with the input A**1** in the second set. Each of the four tri-state buffers **217** in the third stage may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The first type of multiplexer **211** may include an inverter **207** configured to invert its input coupling to the input A**1** in the second set into its output One of the tri-state buffers **217** in each pair in the third stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **207** to pass its first input into its output; the other one of the tri-state buffers **217** in said each pair in the third stage may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **207** not to pass its first input into its output. The outputs of the tri-state buffers **217** in said each pair in the third stage may couple to each other. For example, a top one of the tri-state buffers **217** in a top pair in the third stage may have its first input coupling to the output of a topmost one of the four pairs of tri-state buffers **216** in the second stage and its second input coupling to the output of the inverter **207**; a bottom one of the tri-state buffers **217** in the top pair in the third stage may have its first input coupling to the output of a second top one of the four pairs of tri-state buffers **216** in the second stage and its second input coupling to the input of the inverter **207**. The top one of the tri-state buffers **217** in the top pair in the third stage may be switched on in accordance with its second input to pass its first input into its output; the bottom one of the tri-state buffers **217** in the top pair in the third stage may be switched off in accordance with its second input not to pass its first input into its output. Thereby, each of the two pairs of tri-state buffers **217** in the third stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **207** respectively to pass one of its two first inputs into its output coupling to a first input of one of the tri-state buffers **218** in the fourth stage.

Referring to FIG. **4**A, the first type of multiplexer **211** may include a pair of two tri-state buffers **218** in the fourth stage, i.e., output stage, arranged in parallel, each having a first input coupling to the output of one of the two pairs of tri-state buffers **217** in the third stage and a second input associated with the input A**0** in the second set. Each of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The first type of multiplexer **211** may include an inverter **208** configured to invert its input coupling to the input A**0** in the second set into its output One of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may be switched on in accordance with its second input coupling to one of the input and output of the inverter **208** to pass its first input into its output; the other one of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **208** not to pass its first input into its output. The outputs of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may couple to each other. For example, a top one of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may have its first input coupling to the output of a top one of the two pairs of tri-state buffers **217** in the third stage and its second input coupling to the output of the inverter **208**; a bottom one of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may have its first input coupling to the output of a bottom one of the two pairs of tri-state buffers **217** in the third stage and its second input coupling to the input of the inverter **208**. The top one of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may be switched on in accordance with its second input to pass its first input into its output; the bottom one of the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, may be switched off in accordance with its second input not to pass its first input into its output Thereby, the pair of the two tri-state buffers **218** in the fourth stage, i.e., output stage, may be switched in accordance with its two second inputs coupling to the input and output of the inverter **208** respectively to pass one of its two first inputs into its output acting as the output Dout of the multiplexer **211** of the first type.

FIG. **4**B is a circuit diagram illustrating a tri-state buffer of a multiplexer of a first type in accordance with an embodiment of the present application. Referring to FIGS. **4**A and **4**B, each of the tri-state buffers **215**, **216**, **217** and **218** may include (1) a P-type MOS transistor **231** configured to form a channel with an end at the first input of said each of the tri-state buffers **215**, **216**, **217** and **218** and the other opposite end at the output of said each of the tri-state buffers **215**, **216**, **217** and **218**, (2) a N-type MOS transistor **232** configured to form a channel with an end at the first input of said each of the tri-state buffers **215**, **216**, **217** and **218** and the other opposite end at the output of said each of the tri-state buffers **215**, **216**, **217** and **218**, and (3) an inverter **233** configured to invert its input, at the second input of said each of the tri-state buffers **215**, **216**, **217** and **218**, coupling to a gate terminal of the N-type MOS transistor **232** into its output coupling to a gate terminal of the P-type MOS transistor **231**. For each of the tri-state buffers **215**, **216**, **217** and **218**, when its inverter **233** has its input at a logic level of "1", each of its P-type and N-type MOS transistors **231** and **232** may be switched on to pass its first input to its output via the channels of its P-type and N-type MOS transistors **231** and **232**; when its inverter **233** has its input at a logic level of "0", each of its P-type and N-type MOS transistors **231** and **232** may be switched off not to form any channel therein such that its first input may not be passed to its output. For the two tri-state buffers **215** in each pair in the first stage, their two respective inverters **233** may have their two respective inputs coupling respectively to the output and input of the inverter **219**, which are associated with the input A**3** in the second set. For the two tri-state buffers **216** in each

pair in the second stage, their two respective inverters **233** may have their two respective inputs coupling respectively to the output and input of the inverter **220**, which are associated with the input A**2** in the second set. For the two tri-state buffers **217** in each pair in the third stage, their two respective inverters **233** may have their two respective inputs coupling respectively to the output and input of the inverter **207**, which are associated with the input A**1** in the second set. For the two tri-state buffers **218** in the pair in the fourth stage, i.e., output stage, their two respective inverters **233** may have their two respective inputs coupling respectively to the output and input of the inverter **208**, which are associated with the input A**0** in the second set.

The first type of multiplexer (MUXER) **211** may select one from its first set of sixteen inputs D**0**-D**15** into its output Dout based on a combination of its second set of four inputs A**0**-A**3**.

(2) Second Type of Multiplexer

FIG. **4**C is a circuit diagram of a second type of multiplexer in accordance with an embodiment of the present application.

Referring to FIG. **4**C, a second type of multiplexer **211** is similar to the first type of multiplexer **211** as illustrated in FIGS. **4**A and **4**B but may further include the third type of pass/no-pass switch or switch buffer **292** as seen in FIG. **2**C having its input at the node N**21** coupling to the output of the pair of tri-state buffers **218** in the last stage, e.g., in the fourth stage or output stage in this case. For an element indicated by the same reference number shown in FIGS. **2**C, **4**A, **4**B and **4**C, the specification of the element as seen in FIG. **4**C may be referred to that of the element as illustrated in FIG. **2**C, **4**A or **4**B. Accordingly, referring to FIG. **4**C, the third type of pass/no-pass switch **292** may amplify its input at the node N**21** into its output at the node N**22** acting as an output Dout of the multiplexer **211** of the second type.

The second type of multiplexer (MUXER) **211** may select one from its first set of sixteen inputs D**0**-D**15** into its output Dout based on a combination of its second set of four inputs A**0**-A**3**.

(3) Third Type of Multiplexer

FIG. **4**D is a circuit diagram of a third type of multiplexer in accordance with an embodiment of the present application. Referring to FIG. **4**D, a third type of multiplexer **211** is similar to the first type of multiplexer **211** as illustrated in FIGS. **4**A and **4**B but may further include the fourth type of pass/no-pass switch **292** or switch buffer as seen in FIG. **2**D having its input at the node N**21** coupling to the output of the pair of tri-state buffers **218** in the last stage, e.g., in the fourth stage or output stage in this case. For an element indicated by the same reference number shown in FIGS. **2**C, **2**D, **4**A, **4**B, **4**C and **4**D, the specification of the element as seen in FIG. **4**D may be referred to that of the element as illustrated in FIG. **2**C, **2**D, **4**A, **4**B or **4**C. Accordingly, referring to FIG. **4**D, the fourth type of pass/no-pass switch **292** may amplify its input at the node N**21** into its output at the node N**22** acting as an output Dout of the multiplexer **211** of the third type.

The third type of multiplexer (MUXER) **211** may select one from its first set of sixteen inputs D**0**-D**15** into its output Dout based on a combination of its second set of four inputs A**0**-A**3**.

Alternatively, the first, second or third type of multiplexer (MUXER) **211** may have the first set of inputs, arranged in parallel, having the number of 2 to the power of n and the second set of inputs, arranged in parallel, having the number of n, wherein the number n may be any integer greater than or equal to 2, such as between 2 and 64. FIG. **4**E is a schematic view showing a circuit diagram of a multiplexer in accordance with an embodiment of the present application. In this example, referring to FIG. **4**E, each of the multiplexers **211** of the first through third types as illustrated in FIGS. **4**A, **4**C and **4**D may be modified with its second set of inputs A**0**-A**7**, having the number of n equal to 8, and its first set of 256 inputs D**0**-D**255**, i.e. the resulting values or programming codes for all combinations of its second set of inputs A**0**-A**7**, having the number of 2 to the power of n equal to 8. Each of the multiplexers **211** of the first through third types may include eight stages of tri-state buffers or switch buffers, each having the same architecture as illustrated in FIG. **4**B, coupling to one another stage by stage. The tri-state buffers or switch buffers in the first stage, arranged in parallel, may have the number of 256 each having its first input coupling to one of the 256 inputs D**0**-D**255** of the first set of said each of the multiplexers **211** and each may be switched on or off to pass or not to pass its first input into its output in accordance with its second input associated with the input A**7** of the second set of said each of the multiplexers **211**. The tri-state buffers or switch buffers in each of the second through seventh stages, arranged in parallel, each may have its first input coupling to an output of one of multiple pairs of tri-state buffers or switch buffers in a stage previous to said each of the second through seventh stages and may be switched on or off to pass or not to pass its first input into its output in accordance with its second input associated with one of the respective inputs A**6**-A**1** of the second set of said each of the multiplexers **211**. Each of the tri-state buffers or switch buffers in a pair in the eighth stage, i.e., output stage, may have its first input coupling to an output of one of multiple pairs of tri-state buffers or switch buffers in the seventh stage and may be switched on or off to pass or not to pass its first input into its output, which may act as an output Dout of the multiplexer **211**, in accordance with its second input associated with the input A**0** of the second set of said each of the multiplexers **211**. Alternatively, one of the pass/no-pass switches or switch buffers **292** as seen in FIGS. **4**C and **4**D may be incorporated to amplify its input coupling to the output of the tri-state buffers or switch buffers in the pair in the eighth stage, i.e., output stage, into its output Dout, which may act as an output of the multiplexer **211**.

For example, FIG. **4**F is a schematic view showing a circuit diagram of a multiplexer in accordance with an embodiment of the present application. Referring to FIG. **4**F, the second type of multiplexer **211** may have the first set of inputs D**0**, D**1** and D**2** arranged in parallel and the second set of inputs A**0** and A**1** arranged in parallel. The second type of multiplexer **211** may include two stages of tri-state buffers **217** and **218** coupling to each other stage by stage. For more elaboration, the second type of multiplexer **211** may include third tri-state buffers **217** in the first stage, arranged in parallel, each having a first input coupling to one of the third inputs D**0**-D**2** in the first set and a second input associated with the input A**1** in the second set. Each of the three tri-state buffers **217** in the first stage may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The second type of multiplexer **211** may include the inverter **207** configured to invert its input coupling to the input A**1** in the second set into its output. One of the top two tri-state buffers **217** in a pair in the first stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **207** to pass its first input into its output; the other one of the top two tri-state buffers **217** in the pair in the first stage may be switched off in accordance with its second input coupling to

the other one of the input and output of the inverter **207** not to pass its first input into its output. The outputs of the top two tri-state buffers **217** in the pair in the first stage may couple to each other. Thereby, the pair of top two tri-state buffers **217** in the first stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **207** respectively to pass one of its two first inputs into its output coupling to a first input of one of the tri-state buffers **218** in the second stage. The bottom one of the tri-state buffers **217** in the first stage may be switched on or off in accordance with its second input coupling to the output of the inverter **207** to or not to pass its first input into its output coupling to a first input of the other one of the tri-state buffers **218** in the second stage, i.e., output stage.

Referring to FIG. **4**F, the second type of multiplexer **211** may include a pair of two tri-state buffers **218** in the second stage or output stage, arranged in parallel, a top one of which has a first input coupling to the output of the pair of top two tri-state buffers **217** in the first stage and a second input associated with the input A**0** in the second set, and a bottom one of which has a first input coupling to the output of the bottom one of the tri-state buffers **217** in the first stage and a second input associated with the input A**0** in the second set. Each of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The second type of multiplexer **211** may include the inverter **208** configured to invert its input coupling to the input A**0** in the second set into its output. One of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched on in accordance with its second input coupling to one of the input and output of the inverter **208** to pass its first input into its output; the other one of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **208** not to pass its first input into its output. The outputs of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may couple to each other. Thereby, the pair of the two tri-state buffers **218** in the second stage, i.e., output stage, may be switched in accordance with its two second inputs coupling to the input and output of the inverter **208** respectively to pass one of its two first inputs into its output. The second type of multiplexer **211** may further include the third type of pass/no-pass switch **292** as seen in FIG. **2**C having its input at the node N**21** coupling to the output of the pair of tri-state buffers **218** in the second stage, i.e., output stage. The third type of pass/no-pass switch **292** may amplify its input at the node N**21** into its output at the node N**22** acting as an output Dout of the multiplexer **211** of the second type.

For example, FIG. **4**G is a schematic view showing a circuit diagram of a multiplexer in accordance with an embodiment of the present application. Referring to FIG. **4**G, the second type of multiplexer **211** may have the first set of inputs D**0**-D**3** arranged in parallel and the second set of inputs A**0** and A**1** arranged in parallel. The second type of multiplexer **211** may include two stages of tri-state buffers **217** and **218** coupling to each other stage by stage. For more elaboration, the second type of multiplexer **211** may include third tri-state buffers **217** in the first stage, arranged in parallel, each having a first input coupling to one of the third inputs D**0**-D**3** in the first set and a second input associated with the input A**1** in the second set. Each of the four tri-state buffers **217** in the first stage may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The second type of multiplexer **211** may include the inverter **207** configured to invert its input coupling to the input A**1** in the second set into its output. One of the top two tri-state buffers **217** in a pair in the first stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **207** to pass its first input into its output; the other one of the top two tri-state buffers **217** in the pair in the first stage may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **207** not to pass its first input into its output. The outputs of the top two tri-state buffers **217** in the pair in the first stage may couple to each other. Thereby, the pair of top two tri-state buffers **217** in the first stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **207** respectively to pass one of its two first inputs into its output coupling to a first input of one of the tri-state buffers **218** in the second stage, i.e., output stage. One of the bottom two tri-state buffers **217** in a pair in the first stage may be switched on in accordance with its second input coupling to one of the input and output of the inverter **207** to pass its first input into its output; the other one of the bottom two tri-state buffers **217** in the pair in the first stage may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **207** not to pass its first input into its output. The outputs of the bottom two tri-state buffers **217** in the pair in the first stage may couple to each other. Thereby, the pair of bottom two tri-state buffers **217** in the first stage may be switched in accordance with its two second inputs coupling to the input and output of the inverter **207** respectively to pass one of its two first inputs into its output coupling to a first input of the other one of the tri-state buffers **218** in the second stage, i.e., output stage.

Referring to FIG. **4**G, the second type of multiplexer **211** may include a pair of two tri-state buffers **218** in the second stage or output stage, arranged in parallel, a top one of which has a first input coupling to the output of the pair of top two tri-state buffers **217** in the first stage and a second input associated with the input A**0** in the second set, and a bottom one of which has a first input coupling to the output of the pair of bottom two tri-state buffers **217** in the first stage and a second input associated with the input A**0** in the second set. Each of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched on or off to pass or not to pass its first input into its output in accordance with its second input. The second type of multiplexer **211** may include the inverter **208** configured to invert its input coupling to the input A**0** in the second set into its output. One of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched on in accordance with its second input coupling to one of the input and output of the inverter **208** to pass its first input into its output; the other one of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may be switched off in accordance with its second input coupling to the other one of the input and output of the inverter **208** not to pass its first input into its output. The outputs of the two tri-state buffers **218** in the pair in the second stage, i.e., output stage, may couple to each other. Thereby, the pair of the two tri-state buffers **218** in the second stage, i.e., output stage, may be switched in accordance with its two second inputs coupling to the input and output of the inverter **208** respectively to pass one of its two first inputs into its output. The second type of multiplexer **211** may further include the third type of pass/no-pass switch **292** as seen in FIG. **2**C having its input at the node N**21** coupling to the output of the pair of tri-state buffers **218** in the second stage, i.e., output stage. The third type of

pass/no-pass switch **292** may amplify its input at the node N**21** into its output at the node N**22** acting as an output Dout of the multiplexer **211** of the second type.

Alternatively, referring to FIGS. **4**A-**4**G, each of the tri-state buffers **215**, **216**, **217** and **218** may be replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor, as seen in FIGS. **4**H-**4**L. FIGS. **4**H-**4**L are schematic views showing circuit diagrams of multiplexers in accordance with an embodiment of the present application. For more elaboration, the first type of multiplexer **211** as seen in FIG. **4**H is similar to that as seen in FIG. **4**A, but the difference therebetween is that each of the tri-state buffers **215**, **216**, **217** and **218** is replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor. The second type of multiplexer **211** as seen in FIG. **4**I is similar to that as seen in FIG. **4**C, but the difference therebetween is that each of the tri-state buffers **215**, **216**, **217** and **218** is replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor. The third type of multiplexer **211** as seen in FIG. **4**J is similar to that as seen in FIG. **4**D, but the difference therebetween is that each of the tri-state buffers **215**, **216**, **217** and **218** is replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor. The second type of multiplexer **211** as seen in FIG. **4**K is similar to that as seen in FIG. **4**F, but the difference therebetween is that each of the tri-state buffers **217** and **218** is replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor. The second type of multiplexer **211** as seen in FIG. **4**L is similar to that as seen in FIG. **4**G, but the difference therebetween is that each of the tri-state buffers **217** and **218** is replaced with a transistor, such as N-type MOS transistor or P-type MOS transistor.

Referring to FIGS. **4**H-**4**L, each of the transistors **215** may be configured to form a channel with an input terminal coupling to what the first input of replaced one of the tri-state buffers **215** seen in FIGS. **4**A-**4**G couples, and an output terminal coupling to what the output of the replaced one of the tri-state buffers **215** seen in FIGS. **4**A-**4**G couples, and may have a gate terminal coupling to what the second input of the replaced one of the tri-state buffers **215** seen in FIGS. **4**A-**4**G couples. Each of the transistors **216** may be configured to form a channel with an input terminal coupling to what the first input of replaced one of the tri-state buffers **216** seen in FIGS. **4**A-**4**G couples, and an output terminal coupling to what the output of the replaced one of the tri-state buffers **216** seen in FIGS. **4**A-**4**G couples, and may have a gate terminal coupling to what the second input of the replaced one of the tri-state buffers **216** seen in FIGS. **4**A-**4**G couples. Each of the transistors **217** may be configured to form a channel with an input terminal coupling to what the first input of replaced one of the tri-state buffers **217** seen in FIGS. **4**A-**4**G couples, and an output terminal coupling to what the output of the replaced one of the tri-state buffers **217** seen in FIGS. **4**A-**4**G couples, and may have a gate terminal coupling to what the second input of the replaced one of the tri-state buffers **217** seen in FIGS. **4**A-**4**G couples. Each of the transistors **218** may be configured to form a channel with an input terminal coupling to what the first input of replaced one of the tri-state buffers **218** seen in FIGS. **4**A-**4**G couples, and an output terminal coupling to what the output of the replaced one of the tri-state buffers **218** seen in FIGS. **4**A-**4**G couples, and may have a gate terminal coupling to what the second input of the replaced one of the tri-state buffers **218** seen in FIGS. **4**A-**4**G couples.

Specification for Cross-Point Switches Constructed from Multiplexers

The first and second types of cross-point switches **379** as illustrated in FIGS. **3**A and **3**B are fabricated from a plurality of the pass/no-pass switches **258** seen in FIGS. **2**A-**2**F. Alternatively, cross-point switches **379** may be fabricated from either of the first through third types of multiplexers **211**, mentioned as below.

(1) Third Type of Cross-Point Switch

FIG. **3**C is a circuit diagram illustrating a third type of cross-point switch composed of multiple multiplexers in accordance with an embodiment of the present application. Referring to FIG. **3**C, the third type of cross-point switch **379** may include four multiplexers **211** of the first, second or third type as seen in FIGS. **4**A-**4**L each having three inputs in the first set and two inputs in the second set and being configured to pass one of its three inputs in the first set into its output in accordance with a combination of its two inputs in the second set. Particularly, the second type of the multiplexer **211** employed in the third type of cross-point switch **379** may be referred to that illustrated in FIGS. **4**F and **4**K. Each of the three inputs D**0**-D**2** of the first set of one of the four multiplexers **211** may couple to one of its three inputs D**0**-D**2** of the first set of another two of the four multiplexers **211** and to an output Dout of the other one of the four multiplexers **211**. Thereby, each of the four multiplexers **211** may pass one of its three inputs D**0**-D**2** in the first set coupling to three respective metal lines extending in three different directions to the three outputs Dout of the other three of the four multiplexers **211** into its output Dout in accordance with a combination of its two inputs A**0** and A**1** in the second set. Each of the four multiplexers **211** may include the pass/no-pass switch or switch buffer **292** configured to be switched on or off in accordance with its input SC-**4** to pass or not to pass one of its three inputs D**0**-D**2** in the first set, passed in accordance with the second set of its inputs A**0** and A**1**, into its output Dout. For example, the top one of the four multiplexers **211** may pass one of its three inputs in the first set coupling to the three outputs Dout at nodes N**23**, N**26** and N**25** of the left, bottom and right ones of the four multiplexers **211** into its output Dout at a node N**24** in accordance with a combination of its two inputs $A0_1$ and $A1_1$ in the second set. The top one of the four multiplexers **211** may include the pass/no-pass switch or switch buffer **292** configured to be switched on or off in accordance with the second set of its input SC_1-**4** to pass or not to pass one of its three inputs in the first set, passed in accordance with the second set of its inputs $A0_1$ and $A1_1$, into its output Dout at the node N**24**.

(2) Fourth Type of Cross-Point Switch

FIG. **3**D is a circuit diagram illustrating a fourth type of cross-point switch composed of a multiplexer in accordance with an embodiment of the present application. Referring to FIG. **3**D, the fourth type of cross-point switch **379** may be provided from any of the multiplexers **211** of the first through third types as illustrated in FIGS. **4**A-**4**L. When the fourth type of cross-point switch **379** is provided by one of the multiplexers **211** as illustrated in FIGS. **4**A, **4**C, **4**D and **4**H-**4**J, it is configured to pass one of its 16 inputs D**0**-D**15** in the first set into its output Dout in accordance with a combination of its four inputs A**0**-A**3** in the second set.

Specification for Large I/O Circuits

FIG. **5**A is a circuit diagram of a large I/O circuit in accordance with an embodiment of the present application. Referring to FIG. **5**A, a semiconductor chip may include multiple I/O pads **272** each coupling to its large ESD protection circuit or device **273**, its large driver **274** and its large receiver **275**. The large driver **274**, large receiver **275** and large ESD protection circuit or device **273** may compose

a large I/O circuit **341**. The large ESD protection circuit or device **273** may include a diode **282** having a cathode coupling to the voltage Vcc of power supply and an anode coupling to a node **281** and a diode **283** having a cathode coupling to the node **281** and an anode coupling to the voltage Vss of ground reference. The node **281** couples to one of the I/O pads **272**.

Referring to FIG. **5**A, the large driver **274** may have a first input coupling to an L_Enable signal for enabling the large driver **274** and a second input coupling to data of L_Data_out for amplifying or driving the data of L_Data_out into its output at the node **281** to be transmitted to circuits outside the semiconductor chip through said one of the I/O pads **272**. The large driver **274** may include a P-type MOS transistor **285** and N-type MOS transistor **286** both having respective drain terminals coupling to each other as its output at the node **281** and respective source terminals coupling to the voltage Vcc of power supply and to the voltage Vss of ground reference. The large driver **274** may have a NAND gate **287** having an output coupling to a gate terminal of the P-type MOS transistor **285** and a NOR gate **288** having an output coupling to a gate terminal of the N-type MOS transistor **286**. The large driver **274** may include the NAND gate **287** having a first input coupling to an output of its inverter **289** and a second input coupling to the data of L_Data_out to perform a NAND operation on its first and second inputs into its output coupling to a gate terminal of its P-type MOS transistor **285**. The large driver **274** may include the NOR gate **288** having a first input coupling to the data of L_Data_out and a second input coupling to the L_Enable signal to perform a NOR operation on its first and second inputs into its output coupling to a gate terminal of the N-type MOS transistor **286**. The inverter **289** may be configured to invert its input coupling to the L_Enable signal into its output coupling to the first input of the NAND gate **287**.

Referring to FIG. **5**A, when the L_Enable signal is at a logic level of "1", the output of the NAND gate **287** is always at a logic level of "1" to turn off the P-type MOS transistor **285** and the output of the NOR gate **288** is always at a logic level of "0" to turn off the N-type MOS transistor **286**. Thereby, the large driver **274** may be disabled by the L_Enable signal and the data of L_Data_out may not be passed to the output of the large driver **274** at the node **281**.

Referring to FIG. **5**A, the large driver **274** may be enabled when the L_Enable signal is at a logic level of "0". Meanwhile, if the data of L_Data_out is at a logic level of "0", the outputs of the NAND and NOR gates **287** and **288** are at logic level of "1" to turn off the P-type MOS transistor **285** and on the N-type MOS transistor **286**, and thereby the output of the large driver **274** at the node **281** is at a logic level of "0" to be passed to said one of the I/O pads **272**. If the data of L_Data_out is at a logic level of "1", the outputs of the NAND and NOR gates **287** and **288** are at logic level of "0" to turn on the P-type MOS transistor **285** and off the N-type MOS transistor **286**, and thereby the output of the large driver **274** at the node **281** is at a logic level of "1" to be passed to said one of the I/O pads **272**. Accordingly, the large driver **274** may be enabled by the L_Enable signal to amplify or drive the data of L_Data_out into its output at the node **281** coupling to one of the I/O pads **272**.

Referring to FIG. **5**A, the large receiver **275** may have a first input coupling to said one of the I/O pads **272** to be amplified or driven by the large receiver **275** into its output of L_Data_in and a second input coupling to an L_Inhibit signal to inhibit the large receiver **275** from generating its output of L_Data_in associated with data at its first input. The large receiver **275** may include a NAND gate **290** having a first input coupling to said one of the I/O pads **272** and a second input coupling to the L_Inhibit signal to perform a NAND operation on its first and second inputs into its output coupling to its inverter **291**. The inverter **291** may be configured to invert its input coupling to the output of the NAND gate **290** into its output acting as the output of L_Data_in of the large receiver **275**.

Referring to FIG. **5**A, when the L_Inhibit signal is at a logic level of "0", the output of the NAND gate **290** is always at a logic level of "1" and the output L_Data_in of the large receiver **275** is always at a logic level of "0". Thereby, the large receiver **275** is inhibited from generating its output of L_Data_in associated with its first input at said one of the I/O pads **272**.

Referring to FIG. **5**A, the large receiver **275** may be activated when the L_Inhibit signal is at a logic level of "1". Meanwhile, if data from circuits outside the chip to said one of the I/O pads **272** is at a logic level of "1", the NAND gate **290** has its output at a logic level of "0", and thereby the large receiver **275** may have its output of L_Data_in at a logic level of "1". If data from circuits outside the chip to said one of the I/O pads **272** is at a logic level of "0", the NAND gate **290** has its output at a logic level of "1", and thereby the large receiver **275** may have its output of L_Data_in at a logic level of "0". Accordingly, the large receiver **275** may be activated by the L_Inhibit signal to amplify or drive data from circuits outside the chip to said one of the I/O pads **272** into its output of L_Data_in.

Referring to FIG. **5**A, said one of the I/O pads **272** may have an input capacitance, provided by the large ESD protection circuit or device **273** and large receiver **275** for example, between 2 pF and 100 pF, between 2 pF and 50 pF, between 2 pF and 30 pF, or greater than 2 pF, 5 pF, 10 pF, 15 pF or 20 pF. The large driver **274** may have an output capacitance or driving capability or loading, for example, between 2 pF and 100 pF, between 2 pF and 50 pF, between 2 pF and 30 pF, or greater than 2 pF, 5 pF, 10 pF, 15 pF or 20 pF. The size of the large ESD protection circuit or device **273** may be between 0.5 pF and 20 pF, 0.5 pF and 15 pF, 0.5 pF and 10 pF 0.5 pF and 5 pF or 0.5 pF and 2 pF, or larger than 0.5 pF, 1 pF, 2 pF, 3 pF, 5 pF or 10 pF.

Specification for Small I/O Circuits

FIG. **5**B is a circuit diagram of a small I/O circuit in accordance with an embodiment of the present application. Referring to FIG. **5**B, a semiconductor chip may include multiple I/O pads **372** each coupling to its small ESD protection circuit or device **373**, its small driver **374** and its small receiver **375**. The small driver **374**, small receiver **375** and small ESD protection circuit or device **373** may compose a small I/O circuit **203**. The small ESD protection circuit or device **373** may include a diode **382** having a cathode coupling to the voltage Vcc of power supply and an anode coupling to a node **381** and a diode **383** having a cathode coupling to the node **381** and an anode coupling to the voltage Vss of ground reference. The node **381** couples to one of the I/O pads **372**.

Referring to FIG. **5**B, the small driver **374** may have a first input coupling to an S_Enable signal for enabling the small driver **374** and a second input coupling to data of S_Data_out for amplifying or driving the data of S_Data_out into its output at the node **381** to be transmitted to circuits outside the semiconductor chip through said one of the I/O pads **372**. The small driver **374** may include a P-type MOS transistor **385** and N-type MOS transistor **386** both having respective drain terminals coupling to each other as its output at the node **381** and respective source

terminals coupling to the voltage Vcc of power supply and to the voltage Vss of ground reference. The small driver **374** may have a NAND gate **387** having an output coupling to a gate terminal of the P-type MOS transistor **385** and a NOR gate **388** having an output coupling to a gate terminal of the N-type MOS transistor **386**. The small driver **374** may include the NAND gate **387** having a first input coupling to an output of its inverter **389** and a second input coupling to the data of S_Data_out to perform a NAND operation on its first and second inputs into its output coupling to a gate terminal of its P-type MOS transistor **385**. The small driver **374** may include the NOR gate **388** having a first input coupling to the data of S_Data_out and a second input coupling to the S_Enable signal to perform a NOR operation on its first and second inputs into its output coupling to a gate terminal of the N-type MOS transistor **386**. The inverter **389** may be configured to invert its input coupling to the S_Enable signal into its output coupling to the first input of the NAND gate **387**.

Referring to FIG. **5**B, when the S_Enable signal is at a logic level of "1", the output of the NAND gate **387** is always at a logic level of "1" to turn off the P-type MOS transistor **385** and the output of the NOR gate **388** is always at a logic level of "0" to turn off the N-type MOS transistor **386**. Thereby, the small driver **374** may be disabled by the S_Enable signal and the data of S_Data_out may not be passed to the output of the small driver **374** at the node **381**.

Referring to FIG. **5**B, the small driver **374** may be enabled when the S_Enable signal is at a logic level of "0". Meanwhile, if the data of S_Data_out is at a logic level of "0", the outputs of the NAND and NOR gates **387** and **388** are at logic level of "1" to turn off the P-type MOS transistor **385** and on the N-type MOS transistor **386**, and thereby the output of the small driver **374** at the node **381** is at a logic level of "0" to be passed to said one of the I/O pads **372**. If the data of S_Data_out is at a logic level of "1", the outputs of the NAND and NOR gates **387** and **388** are at logic level of "0" to turn on the P-type MOS transistor **385** and off the N-type MOS transistor **386**, and thereby the output of the small driver **374** at the node **381** is at a logic level of "1" to be passed to said one of the I/O pads **372**. Accordingly, the small driver **374** may be enabled by the S_Enable signal to amplify or drive the data of S_Data_out into its output at the node **381** coupling to one of the I/O pads **372**.

Referring to FIG. **5**B, the small receiver **375** may have a first input coupling to said one of the I/O pads **372** to be amplified or driven by the small receiver **375** into its output of S_Data_in and a second input coupling to an S_Inhibit signal to inhibit the small receiver **375** from generating its output of S_Data_in associated with its first input. The small receiver **375** may include a NAND gate **390** having a first input coupling to said one of the I/O pads **372** and a second input coupling to the S_Inhibit signal to perform a NAND operation on its first and second inputs into its output coupling to its inverter **391**. The inverter **391** may be configured to invert its input coupling to the output of the NAND gate **390** into its output acting as the output of S_Data_in of the small receiver **375**.

Referring to FIG. **5**B, when the S_Inhibit signal is at a logic level of "0", the output of the NAND gate **390** is always at a logic level of "1" and the output S_Data_in of the small receiver **375** is always at a logic level of "0". Thereby, the small receiver **375** is inhibited from generating its output of S_Data_in associated with its first input at said one of the I/O pads **372**.

Referring to FIG. **5**B, the small receiver **375** may be activated when the S_Inhibit signal is at a logic level of "1". Meanwhile, if data from circuits outside the semiconductor chip to said one of the I/O pads **372** is at a logic level of "1", the NAND gate **390** has its output at a logic level of "0", and thereby the small receiver **375** may have its output of S_Data_in at a logic level of "1". If data from circuits outside the chip to said one of the I/O pads **372** is at a logic level of "0", the NAND gate **390** has its output at a logic level of "1", and thereby the small receiver **375** may have its output of S_Data_in at a logic level of "0". Accordingly, the small receiver **375** may be activated by the S_Inhibit signal to amplify or drive data from circuits outside the chip to said one of the I/O pads **372** into its output of S_Data_in.

Referring to FIG. **5**B, said one of the I/O pads **372** may have an input capacitance, provided by the small ESD protection circuit or device **373** and small receiver **375** for example, between 0.1 pF and 10 pF, between 0.1 pF and 5 pF, between 0.1 pF and 3 pF or between 0.1 pF and 2 pF, or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF. The small driver **374** may have an output capacitance or driving capability or loading, for example, between 0.1 pF and 10 pF, between 0.1 pF and 5 pF, between 0.1 pF and 3 pF or between 0.1 pF and 2 pF, or smaller than 10 pF, 5 pF, 3 pF, 2 pF or 1 pF. The size of the small ESD protection circuit or device **373** may be between 0.05 pF and 10 pF, 0.05 pF and 5 pF, 0.05 pF and 2 pF or 0.05 pF and 1 pF; or smaller than 5 pF, 3 pF, 2 pF, 1 pF or 0.5 pF.

Specification for Programmable Logic Blocks

FIG. **6**A is a schematic view showing a block diagram of a programmable logic block in accordance with an embodiment of the present application. Referring to FIG. **6**A, a programmable logic block (LB) **201** may be of various types, including a look-up table (LUT) **210** and a multiplexer **211** having its first set of inputs, e.g., D**0**-D**15** as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J or D**0**-D**255** as illustrated in FIG. **4**E, each coupling to one of resulting values or programming codes stored in the look-up table (LUT) **210** and its second set of inputs, e.g., four-digit inputs of A**0**-A**3** as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J or eight-digit inputs of A**0**-A**7** as illustrated in FIG. **4**E, configured to determine one of the inputs in its first set into its output, e.g., Dout as illustrated in FIG. **4**A, **4**C-**4**E or **4**H-**4**J, acting as an output of the programmable logic block (LB) **201**. The inputs, e.g., A**0**-A**3** as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J or A**0**-A**7** as illustrated in FIG. **4**E, of the second set of the multiplexer **211** may act as inputs of the programmable logic block (LB) **201**.

Referring to FIG. **6**A, the look-up table (LUT) **210** of the programmable logic block (LB) **201** may be composed of multiple memory cells **490** each configured to save or store one of the resulting values, i.e., programming codes. Each of the memory cells **490** may be referred to one **398** as illustrated in FIG. **1**A or **1**B. Its multiplexer **211** may have its first set of inputs, e.g., D**0**-D**15** as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J or D**0**-D**255** as illustrated in FIG. **4**E, each coupling to one of the outputs of one of the memory cells **490**, i.e., one of the outputs Out**1** and Out**2** of the memory cell **398**, for the look-up table (LUT) **210**. Thus, each of the resulting values or programming codes stored in the respective memory cells **490** may couple to one of the inputs of the first set of the multiplexer **211** of the programmable logic block (LB) **201**.

Furthermore, the programmable logic block (LB) **201** may be composed of another memory cell **490** configured to save or store a programming code, wherein the another memory cell **490** may have an output coupling to the input SC-**4** of the multi-stage tri-state buffer **292** as seen in FIG. **4**C, **4**D, **4**I or **4**J of the multiplexer **211** of the second or third

type for the programmable logic block (LB) **201**. Each of the another memory cells **490** may be referred to one **398** as illustrated in FIG. **1**A or **1**B. For its multiplexer **211** of the second or third type as seen in FIG. **4**C, **4**D, **4**I or **4**J for the programmable logic block (LB) **201**, its multi-stage tri-state buffer **292** may have the input SC-**4** coupling to one of the outputs Out**1** and Out**2** of one of the another memory cells **398** as illustrated in FIG. **1**A or **1**B configured to save or store a programming code to switch on or off it. Alternatively, for the multiplexer **211** of the second or third type as seen in FIG. **4**C, **4**D, **4**I or **4**J for the programmable logic block (LB) **201**, its multi-stage tri-state buffer **292** may be provided with the control P-type and N-type MOS transistors **295** and **296** having gate terminals coupling respectively to the outputs Out**1** and Out**2** of one of the another memory cells **398** as illustrated in FIG. **1**A or **1**B configured to save or store a programming code to switch on or off it, wherein its inverter **297** as seen in FIG. **4**C, **4**D, **4**I or **4**J may be removed from it.

The programmable logic block **201** may include the look-up table **210** that may be programed to store or save the resulting values or programing codes for logic operation or Boolean operation, such as AND, NAND, OR, NOR operation or an operation combining the two or more of the above operations. For example, the look-up table **210** may be programed to lead the programmable logic block **201** to achieve the same logic operation as a logic operator, i.e., OR operator or gate, as shown in FIG. **6**B performs. For this case, the programmable logic block **201** may have two inputs, e.g., A**0** and A**1**, and an output, e.g., Dout. FIG. **6**C shows the look-up table **210** configured for achieving the OR operator as illustrated in FIG. **6**B performs. Referring to FIG. **6**C, the look-up table **210** records or stores each of four resulting values or programming codes of the OR operator as illustrated in FIG. **6**B that are generated respectively in accordance with four combinations of its inputs A**0** and A**1**. The look-up table **210** may be programmed with the four resulting values or programming codes respectively stored in the four memory cells **490**, each of which may be referred to one **398** as illustrated in FIG. **1**A or **1**B having its output Out**1** or Out**2** coupling to one of the four inputs D**0**-D**3** of the first set of the multiplexer **211**, as illustrated in FIG. **4**G or **4**L, for the programmable logic block (LB) **201**. The multiplexer **211** may be configured to determine one of its four inputs, e.g., D**0**-D**3**, of the first set into its output, e.g., Dout as illustrated in FIG. **4**G or **4**L, in accordance with one of the combinations of its inputs A**0** and A**1** of the second set. The output Dout of the multiplexer **211** as seen in FIG. **6**A may act as the output of the programmable logic block (LB) **201**.

For example, the look-up table **210** may be programed to lead the programmable logic block **201** to achieve the same logic operation as a logic operator, i.e., AND gate or operator, as shown in FIG. **6**D performs. For this case, the programmable logic block **201** may have two inputs, e.g., A**0** and A**1**, and an output, e.g., Dout. FIG. **6**E shows the look-up table **210** configured for achieving the AND operator as illustrated in FIG. **6**D performs. Referring to FIG. **6**E, the look-up table **210** records or stores each of four resulting values or programming codes of the AND operator as illustrated in FIG. **6**D that are generated respectively in accordance with four combinations of its inputs A**0** and A**1**. The look-up table **210** may be programmed with the four resulting values or programming codes respectively stored in the four memory cells **490**, each of which may be referred to one **398** as illustrated in FIG. **1**A or **1**B having its output Out**1** or Out**2** coupling to one of the four inputs D**0**-D**3** of the first set of the multiplexer **211**, as illustrated in FIG. **4**G or **4**L, for the programmable logic block (LB) **201**. The multiplexer **211** may be configured to determine one of its four inputs, e.g., D**0**-D**3**, of the first set into its output, e.g., Dout as illustrated in FIG. **4**G or **4**L, in accordance with one of the combinations of its inputs A**0** and A**1** of the second set. The output Dout of the multiplexer **211** as seen in FIG. **6**A may act as the output of the programmable logic block (LB) **201**.

For example, the look-up table **210** may be programed to lead the programmable logic block **201** to achieve the same logic operation as a logic operator as shown in FIG. **6**F performs. Referring to FIG. **6**F, the logic operator may be provided with an AND gate **212** and NAND gate **213** arranged in parallel, wherein the AND gate **212** is configured to perform an AND operation on its two inputs X**0** and X**1**, i.e. two inputs of the logic operator, into its output and the NAND gate **213** is configured to perform an NAND operation on its two inputs X**2** and X**3**, i.e. the other two inputs of the logic operator, into its output, and with an NAND gate **214** having two inputs coupling to the outputs of the AND gate **212** and NAND gate **213** respectively. The NAND gate **214** is configured to perform an NAND operation on its two inputs into its output Y acting as an output of the logic operator. The programmable logic block (LB) **201** as seen in FIG. **6**A may achieve the same logic operation as the logic operator as illustrated in FIG. **6**F performs. For this case, the programmable logic block **201** may have four inputs, e.g., A**0**-A**3**, a first one A**0** of which may be equivalent to the input X**0**, a second one A**1** of which may be equivalent to the input X**1**, a third one A**2** of which may be equivalent to the input X**2**, and a fourth one A**3** of which may be equivalent to the input X**3**. The programmable logic block **201** may have an output, e.g., Dout, which may be equivalent to the output Y of the logic operator.

FIG. **6**G shows the look-up table **210** configured for achieving the same logic operation as the logic operator as illustrated in FIG. **6**F performs. Referring to FIG. **6**G, the look-up table **210** records or stores each of sixteen resulting values or programming codes of the logic operator as illustrated in FIG. **6**F that are generated respectively in accordance with sixteen combinations of its inputs X**0**-X**3**. The look-up table **210** may be programmed with the sixteen resulting values or programming codes respectively stored in the sixteen memory cells **490**, each of which may be referred to one **398** as illustrated in FIG. **1**A or **1**B having its output Out**1** or Out**2** coupling to one of the sixteen inputs D**0**-D**15** of the first set of the multiplexer **211**, as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J, for the programmable logic block (LB) **201**. The multiplexer **211** may be configured to determine one of its sixteen inputs, e.g., D**0**-D**15**, of the first set into its output, e.g., Dout as illustrated in FIG. **4**A, **4**C, **4**D or **4**H-**4**J, in accordance with one of the combinations of its inputs A**0**-A**3** of the second set. The output Dout of the multiplexer **211** as seen in FIG. **6**A may act as the output of the programmable logic block (LB) **201**.

Alternatively, the programmable logic block **201** may be substituted with multiple programmable logic gates to be programmed to perform logic operation or Boolean operation as illustrated in FIG. **6**B, **6**D or **6**F.

Alternatively, a plurality of the programmable logic block **201** may be programed to be integrated into a computation operator to perform computation operation, such as addition, subtraction, multiplication or division operation. The computation operator may be an adder, a multiplier, a multiplexer, a shift register, floating-point circuits and/or division circuits. FIG. **6**H is a block diagram illustrating a computation operator in accordance with an embodiment of the present application. For example, the computation operator

as seen in FIG. **6**H may be configured to multiply two two-binary-digit numbers, i.e., [A**1**, A**0**] and [A**3**, A**2**], into a four-binary-digit output, i.e., [C**3**, C**2**, C**1**, C**0**], as seen in FIG. **6**L Referring to FIG. **6**H, Four programmable logic blocks **201**, each of which may be referred to one as illustrated in FIG. **6**A, may be programed to be integrated into the computation operator. The computation operator may have its four inputs [A**1**, A**0**, A**3**, A**2**] coupling respectively to the four inputs of each of the four programmable logic blocks **201**. Each of the programmable logic blocks **201** of the computation operator may generate one of the four binary digits, i.e., C**0**-C**3**, based on a combination of its inputs [A**1**, A**0**, A**3**, A**2**]. In the multiplication of the two-binary-digit number, i.e., [A**1**, A**0**], by the two-binary-digit number, i.e., [A**3**, A**2**], the four programmable logic blocks **201** may generate their four respective outputs, i.e., the four binary digits C**0**-C**3**, based on a common combination of their inputs [A**1**, A**0**, A**3**, A**2**]. The four programmable logic blocks **201** may be programed with four respective look-up tables **210**, i.e., Table-**0**, Table-**1**, Table-**2** and Table-**3**.

For example, referring to FIGS. **6**A, **6**H and **6**I, multiple of the memory cells **490**, each of which may be referred to one **398** as illustrated in FIG. **1**A or **1**B, may be composed for each of the four look-up tables **210**, i.e., Table-**0**, Table-**1**, Table-**2** and Table-**3**, and each of the memory cells **490** for said each of the four look-up tables may be configured to store one of the resulting values, i.e., programming codes, for one of the four binary digits C**0**-C**3**. A first one of the four programmable logic blocks **201** may have its multiplexer **211** provided with its first set of inputs, e.g., D**0**-D**15**, each coupling to one of the outputs Out**1** and Out**2** of one of the memory cells **490** for the look-up table (LUT) of Table-**0** and its second set of inputs, e.g., A**0**-A**3**, configured to determine one of its inputs, e.g., D**0**-D**15**, of the first set into its output, e.g., Dout, acting as an output C**0** of the first one of the programmable logic block (LB) **201**. A second one of the four programmable logic blocks **201** may have its multiplexer **211** provided with its first set of inputs, e.g., D**0**-D**15**, each coupling to one of the outputs Out**1** and Out**2** of one of the memory cells **490** for the look-up table (LUT) of Table-**1** and its second set of inputs, e.g., A**0**-A**3**, configured to determine one of its inputs, e.g., D**0**-D**15**, of the first set into its output, e.g., Dout, acting as an output C**1** of the second one of the programmable logic block (LB) **201**. A third one of the four programmable logic blocks **201** may have its multiplexer **211** provided with its first set of inputs, e.g., D**0**-D**15**, each coupling to one of the outputs Out**1** and Out**2** of one of the memory cells **490** for the look-up table (LUT) of Table-**2** and its second set of inputs, e.g., A**0**-A**3**, configured to determine one of its inputs, e.g., D**0**-D**15**, of the first set into its output, e.g., Dout, acting as an output C**2** of the third one of the programmable logic block (LB) **201**. A fourth one of the four programmable logic blocks **201** may have its multiplexer **211** provided with its first set of inputs, e.g., D**0**-D**15**, each coupling to one of the outputs Out**1** and Out**2** of one of the memory cells **490** for the look-up table (LUT) of Table-**3** and its second set of inputs, e.g., A**0**-A**3**, configured to determine one of its inputs, e.g., D**0**-D**15**, of the first set into its output, e.g., Dout, acting as an output C**3** of the fourth one of the programmable logic block (LB) **201**.

Thereby, referring to FIGS. **6**H and **6**I, the four programmable logic blocks **201** composing the computation operator may generate their four respective outputs, i.e., the four binary digits C**0**-C**3**, based on a common combination of their inputs [A**1**, A**0**, A**3**, A**2**]. In this case, the inputs A**0**-A**3** of the four programmable logic blocks **201** may act as inputs of the computation operator and the outputs C**0**-C**3** of the four programmable logic blocks **201** may act as an output of the computation operator. The computation operator may generate a four-binary-digit output, i.e., [C**3**, C**2**, C**1**, C**0**], based on a combination of its four-binary-digit input, i.e., [A**1**, A**0**, A**3**, A**2**].

Referring to FIGS. **6**H and **6**I, in a particular case for multiplication of 3 by 3, each of the four programmable logic blocks **201** may have a combination of its inputs, i.e., [A**1**, A**0**, A**3**, A**2**]=[1, 1, 1, 1], to determine one of the four binary digits, i.e., [C**3**, C**2**, C**1**, C**0**]=[1, 0, 0, 1]. The first one of the four programmable logic blocks **201** may generate the binary digit C**0** at a logic level of "1" based on the combination of its inputs, i.e., [A**1**, A**0**, A**3**, A**2**]=[1, 1, 1, 1]; the second one of the four programmable logic blocks **201** may generate the binary digit C**1** at a logic level of "0" based on the combination of its inputs, i.e., [A**1**, A**0**, A**3**, A**2**]=[1, 1, 1, 1]; the third one of the four programmable logic blocks **201** may generate the binary digit C**2** at a logic level of "0" based on the combination of its inputs, i.e., [A**1**, A**0**, A**3**, A**2**]=[1, 1, 1, 1]; the fourth one of the four programmable logic blocks **201** may generate the binary digit C**3** at a logic level of "1" based on the combination for its inputs, i.e., [A**1**, A**0**, A**3**, A**2**]=[1, 1, 1, 1].

Alternatively, the four programmable logic blocks **201** may be substituted with multiple programmable logic gates as illustrated in FIG. **6**J to be programmed for a computation operator performing the same computation operation as the four programmable logic blocks **201**. Referring to FIG. **6**J, the computation operator may be programed to perform multiplication on two numbers each expressed by two binary digits, e.g., [A**1**, A**0**] and [A**3**, A**2**] as illustrated in FIGS. **6**H and **6**I, into a four-binary-digit output, e.g., [C**3**, C**2**, C**1**, C**0**] as illustrated in FIGS. **6**H and **6**L The computation operator may be programed with an AND gate **234** configured to perform AND operation on its two inputs respectively at the inputs A**0** and A**3** of the computation operator into its output. The programmable logic gates may be programed with an AND gate **235** configured to perform AND operation on its two inputs respectively at the inputs A**0** and A**2** of the computation operator into its output acting as the output C**0** of the computation operator. The computation operator may be programed with an AND gate **236** configured to perform AND operation on its two inputs respectively at the inputs A**1** and A**2** of the computation operator into its output. The computation operator may be programed with an AND gate **237** configured to perform AND operation on its two inputs respectively at the inputs A**1** and A**3** of the computation operator into its output. The computation operator may be programed with an ExOR gate **238** configured to perform Exclusive-OR operation on its two inputs coupling respectively to the outputs of the AND gates **234** and **236** into its output acting as the output C**1** of the computation operator. The computation operator may be programed with an AND gate **239** configured to perform AND operation on its two inputs coupling respectively to the outputs of the AND gates **234** and **236** into its output. The computation operator may be programed with an ExOR gate **242** configured to perform Exclusive-OR operation on its two inputs coupling respectively to the outputs of the AND gates **239** and **237** into its output acting as the output C**2** of the computation operator. The computation operator may be programed with an AND gate **253** configured to perform AND operation on its two inputs coupling respectively to the outputs of the AND gates **239** and **237** into its output acting as the output C**3** of the computation operator.

To sum up, the programmable logic block **201** may be provided with the memory cells **490**, having the number of

2 to the power of n, for the look-up table **210** to be programed respectively to store the resulting values or programming codes, having the number of 2 to the power of n, for each combination of its inputs having the number of n. For example, the number of n may be any integer greater than or equal to 2, such as between 2 and 64. For the example as illustrated in FIGS. **6**A, **6**G, **6**H and **6**I, each of the programmable logic blocks **201** may be provided with its inputs having the number of n equal to 4, and thus the number of resulting values or programming codes for all combinations of its inputs is 16, i.e., the number of 2 to the power of n equal to 4.

Accordingly, the programmable logic blocks (LB) **201** as seen in FIG. **6**A may perform logic operation on its inputs into its output, wherein the logic operation may include Boolean operation such as AND, NAND, OR or NOR operation. Besides, the programmable logic blocks (LB) **201** as seen in FIG. **6**A may perform computation operation on its inputs into its output, wherein the computation operation may include addition, subtraction, multiplication or division operation.

Specification for Programmable Interconnect

FIG. **7**A is a block diagram illustrating a programmable interconnect programmed by a pass/no-pass switch in accordance with an embodiment of the present application. Referring to FIG. **7**A, two programmable interconnects **361** may be controlled, by the pass/no-pass switch **258** of either of the first through sixth types as seen in FIGS. **2**A-**2**F, to couple to each other. One of the programmable interconnects **361** may couple to the node N**21** of the pass/no-pass switch **258**, and another of the programmable interconnects **361** may couple to the node N**22** of the pass/no-pass switch **258**. Accordingly, the pass/no-pass switch **258** may be switched on to connect said one of the programmable interconnects **361** to said another of the programmable interconnects **361**; the pass/no-pass switch **258** may be switched off to disconnect said one of the programmable interconnects **361** from said another of the programmable interconnects **361**.

Referring to FIG. **7**A, a memory cell **362** may couple to the pass/no-pass switch **258** via a fixed interconnect **364**, i.e., non-programmable interconnect, to turn on or off the pass/no-pass switch **258**, wherein the memory cell **362** may be referred to one **398** as illustrated in FIG. **1**A or **1**B. For the first type of pass/no-pass switch **258** as illustrated in FIG. **2**A used to program the programmable interconnects **361**, the first type of pass/no-pass switch **258** may have its nodes SC-**1** and SC-**2** coupling to two inverted outputs of the memory cell **362**, which may be referred to the two outputs Out**1** and Out**2** of the memory cell **398**, and accordingly receiving the two inverted outputs of the memory cell **362** associated with the programming code stored or saved in the memory cell **362** to switch on or off the first type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the first type respectively.

For the second type of pass/no-pass switch **258** as illustrated in FIG. **2**B used to program the programmable interconnects **361**, the second type of pass/no-pass switch **258** may have its node SC-**3** coupling to an output of the memory cell **362**, which may be referred to the output Out**1** or Out**2** of the memory cell **398**, and accordingly receiving the output of the memory cell **362** associated with the programming code stored or saved in the memory cell **362** to switch on or off the second type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the second type respectively.

For the third or fourth type of pass/no-pass switch **258** as illustrated in FIG. **2**C or **2**D used to program the programmable interconnects **361**, the third or fourth type of pass/no-pass switch **258** may have its node SC-**4** coupling to an output of the memory cell **362**, which may be referred to the output Out**1** or Out**2** of the memory cell **398**, and accordingly receiving the output of the memory cell **362** associated with the programming code stored or saved in the memory cell **362** to switch on or off the third or fourth type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the third or fourth type respectively. Alternatively, its control P-type and N-type MOS transistors **295** and **296** may have gate terminals coupling respectively to two inverted outputs of the memory cell **362**, which may be referred to the two outputs Out**1** and Out**2** of the memory cell **398**, and accordingly receiving the two inverted outputs of the memory cell **362** associated with the programming code stored or saved in the memory cell **362** to switch on or off the third or fourth type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the third or fourth type respectively, wherein its inverter **297** may be removed from the pass/no-pass switch **258** of the third or fourth type.

For the fifth or sixth type of pass/no-pass switch **258** as illustrated in FIG. **2**E or **2**F used to program the programmable interconnects **361**, the fifth or sixth type of pass/no-pass switch **258** may have its nodes SC-**5** and SC-**6** coupling to two outputs of the two respective memory cells **362**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, and accordingly receiving the two outputs of the two respective memory cells **362** associated with two programming codes stored or saved in the two memory cells **362** respectively to switch on or off the fifth or sixth type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the fifth or sixth type respectively. Alternatively, (1) its control P-type and N-type MOS transistors **295** and **296** at its left side may have gate terminals coupling respectively to two inverted outputs of one of the two memory cells **362**, which may be referred to the two outputs Out**1** and Out**2** of the memory cell **398**, and accordingly receiving the two inverted outputs of said one of the two memory cells **362** associated with the programming code stored or saved in said one of the two memory cells **362**, and (2) its control P-type and N-type MOS transistors **295** and **296** at its right side may have gate terminals coupling respectively to two inverted outputs of the other of the two memory cells **362**, which may be referred to the two outputs Out**1** and Out**2** of the memory cell **398**, and accordingly receiving the two inverted outputs of said the other of the two memory cells **362** associated with the programming code stored or saved in said the other of the two memory cells **362**, to switch on or off the fifth or sixth type of pass/no-pass switch **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of the pass/no-pass switch **258** of the fifth or sixth type respectively, wherein its inverters **297** may be removed from the pass/no-pass switch **258** of the fifth or sixth type.

Before the memory cell(s) **362** are programmed or when the memory cell(s) **362** are being programmed, the programmable interconnects **361** may not be used for signal trans-

mission. The memory cell(s) **362** may be programmed to have the pass/no-pass switch **258** switched on to couple the programmable interconnects **361** for signal transmission or to have the pass/no-pass switch **258** switched off to decouple the programmable interconnects **361**. Similarly, each of the first and second types of cross-point switches **379** as seen in FIGS. **3**A and **3**B may be composed of a plurality of the pass/no-pass switch **258** of any type, wherein each of the pass/no-pass switches **258** may have the node(s) (SC-**1** and SC-**2**), SC-**3**, SC-**4** or (SC-**5** and SC-**6**) coupling to the output(s) of the memory cell(s) **362** as mentioned above, and accordingly receiving the output(s) of the memory cell(s) **362** associated with the programming code(s) stored or saved in the memory cell(s) **362** to switch on or off said each of the pass/no-pass switches **258** to couple or decouple two of the programmable interconnects **361** coupling to the two nodes N**21** and N**22** of said each of the pass/no-pass switches **258** respectively.

FIG. **7**B is a circuit diagram illustrating programmable interconnects programmed by a cross-point switch in accordance with an embodiment of the present application. Referring to FIG. **7**B, four programmable interconnects **361** may couple to the respective four nodes N**23**-N**26** of the cross-point switch **379** of the third type as seen in FIG. **3**C. Thereby, one of the four programmable interconnects **361** may be switched by the cross-point switch **379** of the third type to couple to another one, two or three of the four programmable interconnects **361**. For the cross-point switch **379** composed of four of the multiplexers **211** of the first type, each of the multiplexers **211** may have its second set of two inputs A**0** and A**1** coupling respectively to the outputs of two of the memory cells **362**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, via multiple fixed interconnects **364**, i.e., non-programmable interconnects. For the cross-point switch **379** composed of four of the multiplexers **211** of the second or third type as seen in FIG. **4**F or **4**K, each of the multiplexers **211** may have its second set of two inputs A**0** and A**1** coupling respectively to the outputs of two of the memory cells **362**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, via multiple fixed interconnects **364**, i.e., non-programmable interconnects, and its node SC-**4** may couple to the output of another of the memory cells **362**, which may be referred to the output Out**1** or Out**2** of the memory cell **398**, via another fixed interconnect **364**, i.e., non-programmable interconnect. Alternatively, its control P-type and N-type MOS transistors **295** and **296** may have gate terminals coupling respectively to two inverted outputs of another of the memory cells **362**, which may be referred to the two outputs Out**1** and Out**2** of the memory cell **398**, and accordingly receiving the two inverted outputs of said another of the memory cells **362** associated with the programming code stored or saved in the memory cell **362** to switch on or off its pass/no-pass switch **258** of the third or fourth type to couple or decouple the input and output Dout of its pass/no-pass switch **258** of the third or fourth type, wherein its inverter **297** may be removed from the pass/no-pass switch **258** of the third or fourth type. Accordingly, each of the multiplexers **211** may pass its first set of three inputs coupling to three of the four programmable interconnects **361** into its output coupling to the other one of the four programmable interconnects **361** in accordance with its second set of two inputs A**0** and A**1** and alternatively further in accordance with a logic level at the node SC-**4** or logic levels at gate terminals of its control P-type and N-type MOS transistors **295** and **296**.

For example, referring to FIGS. **3**C and **7**B, the following description takes the cross-point switch **379** composed of four of the multiplexers **211** of the second or third type as an example. For programming the programmable interconnects **361**, the top one of the multiplexers **211** may have its second set of inputs $A0_1$, $A1_1$ and SC_1-**4** coupling respectively to the outputs of the three memory cells **362-1**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, the left one of the multiplexers **211** may have its second set of inputs $A0_2$, $A1_2$ and SC_2-**4** coupling respectively to the outputs of the three memory cells **362-2**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, the bottom one of the multiplexers **211** may have its second set of inputs $A0_3$, $A1_3$ and SC_3-**4** coupling respectively to the outputs of the three memory cells **362-3**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, and the right one of the multiplexers **211** may have its second set of inputs $A0_4$, $A1_4$ and SC_4-**4** coupling respectively to the outputs of the three memory cells **362-4**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**. Before the memory cells **362-1**, **362-2**, **362-3** and **3624** are programmed or when the memory cells **362-1**, **362-2**, **362-3** and **362-4** are being programmed, the four programmable interconnects **361** may not be used for signal transmission. The memory cells **362-1**, **362-2**, **362-3** and **362-4** may be programmed to have each of the multiplexers **211** of the second or third type pass one of its three inputs of the first set into its output such that one of the four programmable interconnects **361** may couple to another, another two or another three of the four programmable interconnects **361** for signal transmission in operation.

FIG. **7**C is a circuit diagram illustrating a programmable interconnect programmed by a cross-point switch in accordance with an embodiment of the present application. Referring to FIG. **7**C, the fourth type of cross-point switch **379** illustrated in FIG. **3**D may have the first set of its inputs, e.g., 16 inputs D**0**-D**15**, coupling respectively to multiple of the programmable interconnects **361**, e.g., sixteen of the programmable interconnects **361**, and its output, e.g., Dout, coupling to another of the programmable interconnects **361**. Thereby, said multiple of the programmable interconnects **361** may have one to be switched by the fourth type of cross-point switch **379** to associate with said another of the programmable interconnects **361**. The fourth type of cross-point switch **379** may have its second set of multiple inputs A**0**-A**3** coupling respectively to the outputs of four of the memory cells **362**, each of which may be referred to the output Out**1** or Out**2** of the memory cell **398**, and accordingly receiving the outputs of the four respective memory cells **362** associated with the four programming codes stored or saved in the four respective memory cells **362** to pass one of its inputs of the first set, e.g., D**0**-D**15** coupling to the sixteen of the programmable interconnects **361**, into its output, e.g., Dout coupling to said another of the programmable interconnects **361**. Before the memory cells **362** are programmed or when the memory cells **362** are being programmed, said multiple of the programmable interconnects **361** and said another of the programmable interconnects **361** may not be used for signal transmission. The memory cells **362** may be programmed to have the fourth type of cross-point switch **379** pass one of its inputs of the first set into its output such that one of said multiple of the programmable interconnects **361** may couple to said another of the programmable interconnects **361** for signal transmission in operation.

Specification for Fixed Interconnect

Before the memory cells **490** for the look-up table (LUT) **210** as seen in FIGS. **6**A and **6**H and the memory cells **362** for the programmable interconnects **361** as seen in FIGS. **7**A-**7**C are programmed or when the memory cells **490** for the look-up table (LUT) **210** and the memory cells **362** for the programmable interconnects **361** are being programmed, multiple fixed interconnects **364** that are not field programmable may be provided for signal transmission or power/ground delivery to (1) the memory cells **490** of the look-up table (LUT) **210** of the programmable logic block (LB) **201** as seen in FIG. **6**A or **6**H for programming the memory cells **490** and/or (2) the memory cells **362** as seen in FIGS. **7**A-**7**C for the programmable interconnects **361** for programming the memory cells **362**. After the memory cells **490** for the look-up table (LUT) **210** and the memory cells **362** for the programmable interconnects **361** are programmed, the fixed interconnects **364** may be used for signal transmission or power/ground delivery in operation.

Specification for Standard Commodity Field-Programmable-Gate-Array (FPGA) Integrated-Circuit (IC) Chip

FIG. **8**A is a schematically top view showing a block diagram of a standard commodity FPGA IC chip in accordance with an embodiment of the present application. Referring to FIG. **8**A, a standard commodity FPGA IC chip **200** is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm; with a chip size and manufacturing yield optimized with the minimum manufacturing cost for the used semiconductor technology node or generation. The standard commodity FPGA IC chip **200** may have an area between 400 mm^2 and 9 mm^2, 225 mm^2 and 9 mm^2, 144 mm^2 and 16 mm^2, 100 mm^2 and 16 mm^2, 75 mm^2 and 16 mm^2, or 50 mm^2 and 16 mm^2. Transistors or semiconductor devices of the standard commodity FPGA IC chip **200** used in the advanced semiconductor technology node or generation may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET.

Referring to FIG. **8**A, since the standard commodity FPGA IC chip **200** is a standard commodity IC chip, the number of types of products for the standard commodity FPGA IC chip **200** may be reduced to a small number, and therefore expensive photo masks or mask sets for fabricating the standard commodity FPGA IC chip **200** using advanced semiconductor nodes or generations may be reduced to a few mask sets. For example, the mask sets for a specific technology node or generation may be reduced down to between 3 and 20, 3 and 10, or 3 and 5. Its NRE and production expenses are therefore greatly reduced. With the few types of products for the standard commodity FPGA IC chip **200**, the manufacturing processes may be optimized to achieve very high manufacturing chip yields. Furthermore, the chip inventory management becomes easy, efficient and effective, therefore resulting in a relatively short chip delivery time and becoming very cost-effective.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may be of various types, including (1) multiple of the programmable logic blocks (LB) **201** as illustrated in FIGS. **6**A-**6**J arranged in an array in a central region thereof, (2) multiple cross-point switches **379** as illustrated in FIGS. **3**A-**3**D and **7**A-**7**C arranged around each of the programmable logic blocks (LB) 201, (3) multiple intra-chip interconnects **502** each extending over spaces between neighboring two of the programmable logic blocks **201**, and (4) multiple of the small input/output (I/O) circuits **203**, as illustrated in FIG. **5**B, each having its output S_Data_in coupling to one or more of the intra-chip interconnects **502** and its input S_Data_out, S_Enable or S_Inhibit coupling to another one or more of intra-chip interconnects **502**.

Referring to FIG. **8**A, the intra-chip interconnects **502** may be divided into the programmable interconnects **361** and fixed interconnects **364** as illustrated in FIG. **7**A-**7**C. For the standard commodity FPGA IC chip **200**, each of the small input/output (I/O) circuits **203**, as illustrated in FIG. **5**B, may have its output S_Data_in coupling to one or more of the programmable interconnects **361** and/or one or more of the fixed interconnects **364** and its input S_Data_out, S_Enable or S_Inhibit coupling to another one or more of the programmable interconnects **361** and/or another one or more of the fixed interconnects **364**.

Referring to FIG. **8**A, each of the programmable logic blocks (LB) **201** as illustrated in FIGS. **6**A-**6**J may have its inputs A**0**-A**3** each coupling to one or more of the programmable interconnects **361** of the intra-chip interconnects **502** and/or one or more of the fixed interconnects **364** of the intra-chip interconnects **502** and may be configured to perform logic operation or computation operation on its inputs into its output Dout coupling to another one or more of the programmable interconnects **361** of the intra-chip interconnects **502** and/or another one or more of the fixed interconnects **364** of the intra-chip interconnects **502**, wherein the computation operation may include an addition, subtraction, multiplication or division operation, and the logic operation may include a Boolean operation such as AND, NAND, OR or NOR operation.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may include multiple of the I/O pads **372** as seen in FIG. **5**B, each vertically over one of its small input/output (I/O) circuits **203**, coupling to the node **381** of said one of the small input/output (I/O) circuits **203**. In a first clock, the output Dout of one of the programmable logic blocks **201** as illustrated in FIG. **6**A-**6**J may be transmitted to the input S_Data_out of the small driver **374** of one of the small input/output (I/O) circuits **203** through one or more of the programmable interconnects **361** and/or one or more of the cross-point switches **379** each between two of said one or more of the programmable interconnects **361** joining said each thereof, and then the small driver **374** of said one of the small input/output (I/O) circuits **203** may amplify its input S_Data_out to be transmitted to one of the I/O pads **372** vertically over said one of the small input/output (I/O) circuits **203** for external connection to circuits outside the standard commodity FPGA IC chip **200**. In a second clock, a signal from circuits outside the standard commodity FPGA IC chip **200** may be transmitted to the small receiver **375** of said one of the small input/output (I/O) circuits **203** through said one of the I/O pads **372**, and then the small receiver **375** of said one of the small input/output (I/O) circuits **203** may amplify the signal into its output S_Data_in to be transmitted to one of the inputs A**0**-A**3** of another of the programmable logic blocks **201** as illustrated in FIG. **6**A-**6**J through another one or more of the programmable interconnects **361** and/or one or more of the cross-point switches **379** each between two of said another one or more of the programmable interconnects **361** joining said each thereof.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may be provided with a plurality of the small input/output (I/O) circuit **203** as seen in FIG. **5**B, having the number of 2^n where n may be an integer ranger from 2 to 8, arranged in parallel for each of multiple input/output (I/O) ports of the standard commodity FPGA IC chip **200**. The I/O

ports of the standard commodity FPGA IC chip **200** may have the number of 2^n where n may be an integer ranger from 1 to 5. For an example, the I/O ports of the standard commodity FPGA IC chip **200** may have the number of four and may be defined as first, second, third and fourth I/O ports respectively. Each of the first, second, third and fourth I/O ports of the standard commodity FPGA IC chip **200** may have sixty four small input/output (I/O) circuits **203**, each of which may be referred to one as seen in FIG. **5**B, for receiving or transmitting data in a bit width of 64 bits from or to the circuits outside of the standard commodity FPGA IC chip **200**.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may further include a chip-enable (CE) pad **209** configured for enabling or disabling the standard commodity FPGA IC chip **200**. For example, when a logic level of "0" couples to the chip-enable (CE) pad **209**, the standard commodity FPGA IC chip **200** may be enabled to process data and/or operate with circuits outside of the standard commodity FPGA IC chip **200**; when a logic level of "1" couples to the chip-enable (CE) pad **209**, the standard commodity FPGA IC chip **200** may be disabled not to process data and/or operate with circuits outside of the standard commodity FPGA IC chip **200**.

Referring to FIG. **8**A, for the standard commodity FPGA IC chip **200**, it may further include (1) an input-enable (IE) pad **221** coupling to the first input of the small receiver **375** of each of its small input/output (I/O) circuits **203** as seen in FIG. **5**B, configured for receiving the S_Inhibit signal from the circuits outside of it to activate or inhibit the small receiver **375** of each of its small input/output (I/O) circuits **203** for each of its I/O ports; and (2) multiple input selection (IS) pads **226** configured for selecting one from its I/O ports to receive data, i.e., S_Data_in illustrated in FIG. **5**B, via the metal pads **372** of the selected one of its I/O ports from the circuits outside of it. For the example, for the standard commodity FPGA IC chip **200**, its input selection (IS) pads **226** may have the number of two, e.g., IS1 and IS2 pads, for selecting one from its first, second, third and fourth I/O ports to receive data in the bit width of 64 bits, i.e., S_Data_in illustrated in FIG. **5**B, via the 64 parallel metal pads **372** of the selected one of its first, second, third and fourth I/O ports from the circuits outside of it. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "1" couples to the input-enable (IE) pad **221**, (3) a logic level of "0" couples to the IS1 pad **226** and (4) a logic level of "0" couples to the IS2 pad **226**, the standard commodity FPGA IC chip **200** is enabled to activate the small receivers **375** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its first one from its first, second, third and fourth I/O ports for receiving the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its first I/O port from the circuits outside of the standard commodity FPGA IC chip **200**, wherein its second, third and fourth I/O ports are not selected to receive the data from the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "1" couples to the input-enable (IE) pad **221**, (3) a logic level of "1" couples to the IS1 pad **226** and (4) a logic level of "0" couples to the IS2 pad **226**, the standard commodity FPGA IC chip **200** is enabled to activate the small receivers **375** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its second one from its first, second, third and fourth I/O ports for receiving the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its second 110 port from the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, third and fourth I/O ports are not selected to receive the data from the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "1" couples to the input-enable (IE) pad **221**, (3) a logic level of "0" couples to the IS1 pad **226** and (4) a logic level of "1" couples to the IS2 pad **226**, the standard commodity FPGA IC chip **200** is enabled to activate the small receivers **375** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its third one from its first, second, third and fourth I/O ports for receiving the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its third I/O port from the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, second and fourth I/O ports are not selected to receive the data from the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "1" couples to the input-enable (IE) pad **221**, (3) a logic level of "1" couples to the LS**1** pad **226** and (4) a logic level of "1" couples to the IS2 pad **226**, the standard commodity FPGA IC chip **200** is enabled to activate the small receivers **375** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its fourth one from its first, second, third and fourth I/O ports for receiving the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its fourth I/O port from the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, second and third I/O ports are not selected to receive the data from the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, and (2) a logic level of "0" couples to the input-enable (IE) pad **221**, the standard commodity FPGA IC chip **200** is enabled to inhibit the small receivers **375** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports.

Referring to FIG. **8**A, for the standard commodity FPGA IC chip **200**, it may further include (1) an output-enable (OE) pad **227** coupling to the second input of the small driver **374** of each of its small input/output (I/O) circuits **203** as seen in FIG. **5**B, configured for receiving the S_Enable signal from the circuits outside of it to enable or disable the small driver **374** of each of its small input/output (I/O) circuits **203** for each of its I/O ports; and (2) multiple output selection (OS) pads **228** configured for selecting one from its I/O ports to drive or pass data, i.e., S_Data_out illustrated in FIG. **5**B, via the metal pads **372** of the selected one of its I/O ports to the circuits outside of it. For the example, for the standard commodity FPGA IC chip **200**, its output selection (OS) pads **226** may have the number of two, e.g., OS1 and OS2 pads, for selecting one from its first, second, third and fourth I/O ports to drive or pass data in the bit width of 64 bits, i.e., S_Data_out illustrated in FIG. **5**B, via the 64 parallel metal pads **372** of the selected one of its first, second, third and fourth I/O ports to the circuits outside of it. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "0" couples to the output-enable (OE) pad **227**, (3) a logic level of "0" couples to the S1 pad **228** and (4) a logic level of "0" couples to the OS2 pad **228**, the standard commodity FPGA IC chip **200** is enabled to enable the small drivers **374** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its first one from its first, second, third and fourth I/O ports for driving or passing the data in the bit width of 64 bits via the 64 parallel metal pads

372 of its first I/O port to the circuits outside of the standard commodity FPGA IC chip **200**, wherein its second, third and fourth I/O ports are not selected to drive or pass the data to the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "0" couples to the output-enable (OE) pad **227**, (3) a logic level of "1" couples to the OS1 pad **228** and (4) a logic level of "0" couples to the OS2 pad **228**, the standard commodity FPGA IC chip **200** is enabled to enable the small drivers **374** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its second one from its first, second, third and fourth I/O ports for driving or passing the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its second I/O port to the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, third and fourth I/O ports are not selected to drive or pass the data to the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "0" couples to the output-enable (OE) pad **227**, (3) a logic level of "0" couples to the OS1 pad **228** and (4) a logic level of "1" couples to the OS2 pad **228**, the standard commodity FPGA IC chip **200** is enabled to enable the small drivers **374** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its third one from its first, second, third and fourth I/O ports for driving or passing the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its third I/O port to the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, second and fourth I/O ports are not selected to drive or pass the data to the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209**, (2) a logic level of "0" couples to the output-enable (OE) pad **227**, (3) a logic level of "1" couples to the OS1 pad **228** and (4) a logic level of "1" couples to the OS2 pad **228**, the standard commodity FPGA IC chip **200** is enabled to enable the small drivers **374** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports and to select its fourth one from its first, second, third and fourth I/O ports for driving or passing the data in the bit width of 64 bits via the 64 parallel metal pads **372** of its fourth I/O port to the circuits outside of the standard commodity FPGA IC chip **200**, wherein its first, second and third I/O ports are not selected to drive or pass the data to the circuits outside of the standard commodity FPGA IC chip **200**. Provided that (1) a logic level of "0" couples to the chip-enable (CE) pad **209** and (2) a logic level of "1" couples to the output-enable (OE) pad **227**, the standard commodity FPGA IC chip **200** is enabled to disable the small drivers **374** of its small input/output (I/O) circuits **203** for its first, second, third and fourth I/O ports.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may further include (1) multiple power pads **205** configured for applying the voltage Vcc of power supply to the memory cells **490** for the look-up tables (LUT) **210** of the programmable logic blocks (LB) **201** as illustrated in FIG. **6**A or **6**H and/or the memory cells **362** for the cross-point switches **379** as illustrated in FIGS. **7**A-**7**C through one or more of the fixed interconnects **364**, wherein the voltage Vcc of power supply may be between 0.2V and 2.5V, between 0.2V and 2V between 0.2V and 1.5V, between 0.1V and 1V, or between 0.2V and 1V, or, smaller or lower than or equal to 2.5V 2V 1.8V, 1.5V or 1V, and (2) multiple ground pads **206** configured for providing the voltage Vss of ground reference to the memory cells **490** for the look-up tables (LUT) **210** of the programmable logic blocks (LB) **201** as illustrated in FIG. **6**A or **6**H and/or the memory cells **362** for the cross-point switches **379** as illustrated in FIGS. **7**A-**7**C through one or more of the fixed interconnects **364**.

Referring to FIG. **8**A, the standard commodity FPGA IC chip **200** may further include a clock pad **229** configured for receiving a clock signal from circuits outside of the standard commodity FPGA IC chip **200**.

Referring to FIG. **8**A, for the standard commodity FPGA IC chip **200**, its programmable logic blocks **201** may be reconfigurable for artificial-intelligence (AI) application. For example, in a first clock, one of its programmable logic blocks **201** may have its look-up table (LUT) **201** to be programmed for OR operation as illustrated in FIGS. **6**B and **6**C; however, after one or more events happen, in a second clock said one of its programmable logic blocks **201** may have its look-up table (LUT) **201** to be programmed for AND operation as illustrated in FIGS. **6**D and **6**E for better AI performance.

I. Arrangements for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

FIGS. **8**B-**8**E are schematic views showing various arrangements for (1) the memory cells **490**, employed for the look-up tables **210**, and the multiplexers **211** for the programmable logic blocks **201** and (2) the memory cells **362** and the pass/no-pass switches **258** for the programmable interconnects **361** in accordance with an embodiment of the present application. The pass/no-pass switches **258** may compose the first and second types of cross-point switches **379** as illustrated in FIGS. **3**A and **3**B respectively. The various arrangements are mentioned as below:

(1) First Arrangement for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

Referring to FIG. **8**B, for each of the programmable logic blocks **201** of the standard commodity FPGA IC chip **200**, the memory cells **490** for one of its look-up tables **210** may be distributed on and/or over a first area of a semiconductor substrate **2** of the standard commodity FPGA IC chip **200**, and one of its multiplexers **211** coupling to the memory cells **490** for said one of its look-up tables **210** may be distributed on and/or over a second area of the semiconductor substrate **2** of the standard commodity FPGA IC chip **200**, wherein the first area is nearby or close to the second area. Each of the programmable logic blocks **201** may include one or more of multiplexers **211** and one or more groups of memory cells **490** employed for one or more of look-up tables **210** respectively and coupled to the first set of inputs, e.g., D**0**-D**15**, of said one or more of multiplexers **211** respectively, wherein each of the memory cells **490** in said one or more groups may store one of the resulting values or programming codes for said one or more of look-up tables **210** and may have an output coupling to one of the inputs of the first set, e.g., D**0**-D**15**, of said one or more of multiplexers **211**.

Referring to FIG. **8**B, a group of memory cells **362** employed for the programmable interconnects **361** as seen in FIG. **7**A may be distributed in one or more lines between neighboring two of the programmable logic blocks **201**. Also, a group of pass/no-pass switches **258** employed for the programmable interconnects **361** as seen in FIG. **7**A may be distributed in one or more lines between said neighboring two of the programmable logic blocks **201**. The group of pass/no-pass switches **258** and the group of memory cells **362** compose the cross-point switch **379** as seen in FIG. **3**A

or **3**B. Each of the pass/no-pass switches **258** in the group may couple one or more of the memory cells **362** in the group.

(2) Second Arrangement for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

Referring to FIG. **8**C, for the standard commodity FPGA IC chip **200**, the memory cells **490** employed for all of its look-up tables **210** and the memory cells **362** employed for all of its programmable interconnects **361** may be aggregately distributed in a memory-array block **395** in a certain area of its semiconductor substrate **2**. For more elaboration, for the same programmable logic block **201**, the memory cells **490** employed for its one or more look-up tables (LUTs) **210** and its one or more multiplexers **211** may be arranged in two separate areas, in one of which are the memory cells **490** employed for its one or more look-up tables (LUTs) **210** and in the other one of which are its one or more multiplexers **211**. The pass/no-pass switches **258** employed for programmable interconnects **361** may be distributed in one or more lines between the multiplexers **211** of neighboring two of the programmable logic blocks **201**.

(3) Third Arrangement for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

Referring to FIG. **8**D, for the standard commodity FPGA IC chip **200**, the memory cells **490** employed for all of its look-up tables **210** and the memory cells **362** employed for all of its programmable interconnects **361** may be aggregately distributed in multiple separate memory-array blocks **395***a* and **395***b* in multiple certain areas of its semiconductor substrate **2**. For more elaboration, for the same programmable logic block **201**, the memory cells **490** employed for its one or more look-up tables (LUTs) **210** and its one or more multiplexers **211** may be arranged in two separate areas, in one of which are the memory cells **490** employed for its one or more look-up tables (LUTs) **210** and in the other one of which are its one or more multiplexers **211**. The pass/no-pass switches **258** employed for programmable interconnects **361** may be distributed in one or more lines between the multiplexers **211** of neighboring two of the programmable logic blocks **201**. For the standard commodity FPGA IC chip **200**, some of its multiplexers **211** and some of the pass/no-pass switches **258** may be arranged between the memory-array blocks **395***a* and **395***b*.

(4) Fourth Arrangement for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

Referring to FIG. **8**E, for the standard commodity FPGA IC chip **200**, the memory cells **362** employed for its programmable interconnects **361** may be aggregately arranged in a memory-array block **395** in a certain area of the semiconductor substrate **2** and coupled to (1) multiple first groups of its pass/no-pass switches **258** arranged on or over its semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the first groups may be between neighboring two of its programmable logic blocks **201** in the same row or between the memory-array block **395** and one of its programmable logic blocks **201** in the same row, (2) multiple second groups of its pass/no-pass switches **258** arranged on or over its semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the second groups may be between neighboring two of its programmable logic blocks **201** in the same column or between the memory-array block **395** and one of its programmable logic blocks **201** in the same column, and (3) multiple third groups of the pass/no-pass switches **258** arranged on or over the semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the third groups may be between neighboring two of the first groups of the pass/no-pass switches **258** in the same column and between neighboring two of the second groups of the pass/no-pass switches **258** in the same row. For the standard commodity FPGA IC chip **200**, each of its programmable logic blocks **201** may include one or more multiplexers **211** and one or more groups of memory cells **490** employed for one or more of look-up tables **210** respectively and coupled to the first set of inputs, e.g., D**0**-D**15**, of said one or more of multiplexers **211** respectively, as illustrated in FIG. **8**B, wherein each of the memory cells **490** in said one or more groups may store one of the resulting values or programming codes for said one or more of look-up tables **210** and may have an output coupling to one of the inputs of the first set, e.g., D**0**-D**15**, of said one or more of multiplexers **211**.

(5) Fifth Arrangement for Memory Cells, Multiplexers and Pass/No-Pass Switches for Standard Commodity FPGA IC Chip

Referring to FIG. **8**F, for the standard commodity FPGA IC chip **200**, the memory cells **262** for the programmable interconnects **361** may be aggregately distributed in multiple memory-array blocks **395** on or over its semiconductor substrate **2** and coupled to (1) multiple first groups of its pass/no-pass switches **258** arranged on or over its semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the first groups may be between neighboring two of its programmable logic blocks **201** in the same row or between one of the memory-array blocks **395** and one of its programmable logic blocks **201** in the same row, (2) multiple second groups of its pass/no-pass switches **258** arranged on or over its semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the second groups may be between neighboring two of its programmable logic blocks **201** in the same column or between one of the memory-array blocks **395** and one of its programmable logic blocks **201** in the same column, and (3) multiple third groups of the pass/no-pass switches **258** arranged on or over the semiconductor substrate **2**, wherein each of its pass/no-pass switches **258** in the third groups may be between neighboring two of the first groups of the pass/no-pass switches **258** in the same column and between neighboring two of the second groups of the pass/no-pass switches **258** in the same row. For the standard commodity FPGA IC chip **200**, each of its programmable logic blocks **201** may include one or more multiplexers **211** and one or more groups of memory cells **490** employed for one or more of look-up tables **210** respectively, as illustrated in FIG. **8**B, wherein each of the memory cells **490** in said one or more groups may store one of the resulting values or programming codes for said one or more of look-up tables **210** and may have an output coupling to one of the inputs of the first set, e.g., D**0**-D**15**, of said one or more of multiplexers **211**. One or more of the programmable logic blocks **201** may be positioned between the memory-array blocks **395**.

(6) Memory Cells for First Through Fifth Arrangements

Referring to FIGS. **8**B-**8**F, for the standard commodity FPGA IC chip **200**, each of the memory cells **490** for its look-up tables (LUTs) **210** may be referred to one **398** as illustrated in FIG. **1**A or **1**B having the output Out**1** or Out**2** coupling to one of the inputs D**0**-D**15** in the first set of the multiplexer **211** of its programmable logic block **201** as illustrated in FIGS. **6**A and **6**F-**6**J. For the standard commodity FPGA IC chip **200**, each of the memory cells **362** for its programmable interconnects **361** may be referred to one

398 as illustrated in FIG. 1A or 1B having the output Out1 or Out2 coupling to one of its cross-point switches 379 as illustrated in FIGS. 7A-7C or one of the pass/no-pass switch 258 of its cross-point switches 379.

II. Arrangement for By-Pass Interconnects for Standard Commodity FPGA IC Chip

FIG. 8G is a top view showing programmable interconnects serving as by-pass interconnects in accordance with an embodiment of the present application. Referring to FIG. 8G, the standard commodity FPGA IC chip 200 may include (1) a first group of programmable interconnects 361 to serve as by-pass interconnects 279 each coupling one of the cross-point switches 379 to another far one of the cross-point switches 379 by-passing another one or more of the cross-point switches 379, each of which may be one of the cross-point switches 379 as illustrated in FIGS. 3A-3D, and (2) a second group of programmable interconnects 361 not by-passing any of the cross-point switches 379, but each of the by-pass interconnects 279 may be arranged in parallel with an aggregate of multiple of the programmable interconnects 361 in the second group configured to be coupled to each other or one another via one or more of the cross-point switches 379.

For connection between one of the by-pass interconnects 279 and one the programmable interconnects 361 in the second group, one of the cross-point switches 379 as seen in FIGS. 3A-3C may have the nodes N23 and N25 coupling respectively to two of the programmable interconnects 361 in the second group and the nodes N24 and N26 coupling respectively to two of the by-pass interconnects 279. Thereby, said one of the cross-point switches 379 may switch one selected from two of the programmable interconnects 361 in the second group and two of the by-pass interconnects 279 to be coupled to the other one or more selected from them. For example, said one of the cross-point switches 379 may switch the programmable interconnect 361 in the second group coupling to its node N23 to be coupled to the by-pass interconnect 279 coupling to its node N24. Alternatively, said one of the cross-point switches 379 may switch the programmable interconnect 361 in the second group coupling to its node N23 to be coupled to the programmable interconnect 361 in the second group coupling to its node N25. Alternatively, said one of the cross-point switches 379 may switch the by-pass interconnect 279 coupling to its node N24 to be coupled to the by-pass interconnect 279 coupling to its node N26.

For connection between two of the programmable interconnects 361 in the second group, one of the cross-point switches 379 as seen in FIGS. 3A-3C may have its four nodes N23-N26 coupling to four of the programmable interconnects 361 in the second group respectively. Thereby, said one of the cross-point switches 379 may switch one selected from said four of the programmable interconnects 361 in the second group to be coupled to another one selected from them.

Referring to FIG. 8G, for the standard commodity FPGA IC chip 200, multiple of its cross-point switches 379 surrounds a region 278, in which multiple of its memory cells 362 may be arranged, each of which may be referred to one 398 as illustrated in FIG. 1A or 1B having the output Out1 or Out2 coupling to one of said multiple of its cross-point switches 379 as illustrated in FIGS. 7A-7C or one of the pass/no-pass switches 258 of said one of its cross-point switches 379. For the standard commodity FPGA IC chip 200, in the region 278 are further multiple of its memory cells 490 for the look-up table (LUT) 210 of its programmable logic block 201, each of which may be referred to one 398 as illustrated in FIG. 1A or 1B having the output Out1 or Out2 coupling to one of the inputs D0-D15 in the first set of the multiplexer 211 of its programmable logic block 201 therein as illustrated in FIGS. 6A and 6F-6J. The memory cells 362 for the cross-point switches 379 may be arranged in one or more rings around the programmable logic block 201. Multiple of the programmable interconnects 361 in the second group around the region 278 may couple the second set of inputs, e.g., A0-A3, of the multiplexer 211 of the programmable logic blocks 201 to multiple of the cross-point switches 379 around the region 278 respectively. One of the programmable interconnects 361 in the second group around the region 278 may couple the output, e.g., Dout, of the multiplexer 211 of the programmable logic blocks 201 to one of the cross-point switches 379 around the region 278.

Accordingly, referring to FIG. 8G, the output, e.g., Dout, of the multiplexer 211 of one of the programmable logic blocks 201 may (1) pass to one of the by-pass interconnects 279 alternately through one or more of the programmable interconnects 361 in the second group and one or more of the cross-point switches 379, (2) subsequently pass from said one of the by-pass interconnects 279 to another of the programmable interconnects 361 in the second group alternately through one or more of the cross-point switches 379 and one or more of the by-pass interconnects 279, and (3) finally pass from said another of the programmable interconnects 361 in the second group to one of the inputs in the second set, e.g., A0-A3, of the multiplexer 211 of another of the programmable logic blocks 201 alternately through one or more of the cross-point switches 379 and one or more of the programmable interconnects 361 in the second group.

III. Arrangement for Cross-Point Switches for Standard Commodity FPGA IC Chip

FIG. 8H is a top view showing arrangement for cross-point switches for a standard commodity FPGA IC chip in accordance with an embodiment of the present application. Referring to FIG. 8H, the standard commodity FPGA IC chip 200 may include the programmable logic blocks (LB) 201 arranged in an array, multiple connection blocks (CB) 455 each arranged between neighboring two of the programmable logic blocks (LB) 201 in the same column or row, and multiple switch blocks (SB) 456 each arranged between neighboring two of the connection blocks (CB) 455 in the same column or row. Each of the connection blocks (CB) 455 may be composed of multiple of the cross-point switches 379 of the fourth type as seen in FIGS. 3D and 7C. Each of the switch blocks (SB) 456 may be composed of multiple of the cross-point switches 379 of the third type as seen in FIGS. 3C and 7B.

Referring to FIG. 8H, for each of the connection blocks (CB) 455, each of its cross-point switches 379 of the fourth type may have its inputs, e.g., D0-D15, each coupling to one of the programmable interconnects 361 and its output, e.g., Dout, coupling to another of the programmable interconnects 361. Said one of the programmable interconnects 361 may couple one of the inputs, e.g., D0-D15, of one of the cross-point switches 379 of one of the connection blocks (CB) 455 as illustrated in FIGS. 3D and 7C to (1) the output, e.g., Dout, of one of the programmable logic blocks (LB) 201 as illustrated in FIG. 6A or 6H or (2) one of nodes N23-N26 of one of the cross-point switches 379 of one of the switch blocks (SB) 456 as illustrated in FIGS. 3C and 7B. Alternatively, said another of the programmable interconnects 361 may couple the output, e.g., Dout, of one of the cross-point switches 379 of one of the connection blocks (CB) 455 as illustrated in FIGS. 3D and 7C to (1) one of the inputs, e.g., A0-A3 of one of the programmable logic blocks

(LB) **201** as illustrated in FIG. **6**A or **6**H or (2) one of the nodes N**23**-N**26** of one of the cross-point switches **379** of one of the switch blocks (SB) **456** as illustrated in FIGS. **3**C and **7**B.

For example, referring to FIG. **8**H, one or more of the inputs, e.g., D**0**-D**15**, of the cross-point switch **379** as illustrated in FIGS. **3**D and **7**C for said one of the connection blocks (CB) **455** may couple to the output Dout of the programmable logic block (LB) **201** as illustrated in FIG. **6**A or **6**H at its first side through one or more of the programmable interconnects **361**. Another one or more of the inputs, e.g., D**0**-D**15**, of the cross-point switch **379** as illustrated in FIGS. **3**D and **7**C for said one of the connection blocks (CB) **455** may couple to the output Dout of the programmable logic block (LB) **201** as illustrated in FIG. **6**A or **6**H at its second side opposite to its first side through one or more of the programmable interconnects **361**. Another one or more of the inputs, e.g., D**0**-D**15**, of the cross-point switch **379** as illustrated in FIGS. **3**D and **7**C for said one of the connection blocks (CB) **455** may couple to one of the nodes N**23**-N**26** of the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for the switch blocks (SB) **456** at its third side through one or more of the programmable interconnects **361**. Another one or more of the inputs, e.g., D**0**-D**15**, of the cross-point switch **379** as illustrated in FIGS. **3**D and **7**C for said one of the connection blocks (CB) **455** may couple to one of the nodes N**23**-N**26** of the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for the switch block (SB) **456** at its fourth side opposite to its third side through one or more of the programmable interconnects **361**. The output, e.g., Dout, of the cross-point switch **379** as illustrated in FIGS. **3**D and **7**C for said one of the connection blocks (CB) **455** may couple to one of the nodes N**23**-N**26** of the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for the switch block (SB) **456** at its third or fourth side through one or more of the programmable interconnects **361** or to one of the inputs A**0**-A**3** of the programmable logic block (LB) **201** as illustrated in FIG. **6**A or **6**H at its first or second side through one or more of the programmable interconnects **361**.

Referring to FIG. **8**H, for each of the switch blocks (SB) **456**, its cross-point switch **379** of the third type as illustrated in FIGS. **3**C and **7**B may have its four nodes N**23**-N**26** coupling respectively to four of the programmable interconnects **361** in four different directions. For example, the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for said each of the switch blocks (SB) **456** may have its node N**23** coupling to one of the inputs D**0**-D**15** and output Dout of the cross-point switch **379** as seen in FIGS. **3**D and **7**C for the connection block (CB) **455** at its left side through one of said four of the programmable interconnects **361**, the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for said each of the switch blocks (SB) **456** may have its node N**24** coupling to one of the inputs D**0**-D**15** and output Dout of the cross-point switch **379** as seen in FIGS. **3**D and **7**C for the connection block (CB) **455** at its top side through another of said four of the programmable interconnects **361**, the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for said each of the switch blocks (SB) **456** may have its node N**25** coupling to one of the inputs D**0**-D**15** and output Dout of the cross-point switch **379** as seen in FIGS. **3**D and **7**C for the connection block (CB) **455** at its right side through another of said four of the programmable interconnects **361**, and the cross-point switch **379** as illustrated in FIGS. **3**C and **7**B for said each of the switch blocks (SB) **456** may have its node N**26** coupling to one of the inputs D**0**-D**15** and output Dout of the cross-point switch **379** as seen in FIGS. **3**D and **7**C for the connection block (CB) **455** at its bottom side through the other of said four of the programmable interconnects **361**.

Thereby, referring to FIG. **8**H, signal transmission may be built from one of the programmable logic blocks (LB) **201** to another of the programmable logic blocks (LB) **201** through multiple of the switch blocks (SB) **456**, wherein between each neighboring two of said multiple of the switch blocks (SB) **456** may be arranged one of the connection blocks (CB) **455** for the signal transmission, between said one of the programmable logic blocks (LB) **201** and one of said multiple of the switch blocks (SB) **456** may be arranged one of the connection blocks (CB) **455** for the signal transmission, and between said another of the programmable logic blocks (LB) **201** and one of said multiple of the switch blocks (SB) **456** may be one of the connection blocks (CB) **455** for the signal transmission. For example, a signal may be transmitted from an output, e.g., Dout, of said one of the programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H to one of the inputs, e.g., D**0**-D**15**, of the cross-point switches **379** of the fourth type as seen in FIGS. **3**D and **7**C for a first one of the connection blocks (CB) **455** through one of the programmable interconnects **361**. Next, the cross-point switches **379** of the fourth type for the first one of the connection blocks (CB) **455** may pass the signal from said one of its inputs, e.g., D**0**-D**15**, to its output, e.g., Dout, to be transmitted to a node N**23** of one of the cross-point switches **379** of the third type as seen in FIGS. **3**C and **7**B for one of the switch blocks (SB) **456** through another of the programmable interconnects **361**. Next, said one of the cross-point switches **379** of the third type for one of the switch blocks (SB) **456** may pass the signal from its node N**23** to its node N**25** to be transmitted to one of the inputs, e.g., D**0**-D**15**, of the cross-point switches **379** of the fourth type as seen in FIGS. **3**D and **7**C for a second one of the connection blocks (CB) **455** through another of the programmable interconnects **361**. Next, the cross-point switches **379** of the fourth type for the second one of the connection blocks (CB) **455** may pass the signal from said one of its inputs, e.g., D**0**-D**15**, to its output, e.g., Dout, to be transmitted to one of the inputs, e.g., A**0**-A**3**, of said another of the programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H through another of the programmable interconnects **361**.

IV. Repair for Standard Commodity FPGA IC Chip

FIG. **8**I is a block diagram showing a repair for a standard commodity FPGA IC chip in accordance with an embodiment of the present application. Referring to FIG. **8**I, the standard commodity FPGA IC chip **200** may have a spare **201**-*s* for the programmable logic blocks **201** configured to replace a broken one of the programmable logic blocks **201**. The standard commodity FPGA IC chip **200** may include (1) multiple input repair switch matrixes **276** each having multiple outputs each coupling in series to one of the inputs A**0**-A**3** of one of the programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H and (2) multiple output repair switch matrixes **277** each having one or more input(s) coupling in series to the one or more output(s) Dout of one of the programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H. Furthermore, the standard commodity FPGA IC chips **200** may include (1) multiple spare input repair switch matrixes **276**-*s* each having multiple outputs each coupling in parallel to one of the outputs of each of the others of the spare input repair switch matrixes **276**-*s* and coupling in series to one of the inputs A**0**-A**3** of the spare **201**-*s* for the programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H, and (2) multiple spare output repair switch matrixes **277**-*s* each having one or more input(s) coupling respec-

tively in parallel to the one or more input(s) of each of the others of the spare output repair switch matrixes **277**-*s* and coupling respectively in series to the one or more output(s) Dout of the spare **201**-*s* for the programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H. Each of the spare input repair switch matrixes **276**-*s* may have multiple inputs each coupling in parallel to one of the inputs of one of the input repair switch matrixes **276**. Each of the spare output repair switch matrixes **277**-*s* may have one or more outputs coupling respectively in parallel to the one or more outputs of one of the output repair switch matrixes **277**.

Thereby, referring to FIG. **8**I, when one of the programmable logic blocks **201** is broken, one of the input repair switch matrixes **276** and one of the output repair switch matrixes **277** coupling to the inputs and output(s) of said one of the programmable logic blocks **201** respectively may be tamed off; one of the spare input repair switch matrixes **276**-*s* having its inputs coupling respectively in parallel to the inputs of said one of the input repair switch matrixes **276** and one of the spare output repair switch matrixes **277**-*s* having its output(s) coupling respectively in parallel to the output(s) of said one of the output repair switch matrixes **277** may be turned on; the others of the spare input repair switch matrixes **276**-*s* and the others of the spare output repair switch matrixes **277**-*s* may be turned off. Accordingly, the broken one of the programmable logic blocks **201** may be replaced with the spare **201**-*s* for the programmable logic blocks **201**.

FIG. **8**J is a block diagram showing a repair for a standard commodity FPGA IC chip in accordance with an embodiment of the present application. Referring to FIG. **8**J, the programmable logic blocks (LB) **201** may be arranged in an array. When one of the programmable logic blocks (LB) **201** arranged in a column is broken, all of the programmable logic blocks (LB) **201** arranged in the column may be tamed off and multiple spares **201**-*s* for the programmable logic blocks (LB) **201** arranged in a column may be turned on. Next, the columns for the programmable logic blocks (LB) **201** and the spares **201**-*s* for the programmable logic blocks (LB) **201** may be renumbered, and each of the programmable logic blocks **201** after repaired in a renumbered column and in a specific row may perform the same operations as one of the programmable logic blocks (LB) **201** before repaired in a column having the same number as the renumbered column and in the specific row. For example, when one of the programmable logic blocks (LB) **201** arranged in the column N-**1** is broken, all of the programmable logic blocks (LB) **201** arranged in the column N-**1** may be turned off and the spares **201**-*s* for the programmable logic blocks (LB) **201** arranged in the rightmost column may be turned on. Next, the columns for the programmable logic blocks (LB) **201** and the spares **201**-*s* for the programmable logic blocks (LB) **201** may be renumbered such that the rightmost column arranged for the spare **201**-*s* for the programmable logic blocks (LB) **201** before repaired may be renumbered to column **1** after the programmable logic blocks (LB) **201** are repaired, the column **1** arranged for the programmable logic blocks (LB) **201** before repaired may be renumbered to column **2** after the programmable logic blocks (LB) **201** are repaired, and so on. The column n−2 arranged for the programmable logic blocks (LB) **201** before repaired may be renumbered to column n−1 after the programmable logic blocks (LB) **201** are repaired, wherein n is an integer ranging from 3 to N. Each of the programmable logic blocks (LB) **201** after repaired in the renumbered column m and in a specific row may perform the same operation as one of the programmable logic blocks **201** before repaired in the column m and in the specific row, where m is an integer ranging from 1 to N. For example, each of the programmable logic blocks (LB) **201** after repaired in the renumbered column **1** and in a specific row may perform the same operations as one of the programmable logic blocks **201** before repaired in the column **1** and in the specific row.

V. Programmable Logic Blocks for Standard Commodity FPGA IC Chip

Alternatively, FIG. **8**K is a block diagram illustrating a programmable logic block for a standard commodity FPGA IC chip in accordance with an embodiment of the present application. Referring to FIG. **8**K, each of the programmable logic blocks **201** as seen in FIG. **8**A may include (1) one or more cells (A) **2011** for fixed-wired adders, having the number ranging from 1 to 16 for example, (2) one or more cells (M) **2012** for fixed-wired multipliers, having the number ranging from 1 to 16 for example, (3) one or more cells (C/R) **2013** for caches and registers, each having capacity ranging from 256 to 2048 bits for example, and (4) multiple cells (LC) **2014** for logic operation, having the number ranging from 64 to 2048 for example. Said each of the programmable logic blocks **201** as seen in FIG. **8**A may further include multiple intra-block interconnects **2015** each extending over spaces between neighboring two of its cells **2011**, **2012**, **2013** and **2014** arranged in an array therein. For said each of the programmable logic blocks, its intra-chip interconnects **502** may be divided into the programmable interconnects **361** and fixed interconnects **364** as illustrated in FIG. **7**A-**7**C; the programmable interconnects **361** of its intra-chip interconnects **2015** may couple to the programmable interconnects **361** of the intra-chip interconnects **502** of the FPGA IC chip **200** respectively, and the fixed interconnects **364** of its intra-chip interconnects **2015** may couple to the fixed interconnects **364** of the intra-chip interconnects **502** of the FPGA IC chip **200** respectively.

Referring to FIGS. **8**A and **8**K, each of the cells (LC) **2014** for logic operation may be arranged with multiple programmable logic architectures having the number ranging from 4 to 256 for example, each of which may be seen in FIG. **6**A with its memory cells **490** for its look-up table **210** coupling respectively to the first set of inputs of its multiplexer **211** having the number ranging from 4 to 256 for example, one from which may be selected by its multiplexer **211** into its output in accordance with the second set of inputs of its multiplexer **211** having the number ranging from 2 to 8 for example each coupling to one of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015**. For example, the logic architecture may have its 16 memory cells **490** for its look-up table **210** coupling respectively to the first set of 16 inputs of its multiplexer **211**, one from which may be selected by its multiplexer **211** into its output in accordance with the second set of 4 inputs of its multiplexer **211** each coupling to one of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015**, as seen in FIGS. **6**A and **6**F-**6**J. Further, said each of the cells (LC) **2014** for logic operation may be arranged with a register configured for temporally saving the output of the logic architecture or one of the inputs of the second set of the multiplexer **211** of the logic architecture.

FIG. **8**L is a circuit diagram illustrating a cell of an adder in accordance with an embodiment of the present application. FIG. **8**M is a circuit diagram illustrating an adding unit for a cell of an adder in accordance with an embodiment of the present application. Referring to FIGS. **8**A, **8**L and **8**M, each of the cells (A) **2011** for fixed-wired adders may

include multiple adding units **2016** coupling in series and stage by stage to each other or one another. For example, said each of the cells (A) **2011** for fixed-wired adders as seen in FIG. **8**K may include 8 stages of the adding unit **2016** coupling in series and stage by stage to one another as seen in FIGS. **8**L and **8**M to add its first 8-bit input (A**7**, A**6**, A**5**, A**4**, A**3**, A**2**, A**1**, A**0**) coupling to eight of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015** by its second 8-bit input (B**7**, B**6**, B**5**, B**4**, B**3**, B**2**, B**1**, B**0**) coupling to another eight of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015** into its 9-bit output (Cout, S**7**, S**6**, S**5**, S**4**, S**3**, S**2**, S**1**, S**0**) coupling to another nine of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015**. Referring to FIGS. **8**L and **8**M, the first stage of the adding unit **2016** may take its carry-in input Cin from a previous computation result coupling to one of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015** into account to add its first input In**1** coupling to the input A**0** of said each of the cells (A) **2011** for fixed-wired adders by its second input In**2** coupling to the input B**0** of said each of the cells (A) **2011** into its two outputs, one of which is an output Out acting as the output S**0** of said each of the cells (A) **2011** for fixed-wired adders and the other one of which is a carry-out output Cout coupling to a carry-in input Cin of the adding unit **2016** of the second stage. Each of the adding units **2016** of the second through seventh stages may take its carry-in input Cin from the carry-out output Cout of one of the adding units **2016** of the first through sixth stages previous to said each of the adding units **2016** into account to add its first input In**1** coupling to one of the inputs A**1**, A**2**, A**3**, A**4**, A**5** and A**6** of said each of the cells (A) **2011** for fixed-wired adders by its second input In**2** coupling to one of the inputs B**1**, B**2**, B**3**, B**4**, B**5** and B**6** of said each of the cells (A) **2011** into its two outputs, one of which is an output Out acting as one of the outputs S**1**, S**2**, S**3**, S**4**, S**5** and S**6** of said each of the cells (A) **2011** for fixed-wired adders and the other one of which is a carry-out output Cout coupling to a carry-in input Cin of one of the adding units **2016** of the third through eighth stages next to said each of the adding units **2016**. For example, the seventh stage of adding unit **2016** may take its carry-in input Cin from a carry-out output Cout of the adding unit **2016** of the sixth stage into account to add its first input In**2** coupling to the input A**6** of said each of the cells (A) **2011** for fixed-wired adders by its second input In**2** coupling to the input B**6** of said each of the cells (A) **2011** into its two outputs, one of which is an output Out acting as the output S**6** of said each of the cells (A) **2011** for fixed-wired adders and the other one of which is a carry-out output Cout coupling to a carry-in input Cin of the adding unit **2016** of the eighth stage. The eighth stage of the adding unit **2016** may take its carry-in input Cin from the carry-out output Cout of the adding unit **2016** of the seventh stage into account to add its first input In**1** coupling to the input A**7** of said each of the cells (A) **2011** for fixed-wired adders by its second input In**2** coupling to the input B**7** of said each of the cells (A) **2011** into its two outputs, one of which is an output Out acting as the output S**7** of said each of the cells (A) **2011** for fixed-wired adders and the other one of which is a carry-out output Cout acting as the carry-out output Cout of said each of the cells (A) **2011** for fixed-wired adders.

Referring to FIGS. **8**L and **8**M, each of the adding units **2016** of the first through eighth stages may include (1) an ExOR gate **342** configured to perform Exclusive-OR operation on its first and second inputs coupling respectively to the first and second inputs In**1** and In**2** of said each of the adding units **2016** of the first through eighth stages into its output, (2) an ExOR gate **343** configured to perform Exclusive-OR operation on its first input coupling to the output of the ExOR gate **342** and its second input coupling to the carry-in input Cin of said each of the adding units **2016** of the first through eighth stages into its output acting as the output Out of said each of the adding units **2016** of the first through eighth stages, (3) an AND gate **344** configured to perform Exclusive-OR operation on its first input coupling to the carry-in input Cin of said each of the adding units **2016** of the first through eighth stages and its second input coupling to the output of the ExOR gate **342** into its output, (4) an AND gate **345** configured to perform Exclusive-OR operation on its first and second inputs coupling respectively to the second and first inputs In**2** and In**1** of said each of the adding units **2016** of the first through eighth stages into its output, and (5) an OR gate **346** configured to perform OR operation on its first input coupling to the output of the AND gate **344** and its second input coupling to the output of the AND gate **345** into its output acting the Carry-out output Cout of said each of the adding units **2016** of the first through eighth stages.

FIG. **8**N is a circuit diagram illustrating a cell of a fixed-wired multiplier in accordance with an embodiment of the present application. Referring to FIGS. **8**A and **8**N, each of the cells (M) **2012** for fixed-wired multipliers may include multiple stages of the adding units **2016**, each of which may be referred to the architecture as illustrated in FIG. **8**M, coupling in series and stage by stage to each other or one another. For example, said each of the cells (M) **2012** for fixed-wired multipliers as seen in FIG. **8**K may include 8 stages of the 7 adding units **2016** coupling in series and stage by stage to one another as seen in FIGS. **8**N and **8**M to multiplies its first 8-bit input (X**7**, X**6**, X**5**, X**4**, X**3**, X**2**, X**1**, X**0**) coupling to eight of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015** by its second 8-bit input (Y**7**, Y**6**, Y**5**, Y**4**, Y**3**, Y**2**, Y**1**, Y**0**) coupling to another eight of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015** into its 16-bit output (P**15**, P**14**, P**13**, P**12**, P**11**, P**10**, P**9**, P**8**, P**7**, P**6**, P**5**, P**4**, P**3**, P**2**, P**1**, P**0**) coupling to another sixteen of the programmable interconnects **361** and fixed interconnects **364** of the intra-block interconnects **2015**. Referring to FIGS. **8**N and **8**M, said each of the cells (M) **2012** for fixed-wired multipliers may include 64 AND gates **347** each configured to perform AND operation on its first input coupling to one of the first 8 inputs X**7**, X**6**, X**5**, X**4**, X**3**, X**2**, X**1** and X**0** of said each of the cells (M) **2012** for fixed-wired multipliers and its second input coupling to one of the second 8 inputs Y**7**, Y**6**, Y**5**, Y**4**, Y**3**, Y**2**, Y**1** and Y**0** of said each of the cells (M) **2012** for fixed-wired multipliers into its output. For more elaboration, for said each of the cells (M) **2012** for fixed-wired multipliers, its 64 AND gates **347** arranged in 8 rows may have their first and second inputs coupling respectively to 64 (8-by-8) combinations of each of its first 8 inputs X**7**, X**6**, X**5**, X**4**, X**3**, X**2**, X**1** and X**0** and each of its second 8 inputs Y**7**, Y**6**, Y**5**, Y**4**, Y**3**, Y**2**, Y**1** and Y**0**; its 8 AND gates **347** in the first row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X**7**, X**6**, X**5**, X**4**, X**3**, X**2**, X**1** and X**0** arranged from left to right and their second respective inputs coupling to its second input Y**0** into their respective outputs; its 8 AND gates **347** in the second row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X**7**, X**6**, X**5**, X**4**, X**3**, X**2**, X**1** and X**0** arranged from

left to right and their second respective inputs coupling to its second input Y1 into their respective outputs; its 8 AND gates **347** in the third row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y2 into their respective outputs; its 8 AND gates **347** in the fourth row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y3 into their respective outputs; its 8 AND gates **347** in the fifth row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y4 into their respective outputs; its 8 AND gates **347** in the sixth row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y5 into their respective outputs; its 8 AND gates **347** in the seventh row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y6 into their respective outputs; its 8 AND gates **347** in the eighth row may perform AND operation on their first respective inputs coupling respectively to its first 8 inputs X7, X6, X5, X4, X3, X2, X1 and X0 arranged from left to right and their second respective inputs coupling to its second input Y7 into their respective outputs.

Referring to FIGS. **8**M and **8**N, for said each of the cells (M) **2012** for fixed-wired multipliers, the output of the rightmost one of its AND gates **347** in the first row may act as its output P0. For said each of the cells (M) **2012** for fixed-wired multipliers, the outputs of the left seven of its AND gates **347** in the first row may couple respectively to the first inputs In1 of its 7 adding units **2016** of the second stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the outputs of the right seven of its AND gates **347** in the second row may couple respectively to the second inputs In2 of its 7 adding units **2016** of the second stage.

Referring to FIGS. **8**M and **8**N, for said each of the cells (M) **2012** for fixed-wired multipliers, its 7 adding units **2016** of the first stage may take their respective carry-in inputs Cin at a logic level of "0" into account to add their first respective inputs In1 by their second respective inputs In2 into their respective outputs Out, the rightmost one of which may act as its output P1 and the left six of which may couple respectively to the first inputs In1 of the right six of its 7 adding units **2016** of the second stage, and their respective carry-out outputs Cout coupling respectively to the carry-in inputs Cin of its 7 adding units **2016** of the second stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the output of the leftmost one of its AND gates **347** in the second row may couple to the first input In1 of the leftmost one of its adding units **2016** of the second stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the outputs of the right seven of its AND gates **347** in the third row may couple respectively to the second inputs In2 of its 7 adding units **2016** of the second stage.

Referring to FIGS. **8**M and **8**N, for said each of the cells (M) **2012** for fixed-wired multipliers, its 7 adding units **2016** of each of the second through sixth stages may take their respective carry-in inputs Cin into account to add their first respective inputs In1 by their second respective inputs In2 into their respective outputs Out, the rightmost one of which may act as one of its outputs P2-P6 and the left six of which may couple respectively to the first inputs In1 of the right six of its 7 adding units **2016** of next one of the third through seventh stages next to said each of the second through sixth stages, and their respective carry-out outputs Cout coupling respectively to the carry-in inputs Cin of its 7 adding units **2016** of said next one of the third through seventh stages. For said each of the cells (M) **2012** for fixed-wired multipliers, the output of the leftmost one of its AND gates **347** in each of the third through seventh rows may couple to the first input In1 of the leftmost one of its adding units **2016** of one of the third through seventh stages. For said each of the cells (M) **2012** for fixed-wired multipliers, the outputs of the right seven of its AND gates **347** in each of the fourth through eighth rows may couple respectively to the second inputs In2 of its 7 adding units **2016** of one of the third through seventh stages.

For example, referring to FIGS. **8**M and **8**N, for said each of the cells (M) **2012** for fixed-wired multipliers, its 7 adding units **2016** of the second stage may take their respective carry-in inputs Cin into account to add their first respective inputs In1 by their second respective inputs In2 into their respective outputs Out, the rightmost one of which may act as its output P2 and the left six of which may couple respectively to the first inputs In1 of the right six of its 7 adding units **2016** of the third stage, and their respective carry-out outputs Cout coupling respectively to the carry-in inputs Cin of its 7 adding units **2016** of the third stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the output of the leftmost one of its AND gates **347** in the third row may couple to the first input In1 of the leftmost one of its adding units **2016** of the third stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the outputs of the right seven of its AND gates **347** in the fourth row may couple respectively to the second inputs In2 of its 7 adding units **2016** of the third stage.

Referring to FIGS. **8**M and **8**N, for said each of the cells (M) **2012** for fixed-wired multipliers, its 7 adding units **2016** of the seventh stage may take their respective carry-in inputs Cin into account to add their first respective inputs In1 by their second respective inputs In2 into their respective outputs Out, the rightmost one of which may act as its output P7 and the left six of which may couple respectively to the second inputs In2 of the right six of its 7 adding units **2016** of the eighth stage, and their respective carry-out outputs Cout coupling respectively to the first inputs In1 of its 7 adding units **2016** of the eighth stage. For said each of the cells (M) **2012** for fixed-wired multipliers, the output of the leftmost one of its AND gates **347** in the eighth row may couple to the second input In2 of the leftmost one of its adding units **2016** of the eighth stage.

Referring to FIGS. **8**M and **8**N, the rightmost one of its 7 adding units **2016** of the eighth stage of said each of the cells (M) **2012** for fixed-wired multipliers may take its carry-in input Cin at a logic level of "0" into account to add its first input In1 by its second input In2 into its output Out acting as the output P8 of said each of the cells (M) **2012** for fixed-wired multipliers and its carry-out output Cout coupling to the carry-in input Cin of the second rightmost one of its 7 adding units **2016** of the eighth stage of said each of the cells (M) **2012** for fixed-wired multipliers left to the rightmost one thereof. Each of the second rightmost one through second leftmost one of its 7 adding units **2016** of the eighth stage of said each of the cells (M) **2012** for fixed-wired multipliers may take its respective carry-in inputs Cin into account to add its first input In1 by its second input In2

into its outputs Out acting as one of the outputs P9-P13 of said each of the cells (M) 2012 for fixed-wired multipliers and its carry-out output Cout coupling to the carry-in input Cin of one of the third rightmost one through leftmost one of its 7 adding units 2016 of the eighth stage of said each of the cells (M) 2012 for fixed-wired multipliers left to said each of the second rightmost one through second leftmost one thereof. The leftmost one of its 7 adding units 2016 of the eighth stage of said each of the cells (M) 2012 for fixed-wired multipliers may take its carry-in input Cin into account to add its first input In1 by its second input In2 into its output Out acting as the output P14 of said each of the cells (M) 2012 for fixed-wired multipliers and its carry-out output Cout acting as the output P15 thereof.

Each of the cells (C/R) 2013 for caches and registers as seen in FIG. 8K may be configured for temporally save or store (1) the inputs and outputs of the cells (A) 2011 for fixed-wired adders, such as the carry-in input Cin of its adding unit of the first stage, its first and second 8-bit inputs (A7, A6, A5, A4, A3, A2, A1, A0) and (B7, B6, B5, B4, B3, B2, B1, B0) and/or its 9-bit output (Cout, S7, S6, S5, S4, S3, S2, S1, S0) as illustrated in FIGS. 8L and 8M, (2) the inputs and outputs of the cells (M) 2012 for fixed-wired multipliers, such as its first and second 8-bit inputs (X7, X6, X5, X4, X3, X2, X1, X0) and (Y7, Y6, Y5, Y4, Y3, Y2, Y1, Y0) and/or its 16-bit output (P15, P14, P13, P12, P11, P10, P9, P8, P7, P6, P5, P4, P3, P2, P1, P0) as illustrated in FIGS. 8M and 8N, and/or (3) the inputs and outputs of the cells (LC) 2014 for logic operation, i.e., the output of its logic architecture or one of the inputs of the second set of the multiplexer 211 of its logic architecture.

Specification for Dedicated Programmable Interconnection (DPI) Integrated-Circuit (IC) Chip

FIG. 9 is a schematically top view showing a block diagram of a dedicated programmable interconnection (DPI) integrated-circuit (IC) chip in accordance with an embodiment of the present application. Referring to FIG. 9, a dedicated programmable interconnection (DPI) integrated-circuit (IC) chip 410 is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm; with a chip size and manufacturing yield optimized with the minimum manufacturing cost for the used semiconductor technology node or generation. The dedicated IP IC chip 410 may have an area between 400 mm^2 and 9 mm^2, 225 mm^2 and 9 mm^2, 144 mm^2 and 16 mm^2, 100 mm^2 and 16 mm^2, 75 mm^2 and 16 mm^2, or 50 mm^2 and 16 mm^2. Transistors or semiconductor devices of the dedicated IP IC chip 410 used in the advanced semiconductor technology node or generation may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET.

Referring to FIG. 9, since the dedicated programmable interconnection (DPI) integrated-circuit (IC) chip 410 is a standard commodity IC chip, the number of types of products for the DPIIC chip 410 may be reduced to a small number, and therefore expensive photo masks or mask sets for fabricating the DPIIC chip 410 using advanced semiconductor nodes or generations may be reduced to a few mask sets. For example, the mask sets for a specific technology node or generation may be reduced down to between 3 and 20, 3 and 10, or 3 and 5. Its NRE and production expenses are therefore greatly reduced. With the few types of products for the DPIIC chip 410, the manufacturing processes may be optimized to achieve very high manufacturing chip yields. Furthermore, the chip inventory management becomes easy, efficient and effective, therefore resulting in a relatively short chip delivery time and becoming very cost-effective.

Referring to FIG. 9, the DPIIC chip 410 may be of various types, including (1) multiple memory-array blocks 423 arranged in an array in a central region thereof, (2) multiple groups of cross-point switches 379 as illustrated in FIG. 3A, 3B, 3C or 3D, each group of which is arranged in one or more rings around one of the memory-array blocks 423, and (3) multiple small input/output (I/O) circuits 203, as illustrated in FIG. 5B, each having the node of S_Data_in coupling to one of the nodes N23-N26 of one of its cross-point switches 379 as illustrated in FIGS. 3A-3C through one of the programmable interconnects 361 or to one of the inputs D0-D15 of one of its cross-point switches 379 as illustrated in FIG. 3D through one of the programmable interconnects 361 and the node of S_Data_out coupling to one of the nodes N23-N26 of another of its cross-point switches 379 as illustrated in FIGS. 3A-3C through another of the programmable interconnects 361 or to the output Dout of another of its cross-point switches 379 as illustrated in FIG. 3D through another of the programmable interconnects 361. In each of the memory-array blocks 423 are multiple of memory cells 362, each of which may be referred to one 398 as illustrated in FIG. 1A or 1B, each having an output Out1 and/or Out2 coupling to one of the pass/no-pass switches 258 for one of the cross-point switches 379 as illustrated in FIGS. 3A, 3B and 7A close to said each of the memory-array blocks 423 to switch on or off said one of the pass/no-pass switches 258. Alternatively, in each of the memory-array blocks 423 are multiple of memory cells 362, each of which may be referred to one as illustrated in FIG. 1A or 1B, each having an output Out1 or Out2 coupling to one of the inputs, e.g., A0 and A1, of the second set and inputs SC-4 of one of the multiplexers 211 of one of the cross-point switches 379 as illustrated in FIGS. 3C and 7B close to said each of the memory-array blocks 423. Alternatively, in each of the memory-array blocks 423 are multiple of memory cells 362, each of which may be referred to one as illustrated in FIG. 1A or 1B, each having an output Out1 or Out2 coupling to one of the inputs, e.g., A0-A3, of the second set of the multiplexer 211 of one of the cross-point switches 379 as illustrated in FIGS. 3D and 7C close to said each of the memory-array blocks 423.

Referring to FIG. 9, the DPIIC chip 410 may include multiple intra-chip interconnects (not shown) each extending over spaces between neighboring two of the memory-array blocks 423, wherein said each of the intra-chip interconnects may be the programmable interconnect 361 or fixed interconnect 364 as illustrated in FIGS. 7A-7C. For the DPIIC chip 410, each of its small input/output (I/O) circuits 203, as illustrated in FIG. 5B, may have its output S_Data_in coupling to one or more of its programmable interconnects 361 and/or one or more of its fixed interconnects 364 and its input S_Data_out, S_Enable or S_Inhibit coupling to another one or more of its programmable interconnects 361 and/or another one or more of its fixed interconnects 364.

Referring to FIG. 9, the DPIIC chip 410 may include multiple of the I/O pads 372 as seen in FIG. 5B, each vertically over one of its small input/output (I/O) circuits 203, coupling to the node 381 of said one of its small input/output (I/O) circuits 203. In a first clock, a signal from one of the nodes N23-N26 of one of the cross-point switches 379 as illustrated in FIGS. 3A-3C, 7A and 7B, or the output Dout of one of the cross-point switches 379 as illustrated in

FIGS. **3**D and **7**C, may be transmitted to the input S_Data_out of the small driver **374** of one of the small input/output (I/O) circuits **203** through one or more of the programmable interconnects **361**, and then the small driver **374** of said one of the small input/output (I/O) circuits **203** may amplify its input S_Data_out to be transmitted to one of the I/O pads **372** vertically over said one of the small input/output (I/O) circuits **203** for external connection to circuits outside the DPIIC chip **410**. In a second clock, a signal from circuits outside the DPIIC chip **410** may be transmitted to the small receiver **375** of said one of the small input/output (I/O) circuits **203** through said one of the I/O pads **372**, and then the small receiver **375** of said one of the small input/output (I/O) circuits **203** may amplify the signal into its output S_Data_in to be transmitted to one of the nodes N**23**-N**26** of another of the cross-point switches **379** as illustrated in FIGS. **3**A-**3**C, **7**A and **7**B, or to one of the inputs D**0**-D**15** of another of the cross-point switches **379** as illustrated in FIGS. **3**D and **7**C, through another one or more of the programmable interconnects **361**. Referring to FIG. **9**, the DPIIC chip **410** may further include (1) multiple power pads **205** for applying the voltage Vcc of power supply to the memory cells **362** for the cross-point switches **379** as illustrated in FIGS. **7**A-**7**C, wherein the voltage Vcc of power supply may be between 0.2V and 2.5V between 0.2V and 2V between 0.2V and 1.5V, between 0.1V and 1V, or between 0.2V and 1V, or, smaller or lower than or equal to 2.5V, 2V 1.8V 1.5V or 1V, and (2) multiple ground pads **206** for providing the voltage Vss of ground reference to the memory cells **362** for the cross-point switches **379** as illustrated in FIGS. **7**A-**7**C.

Referring to FIG. **9**, the DPIIC chip **410** may further include multiple 6T SRAM cells **398** as illustrated in FIG. **1**A used as cache memory for data latch or storage. Each of the 6T SRAM cells **398** may include two switches **449**, such as N-type or P-type MOS transistors, for bit and bit-bar data transfer, and two pairs of P-type and N-type MOS transistors **447** and **448** for data latch or storage nodes. Each of the 6T SRAM cells **398** acting as the cache memory provides the two switches **449** for writing data into it and reading data stored in it. The DPIIC chip **410** may further include a sense amplifier for reading (amplifying or detecting) data from the 6T SRAM cells **398** acting as the cache memory. Accordingly, the 6T SRAM cells **398** of the DPIIC chip **410** may act as cache memory to store data from any of the semiconductor chips **200**, **250**, **251**, **260**, **265**, **266**, **267**, **268**, **269**, **269***a*, **269***b*, **269***c*, **324** and **402** of one of the standard commodity logic drive **300** as seen in FIGS. **11**A-**11**N during the processing or computing of the standard commodity logic drive **300**.

Specification for Dedicated Input/Output (I/O) Chip

FIG. **10** is a block diagram for a dedicated input/output (I/O) chip in accordance with an embodiment of the present application. Referring to FIG. **10**, a dedicated input/output (I/O) chip **265** may include a plurality of the large I/O circuit **341** (only one is shown) and a plurality of the small I/O circuit **203** (only one is shown). The large I/O circuit **341** may be referred to one as illustrated in FIG. **5**A; the small I/O circuit **203** may be referred to one as illustrated in FIG. **5**B.

Referring to FIGS. **5**A, **5**B and **10**, each of the large I/O circuits **341** may be provided with the large driver **274** having the input L_Data_out coupling to the output S_Data_in of the small receiver **375** of one of the small I/O circuits **203**. Each of the large I/O circuits **341** may be provided with the large receiver **275** having the node of L_Data_in coupling to the node of S_Data_out of the small driver **374** of one of the small I/O circuits **203**. When the large driver **274** is enabled by the L_Ebable signal, the small receiver **375** is activated by the S_Inhibit signal, the large receiver **275** is inhibited by the L_Inhibit signal and the small driver **374** is disabled by the S_Ebable signal, data from the I/O pad **372** of the small I/O circuit **203** may pass to the I/O pad **272** of the large I/O circuit **341** through, in sequence, the small receiver **375** and large driver **274**. When the large receiver **275** is activated by the L_Inhibit signal, the small driver **374** is enabled by the S_Ebable signal, the large driver **274** is disabled by the L_Ebable signal and the small receiver **375** is inhibited by the S_Inhibit signal, data from the I/O pad **272** of the large I/O circuit **341** may pass to the I/O pad **372** of the small I/O circuit **203** through, in sequence, the large receiver **275** and small driver **374**.

Specification for Logic Drive

Various types of standard commodity logic drives, packages, package drives, devices, modules, disks or disk drives (to be abbreviated as "drive" below, that is when "drive" is mentioned below, it means and reads as "drive, package, package drive, device, module, disk or disk drive") are introduced in the following paragraphs.

I. First Type of Logic Drive

FIG. **11**A is a schematically top view showing arrangement for various chips packaged in a first type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIG. **11**A, the standard commodity logic drive **300** may be packaged with a plurality of the standard commodity FPGA IC chip **200** as illustrated in FIGS. **8**A-**8**J, one or more non-volatile memory (NVM) IC chips **250** and a dedicated control chip **260**, which are arranged in an array, wherein the dedicated control chip **260** may be surrounded by the standard commodity FPGA IC chips **200** and NVM IC chips **250**, i.e., NVM chips, and arranged between the NVM IC chips **250** and/or between the standard commodity FPGA IC chips **200**. One of the NVM IC chips **250** at a right middle side of the logic drive **300** may be arranged between two of the standard commodity FPGA IC chips **200** at right top and right bottom sides of the logic drive **300**. Some of the FPGA IC chips **200** may be arranged in a line at a top side of the logic drive **300**.

Referring to FIG. **11**A, the logic drive **300** may include multiple inter-chip interconnects **371** each extending over spaces between neighboring two of the standard commodity FPGA IC chips **200**, NVM IC chips **250** and dedicated control chip **260**. The logic drive **300** may include a plurality of the DPIIC chip **410** aligned with a cross of a vertical bundle of inter-chip interconnects **371** and a horizontal bundle of inter-chip interconnects **371**. Each of the DPIIC chips **410** is at corners of four of the standard commodity FPGA IC chips **200**, NVM IC chips **250** and dedicated control chip **260** around said each of the DPIIC chips **410**. For example, one of the DPIIC chips **410** at a left top corner of the dedicated control chip **260** may have a first minimum distance to a first one of the standard commodity FPGA IC chips **200** at a left top corner of said one of the DPIIC chips **410**, wherein the first minimum distance is the one between the right bottom corner of the first one of the standard commodity FPGA IC chips **200** and the left top corner of said one of the DPIIC chips **410**; said one of the DPIIC chips **410** may have a second minimum distance to a second one of the standard commodity FPGA IC chips **200** at a right top corner of said one of the DPIIC chips **410**, wherein the second minimum distance is the one between the left bottom corner of the second one of the standard commodity FPGA IC chips **200** and the right top corner of said one of the

DPIIC chips **410**; said one of the DPIIC chips **410** may have a third minimum distance to one of the NVM IC chips **250** at a left bottom corner of said one of the DPIIC chips **410**, wherein the third minimum distance is the one between the right top corner of said one of the NVM IC chips **250** and the left bottom corner of said one of the DPIIC chips **410**; said one of the DPIIC chips **410** may have a fourth minimum distance to the dedicated control chip **260** at a right bottom corner of said one of the DPIIC chips **410**, wherein the fourth minimum distance is the one between the left top corner of the dedicated control chip **260** and the right bottom corner of said one of the DPIIC chips **410**.

Referring to FIG. **11**A, each of the inter-chip interconnects **371** may be the programmable or fixed interconnect **361** or **364** as illustrated in FIGS. **7**A-**7**C in the sections of "Specification for Programmable Interconnect" and "Specification for Fixed Interconnect". Signal transmission may be built (1) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects **502** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**. Signal transmission may be built (1) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects **502** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**.

Referring to FIG. **11**A, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the others of the standard commodity FPGA IC chips **200**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the others of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the other of the NVM IC chips **250**.

Accordingly, referring to FIG. **11**A, a first one of the standard commodity FPGA IC chips **200** may have a first one of the programmable logic blocks **201**, as illustrated in FIG. **6**A or **6**H, to transmit its output Dout to one of the inputs A**0**-A**3** of a second one of the programmable logic blocks **201**, as illustrated in FIG. **6**A or **6**H, of a second one of the standard commodity FPGA IC chips **200** through one of the cross-point switches **379** of one of the DPIIC chips **410**. The output Dout of the first one of the programmable logic blocks **201** may be passed to said one of the inputs A**0**-A**3** of the second one of the programmable logic blocks **201** through, in sequence, (1) the programmable interconnects **361** of the intra-chip interconnects **502** of the first one of the standard commodity FPGA IC chips **200**, (2) a first group of programmable interconnects **361** of the inter-chip interconnects **371**, (3) a first group of programmable interconnects **361** of the intra-chip interconnects of said one of the DPIIC chips **410**, (4) said one of the cross-point switches **379** of said one of the DPIIC chips **410**, (5) a second group of programmable interconnects **361** of the intra-chip interconnects of said one of the DPIIC chips **410**, (6) a second group of programmable interconnects **361** of the inter-chip interconnects **371** and (7) the programmable interconnects **361** of the intra-chip interconnects **502** of the second one of the standard commodity FPGA IC chips **200**.

Alternatively, referring to FIG. **11**A, one of the standard commodity FPGA IC chips **200** may have a first one of the programmable logic blocks **201**, as illustrated in FIG. **6**A or **6**H, to transmit its output Dout to one of the inputs A**0**-A**3** of a second one of the programmable logic blocks **201**, as illustrated in FIG. **6**A or **6**H, of said one of the standard commodity FPGA IC chips **200** through one of the cross-point switches **379** of one of the DPIIC chips **410**. The output Dout of the first one of the programmable logic blocks **201** may be passed to one of the inputs A**0**-A**3** of the second one of the programmable logic blocks **201** through, in sequence, (1) a first group of programmable interconnects **361** of the intra-chip interconnects **502** of said one of the standard commodity FPGA IC chips **200**, (2) a first group of programmable interconnects **361** of the inter-chip interconnects **371**, (3) a first group of programmable interconnects **361** of the intra-chip interconnects of said one of the DPIIC chips **410**, (4) said one of the cross-point switches **379** of said one of the DPIIC chips **410**, (5) a second group of programmable interconnects **361** of the intra-chip interconnects of said one of the DPIIC chips **410**, (6) a second group of programmable interconnects **361** of the inter-chip interconnects **371** and (7) a second group of programmable interconnects **361** of the intra-chip interconnects **502** of said one of the standard commodity FPGA IC chips **200**.

Referring to FIG. **11**A, the logic drive **300** may include multiple dedicated input/output (I/O) chips **265** in a peripheral region thereof surrounding a central region thereof having the standard commodity FPGA IC chips **200**, NVM IC chips **250**, dedicated control chip **260** and DPIIC chips **410** located therein. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from one of the DPIIC chips **410** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the

inter-chip interconnects **371** may couple from one of the NVM IC chips **250** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **364** of the inter-chip interconnects **371** may couple from the dedicated control chip **260** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the dedicated input/output (I/O) chips **265** to the others of the dedicated input/output (I/O) chips **265**.

Referring to FIG. **11**A, each of the standard commodity FPGA IC chips **200** may be referred to ones as illustrated in FIGS. **8**A-**8**J, and each of the DPIIC chips **410** may be referred to ones as illustrated in FIG. **9**.

Referring to FIG. **11**A, each of the dedicated I/O chips **265** and dedicated control chip **260** may be designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Packaged in the same logic drive **300**, the semiconductor technology node or generation used in each of the dedicated I/O chip **265** and dedicated control chip **260** is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in each of the standard commodity FPGA IC chips **200** and the DPIIC chips **410**.

Referring to FIG. **11**A, transistors or semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Packaged in the same logic drive **300**, transistors or semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be different from those used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use the conventional MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET.

Referring to FIG. **11**A, each of the NVM IC chips **250** may be a NAND flash chip, in a bare-die format or in a multi-chip flash package format. Data stored in the NVM IC chips **250** of the standard commodity logic drive **300** are kept even if the logic drive **300** is powered off. Alternatively, the NVM IC chips **250** may be Non-Volatile Radom-Access-Memory (NVRAM) IC chips, in a bare-die format or in a package format. The NVRAM may be a Ferroelectnc RAM (FRAM), Magnetoresistive RAM (MRAM), or Phase-change RAM (PRAM). Each of the NVM IC chips **250** may have a standard memory density, capacity or size of greater than or equal to 64 Mb, 512 Mb, 1 Gb, 4 Gb, 16 Gb, 64 Gb, 128 Gb, 256 Gb, or 512 Gb, wherein "b" is bits. Each of the NVM IC chips **250** may be designed and fabricated using advanced NAND flash technology nodes or generations, for example, more advanced than or smaller than or equal to 45 nm, 28 nm, 20 nm, 16 nm or 10 nm, wherein the advanced NAND flash technology may comprise Single Level Cells (SLC) or multiple level cells (MLC) (for example, Double Level Cells DLC, or triple Level cells TLC), and in a 2D-NAND or a 3D NAND structure. The 3D NAND structures may comprise multiple stacked layers or levels of NAND cells, for example, greater than or equal to 4, 8, 16, 32 stacked layers or levels of NAND cells. Accordingly, the standard commodity logic drive **300** may have a standard non-volatile memory density, capacity or size of greater than or equal to 8 MB, 64 MB, 128 MB, 512 MB, 1 GB, 4 GB, 16 GB, 64 GB, 256 GB, or 512 GB, wherein "B" is bytes, each byte has 8 bits.

Referring to FIG. **11**A, packaged in the same logic drive **300**, the voltage Vcc of power supply used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be greater than or equal to 1.5V, 2.0V, 2.5V, 3V, 3.5V, 4V, or 5V, while the voltage Vcc of power supply used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may be between 0.2V and 2.5V, between 0.2V and 2V, between 0.2V and 1.5V, between 0.1V and 1V, or between 0.2V and 1V, or smaller or lower than or equal to 2.5V, 2V, 1.8V, 1.5V or 1V Packaged in the same logic drive **300**, the voltage Vcc of power supply used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use the voltage Vcc of power supply at 4V, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the voltage Vcc of power supply at 1.5V; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use the voltage Vcc of power supply at 2.5V, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the voltage Vcc of power supply at 0.75V.

Referring to FIG. **11**A, packaged in the same logic drive **300**, the gate oxide (physical) thickness of the Field-Effect-Transistors (FETs) of semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be thicker than or equal to 5 nm, 6 nm, 7.5 nm, 10 nm, 12.5 nm, or 15 nm, while the gate oxide (physical) thickness of FETs of semiconductor devices used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may be thinner than 4.5 nm, 4 nm, 3 nm or 2 nm. Packaged in the same logic drive **300**, the gate oxide (physical) thickness of FETs of the semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control chip **260** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use a gate oxide (physical) thickness of FETs of 10 nm, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use a gate oxide (physical) thickness of FETs of 3 nm; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control chip **260** may use a gate oxide (physical) thickness of FETs of 7.5 nm, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use a gate oxide (physical) thickness of FETs of 2 nm.

Referring to FIG. **11**A, each of the dedicated I/O chip(s) **165** in the multi-chip package of the standard commodity logic drive **300** may have the circuits as illustrated in FIG. **10**. Each of the dedicated I/O chip(s) **165** may arrange a plurality of the large I/O circuit **341** and I/O pad **272**, as seen in FIGS. **5**A and **10**, for the logic drive **300** to employ one or multiple (2, 3, 4, or more than 4) Universal Serial Bus

(USB) ports, one or more IEEE 1394 ports, one or more Ethernet ports, one or more HDMI ports, one or more VGA ports, one or more audio ports or serial ports, for example, RS-232 or COM (communication) ports, wireless transceiver I/Os, and/or Bluetooth transceiver I/Os, and etc. Each of the dedicated I/O chips **165** may have a plurality of the large I/O circuit **341** and I/O pad **272**, as seen in FIGS. **10**A and **15**, for the logic drive **300** to employ Serial Advanced Technology Attachment (SATA) ports, or Peripheral Components Interconnect express (PCIe) ports to communicate, connect or couple with a memory drive.

Referring to FIG. **11**A, the standard commodity FPGA IC chips **200** may have standard common features or specifications, mentioned as below: (1) the count of the programmable logic blocks (LB) **201** for each of the standard commodity FPGA IC chips **200** may be greater than or equal to 16K, 64K, 256K, 512K, 1M, 4M, 16M, 64M, 256M, 1G, or 4G; (2) the number of the inputs of each of its programmable logic blocks (LB) **201** for each of the standard commodity FPGA IC chips **200** may be greater or equal to 4, 8, 16, 32, 64, 128, or 256; (3) the voltage Vcc of power supply applied to the power pads **205** for each of the standard commodity FPGA IC chips **200** may be between 0.2V and 2.5V, between 0.2V and 2V, between 0.2V and 1.5V, between 0.1V and 1V, or between 0.2V and 1V, or, smaller or lower than or equal to 2.5V, 2V, 1.8V, 1.5V or 1V; (4) the I/O pads **372** of the standard commodity FPGA IC chips **200** may have the same layout and number, and the I/O pads **372** at the same relative location to the respective standard commodity FPGA IC chips **200** have the same function.

II. Second Type of Logic Drive

FIG. **11**B is a schematically top view showing arrangement for various chips packaged in a second type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIG. **11**B, the dedicated control chip **260** and dedicated I/O chips **265** have functions that may be combined into a single chip **266**, i.e., dedicated control and I/O chip, to perform above-mentioned functions of the dedicated control chip **260** and dedicated I/O chips **265**. The dedicated control and I/O chip **266** may include the architecture as seen in FIG. **10**. The dedicated control chip **260** as seen in FIG. **11**A may be replaced with the dedicated control and I/O chip **266** to be packaged at the place where the dedicated control chip **260** is arranged. For an element indicated by the same reference number shown in FIGS. **11**A and **11**B, the specification of the element as seen in FIG. **11**B and the process for forming the same may be referred to that of the element as illustrated in FIG. **11**A and the process for forming the same.

For interconnection, referring to FIG. **11**B, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the dedicated control and I/O chip **266**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the dedicated control and I/O chip **266**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the dedicated control and I/O chip **266** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the dedicated control and I/O chip **266** to all of the NVM IC chips **250**.

Referring to FIG. **11**B, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, a semiconductor node or generation less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Packaged in the same logic drive **300**, the semiconductor technology node or generation used in each of the dedicated I/O chip **265** and dedicated control and I/O chip **266** is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**.

Referring to FIG. **11**B, transistors or semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Packaged in the same logic drive **300**, transistors or semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use the conventional MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET.

Referring to FIG. **11**B, packaged in the same logic drive **300**, the voltage Vcc of power supply used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be greater than or equal to 1.5V, 2.0V, 2.5V, 3 V, 3.5V, 4V, or 5V, while the voltage Vcc of power supply used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may be between 0.2V and 2.5V, between 0.2V and 2V, between 0.2V and 1.5V, between 0.1V and 1V, or between 0.2V and 1V, or smaller or lower than or equal to 2.5V, 2V, 1.8V, 1.5V or 1V. Packaged in the same logic drive **300**, the voltage Vcc of power supply used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use the voltage Vcc of power supply at 4V, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the voltage Vcc of power supply at 1.5V; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use the voltage Vcc of power supply at 2.5V while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the voltage Vcc of power supply at 0.75V.

Referring to FIG. **11**B, packaged in the same logic drive **300**, the gate oxide (physical) thickness of the Field-Effect-Transistors (FETs) of semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be thicker than or equal to 5 nm, 6 nm, 7.5 nm, 10 nm, 12.5 nm, or 15 nm, while the gate oxide (physical) thickness of FETs of semiconductor devices used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may be thinner than 4.5 nm, 4 nm, 3 nm or 2 nm. Packaged in the same logic drive **300**, the gate oxide

(physical) thickness of FETs of the semiconductor devices used in each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use a gate oxide (physical) thickness of FETs of 10 nm, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use a gate oxide (physical) thickness of FETs of 3 nm; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and dedicated control and I/O chip **266** may use a gate oxide (physical) thickness of FETs of 7.5 nm, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use a gate oxide (physical) thickness of FETs of 2 nm.

III. Third Type of Logic Drive

FIG. **11**C is a schematically top view showing arrangement for various chips packaged in a third type of standard commodity logic drive in accordance with an embodiment of the present application. The structure shown in FIG. **11**C is similar to that shown in FIG. **11**A but the difference therebetween is that an Innovated ASIC or COT (abbreviated as IAC below) chip **402** may be further provided to be packaged in the logic drive **300**. For an element indicated by the same reference number shown in FIGS. **11**A and **11**C, the specification of the element as seen in FIG. **11**C and the process for forming the same may be referred to that of the element as illustrated in FIG. **11**A and the process for forming the same.

Referring to FIG. **11**C, the IAC chip **402** may be configured for Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, etc. Each of the dedicated I/O chips **265**, dedicated control chip **260** and IAC chip **402** is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Alternatively, the advanced semiconductor technology nodes or generations, such as more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm, may be used for the IAC chip **402**. Packaged in the same logic drive **300**, the semiconductor technology node or generation used in each of the dedicated I/O chips **265**, dedicated control chip **260** and IAC chip **402** is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in the IAC chip **402** may be a FINFET, a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Packaged in the same logic drive **300**, transistors or semiconductor devices used in each of the dedicated I/O chips **265**, dedicated control chip **260** and IAC chip **402** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265**, dedicated control chip **260** and IAC chip **402** may use the conventional MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265**, dedicated control chip **260** and IAC chip **402** may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET.

Since the IAC chip **402** in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing a current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm, may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation is over US $2M, US $5M, or US $10M. Implementing the same or similar innovation or application using the third type of logic drive **300** including the IAC chip **402** designed and fabricated using older or less advanced technology nodes or generations, may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing the current or conventional ASIC or COT chip, the NRE cost of developing the IAC chip **402** for the same or similar innovation or application used in the third type of logic drive **300** may be reduced by a factor of larger than 2, 5, 10, 20, or 30.

For interconnection, referring to FIG. **11**C, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the IAC chip **402**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the IAC chip **402**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the IAC chip **402** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the IAC chip **402** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the IAC chip **402** to all of the NVM IC chips **250**.

IV. Fourth Type of Logic Drive

FIG. **11**D is a schematically top view showing arrangement for various chips packaged in a fourth type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIG. **11**D, the functions of the dedicated control chip **260** and IAC chip **402** as seen in FIG. **11**C may be incorporated into a single chip **267**, i.e., dedicated control and IAC (abbreviated as DCIAC below) chip. The structure shown in FIG. **11**D is similar to that shown in FIG. **11**A but the difference therebetween is that the DCIAC chip **267** may be further provided to be packaged in the logic drive **300**. The dedicated control chip **260** as seen in FIG. **11**A may be replaced with the DCIAC chip **267** to be packaged at the place where the dedicated control chip **260** is arranged. For an element indicated by the same reference number shown in FIGS. **11**A and **11**D, the specification of the element as seen in FIG. **11**D and the process for forming the same may be referred to that of the element as illustrated in FIG. **11**A and the process for forming the same. The DCIAC chip **267** now comprises the

control circuits, Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, and etc.

Referring to FIG. **11**D, each of the dedicated I/O chips **265** and DCIAC chip **267** is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm. Alternatively, the advanced semiconductor technology nodes or generations, such as more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm, may be used for the DCIAC chip **267**. Packaged in the same logic drive **300**, the semiconductor technology node or generation used in each of the dedicated I/O chips **265** and DCIAC chip **267** is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in the DCIAC chip **267** may be a FINFET, a FINFET on Silicon-On-Insulator (FINFET **501**), a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Packaged in the same logic drive **300**, transistors or semiconductor devices used in each of the dedicated I/O chips **265** and DCIAC chip **267** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and DCIAC chip **267** may use the conventional MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET; alternatively, packaged in the same logic drive **300**, each of the dedicated I/O chips **265** and DCIAC chip **267** may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while one of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET.

Since the DCIAC chip **267** in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing a current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, more advanced than or below 30 nm, 20 nm or 10 nm, may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation is over US $2M, US $5M or US $10M. Implementing the same or similar innovation or application using the fourth type of logic drive **300** including the DCIAC chip **267** designed and fabricated using older or less advanced technology nodes or generations may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing a current or conventional ASIC or COT chip, the NRE cost of developing the DCIAC chip **267** for the same or similar innovation or application used in the fourth type of logic drive **300** may be reduced by a factor of larger than 2, 5, 10, 20 or 30.

For interconnection, referring to FIG. **11**D, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the DCIAC chip **267**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the DCIAC chip **267**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the DCIAC chip **267** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the DCIAC chip **267** to all of the NVM IC chips **250**.

V. Fifth Type of Logic Drive

FIG. **11**E is a schematically top view showing arrangement for various chips packaged in a fifth type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIG. **11**E, the functions of the dedicated control chip **260**, dedicated I/O chips **265** and IAC chip **402** as seen in FIG. **11**C may be incorporated into a single chip **268**, i.e., dedicated control, dedicated I/O, and IAC (abbreviated as DCDI/OIAC below) chip. The structure shown in FIG. **11**E is similar to that shown in FIG. **11**A but the difference therebetween is that the DCDI/OIAC chip **268** may be further provided to be packaged in the logic drive **300**. The dedicated control chip **260** as seen in FIG. **11**A may be replaced with the DCDI/OIAC chip **268** to be packaged at the place where the dedicated control chip **260** is arranged. For an element indicated by the same reference number shown in FIGS. **11**A and **11**E, the specification of the element as seen in FIG. **11**E and the process for forming the same may be referred to that of the element as illustrated in FIG. **11**A and the process for forming the same. The DCDI/OIAC chip **268** may include the architecture as seen in FIG. **10**. Further, the DCDI/OIAC chip **268** now comprises the control circuits, Intellectual Property (IP) circuits, Application Specific (AS) circuits, analog circuits, mixed-mode signal circuits, Radio-Frequency (RF) circuits, and/or transmitter, receiver, transceiver circuits, and etc.

Referring to FIG. **11**E, the DCDI/OIAC chip **268** is designed, implemented and fabricated using varieties of semiconductor technology nodes or generations, including old or matured technology nodes or generations, for example, less advanced than or equal to, or above or equal to 30 nm, 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm, 500 nm. Alternatively, the advanced semiconductor technology nodes or generations, such as more advanced than or equal to, or below or equal to 40 nm, 20 nm or 10 nm, may be used for the DCDI/OIAC chip **268**. Packaged in the same logic drive **300**, the semiconductor technology node or generation used in the DCDI/OIAC chip **268** is 1, 2, 3, 4, 5 or greater than 5 nodes or generations older, more matured or less advanced than that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in the DCDI/OIAC chip **268** may be a FINFET, a FINFET on Silicon-On-Insulator (FINFET **501**), a Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, a Partially Depleted Silicon-on-insulator (PDSOI) MOSFET or a conventional MOSFET. Packaged in the same logic drive **300**, transistors or semiconductor devices used in the DCDI/OIAC chip **268** may be different from that used in each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**; for example, packaged in the same logic drive **300**, the DCDI/OIAC chip **268** may use the conventional MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET; alternatively, pack-

aged in the same logic drive **300**, the DCDI/OIAC chip **268** may use the Fully Depleted Silicon-on-insulator (FDSOI) MOSFET, while each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may use the FINFET.

Since the DCDI/OIAC chip **268** in this aspect of disclosure may be designed and fabricated using older or less advanced technology nodes or generations, for example, less advanced than or equal to, or above or equal to 40 nm, 50 nm, 90 nm, 130 nm, 250 nm, 350 nm or 500 nm, its NRE cost is cheaper than or less than that of the current or conventional ASIC or COT chip designed and fabricated using an advanced IC technology node or generation, for example, a technology node or generation more advanced than or below 30 nm, 20 nm or 10 nm. The NRE cost for designing an current or conventional ASIC or COT chip using an advanced IC technology node or generation, for example, a technology node or generation more advanced than or below 30 nm, 20 nm or 10 nm, may be more than US $5M, US $10M, US $20M or even exceeding US $50M, or US $100M. The cost of a photo mask set for an ASIC or COT chip at the 16 nm technology node or generation is over US $2M, US $5M or US $10M. Implementing the same or similar innovation or application using the fifth type of logic drive **300** including the DCDI/OIAC chip **268** designed and fabricated using older or less advanced technology nodes or generations, may reduce NRE cost down to less than US $10M, US $7M, US $5M, US $3M or US $1M. Compared to the implementation by developing a current or conventional ASIC or COT chip, the NRE cost of developing the DCDI/OIAC chip **268** for the same or similar innovation or application used in the fifth type of logic drive **300** may be reduced by a factor of larger than 2, 5, 10, 20 or 30.

For interconnection, referring to FIG. **11**E, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the DCDI/OIAC chip **268**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the DCDI/OIAC chip **268**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the DCDI/OIAC chip **268** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the DCDI/OIAC chip **268** to all of the NVM IC chips **250**.

VI. Sixth Type of Logic Drive

FIGS. **11**F and **11**G are schematically top views showing arrangement for various chips packaged in a sixth type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIGS. **11**F and **11**G, the logic drive **300** as illustrated in FIGS. **11**A-**11**E may further include a processing and/or computing (PC) IC chip **269**, such as central processing unit (CPU) chip, graphic processing unit (GPU) chip, digital signal processing (DSP) chip, tensor processing unit (TPU) chip or application processing unit (APU) chip. The APU chip may be (1) a combination of CPU and DSP unit operating with each other, (2) a combination of CPU and GPU operating with each other, (3) a combination of GPU and DSP unit operating with each other or (4) a combination of CPU, GPU and DSP unit operating with one another. The structure shown in FIG. **11**F is similar to those shown in FIGS. **11**A, **11**B, **11**D and **11**E but the difference therebetween is that the PCIC chip **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260** for the scheme in FIG. **11**A, the dedicated control and I/O chip **266** for the scheme in FIG. **11**B, the DCIAC chip **267** for the scheme in FIG. **11**D or the DCDI/OIAC chip **268** for the scheme in FIG. **11**E. The structure shown in FIG. **11**G is similar to that shown in FIG. **11**C but the difference therebetween is that the PCIC chip **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260**. For an element indicated by the same reference number shown in FIGS. **11**A, **11**B, **11**D, **11**E and **11**F, the specification of the element as seen in FIG. **11**F and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A, **11**B, **11**D and **11**E and the process for forming the same. For an element indicated by the same reference number shown in FIGS. **11**A, **11**C and **11**G, the specification of the element as seen in FIG. **11**G and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A and **11**C and the process for forming the same.

Referring to FIGS. **11**F and **11**G, in a center region between neighboring two of the vertical bundles of inter-chip interconnects **371** and between neighboring two of the horizontal bundles of inter-chip interconnects **371** may be arranged the PCIC chip **269** and one of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** and DCDI/OIAC chip **268**. For interconnection, referring to FIGS. **11**F and **11**G, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the PCIC chip **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the PCIC chip **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the PCIC chip **269** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the PCIC chip **269** to the dedicated control chip **260**, the control and I/O chip **266**, the DCIAC chip **267** or the DCDI/OIAC chip **268**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the PCIC chip **269** to all of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the PCIC chip **269** to the IAC chip **402** as seen in FIG. **11**G. The PCIC chip **269** is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm, which may be the same as, one generation or node less advanced than or one generation or node more advanced than that used for each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in the PCIC chip **269** may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET.

VII. Seventh Type of Logic Drive

FIGS. **11**H and **11**I are schematically top views showing arrangement for various chips packaged in a seventh type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIGS. **11**H and **11**I, the logic drive **300** as illustrated in FIGS. **11**A-**11**E may further include two PCIC chips **269**, a combination of which may be two selected from a central

processing unit (CPU) chip, graphic processing unit (GPU) chip, digital signal processing (DSP) chip and tensor processing unit (TPU) chip. For example, (1) one of the two PCIC chips **269** may be a central processing unit (CPU) chip, and the other one of the two PCIC chips **269** may be a graphic processing unit (GPU) chip; (2) one of the two PCIC chips **269** may be a central processing unit (CPU) chip, and the other one of the two PCIC chips **269** may be a digital signal processing (DSP) chip; (3) one of the two PCIC chips **269** may be a central processing unit (CPU) chip, and the other one of the two PCIC chips **269** may be a tensor processing unit (TPU) chip; (4) one of the two PCIC chips **269** may be a graphic processing unit (GPU) chip, and the other one of the two PCIC chips **269** may be a digital signal processing (DSP) chip; (5) one of the two PCIC chips **269** may be a graphic processing unit (GPU) chip, and the other one of the two PCIC chips **269** may be a tensor processing unit (TPU) chip; (6) one of the two PCIC chips **269** may be a digital signal processing (DSP) chip, and the other one of the two PCIC chips **269** may be a tensor processing unit (TPU) chip. The structure shown in FIG. **11**H is similar to those shown in FIGS. **11**A, **11**B, **11**D and **11**E but the difference therebetween is that the two PCIC chips **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260** for the scheme in FIG. **11**A, the dedicated control and I/O chip **266** for the scheme in FIG. **11**B, the DCIAC chip **267** for the scheme in FIG. **11**D or the DCDI/OIAC chip **268** for the scheme in FIG. **11**E. The structure shown in FIG. **11**I is similar to that shown in FIG. **11**C but the difference therebetween is that the two PCIC chips **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260**. For an element indicated by the same reference number shown in FIGS. **11**A, **11**B, **11**D, **11**E and **11**H, the specification of the element as seen in FIG. **11**H and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A, **11**B, **11**D and **11**E and the process for forming the same. For an element indicated by the same reference number shown in FIGS. **11**A, **11**C and **11**I, the specification of the element as seen in FIG. **11**I and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A and **11**C and the process for forming the same.

Referring to FIGS. **11**H and **11**I, in a center region between neighboring two of the vertical bundles of inter-chip interconnects **371** and between neighboring two of the horizontal bundles of inter-chip interconnects **371** may be arranged the two PCIC chips **269** and one of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** and DCDI/OIAC chip **268**. For interconnection, referring to FIGS. **11**H and **11**I, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to both of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to both of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the dedicated control chip **260**, the dedicated control and I/O chip **266**, the DCIAC chip **267** or the DCDI/OIAC chip **268**. One of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the other of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the IAC chip **402** as seen in FIG. **11**G. Each of the PCIC chips **269** is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm, which may be the same as, one generation or node less advanced than or one generation or node more advanced than that used for each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in each of the PCIC chips **269** may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FD-SOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET.

VIII. Eighth Type of Logic Drive

FIGS. **11**J and **11**K are schematically top views showing arrangement for various chips packaged in an eighth type of standard commodity logic drive in accordance with an embodiment of the present application. Referring to FIGS. **11**J and **11**K, the logic drive **300** as illustrated in FIGS. **11**A-**11**E may further include three PCIC chips **269**, a combination of which may be three selected from a central processing unit (CPU) chip, graphic processing unit (GPU) chip, digital signal processing (DSP) chip or tensor processing unit (TPU) chip. For example, (1) one of the three PCIC chips **269** may be a central processing unit (CPU) chip, another one of the three PCIC chips **269** may be a graphic processing unit (GPU) chip, the other one of the three PCIC chips **269** may be a digital signal processing (DSP) chip; (2) one of the three PCIC chips **269** may be a central processing unit (CPU) chip, another one of the three PCIC chips **269** may be a graphic processing unit (GPU) chip, the other one of the three PCIC chips **269** may be a tensor processing unit (TPU) chip; (3) one of the three PCIC chips **269** may be a central processing unit (CPU) chip, another one of the three PCIC chips **269** may be a digital signal processing (DSP) chip, the other one of the three PCIC chips **269** may be a tensor processing unit (TPU) chip; (4) one of the three PCIC chips **269** may be a graphic processing unit (GPU) chip, another one of the three PCIC chips **269** may be a digital signal processing (DSP) chip, the other one of the three PCIC chips **269** may be a tensor processing unit (TPU) chip. The structure shown in FIG. **11**J is similar to those shown in FIGS. **11**A, **11**B, **11**D and **11**E but the difference therebetween is that the three PCIC chips **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260** for the scheme in FIG. **16**A, the dedicated control and I/O chip **266** for the scheme in FIG. **11**B, the DCIAC chip **267** for the scheme in FIG. **11**D or the DCDI/OIAC chip **268** for the scheme in FIG. **11**E. The structure shown in FIG. **11**K is similar to that shown in FIG. **11**C but the difference therebetween is that the three PCIC chips **269** may be further provided to be packaged in the logic drive **300** and close to the dedicated control chip **260**. For an element indicated by the same reference number shown in FIGS. **11**A, **11**B, **11**D, **11**E and **11**J, the specification of the element as seen in FIG. **11**J and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A, **11**B, **11**D and **11**E and the process for forming the same. For an element indicated by the same

reference number shown in FIGS. **11**A, **11**C and **11**K, the specification of the element as seen in FIG. **11**K and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A and **11**C and the process for forming the same.

Referring to FIGS. **11**J and **11**K, in a center region between neighboring two of the vertical bundles of inter-chip interconnects **371** and between neighboring two of the horizontal bundles of inter-chip interconnects **371** may be arranged the three PCIC chips **269** and one of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** and DCDI/OIAC chip **268**. For interconnection, referring to FIGS. **11**J and **11**K, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the dedicated control chip **260**, the dedicated control and I/O chip **266**, the DCIAC chip **267** or the DCDI/OIAC chip **268**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the other two of the PCIC chips **269**. One or more of the programmable or fixed interconnects **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the IAC chip **402** as seen in FIG. **11**G. Each of the PCIC chips **269** is designed, implemented and fabricated using an advanced semiconductor technology node or generation, for example more advanced than or equal to, or below or equal to 30 nm, 20 nm or 10 nm, which may be the same as, one generation or node less advanced than or one generation or node more advanced than that used for each of the standard commodity FPGA IC chips **200** and DPIIC chips **410**. Transistors or semiconductor devices used in each of the PCIC chips **269** may be a FIN Field-Effect-Transistor (FINFET), a FINFET on Silicon-On-Insulator (FINFET SOI), a Fully Depleted Silicon-On-Insulator (FD-SOI) MOSFET, a Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or a conventional MOSFET.

IX. Ninth Type of Logic Drive

FIG. **11**L is a schematically top view showing arrangement for various chips packaged in a ninth type of standard commodity logic drive in accordance with an embodiment of the present application. For an element indicated by the same reference number shown in FIGS. **11**A-**11**L, the specification of the element as seen in FIG. **11**L and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A-**11**K and the process for forming the same. Referring to FIG. **11**L, a ninth type of standard commodity logic drive **300** may be packaged with one or more processing and/or computing (PC) integrated circuit (IC) chips **269**, one or more standard commodity FPGA IC chips **200** as illustrated in FIGS. **8**A-**8**J, one or more non-volatile memory (NVM) IC chips **250**, one or more volatile memory (VM) integrated circuit (IC) chips **324**, one or more high speed, high bandwidth memory (HBM) IC chips **251** and a dedicated control chip **260**, which are arranged in an array, wherein the dedicated control chip **260** may be arranged in a center region surrounded by the PCIC chips **269**, standard commodity FPGA IC chips **200**, NVM IC chips **250** and VMIC chips **324**. The combination for the PCIC chips **269** may comprise: (1) multiple GPU chips, for example 2, 3, 4 or more than 4 GPU chips, (2) one or more CPU chips and/or one or more GPU chips, (3) one or more CPU chips and/or one or more DSP chips, (4) one or more CPU chips, one or more GPU chips and/or one or more DSP chips, (5) one or more CPU chips and/or one or more TPU chips, or (6) one or more CPU chips, one or more DSP chips and/or one or more TPU chips. Each of the HBM IC chips **251** may be a high speed, high bandwidth, wide bitwidth DRAM IC chip, high speed, high bandwidth, wide bitwidth cache SRAM chip, high speed, high bandwidth, wide bitwidth NVM chip, high speed, high bandwidth, wide bitwidth magnetoresistive random-access-memory (MRAM) chip or high speed, high bandwidth, wide bitwidth resistive random-access-memory (RRAM) chip. The PCIC chips **269** and standard commodity FPGA IC chips **200** may operate with the HBM IC chips **251** for high speed, high bandwidth, wide bitwidth parallel processing and/or parallel computing.

Referring to FIG. **11**L, the logic drive **300** may include the inter-chip interconnects **371** each extending over spaces between neighboring two of the standard commodity FPGA IC chip **200**, NVM IC chip **250**, VMIC chip **324**, dedicated control chip **260**, PCIC chips **269** and HBMIC chip **251**. The logic drive **300** may include a plurality of the DPIIC chip **410** aligned with a cross of a vertical bundle of inter-chip interconnects **371** and a horizontal bundle of inter-chip interconnects **371**. Each of the DPIIC chips **410** is at corners of four of the standard commodity FPGA IC chip **200**, NVM IC chip **250**, VMIC chip **324**, dedicated control chip **260**, PCIC chips **269** and HBMIC chip **251** around said each of the DPIIC chips **410**. Each of the inter-chip interconnects **371** may be the programmable or fixed interconnect **361** or **364** as mentioned above in the sections of "Specification for Programmable Interconnect" and "Specification for Fixed Interconnect". Signal transmission may be built (1) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects **371** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**. Signal transmission may be built (1) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects **502** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**.

Referring to FIG. **11**L, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to all of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the

inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to the NVM IC chip **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to the VMIC chip **324**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to all of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to the HBMIC chip **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the VMIC chip **324**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the PCIC chips **269**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the HBMIC chip **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the others of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the HBMIC chip **251** and the communication between said each of the PCIC chips **269** and the HBMIC chip **251** may have a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the NVM IC chip **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to the VMIC chip **324**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the NVM IC chip **250** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the NVM IC chip **250** to the VMIC chip **324**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the NVM IC chip **250** to the HBMIC chip **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the VMIC chip **324** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the VMIC chip **324** to the HBMIC chip **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the HBMIC chip **251** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all the others of the PCIC chips **269**.

Referring to FIG. **11**L, the logic drive **300** may include multiple dedicated input/output (I/O) chips **265** in a peripheral region thereof surrounding a central region thereof having the standard commodity FPGA IC chip **200**, NVM IC chip **250**, VMIC chip **321**, dedicated control chip **260**, PCIC chips **269**, HBMIC chip **251** and DPIIC chips **410** located therein. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the standard commodity FPGA IC chip **200** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the NVM IC chip **250** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the VMIC chip **321** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the dedicated control chip **260** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the PCIC chips **269** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the HBMIC chip **251** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the dedicated input/output (I/O) chips **265** to the others of the dedicated input/output (I/O) chips **265**.

Referring to FIG. **11**L, the standard commodity FPGA IC chip **200** may be referred to one as illustrated in FIGS. **8**A-**8**J, and each of the DPIIC chips **410** may be referred to one as illustrated in FIG. **9**. The specification of the commodity standard FPGA IC chip **200**, DPIIC chips **410**, dedicated I/O chips **265**, NVM IC chips **250** and dedicated control chip **260** may be referred to that as illustrated in FIG. **11**A.

For example, referring to FIG. **11**L, all of the PCIC chips **269** in the logic drive **300** may be GPU chips, for example 2, 3, 4 or more than 4 GPU chips and the HBM IC chip **251** in the logic drive **300** may be a high speed, high bandwidth, wide bitwidth DRAM IC chip, high speed, high bandwidth, wide bitwidth cache SRAM chip, magnetoresistive random-access-memory (MRAM) chip or resistive random-access-memory (RRAM) chip. The communication between one of the PCIC chips **269**, i.e., GPU chips, and the HBM IC chip **251** may have a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

For example, referring to FIG. **11**L, all of the PCIC chips **269** in the logic drive **300** may be TPU chips, for example 2, 3, 4 or more than 4 TPU chips and the HBM IC chip **251** in the logic drive **300** may be a high speed, high bandwidth, wide bitwidth DRAM IC chip, high speed, high bandwidth, wide bitwidth cache SRAM chip, magnetoresistive random-access-memory (MRAM) chip or resistive random-access-memory (RRAM) chip. The communication between one of the PCIC chips **269**, i.e., TPU chips, and the HBM IC chip

251 may have a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

X. Tenth Type of Logic Drive

FIG. 11M is a schematically top view showing arrangement for various chips packaged in a tenth type of standard commodity logic drive in accordance with an embodiment of the present application. For an element indicated by the same reference number shown in FIGS. 11A-11M, the specification of the element as seen in FIG. 11M and the process for forming the same may be referred to that of the element as illustrated in FIGS. 11A-11L and the process for forming the same. Referring to FIG. 11M, the logic drive 300 may be packaged with multiple GPU chips 269*a* and a CPU chip 269*b* for the PCIC chips 269 as above mentioned. Further, the logic drive 300 may be packaged with multiple HBMIC chips 251 each arranged next to one of the GPU chips 269*a* for communication with said one of the GPU chips 269*a* in a high speed, high bandwidth and wide bitwidth. Each of the HBM IC chips 251 in the logic drive 300 may be a high speed, high bandwidth, wide bitwidth DRAM IC chip, high speed, high bandwidth, wide bitwidth cache SRAM chip, high speed, high bandwidth, wide bitwidth magnetoresistive random-access-memory (MRAM) chip or high speed, high bandwidth, wide bitwidth resistive random-access-memory (RRAM) chip. The logic drive 300 may be further packaged with a plurality of the standard commodity FPGA IC chip 200 and one or more of the NVM IC chips 250 configured to store the resulting values or programming codes in a non-volatile manner for programming the programmable logic blocks 201 or cross-point switches 379 of the standard commodity FPGA IC chips 200 and for programming the cross-point switches 379 of the DPIIC chips 410, as illustrated in FIGS. 6A-9. The CPU chip 269*b*, dedicated control chip 260, standard commodity FPGA IC chips 200, GPU chips 269*a*, NVM IC chips 250 and HBMIC chips 251 may be arranged in an array, wherein the CPU chip 269*b* and dedicated control chip 260 may be arranged in a center region surrounded by a periphery region having the standard commodity FPGA IC chips 200, GPU chips 269*a*, NVM IC chips 250 and HBMIC chips 251 mounted thereto.

Referring to FIG. 11M, the logic drive 300 may include the inter-chip interconnects 371 each extending over spaces between neighboring two of the standard commodity FPGA IC chips 200, NVM IC chips 250, dedicated control chip 260, GPU chips 269*a*, CPU chip 269*b* and HBMIC chips 251. The logic drive 300 may include a plurality of the DPIIC chip 410 aligned with a cross of a vertical bundle of inter-chip interconnects 371 and a horizontal bundle of inter-chip interconnects 371. Each of the DPIIC chips 410 is at corners of four of the standard commodity FPGA IC chips 200, NVM IC chips 250, dedicated control chip 260, GPU chips 269*a*, CPU chip 269*b* and HBMIC chips 251 around said each of the DPIIC chips 410. Each of the inter-chip interconnects 371 may be the programmable or fixed interconnect 361 or 364 as mentioned above in the sections of "Specification for Programmable Interconnect" and "Specification for Fixed Interconnect". Signal transmission may be built (1) between one of the programmable interconnects 361 of the inter-chip interconnects 371 and one of the programmable interconnects 361 of the intra-chip interconnects 371 of one of the standard commodity FPGA IC chips 200 via one of the small input/output (I/O) circuits 203 of said one of the standard commodity FPGA IC chips 200 or (2) between one of the programmable interconnects 361 of the inter-chip interconnects 371 and one of the programmable interconnects 361 of the intra-chip interconnects of one of the DPIIC chips 410 via one of the small input/output (I/O) circuits 203 of said one of the DPIIC chips 410. Signal transmission may be built (1) between one of the fixed interconnects 364 of the inter-chip interconnects 371 and one of the fixed interconnects 364 of the intra-chip interconnects 502 of one of the standard commodity FPGA IC chips 200 via one of the small input/output (I/O) circuits 203 of said one of the standard commodity FPGA IC chips 200 or (2) between one of the fixed interconnects 364 of the inter-chip interconnects 371 and one of the fixed interconnects 364 of the intra-chip interconnects of one of the DPIIC chips 410 via one of the small input/output (I/O) circuits 203 of said one of the DPIIC chips 410.

Referring to FIG. 11M, one or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to all of the DPIIC chips 410. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to the dedicated control chip 260. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to both of the NVM IC chips 250. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to all of the GPU chips 269*a*. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to the CPU chip 269*b*. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to all of the HBMIC chips 251. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the standard commodity FPGA IC chips 200 to the other of the standard commodity FPGA IC chips 200. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to the dedicated control chip 260. One or more the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to both of the NVM IC chips 250. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to all of the GPU chips 269*a*. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to the CPU chip 269*b*. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to all of the HBMIC chips 251. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from each of the DPIIC chips 410 to the others of the DPIIC chips 410. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from the CPU chip 269*b* to all of the GPU chips 269*a*. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from the CPU chip 2696 to both of the NVM IC chips 250. One or more of the programmable or fixed interconnects 361 or 364 of the inter-chip interconnects 371 may couple from the CPU chip 269*b* to all of the HBMIC chips 251. One or more of the programmable or fixed interconnects 361 or 364 of the

inter-chip interconnects **371** may couple from one of the GPU chips **269***a* to one of the HBMIC chips **251** and the communication between said one of the GPU chips **269***a* and said one of the HBM IC chips **251** may have a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the GPU chips **269***a* to both of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the GPU chips **269***a* to the others of the GPU chips **269***a*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the GPU chips **269***a* to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **269***b* to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to all of the HBMIC chips **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the other of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to the others of the HBMIC chips **251**.

Referring to FIG. **11**M, the logic drive **300** may include multiple dedicated input/output (I/O) chips **265** in a peripheral region thereof surrounding a central region thereof having the standard commodity FPGA IC chips **200**, NVM IC chips **250**, dedicated control chip **260**, GPU chips **269***a*, CPU chip **2696**, HBMIC chips **251** and DPIIC chips **410** located therein. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the dedicated control chip **260** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the GPU chips **269***a* to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **269***b* to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to all of the dedicated input/output (I/O) chips **265**.

Accordingly, in the tenth type of logic drive **300**, the GPU chips **269***a* may operate with the HBM IC chips **251** for high speed, high bandwidth, wide bitwidth parallel processing and/or computing. Referring to FIG. **11**M, each of the standard commodity FPGA IC chips **200** may be referred to one as illustrated in FIGS. **8**A-**8**J, and each of the DPIIC chips **410** may be referred to one as illustrated in FIG. **9**. The specification of the commodity standard FPGA IC chips **200**, DPIIC chips **410**, dedicated I/O chips **265**, NVM IC chips **250** and dedicated control chip **260** may be referred to that as illustrated in FIG. **11**A.

XI. Eleventh Type of Logic Drive

FIG. **11**N is a schematically top view showing arrangement for various chips packaged in an eleventh type of standard commodity logic drive in accordance with an embodiment of the present application. For an element indicated by the same reference number shown in FIGS. **11**A-**11**N, the specification of the element as seen in FIG. **11**N and the process for forming the same may be referred to that of the element as illustrated in FIGS. **11**A-**11**M and the process for forming the same. Referring to FIG. **11**M, the logic drive **300** may be packaged with multiple TPU chips **269***c* and a CPU chip **269***b* for the PCIC chips **269** as above mentioned. Further, the logic drive **300** may be packaged with multiple HBMIC chips **251** each arranged next to one of the TPU chips **269***c* for communication with said one of the TPU chips **269***c* in a high speed, high bandwidth and wide bitwidth. Each of the HBM IC chips **251** in the logic drive **300** may be a high speed, high bandwidth, wide bitwidth DRAM IC chip, high speed, high bandwidth, wide bitwidth cache SRAM chip, high speed, high bandwidth, wide bitwidth magnetoresistive random-access-memory (MRAM) chip or high speed, high bandwidth, wide bitwidth resistive random-access-memory (RRAM) chip. The logic drive **300** may be further packaged with a plurality of the standard commodity FPGA IC chip **200** and one or more of the NVM IC chips **250** configured to store the resulting values or programming codes in a non-volatile manner for programming the programmable logic blocks **201** or cross-point switches **379** of the standard commodity FPGA IC chips **200** and for programming the cross-point switches **379** of the DPIIC chips **410**, as illustrated in FIGS. **6**A-**9**. The CPU chip **269***b*, dedicated control chip **260**, standard commodity FPGA IC chips **200**, TPU chips **269***c*, NVM IC chips **250** and HBMIC chips **251** may be arranged in an array, wherein the CPU chip **2696** and dedicated control chip **260** may be arranged in a center region surrounded by a periphery region having the standard commodity FPGA IC chips **200**, TPU chips **269***c*, NVM IC chips **250** and HBMIC chips **251** mounted thereto.

Referring to FIG. **11**N, the logic drive **300** may include the inter-chip interconnects **371** each extending over spaces between neighboring two of the standard commodity FPGA IC chips **200**, NVM IC chips **250**, dedicated control chip **260**, TPU chips **269***c*, CPU chip **269***b* and HBMIC chips **251**. The logic drive **300** may include a plurality of the DPIIC chip **410** aligned with a cross of a vertical bundle of inter-chip interconnects **371** and a horizontal bundle of inter-chip interconnects **371**. Each of the DPIIC chips **410** is at corners of four of the standard commodity FPGA IC chips **200**, NVM IC chips **250**, dedicated control chip **260**, TPU chips **269***c*, CPU chip **2696** and HBMIC chips **251** around said each of the DPIIC chips **410**. Each of the inter-chip interconnects **371** may be the programmable or fixed interconnect **361** or **364** as mentioned above in the sections of "Specification for Programmable Interconnect" and "Specification for Fixed Interconnect". Signal transmission may be

built (1) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects **371** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the programmable interconnects **361** of the inter-chip interconnects **371** and one of the programmable interconnects **361** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**. Signal transmission may be built (1) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects **502** of one of the standard commodity FPGA IC chips **200** via one of the small input/output (I/O) circuits **203** of said one of the standard commodity FPGA IC chips **200** or (2) between one of the fixed interconnects **364** of the inter-chip interconnects **371** and one of the fixed interconnects **364** of the intra-chip interconnects of one of the DPIIC chips **410** via one of the small input/output (I/O) circuits **203** of said one of the DPIIC chips **410**.

Referring to FIG. **11**N, one or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to both of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the TPU chips **269***c*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the CPU chip **269***b*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the HBMIC chips **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to the other of the standard commodity FPGA IC chips **200**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the dedicated control chip **260**. One or more the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to both of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the TPU chips **269***c*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the CPU chip **269***b*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the HBMIC chips **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to the others of the DPIIC chips **410**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **2696** to all of the TPU chips **269***c*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **2696** to both of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **269***b* to all of the HBMIC chips **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from one of the TPU chips **269***c* to one of the HBMIC chips **251** and the communication between said one of the TPU chips **269***c* and said one of the HBM IC chips **251** may have a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the TPU chips **269***c* to both of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the TPU chips **269***c* to the others of the TPU chips **269***c*. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the TPU chips **269***c* to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **2696** to the dedicated control chip **260**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to all of the HBMIC chips **251**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to the other of the NVM IC chips **250**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to the others of the HBMIC chips **251**.

Referring to FIG. **11**N, the logic drive **300** may include multiple dedicated input/output (I/O) chips **265** in a peripheral region thereof surrounding a central region thereof having the standard commodity FPGA IC chips **200**, NVM IC chips **250**, dedicated control chip **260**, TPU chips **269***c*, CPU chip **269***b*, HBMIC chips **251** and DPIIC chips **410** located therein. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the standard commodity FPGA IC chips **200** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the DPIIC chips **410** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the NVM IC chips **250** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the dedicated control chip **260** to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the TPU chips **269***c* to all of the dedicated input/output (I/O)

chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from the CPU chip **269***b* to all of the dedicated input/output (I/O) chips **265**. One or more of the programmable or fixed interconnects **361** or **364** of the inter-chip interconnects **371** may couple from each of the HBMIC chips **251** to all of the dedicated input/output (I/O) chips **265**.

Accordingly, in the eleventh type of logic drive **300**, the TPU chips **269***c* may operate with the HBM IC chips **251** for high speed, high bandwidth, wide bitwidth parallel processing and/or computing. Referring to FIG. **11**N, each of the standard commodity FPGA IC chips **200** may be referred to one as illustrated in FIGS. **8**A-**8**J, and each of the DPIIC chips **410** may be referred to one as illustrated in FIG. **9**. The specification of the commodity standard FPGA IC chips **200**, DPIIC chips **410**, dedicated I/O chips **265**, NVM IC chips **250** and dedicated control chip **260** may be referred to that as illustrated in FIG. **11**A.

Accordingly, referring to FIGS. **11**F-**11**N, once the programmable interconnects **361** of the FPGA IC chips **200** and DPIIC chips **410** are programmed, the programmed programmable interconnects **361** together with the fixed interconnects **364** of the standard commodity FPGA IC chips **200** and DPIIC chips **410** may provide some specific functions for some given applications. The standard commodity FPGA IC chip or chips **200** may operate together with the PCIC chip or chips **269**, e.g., GPU chip(s), CPU chip(s), TPU chip(s) or DSP chip(s), in the same logic drive **300** to provide powerful functions and operations in applications, for example, Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), driverless car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

Interconnection for Logic Drive

FIGS. **12**A-**12**C are various block diagrams showing various connections between chips in a logic drive in accordance with an embodiment of the present application. Referring to FIGS. **12**A-**12**C, a block **250** may be a combination of the NVM IC chips **250** in the logic drive **300** illustrated in FIGS. **11**A-**11**N; two blocks **200** may be two different groups of the standard commodity FPGA IC chips **200** in the logic drive **300** illustrated in FIGS. **11**A-**11**N; a block **410** may be a combination of the DPIIC chips **410** in the logic drive **300** illustrated in FIGS. **11**A-**11**N; a block **265** may be a combination of the dedicated I/O chips **265** in the logic drive **300** illustrated in FIGS. **11**A-**11**N; a block **360** may be the dedicated control chip **260**, the dedicated control and I/O chip **266**, the DCIAC chip **267** or DCDI/OIAC chip **268** in the logic drive **300** illustrated in FIGS. **11**A-**11**N.

Referring to FIGS. **11**A-**11**N and **12**A-**12**C, each of the NVM IC chips **250** may reload resulting values or first programming codes from the external circuitry **271** outside the logic drive **300** such that each of the resulting values or first programming codes may pass from said each of the NVM IC chips **250** to one of the memory cells **490** of the standard commodity FPGA IC chips **200** via the fixed interconnects **364** of the inter-chip interconnects **371** and the fixed interconnects **364** of the intra-chip interconnects **502** of the standard commodity FPGA IC chips **200** for programing one of the programmable logic blocks **201** of the standard commodity FPGA IC chips **200** as illustrated in FIG. **6**A or **6**H. Each of the NVM IC chips **250** may reload second programming codes from the external circuitry **271** outside the logic drive **300** such that each of the second programming codes may pass from said each of the NVM IC chips **250** to one of the memory cells **362** of the standard commodity FPGA IC chips **200** via the fixed interconnects **364** of the inter-chip interconnects **371** and the fixed interconnects **364** of the intra-chip interconnects **502** of the standard commodity FPGA IC chips **200** for programing one of the pass/no-pass switches **258** or cross-point switches **379** of the standard commodity FPGA IC chips **200** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C. Each of the NVM IC chips **250** may reload third programming codes from the external circuitry **271** outside the logic drive **300** such that each of the third programming codes may pass from said each of the NVM IC chips **250** to one of the memory cells **362** of the DPIIC chips **410** via the fixed interconnects **364** of the inter-chip interconnects **371** and the fixed interconnects **364** of the intra-chip interconnects of the DPIIC chips **410** for programing one of the pass/no-pass switches **258** or cross-point switches **379** of the DPIIC chips **410** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C. The external circuitry **271** may not be allowed to reload the resulting values and first, second and third programming codes from any of the NVM IC chips **250** in the logic drive **300**. Alternatively, the external circuitry **271** may be allowed to reload the resulting values and first, second and third programming codes from one or all of the NVM IC chips **250** in the logic drive **300**.

I. First Type of Interconnection for Logic Drive

Referring to FIGS. **11**A-**11**N and **12**A, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all the others of the dedicated I/O chips **265**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all the others of the dedicated I/O chips **265**.

Referring to FIGS. **11**A-**11**N and **12**A, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all the others of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects

371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all the others of the DPIIC chips 410.

Referring to FIGS. 11A-11N and 12A, one or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the standard commodity FPGA IC chips 200 to one or more of the small I/O circuits 203 of all the others of the standard commodity FPGA IC chips 200. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the standard commodity FPGA IC chips 200 to one or more of the small I/O circuits 203 of all the others of the standard commodity FPGA IC chips 200.

Referring to FIGS. 11A-11N and 12A, one or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to one or more of the small I/O circuits 203 of all of the DPIIC chips 410. One more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to one or more of the small I/O circuits 203 of all of the DPIIC chips 410. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the large I/O circuits 341 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to one or more of the large I/O circuits 341 of all of the NVM IC chips 250. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the large I/O circuits 341 of all of the dedicated I/O chips 265. One or more of the large I/O circuits 341 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 may couple to the external circuitry 271 outside the logic drive 300.

Referring to FIGS. 11A-11N and 12A, one or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the large I/O circuits 341 of each of the dedicated I/O chips 265 to one or more of the large I/O circuits 341 of all of the NVM IC chips 250. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the large I/O circuits 341 of each of the dedicated I/O chips 265 to one or more of the large I/O circuits 341 of the others of the dedicated I/O chips 265. One or more of the large I/O circuits 341 of each of the dedicated I/O chips 265 may couple to the external circuitry 271 outside the logic drive 300.

Referring to FIGS. 11A-11N and 12A, one or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the large I/O circuits 341 of each of the NVM IC chips 250 to one or more of the large I/O circuits 341 of the others of the NVM IC chips 250. One or more of the large I/O circuits 341 of each of the NVM IC chips 250 may couple to the external circuitry 271 outside the logic drive 300. In this case, each of the NVM IC chips 250 in the logic drive 300 may not be provided with any I/O circuit having input or output capacitance, driving capability or loading smaller than 2 pF, but provided with the large I/O circuits 341 as seen in FIG. 5A to perform the above-mentioned connection. Each of the NVM IC chips 250 may pass data to all of the standard commodity FPGA IC chips 200 through one or more of the dedicated I/O chips 265; each of the NVM IC chips 250 may pass data to all of the DPIIC chips 410 through one or more of the dedicated I/O chips 265; each of the NVM IC chips 250 may have no freedom to pass any data to any of the standard commodity FPGA IC chips 200 not through any of the dedicated I/O chips 265; each of the NVM IC chips 250 may have no freedom to pass any data to any of the DPIIC chips 410 not through any of the dedicated I/O chips 265.

(1) Interconnection for Programming Memory Cells

Referring to FIGS. 11A-11N and 12A, in an aspect, the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 may generate a control command to one of its large I/O circuits 341 to drive the control command to a first one of the large I/O circuits 341 of one of the NVM IC chips 250 via one or more of the fixed interconnects 364 of the inter-chip interconnects 371. For said one of the NVM IC chips 250, the control command is driven by the first one of its large I/O circuits 341 to its internal circuits to command its internal circuits to pass the third programming code to a second one of its large I/O circuits 341; the second one of its large I/O circuits 341 may drive the third programming code to one of the large I/O circuits 341 of one of the dedicated I/O chips 265 via one or more of the fixed interconnects 364 of the inter-chip interconnects 371. For said one of the dedicated I/O chips 265, said one of its large I/O circuits may drive the third programming code to one of its small I/O circuits 203; said one of its small I/O circuits 203 may drive the third programming code to one of the small I/O circuits 203 of one of the DPIIC chips 410 via one or more of the fixed interconnects 364 of the inter-chip interconnects 371. For said one of the DPIIC chips 410, said one of its small I/O circuits 203 may drive the third programming code to one of its memory cells 362 in one of its memory-array blocks 423 as seen in FIG. 9 via one or more of the fixed interconnects 364 of its intra-chip interconnects; the third programming code may be stored in said one of its memory cells 362 for programming one of its pass/no-pass switches 258 and/or cross-point switches 379 as illustrated in FIGS. 2A-2F, 3A-3D and 7A-7C.

Alternatively, referring to FIGS. 11A-11N and 12A, the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 may generate a control command to one of its large I/O circuits 341 to drive the control command to a first one of the large I/O circuits 341 of one of the NVM

IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its large I/O circuits **341** to its internal circuits to command its internal circuits to pass the second programming code to a second one of its large I/O circuits **341**; the second one of its large I/O circuits **341** may drive the second programming code to one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its large I/O circuits may drive the second programming code to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the second programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the second programming code to one of its memory cells **362** via one or more of the fixed interconnects **364** of its intra-chip interconnects **502**; the second programming code may be stored in said one of its memory cells **362** for programming one of its pass/no-pass switches **258** and/or cross-point switches **379** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C.

Alternatively, referring to FIGS. **11**A-**11**N and **12**A, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its large I/O circuits **341** to drive the control command to a first one of the large I/O circuits **341** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its large I/O circuits **341** to its internal circuits to command its internal circuits to pass the resulting value or first programming code to a second one of its large I/O circuits **341**; the second one of its large I/O circuits **341** may drive the resulting value or first programming code to one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its large I/O circuits may drive the resulting value or first programming code to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the resulting value or first programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the resulting value or first programming code to one of its memory cells **490** via one of its fixed interconnects **364**; the resulting value or first programming code may be stored in said one of its memory cells **490** for programming one of its programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H.

(2) Interconnection for Operation

Referring to FIGS. **11**A-**11**N and **12**A, in an aspect, one of the dedicated I/O chips **265** may have one of its large I/O circuits **341** to drive a signal from the external circuitry **271** outside the logic drive **300** to one of its small I/O circuits **203**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the signal to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the dedicated DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** via a first one of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the signal from the first one of the programmable interconnects **361** of its intra-chip interconnects to a second one of the programmable interconnects **361** of its intro-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the signal to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intro-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the signal to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intro-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of the inputs A**0**-A**3** of one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H.

Referring to FIGS. **11**A-**11**N and **12**A, in another aspect, for a first one of the standard commodity FPGA IC chips **200**, one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H may generate an output Dout to be passed to one of its cross-point switches **379** via a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502**; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the output Dout to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the output Dout to one of the small I/O circuits **203** of a second one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For the second one of the FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects

502 to be passed to one of the inputs A0-A3 of one of its programmable logic blocks (LB) 201 as seen in FIG. 6A or 6H.

Referring to FIGS. 11A-11N and 12A, in another aspect, for one of the standard commodity FPGA IC chips 200, one of its programmable logic blocks (LB) 201 as seen in FIG. 6A or 6H may generate an output Dout to be passed to one of its cross-point switches 379 via a first group of the programmable interconnects 361 and by-pass interconnects 279 of its intra-chip interconnects 502; said one of its cross-point switches 379 may switch the output Dout to pass from the first group of the programmable interconnects 361 and by-pass interconnects 279 of its intra-chip interconnects 502 to a second group of the programmable interconnects 361 and by-pass interconnects 279 of its intra-chip interconnects 502 to be passed to one of its small I/O circuits 203; said one of its small I/O circuits 203 may drive the output Dout to a first one of the small I/O circuits 203 of one of the DPIIC chips 410 via one or more of the programmable interconnects 361 of the inter-chip interconnects 371. For said one of the DPIIC chips 410, the first one of its small I/O circuits 203 may drive the output Dout to one of its cross-point switches 379 via a first group of the programmable interconnects 361 of its intra-chip interconnects; said one of its cross-point switches 379 may switch the output Dout to pass from the first group of the programmable interconnects 361 of its intra-chip interconnects to a second group of the programmable interconnects 361 of its intra-chip interconnects to be passed to a second one of its small I/O circuits 203; the second one of its small I/O circuits 203 may drive the output Dout to one of the small I/O circuits 203 of one of the dedicated I/O chips 265 via one or more of the programmable interconnects 361 of the inter-chip interconnects 371. For said one of the dedicated I/O chips 265, said one of its small I/O circuits 203 may drive the output Dout to one of its large I/O circuits 341 to be passed to the external circuitry 271 outside the logic drive 300.

(3) Interconnection for Controlling

Referring to FIGS. 11A-11N and 12A, for the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360, one of its large I/O circuits 341 may receive or drive a control command from or to the external circuitry 271 outside the logic drive 300.

Alternatively, referring to FIGS. 11A-11N and 12A, one of the dedicated I/O chips 265 may have a first one of its large I/O circuits 341 to drive a control command from the external circuitry 271 outside the logic drive 300 to a second one of its large I/O circuits 341. For said one of the dedicated I/O chips 265, the second one of its large I/O circuits 341 may drive the control command to one of the large I/O circuits 341 of the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 via one or more of the fixed interconnects 364 of the inter-chip interconnects 371.

Alternatively, referring to FIGS. 11A-11N and 12A, for the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360, one of its large I/O circuits 341 may drive a control command to a first one of the large I/O circuits 341 of one of the dedicated I/O chips 265 via one or more of the fixed interconnects 364 of the inter-chip interconnects 371. For said one of the dedicated I/O chips 265, the first one of its large I/O circuits 341 may drive the control command to a second one of its large I/O circuits 341 to be passed to the external circuitry 271 outside the logic drive 300.

Thereby, referring to FIGS. 11A-11N and 12A, a control command may be provided from the external circuitry 271 outside the logic drive 300 to the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 or from the dedicated control chip 260, dedicated control and I/O chip 266, DCIAC chip 267 or DCDI/OIAC chip 268 in the control block 360 to the external circuitry 271 outside the logic drive 300.

II. Second Type of Interconnection for Logic Drive

Referring to FIGS. 11A-11N and 12B, one or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all of the DPIIC chips 410. One or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all the others of the dedicated I/O chips 265. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all of the DPIIC chips 410. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the dedicated I/O chips 265 to one or more of the small I/O circuits 203 of all the others of the dedicated I/O chips 265.

Referring to FIGS. 11A-11N and 12B, one or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all the others of the DPIIC chips 410. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all of the standard commodity FPGA IC chips 200. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the DPIIC chips 410 to one or more of the small I/O circuits 203 of all the others of the DPIIC chips 410.

Referring to FIGS. 11A-11N and 12B, one or more of the programmable interconnects 361 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the standard commodity FPGA IC chips 200 to one or more of the small I/O circuits 203 of all the others of the standard commodity FPGA IC chips 200. One or more of the fixed interconnects 364 of the inter-chip interconnects 371 may couple one or more of the small I/O circuits 203 of each of the standard commodity FPGA IC chips 200 to one

or more of the small I/O circuits **203** of all the others of the standard commodity FPGA IC chips **200**.

Referring to FIGS. **11**A-**11**N and **12**B, one or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the large I/O circuits **341** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the large I/O circuits **341** of all of the dedicated I/O chips **265**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the large I/O circuits **341** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the large I/O circuits **341** of all of the NVM IC chips **250**. One or more of the large I/O circuits **341** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may couple to the external circuitry **271** outside the logic drive **300**.

Referring to FIGS. **11**A-**11**N and **12**B, one or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the large I/O circuits **341** of each of the NVM IC chips **250** to one or more of the large I/O circuits **341** of all of the dedicated I/O chips **265**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the large I/O circuits **341** of each of the NVM IC chips **250** to one or more of the large I/O circuits **341** of all the others of the NVM IC chips **250**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the large I/O circuits **341** of each of the dedicated I/O chips **265** to one or more of the large I/O circuits **341** of all the others of the dedicated I/O chips **265**. One or more of the large I/O circuits **341** of each of the NVM IC chips **250** may couple to the external circuitry **271** outside the logic drive **300**. One or more of the large I/O circuits **341** of each of the dedicated I/O chips **265** may couple to the external circuitry **271** outside the logic drive **300**.

Referring to FIGS. **11**A-**11**N and **12**B, in this case, each of the NVM IC chips **250** in the logic drive **300** may not be provided with any I/O circuit having input or output capacitance, driving capability or loading smaller than 2 pF, but provided with the large I/O circuits **341** as seen in FIG. **5**A to perform the above-mentioned connection. Each of the NVM IC chips **250** may pass data to all of the standard commodity FPGA IC chips **200** through one or more of the dedicated I/O chips **265**; each of the NVM IC chips **250** may pass data to all of the DPIIC chips **410** through one or more of the dedicated I/O chips **265**; each of the NVM IC chips **250** may have no freedom to pass any data to any of the standard commodity FPGA IC chips **200** not through any of the dedicated I/O chips **265**; each of the NVM IC chips **250** may have no freedom to pass any data to any of the DPIIC chips **410** not through any of the dedicated I/O chips **265**. In this case, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may not be provided with any I/O circuit having input or output capacitance, driving capability or loading smaller than 2 pF, but provided with the large I/O circuits **341** as seen in FIG. **5**A to perform the above-mentioned connection. The dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may pass control commands or other signals to all of the standard commodity FPGA IC chips **200** through one or more of the dedicated I/O chips **265**; the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may pass control commands or other signals to all of the DPIIC chips **410** through one or more of the dedicated I/O chips **265**; the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may have no freedom to pass any control command or other signal to any of the standard commodity FPGA IC chips **200** not through any of the dedicated I/O chips **265**; the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may have no freedom to pass any control command or other signal to any of the DPIIC chips **410** not through any of the dedicated I/O chips **265**.

(1) Interconnection for Programming Memory Cells

Referring to FIGS. **11**A-**11**N and **12**B, in an aspect, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its large I/O circuits **341** to drive the control command to a first one of the large I/O circuits **341** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its large I/O circuits **341** to its internal circuits to command its internal circuits to pass the third programming code to a second one of its large I/O circuits **341**; the second one of its large I/O circuits **341** may drive the third programming code to one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its large I/O circuits may drive the third programming code to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the third programming code to one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, said one of its small I/O circuits **203** may drive the third programming code to one of its memory cells **362** in one of its memory-array blocks **423** as seen in FIG. **9** via one or more of the fixed interconnects **364** of its intra-chip interconnects; the third programming code may be stored in said one of its memory cells **362** for programming one of its pass/no-pass switches **258** and/or cross-point switches **379** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C.

Alternatively, referring to FIGS. **11**A-**11**N and **12**B, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its large I/O circuits **341** to drive the control command to a first one of the large I/O circuits **341** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its large I/O circuits **341** to its internal circuits to command its internal circuits to pass the second programming code to a second one of its large I/O circuits **341**; the second one of its large I/O circuits **341** may drive the second programming code to one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its large I/O circuits may drive the second programming code to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the second programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed intercon-

nects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the second programming code to one of its memory cells **362** via one or more of the fixed interconnects **364** of its intra-chip interconnects **502**; the second programming code may be stored in said one of its memory cells **362** for programming one of its pass/no-pass switches **258** and/or cross-point switches **379** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C.

Alternatively, referring to FIGS. **11**A-**11**N and **12**B, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its large I/O circuits **341** to drive the control command to a first one of the large I/O circuits **341** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its large I/O circuits **341** to its internal circuits to command its internal circuits to pass the resulting value or first programming code to a second one of its large I/O circuits **341**; the second one of its large I/O circuits **341** may drive the resulting value or first programming code to one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its large I/O circuits may drive the resulting value or first programming code to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the resulting value or first programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the resulting value or first programming code to one of its memory cells **490** via one or more of the fixed interconnects **364** of its intra-chip interconnects **502**; the resulting value or first programming code may be stored in said one of its memory cells **490** for programming one of its programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H.

(2) Interconnection for Operation

Referring to FIGS. **11**A-**11**N and **12**B, in an aspect, one of the dedicated I/O chips **265** may have one of its large I/O circuits **341** to drive a signal from the external circuitry **271** outside the logic drive **300** to one of its small I/O circuits **203**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the signal to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the dedicated DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the signal from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the signal to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the signal to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of the inputs A**0**-A**3** of one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H.

Referring to FIGS. **11**A-**11**N and **12**B, in another aspect, for a first one of the standard commodity FPGA IC chips **200**, one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H may generate an output Dout to be passed to one of its cross-point switches **379** via a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502**; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the output Dout to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the output Dout to one of the small I/O circuits **203** of a second one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For the second one of the FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of the inputs A**0**-A**3** of one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H.

Referring to FIGS. **11**A-**11**N and **12**B, in another aspect, for one of the standard commodity FPGA IC chips **200**, one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H may generate an output Dout to be passed to one of its cross-point switches **379** via a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502**; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of its small I/O circuits **203**;

said one of its small I/O circuits **203** may drive the output Dout to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the output Dout to one of the small I/O circuits **203** of one of the dedicated I/O chips **265** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the output Dout to one of its large I/O circuits **341** to be passed to the external circuitry **271** outside the logic drive **300**.

(3) Interconnection for Controlling

Referring to FIGS. **11**A-**11**N and **12**B, for the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360**, one of its large I/O circuits **341** may receive or drive a control command from or to the external circuitry **271** outside the logic drive **300**.

Alternatively, referring to FIGS. **11**A-**11**N and **12**B, one of the dedicated I/O chips **265** may have a first one of its large I/O circuits **341** to drive a control command, from the external circuitry **271** outside the logic drive **300** to a second one of its large I/O circuits **341**. For said one of the dedicated I/O chips **265**, the second one of its large I/O circuits **341** may drive the control command to one of the large I/O circuits **341** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**.

Alternatively, referring to FIGS. **11**A-**11**N and **12**B, for the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360**, one of its large I/O circuits **341** may drive a control command to a first one of the large I/O circuits **341** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, the first one of its large I/O circuits **341** may drive the control command to a second one of its large I/O circuits **341** to be passed to the external circuitry **271** outside the logic drive **300**.

Thereby, referring to FIGS. **11**A-**11**N and **12**B, a control command may be provided from the external circuitry **271** outside the logic drive **300** to the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** or from the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to the external circuitry **271** outside the logic drive **300**.

III. Third Type of Interconnection for Logic Drive

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all the others of the dedicated I/O chips **265**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all the others of the dedicated I/O chips **265**.

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all the others of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the DPIIC chips **410** to one or more of the small I/O circuits **203** of all the others of the DPIIC chips **410**.

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the standard commodity FPGA IC chips **200** to one or more of the small I/O circuits **203** of all the others of the standard commodity FPGA IC chips **200**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the standard commodity FPGA IC chips **200** to one or more of the small I/O circuits **203** of all the others of the standard commodity FPGA IC chips **200**.

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control

chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the NVM IC chips **250**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to one or more of the small I/O circuits **203** of all of the dedicated I/O chips **265**. One or more of the large I/O circuits **341** of the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may couple to the external circuitry **271** outside the logic drive **300**. NVM IC

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of all of the NVM IC chips **250**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the dedicated I/O chips **265** to one or more of the small I/O circuits **203** of the others of the dedicated I/O chips **265**. One or more of the large I/O circuits **341** of each of the dedicated I/O chips **265** may couple to the external circuitry **271** outside the logic drive **300**.

Referring to FIGS. **11**A-**11**N and **12**C, one or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the NVM IC chips **250** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the NVM IC chips **250** to one or more of the small I/O circuits **203** of all of the standard commodity FPGA IC chips **200**. One or more of the programmable interconnects **361** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the NVM IC chips **250** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the NVM IC chips **250** to one or more of the small I/O circuits **203** of all of the DPIIC chips **410**. One or more of the fixed interconnects **364** of the inter-chip interconnects **371** may couple one or more of the small I/O circuits **203** of each of the NVM IC chips **250** to one or more of the small I/O circuits **203** of the others of the NVM IC chips **250**. One or more of the large I/O circuits **341** of each of the NVM IC chips **250** may couple to the external circuitry **271** outside the logic drive **300**.

(1) Interconnection for Programming Memory Cells

Referring to FIGS. **11**A-**11**N and **12**C, in an aspect, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its small I/O circuits **203** to drive the control command to a first one of the small I/O circuits **203** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its small I/O circuits **203** to its internal circuits to command its internal circuits to pass the third programming code to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the third programming code to one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, said one of its small I/O circuits **203** may drive the third programming code to one of its memory cells **362** in one of its memory-array blocks **423** as seen in FIG. **9** via one or more of the fixed interconnects **364** of its intra-chip interconnects; the third programming code may be stored in said one of its memory cells **362** for programming one of its pass/no-pass switches **258** and/or cross-point switches **379** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C.

Alternatively, referring to FIGS. **11**A-**11**N and **12**C, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its small I/O circuits **203** to drive the control command to a first one of the small I/O circuits **203** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its small I/O circuits **203** to its internal circuits to command its internal circuits to pass the second programming code to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the second programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the second programming code to one of its memory cells **362** via one or more of the fixed interconnects **364** of its intra-chip interconnects **502**; the second programming code may be stored in said one of its memory cells **362** for programming one of its pass/no-pass switches **258** and/or cross-point switches **379** as illustrated in FIGS. **2**A-**2**F, **3**A-**3**D and **7**A-**7**C.

Alternatively, referring to FIGS. **11**A-**11**N and **12**C, the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** may generate a control command to one of its small I/O circuits **203** to drive the control command to a first one of the small I/O circuits **203** of one of the NVM IC chips **250** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the NVM IC chips **250**, the control command is driven by the first one of its small I/O circuits **203** to its internal circuits to command its internal circuits to pass the resulting value or first programming code to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the resulting value or first programming code to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the resulting value or first

programming code to one of its memory cells **490** via one or more of the fixed interconnects **364** of its intra-chip interconnects **502**; the resulting value or first programming code may be stored in said one of its memory cells **490** for programming one of its programmable logic blocks **201** as illustrated in FIG. **6**A or **6**H.

(2) Interconnection for Operation

Referring to FIGS. **11**A-**11**N and **12**C, in an aspect, one of the dedicated I/O chips **265** may have one of its large I/O circuits **341** to drive a signal from the external circuitry **271** outside the logic drive **300** to one of its small I/O circuits **203**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the signal to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the dedicated DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** via a first one of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the signal from the first one of the programmable interconnects **361** of its intra-chip interconnects to a second one of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the signal to one of the small I/O circuits **203** of one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the standard commodity FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the signal to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the signal to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of the inputs A**0**-A**3** of one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H.

Referring to FIGS. **11**A-**11**N and **12**C, in another aspect, for a first one of the standard commodity FPGA IC chips **200**, one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H may generate an output Dout to be passed to one of its cross-point switches **379** via a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502**; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the output Dout to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the output Dout to one of the small I/O circuits **203** of a second one of the standard commodity FPGA IC chips **200** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For the second one of the FPGA IC chips **200**, said one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** through a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** as seen in FIG. **8**G; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of the inputs A**0**-A**3** of one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H.

Referring to FIGS. **11**A-**11**N and **12**C, in another aspect, for one of the standard commodity FPGA IC chips **200**, one of its programmable logic blocks (LB) **201** as seen in FIG. **6**A or **6**H may generate an output Dout to be passed to one of its cross-point switches **379** via a first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502**; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to a second group of the programmable interconnects **361** and by-pass interconnects **279** of its intra-chip interconnects **502** to be passed to one of its small I/O circuits **203**; said one of its small I/O circuits **203** may drive the output Dout to a first one of the small I/O circuits **203** of one of the DPIIC chips **410** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the DPIIC chips **410**, the first one of its small I/O circuits **203** may drive the output Dout to one of its cross-point switches **379** via a first group of the programmable interconnects **361** of its intra-chip interconnects; said one of its cross-point switches **379** may switch the output Dout to pass from the first group of the programmable interconnects **361** of its intra-chip interconnects to a second group of the programmable interconnects **361** of its intra-chip interconnects to be passed to a second one of its small I/O circuits **203**; the second one of its small I/O circuits **203** may drive the output Dout to one of the small I/O circuits **203** of one of the dedicated I/O chips **265** via one or more of the programmable interconnects **361** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the output Dout to one of its large I/O circuits **341** to be passed to the external circuitry **271** outside the logic drive **300**.

(3) Interconnection for Controlling

Referring to FIGS. **11**A-**11**N and **12**C, for the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360**, one of its large I/O circuits **341** may receive or drive a control command from or to the external circuitry **271** outside the logic drive **300**.

Alternatively, referring to FIGS. **11**A-**11**N and **12**C, one of the dedicated I/O chips **265** may have one of its large I/O circuits **341** to drive a control command from the external circuitry **271** outside the logic drive **300** to one of its small I/O circuits **203**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the control command to one of the small I/O circuits **203** of the

dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**.

Alternatively, referring to FIGS. **11**A-**11**N and **12**A, for the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360**, one of its small I/O circuits **203** may drive a control command to one of the small I/O circuits **203** of one of the dedicated I/O chips **265** via one or more of the fixed interconnects **364** of the inter-chip interconnects **371**. For said one of the dedicated I/O chips **265**, said one of its small I/O circuits **203** may drive the control command to one of its large I/O circuits **341** to be passed to the external circuitry **271** outside the logic drive **300**.

Thereby, referring to FIGS. **11**A-**11**N and **12**A, a control command may be provided from the external circuitry **271** outside the logic drive **300** to the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** or from the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the control block **360** to the external circuitry **271** outside the logic drive **300**.

Data Buses for Standard Commodity FPGA IC Chips and High Bandwidth Memory (HBM) IC Chips

FIG. **12**D is a block diagram illustrating multiple data buses for one or more standard commodity FPGA IC chips and high bandwidth memory (HBM) IC chips in accordance with the present application. Referring to FIGS. **11**L-**11**N and **12**D, the logic drive **300** may be provided with multiple data buses **315** each constructed from multiple of the programmable interconnects **361** and/or multiple of the fixed interconnects **364**. For example, for the logic drive **300**, multiple of its programmable interconnects **361** may be programmed into one of its data buses **315**. Alternatively, multiple of its programmable interconnects **361** may be programmed to be combined with multiple of its fixed interconnects **364** into one of its data buses **315**. Alternatively, multiple of its fixed interconnects **364** may be combined into one of its data buses **315**.

Referring to FIG. **12**D, one of the data buses **315** may couples multiple of the standard commodity FPGA IC chips **200** and multiple of the high bandwidth memory (HBM) IC chips **251** (only one is shown). For example, in a first clock, said one of the data buses **315** may be switched to couple one of the I/O ports of a first one of the standard commodity FPGA IC chips **200** to one of the I/O ports of a second one of the standard commodity FPGA IC chips **200**. Said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** is selected in accordance with the logic levels at the chip-enable pad **209**, input-enable pad **221**, input-selection pads **226** and output-enable pad **227** of the first one of the standard commodity FPGA IC chips **200** as illustrated in FIG. **8**A to receive data from said one of the data buses **315**; said one of the I/O ports of the second one of the standard commodity FPGA IC chips **200** is selected in accordance with the logic levels at the chip-enable pad **209**, input-enable pad **221**, output-enable pad **227** and output-selection pads **228** of the second one of the standard commodity FPGA IC chips **200** as illustrated in FIG. **8**A to drive or pass data to said one of the data buses **315**. Thereby, in the first clock, said one of the I/O ports of the second one of the standard commodity FPGA IC chips **200** may drive or pass data to said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** through said one of the data buses **315**. In the first clock, said one of the data buses **315** is not used for data transmission by the other(s) of the standard commodity FPGA IC chips **200** coupling thereto or by the high bandwidth memory (HBM) IC chips **251** coupling thereto.

Further, referring to FIG. **12**D, in a second clock, said one of the data buses **315** may be switched to couple said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** to one of I/O ports of a first one of the high bandwidth memory (HBM) IC chips **251**. Said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** is selected in accordance with the logic levels at the chip-enable pad **209**, input-enable pad **221**, input-selection pads **226** and output-enable pad **227** of the first one of the standard commodity FPGA IC chips **200** as illustrated in FIG. **8**A to receive data from said one of the data buses **315**; said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** is selected to drive or pass data to said one of the data buses **315**. Thereby, in the second clock, said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** may drive or pass data to said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** through said one of the data buses **315**. In the second clock, said one of the data buses **315** is not used for data transmission by the other(s) of the standard commodity FPGA IC chips **200** coupling thereto or by the other(s) of the high bandwidth memory (HBM) IC chips **251** coupling thereto.

Further, referring to FIG. **12**D, in a third clock said one of the data buses **315** may be switched to couple said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** to said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251**. Said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** is selected in accordance with the logic levels at the chip-enable pad **209**, input-enable pad **221**, output-enable pad **227** and output-selection pads **228** of the second one of the standard commodity FPGA IC chips **200** as illustrated in FIG. **8**A to drive or pass data to said one of the data buses **315**; said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** is selected to receive data from said one of the data buses **315**. Thereby, in the third clock, said one of the I/O ports of the first one of the standard commodity FPGA IC chips **200** may drive or pass data to said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** through said one of the data buses **315**. In the third clock, said one of the data buses **315** is not used for data transmission by the other(s) of the standard commodity FPGA IC chips **200** coupling thereto or by the other(s) of the high bandwidth memory (HBM) IC chips **251** coupling thereto.

Further, referring to FIG. **12**D, in a fourth clock said one of the data buses **315** may be switched to couple said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** to one of I/O ports of a second one of the high bandwidth memory (HBM) IC chips **251**. Said one of the I/O ports of the second one of the high bandwidth memory (HBM) IC chips **251** is selected to drive or pass data to said one of the data buses **315**; said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** is selected to receive data from said one of the data buses **315**. Thereby, in the fourth clock, said one of the I/O ports of the second one of the high bandwidth memory (HBM) IC chips **251** may drive or pass data to said one of the I/O ports of the first one of the high bandwidth memory (HBM) IC chips **251** through said one of the data buses **315**. In the fourth clock, said one of the data buses **315** is not used for data transmission by the standard commodity FPGA IC

chips **200** coupling thereto or by the other(s) of the high bandwidth memory (HBM) IC chips **251** coupling thereto.

Algorithm for Data Loading to Memory Cells

FIG. **13**A is a block diagram showing an algorithm for data loading to memory cells in accordance with an embodiment of the present application. Referring to FIG. **13**A, for loading data to the memory cells **490** and **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and to the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**, a buffering/driving unit or buffer **340** may be provided for buffering data, such as the resulting values or programming codes, transmitted in series thereto and driving or amplifying the data in parallel to the memory cells **490** and **362** of the standard commodity FPGA IC chip **200** and/or to the memory cells **362** of the DPIIC chip **410**. Furthermore, a control unit **337** may be provided for controlling the buffering/driving unit **340** to buffer the resulting values or programming codes transmitted in series to its input and drive them in parallel to its outputs. Each of the outputs of the buffering/driving unit **340** may couple to one of the memory cells **490** and **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and/or couple to one of the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**.

FIG. **13**B is a circuit diagram showing architecture for data loading in accordance with an embodiment of the present application. Referring to FIG. **13**B, in a serial-advanced-technology-attachment (SATA) standard, the buffering/driving unit **340** may include (1) the memory units **446**, each of which may be the first type of SRAM cell as illustrated in FIG. **1**A, (2) multiple switches **449** as illustrated in FIG. **1**A each having a channel with an end coupling in parallel to each other or one another through a bit line **452** or bit-bar line **453** as illustrated in FIG. **1**A coupling to the input of the buffering/driving unit **340** and the other end coupling in series to one of the memory units **446**, and (3) multiple switches **336** each having a channel with an end coupling in series to one of the memory units **446** and the other end coupling in series to one of the memory cells **490** and **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J or one of the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**.

Referring to FIG. **13**B, the control unit **337** couples to gate terminals of the switches **449** through multiple word lines **451** as illustrated in FIG. **1**A and to gate terminals of the switches **336** through a word line **454**. Thereby, the control unit **337** is configured in turn and one by one to turn on one of the switches **449** and off the others of the switches **449** in each of first clock periods in each of clock cycles and configured to turn off all of the switches **449** in a second clock period in said each of clock cycles. The control unit **337** is configured to turn on all of the switches **336** in the second clock period in said each of clock cycles and off all of the switches **336** in said each of first clock periods in said each of clock cycles with a data bit-width of equal to or greater than 2, 4, 8, 16, 32 or 64 between the buffering/driving unit **340** and the memory cells **490** or **362** of the standard commodity FPGA IC chip **200** or between the buffering/driving unit **340** and the memory cells **362** of the DPIIC chip **410**.

For example, referring to FIG. **13**B, in a first one of the first clock periods in a first one of the clock cycles, the control unit **337** may turn on the bottommost one of the switches **449** and off the others of the switches **449**, and thereby first data, such as a first one of the resulting values or programming codes, from the input of the buffering/driving unit **340** may pass through the channel of the bottommost one of the switches **449** to be latched or stored in the bottommost one of the memory units **446**. Next, in a second one of the first clock periods in the first one of the clock cycles, the control unit **337** may turn on the second bottom one of the switches **449** and off the others of the switches **449**, and thereby second data, such as a second one of the resulting values or programming codes, from the input of the buffering/driving unit **340** may pass through the channel of the second bottom one of the switches **449** to be latched or stored in the second bottom one of the memory units **446**. In the first one of the clock cycles, the control unit **337** may turn on the switches **449**, in turn and one by one, and off the others of the switches **449** in the first clock periods, and thereby data, such as a first set of resulting values or programming codes, from the input of the buffering/driving unit **340** may, in turn and one by one, pass through the channels of the switches **449** to be latched or stored in the memory units **446**, respectively. In the first one of the clock cycles, after the data from the input of the buffering/driving unit **340** are latched or stored, in turn and one by one, in all of the memory units **446**, the control unit **337** may turn on all of the switches **336** and off all of the switches **449** in the second clock period, and thereby the data latched or stored in the memory units **446** may pass in parallel through the channels of the switches **336** to a first group of the memory cells **490** and/or **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and/or the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**, respectively.

Next, referring to FIG. **13**B, in a second one of the clock cycles, the control unit **337** and buffering/driving unit **340** may perform the same steps as illustrated above in the first one of the clock cycles. In the second one of the clock cycles, the control unit **337** may turn on the switches **449**, in turn and one by one, and off the others of the switches **449** in the first clock periods, and thereby data, such as a second set of resulting values or programming codes, from the input of the buffering/driving unit **340** may, in turn and one by one, pass through the channels of the switches **449** to be latched or stored in the memory units **446**, respectively. In the second one of the clock cycles, after the data from the input of the buffering/driving unit **340** are latched or stored, in turn and one by one, in all of the memory units **446**, the control unit **337** may turn on all of the switches **336** and off all of the switches **449** in the second clock period, and thereby the data latched or stored in the memory units **446** may pass in parallel through the channels of the switches **336** to a second group of the memory cells **490** and/or **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and/or the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**, respectively.

Referring to FIG. **13**B, the above steps may be repeated for multiple times to have data, such as the resulting values or programming codes, from the input of the buffering/driving unit **340** to be loaded in the memory cells **490** and/or **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and/or the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**. The buffering/driving unit **340** may latch the data from its single input and increase data bit-width to the memory cells **490** and/or **362** of the standard commodity FPGA IC chip(s) **200** as seen in FIGS. **8**A-**8**J and/or the memory cells **362** of the memory-array blocks **423** of the DPIIC chips **410** as seen in FIG. **9** in the logic drive **300** as seen in FIGS. **11**A-**11**N.

Alternatively, in a peripheral-component-interconnect (PCI) standard, referring to FIGS. **13**A and **13**B, a plurality of the buffering/driving unit **340** having the number equal to or greater than 4, 8, 16, 32, or 64, for example, may be provided in parallel to buffer data, such as the resulting values or programming codes, in parallel from its inputs and drive or amplify the data to the memory cells **490** and/or **362** of the standard commodity FPGA IC chip(s) **200** as seen in FIGS. **8**A-**8**J and/or the memory cells **362** of the memory-array blocks **423** of the DPIIC chips **410** as seen in FIG. **9** in the logic drive **300** as seen in FIGS. **11**A-**11**N. Each of the buffering/driving units **340** may perform the same function as mentioned above.

I. First Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Standard Commodity FPGA IC Chip

Referring to FIGS. **13**A and **13**B, in a case that a bit width between the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J and an external circuitry thereof is 32 bits, the buffering/driving units **340** having the number of 32 may be set in parallel in the standard commodity FPGA IC chip **200** to buffer data, such as the resulting values or programming codes, from their 32 respective inputs coupling to the external circuitry, i.e., with a bit width of 32 bits in parallel, and drive or amplify the data to the memory cells **490** and/or **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J. In each of the clock cycles, the control unit **337** set in the standard commodity FPGA IC chip **200** may turn on the switches **449**, in turn and one by one, of each of the 32 buffering/driving units **340** and off the others of the switches **449** of said each of the 32 buffering/driving units **340** in the first clock periods and turn off all of the switches **336** of said each of the 32 buffering/driving units **340** in the first clock periods, and thereby data, such as the resulting values or programming codes, from the input of said each of the 32 buffering/driving units **340** may, in turn and one by one, pass through the channels of the switches **449** of said each of the 32 buffering/driving units **340** to be latched or stored in the memory units **446** of said each of the 32 buffering/driving units **340**, respectively. In said each of the clock cycles, after the data from their 32 respective inputs in parallel are latched or stored, in turn and one by one, in all of the memory units **446** of the 32 buffering/driving units **340**, the control unit **337** may turn on all of the switches **336** of the 32 buffering/driving units **340** and off all of the switches **449** of the 32 buffering/driving units **340** in the second clock period, and thereby the data latched or stored in all of the memory units **446** of the 32 buffering/driving units **340** may pass in parallel through the channels of the switches **336** of the 32 buffering/driving units **340** to the memory cells **490** and/or **362** of the standard commodity FPGA IC chip **200** as seen in FIGS. **8**A-**8**J, respectively.

Each of the memory cells **490** for the look-up tables (LUTs) **210** may be referred to one **398** as illustrated in FIG. **1**A or **1**B, and the memory cells **362** for the cross-point switches **379** may be referred to one **398** as illustrated in FIG. **1**A or **1**B. For each of the logic drives **300** as seen in FIGS. **11**A-**11**N, each of the standard commodity FPGA IC chips **200** may be provided with the first arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** as mentioned above.

II. Second Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for DPIIC Chip

Referring to FIGS. **13**A and **13**B, in a case that a bit width between the DPIIC chip **410** as seen in FIG. **9** and an external circuitry thereof is 32 bits, the buffering/driving units **340** having the number of 32 may be set in parallel in the DPIIC chip **410** to buffer data, such as the programming codes, from their 32 respective inputs coupling to the external circuitry, i.e., with a bit width of 32 bits in parallel, and drive or amplify the data to the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**. In each of the clock cycles, the control unit **337** set in the DPIIC chip **410** may turn on the switches **449**, in turn and one by one, of each of the 32 buffering/driving units **340** and off the others of the switches **449** of said each of the 32 buffering/driving units **340** in the first clock periods and turn off all of the switches **336** of said each of the 32 buffering/driving units **340** in the first clock periods, and thereby data, such as the programming codes, from the input of said each of the 32 buffering/driving units **340** may, in turn and one by one, pass through the channels of the switches **449** of said each of the 32 buffering/driving units **340** to be latched or stored in the memory units **446** of said each of the 32 buffering/driving units **340**, respectively. In said each of the clock cycles, after the data in parallel from their 32 respective inputs are latched or stored, in turn and one by one, in all of the memory units **446** of the 32 buffering/driving units **340**, the control unit **337** may turn on all of the switches **336** of the 32 buffering/driving units **340** and off all of the switches **449** of the 32 buffering/driving units **340** in the second clock period, and thereby the data latched or stored in all of the memory units **446** of the 32 buffering/driving units **340** may pass in parallel through the channels of the switches **336** of the 32 buffering/driving units **340** to the memory cells **362** of the memory-array blocks **423** of the DPIIC chip **410** as seen in FIG. **9**, respectively.

Each of the memory cells **362** for the cross-point switches **379** may be referred to one **398** as illustrated in FIG. **1**A or **1**B. For each of the logic drives **300** as seen in FIGS. **11**A-**11**N, each of the DPIIC chips **410** may be provided with the second arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** as mentioned above.

III. Third Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the third arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for the logic drive **300** as seen in FIGS. **11**A-**11**N may be similar to the first arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for each of the standard commodity FPGA IC chips **200** of the logic drive **300**, but the difference therebetween is that the control unit **337** in the third arrangement is set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** as seen in FIGS. **11**A-**11**N, but instead is not set in any of the standard commodity FPGA IC chips **200** of the logic drives **300**. The control unit **337** set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** may (1) pass a control command to one of the switches **449** of the buffering/driving unit **340** in one of the standard commodity FPGA IC chips **200** through one of the word lines **451** provided by one or more of the fixed interconnects **364** of the inter-chip interconnects **371**, or (2) pass a control command to the all switches **336** of the buffering/driving unit **340** in said one of the standard commodity FPGA IC chips **200** through the word line **454** provided by another of the fixed interconnects **364** of the inter-chip interconnects **371**.

IV. Fourth Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the fourth arrangement for the control unit **337**, buffering/driving unit **340** and

memory cells **362** for the logic drive **300** as seen in FIGS. **11**A-**11**N may be similar to the second arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** for each of the DPIIC chips **410** of the logic drive **300**, but the difference therebetween is that the control unit **337** in the fourth arrangement is set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** as seen in FIGS. **11**A-**11**N, but instead is not set in any of the DPIIC chips **410** of the logic drives **300**. The control unit **337** set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** may (1) pass a control command to one of the switches **449** of the buffering/driving unit **340** in one of the DPIIC chips **410** through one of the word lines **451** provided by one or more of the fixed interconnects **364** of the inter-chip interconnects **371**, or (2) pass a control command to the all switches **336** of the buffering/driving unit **340** in said one of the DPIIC chips **410** through the word line **454** provided by another of the fixed interconnects **364** of the inter-chip interconnects **371**.

V. Fifth Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the fifth arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for the logic drive **300** as seen in FIGS. **11**B, **11**E, **11**F, **11**H and **11**J may be similar to the first arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for each of the standard commodity FPGA IC chips **200** of the logic drive **300**, but the difference therebetween is that both of the control unit **337** and buffering/driving unit **340** in the fifth arrangement are set in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** as seen in FIGS. **11**B, **11**E, **11**F, **11**H and **11**J, but instead are not set in any of the standard commodity FPGA IC chips **200** of the logic drives **300**. Data may be transmitted in series to the buffering/driving unit **340** in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** to be latched or stored in the memory units **446** of the buffering/driving unit **340**. The buffering/driving unit **340** in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** may pass data in parallel from its memory units **446** to a group of the memory cells **490** and/or **362** of one of the standard commodity FPGA IC chips **200** through, in sequence, the small I/O circuits **203**, arranged in parallel, of the dedicated control and I/O chip **266** or DCDI/OIAC chip **268**, the fixed interconnects **364**, arranged in parallel, of the inter-chip interconnects **371** and the small I/O circuits **203**, arranged in parallel, of said one of the standard commodity FPGA IC chips **200**.

VI. Sixth Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the sixth arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** for the logic drive **300** as seen in FIGS. **11**B, **11**E, **11**F, **11**H and **11**J may be similar to the second arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** for each of the DPIIC chips **410** of the logic drive **300**, but the difference therebetween is that both of the control unit **337** and buffering/driving unit **340** in the sixth arrangement are set in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** as seen in FIGS. **11**B, **11**E, **11**F, **11**H and **11**J, but instead are not set in any of the DPIIC chips **410** of the logic drives **300**. Data may be transmitted in series to the buffering/driving unit **340** in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** to be latched or stored in the memory units **446** of the buffering/driving unit **340**. The buffering/driving unit **340** in the dedicated control and I/O chip **266** or DCDI/OIAC chip **268** may pass data in parallel from its memory units **446** to a group of the memory cells **362** of one of the DPIIC chips **410** through, in sequence, the small I/O circuits **203**, arranged in parallel, of the dedicated control and I/O chip **266** or DCDI/OIAC chip **268**, the fixed interconnects **364**, arranged in parallel, of the inter-chip interconnects **371** and the small I/O circuits **203**, arranged in parallel, of said one of the DPIIC chips **410**.

VII. Seventh Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the seventh arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for the logic drive **300** as seen in FIGS. **11**A-**11**N may be similar to the first arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **490** and **362** for each of the standard commodity FPGA IC chips **200** of the logic drive **300**, but the difference therebetween is that the control unit **337** in the seventh arrangement is set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** as seen in FIGS. **11**A-**11**N, but instead is not set in any of the standard commodity FPGA IC chips **200** of the logic drives **300**. Further, the buffering/driving unit **340** in the seventh arrangement is set in one of the dedicated I/O chips **265** as seen in FIGS. **11**A-**11**N, but instead is not set in any of the standard commodity FPGA IC chips **200** of the logic drives **300**. The control unit **337** set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** may (1) pass a control command to one of the switches **449** of the buffering/driving unit **340** in one of the dedicated I/O chips **265** through one of the word lines **451** provided by one of the fixed interconnects **364** of the inter-chip interconnects **371**, and (2) pass a control command to the all switches **336** of the buffering/driving unit **340** in said one of the dedicated I/O chips **265** through the word line **454** provided by another of the fixed interconnects **364** of the inter-chip interconnects **371**. Data may be transmitted in series to the buffering/driving unit **340** in said one of the dedicated I/O chips **265** to be latched or stored in the memory units **446** of the buffering/driving unit **340**. The buffering/driving unit **340** in said one of the dedicated I/O chips **265** may pass data in parallel from its memory units **446** to a group of the memory cells **490** and/or **362** of one of the standard commodity FPGA IC chips **200** through, in sequence, the small I/O circuits **203**, arranged in parallel, of said one of the dedicated I/O chips **265**, a group of the fixed interconnects **364**, arranged in parallel, of the inter-chip interconnects **371** and the small I/O circuits **203**, arranged in parallel, of said one of the standard commodity FPGA IC chips **200**.

VIII. Eighth Type of Arrangement for Control Unit, Buffering/Driving Unit and Memory Cells for Logic Drive

Referring to FIGS. **13**A and **13**B, the eighth arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** for the logic drive **300** as seen in FIGS. **11**A-**11**N may be similar to the second arrangement for the control unit **337**, buffering/driving unit **340** and memory cells **362** for each of the DPIIC chips **410** of the logic drive **300**, but the difference therebetween is that the control unit **337** in the eighth arrangement is set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** as seen in FIGS. **11**A-**11**N, but instead is not set in any of the DPIIC chips **410** of the logic drives **300**. Further, the buffering/driving unit **340** in the eighth arrangement is set in one of the dedicated I/O chips **265** as seen in FIGS. **11**A-**11**N, but instead is not set in any

of the DPIIC chips **410** of the logic drives **300**. The control unit **337** set in the dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** may (1) pass a control command to one of the switches **449** of the buffering/driving unit **340** in one of the dedicated I/O chips **265** through one of the word lines **451** provided by one of the fixed interconnects **364** of the inter-chip interconnects **371**, and (2) pass a control command to the all switches **336** of the buffering/driving unit **340** in said one of the dedicated I/O chips **265** through the word line **454** provided by another of the fixed interconnects **364** of the inter-chip interconnects **371**. Data may be transmitted in series to the buffering/driving unit **340** in said one of the dedicated I/O chips **265** to be latched or stored in the memory units **446** of the buffering/driving unit **340**. The buffering/driving unit **340** in said one of the dedicated I/O chips **265** may pass data in parallel from its memory units **446** to a group of the memory cells **362** of one of the DPIIC chips **410** through, in sequence, the small I/O circuits **203**, arranged in parallel, of said one of the dedicated I/O chips **265**, a group of the fixed interconnects **364**, arranged in parallel, of the inter-chip interconnects **371** and the small I/O circuits **203**, arranged in parallel, of said one of the DPIIC chips **410**.

First Interconnection Scheme for Chip (FISC) and Process for Forming the Same

Each of the standard commodity FPGA IC chips **200**, DPIIC chips **410**, dedicated I/O chips **265**, dedicated control chip **260**, dedicated control and I/O chip **266**, IAC chip **402**, DCIAC chip **267**, DCDI/OIAC chip **268**, NVM IC chips **250**, DRAM IC chips **321**, IBM IC chips **251** and PCIC chips **269** may be formed by following steps.

FIG. **14**A is a cross-sectional view of a semiconductor wafer in accordance with an embodiment of the present application.

Referring to FIG. **14**A, a semiconductor substrate or semiconductor blank wafer **2** may be a silicon substrate or silicon wafer, a GaAs substrate, GaAs wafer, a SiGe substrate, SiGe wafer, Silicon-On-Insulator (SOI) substrate with the substrate wafer size, for example 8", 12" or 18" in the diameter.

Referring to FIG. **14**A, multiple semiconductor devices **4** are formed in or over a semiconductor-device area of the semiconductor substrate **2**. The semiconductor devices **4** may comprise a memory cell, a logic circuit, a passive device, such as a resistor, a capacitor, an inductor or a filter, or an active device, such as p-channel MOS device, n-channel MOS device, CMOS (Complementary Metal Oxide Semiconductor) device, BJT (Bipolar Junction Transistor) device, BiCMOS (Bipolar CMOS) device or FIN Field-Effect-Transistor (FINFET), FINFET on Silicon-On-Insulator (FINFET SOI), Fully Depleted Silicon-On-Insulator (FDSOI) MOSFET, Partially Depleted Silicon-On-Insulator (PDSOI) MOSFET or conventional MOSFET, used for the transistors of the standard commodity FPGA IC chips **200**, DPIIC chips **410**, dedicated I/O chips **265**, dedicated control chip **260**, dedicated control and I/O chip **266**, IAC chip **402**, DCIAC chip **267**, DCDI/OIAC chip **268**, NVM IC chips **250**, DRAM IC chips **321**, HBM IC chips **251** and PCIC chips **269**.

With regards to the logic drive **300** as seen in FIGS. **11**A-**11**N, the semiconductor devices **4** may compose the multiplexer **211** of the programmable logic blocks (LB) **201**, cells (A) **2011** for fixed-wired adders of the programmable logic blocks (LB) **201**, cells (M) **2012** for fixed-wired multipliers of the programmable logic blocks (LB) **201**, cells (C/R) **2013** for caches and registers of the programmable logic blocks (LB) **201**, memory cells **490** for the look-up table **210** of the programmable logic blocks (LB) **201**, memory cells **362** for the pass/no-pass switches **258**, pass/no-pass switches **258**, cross-point switches **379** and small I/O circuits **203**, as illustrated in FIGS. **8**A-**8**N, for each of its standard commodity FPGA IC chips **200**. The semiconductor devices **4** may compose the memory cells **362** for the pass/no-pass switches **258**, pass/no-pass switches **258**, cross-point switches **379** and small I/O circuits **203**, as illustrated in FIG. **9**, for each of its DPIIC chips **410**. The semiconductor devices **4** may compose the large and small I/O circuits **341** and **203**, as illustrated in FIG. **10**, for each of its dedicated I/O chips **265**, its dedicated control and I/O chip **266** or its DCDI/OIAC chip **268**. The semiconductor devices **4** may compose the control unit **337** as seen in FIGS. **13**A and **13**B set in each of its standard commodity FPGA IC chips **200**, each of its DPIIC chips **410**, its dedicated control chip **260**, its dedicated control and I/O chip **266**, its DCIAC chip **267** or its DCDI/OIAC chip **268**. The semiconductor devices **4** may compose the buffering/driving unit **340** as seen in FIGS. **13**A and **13**B set in each of its standard commodity FPGA IC chips **200**, each of its DPIIC chips **410**, each of its dedicated I/O chips **265**, its dedicated control and I/O chip **266** or its DCDI/OIAC chip **268**.

Referring to FIG. **14**A, a first interconnection scheme **20**, connected to the semiconductor devices **4**, is formed over the semiconductor substrate **2**. The first interconnection scheme **20** in, on or of the Chip (HSC) is formed over the semiconductor substrate **2** by a wafer process. The FISC **20** may comprise 4 to 15 layers, or 6 to 12 layers of interconnection metal layers **6** (only three layers are shown) patterned with multiple metal pads, lines or traces **8** and multiple metal vias **10**. The metal pads, lines or traces **8** and metal vias **10** of the FISC **20** may be used for the programmable and fixed interconnects **361** and **364** of the intra-chip interconnects **502**, as seen in FIG. **8**A, of each of the standard commodity FPGA IC chips **200**. The first interconnection scheme **20** in, on or of the Chip (FISC) may include multiple insulating dielectric layers **12** and multiple interconnection metal layers **6** each in neighboring two of the insulating dielectric layers **12**. Each of the interconnection metal layers **6** of the FISC **20** may include the metal pads, lines or traces **8** at a top portion thereof and the metal vias **10** at a bottom portion thereof. One of the insulating dielectric layers **12** of the FISC **20** may be between the metal pads, lines or traces **8** of neighboring two of the interconnection metal layers **6**, a top one of which may have the metal vias **10** in said one of the insulating dielectric layers **12**. For each of the interconnection metal layers **6** of the FISC **20**, its metal pads, lines or traces **8** may have a thickness t1 of less than 3 μm (such as between 3 nm and 500 nm, between 10 nm and 1,000 nm, between 10 nm and 2,000 nm, or between 10 nm and 3,000 nm, or thinner than or equal to 5 nm, 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm) and may have a minimum width, for example, between 3 nm and 500 nm, or between 10 nm and 1,000 nm, or, narrower than 5 nm, 10 nm, 20 nm, 30 nm, 50 nm, 70 nm, 100 nm, 150 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm. For example, the metal pads, lines or traces **8** and metal vias **10** of the FISC **20** are principally made of copper by a damascene process such as single-damascene process or double-damascene process, mentioned as below. For each of the interconnection metal layers **6** of the FISC **20**, its metal pads, lines or traces **8** may include a copper layer having a thickness of less than 3 μm (such as between 0.2 and 2 μm). Each of the insulating dielectric layers **12** of the FISC **20**

may have a thickness between, for example, 3 nm and 500 nm, between 10 nm and 1,000 nm, between 10 nm and 2,000 nm or between 10 nm and 3,000 nm, or thinner than 5 nm, 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, 1,000 nm or 2,000 nm.

I. Single Damascene Process for FISC

In the following, a single damascene process for the FISC **20** is illustrated in FIGS. **14**B-**14**H. Referring to FIG. **14**B, a first insulating dielectric layer **12** is provided and multiple metal vias **10** or metal pads, lines or traces **8** (only one is shown) having exposed top surfaces are provided in the first insulating dielectric layer **12**. A top-most layer of the first insulating dielectric layer **12** may be, for example, a low k dielectric layer, such as SiOC layer.

Referring to FIG. **14**C, a chemical vapor deposition (CVD) method may be performed to deposit a second insulating dielectric layer **12** (upper one) on or over the first insulating dielectric layer **12** (lower one) and on the exposed vias **10** or metal pads, lines or traces **8** in the first insulating dielectric layer **12**. The second insulting dielectric layer **12** (upper one) may be formed by (a) depositing a bottom differentiate etch-stop layer **12***a*, for example, a Silicon Carbon Nitride layer (SiCN), on the top-most layer of the first insulting dielectric layer **12** (lower one) and on the exposed top surfaces of the vias **10** or metal pads, lines or traces **8** in the first insulating dielectric layer **12** (lower one), and (b) next depositing a low k dielectric layer **12***b*, for example, a SiOC layer, on the bottom differentiate etch-stop layer **12***a*. The low k dielectric layer **12***b* may have low k dielectric material having a dielectric constant smaller than that of the SiO material. The SiCN, SiOC, and SiO_2 layers may be deposited by CVD methods. The material used for the first and second insulating dielectric layers **12** of the FISC **20** comprises inorganic material, or material compounds comprising silicon, nitrogen, carbon, and/or oxygen.

Next, referring to FIG. **14**D, a photoresist layer **15** is coated on the second insulting dielectric layer **12** (upper one), and then the photoresist layer **15** is exposed and developed to form multiple trenches or openings **15***a* (only one is shown) in the photoresist layer **15**. Next, referring to FIG. **14**E, an etching process is performed to form trenches or openings **12***d* (only one is shown) in the second insulating dielectric layer **12** (upper one) and under the trenches or openings **15***a* in the photoresist layer **15**. Next, referring to FIG. **14**F, the photoresist layer **15** may be removed.

Next, referring to FIG. **14**G, an adhesion layer **18** may be deposited on a top surface of the second insulating dielectric layer **12** (upper one), a sidewall of the trenches or openings **12***d* in the second insulating dielectric layer **12** (upper one) and a top surface of the vias **10** or metal pads, lines or traces **8** in the first insulating dielectric layer **12** (lower one) by, for example, sputtering or Chemical Vapor Depositing (CVD) a titanium (Ti) or titanium nitride (TiN) layer **18** (with thickness for example, between 1 nm and 50 nm). Next, an electroplating seed layer **22** may be deposited on the adhesion layer **18** by, for example, sputtering or CVD depositing a copper seed layer **22** (with a thickness, for example, between 3 nm and 200 nm) on the adhesion layer **18**. Next, a copper layer **24** (with a thickness, for example, between 10 nm and 3,000 nm, 10 nm and 1,000 nm or 10 nm and 500 nm) may be electroplated on the copper seed layer **22**.

Next, referring to FIG. **14**H, a chemical-mechanical polishing (CMP) process may be applied to remove the adhesion layer **18**, electroplating seed layer **22** and copper layer **24** outside the trenches or openings **12***d* in the second insulating dielectric layer **12** (upper one) until the top surface of the second insulating dielectric layer **12** (upper one) is exposed. The metals left or remained in trenches or openings **12***d* in the second insulating dielectric layer **12** (upper one) are used as the metal vias **10** or metal pads, lines or traces **8** for each of the interconnection metal layers **6** of the FISC **20**.

In the single-damascene process, the copper electroplating process step and the CMP process step are performed for the metal pads, lines or traces **8** of a lower one of the interconnection metal layers **6**, and are then performed sequentially again for the metal vias **10** of an upper one of the interconnection metal layers **6** in the insulating dielectric layer **12** on the lower one of the interconnection metal layers **6**. In other words, in the single damascene copper process, the copper electroplating process step and the CMP process step are performed two times for forming the metal pads, lines or traces **8** of the lower one of the interconnection metal layers **6**, and metal vias **10** of the upper one of the interconnection metal layers **6** in the insulating dielectric layer **12** on the lower one of interconnection metal layers **6**.

II. Double Damascene Process for FISC

Alternatively, a double damascene process may be performed for fabricating the metal vias **10** and metal pads, lines or traces **8** of the FISC **20**, as illustrated in FIGS. **14**I-**14**Q. Referring to FIG. **14**I, a first insulating dielectric layer **12** is provided and multiple metal pads, lines or traces **8** (only one is shown) having exposed top surfaces are provided in the first insulating dielectric layer **12**. A top-most layer of the first insulating dielectric layer **12** may be, for example, a Silicon Carbon Nitride layer (SiCN) or Silicon Nitride (SiN). Next, a dielectric stack layer comprising second and third insulating dielectric layers **12** are deposited on the top-most layer of the first insulting dielectric layer **12** and the exposed top surfaces of metal pads, lines or traces **8** in the first insulating dielectric layer **12**. The dielectric stack layer comprises, from bottom to top, (a) a bottom low k dielectric layer **12***e*, such as SiOC layer, (to be used as an inter-metal dielectric layer to have the metal vias **10** formed therein) on the first insulating dielectric layer **12** (lower one), (b) a middle differentiate etch-stop layer **12***f*, such as Silicon Carbon Nitride layer (SiCN) or Silicon Nitride layer (SiN), on the bottom low k dielectric layer **12***e*, (c) a top low k SiOC layer **12***g* (to be used as the insulating dielectrics between the metal pads, lines or traces **8** in or of the same interconnection metal layer **6**) on the middle differentiate etch-stop layer **12***f*, and (d) a top differentiate etch-stop layer **12***h*, such as Silicon Carbon Nitride layer (SiCN) or Silicon Nitride (SiN) layer, on the top low k SiOC layer **12***g*. All layers of SiCN, SiN or SiOC may be deposited by CVD methods. The bottom low k dielectric layer **12***e* and middle differentiate etch-stop layer **12***f* may compose the second insulating dielectric layer **12** (middle one); the top low k SiOC layer **12***g* and top differentiate etch-stop layer **12***h* may compose the third insulating dielectric layer **12** (top one).

Next, referring to FIG. **14**J, a first photoresist layer **15** is coated on the top differentiate etch-stop layer **12***h* of the third insulting dielectric layer **12** (top one), and then the first photoresist layer **15** is exposed and developed to form multiple trenches or openings **15***a* (only one is shown) in the first photoresist layer **15** to expose the top differentiate etch-stop layer **12***h* of the third insulting dielectric layer **12** (top one). Next, referring to FIG. **14**K, an etching process is performed to form trenches or top openings **12***i* (only one is shown) in the third insulating dielectric layer **12** (top one) and under the trenches or openings **15***a* in the first photoresist layer **15** and to stop at the middle differentiate etch-stop layer **12***f* of the second insulting dielectric layer **12** (middle one) for the later double-damascene copper process

to from the metal pads, lines or traces **8** of the interconnection metal layer **6**. Next, referring to FIG. **14**L, the first photoresist layer **15** may be removed.

Next, referring to FIG. **14**M, a second photoresist layer **17** is coated on the top differentiate etch-stop layer **12***h* of the third insulting dielectric layer **12** (top one) and the middle differentiate etch-stop layer **12***f* of the second insulting dielectric layer **12** (middle one), and then the second photoresist layer **17** is exposed and developed to form multiple trenches or openings **17***a* (only one is shown) in the second photoresist layer **17** to expose the middle differentiate etch-stop layer **12***f* of the second insulting dielectric layer **12** (middle one). Next, referring to FIG. **14**N, an etching process is performed to form holes or bottom openings **12***j* (only one is shown) in the second insulating dielectric layer **12** (middle one) and under the trenches or openings **17***a* in the second photoresist layer **17** and to stop at the metal pads, lines or traces **8** (only one is shown) in the first insulating dielectric layer **12** for the later double-damascene copper process to from the metal vias **10** in the second insulating dielectric layer **12**, i.e., inter-metal dielectric layer. Next, referring to FIG. **14**O, the second photoresist layer **17** may be removed. The second and third insulating dielectric layers **12** (middle and upper ones) may compose a dielectric stack layer. One of the trenches or top openings **12***i* in the top portion of the dielectric stack layer, i.e., third insulating dielectric layer **12** (upper one), may overlap one of the bottom openings or holes **12***j* in the bottom portion of the dielectric stack layer, i.e., second insulating dielectric layer **12** (middle one), and have a size larger than that of said one of the bottom openings or holes **12***j*. In other words, the bottom openings or holes **12***j* in the bottom portion of the dielectric stack layer, i.e., second insulating dielectric layer **12** (middle one), are inside or enclosed by the trenches or top openings **12***i* in the top portion of the dielectric stack layer, i.e., third insulating dielectric layer **12** (upper one), form a top view.

Next, referring to FIG. **14**P, an adhesion layer **18** may be deposited on top surfaces of the second and third insulating dielectric layers **12** (middle and upper ones), a sidewall of the trenches or top openings **12***i* in the third insulating dielectric layer **12** (upper one), a sidewall of the holes or bottom openings **12***j* in the second insulating dielectric layer **12** (middle one) and a top surface of the metal pads, lines or traces **8** in the first insulating dielectric layer **12** (bottom one) by, for example, sputtering or Chemical Vapor Depositing (CVD) a titanium (Ti) or titanium nitride (TiN) layer **18** (with thickness for example, between 1 nm and 50 nm). Next, an electroplating seed layer **22** may be deposited on the adhesion layer **18** by, for example, sputtering or CVD depositing a copper seed layer **22** (with a thickness, for example, between 3 nm and 200 nm) on the adhesion layer **18**. Next, a copper layer **24** (with a thickness, for example, between 20 nm and 6,000 nm, 10 nm and 3,000 nm or 10 nm and 1,000 nm) may be electroplated on the copper seed layer **22**.

Next, referring to FIG. **14**Q, a chemical-mechanical polishing (CMP) process may be applied to remove the adhesion layer **18**, electroplating seed layer **22** and copper layer **24** outside the holes or bottom openings **12***j* and trenches or top openings **12***i* in the second and third insulating dielectric layers **12** (middle and top ones) until the top surface of the third insulating dielectric layer **12** (top one) is exposed. The metals left or remained in the trenches or top openings **12***i* in the third insulating dielectric layer **12** (top one) are used as the metal pads, lines or traces **8** for each of the interconnection metal layers **6** of the FISC **20**. The metals left or remained in the holes or bottom openings **12***j* in the second insulating dielectric layer **12** (middle one) are used as the metal vias **10** for each of the interconnection metal layers **6** of the FISC **20** for coupling the metal pads, lines or traces **8** below and above the metal vias **10**.

In the double-damascene process, the copper electroplating process step and CMP process step are performed one time for forming the metal pads, lines or traces **8** and metal vias **10** in two of the insulating dielectric layers **12**.

Accordingly, the processes for forming the metal pads, lines or traces **8** and metal vias **10** using the single damascene copper process as illustrated in FIGS. **14**B-**14**H or the double damascene copper process as illustrated in FIGS. **14**I-**14**Q may be repeated multiple times to form a plurality of the interconnection metal layer **6** for the FISC **20**. The FISC **20** may comprise 4 to 15 layers or 6 to 12 layers of interconnection metal layers **6**. The topmost one of the interconnection metal layers **6** of the FISC may have multiple metal pads **16**, such as copper pads formed by the above-mentioned single or double damascene process or aluminum pads formed by a sputter process.

III. Passivation Layer for Chip

Referring to FIG. **14**A, a passivation layer **14** is formed over the first interconnection scheme **20** of the chip (FISC) and over the insulating dielectric layers **12**. The passivation layer **14** can protect the semiconductor devices **4** and the interconnection metal layers **6** from being damaged by moisture foreign ion contamination, or from water moisture or contamination form external environment, for example sodium mobile ions. In other words, mobile ions (such as sodium ion), transition metals (such as gold, silver and copper) and impurities may be prevented from penetrating through the passivation layer **14** to the semiconductor devices **4**, such as transistors, polysilicon resistor elements and polysilicon-polysilicon capacitor elements, and to the interconnection metal layers **6**.

Referring to FIG. **14**A, the passivation layer **14** is commonly made of a mobile ion-catching layer or layers, for example, a combination of SiN, SiON, and/or SiCN layer or layers deposited by a chemical vapor deposition (CVD) process. The passivation layer **14** commonly has a thickness t**3** of more than 0.3 μm, such as between 0.3 and 1.5 μm. In a preferred case, the passivation layer **14** may have a silicon-nitride layer having a thickness of more than 0.3 μm. The total thickness of the mobile ion catching layer or layers, i.e., a combination of SiN, SiON, and/or SiCN layer or layers, may be thicker than or equal to 100 nm, 150 nm, 200 nm, 300 nm, 450 nm or 500 nm.

Referring to FIG. **14**A, an opening **14***a* in the passivation layer **14** is formed to expose a metal pad **16** of a topmost one of the interconnection metal layers **6** of the FISC **20**. The metal pad **16** may be used for signal transmission or for connection to a power source or a ground reference. The metal pad **16** may have a thickness t**4** of between 0.4 and 3 μm or between 0.2 and 2 μm. For example, the metal pad **16** may be composed of a sputtered aluminum layer or a sputtered aluminum-copper-alloy layer with a thickness of between 0.2 and 2 μm. Alternatively, the metal pad **16** may include the electroplated copper layer **24** formed by the single damascene process as seen in FIG. **14**H or by the double damascene process as seen in FIG. **14**Q.

Referring to FIG. **14**A, the opening **14***a* may have a transverse dimension d, from a tap view, of between 0.5 and 20 μm or between 20 and 200 μm. The shape of the opening **14***a* from a top view may be a circle, and the diameter of the circle-shaped opening **14***a* may be between 0.5 and 20 μm or between 20 and 200 μm. Alternatively, the shape of the

opening **14***a* from a top view may be a square, and the width of the square-shaped opening **14***a* may be between 0.5 and 20 μm or between 20 and 200 μm. Alternatively, the shape of the opening **14***a* from a top view may be a polygon, such as hexagon or octagon, and the polygon-shaped opening **14***a* may have a width of between 0.5 and 20 μm or between 20 and 200 μm. Alternatively, the shape of the opening **14***a* from a top view may be a rectangle, and the rectangle-shaped opening **14***a* may have a shorter width of between 0.5 and 20 μm or between 20 and 200 μm. Further, there may be some of the semiconductor devices **4** under the metal pad **16** exposed by the opening **14***a*. Alternatively, there may be no active devices under the metal pad **16** exposed by the opening **14***a*.

First Type of Micro-Bump

FIGS. **15**A-**15**H are schematically cross-sectional views showing a process for forming a chip with a first type of micro-bump or micro-pillar thereon in accordance with an embodiment of the present application. For connection to circuitry outside a chip, multiple micro-bumps may be formed over the metal pads **16** exposed by the openings **14***a* in the passivation layer **14**.

FIG. **15**A is a simplified drawing from FIG. **14**A. Referring to FIG. **15**B, an adhesion layer **26** having a thickness of between 0.001 and 0.7 μm, between 0.01 and 0.5 μm or between 0.03 and 0.35 μm may be sputtered on the passivation layer **14** and on the metal pad **16**, such as aluminum pad or copper pad, exposed by opening **14***a*. The material of the adhesion layer **26** may include titanium, a titanium-tungsten alloy, titanium nitride, chromium, titanium-tungsten-alloy layer, tantalum nitride, or a composite of the abovementioned materials. The adhesion layer **26** may be formed by an atomic-layer-deposition (ALD) process, chemical vapor deposition (CVD) process or evaporation process. For example, the adhesion layer **26** may be formed by sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 50 nm) on the passivation layer **14** and on the metal pads **16** at a bottom of the openings **14** in the passivation layer **14**.

Next, referring to FIG. **15**C, an electroplating seed layer **28** having a thickness of between 0.001 and 1 μm, between 0.03 and 2 μm or between 0.05 and 0.5 μm may be sputtered on the adhesion layer **26**. Alternatively, the electroplating seed layer **28** may be formed by an atomic-layer-deposition (ALD) process, chemical-vapor-deposition (CVD) process, vapor deposition method, electroless plating method or PVD (Physical Vapor Deposition) method. The electroplating seed layer **28** is beneficial to electroplating a metal layer thereon. Thus, the material of the electroplating seed layer **28** varies with the material of a metal layer to be electroplated on the electroplating seed layer **28**. When a copper layer is to be electroplated on the electroplating seed layer **28**, copper is a preferable material to the electroplating seed layer **28**. For example, the electroplating seed layer **28** may be deposited on or over the adhesion layer **26** by, for example, sputtering or CVD depositing a copper seed layer (with a thickness between, for example, 3 nm and 300 nm or 3 nm and 200 μm) on the adhesion layer **26**.

Next, referring to FIG. **15**D, a photoresist layer **30**, such as positive-type photoresist layer, having a thickness of between 2 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 2 μm and 15 μm, or 2 μm and 10 μm, between 5 and 300 μm or between 20 and 50 μm, or smaller than or equal to 60 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm is spin-on coated on the electroplating seed layer **28**. The photoresist layer **30** is patterned with the processes of exposure, development, etc., to form an opening **30***a* in the photoresist layer **30** exposing the electroplating seed layer **28** over the pad **16**. A 1× stepper, 1× contact aligner or laser scanner may be used to expose the photoresist layer **30** during the process of exposure.

For example, the photoresist layer **30** may be formed by spin-on coating a positive-type photosensitive polymer layer having a thickness of between 5 and 100 μm on the electroplating seed layer **28**, then exposing the photosensitive polymer layer by using a 1× stepper, 1× contact aligner or laser scanner with at least two of G-line having a wavelength ranging from 434 to 438 nm, H-line having a wavelength ranging from 403 to 407 nm, and I-line having a wavelength ranging from 363 to 367 nm, to illuminate the photosensitive polymer layer, that is, G-line and H-line, G-line and Mine, H-line and I-line, or G-line, H-line and I-line illuminate the photosensitive polymer layer, then developing the exposed polymer layer, and then removing the residual polymeric material or other contaminants on the electroplating seed layer **28** with an O_2 plasma or a plasma containing fluorine of below 200 PPM and oxygen, such that the photoresist layer **30** may be patterned with multiple openings **30***a* in the photoresist layer **30** exposing the electroplating seed layer **28** over the pad **16**.

Referring to FIG. **15**D, each of the openings **30***a* in the photoresist layer **30** may overlap one of the openings **14***a* in the passivation layer **14** for forming one of micro-pillars or micro-bumps in said one of the openings **30***a* by following processes to be performed later, exposing the electroplating seed layer **28** at the bottom of said one of the openings **30***a*, and may extend out of said one of the openings **14***a* to an area or ring of the passivation layer **14** around said one of the openings **14***a*.

Next, referring to FIG. **15**E, a metal layer **32**, such as copper, may be electroplated on the electroplating seed layer **28** exposed by the trenches or openings **30***a*. For example, in a first aspect, the metal layer **32** may be formed by electroplating a copper layer with a thickness between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm on the electroplating seed layer **28**, made of copper, exposed by the trenches or openings **30***a*. In another example for the first aspect, the metal layer **32** may be formed by electroplating a copper layer with a thickness smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm on the electroplating seed layer **28**, made of copper, exposed by the trenches or openings **30***a*. Alternatively, in a second aspect, the metal layer **32** may be formed by electroplating a copper layer with a thickness between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm on the electroplating seed layer **28**, made of copper, exposed by the trenches or openings **30***a* and then electroplating a nickel layer with a thickness between 0.5 μm and 3 μm on the electroplated copper layer in the trenches or openings **30***a*. In another example for the second aspect, the metal layer **32** may be formed by electroplating a copper layer with a thickness smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm on the electroplating seed layer **28**, made of copper, exposed by the trenches or openings **30***a* and then electroplating a nickel layer with a thickness between 0.5 μm and 3 μm on the

electroplated copper layer in the trenches or openings **30***a*. Next, a solder cap or layer **33**, such as tin, a tin-lead alloy, tin-copper alloy, tin-silver alloy, tin-silver-copper alloy (SAC) or tin-silver-copper-zin alloy, having a thickness, for example, between 1 μm and 50 μm, 1 μm and 30 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 5 μm and 10 μm, 5 μm and 10 μm, 1 μm and 10 μm, or 1 μm and 3 μm may be electroplated on the metal layer **32** in the trenches or openings **30***a*. For example, the solder cap **33** may be electroplated on the copper layer of the metal layer **32** for the first aspect or on the nickel layer of the metal layer **32** for the second aspect. The solder cap or layer **33** may be a lead-free solder containing tin, copper, silver, bismuth, indium, zinc and/or antimony.

Referring to FIG. **15**F, after the solder cap **33** is formed, most of the photoresist layer **30** may be removed using an organic solution with amide. However, some residuals from the photoresist layer **30** could remain on the metal layer **32** and/or solder cap **33** and on the electroplating seed layer **28**. Thereafter, the residuals may be removed from the metal layer **32** and/or solder cap **33** and from the electroplating seed layer **28** with a plasma, such as O_2 plasma or plasma containing fluorine of below 200 PPM and oxygen. Next, the electroplating seed layer **28** and adhesion layer **26** not under the metal layer **32** are subsequently removed with a dry etching method or a wet etching method. As to the wet etching method, when the adhesion layer **26** is a titanium-tungsten-alloy layer, it may be etched with a solution containing hydrogen peroxide; when the adhesion layer **26** is a titanium layer, it may be etched with a solution containing hydrogen fluoride; when the electroplating seed layer **28** is a copper layer, it may be etched with a solution containing NH_4OH. As to the dry etching method, when the adhesion layer **26** is a titanium layer or a titanium-tungsten-alloy layer, it may be etched with a chlorine-containing plasma etching process or with an RIE process. Generally, the dry etching method to etch the electroplating seed layer **28** and the adhesion layer **26** not under the metal layer **32** may include a chemical plasma etching process, a sputtering etching process, such as argon sputter process, or a chemical vapor etching process.

Next, referring to FIG. **15**G, the solder cap or layer **33** may be reflowed into multiple solder bumps. Thereby, the adhesion layer **26**, electroplating seed layer **28**, electroplated metal layer **32** and solder bumps **33** may compose a first type of micro-pillars or micro-bumps **34** on the metal pads **16** at bottoms of the openings **14***a* in the passivation layer **14**. Each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of the passivation layer **14**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 10 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the first type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of the passivation layer **14**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Referring to FIG. **15**H, after the first type of micro-pillars or micro-bumps **34** are formed over the semiconductor wafer as seen in FIG. **15**G, the semiconductor wafer may be separated, cut or diced into multiple individual semiconductor chips **100**, integrated circuit chips, by a laser cutting process or by a mechanical cutting process. These semiconductor chips **100** may be packaged using the following steps as shown in FIGS. **18**L-**18**W, **19**N-**19**T, **20**A, **20**B, **21**A, **21**B, **22**G-**22**O, **23**A-**23**C, **24**A-**24**F, **26**A-**26**M, **27**A-**27**D, **28**A-**28**C, **29**A-**29**F, **30**A-**30**C and **35**A-**35**D.

Alternatively, FIG. **15**I is a schematically cross-sectional view showing a second type of micro-bump or micro-pillar on a chip in accordance with an embodiment of the present application; Referring to FIG. **15**I, before the adhesion layer **26** is formed as shown in FIG. **15**B, a polymer layer **36**, that is, an insulating dielectric layer contains an organic material, for example, a polymer, or material compounds comprising carbon, may be formed on the passivation layer **14** by a process including a spin-on coating process, a lamination process, a screen-printing process, a spraying process or a molding process, and multiple openings in the polymer layer **36** are formed over the metal pads **16**. The polymer layer **36** has a thickness between 3 and 30 micrometers or between 5 and 15 micrometers and the material of the polymer layer **36** may include benzocyclobutane (BCB), parylene, photoepoxy SU-8, elastomer, silicone, polyimide (PI), polybenzoxazole (PBO) or epoxy resin.

In a case, the polymer layer **36** may be formed by spin-on coating a negative-type photosensitive polyimide layer having a thickness between 6 and 50 micrometers on the passivation layer **14** and on the pads **16**, then baking the spin-on coated polyimide layer, then exposing the baked polyimide layer using a 1× stepper, 1× contact aligner or laser scanner with at least two of G-line having a wavelength ranging from 434 to 438 nm, H-line having a wavelength ranging from 403 to 407 nm, and I-line having a wavelength ranging from 363 to 367 nm, illuminating the baked polyimide layer, that is, G-line and H-line, G-line and I-line, H-line and I-line, or G-line, H-line and I-line illuminate the baked polyimide layer, then developing the exposed polyimide layer to form multiple openings exposing the pads **16**, then curing or heating the developed polyimide layer at a temperature between 180 and 400° C. or higher than or equal to 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. for a time between 20 and 150 minutes in a nitrogen ambient or in an oxygen-free ambient, the cured polyimide layer having a thickness between 3 and 30 micrometers, and then removing the residual polymeric material or other contaminants from the pads **16** with an O_2 plasma or a plasma containing fluorine of below 200 PPM and oxygen.

Thereby, referring to FIG. **15**I, the first type of micro-pillars or micro-bumps **34** may be formed on the metal pads **16** at bottoms of the openings **14***a* in the passivation layer **14**

and on the polymer layer **26** around the metal pads **16**. The specification of the micro-pillars or micro-bumps **34** as seen in FIG. **15**I may be referred to that of the micro-pillars or micro-bumps **34** as illustrated in FIG. **15**G. Each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of the polymer layer **26**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the first type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of the polymer layer **26**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Second Type of Micro-Bumps

Alternatively, FIGS. **15**J and **15**K are schematically cross-sectional views showing a second type of micro-bump or micro-pillar on chip in accordance with an embodiment of the present application. Referring to FIGS. **15**J and **15**K, the process for forming the second type of micro-bump or micro-pillar **34** may be referred to that for forming the fast type of micro-bump or micro-pillar **34** as seen in FIGS. **15**A-**15**I, but the difference therebetween is that the solder cap **33** formed for the first type of micro-bump or micro-pillar **34** as seen in FIGS. **15**E-**15**I is skipped not to be formed for the second type of micro-bump or micro-pillar **34**. Thus, the reflowing process for the first type of micro-bump or micro-pillar **34** as seen in FIG. **15**G may be skipped in the process for forming the second type of micro-bump or micro-pillar **34** as seen in FIGS. **15**J and **15**K.

Referring to FIG. **15**J, the adhesion layer **26**, electroplating seed layer **28**, electroplated metal layer **32** may compose the second type of micro-pillars or micro-bumps **34** on the metal pads **16** at bottoms of the openings **14***a* in the passivation layer **14**. Each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of the passivation layer **14**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the second type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of the passivation layer **14**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Referring to FIG. **15**K, the second type of micro-pillars or micro-bumps **34** may be formed on the metal pads **16** at bottoms of the openings **14***a* in the passivation layer **14** and on the polymer layer **26** around the metal pads **16**. Each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of the polymer layer **26**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the second type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of the polymer layer **26**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Embodiment for SISC over Passivation Layer

Alternatively, before the micro-bumps **34** are formed, a Second Interconnection Scheme in, on or of the Chip (SISC) may be formed on or over the passivation layer **14** and the FISC **20**. FIGS. **16**A-**16**D are schematically cross-sectional views showing a process for forming an interconnection

metal layer over a passivation layer in accordance with an embodiment of the present application.

Referring to FIG. **16**A, the process for fabricating the SISC over the passivation layer **14** may continue from the step shown in FIG. **15**C. A photoresist layer **38**, such as positive-type photoresist layer, having a thickness of between 1 and 50 μm is spin-on coated or laminated on the electroplating seed layer **28**. The photoresist layer **38** is patterned with the processes of exposure, development, etc., to form multiple trenches or openings **38***a* in the photoresist layer **38** exposing the electroplating seed layer **28**. A 1× stepper, 1× contact aligner or laser scanner may be used to expose the photoresist layer **38** with at least two of G-line having a wavelength ranging from 434 to 438 nm, H-line having a wavelength ranging from 403 to 407 nm, and I-line having a wavelength ranging from 363 to 367 nm, illuminating the photoresist layer **96**, that is, G-line and H-line, G-line and I-line, H-line and I-line, or G-line, H-line and I-line illuminate the photoresist layer **38**, then developing the exposed photoresist layer **38**, and then removing the residual polymeric material or other contaminants on the electroplating seed layer **28** with an O_2 plasma or a plasma containing fluorine of below 200 PPM and oxygen, such that the photoresist layer **38** may be patterned with multiple trenches or openings **38***a* in the photoresist layer **38** exposing the electroplating seed layer **28** for forming metal pads, lines or traces in the trenches or openings **38***a* and on the electroplating seed layer **28** by following processes to be performed later. One of the trenches or openings **38***a* in the photoresist layer **38** may overlap the whole area of one of the openings **14***a* in the passivation layer **14**.

Next, referring to FIG. **16**B, a metal layer **40**, such as copper, may be electroplated on the electroplating seed layer **28** exposed by the trenches or openings **38***a*. For example, the metal layer **40** may be formed by electroplating a copper layer with a thickness of between 0.3 and 20 μm, 0.5 and 5 μm, 1 μm and 10 μm or 2 μm and 10 μm on the electroplating seed layer **28**, made of copper, exposed by the trenches or openings **38***a*.

Referring to FIG. **16**C, after the metal layer **40** is formed, most of the photoresist layer **38** may be removed and then the electroplating seed layer **28** and adhesion layer **26** not under the metal layer **40** may be etched. The removing and etching processes may be referred respectively to the process for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the adhesion layer **26**, electroplating seed layer **28** and electroplated metal layer **40** may be patterned to form an interconnection metal layer **27** over the passivation layer **14**.

Next, referring to FIG. **16**D, a polymer layer **42**, i.e., insulting or inter-metal dielectric layer, is formed on the passivation layer **14** and metal layer **40** and multiple openings **42***a* in the polymer layer **42** are over multiple contact points of the interconnection metal layer **27**. The material of the polymer layer **42** and the process for forming the same may be referred to that of the polymer layer **36** and the process for forming the same as illustrated in FIG. **15**I.

The process for forming the interconnection metal layer **27** as illustrated in FIGS. **15**A, **15**B and **16**A-**16**C and the process for forming the polymer layer **42** as seen in FIG. **16**D may be alternately performed more than one times to fabricate the SISC **29** as seen in FIG. **17**. FIG. **17** is a cross-sectional view showing a second interconnection scheme of a chip (SISC) is formed with multiple interconnection metal layers **27** and multiple polymer layers **42** and **51**, i.e., insulating or inter-metal dielectric layers, alternatively arranged in accordance with an embodiment of the present application. Referring to FIG. **17**, the SISC **29** may include an upper one of the interconnection metal layers **27** formed with multiple metal vias **27***a* in the openings **42***a* in one of the polymer layers **42** and multiple metal pads, lines or traces **27***b* on said one of the polymer layers **42**. The upper one of the interconnection metal layers **27** may be connected to a lower one of the interconnection metal layers **27** through the metal vias **27***a* of the upper one of the interconnection metal layers **27** in the openings **42***a* in said one of the polymer layers **42**. The SISC **29** may include the bottommost one of the interconnection metal layers **27** formed with multiple metal vias **27***a* in the openings **14***a* in the passivation layer **14** and multiple metal pads, lines or traces **27***b* on the passivation layer **14**. The bottommost one of the interconnection metal layers **27** may be connected to the interconnection metal layers **6** of the FISC **20** through the metal vias **27***a* of the bottommost one of the interconnection metal layers **27** in the openings **14***a* in the passivation layer **14**.

Alternatively, referring to FIGS. **16**L, **16**M and **17**, a polymer layer **51** may be formed on the passivation layer **14** before the bottommost one of the interconnection metal layers **27** is formed. The material of the polymer layer **51** and the process for forming the same may be referred to the polymer layer **36** and the process for forming the same as shown in FIG. **15**L In this case, the SISC **29** may include the bottommost one of the interconnection metal layers **27** formed with multiple metal vias **27***a* in the openings **51***a* in the polymer layer **51** and multiple metal pads, lines or traces **27***b* on the polymer layer **51**. The bottommost one of the interconnection metal layers **27** may be connected to the interconnection metal layers **6** of the FISC **20** through the metal vias **27***a* of the bottommost one of the interconnection metal layers **27** in the openings **14***a* in the passivation layer **14** and in the openings **51***a* in the polymer layer **51**.

Accordingly, the SISC **29** may be optionally formed with 2 to 6 layers or 3 to 5 layers of interconnection metal layers **27** over the passivation layer **14**. For each of the interconnection metal layers **27** of the SISC **29**, its metal pads, line or traces **27***b* may have a thickness between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm or 2 μm and 10 μm, or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm and a width between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, 1 μm and 10 μm or 2 μm and 10 μm, or wider than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. Each of the polymer layers **42** and **51** may have a thickness between, for example, 0.3 μm and 20 μm, 0.5 μm and 10 μm, 1 μm and 5 μm, or 1 μm and 10 μm, or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm or 3 μm. The metal pads, lines or traces **27***b* of the interconnection metal layers **27** of the SISC **29** may be used for the programmable interconnects **202**.

FIGS. **16**E-**16**J are schematically cross-sectional views showing a process for forming a first type of micro-pillars or micro-bumps on an interconnection metal layer over a passivation layer in accordance with an embodiment of the present application. Referring to FIG. **16**E, an adhesion layer **44** may be sputtered on the polymer layer **42** and on the metal layer **40** exposed by the opening **42***a*. The specification of the adhesion layer **44** and the process for forming the same may be referred to that of the adhesion layer **26** and the process for forming the same as illustrated in FIG. **15**B. An electroplating seed layer **46** may be sputtered on the adhesion layer **44**. The specification of the electroplating seed layer **46** and the process for forming the same may be

referred to that of the electroplating seed layer **28** and the process for forming the same as illustrated in FIG. **15**C.

Next, referring to FIG. **16**F, a photoresist layer **48** is formed on the electroplating seed layer **46**. The photoresist layer **48** is patterned with the processes of exposure, development, etc., to form an opening **48***a* in the photoresist layer **48** exposing the electroplating seed layer **46**. The specification of the photoresist layer **48** and the process for forming the same may be referred to that of the photoresist layer **48** and the process for forming the same as illustrated in FIG. **15**D.

Next, referring to FIG. **16**G, a metal layer **50** is electroplated on the electroplating seed layer **46** exposed by the opening **48***a*. The specification of the metal layer **50** and the process for forming the same may be referred to that of the metal layer **32** and the process for forming the same as illustrated in FIG. **15**E. Next, a solder cap or layer **33** is electroplated on the metal layer **50** in the opening **48***a*. The specification of the solder cap **33** and the process for forming the same as illustrated herein may be referred to that of the solder cap **33** and the process for forming the same as illustrated in FIG. **15**E.

Next, referring to FIG. **16**H, most of the photoresist layer **48** may be removed and then the electroplating seed layer **46** and adhesion layer **44** not under the metal layer **50** may be etched. The processes for removing the photoresist layer **48** and etching electroplating seed layer **46** and adhesion layer **44** may be referred respectively to the processes for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F.

Next, referring to FIG. **16**I, the solder cap or layer **33** may be reflowed into multiple solder bumps. Thereby, the adhesion layer **44**, electroplating seed layer **46**, electroplated metal layer **50** and solder bumps **33** may compose the first type of micro-pillars or micro-bumps **34** on the topmost one of the interconnection metal layers **27** of the SISC **29** at bottoms of the openings **42***a* in the topmost one of the polymer layers **42** of the SISC **29**. The specification of the micro-pillars or micro-bumps **34** of the first type as seen in FIG. **16**I may be referred to that as illustrated in FIG. **15**G. Each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of a topmost one of the polymer layers **42** of the SISC **29**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the first type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the first type may have a height, protruding from a top surface of a topmost one of the polymer layers **42** of the SISC **29**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Alternatively, referring to FIG. **16**N, the second type of micro-bump or micro-pillar **34** as seen in FIG. **15**J or **15**K may be formed on the topmost one of the interconnection metal layers **27** of the SISC **29** at bottoms of the openings **42***a* in the topmost one of the polymer layers **42** of the SISC **29**. The adhesion layer **26**, electroplating seed layer **28**, electroplated metal layer **32** as seen in FIG. **15**J or **15**K may compose the second type of micro-pillars or micro-bumps **34**. Each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of a topmost one of the polymer layers **42** of the SISC **29**, between 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 1 μm and 15 μm, 5 μm and 15 μm, 1 μm and 10 μm or 3 μm and 10 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. The space from one of the micro-pillars or micro-bumps **34** of the second type to its nearest neighboring one of the micro-pillars or micro-bumps **34** is between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm. Alternatively, each of the micro-bumps **34** of the second type may have a height, protruding from a top surface of a topmost one of the polymer layers **42** of the SISC **29**, smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm, 5 μm or 3 μm, and a largest dimension in a horizontal cross-section (for example, the diameter of a circle shape, or the diagonal length of a square or rectangle shape) between, for example, 1 μm and 60 μm, 3 μm and 60 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 15 μm, 3 μm and 10 μm, 1 μm and 15 μm or 1 μm and 10 μm, or smaller than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, 10 μm or 5 μm.

Referring to FIG. **16**J, after the micro-pillars or micro-bumps **34** of the first or second type are formed over the semiconductor wafer as shown in FIG. **16**I, the semiconductor wafer may be separated, cut or diced into multiple individual semiconductor chips **100**, integrated circuit chips, by a laser cutting process or by a mechanical cutting process. These semiconductor chips **100** may be packaged using the following steps as shown in FIGS. **18**L-**18**W, **19**N-**19**T, **20**A, **20**B, **21**A, **21**B, **22**G-**22**O, **23**A-**23**C, **24**A-**24**F, **26**A-**26**M, **27**A-**27**D, **28**A-**28**C, **29**A-**29**F, **30**A-**30**C and **35**A-**35**D.

Referring to FIG. **16**K, the above-mentioned interconnection metal layers **27** may comprise a power interconnection metal trace or a ground interconnection metal trace to connect multiple of the metal pads **16** and to have the micro-pillars or micro-bumps **34** formed thereon. Referring to FIG. **16**M, the above-mentioned interconnection metal

layers **27** may comprise an interconnection metal trace to connect multiple of the metal pads **16** and to have no micro-pillar or micro-bump formed thereon.

Referring to FIGS. **16**J-**16**M and **17**, the interconnection metal layers **27** of the FISC **29** may be used for the programmable and fixed interconnects **361** and **364** of the intra-chip interconnects **502**, as seen in FIG. **8**A, of each of the standard commodity FPGA IC chips **200**.

Embodiment for Interposer for Multi-Chip-On-Interposer (COIP) Flip-Chip Packaging Method

Multiple semiconductor chips **100** as seen in FIGS. **15**H-**15**K, **16**J-**16**N and **17** may be mounted on an interposer. The interposer may be provided with high density interconnects for fan-out of the semiconductor chips **100** and interconnection between the semiconductor chips **100**.

FIGS. **18**A-**18**H are schematically cross-sectional views showing a process for forming a first type of vias in accordance with an embodiment of the present application. FIGS. **19**A-**19**J are schematically cross-sectional views showing a process for forming a second type of vias in accordance with an embodiment of the present application.

Referring to FIG. **18**A for forming the first type of vias, i.e., deep vias, or FIG. **19**A for forming the second type of vias, i.e., shallow vias, a substrate **552** may be provided in a wafer format with 8 inches, 12 inches or 18 inches in diameter or in a panel format having a square or rectangle shape with a width or a length greater than or equal to 20 cm, 30 cm, 50 cm, 75 cm, 100 cm, 150 cm, 200 cm or 300 cm. The substrate **552** may be a substrate of silicon, metal, ceramics, glass, steel, plastics, polymer, epoxy-based polymer, or epoxy-based compound. As an example, a silicon wafer may be used as the substrate **552** in forming the interposer.

Next, referring to FIG. **18**A or **19**A, a masking insulting layer **553** may be deposited on the substrate **552**, e.g., silicon wafer. The masking insulting layer **553** may include a thermally grown silicon oxide (SiO_2) and/or a CVD silicon nitride (Si_3N_4), for example. Subsequently, a photoresist layer **554**, such as positive-type photoresist layer, is spin-on coated on the masking insulting layer **553**. The photoresist layer **554** is patterned with the processes of exposure, development, etc., to form multiple openings **554***a* in the photoresist layer **554** exposing the masking insulting layer **553**.

Next, referring to FIG. **18**B for forming the first type of vias or FIG. **19**B for forming the second type of vias, the masking insulting layer **553** under the openings **554***a* may be removed with a dry etching method or a wet etching method to form multiple openings or holes **553***a* in the masking insulting layer **553** and under the openings **554***a*. For forming the first type of vias, each of the openings **553***a* as shown in FIG. **18**B may have a depth, in the masking insulting layer **553**, between 30 μm and 150 μm, or 50 μm and 100 μm, and a diameter or largest transverse size between 5 μm and 50 μm, or 5 μm and 15 μm. For forming the second type of vias, each of the openings **553***a* as shown in FIG. **19**B may have a depth, in the masking insulting layer **553**, between 5 μm and 50 μm, or 5 μm and 30 μm, and a diameter or largest transverse size between 20 μm and 150 μm or 30 μm and 80 μm.

Referring to FIG. **18**C for forming the first type of vias or FIG. **19**C for forming the second type of vias, the photoresist layer **554** is then removed. Next, using the masking insulting layer **553** as a mask, the substrate **552** under the openings **553***a* may be then removed with a dry etching method or a wet etching method to form multiple holes **552***a* in the substrate **552** and under the openings **553***a*, as seen in FIG. **18**C or **19**C.

For the first type of vias, referring to FIG. **18**C, each of the holes **552***a* may be a deep hole with a depth of between 30 μm and 150 μm or between 50 μm and 100 μm and with a diameter or size of between 5 μm and 50 μm or between 5 μm and 15 μm. For the second type of vias, referring to FIG. **19**C, each of the holes **552***a* may be a shallow hole with a depth of between 5 μm and 50 μm or between 5 μm and 30 μm and with a diameter or size of between 20 μm and 120 μm or between 20 μm and 80 μm.

Next, the masking insulting layer **553** may be removed as seen in FIG. **18**D for forming the first type of vias or FIG. **19**D for forming the second type of vias. Referring to FIG. **18**E for forming the first type of vias or FIG. **19**E for forming the second type of vias, an insulating layer **555** may be then formed on a sidewall and bottom of each of the holes **552***a* and a top surface **552***b* of the substrate **552**. The insulating layer **555** may include a thermally grown silicon oxide (SiO_2) and/or a CVD silicon nitride (Si_3N_4), for example.

Next, referring to FIG. **18**F for forming the first type of vias or FIG. **19**F for forming the second type of vias, an adhesion/seed layer **556** may be deposited on the insulating layer **555**. For forming the adhesion/seed layer **556**, an adhesion layer may be first formed by, for example, sputtering or Chemical Vapor Depositing (CVD) a titanium (Ti) or titanium nitride (TiN) layer (with thickness for example, between 1 nm and 50 nm) on the insulating layer **555**; next, an electroplating seed layer may be deposited on the adhesion layer by, for example, sputtering or CVD depositing a copper layer (with a thickness, for example, between 3 nm and 200 nm) on the adhesion layer. The adhesion layer and electroplating seed layer may compose the adhesion/seed layer **556**.

For the first type of vias, referring to FIG. **18**G, a copper layer **557** is then electroplated on the electroplating seed layer of the adhesion/seed layer **556** until the holes **552***a* are filled up with the copper layer **557**. Referring to FIG. **18**H, a chemical-mechanical polishing (CMP) process or mechanical polishing process may be applied to remove the copper layer **557**, adhesion/seed layer **556** and insulating layer **555** outside the holes **552***a* until the top surface **552***b* of the substrate **552** is exposed. Referring to FIG. **18**H, the remaining copper layer **557**, adhesion/seed layer **556** and insulating layer **555** in each of the holes **552***a* may compose one of the vias **558** of the first type. Each of the vias **558** of the first type may have a depth, in the substrate **552**, between 30 μm and 150 μm, or 50 μm and 100 μm, and a diameter or largest transverse size between 5 μm and 50 μm, or 5 μm and 15 μm.

For the second type of vias, referring to FIG. **19**G, a photoresist layer **559**, such as positive-type photoresist layer, is spin-on coated on the adhesion/seed layer **556**. The photoresist layer **559** is patterned with the processes of exposure, development, etc., to form multiple openings **559***a* in the photoresist layer **559** exposing the electroplating seed layer of the adhesion/seed layer **556** at a sidewall and bottom of each of the holes **552***a* and at an annular region of the top surface **552***b* around said each of the holes **552***a*. Next, referring to FIG. **19**H, a copper layer **557** is then electroplated on the electroplating seed layer of the adhesion/seed layer **556** until the holes **552***a* are filled up with the copper layer **557**. Next, the photoresist layer **559** is removed as seen in FIG. **19**I. Next, referring to FIG. **19**J, a chemical-mechanical polishing (CMP) process or mechanical polishing

process may be applied to remove the copper layer **557**, adhesion/seed layer **556** and insulating layer **555** outside the holes **552***a* until the top surface **552***b* of the substrate **552** is exposed. Referring to FIG. **19**J, the remaining copper layer **557**, adhesion/seed layer **556** and insulating layer **555** in each of the holes **552***a* may compose one of the vias **558** of the second type. Each of the vias **558** of the second type may have a depth, in the substrate **552**, between 5 μm and 50 μm, or 5 μm and 30 μm, and a diameter or largest transverse size between 20 μm and 150 μm or 30 μm and 80 μm.

Next, referring to FIG. **18**I for forming an interposer with the first type of vias **558** or FIG. **19**K for forming an interposer with the second type of vias **558**, a first interconnection scheme **560** for an interposer (FISIP) may formed over the substrate **552** by a wafer process. The FISIP **560** may comprise 2 to 10 layers, or 3 to 6 layers of interconnection metal layers **6** (only two layers are shown) patterned with multiple metal pads, lines or traces **8** and multiple metal vias **10** as illustrated in FIG. **14**A. The metal pads, lines or traces **8** and metal vias **10** of the FISIP **560** may be used for the programmable and fixed interconnects **361** and **364** of the inter-chip interconnects **371** as seen in FIGS. **11**A-**11**N. The FISIP **560** may include multiple insulating dielectric layers **12** and multiple interconnection metal layers **6** each in neighboring two of the insulating dielectric layers **12** as illustrated in FIG. **14**A. Each of the interconnection metal layers **6** of the FISIP **560** may include the metal pads, lines or traces **8** at a top portion thereof and the metal vias **10** at a bottom portion thereof. One of the insulating dielectric layers **12** of the FISIP **560** may be between the metal pads, lines or traces **8** of neighboring two of the interconnection metal layers **6**, a top one of which may have the metal vias **10** in said one of the insulating dielectric layers **12**. For each of the interconnection metal layers **6** of the FISIP **560**, its metal pads, lines or traces **8** may have a thickness t**11** of between 3 nm and 500 nm, between 10 nm and 1,000 nm, between 10 nm and 2,000 nm or between 10 nm and 3,000 nm, or thinner than or equal to 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm and may have a minimum width equal to or smaller than 10 nm, 50 nm, 100 nm, 150 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm; a minimum space between neighboring two of its metal pads, lines or traces **8** may be equal to or smaller than 10 nm, 50 nm, 100 nm, 150 nm, 200 nm, 300 nm, 500 nm, 1,000 nm, 1,500 nm or 2,000 nm; a minimum pitch of neighboring two of its metal pads, lines or traces **8** may be equal to or smaller than 20 nm, 100 nm, 200 nm, 300 nm, 400 nm, 600 nm, 1,000 nm, 3,000 nm or 4,000 nm. For example, the metal pads, lines or traces **8** and metal vias **10** are principally made of copper by a damascene process such as single-damascene process as mentioned in FIGS. **14**B-**14**H or double-damascene process as mentioned in FIGS. **14**I-**14**Q. For each of the interconnection metal layers **6** of the FISIP **560**, its metal pads, lines or traces **8** may include a copper layer having a thickness of less than 3 μm (such as between 0.2 and 2 μm). Each of the insulating dielectric layers **12** of the FISIP **560** may have a thickness, for example, between 3 nm and 500 nm, between 10 nm and 1,000 nm, between 10 nm and 2,000 nm or between 10 nm and 3,000 nm, or thinner than or equal to 10 nm, 30 nm, 50 nm, 100 nm, 200 nm, 300 nm, 500 μm, 1,000 nm or 2,000 nm.

The process for forming the FISIP **560** may be referred to the process for forming the FISC **20** as illustrated in FIGS. **14**B-**14**H for the single-damascene process. Alternatively, the process for forming the FISIP **560** may be referred to the process for forming the FISC **20** as illustrated in FIGS. **14**I-**14**Q for the double-damascene process.

Referring to FIG. **18**I or **19**K, a passivation layer **14** as illustrated in FIG. **14**A may be formed over the FISIP **560**. The passivation layer **14** may protect the interconnection metal layers **6** of the FISIP **560** from being damaged by moisture foreign ion contamination, or from water moisture or contamination form external environment, for example sodium mobile ions. In other words, mobile ions (such as sodium ion), transition metals (such as gold, silver and copper) and impurities may be prevented from penetrating through the passivation layer **14** to the interconnection metal layers **6** of the FISIP **560**.

Referring to FIG. **18**I or **19**K, the specification for the passivation layer **14** for the interposer and the process for forming the same may be referred to those for the semiconductor chip **100** as illustrated in FIG. **14**A. An opening **14***a* in the passivation layer **14** is formed to expose a metal pad **16** of a topmost one of the interconnection metal layers **6** of the FISIP **560**. The metal pad **16** of the FISIP **560** may be used for signal transmission or for connection to a power source or a ground reference. The specification for the openings **14***a* and metal pad **16** for the interposer and the process for forming the same may be referred to those for the semiconductor chip **100** as illustrated in FIG. **14**A. Further, there may be one of the vias **558** vertically under one of the metal pad **16** exposed by one of the openings **14***a*.

Optionally, referring to FIG. **18**I or **19**K, a polymer layer, like the one **36** as illustrated in FIG. **15**I, may be formed on the passivation layer **14**. Each opening in the polymer layer may expose one of the metal pads **16** at bottoms of the openings **14***a*.

Optionally, referring to FIG. **18**I or **19**K, a second interconnection scheme **588** for the interposer (SISIP) may be formed over the passivation layer **14** for the interposer as seen in FIG. **18**I or **19**K. The specification for the SISIP **588** and the process for forming the same may be referred to the specification for the SISC **29** and the process for forming the same as illustrated in FIGS. **16**A-**16**N and **17**. The SISIP **588** may include one or more interconnection metal layers **27** as illustrated in FIGS. **16**J-**16**M and **17** and one or more dielectric or polymer layers **42** and/or **51** as illustrated in FIGS. **16**J-**16**N and **17**. For example, the SISIP **588** may include the polymer layer **51** as illustrated in FIGS. **16**L, **16**M and **17** directly on the passivation layer **14** and under the bottommost one of its one or more interconnection metal layers **27**. The SISIP **588** may include one of the polymer layers **42** as illustrated in FIG. **17** between neighboring two of its interconnection metal layers **27**. The SISIP **588** may include one of the polymer layers **42** as illustrated in FIGS. **16**J-**16**N and **17** on the topmost one of its one or more interconnection metal layers **27**. Each of the interconnection metal layers **27** of the SISIP **588** may include the adhesion layer **26**, the electroplating seed layer **28** on the adhesion layer **26** and the metal layer **40** on the electroplating seed layer **28** as illustrated in FIGS. **16**J-**16**N and **17**, wherein an adhesion/seed layer **589** herein may represent a combination of the adhesion layer **26** and the electroplating seed layer **28**. The interconnection metal layers **27** of the SISIP **588** may be used for the programmable and fixed interconnects **361** and **364** of the inter-chip interconnects **371** as seen in FIGS. **11**A-**11**N. The SISIP **588** may include 1 to 5 layers, or 1 to 3 layers, of interconnection metal layers.

Micro-Bumps M Front Side of Interposer

Next, referring to FIG. **18**J for forming an interposer **551** with the first type of vias **558** or FIG. **19**L for forming an interposer **551** with the second type of vias **558**, multiple

micro-bumps **34** of the first or second type as illustrated in FIGS. **15**A-**15**K and **16**E-**16**N may be formed on the topmost one of the interconnection metal layers **27** of the SISIP **588** or the topmost one of the interconnection metal layers **6** of the FISIP **560**. The specification for the micro bumps **34** of the first or second type for the interposer **551** and the process for forming the same may be referred to those for the semiconductor chip **100** as illustrated in FIGS. **15**A-**15**K and **16**E-**16**N.

Referring to FIG. **18**K or **19**M, an interconnection scheme **561** may be composed of the FISIP **560** and passivation layer **14** as illustrated in FIG. **18**I or **19**K, and each of the micro-bumps **34** of the first or second type as illustrated in FIGS. **15**A-**15**K and **16**E-**16**N may have the adhesion layer **26** formed on one of the metal pads **16** and on the passivation layer **14** around one of the openings **14***a*.

Alternatively, referring to FIG. **18**K or **19**M, the interconnection scheme **561** may be composed of the FISIP **560** and passivation layer **14** as illustrated in FIG. **18**I or **19**K and further of a polymer layer, like the one **36** as seen in FIG. **15**I, on the passivation layer **14**, wherein each opening in the polymer layer, like the one **36***a* as seen in FIG. **15**I, may expose one of the metal pads **16**, and each of the micro-bumps **34** of the first or second type as illustrated in FIGS. **15**A-**15**K and **16**E-**16**N may have the adhesion layer **26** formed on one of the metal pads **16** and on the polymer layer around one of the openings in the polymer layer.

Alternatively, referring to FIG. **18**K or **19**M, the interconnection scheme **561** may be composed of the FISIP **560** and passivation layer **14** as illustrated in FIG. **18**I or **19**K and further of the SISIP **588** as illustrated in FIGS. **16**J-**16**N and **17** over the passivation layer **14**, wherein each opening **42***a* in a topmost one of the polymer layers **42** of the SISIP **588** may expose a metal pad of a topmost one of the interconnection metal layers **27** of the SISIP **588** and each of the micro-bumps **34** of the first or second type as illustrated in FIGS. **15**A-**15**K and **16**E-**16**N may have the adhesion layer **26** formed on one of the metal pad and on the topmost one of the polymer layers **42** around one of the openings **42***a* in the topmost one of the polymer layers **42**.

In FIG. **18**J or **19**L, the second type of micro-bumps **34** are shown to be formed on the topmost one of the interconnection metal layers **27** of the SISIP **588** of the interconnection scheme **561**. For explaining the subsequent processes, the interconnection scheme **561** is simplified as seen in FIG. **18**K or **19**M.

Chip-to-Interposer Assembly for Multi-Chip-On-Interposer (COIP) Flip-Chip Packaging Method

FIGS. **18**K-**18**W and **19**M-**19**T are schematic views showing two processes for forming a COIP logic drive in accordance with two embodiments of the present application. Next, each of the semiconductor chips **100** as seen in FIGS. **15**H-**15**K, **16**J-**16**N or **17** may have the micro-bumps **34** of the first or second type to be bonded to the first or second type of micro-bumps **34** of the interposer **551** as seen in FIG. **18**K or **19**M.

For a first case, referring to FIG. **18**L or **19**N, each of the semiconductor chips **100** as seen in FIGS. **15**I, **16**J-**16**M or **17** may have the micro-bumps **34** of the first type to be bonded to the second type of micro-bumps **34** of the interposer **551**. For example, the first type of micro-bumps **34** of said each of the semiconductor chips **100** may have the solder bumps **33** to be bonded onto the electroplated copper layer of the micro-bumps **34** of the second type of the interposer **551** into multiple bonded contacts **563** as seen in FIG. **18**M or **19**O, wherein each of micro-bumps **34** of the first type of said each of the semiconductor chips **100** may have its metal layer **32** formed with the electroplated copper layer having a thickness greater than that of the electroplated copper layer of the metal layer **32** of each of the micro-bumps **34** of the second type of the interposer **551**.

For a second case, each of the semiconductor chips **100** as seen in FIGS. **15**J, **15**K and **16**N may have the micro-bumps **34** of the second type to be bonded to the first type of micro-bumps **34** of the interposer **551**. For example, the second type of micro-bumps **34** of said each of the semiconductor chips **100** may have the electroplated metal layer **32**, e.g. copper layer, to be bonded onto the solder caps **33** of the micro-bumps **34** of the first type of the interposer **551** into multiple bonded contacts **563** as seen in FIG. **18**M or **19**O, wherein each of micro-bumps **34** of the second type of said each of the semiconductor chips **100** may have its metal layer **32** formed with the electroplated copper layer having a thickness greater than that of the electroplated copper layer of the metal layer **32** of each of the micro-bumps **34** of the first type of the interposer **551**.

For a third case, referring to FIG. **18**L or **19**N, each of the semiconductor chips **100** as seen in FIGS. **15**I, **16**J-**16**M or **17** may have the micro-bumps **34** of the first type to be bonded to the first type of micro-bumps **34** of the interposer **551**. For example, the first type of micro-bumps **34** of said each of the semiconductor chips **100** may have the solder bumps **33** to be bonded onto the solder caps **33** of the micro-bumps **34** of the first type of the interposer **551** into multiple bonded contacts **563** as seen in FIG. **18**M or **19**O, wherein each of micro-bumps **34** of the first type of said each of the semiconductor chips **100** may have its metal layer **32** formed with the electroplated copper layer having a thickness greater than that of the electroplated copper layer of the metal layer **32** of each of the micro-bumps **34** of the first type of the interposer **551**.

In view of the logic drives **300** shown in FIGS. **11**A-**11**N, each of the semiconductor chips **100** may be one of the standard commodity FPGA IC chips **200**, DPIIC chips **410**, NVM IC chips **250**, HBM IC chips **251**, dedicated I/O chips **265**, PCIC chips **269** (such as CPU chips, GPU chips, TPU chips or APU chips), DRAM IC chips **321**, dedicated control chips **260**, dedicated control and I/O chips **266**, IAC chips **402**, DCIAC chips **267** and DCDI/OIAC chips **268**. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the GPU chip **269** arranged respectively from left to right. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the CPU chip **269** arranged respectively from left to right. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the dedicated control chip **260** arranged respectively from left to right. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be two of the standard commodity FPGA IC chips **200** respectively. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the NVM IC chip **250** arranged respectively from left to right. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the DRAM IC chip **321** arranged respectively from left to right. For example, the two semiconductor chips **100** shown in FIG. **18**L or **19**N may be the standard commodity FPGA IC chip **200** and the HBM IC chip **251** arranged respectively from left to right.

Next, referring to FIG. **18**M or **19**O, an underfill **564**, such as epoxy resins or compounds, may be filled into a gap

between each of the semiconductor chips **100** and the interposer **551** by a dispensing method performed using a dispenser. The underfill **564** may then be cured at temperature equal to or above 100° C., 120° C., or 150° C.

Next, referring to FIG. **18**N following the step of FIG. **18**M or FIG. **19**P following the step of FIG. **19**O, a polymer layer **565**, e.g., resin or compound, may be applied to fill the gaps between the semiconductor chips **100** and cover the backsides **100***a* of the semiconductor chips **100** by methods, for example, spin-on coating, screen-printing, dispensing or molding in a wafer or panel format. For the molding method, a compress molding method (using top and bottom pieces of molds) or casting molding (using a dispenser) may be employed. The polymer layer **565** may be, for example, polyimide, BenzoCycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer, or silicone. For more elaboration, the polymer layer **565** may be, for example, photosensitive polyimide/PBO PIMEL® supplied by Asahi Kasei Corporation, Japan, or epoxy-based molding compounds, resins or sealants provided by Nagase ChemteX Corporation, Japan. The polymer layer **565** may be then cured or cross-linked by raising a temperature to a certain temperature degree, for example, higher than or equal to 50° C., 70° C., 90° C., 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C.

Next, referring to FIG. **18**O following the step of FIG. **18**N or FIG. **19**Q following the step of FIG. **19**P, a chemical mechanical polishing (CMP), polishing or grinding process may be applied to remove a top portion of the polymer layer **565** and top portions of the semiconductor chips **100** and to planarize a top surface of the polymer layer **565** until all of the backsides **100***a* of the semiconductor chips **100** are fully exposed or until the backside **100***a* of one of the semiconductor chips **100** is exposed.

Next, referring to FIG. **18**P following the step of FIG. **18**O or FIG. **19**R following the step of FIG. **19**Q, the interposer **551** has a backside **551***a* to be polished by a CMP process or a wafer backside grinding process until each of the vias **558** is exposed, that is, its insulating layer **555** at its backside is removed into an insulating lining surrounding its adhesion/seed layer **556** and copper layer **557**, and a backside of its copper layer **557** or a backside of the adhesion layer or electroplating seed layer of its adhesion/seed layer **556** is exposed.

Referring to FIG. **18**Q following the step of FIG. **18**P, a polymer layer **585**, i.e., insulating dielectric layer, may be formed on the backside **551***a* of the interposer **551** and the backsides of the vias **558** by a method of spin-on coating, screen-printing, dispensing or molding, and multiple openings **585***a* in the polymer layer **585** may be formed over the vias **558** to be exposed by the openings **585***a*. The polymer layer **585** may contain, for example, polyimide, BenzoCycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer or silicone. The polymer layer **585** may comprise organic material, for example, a polymer, or materials or compounds comprising carbon. The polymer layer **585** may be photosensitive, and may be used as photoresist as well for patterning multiple openings **585***a* therein to expose the vias **558**. That is, the polymer layer **585** may be coated, exposed to light through a photomask, and then developed to form the openings **585***a* therein. The openings **585***a* in the polymer layer **585** overlap the top surfaces of the vias **558** respectively to be exposed by the openings **585***a*. In some applications or designs, the size or transverse largest dimension of one of the openings **585***a* in the polymer layer **585** may be smaller than that of the area of the backside of one of the vias **558** under said one of the openings **585***a*. In other applications or designs, the size or transverse largest dimension of one of the openings **585***a* in the polymer layer **585** may be greater than that of the area of the backside of one of the vias **558** under said one of the openings **585***a*. Next, the polymer layer **585**, i.e., insulating dielectric layer, is cured at a temperature, for example, equal to or higher than 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. The polymer layer **585** has a thickness between 3 and 30 micrometers or between 5 and 15 micrometers. The polymer layer **585** may be added with some dielectric particles or glass fibers. The material of the polymer layer **585** and the process for forming the same may be referred to that of the polymer layer **36** and the process for forming the same as illustrated in FIG. **15**I.

Metal Bumps at Backside of Interposer for Multi-Chip-On-Interposer (COIP) Flip-Chip Packaging Method

Next, multiple metal pads, pillars or bumps may be formed on a backside of the interposer **551**, as seen in FIGS. **18**R-**18**V. FIGS. **18**R-**18**V are schematically cross-sectional views showing a process for forming metal pads, pillars or bumps on vias in an interposer in accordance with an embodiment of the present application.

Referring to FIG. **18**R, an adhesion/seed layer **566** is formed on the polymer layer **585** and on the backside of the vias **558**. With regard to the adhesion/seed layer **566**, an adhesion layer **566***a* having a thickness of between 0.001 and 0.7 μm, between 0.01 and 0.5 μm or between 0.03 and 0.35 μm may be first sputtered on the polymer layer **585** and on the copper layer **557**, or the adhesion layer or electroplating seed layer of the adhesion/seed layer **556**, at the backsides of the vias **558**. With regard to the adhesion/seed layer **566**, the material of its adhesion layer **566***a* may include titanium, a titanium-tungsten alloy, titanium nitride, chromium, titanium-tungsten-alloy layer, tantalum nitride, or a composite of the abovementioned materials. The adhesion layer **566***a* may be formed by an atomic-layer-deposition (ALD) process, chemical vapor deposition (CVD) process or evaporation process. For example, its adhesion layer **566***a* may be formed by sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm or between 5 nm and 50 nm) on the polymer layer **585** and on the copper layer **557**, or the adhesion layer or electroplating seed layer of the adhesion/seed layer **556**, at the backsides of the vias **558**.

Next, with regard to the adhesion/seed layer **566**, an electroplating seed layer **566***b* having a thickness of between 0.001 and 1 μm, between 0.03 and 2 μm or between 0.05 and 0.5 μm may be sputtered on a whole top surface of its adhesion layer **566***a*. Alternatively, the electroplating seed layer **566***b* may be formed by an atomic-layer-deposition (ALD) process, chemical-vapor-deposition (CVD) process, vapor deposition method, electroless plating method or PVD (Physical Vapor Deposition) method. The electroplating seed layer **566***b* is beneficial to electroplating a metal layer thereon. Thus, the material of the electroplating seed layer **5666** varies with the material of a metal layer to be electroplated on the electroplating seed layer **566***b*. When a copper layer, for a first type of metal bumps **570** to be formed in the following steps, is to be electroplated on the electroplating seed layer **566***b*, copper is a preferable material to the electroplating seed layer **5666**. When a copper barrier layer, for multiple metal pads **571** to be formed in the following steps or for a second type of metal bumps **570** to be formed in the following steps, is to be electroplated on the electroplating seed layer **566***b*, copper is a preferable mate-

rial to the electroplating seed layer **5666**. When a gold layer, for a third type of metal bumps **570** to be formed in the following steps, is to be electroplated on the electroplating seed layer **5666**, gold is a preferable material to the electroplating seed layer **5666**. For example, the electroplating seed layer **566***b*, for the metal pads **571** or first or second type of metal bumps **570** to be formed in the following steps, may be deposited on or over the adhesion layer **566***a* by, for example, sputtering or CVD depositing a copper seed layer (with a thickness between, for example, 3 nm and 400 nm or 10 nm and 200 nm) on the adhesion layer **566***a*. The electroplating seed layer **566***b*, for the third type of metal bumps **570** to be formed in the following steps, may be deposited on or over the adhesion layer **566***a* by, for example, sputtering or CVD depositing a gold seed layer (with a thickness between, for example, 1 nm and 300 nm or 1 nm and 50 nm) on the adhesion layer **566***a*. The adhesion layer **566***a* and electroplating seed layer **5666** compose the adhesion/seed layer **566** as seen in FIG. **18**Q.

Next, referring to **18**S, a photoresist layer **567**, such as positive-type photoresist layer, having a thickness of between 5 and 500 μm is spin-on coated or laminated on the electroplating seed layer **5666** of the adhesion/seed layer **566**. The photoresist layer **567** is patterned with the processes of exposure, development, etc., to form multiple openings **567***a* in the photoresist layer **567** exposing the electroplating seed layer **566***b* of the adhesion/seed layer **566**. A 1× stepper, 1× contact aligner or laser scanner may be used to expose the photoresist layer **567** with at least two of G-line having a wavelength ranging from 434 to 438 nm, H-line having a wavelength ranging from 403 to 407 nm, and I-line having a wavelength ranging from 363 to 367 nm, illuminating the photoresist layer **567**, that is, G-line and H-line, G-line and I-line, H-line and I-line, or G-line, H-line and I-line illuminate the photoresist layer **567**, then developing the exposed photoresist layer **567**, and then removing the residual polymeric material or other contaminants on the electroplating seed layer **566***b* of the adhesion/seed layer **566** with an O_2 plasma or a plasma containing fluorine of below 200 PPM and oxygen, such that the photoresist layer **567** may be patterned with multiple openings **567***a* in the photoresist layer **567** exposing the electroplating seed layer **5666** of the adhesion/seed layer **566** over the vias **558**.

Referring to FIG. **18**S, one of the openings **567***a* in the photoresist layer **567** may overlap one of the openings **585***a* in the polymer layer **585** for forming one of metal pads or bumps by following processes to be performed later, exposing the electroplating seed layer **566***b* of the adhesion/seed layer **566** at the bottom of said one of the openings **567***a*, and may extend out of said one of the openings **585***a* to an area or ring of the polymer layer **585** around said one of the openings **585***a*.

Referring to FIG. **18**T, a metal layer **568** is electroplated on the electroplating seed layer **566***b* of the adhesion/seed layer **566** exposed by the openings **567***a*. For forming multiple metal pads, the metal layer **568** may be formed by electroplating a copper barrier layer, such as nickel layer, with a thickness, for example, between 1 μm and 50 μm, 1 μm and 40 μm, 1 μm and 30 μm, 1 μm and 20 μm, 1 μm and 10 μm, 1 μm and 5 μm or 1 μm and 3 μm on the electroplating seed layer **5666**, made of copper, exposed by the openings **567***a*.

Referring to FIG. **18**U, after the metal layer **568** is formed, most of the photoresist layer **567** may be removed and then the adhesion/seed layer **566** not under the metal layer **568** may be etched. The removing and etching processes may be referred respectively to the processes for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the adhesion/seed layer **566** and electroplated metal layer **568** may be patterned to form multiple metal pads **571** on the vias **558** and on the polymer layer **585**. Each of the metal pads **571** may be composed of the adhesion/seed layer **566** and the electroplated metal layer **568** on the electroplating seed layer **5666** of the adhesion/seed layer **566**.

Next, referring to FIG. **18**V, multiple solder bumps **569** may be formed on the metal pads **571** by a screen printing method or a solder-ball mounting method, and then by a solder reflow process. The solder bumps **569** may be a lead-free solder containing tin, copper, silver, bismuth, indium, zinc, antimony, and/or traces of other metals, for example, Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn—Ag Cu—Zn solder. The solder bumps **569** and metal pads **571** may compose a fourth type of metal bumps **570**. One of the metal bumps **570** of the fourth type are used for connecting or coupling one of the semiconductor chips **100**, such as the dedicated I/O chip **265** as seen in FIGS. **11**A-**11**N, of the logic drive **300** to the external circuits or components outside of the logic drive **300** through one of the bonded contacts **563**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interconnection scheme **561** of the interposer **551** and one of the vias **558** of the interposer **551** in sequence. Each of the metal bumps **570** of the fourth type may have a height, protruding from a backside surface of the interposer **551** or a backside surface **585***b* of the polymer layer **585**, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm or between 10 μm and 30 μm, or greater or taller than or equal to 75 μm, 50 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example, and a largest dimension in cross-sections, such as a diameter of a circle shape or a diagonal length of a square or rectangle shape, between 5 μm and 200 μm, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example. The smallest space from one of the solder bumps **569** to its nearest neighboring one of the solder bumps **569** is, for example, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

Alternatively, for the first type of metal pillars or bumps **570**, the metal layer **568** as seen in FIG. **18**T may be formed by electroplating a copper layer with a thickness of between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm on the electroplating seed layer **566***b*, made of copper, exposed by the openings **567***a*.

Referring to FIG. **18**U, after the metal layer **568** is formed, most of the photoresist layer **567** may be removed and then the adhesion/seed layer **566** not under the metal layer **568** may be etched. The removing and etching processes may be referred respectively to the processes for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the adhesion/seed layer **566** and electroplated metal layer **568** may be patterned to form the first type of metal bumps **570** on the vias **558** and on the polymer layer **585**. Each of the metal pillars or bumps **570** of the first

type may be composed of the adhesion/seed layer **566** and the electroplated metal layer **568** on the adhesion/seed layer **566**.

The first type of metal pillars or bumps **570** may have a height, protruding from a backside surface of the interposer **551** or a backside surface **585***b* of the polymer layer **585**, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm or 10 μm and 30 μm, or greater or taller than or equal to 50 μm, 30 μm, 20 μm, 15 μm, or 5 μm, and a largest dimension in a cross-section (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape), for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm or 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm. The smallest space between neighboring two of the metal pillars or bumps **570** of the first type may be, for example, between 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm or 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

Alternatively, for a second type of metal pillars or bumps **570**, the metal layer **568** as seen in FIG. **18**T may be formed by electroplating a copper barrier layer, such as nickel layer, with a thickness, for example, between 1 μm and 50 μm, 1 μm and 40 μm, 1 μm and 30 μm, 1 μm and 20 μm, 1 μm and 10 μm, 1 μm and 5 μm or 1 μm and 3 μm on the electroplating seed layer **566***b*, made of copper, exposed by the openings **657***a*, and then electroplating a solder layer with a thickness, for example, between 1 μm and 150 μm, 1 μm and 120 μm, 5 μm and 120 μm, 5 μm and 100 μm, 5 μm and 75 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 5 μm and 20 μm, 5 μm and 10 μm, 1 μm and 5 μm, or 1 μm and 3 μm on the copper barrier layer in the openings **657***a*. The solder layer may be a lead-free solder containing tin, copper, silver, bismuth, indium, zinc, antimony, and/or traces of other metals, for example, Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn—Ag—Cu—Zn solder. Furthermore, after most of the photoresist layer **567** is removed and the adhesion/seed layer **566** not under the metal layer **568** is etched as seen in FIG. **18**U, a reflow process may be performed to reflow the solder layer into multiple solder balls or bumps in a circular shape for the second type of metal bumps. Thereby, each of the metal pillars or bumps **570** of the second type formed on one of the vias **558** and on the polymer layer **585** may be composed of the adhesion/seed layer **566**, the copper barrier layer on the adhesion/seed layer **566** and one of the solder balls or bumps on the copper barrier layer.

The second type of metal pillars or bumps **570** may have a height, protruding from a backside surface of the interposer **551** or a backside surface **585***b* of the polymer layer **585**, between 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater or taller than or equal to 75 μm, 50 μm, 30 μm, 20 μm, 15 μm, or 10 μm and a largest dimension in a cross-section (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape), for example, between 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater than or equal to 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between neighboring two of the metal pillars or bumps **570** of the second type may be, for example, between 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

Alternatively, for a third type of metal pillars or bumps **570**, the electroplating seed layer **5666** as illustrated in FIG. **18**R may be formed by sputtering or CVD depositing a gold seed layer (with a thickness, for example, between 1 μm and 300 μm, or 1 nm and 100 nm) on the adhesion layer **566***a* as illustrated in FIG. **18**R. The adhesion layer **566***a* and electroplating seed layer **566***b* compose the adhesion/seed layer **566** as seen in FIG. **18**R. The metal layer **568**, as seen in FIG. **18**T, may be formed by electroplating a gold layer with a thickness, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm on the electroplating seed layer **5666**, made of gold, exposed by the openings **567***a*. Next, most of the photoresist layer **567** may be removed and then the adhesion/seed layer **566** not under the metal layer **568** may be etched to form the third type of metal bumps on the vias **558** and on the polymer layer **585**. Each of the metal pillars or bumps **570** of the third type may be composed of the adhesion/seed layer **566** and the electroplated gold layer **568** on the adhesion/seed layer **566**.

The third type of metal pillars or bumps **570** may have a height, protruding from a backside surface of the interposer **551** or a backside surface **585***b* of the polymer layer **585**, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller or shorter than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm and a largest dimension in a cross-section (for example, the diameter of a circle shape or the diagonal length of a square or rectangle shape), for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm. The smallest space between neighboring two of the metal pillars or bumps **570** of the third type may be, for example, between 3 μm and 40 μm, 3 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm, or smaller than or equal to 40 μm, 30 μm, 20 μm, 15 μm, or 10 μm.

One of the metal bumps of the first, second or third type may be used for connecting or coupling one of the semiconductor chips **100**, such as the dedicated I/O chip **265** as seen in FIGS. **11**A-**11**N, of the logic drive **300** to the external circuits or components outside of the logic drive **300** through one of the bonded contacts **563**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interconnection scheme **561** of the interposer **551** and one of the vias **558** of the interposer **551** in sequence.

Besides, FIG. **19**S is a schematically cross-sectional view showing a process for forming metal pillars or bumps on backsides of vias of a second type in an interposer in accordance with an embodiment of the present application. Referring to FIG. **19**S following the step of FIG. **19**R, multiple solder bumps may be formed into a fifth type of metal bumps **570** on the backside surfaces of the vias **558** by a screen printing method or a solder-ball mounting method, and then by a solder reflow process. The material used for forming the solder bumps for the fifth type of metal bumps **570** may be a lead-free solder containing tin, copper, silver, bismuth, indium, zinc, antimony, and/or traces of other metals, for example, Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn—Ag—Cu—Zn solder. One of the metal bumps **570** of the fifth type may be used for connecting or coupling one of the semiconductor chips **100**, such as the dedicated I/O chip **265** as seen in FIGS. **11**A-**11**N, of the logic drive **300** to the external circuits or components outside of the logic drive **300** through one of the bonded contacts **563**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interconnection scheme **561** of the

interposer **551** and one of the vias **558** of the interposer **551** in sequence. Each of the metal bumps **570** of the fifth type may have a height, from a backside surface of the interposer **551**, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm or between 10 μm and 30 μm, or greater or taller than or equal to 75 μm, 50 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example, and a largest dimension in cross-sections, such as a diameter of a circle shape or a diagonal length of a square or rectangle shape, between 5 μm and 200 μm, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example. The smallest space from one of the metal bumps **570** of the fifth type to its nearest neighboring one of the metal bumps **570** of the fifth type is, for example, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

Singulation for Multi-Chip-On-Interposer (COIP) Flip-Chip Packaging Method

Next, the package structure shown in FIG. **18**V or **19**S may be separated, cut or diced into multiple individual chip packages, i.e., standard commodity COIP logic drives **300** or single-layer-packaged logic drive, as shown in FIG. **18**W or **19**T by a laser cutting process or by a mechanical cutting process.

The standard commodity COIP logic drive **300** may be in a shape of square or rectangle with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the standard commodity COIP logic drive **300**. For example, the standard shape of the COIP logic drive **300** may be a square with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the standard commodity COIP logic drive **300** may be a rectangle with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm, and a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Furthermore, the metal bumps or pillars **570** at a backside of the interposer **551** in the logic drive **300** may be in a standard footprint, for example, in an area array of M×N with a standard dimension of pitch and space between neighboring two of the metal bumps or pillars **570**. The locations of the metal bumps or pillars **570** are also at a standard location.

Interconnection for COIP Logic Drive

FIGS. **20**A and **20**B are schematically cross-sectional views showing various interconnection for an interposer arranged with a first type of vias in accordance with an embodiment of the present application; the first, second, third, fourth or fifth type of metal bumps **570** may be formed on the first type of vias **558** of the interposer **551**. For illustration, the fourth type of metal bumps **570** is taken as an example in FIGS. **20**A and **20**B. FIGS. **21**A and **21**B are schematically cross-sectional views showing various interconnection for an interposer arranged with a second type of vias in accordance with an embodiment of the present application; the first, second, third, fourth or fifth type of metal bumps **570** may be formed on the second type of vias **558** of the interposer **551**. For illustration, the fifth type of metal bumps **570** is taken as an example in FIGS. **21**A and **21**B.

Referring to FIGS. **20**A and **21**A, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551** and one or more of the vias **558** of the interposer **551** may connect one or more of the metal pillars or bumps **570** to one of the semiconductor chips **100** and connect one of the semiconductor chips **100** to another of the semiconductor chips **100**. For a first case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a first interconnection net **573** connecting multiple of the metal pillars or bumps **570** to each other or one another and connecting multiple of the semiconductor chips **100** to each other or one another. Said multiple of the metal pillars or bumps **570** and said multiple of the semiconductor chips **100** may be connected together by the first interconnection net **573**. The first interconnection net **573** may be a power or ground plane or bus for delivering power or ground supply.

Referring to FIGS. **20**A and **21**A, for a second case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and one or more of the vias **558** of the interposer **551** may compose a second interconnection net **574** connecting one or more of the metal pillars or bumps **570** to each other or one another and connecting multiple of the bonded contacts **563** between one of the semiconductor chips **100** and the interposer **551** to each other or one another. Said multiple of the metal pillars or bumps **570** and said multiple of the bonded contacts **563** may be connected together by the second interconnection net **574**. The second interconnection net **574** may be a power or ground plane or bus for delivering power or ground supply.

Referring to FIGS. **20**A and **21**A, for a third case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and one of the vias **558** of the interposer **551** may compose a third interconnection net **575** connecting one of the metal pillars or bumps **570** to one of the bonded contacts **563** between one of the semiconductor chips **100** and the interposer **551**. The third interconnection net **575** may be a signal bus or trace for signal transmission or a power or ground plane or bus for delivering power or ground supply. For example, the third interconnection net **575** may be a signal bus or trace coupling to one of the large I/O circuits **341**, as seen in FIG. **5**A, of said one of the semiconductor chips **100** via said one of the bonded contacts **563**.

Referring to FIGS. **20**B and **21**B, for a fourth case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a fourth interconnection net **576** not connecting to any of the metal pillars or bumps **570** of the COIP logic drive **300** but connecting multiple of the semiconductor chips **100** to each other or one another. The fourth interconnection net **576** may be one of the programmable interconnects **361** of the inter-chip interconnects **371** for signal transmission. For example, the fourth interconnection net **576** may be a signal bus or trace coupling one of the small I/O circuits **203**, as seen in FIG. **5**B, of one of the semiconductor chips **100** to one of the small I/O circuits **203** of another of the semiconductor chips **100**.

Referring to FIGS. **20**B and **21**B, for a fifth case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SNIP **588** of the interposer **551** may compose a fifth interconnection net **577** not connecting to any of the metal

pillars or bumps **570** of the COIP logic drive **300** but connecting multiple of the bonded contacts **563** between one of the semiconductor chips **100** and the interposer **551** to each other or one another. The fifth interconnection net **577** may be a signal bus or trace for signal transmission.

Embodiment for Chip Package with TPVs

(1) First Embodiment for Forming TPVs and Micro-Bumps on Interposer

Alternatively, the COIP logic drive **300** may be provided with multiple through package vias, or through polymer vias (TPVs) in the polymer layer **565** on a front side of the interposer **551**. FIGS. **22**A-**22**O are cross-sectional views showing a process for forming a multi-chip-on-interposer (COIP) logic drive with multiple through package vias (TPVs) in accordance with the present application. Referring to FIG. **22**A, the through package vias (TPVs) **582** may be formed on the front side of the interposer **551** using the same adhesion/seed layer **580**, composed of an adhesion layer **26** and a seed layer **28** on the adhesion layer **26** as illustrated in FIGS. **15**B and **15**C, for forming the micro-bumps **34** as seen in FIG. **18**J or **19**L. For more elaboration, after the step as illustrated in FIG. **18**I or **19**K, the adhesion/seed layer **580** used for forming the micro-bumps **34** and the through package vias (TPVs) may be first formed on the interconnection scheme **561**, i.e., on its polymer layer **42** and its interconnection metal layer **27** at the bottoms of its openings **42***a*. In this case, the interconnection scheme **561** includes the FISIP **560**, the passivation layer **14** on the FISP **560** and a polymer layer **36** as seen in FIG. **15**I on the passivation layer **14**, wherein each opening **36***a* in the polymer layer **36** may overlay one of the openings **14***a* and one of the metal pads **16**. The specification of the adhesion layer **26** and seed layer **28** as seen in FIG. **22**A and the process for forming the same may be referred to those as illustrated in FIGS. **15**B and **15**C. The specification of the polymer layer **36** as seen in FIG. **22**A and the process for forming the same may be referred to those as illustrated in FIG. **15**I. During the process for forming the interposer **551**, the adhesion layer **26** of the adhesion/seed layer **580** may be formed on its metal pads **16** at bottoms of the openings **14***a* in its passivation layer **14**, on its passivation layer **14** around the metal pads **16** and on its polymer layer **36**; next, the seed layer **28** of the adhesion/seed layer **580** may be formed on the adhesion layer **26** of the adhesion/seed layer **580**.

Next, referring to FIG. **22**B, a photoresist layer **30** is formed on the seed layer **28** of the adhesion/seed layer **580**. The specification of the photoresist layer **30** as seen in FIG. **22**B and the process for forming the same may be referred to those as illustrated in FIG. **15**D. Each of openings **30***a* in the photoresist layer **30** may overlap one of the openings **36***a* and one of the openings **14***a* for forming one of micro-pillars or micro-bumps in said each of the openings **30***a* by following processes to be performed later, exposing the electroplating seed layer **28** of the adhesion/seed layer **580** at the bottom of said each of the openings **30***a*, and may extend out of said one of the openings **36***a* to an area or ring of the polymer layer **36** around said one of the openings **36***a*.

Next, referring to FIG. **22**B, for forming the second type of micro-pillars or micro-bumps, a metal layer **32**, such as copper, may be electroplated on the electroplating seed layer **28** exposed by the openings **30***a*. The specification of the metal layer **32** as seen in FIG. **22**B and the process for forming the same may be referred to those as illustrated in FIGS. **15**E, **15**J and **15**K. Alternatively, for forming the first type of micro-pillars or micro-bumps, a metal layer **32**, such as copper, may be electroplated on the electroplating seed layer **28** exposed by the openings **30***a*, and a solder cap **33** may be electroplated on the metal layer **32**. The specification of the metal layer **32** and solder cap **33** as illustrated herein and the process for forming the same may be referred to those as illustrated in FIG. **15**E.

Next, referring to FIG. **22**C, most of the photoresist layer **30** may be removed using an organic solution with amide. The process for removing the photoresist layer **30** may be referred to that as illustrated in FIG. **15**F.

Next, referring to FIG. **22**D, a photoresist layer **581** is formed on the electroplating seed layer **28** of the adhesion/seed layer **580** and on the metal layer **32** for forming the second type of micro-pillars or micro-bumps or metal cap **33** for forming the first type of micro-pillars or micro-bumps. The specification of the photoresist layer **581** as seen in FIG. **22**D and the process for forming the same may be referred to the specification of the photoresist layer **30** as illustrated in FIG. **15**D. Each of openings **581***a* in the photoresist layer **581** may overlap one of the openings **36***a* and one of the openings **14***a* for forming one of the through package vias (TPV) in said one of the openings **581***a* by following processes to be performed later, exposing the electroplating seed layer **28** of the adhesion/seed layer **580** at the bottom of said one of the openings **581***a*, and may extend out of said one of the openings **36***a* to an area or ring of the polymer layer **36** around said one of the openings **36***a*. For example, the photoresist layer **581** may have a thickness between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm.

Next, referring to FIG. **22**E, a metal layer **582**, such as copper, may be electroplated on the electroplating seed layer **28** exposed by the openings **581***a*. For example, the metal layer **582** may be formed by electroplating a copper layer with a thickness between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm on the electroplating seed layer **28**, made of copper, of the adhesion/seed layer **580** exposed by the openings **581***a*.

Next, referring to FIG. **22**F, most of the photoresist layer **581** may be removed using an organic solution with amide and then the electroplating seed layer **28** and adhesion layer **26** of the adhesion/seed layer **580** not under the metal layers **32** and **582** may be etched. The removing and etching processes may be referred respectively to the process for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the micro-bumps **34** and through package vias (TPVs) **582** may be formed on the interposer **551**.

(2) Second Embodiment for Forming TPVs and Micro-Bumps on Interposer

Alternatively, the TPVs **582** may be formed on the micro-pillars or micro-bumps **34**. FIGS. **25**A-**25**E are cross-sectional views showing a process for forming TPVs and micro-bumps on an interposer in accordance with the present application. Referring to FIG. **25**A following the step as illustrated in FIG. **22**A, a photoresist layer **30** is formed on the electroplating seed layer **28** of the adhesion/seed layer **580**. The specification of the photoresist layer **30** as seen in FIG. **25**A and the process for forming the same may be referred to those as illustrated in FIG. **15**D. Each of openings **30***a* in the photoresist layer **30** may overlap one of the openings **36***a* and one of the openings **14***a* for forming one of the micro-pillars or micro-bumps or one of multiple pads for the TPVs in said one of the openings **30***a* by following processes to be performed later, exposing the electroplating seed layer **28** of the adhesion/seed layer **580** at the bottom of said one of the openings **30***a*, and may extend out of said

one of the openings **36***a* to an area or ring of the polymer layer **36** around said one of the openings **36***a*.

Next, referring to FIG. **25**A, for forming the second type of micro-pillars or micro-bumps, a metal layer **32**, such as copper, may be electroplated on the electroplating seed layer **28** of the adhesion/seed layer **580** exposed by the openings **30***a* for forming the micro-pillars or micro-bumps and the pads for the TPVs. The specification of the metal layer **32** as seen in FIG. **25**A and the process for forming the same may be referred to those as illustrated in FIGS. **15**E, **15**J and **15**K.

Next, referring to FIG. **25**B, most of the photoresist layer **30** may be removed using an organic solution with amide. The process for removing the photoresist layer **30** may be referred to that as illustrated in FIG. **15**F.

Next, referring to FIG. **25**C, a photoresist layer **581** is formed on the electroplating seed layer **28** of the adhesion/seed layer **580** and on the metal layer **32**. The specification of the photoresist layer **581** as seen in FIG. **25**C and the process for forming the same may be referred to the specification of the photoresist layer **30** as illustrated in FIG. **15**D. Each of openings **581***a* in the photoresist layer **581** may overlap the metal layer **32** for one of the pads for the TPVs and may expose the metal layer **32** for said one of the pads for the TPVs at the bottom of said one of the openings **581***a*. For example, the photoresist layer **581** may have a thickness between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm.

Next, referring to FIG. **25**D, a metal layer **582**, such as copper, may be electroplated on the metal layer **32** for the pads for the TPVs exposed by the openings **581***a*. For example, the metal layer **582** may be formed by electroplating a copper layer with a thickness between 5 μm and 300 μm, 5 μm and 200 μm, 5 μm and 150 μm, 5 μm and 120 μm, 10 μm and 100 μm, 10 μm and 60 μm, 10 μm and 40 μm, or 10 μm and 30 μm on the metal layer **32** for the pads for the TPVs, made of copper, exposed by the openings **581***a*.

Next, referring to FIG. **25**E, most of the photoresist layer **581** may be removed using an organic solution with amide and then the electroplating seed layer **28** and adhesion layer **26** of the adhesion/seed layer **580** not under the metal layer **32** may be etched. The removing and etching processes may be referred respectively to the process for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the micro-bumps **34** and through package vias (TPVs) **582** may be formed on the interposer **551**.

(3) Package for COIP Logic Drive

Next, referring to FIG. **22**G or **23**A, each of the semiconductor chips **100** as seen in FIGS. **15**H, **15**I, **16**J-**16**M or **17** may have its micro-bumps **34** of the first type to be bonded to the second type of micro-bumps **34** of the interposer **551** as illustrated in FIG. **22**F or **25**E into multiple bonded contacts **563** as seen in FIG. **22**H or **23**A. Alternatively, each of the semiconductor chips **100** as seen in FIG. **15**H, **15**I, **16**J-**16**M or **17** may have its micro-bumps **34** of the first type to be bonded to be bonded to the first type of micro-bumps **34** as illustrated in FIG. **22**F into multiple bonded contacts **563** as seen in FIG. **22**H or **23**A. Alternatively, each of the semiconductor chips **100** as seen in FIG. **15**J, **15**K or **16**N may have its micro-bumps **34** of the second type to be bonded to the first type of micro-bumps **34** of the interposer **551** as illustrated in FIG. **22**F into multiple bonded contacts **563** as seen in FIG. **22**H or **23**A. The bonding process may be referred to the process for bonding the micro-bumps **34** of the semiconductor chips **100** to the micro-bumps **34** of the interposer **551** as illustrated in FIG. **18**K or **19**M.

Next, referring to FIGS. **22**H and **221** or to FIG. **23**A, an underfill **564**, such as epoxy resins or compounds, may be filled into a gap between each of the semiconductor chips **100** and the interposer **551** as illustrated in FIG. **22**F or **25**E by a dispensing method performed using a dispenser. The underfill **564** may then be cured at temperature equal to or above 100° C., 120° C., or 150° C. FIG. **22**I is a top view showing a path for a dispenser moving to fill an underfill into a gap between a semiconductor chip and an interposer in accordance with the present application. Referring to FIG. **22**I, a dispenser may move along multiple paths or clearness **584** each arranged between multiple of the TPVs **582** arranged in a line and one of the semiconductor chips **100** to dispense the underfill **564** into the gap between said one of the semiconductor chips **100** and the interposer **551** as illustrated in FIG. **22**H or **23**A.

Next, referring to FIG. **22**J or FIG. **23**, a polymer layer **565**, e.g., resin or compound, may be applied to fill the gaps each between neighboring two of the semiconductor chips **100** and the gaps each between neighboring two of the TPVs **582** and cover the backsides **100***a* of the semiconductor chips **100** and the tips of the TPVs **582** by methods, for example, spin-on coating, screen-printing, dispensing or molding in a wafer or panel format. The specification of the polymer layer **565** and the process for forming the same may be referred to those as illustrated in FIG. **18**N or **19**P.

Next, referring to FIG. **22**K or FIG. **23**A, a chemical mechanical polishing (CMI'), polishing or grinding process may be applied to remove a top portion of the polymer layer **565** and top portions of the semiconductor chips **100** and to planarize a top surface of the polymer layer **565** until all of the tips of the TPVs **582** are fully exposed.

Next, referring to FIG. **22**L or FIG. **23**A, the interposer **551** as illustrated in FIG. **22**F or **25**E has a backside **551***a* to be polished by a CMP process or a wafer backside grinding process until each of the vias **558** is exposed, that is, its insulating layer **555** at its backside is removed into an insulating lining surrounding its adhesion/seed layer **556** and copper layer **557**, and a backside of its copper layer **557** or a backside of the adhesion layer or electroplating seed layer of its adhesion/seed layer **556** is exposed.

Next, referring to FIG. **22**M, the polymer layer **585** as illustrated in FIG. **18**Q may be formed on a backside of the interposer **551** formed with the first type of vias **558** and the metal bumps or pillars **570** as illustrated in FIGS. **18**R-**18**V may be formed on the backside of the interposer **551** formed with the first type of vias **558**. The specification of the polymer layer **585** and the process for forming the same may be referred to those as illustrated in FIG. **18**Q. The specification of the metal bumps or pillars **570** and the process for forming the same may be referred to those as illustrated in FIGS. **18**R-**18**V. In this case, the TPVs **582** is formed on the polymer layer **36** and topmost one of the interconnection metal layers **8** of the FISIP **560** as illustrated in FIG. **22**F; alternatively, the TPVs **582** may be formed on the metal layer **32** for the pads for the TPVs as seen in FIG. **25**E.

Alternatively, referring to FIG. **23**A, the metal bumps or pillars **570** as illustrated in FIG. **19**S may be formed on a backside of the interposer **551** formed with the second type of vias **558**. The specification of the metal bumps or pillars **570** and the process for forming the same may be referred to those as illustrated in FIG. **19**S. In this case, the TPVs **582** is formed on the polymer layer **36** and topmost one of the interconnection metal layers **8** of the FISIP **560** as illustrated

in FIG. **22**F; alternatively, the TPVs **582** may be formed on the metal layer **32** for the pads for the TPVs as seen in FIG. **25**E.

Next, the package structure shown in FIG. **22**M or **23**A may be separated, cut or diced into multiple individual chip packages, i.e., standard commodity COIP logic drives **300** or single-layer-packaged logic drive as shown in FIG. **22**N or **23**B by a laser cutting process or by a mechanical cutting process.

Alternatively, referring to FIGS. **22**O and **23**C, after the metal bumps **34** are formed on the backside of the interposer **551** as seen in FIG. **22**M or **23**B, multiple solder bumps **578** may be formed on the exposed tips of the TPVs **582** by a method of screen printing or solder ball mounting. Next, the package structure formed with the solder bumps **578** may be separated, cut or diced into multiple individual chip packages, i.e., standard commodity COIP logic drives **300** or single-layer-packaged logic drive as shown in FIG. **22**O or **23**C, by a laser cutting process or by a mechanical cutting process. The solder bumps **578** may join an external electronic component to connect the COIP logic drive **300** to the external electronic component. The material used for forming the solder bumps **578** may be a lead-free solder containing tin, copper, silver, bismuth, indium, zinc, antimony, and/or traces of other metals, for example, Sn—Ag—Cu (SAC) solder, Sn—Ag solder, or Sn—Ag—Cu—Zn solder. Each of the solder bumps **578** may have a height, from a backside surface **565***a* of the polymer layer **565**, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 nm and 40 μm or between 10 μm and 30 μm, or greater or taller than or equal to 75 μm, 50 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example, and a largest dimension in cross-sections, such as a diameter of a circle shape or a diagonal length of a square or rectangle shape, between 5 μm and 200 μm, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 100 μm, 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm, for example. The smallest space from one of the solder bumps **578** to its nearest neighboring one of the solder bumps **578** is, for example, between 5 μm and 150 μm, between 5 μm and 120 μm, between 10 μm and 100 μm, between 10 μm and 60 μm, between 10 μm and 40 μm, or between 10 μm and 30 μm, or greater than or equal to 60 μm, 50 μm, 40 μm, 30 μm, 20 μm, 15 μm or 10 μm.

The standard commodity COIP logic drive **300** as shown in FIG. **22**N, **22**O, **23**B or **23**C may be in a shape of square or rectangle with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the standard commodity COIP logic drive **300**. For example, the standard shape of the COIP logic drive **300** may be a square with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Alternatively, the standard shape of the standard commodity COIP logic drive **300** may be a rectangle with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm, and a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm, or 5 mm. Furthermore, the metal bumps or pillars **570** at a backside of the interposer **551** in the logic drive **300** may be in a standard footprint, for example, in an area array of M×N with a standard dimension of pitch and space between neighboring two of the metal bumps or pillars **570**. The locations of the metal bumps or pillars **570** are also at a standard location.

Package-on-Package (POP) Assembly for COIP LOGIC Drives

FIGS. **24**A-**24**C are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application. Referring to FIGS. **24**A-**24**C, when a top one of the COIP logic drives as seen in FIG. **22**N or **23**B is mounted onto a bottom one of the COIP logic drives **300**, the bottom one of the COIP logic drives **300** may have its TPVs **582** in its polymer layer **565** to couple to circuits, interconnection metal schemes, metal pads, metal pillars or bumps, and/or components of the top one of the COD logic drives **300** at the backside of the bottom one of the COIP logic drives **300**. The process for fabricating a package-on-package assembly is mentioned as below:

First, referring to FIG. **24**A, a plurality of the bottom one of the COIP logic drives **300** (only one is shown) may have its metal pillars or bumps **570** mounted onto multiple metal pads **109** of a circuit carrier or substrate **110** at a topside thereof, such as printed circuit board (PCB), ball-grid-array (BGA) substrate, flexible circuit film or tape, or ceramic circuit substrate. An underfill **114** may be filled into a gap between the circuit carrier or substrate **110** and the bottom one of the COIP logic drives **300**. Alternatively, the underfill **114** between the circuit carrier or substrate **110** and the bottom one of the COIP logic drives **300** may be skipped. Next, a surface-mount technology (SMT) may be used to mount a plurality of the top one of the COIP logic drives **300** (only one is shown) onto the plurality of the bottom one of the COIP logic drives **300**, respectively.

For the surface-mount technology (SMT), solder or solder cream or flux **112** may be first printed on the backside surface **582***a* of the TPVs **582** of the bottom one of the COIP logic drives **300**. Next, referring to FIG. **24**B, the top one of the COIP logic drives **300** may have its metal pillars or bumps **570** placed on the solder or solder cream or flux **112**. Next, a reflowing or heating process may be performed to fix the metal pillars or bumps **570** of the top one of the COIP logic drives **300** to the TPVs **582** of the bottom one of the COIP logic drives **300**. Next, an underfill **114** may be filled into a gap between the top and bottom ones of the COIP logic drives **300**. Alternatively, the underfill **114** between the top and bottom ones of the COIP logic drives **300** may be skipped.

In the next optional step, referring to FIG. **24**B, other multiple of the COIP logic drives **300** as seen in FIG. **22**N or **23**B may have its metal pillars or bumps **570** mounted onto the TSVs **582** of the plurality of the top one of the COIP logic drives **300** using the surface-mount technology (SMT) and the underfill **114** is then optionally formed therebetween. The step may be repeated by multiple times to form three or more than three of the COIP logic drives **300** stacked on the circuit carrier or substrate **110**.

Next, referring to FIG. **24**B, multiple solder balls **325** are planted on a backside of the circuit carrier or substrate **110**. Next, referring to FIG. **24**C, the circuit carrier or structure **110** may be separated, cut or diced into multiple individual substrate units **113**, such as printed circuit boards (PCBs), ball-grid-array (BGA) substrates, flexible circuit films or tapes, or ceramic circuit substrates, by a laser cutting process or by a mechanical cutting process. Thereby, the number i of the COIP logic drives **300** may be stacked on one of the

substrate units **113**, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8.

Alternatively, FIGS. **24**D-**24**F are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application. Referring to FIGS. **24**D and **24**E, a plurality of the top one of the COIP logic drives **300** as seen in FIG. **22**N or **23**B may have its metal pillars or bumps **570** fixed or mounted, using the SMT technology, to the TPVs **582** of the structure in a wafer or panel level as seen in FIG. **22**M or **23**A before being separated into a plurality of the bottom one of the COIP logic drives **300**.

Next, referring to FIG. **24**E, the underfill **114** may be filled into a gap between each of the top ones of the COIP logic drives **300** as seen in FIG. **22**N or **23**B and the structure in a wafer or panel level as seen in FIG. **22**M or **23**A. Alternatively, the underfill **114** between each of the top ones of the COIP logic drives **300** as seen in FIG. **22**N or **23**B and the structure in a wafer or panel level as seen in FIG. **22**M or **23**A may be skipped.

In the next optional step, referring to FIG. **24**E, other multiple of the COIP logic drives **300** as seen in FIG. **22**N or **23**B may have its metal pillars or bumps **570** mounted onto the TSVs **582** of the top ones of the COIP logic drives **300** using the surface-mount technology (SMT) and the underfill **114** is then optionally formed therebetween. The step may be repeated by multiple times to form two or more than two of the COIP logic drives **300** stacked on the structure in a wafer or panel level as seen in FIG. **22**M or **23**A.

Next, referring to FIG. **24**F, the structure in a wafer or panel level as seen in FIG. **22**M or **23**A may be separated, cut or diced into a plurality of the bottom one of the COIP logic drives **300** by a laser cutting process or by a mechanical cutting process. Thereby, the number i of the COIP logic drives **300** may be stacked together, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8. Next, the COIP logic drives **300** stacked together may have a bottommost one provided with the metal pillars or bumps **570** to be mounted onto the multiple metal pads **109** of the circuit carrier or substrate **110** as seen in FIG. **24**B, such as ball-grid-army substrate, at the topside thereof. Next, an underfill **114** may be filled into a gap between the circuit carrier or substrate **110** and the bottommost one of the COIP logic drives **300**. Alternatively, the underfill **114** between the circuit carrier or substrate **110** and the bottommost one of the COIP logic drives **300** may be skipped. Next, multiple solder balls **325** are planted on a backside of the circuit carrier or substrate **110**. Next, the circuit carrier or structure **110** may be separated, cut or diced into multiple individual substrate units **113**, such as printed circuit boards (PCB) or BGA (Ball-Grid-array) substrates, by a laser cutting process or by a mechanical cutting process, as seen in FIG. **24**C. Thereby, the number i of the COIP logic drives **300** may be stacked on one of the substrate units **113**, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8.

The COIP logic drives **300** with the TPVs **582** to be stacked in a vertical direction to form the POP assembly may be in a standard format or have standard sizes. For example, the COIP logic drives **300** and their combination as mentioned below may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the COIP logic drives **300**. For example, the standard shape of the COIP logic drives **300** may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm or 5 mm. Alternatively, the standard shape of the COIP logic drives **300** and their combination as mentioned below may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm or 5 mm.

Embodiment for Chip Package with TPVs and BISD

Alternatively, a backside metal interconnection scheme for the COIP logic Drive **300** (BISD) may be formed for interconnection at backsides of the semiconductor chips **100**. FIGS. **26**A-**26**M are schematic views showing a process for forming a backside metal interconnection scheme for a COIP logic drive (BISD) in accordance with the present application.

Referring to FIG. **26**A following the step as illustrated in FIG. **22**K, a polymer layer **97**, i.e., insulating dielectric layer, is formed on the backsides of the semiconductor chips **100** and on the backside surface **565***a* of the polymer layer **565** by a method of spin-on coating, screen-printing, dispensing or molding, and openings **97***a* in the polymer layer **97** are formed over the tips of the TPVs **582** to expose the tips of the TPVs **582**. The polymer layer **97** may contain, for example, polyimide, BenzoCycloButene (BCB), parylene, epoxy-based material or compound, photo epoxy SU-8, elastomer or silicone. The polymer layer **97** may comprise organic material, for example, a polymer, or material compounds comprising carbon. The polymer layer **97** may be photosensitive, and may be used as photoresist as well for patterning multiple openings **97***a* therein to have metal vias formed therein by following processes to be performed later. The polymer layer **97** may be coated, exposed to light through a photomask, and then developed to form the openings **97***a* therein. Next, the polymer layer **97**, i.e., insulating dielectric layer, is cured at a temperature, for example, equal to or higher than 100° C., 125° C., 150° C., 175° C., 200° C., 225° C., 250° C., 275° C. or 300° C. The polymer layer **97** after cured may have a thickness between, for example, 3 μm and 50 μm, 3 μm and 30 μm, 3 μm and 20 μm, or 3 μm and 15 μm, or thicker than or equal to 3 μm, 5 μm, 10 μm, 20 μm, or 30 μm. The polymer layer **97** may be added with some dielectric particles or glass fibers. The material of the polymer layer **97** and the process for forming the same may be referred to that of the polymer layer **36** and the process for forming the same as illustrated in FIG. **15**I.

Next, an emboss process is performed on the polymer layer **97** and on the exposed tips of the TPVs **582** to form the BISD **79**. Referring to FIG. **26**B, an adhesion layer **81** having a thickness of between 0.001 and 0.7 nm, between 0.01 and 0.5 μm or between 0.03 and 0.35 μm may be sputtered on the polymer layer **97** and on the tips of the TPVs **582**. The material of the adhesion layer **81** may include titanium, a titanium-tungsten alloy, titanium nitride, chromium, titanium-tungsten-alloy layer, tantalum nitride, or a composite of the abovementioned materials. The adhesion layer **81** may be formed by an atomic-layer-deposition (ALD) process, chemical vapor deposition (CVD) process or evaporation process. For example, the adhesion layer **81** may be formed by sputtering or CVD depositing a titanium (Ti) or titanium nitride (TiN) layer (with a thickness, for example, between 1 nm and 200 nm or between 5 nm and 50 nm) on the polymer layer **97** and on the tips of the TPVs **582**.

Next, referring to FIG. **26**B, an electroplating seed layer **83** having a thickness of between 0.001 and 1 μm, between 0.03 and 2 μm or between 0.05 and 0.5 μm may be sputtered on a whole top surface of the adhesion layer **81**. Alternatively, the electroplating seed layer **83** may be formed by an atomic-layer-deposition (ALD) process, chemical-vapor-deposition (CVD) process, vapor deposition method, electroless plating method or PVD (Physical Vapor Deposition) method. The electroplating seed layer **83** is beneficial to electroplating a metal layer thereon. Thus, the material of the electroplating seed layer **83** vanes with the material of a metal layer to be electroplated on the electroplating seed layer **83**. When a copper layer is to be electroplated on the electroplating seed layer **83**, copper is a preferable material to the electroplating seed layer **83**. For example, the electroplating seed layer may be deposited on or over the adhesion layer **81** by, for example, sputtering or CVD depositing a copper seed layer (with a thickness between, for example, 3 nm and 300 nm or 10 nm and 120 nm) on the adhesion layer **81**. The adhesion layer **81** and electroplating seed layer **83** may compose the adhesion/seed layer **579**.

Next, referring to **26**C, a photoresist layer **75**, such as positive-type photoresist layer, having a thickness of between 5 and 50 μm is spin-on coated or laminated on the electroplating seed layer **83** of the adhesion/seed layer **579**. The photoresist layer **75** is patterned with the processes of exposure, development and etc., to form multiple trenches or openings **75***a* in the photoresist layer **75** exposing the electroplating seed layer **83**. A 1× stepper, 1× contact aligner or laser scanner may be used to expose the photoresist layer **75** with at least two of G-line having a wavelength ranging from 434 to 438 nm, H-line having a wavelength ranging from 403 to 407 nm, and I-line having a wavelength ranging from 363 to 367 nm, illuminating the photoresist layer **75**, that is, G-line and H-line, G-line and I-line, H-line and I-line, or G-line, H-line and I-line illuminate the photoresist layer **75**, then developing the exposed polymer layer **75**, and then removing the residual polymeric material or other contaminants on the electroplating seed layer **83** of the adhesion/seed layer **579** with an O_2 plasma or a plasma containing fluorine of below 200 PPM and oxygen, such that the photoresist layer **75** may be patterned with multiple openings **75***a* in the photoresist layer **75** exposing the electroplating seed layer **83** of the adhesion/seed layer **579** for forming metal pads, lines or traces in the trenches or openings **75***a* and on the electroplating seed layer **83** of the adhesion/seed layer **579** by following processes to be performed later. One of the trenches or openings **75***a* in the photoresist layer **75** may overlap the whole area of one of the openings **97***a* in the polymer layer **97**.

Next, referring to FIG. **26**D, a metal layer **85**, such as copper, is electroplated on the electroplating seed layer **83** of the adhesion/seed layer **579** exposed by the trenches or openings **75***a*. For example, the metal layer **85** may be formed by electroplating a copper layer with a thickness between 5 μm and 80 μm, 5 μm and 50 μm, 5 μm and 40 μm, 5 μm and 30 μm, 3 μm and 20 μm, 3 μm and 15 μm, or 3 μm and 10 μm on the electroplating seed layer **83**, made of copper, of the adhesion/seed layer **579** exposed by the trenches or openings **75***a*.

Referring to FIG. **26**E, after the metal layer **85** is formed, most of the photoresist layer **75** may be removed and then the adhesion layer **81** and electroplating seed layer **83** not under the metal layer **85** may be etched. The removing and etching processes may be referred respectively to the processes for removing the photoresist layer **30** and etching the electroplating seed layer **28** and adhesion layer **26** as illustrated in FIG. **15**F. Thereby, the adhesion layer **81**, electroplating seed layer **83** and electroplated metal layer **85** may be patterned to form an interconnection metal layer **77** on the polymer layer **97** and in the openings **97***a* in the polymer layer **97**. The interconnection metal layer **77** may be formed with multiple metal vias **77***a* in the openings **97***a* in the polymer layer **97** and multiple metal pads, lines or traces **77***b* on the polymer layer **97**.

Next, referring to FIG. **26**F, a polymer layer **87**, i.e., insulting or inter-metal dielectric layer, is formed on the polymer layer **97** and metal layer **85** and multiple openings **87***a* in the polymer layer **87** are over multiple contact points of the interconnection metal layer **77**. The polymer layer **87** has a thickness between 3 and 30 micrometers or between 5 and 15 micrometers. The polymer layer **87** may be added with some dielectric particles or glass fibers. The material of the polymer layer **87** and the process for forming the same may be referred to that of the polymer layer **97** or **36** and the process for forming the same as illustrated in FIG. **26**A or **15**I.

The process for forming the interconnection metal layer **77** as illustrated in FIGS. **26**B-**26**E and the process for forming the polymer layer **87** may be alternately performed more than one times to fabricate the BISD **79** as seen in FIG. **26**G. Referring to FIG. **26**G, the BISD **79** may include an upper one of the interconnection metal layers **77** formed with multiple metal vias **77***a* in the openings **87***a* in one of the polymer layers **87** and multiple metal pads, lines or traces **77***b* on said one of the polymer layers **87**. The upper one of the interconnection metal layers **77** may be connected to a lower one of the interconnection metal layers **77** through the metal vias **77***a* of the upper one of the interconnection metal layers **77** in the openings **87***a* in said one of the polymer layers **87**. The BISD **79** may include the bottom-most one of the interconnection metal layers **77** formed with multiple metal vias **77***a* in the openings **97***a* in the polymer layer **97** and on the TPVs **582** and multiple metal pads, lines or traces **77***b* on the polymer layer **97**.

Next, referring to FIG. **26**H, multiple metal bumps **583** may be optionally formed on metal pads **77***e* of the topmost one of the interconnection metal layers **77** exposed by the topmost one of the polymer layer **87** of the BISD **79**. The metal bumps **583** may have five types like the first through fifth types of metal bumps **570** as illustrated in FIGS. **18**R-**18**V and **19**S respectively. The specification of the metal bumps **583** and the process for forming the same may be referred to the specification of the metal bumps **570** of any type and the process for forming the same as illustrated in FIGS. **18**R-**18**V and **19**S.

Each of the first through third types of metal bumps **583**, which can be referred to the first through third types of metal bumps **570** as illustrated in FIGS. **18**R-**18**U respectively, may have the adhesion/seed layer **566** formed with the adhesion layer **566***a* on one of the metal pads **77***e* of the topmost one of the interconnection metal layers **77** and the electroplating seed layer **5666** on the adhesion layer **566***a*, and the metal layer **568** on the seed layer of the adhesion/seed layer **566**. Each of the fourth type of metal bumps **583**, which can be referred to the fourth type of metal bumps **570** as illustrated in FIGS. **18**R-**18**V, may have the adhesion/seed layer **566** formed with the adhesion layer **566***a* on one of the metal pads **77***e* of the topmost one of the interconnection metal layers **77** and the electroplating seed layer **566***b* on the adhesion layer **566***a*, the metal layer **568** on the electroplating seed layer **566***b* of the adhesion/seed layer **566** and the solder bumps **569** on the metal layer **568**. Each of the fifth type of metal bumps **583**, which can be referred to the fifth

type of metal bumps **570** as illustrated in **19**S, may have the solder bumps formed directly on one of the metal pads **77***e* of the topmost one of the interconnection metal layers **77**.

Alternatively, the metal bumps **583** may be skipped not to be formed on the metal pads **77***e* of the topmost one of the interconnection metal layers **77**.

Next, referring to FIG. **26**I, the interposer **551** as illustrated in FIG. **22**F or **25**D has a backside **551***a* to be polished by a CMP process or a wafer backside grinding process until each of the vias **558** is exposed, that is, its insulating layer **555** at its backside is removed into an insulating lining surrounding its adhesion/seed layer **556** and copper layer **557**, and a backside of its copper layer **557** or a backside of the adhesion layer or electroplating seed layer of its adhesion/seed layer **556** is exposed.

Next, referring to FIG. **26**J, multiple metal bumps or pillars **570** as illustrated in FIGS. **18**R-**18**V may be formed on a backside of the interposer **551** formed with the first type of vias **558** as illustrated in FIG. **22**F or **25**E. The specification of the metal bumps or pillars **570** and the process for forming the same may be referred to those as illustrated in FIGS. **18**R-**18**V. In the case that none of the metal bumps **583** as seen in FIG. **26**J are formed on the metal pads **77***e* of the topmost one of the interconnection metal layers **77**, the resulting structure may be seen in FIG. **26**L.

Alternatively, referring to FIG. **27**A, multiple metal bumps or pillars **570** as illustrated in FIG. **19**R may be formed on a backside of the interposer **551** formed with the second type of vias **558**. The specification of the metal bumps or pillars **570** and the process for forming the same may be referred to those as illustrated in FIG. **19**R. Alternatively, the TPVs **582** may be formed on the metal layer **32** as seen in FIG. **25**E. In the case that none of the metal bumps **583** as seen in FIG. **26**J are formed on the metal pads **77***b* of the topmost one of the interconnection metal layers **77**, the resulting structure may be seen in FIG. **27**C.

Next, the package structure shown in FIG. **26**J or **27**A may be separated, cut or diced into multiple individual chip packages, i.e., standard commodity COIP logic drives **300** or single-layer-packaged logic drive as shown in FIG. **26**K or **27**B by a laser cutting process or by a mechanical cutting process. In the case that none of the metal bumps **583** as seen in FIGS. **26**K and **27**B are formed on the metal pads **77***b* of the topmost one of the interconnection metal layers **77**, the resulting structures may be seen in FIGS. **26**M and **27**D respectively.

Referring to FIGS. **26**K and **27**B, the metal bumps **583** or metal pads **77***e* may be formed over (1) multiple gaps each between neighboring two of the semiconductor chips **100** in or of the COIP logic drive **300**, (2) a peripheral area of the COIP logic drive **300** and outside the edges of the semiconductor chips **100** of the COIP logic drive **300**, and (3) the backsides of the semiconductor chips **100**. The BISD **79** may comprise 1 to 6 layers, or 2 to 5 layers of interconnection metal layers **77**. One of the metal pads, lines or traces **77***b* of each of the interconnection metal layers **77** of the BISD **79** may have the adhesion layer **81** and electroplating seed layer **83** of the adhesion/seed layer **579** only at the bottom thereof, but not at the sidewalls thereof.

Referring to FIGS. **26**K and **27**B, one of the metal pads, lines or traces **77***b*, of each of the interconnection metal layers **77** of the BISD **79** may have a thickness between, for example, 0.3 μm and 40 μm, 0.5 μm and 30 μm, 1 μm and 20 μm, 1 μm and 15 μm, 1 μm and 10 μm, or 0.5 μm to 5 μm, or thicker than or equal to 0.3 μm, 0.7 μm, 1 μm, 2 μm, 3 μm, 5 μm, 7 μm or 10 μm, and a width between, for example, 0.3 μm and 40 μm, 0.5 μm and 30 μm, 1 μm and 20 μm, 1 μm and 15 μm, 1 μm and 10 μm, or 0.5 μm to 5 μm, or wider than or equal to 0.3 μm, 0.7 μm, 1 μm, 2 μm, 3 μm, 5 μm, 7 μm or 10 μm. The polymer layer **87** between neighboring two of the interconnection metal layers **77** of the BISD **79** may have a thickness between, for example, 0.3 μm and 50 μm, 0.3 μm and 30 μm, 0.5 μm and 20 μm, 1 μm and 10 μm, or 0.5 μm and 5 μm, or thicker than or equal to 0.3 μm, 0.5 μm, 0.7 μm, 1 μm, 1.5 μm, 2 μm, 3 μm or 5 μm.

FIG. **26**N is a top view showing a metal plane in accordance with an embodiment of the present application. Referring to FIG. **26**N, one of the interconnection metal layers **77** may include two metal planes **77***c* and **77***d* used as a power plane and ground plane respectively, wherein the metal planes **77***c* and **77***d* may have a thickness, for example, between 5 μm and 50 μm, 5 μm and 30 μm, 5 μm and 20 μm or 5 μm and 15 μm, or thicker than or equal to 5 μm, 10 μm, 20 μm or 30 μm. Each of the metal planes **77***c* and **77***d* may be layout as an interlaced or interleaved shaped structure or fork-shaped structure, that is, each of the metal planes **77***c* and **77***d* may have multiple parallel-extension sections and a transverse connection section coupling the parallel-extension sections. One of the metal planes **77***c* and **77***d* may have one of the parallel-extension sections arranged between neighboring two of the parallel-extension sections of the other of the metal planes **77***c* and **77***d*.

Alternatively, referring to FIGS. **26**K and **27**B, one of the interconnection metal layers **77**, e.g., the topmost one, may include a metal plane, used as a heat dissipater or spreader for heat dissipation or spreading, having a thickness, for example, between 5 μm and 50 μm, 5 μm and 30 μm, 5 μm and 20 μm or 5 μm and 15 μm, or thicker than or equal to 5 μm, 10 μm, 20 μm or 30 μm.

Programing for TSVs, Metal Pads and Metal Pillars or Bumps

Referring to FIGS. **26**K, **26**M, **27**B and **27**D, one of the TPVs **582** may be programmed by one or more of the memory cells **362** in one or more of the DPIIC chips **410**, wherein said one or more of the memory cells **362** may be programmed to switch on or off one or more of the cross-point switches **379** distributed in said one or more of the DPIIC chips **410** as seen in FIGS. **3**A-**3**C and **9** to form a signal path from said one of the TPVs **582** to any of the standard commodity FPGA IC chips **200**, dedicated I/O chips **265**, VMIC chip **324**, NVM IC chips **250**, HBM IC chips **251**, DRAM IC chips **321**, PCIC chips **269**, dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the logic drive **300** as seen in FIGS. **11**A-**11**N through one or more of the programmable interconnects **361** of the inter-chip interconnects **371** provided by the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and/or the interconnection metal layers **77** of the BISD **79**. Thereby, the TPVs **582** may be programmable.

Furthermore, referring to FIGS. **26**K, **26**M, **27**B and **27**D, one of the metal bumps or pillars **570** may be programmed by one or more of the memory cells **362** in one or more of the DPIIC chips **410**, wherein said one or more of the memory cells **362** may switch on or off one or more of the cross-point switches **379** distributed in said one or more of the DPIIC chips **410** as seen in FIGS. **3**A-**3**C and **9** to form a signal path from said one of the metal bumps or pillars **570** to any of the standard commodity FPGA IC chips **200**, dedicated I/O chips **265**, VMIC chip **324**, NVM IC chips **250**, HBM IC chips **251**, DRAM IC chips **321**, PCIC chips **269**, dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the logic drive **300** as seen in FIGS. **11**A-**11**N through one or

more of the programmable interconnects **361** of the inter-chip interconnects **371** provided by the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and/or the interconnection metal layers **77** of the BISD **79**. Thereby, the metal bumps or pillars **570** may be programmable.

Furthermore, referring to FIGS. **26**M and **27**D, one of the metal pads **77***e* may be programmed by one or more of the memory cells **362** in one or more of the DPIIC chips **410**, wherein said one or more of the memory cells **362** may switch on or off one or more of the cross-point switches **379** distributed in said one or more of the DPIIC chips **410** as seen in FIGS. **3**A-**3**C and **9** to form a signal path from said one of the metal pads **77***e* to any of the standard commodity FPGA IC chips **200**, dedicated I/O chips **265**, VMIC chip **324**, NVM IC chips **250**, HBM IC chips **251**, DRAM IC chips **321**, PCIC chips **269**, dedicated control chip **260**, dedicated control and I/O chip **266**, DCIAC chip **267** or DCDI/OIAC chip **268** in the logic drive **300** as seen in FIGS. **11**A-**11**N through one or more of the programmable interconnects **361** of the inter-chip interconnects **371** provided by the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and/or the interconnection metal layers **77** of the BISD **79**. Thereby, the metal pads **77***e* may be programmable.

Interconnection for Logic Drive with Interposer and BISD

FIGS. **28**A-**28**C are cross-sectional views showing various interconnection nets in a COIP logic drive in accordance with embodiments of the present application.

Referring to FIG. **28**B the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may connect one or more of the metal pillars or bumps **570** to one of the semiconductor chips **100** and connect one of the semiconductor chips **100** to another of the semiconductor chips **100**. For a first case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551**, the interconnection metal layers **77** of the BISD **79** and the TPVs **582** may compose a first interconnection net **411** connecting multiple of the metal pillars or bumps **570** to each other or one another, connecting multiple of the semiconductor chips **100** to each other or one another and connecting multiple of the metal pads **77***e* to each other or one another. Said multiple of the metal pillars or bumps **570**, said multiple of the semiconductor chips **100** and said multiple of the metal pads **77***e* may be connected together by the first interconnection net **411**. The first interconnection net **411** may be a signal bus for delivering signals or a power or ground plane or bus for delivering power or ground supply.

Referring to FIG. **28**A, for a second case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a second interconnection net **412** connecting multiple of the metal pillars or bumps **570** to each other or one another and connecting multiple of the bonded contacts **563** between one of the semiconductor chips and the interposer **551** to each other or one another. Said multiple of the metal pillars or bumps **570** and said multiple of the bonded contacts **563** may be connected together by the second interconnection net **412**. The second interconnection net **412** may be a signal bus for delivering signals or a power or ground plane or bus for delivering power or ground supply.

Referring to FIG. **28**A, for a third case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a thud interconnection net **413** connecting one of the metal pillars or bumps **570** to one of the bonded contacts **563**. The third interconnection net **413** may be a signal bus or trace for signal transmission or a power or ground plane or bus for delivering power or ground supply.

Referring to FIG. **28**A, for a fourth case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a fourth interconnection net **414** not connecting to any of the metal pillars or bumps **570** of the COIP logic drive **300** but connecting multiple of the semiconductor chips **100** to each other or one another. The fourth interconnection net **414** may be one of the programmable interconnects **361** of the inter-chip interconnects **371** for signal transmission.

Referring to FIG. **28**A, for a fifth case, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** may compose a fifth interconnection net **415** not connecting to any of the metal pillars or bumps **570** of the COIP logic drive **300** but connecting multiple of the bonded contacts **563** between one of the semiconductor chips **100** and the interposer **551** to each other or one another. The fifth interconnection net **415** may be a signal bus or trace for signal transmission or a power or ground plane or bus for delivering power or ground supply.

Referring to FIG. **28**A-**28**C, the interconnection metal layers **77** of the BISD **79** may be connected to the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** through the TPVs **582**. For example, each of the metal pads **77***e* of the BISD **79** in a first group may be connected to one of the semiconductor chips **100** through the interconnection metal layers **77** of the BISD **79**, one or more of the TPVs **582** and the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, in sequence, as provided by the first interconnection net **411**. Furthermore, one of the metal pads **77***e* in the first group may be further connected to one or more of the metal pillars or bumps **570** through, in sequence, the interconnection metal layers **77** of the BISD **79**, one or more of the TPVs **582** and the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, as provided by the first interconnection net **411**. Alternatively, multiple of the metal pads **77***e* in the first group may be connected to each other or one another through the interconnection metal layers **77** of the BISD **79** and to one or more of the metal pillars or bumps **570** through, in sequence, the interconnection metal layers **77** of the BISD **79**, one or more of the TPVs **582** and the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, wherein said multiple of the metal pads **77***e* in the first group may be divided into a first subset of one or ones over a backside of one of the semiconductor chips **100** and a second subset of one or ones over a backside of another of the semiconductor chips **100**, as provided by the first interconnection net **411**. Alternatively, one or multiple of the metal pads **77***e* in the first group may not be connected to any of the metal pillars or bumps **570** of the COIP logic drive **300**, as provided by a sixth interconnection net **419** in FIG. **28**A.

Referring to FIGS. **28**A-**28**C, each of the metal pads **77***e* of the BISD **79** in a second group may not be connected to any of the semiconductor chips **100** of the COIP logic drive **300** but connected to one or more of the metal pillars or bumps **570** through the interconnection metal layers **77** of the BISD **79**, one or more of the TPVs **582** and the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, in sequence, as provided by a seventh interconnection net **420** in FIG. **28**A and an eighth interconnection net **422** in FIG. **28**C. Alternatively, multiple of the metal pads **77***e* of the BISD **79** in

the second group may not be connected to any of the semiconductor chips **100** of the COIP logic drive **300** but connected to each other or one another through the interconnection metal layers **77** of the BISD **79** and to one or more of the metal pillars or bumps **570** through, in sequence, the interconnection metal layers **77** of the BISD **79**, one or more of the TPVs **582** and the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, wherein said multiple of the metal pads **77***e* in the second group may be divided into a first subset of one or ones over a backside of one of the semiconductor chips **100** and a second subset of one or ones over a backside of another of the semiconductor chips **100**, as provided by the eighth interconnection net **422** in FIG. **28**C.

Referring to FIG. **28**A-**28**C, one of the interconnection metal layers **77** in the BISD **79** may include the power plane **77***c* and ground plane **77***d* of a power supply as shown in FIG. **28**D. FIG. **28**D is a top view of FIGS. **28**A-**28**C, showing a layout of metal pads of a logic drive in accordance with an embodiment of the present application. Referring to FIG. **28**D, the metal pads **77***e* may be layout in an array at a backside of the COIP logic drive **300**. Some of the metal pads **77***e* may be vertically aligned with the semiconductor chips **100**. A first group of the metal pads **77***e* is arranged in an array in a central region of a backside surface of the chip package, i.e., logic drive **300**, and a second group of the metal pads **77***e* may be arranged in an array in a peripheral region, surrounding the central region, of the backside surface of the chip package, i.e., logic drive **300**. More than 90% or 80% of the metal pads **77***e* in the first group may be used for power supply or ground reference. More than 50% or 60% of the metal pads **77***e* in the second group may be used for signal transmission. The metal pads **77***e* in the second group may be arranged from one or more rings, such as 1 2, 3, 4, 5 or 6 rings, along the edges of the backside surface of the chip package, i.e., logic drive **300**. The minimum pitch of the metal pads **77***e* in the second group may be smaller than that of the metal pads **77***e* in the first group.

Alternatively, referring to FIGS. **28**A-**28**C, one of the interconnection metal layers **77** of the BISD **79**, such as the topmost one, may include a thermal plane for heat dispassion and one or more of the TPVs **582** may be provided as thermal vias formed under the thermal plane for heat dispassion.

Package-on-Package (POP) Assembly for COIP Logic Drives

FIGS. **29**A-**29**F are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application. Referring to FIG. **29**A, when a top one of the COIP logic drives **300** as seen in FIG. **26**M or **27**D is mounted onto a bottom one of the COIP logic drives **300** as seen in FIG. **26**M or **27**D, the bottom one of the COIP logic drives **300** may have its BISD **79** to couple the interposer **551** of the top one of the COIP logic drives **300** via the metal pillars or bumps **570** provided from the top one of the COIP logic drives **300**. The process for fabricating a package-on-package assembly is mentioned as below:

First, referring to FIG. **29**A, a plurality of the bottom one of the COIP logic drive **300** (only one is shown) as seen in FIG. **26**M or **27**D may have its metal pillars or bumps **570** mounted onto multiple metal pads **109** of a circuit carrier or substrate **110** at a topside thereof, such as Printed Circuit Board (PCB), Ball-Grid-Array (BGA) substrate, flexible circuit film or tape, or ceramic circuit substrate. An underfill **114** may be filled into a gap between the circuit carrier or substrate **110** and the bottom one of the COIP logic drives **300**. Alternatively, the underfill **114** may be skipped. Next, a surface-mount technology (SMT) may be used to mount a plurality of the top one of the COIP logic drives **300** (only one is shown) as seen in FIG. **26**M or **27**D onto the plurality of the bottom one of the COIP logic drives **300**. Solder or solder cream or flux **112** may be first printed on the metal pads **77***e* of the BISD **79** of the bottom one of the COIP logic drives **300**.

Next, referring to FIGS. **29**A and **29**B, the top one of the COIP logic drives **300** may have its metal pillars or bumps **570** placed on the solder or solder cream or flux **112**. Next, referring to FIG. **22**B, a reflowing or heating process may be performed to fix the metal pillars or bumps **570** of the top one of the COIP logic drives **300** to the metal pads **77***e* of the BISD **79** of the bottom one of the COIP logic drives **300**. Next, an underfill **114** may be filled into a gap between the top and bottom ones of the COIP logic drives **300**. Alternatively, the underfill **114** may be skipped.

In the next optional step, referring to FIG. **29**B, other multiple of the COIP logic drives **300** as seen in FIG. **26**M or **27**D may have its metal pillars or bumps **570** to be mounted onto the metal pads **77***e* of the BISD **79** of the plurality of the top one of the COIP logic drives **300** using the surface-mount technology (SMT) and the underfill **114** is then optionally formed therebetween. The step may be repeated by multiple times to form the COIP logic drives **300** stacked in three-layered fashion or more-than-three-layered fashion on the circuit carrier or substrate **110**.

Next, referring to FIG. **29**B, multiple solder balls **325** are planted on a backside of the circuit carrier or substrate **110**. Next, referring to FIG. **29**C, the circuit carrier or structure **110** may be separated, cut or diced into multiple individual substrate units **113**, such as Printed Circuit Boards (PCBs), Ball-Grid-Array (BGA) substrates, flexible circuit films or tapes, or ceramic circuit substrates, by a laser cutting process or by a mechanical cutting process. Thereby, the number i of the COIP logic drives **300** may be stacked on one of the substrate units **113**, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8.

Alternatively, FIGS. **29**D through **29**F are schematically views showing a process for fabricating a package-on-package assembly in accordance with an embodiment of the present application. Referring to FIGS. **29**D and **29**E, a plurality of the top one of the COIP logic drive **300** as seen in FIG. **26**M or **27**D may have its metal pillars or bumps **570** fixed or mounted, using the SMT technology, to the metal pads **77***e* of the BISD **79** of the structure in a wafer or panel level as seen in FIG. **26**M or **27**C before being separated into a plurality of the bottom one of the COIP logic drives **300**.

Next, referring to FIG. **29**E, the underfill **114** may be filled into a gap between each of the top ones of the COIP logic drives **300** and the structure in a wafer or panel level as seen in FIG. **26**M or **27**C. Alternatively, the underfill **114** may be skipped.

In the next optional step, referring to FIG. **29**E, other multiple of the COIP logic drives **300** as seen in FIG. **26**M or **27**D may have its metal pillars or bumps **570** to be mounted onto the metal pads **77***e* of the BISD **79** of the plurality of the top one of the COIP logic drives **300** using the surface-mount technology (SMT) and the underfill **114** is then optionally formed therebetween. The step may be repeated by multiple times to form the COIP logic drives **300** stacked in two-layered fashion or more-than-two-layered fashion on the structure in a wafer or panel level as seen in FIG. **26**M or **27**C.

Next, referring to FIG. **29**F, the structure in a wafer or panel level as seen in FIG. **26**M or **27**C may be separated, cut or diced into a plurality of the bottom one of the COIP logic drives **300** by a laser cutting process or by a mechanical cutting process. Thereby, the number i of the COIP logic drives **300** may be stacked together, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8. Next, the COIP logic drives **300** stacked together may have a bottommost one provided with the metal pillars or bumps **570** to be mounted onto the multiple metal pads **109** of the circuit carrier or substrate **110** as seen in FIG. **22**A, such as ball-grid-array substrate, at a topside thereof. Next, an underfill **114** may be filled into a gap between the circuit carrier or substrate **110** and the bottommost one of the COIP logic drives **300**. Alternatively, the underfill **114** may be skipped. Next, multiple solder balls **325** are planted on a backside of the circuit carrier or substrate **110**. Next, the circuit carrier or structure **110** may be separated, cut or diced into multiple individual substrate units **113**, such as printed circuit boards (PCB) or BGA (Ball-Grid-array) substrates, by a laser cutting process or by a mechanical cutting process, as seen in FIG. **29**C. Thereby, the number i of the COIP logic drives **300** may be stacked on one of the substrate units **113**, wherein the number i may be equal to or greater than 2, 3, 4, 5, 6, 7 or 8.

The COIP logic drives **300** with the TPVs **582** to be stacked in a vertical direction to form the POP assembly may be in a standard format or have standard sizes. For example, the COIP logic drives **300** may be in a shape of square or rectangle, with a certain widths, lengths and thicknesses. An industry standard may be set for the shape and dimensions of the COIP logic drives **300**. For example, the standard shape of each of the COIP logic drives **300** may be a square, with a width greater than or equal to 4 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm or 5 mm. Alternatively, the standard shape of each of the COIP logic drives **300** may be a rectangle, with a width greater than or equal to 3 mm, 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm or 40 mm, and a length greater than or equal to 5 mm, 7 mm, 10 mm, 12 mm, 15 mm, 20 mm, 25 mm, 30 mm, 35 mm, 40 mm, 45 mm or 50 mm; and having a thickness greater than or equal to 0.03 mm, 0.05 mm, 0.1 mm, 0.3 mm, 0.5 mm, 1 mm, 2 mm, 3 mm, 4 mm or 5 mm.

Interconnection for Multiple COIP Drives Stacked together

FIGS. **30**A-**30**C are cross-sectional views showing various connection of multiple logic drives in POP assembly in accordance with embodiment of the present application. Referring to FIG. **30**A, in the POP assembly, each of the COIP logic drives **300** may include one or more of the TPVs **582** used as first inter-drive interconnects **461** stacked and coupled to each other or one another for connecting to an upper one of the COIP logic drives **300** and/or to a lower one of the COIP logic drives **300**, without connecting or coupling to any of the semiconductor chips **100** in the POP assembly. In each of the COIP logic drives **300**, each of the first inter-drive interconnects **461** is formed, from top to bottom, of: (i) one of the metal pads **77***e* of the BISD **79**, (ii) a stacked portion of the interconnection metal layers **77** of the BISD **79**, (iii) one of the TPVs **582**, (iv) a stacked portion of the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of the interposer **551**, (v) one of the vim **558** of the interposer **551**, and (vi) one of the metal pillars or bumps **570**.

Alternatively, referring to FIG. **30**A, a second inter-drive interconnect **462** in the POP assembly may be provided like the first inter-drive interconnect **461**, but the second inter-drive interconnect **462** may connect or couple to one or more of the semiconductor chips **100** through the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551**.

Alternatively, referring to FIG. **30**B, each of the COIP logic drives **300** may provide a third inter-drive interconnect **463** like the first inter-drive interconnect **461** in FIG. **30**A, but the third inter-drive interconnect **463** is not stacked down to one of the metal pillars or bumps **570**, which are positioned vertically under the third inter-drive interconnect **463**, joining a lower one of the COIP logic drives **300** or the substrate unit **113**. Its third inter-drive interconnect **463** may couple to another one or more of its metal pillars or bumps **570**, which are positioned not vertically under its TPVs **582** but vertically under one of its semiconductor chips **100**, joining a lower one of the COIP logic drives **300** or the substrate unit **113**.

Alternatively, referring to FIG. **30**B, each of the COIP logic drives **300** may provide a fourth inter-drive interconnect **464** composed of (i) a first horizontally-distributed portion of the interconnection metal layers **77** of its BISD **79**, (ii) one of its TPVs **582** coupling to one or more of the metal pads **77***e* of the first horizontally-distributed portion vertically over one or more of its semiconductor chips **100**, and (iii) a second horizontally-distributed portion of the interconnection metal layers **6** of its interposer **551** connecting or coupling said one of its TPVs **582** to one or more of its semiconductor chips **100**. The second horizontally-distributed portion of its fourth inter-drive interconnect **464** may couple to its metal pillars or bumps **570**, which are positioned not vertically under said one of its TPVs **582** but vertically under said one or more of its semiconductor chips **100**, joining a lower one of the COIP logic drives **300** or the substrate unit **113**.

Alternatively, referring to FIG. **30**C, each of the COIP logic drives **300** may provide a fifth inter-drive interconnect **465** composed of (i) a first horizontally-distributed portion of the interconnection metal layers **77** of its BISD **79**, (ii) one of its TPVs **582** coupling to one or more of the metal pads **77***e* of the first horizontally-distributed portion vertically over one or more of its semiconductor chips **100**, and (iii) a second horizontally-distributed portion of the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of its interposer **551** connecting or coupling said one of its TPVs **582** to one or more of its semiconductor chips **100**. The second horizontally-distributed portion of its fifth inter-drive interconnect **465** may not couple to any of its metal pillars or bumps **570** joining a lower one of the COIP logic drives **300** or the substrate unit **113**.

Immersive IC Interconnection Environment (IE)

Referring to FIGS. **30**A-**30**C, the COIP logic drives **300** may be stacked to form a super-rich interconnection scheme or environment, wherein their semiconductor chips **100** represented for the standard commodity FPGA IC chips **200**, provided with the programmable logic blocks **201** as illustrated in FIGS. **6**A-**6**J and the cross-point switches **379** as illustrated in FIGS. **3**A-**3**D, immerses in the super-rich interconnection scheme or environment, i.e., programmable 3D Immersive IC Interconnection Environment (IIIE). For one of the standard commodity FPGA IC chips **200** in one of the COIP drives **300**, (1) the interconnection metal layers **6** of the FISC **20** of said one of the standard commodity FPGA IC chips **200**, interconnection metal layers **27** of the SISC **29** of said one of the standard commodity FPGA IC

chips **200**, bonded contacts **563** between said one of the standard commodity FPGA IC chips **200** and the interposer **551** of said one of the COIP drives **300**, the interconnection metal layers **6** and/or **27**, i.e., inter-chip interconnects **371**, of the FISIP **560** and/or SISIP **588** of the interposer **551** of said one of the COIP drives **300**, and the metal pillars or bumps **570** between a lower one and said one of the COIP logic drives **300** are provided under the programmable logic blocks **201** and cross-point switches **379** of said one of the standard commodity FPGA IC chips **200**; (2) the interconnection metal layers **77** of the BISD **79** of said one of the COIP logic drives **300** and the copper pads **77***e* of the BISD **79** of said one of the COIP logic drives **300** are provided over the programmable logic blocks **201** and cross-point switches **379** of said one of the standard commodity FPGA IC chips **200**; and (3) the TPVs **582** of said one of the COIP logic drives **300** are provided surrounding the programmable logic blocks **201** and cross-point switches **379** of said one of the standard commodity FPGA IC chips **200**. The programmable 3D IIIE provides the super-rich interconnection scheme or environment, comprising the FISC **20** of each of the semiconductor chips **100**, SISC **29** of each of the semiconductor chips **100**, bonded contacts **563** between each of the semiconductor chips **100** and one of the interposers **551**, the interposers **551**, BISD **79** of each of the COIP logic drives, TPVs **582** of each of the COIP logic drives **300** and metal pillars or bumps **570** between each two of the COIP logic drives **300**, for constructing an interconnection scheme or system in three dimensions (3D). The interconnection scheme or system in a horizontal direction may be programmed by the cross-point switches **379** of each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** of each of the COIP drives **300**. Also, the interconnection scheme or system in a vertical direction may be programmed by the cross-point switches **379** of each of the standard commodity FPGA IC chips **200** and DPIIC chips **410** of each of the COIP logic drives **300**.

FIGS. **31**A and **31**B are conceptual views showing interconnection between multiple programmable logic blocks from an aspect of human's nerve system in accordance with an embodiment of the present application. For an element indicated by the same reference number shown in FIGS. **31**A and **31**B and in above-illustrated figures, the specification of the element as seen in FIGS. **31**A and **31**B may be referred to that of the element as above illustrated in the figures. Referring to FIG. **31**A, the programmable 3D IIIE is similar or analogous to a human brain. The programmable logic blocks **201** as seen in FIG. **6**A or **6**H are similar or analogous to neurons or nerve cells; the interconnection metal layers **6** of the FISC **20** and/or the interconnection metal layers **27** of the SISC **29** are similar or analogous to the dendrites connecting to the neurons or nerve cells **201**. The bonded contacts **563** connecting to the small receivers **375** of the small I/O circuits **203** of said one of the standard commodity FPGA IC chips **200** for the inputs of the programmable logic blocks **201** of said one of the standard commodity FPGA IC chips **200** are similar or analogous to post-synaptic cells at ends of the dendrites. For a short distance between two of the programmable logic blocks **201** in one of the standard commodity FPGA IC chips **200**, the interconnection metal layers **6** of its FISC **20** and the interconnection metal layers **27** of its SISC **29** may construct an interconnect **482** like an axon connecting from one of the neurons or nerve cells **201** to another of the neurons or nerve cells **201**. For a long distance between two of the standard commodity FPGA IC chips **200**, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposers **551** of the COIP logic drives **300**, the interconnection metal layers **77** of the BISD **79** of the COIP logic drives **300** and the TPVs **582** of the COIP logic drives **300** may construct the axon-like interconnect **482** connecting from one of the neurons or nerve cells **201** to another of the neurons or nerve cells **201**. One of the bonded contacts **563** physically between a first one of the standard commodity FPGA IC chips **200** and one of the interposers **551** for physically connecting to the axon-like interconnect **482** may be programmed to connect to the small drivers **374** of the small I/O circuits **203** of a second one of the standard commodity FPGA IC chips **200** is similar or analogous to pre-synaptic cells at a terminal of the axon **482**.

For more elaboration, referring to FIG. **31**A, a first one **200-1** of the standard commodity FPGA IC chips **200** may include first and second ones LB**1** and LB**2** of the programmable logic blocks **201** like the neurons, the FISC **20** and SISC **29** like the dendrites **481** coupled to the first and second ones LB**1** and LB**2** of the programmable logic blocks **201** and the cross-point switches **379** programmed for connection of its FISC **20** and SISC **29** to the first and second ones LB**1** and LB**2** of the programmable logic blocks **201**. A second one **200-2** of the standard commodity FPGA IC chips **200** may include third and fourth ones LB**3** and LB**4** of the programmable logic blocks **210** like the neurons, the FISC **20** and SISC **29** like the dendrites **481** coupled to the third and fourth ones LB**3** and LB**4** of the programmable logic blocks **210** and the cross-point switches **379** programmed for connection of its FISC **20** and SISC **29** to the third and fourth ones LB**3** and LB**4** of the programmable logic blocks **210**. A first one **300-1** of the COIP logic drives **300** may include the first and second ones **200-1** and **200-2** of the standard commodity FPGA IC chips **200**. A third one **200-3** of the standard commodity FPGA IC chips **200** may include a fifth one LB**5** of the programmable logic blocks **201** like the neurons, the FISC **20** and SISC **29** like the dendrites **481** coupled to the fifth one LB**5** of the programmable logic blocks **201** and its cross-point switches **379** programmed for connection of its FISC **20** and SISC **29** to the fifth one LB**5** of the programmable logic blocks **201**. A fourth one **200-4** of the standard commodity FPGA IC chips **200** may include a sixth one LB**6** of the programmable logic blocks **201** like the neurons, the FISC **20** and SISC **29** like the dendrites **481** coupled to the sixth one LB**6** of the programmable logic blocks **201** and the cross-point switches **379** programmed for connection of its FISC **20** and SISC **29** to the sixth one LB**6** of the programmable logic blocks **201**. A second one **300-2** of the COIP logic drives **300** may include the third and fourth ones **200-3** and **200-4** of the standard commodity FPGA IC chips **200**. (1) A first portion, which is provided by the interconnection metal layers **6** and **27** of the FISC **20** and SISC **29**, extending from the programmable logic block LB**1**, (2) one of the bonded contacts **563** extending from the first portion, (3) a second portion, which is provided by the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** and/or the TPVs **582** of the first one **300-1** of the COIP logic drives **300** and/or the interconnection metal layers **77** of the BISD **79** of the first one **300-1** of the COIP logic drives **300**, extending from said one of the bonded contacts **563**, (4) the other one of the bonded contacts **563** extending from the second portion, and (5) a third portion, which is provided by the interconnection metal layers **6** and **27** of the FISC **20** and SISC **29**, extending from the other one of the bonded contacts **563** to the programmable logic block LB**2** may compose the axon-like interconnect **482**. The axon-like interconnect **482** may be programmed to connect

the first one LB1 of the programmable logic block **201** to either of the second through sixth ones LB2, LB3, LB4, LB5 and LB6 of the programmable logic blocks **201** according to switching of first through fifth ones **258-1** through **258-5** of the pass/no-pass switches **258** of the cross-point switches **379** set on the axon-like interconnect **482**. The first one **258-1** of the pass/no-pass switches **258** may be arranged in the first one **200-1** of the standard commodity FPGA IC chips **200**. The second and third ones **258-2** and **258-3** of the pass/no-pass switches **258** may be arranged in one of the DPIIC chips **410** in the first one **300-1** of the COIP logic drives **300**. The fourth one **258-4** of the pass/no-pass switches **258** may be arranged in the third one **200-3** of the standard commodity FPGA IC chips **200**. The fifth one **258-5** of the pass/no-pass switches **258** may be arranged in one of the DPIIC chips **410** in the second one **300-2** of the COIP logic drives **300**. The first one **300-1** of the COIP logic drives **300** may have the metal pads **77***e* coupling to the second one **300-2** of the COIP logic drives **300** through the metal bumps or pillars **570**. Alternatively, the first through fifth ones **258-1** through **258-5** of the pass/no-pass switches **258** set on the axon-like interconnect **482** may be omitted. Alternatively, the pass/no-pass switches **258** set on the dendrites-like interconnect **481** may be omitted.

Furthermore, referring to FIG. **31**B, the axon-like interconnect **482** may be considered as a scheme or structure of a tree including (i) a trunk or stem connecting to the first one LB1 of the programmable logic blocks **201**, (ii) multiple branches branching from the trunk or stem for connecting its trunk or stem to one of the second and sixth ones LB2-LB6 of the programmable logic blocks **201**, (iii) a first one **379-1** of the cross-point switches **379** set between its trunk or stem and each of its branches for switching the connection between its trunk or stem and one of its branches, (iv) multiple sub-branches branching from one of its branches for connecting said one of its branches to one of the fifth and sixth ones LB5 and LB6 of the programmable logic blocks **201**, and (v) a second one **379-2** of the cross-point switches **379** set between said one of its branches and each of its sub-branches for switching the connection between said one of its branches and one of its sub-branches. The first one **379-1** of the cross-point switches **379** may be provided in one of the DPIIC chips **410** in the first one **300-1** of the COIP logic drives **300**, and the second one **379-2** of the cross-point switches **379** may be provided in one of the DPIIC chips **410** in the second one **300-2** of the COIP logic drives **300**. Each of the dendrite-like interconnects **481** may include (i) a stem connecting to one of the first through sixth ones LB1-LB6 of the programmable logic blocks **201**, (ii) multiple branches branching from the stem, (iii) a cross-point switch **379** set between its stem and each of its branches for switching the connection between its stem and one of its branches. Each of the programmable logic blocks **201** may couple to multiple of the dendrite-like interconnects **481** composed of the interconnection metal layers **6** of the FISC **20** and the interconnection metal layers **27** of the SISC **29**. Each of the programmable logic blocks **201** may be coupled to a distal terminal of one or more of the axon-like interconnects **482**, extending from others of the programmable logic blocks **201**, through the dendrite-like interconnects **481** extending from said each of the programmable logic blocks **201**.

Referring to FIGS. **31**A and **31**B, each of the COIP logic drives **300-1** and **300-2** may provide a reconfigurable plastic, elastic and/or integral architecture for system/machine computing or processing using integral and alterable memory units and logic units in each of the programmable logic blocks **201**, in addition to the sequential, parallel, pipelined or Von Neumann computing or processing system architecture and/or algorithm. Each of the COIP logic devices **300-1** and **300-2** with plasticity, elasticity and integrality may include integral and alterable memory units and logic units to alter or reconfigure logic functions and/or computing (or processing) architecture (or algorithm) and/or memories (data or information) in the memory units. The properties of the plasticity, elasticity and integrality of the COIP logic drive **300-1** or **300-2** is similar or analogous to that of a human brain. The brain or nerves have plasticity, elasticity and integrality. Many aspects of brain or nerves can be altered (or are "plastic" or "elastic") and reconfigured through adulthood. The COIP logic drives **300-1** and **300-2**, or standard commodity FPGA IC chips **200-1**, **200-2**, **200-3** and **200-4**, described and specified above provide capabilities to alter or reconfigure the logic functions and/or computing (or processing) architecture (or algorithm) for a given fixed hardware using the memories (data or information) stored in the near-by programing memory cells (PM), e.g., programming codes stored in the memory cells **362** for the cross-point switches **379** or pass/no-pass switches **258** as seen in FIGS. **7**A-**7**C. In the COIP logic drives **300-1** and **300-2**, or standard commodity FPGA IC chips **200-1**, **200-2**, **200-3** and **200-4**, the memories (data or information) stored in the memory cells of PM are used for altering or reconfiguring the logic functions and/or computing/processing architecture (or algorithm), while some other memories stored in the memory cells are just used for data or information (Data Memory cells, DM), e.g., data in each event or programming codes or resulting values stored in the memory cells **490** for the look-up tables **210** as seen in FIG. **6**A or **6**H.

For example, FIG. **31**C is a schematic diagram for a reconfigurable plastic, elastic and/or integral architecture in accordance with an embodiment of the present application. Referring to FIG. **31**C, the third one LB3 of the programmable logic blocks **201** may include four logic units LB31, LB32, LB33 and LB34, a cross-point switch **379**, four sets of programing memory (PM) cells **362-1**, **362-2**, **362-3** and **3624**, and four sets of data memory (DM) cells **490-1**, **490-2**, **490-3** and **4904**. The cross-point switch **379** may be referred to one as illustrated in FIG. **7**B. For an element indicated by the same reference number shown in FIGS. **31**C and **7**B, the specification of the element as seen in FIG. **31**C may be referred to that of the element as illustrated in FIG. **7**B. The four programmable interconnects **361** at four ends of the cross-point switch **379** may couple to the four logic units LB31, LB32, LB33 and LB34. Each of the logic units LB31, LB32, LB33 and LB34 may have the same architecture as the logic block **201** illustrated in FIG. **6**A or **6**H with its output Dout or one of its inputs A0-A3 coupling to one of the four programmable interconnects **361** at the four ends of the cross-point switch **379**. Each of the logic units LB31, LB32, LB33 and LB34 may couple to one of the four sets of data memory (DM) cells **490-1**, **490-2**, **490-3** and **4904** for storing data in each event and/or storing resulting values or programming codes acting as its look-up table **210** for example. Thereby, the logic functions and/or computing/processing architecture or algorithm of the programmable logic block LB3 may be altered or reconfigured.

The plasticity, elasticity and integrality of the COIP logic drive are based on events. For the n^{th} event (E_n), the n^{th} state (S_n) of the n^{th} integral unit (IU_n) after the n^{th} event of the COIP logic drive may include the logic, PM and DM at the n^{th} states, L_n, PM_n and DM_n, wherein n is a positive integer, 1, 2, 3, ... S_n is a function of IU_n, L_n, PM_n and DM_n, that is S_n (IU_n, L_n, PM_n, DM_n). The n^{th} integral unit IU_n may comprise various logic blocks, various PM memory cells (in

terms of number, quantity and address/location) with various memories (in terms of content, data or information), and various DM memory cells (in terms of number, quantity and address/location) with various memories (in terms of content, data or information) for a specific logic function, a specific set of PM and DM, different from other integral units. The n^{th} state (S_n) and the n^{th} integral unit (IU_n) are generated based on previous events occurred before the n^{th} event (E_n).

Some events may be with great magnitude and are categorized as Grand Events (GE). If the n^{th} event is characterized as a GE, the n^{th} state S_n (IU_n, L_n, PM_n, DM_n) may be reconfigured into a new state S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}), just like the human brain reconfigures the brain during the deep sleep. The newly generated states may become long term memories. The new $(n+1)^{th}$ state (S_{n+1}) for a new $(n+1)^{th}$ integral unit (IU_{n+1}) are generated based on algorithm and criteria for a grand reconfiguration after a Grand Event. As an example, the algorithm and criteria are described as follows: When the Event n (E_n) is quite different in magnitude from previous n−1 events, the E_n is categorized as a Grand Event, and resulted in a $(n+1)^{th}$ state S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}) from the n^{th} state S_n (IU_n, L_n, PM_n, DM_n). After the Grand Event E, the machine/system performs a Grand Reconfiguration with some certain given criteria. The Grand Reconfiguration comprises condense or concise processes and learning processes:

I. Condense or Concise Processes:

(A) DM reconfiguration: (1) The machine/system checks the DM_n, e.g., resulting values or programming codes in the data memory cells **490** as illustrated in FIGS. **31**C, **6**A and **6**H, to find identical memories, and then keeping only one memory of all identical memories, deleting all other identical memories; and (2) The machine/system checks the D_n, e.g., resulting values or programming codes in the data memory cells **490** as illustrated in FIGS. **31**C, **6**A and **6**H, to find similar memories (similarity within a given percentage x %, for example, x is equal to or smaller than 2%, 3%, 5% or 10%), and keeping only one or two memories of all similar memories, deleting all other similar memories; alternatively, a representative memory (data or information) of all similar memories may be generated and kept, while deleting all similar memories.

(B) Logic reconfiguration: (1) The machine/system checks the PM_n, e.g., programming codes in the programming memory cells **362** as illustrated in FIGS. **31**C and **7**B, for corresponding logic functions to find identical logics (PMs), and keeping only one logic (PMs) of all identical logics (PMs), deleting all other identical logics (PMs); (2) The machine/system checks the PM_n, e.g., programming codes in the programming memory cells **362** as illustrated in FIGS. **31**C and **7**B, for corresponding logic functions to find similar logics (PMs) (similarity with a given percentage x % of difference, for example, x is equal to or smaller than 2%, 3%, 5% or 10%), and keeping only one or two logics (PMs) of all similar logics (PMs), deleting all other similar logics (PMs). Alternatively, a representative logic (PMs) (data or information in PM for the corresponding representative logic) of all similar logics (PMs) may be generated and kept, while deleting all similar logics (PMs).

II. Learning Processes:

Based on S_n (IU_n, L_n, PM_n, DM_n), performing a logarithm to select or screen (memorize) useful, significant and important integral units, logics, PMs, e.g., programming codes in the programming memory cells **362** as illustrated in FIGS. **31**C and **7**B, and DMs, e.g., resulting values or programming codes in the data memory cells **490** as illustrated in FIGS. **31**C, **6**A and **6**H, and delete (forget) non-useful, non-significant or non-important integral units, logics, PMs, e.g., programming codes in the programming memory cells **362** as illustrated in FIGS. **31**C and **7**B, or DMs, e.g., resulting values or programming codes in the data memory cells **490** as illustrated in FIGS. **31**C, **6**A and **6**H. The selection or screening algorithm may be based on a given statistical method, for example, based on the frequency of use of integral units, logics, PMs, e.g., programming codes in the programming memory cells **362** as illustrated in FIGS. **31**C and **7**B, and/or DMs, e.g., resulting values or programming codes in the data memory cells **490** as illustrated in FIGS. **31**C, **6**A and **6**H, in the previous n events. Another example, the Bayesian inference may be used for generating S_{n+1} (IU_{n+1}, L_{n+1}, PM_{n+1}, DM_{n+1}).

The algorithm and criteria provide learning processes for the system/machine states after events. The plasticity, elasticity and integrality of the COIP logic drive provide capabilities suitable for applications in machine learning and artificial intelligence.

An example of plasticity, elasticity and integrality is taken using the programmable logic block LB**3**, as illustrated in FIGS. **31**A-**31**C, as GPS (Global Positioning System) functions, as below:

The programmable logic block LB**3** is, for example, functioning as GPS, remembering routes and enabling to drive to various locations. A driver and/or machine/system was planning to drive from San Francisco to San Jose, and the programmable logic block LB**3** may functions as:

(1) In a first event E**1**, the driver and/or machine/system looked up a map and found two Freeways 101 and 280 to get to San Jose from San Francisco. The machine/system used the logic units LB**31** and LB**32** for computing and processing the first event E**1** and memorized a first logic configuration L**1** for the first event E**1** and the related data, information or outcomes of the first event E**1**. That was: the machine/system (a) formulated the logic units LB**31** and LB**32** at the first logic configuration L**1** based on a first set of programming memories (PM**1**) in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB**3** and (b) stored a first set of data memories (DM**1**) in the data memory cells **490-1** and **490-2** of the programmable logic block LB**3**. The integral state of GPS functions in the programmable logic block LB**3** after the first event E**1** may be defined as S**1**LB**3** relating to the first logic configuration L**1** for the first event E**1**, the first set of programming memories PM**1** and the first set of data memories DM**1**.

(2) In a second event E**2**, the driver and/or machine/system decided to take Freeway 101 to get to San Jose from San Francisco. The machine/system used the logic units LB**31** and LB**33** for computing and processing the second event E**2** and memorized a second logic configuration L**2** for the second event E**2** and the related data, information or outcomes of the second event E**2**. That was: the machine/system (a) formulated the logic units LB**31** and LB**33** at the second logic configuration L**2** based on a second set of programming memories (PM**2**) in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB**3** and/or the first set of data memories DM**1** and (b) stored a second set of data memories (DM**2**) in the data memory cells **490-1** and **490-3** of the programmable logic block LB**3**. The integral state of GPS functions in the programmable logic block LB**3** after the second event E**2** may be defined as S**2**LB**3** relating to the second logic configuration L**2** for the second event E**2**, the second set of programming memories PM**2** and the second set of data

memories DM2. The second set of data memories DM2 may include newly added information relating to the second event E2 and the data and information reorganized based on the first set of data memories DM1, and thereby keeps useful and important information of the first event E1.

(3) In a third event E3, the driver and/or machine/system drove from San Francisco to San Jose through Freeway 101. The machine/system used the logic units LB31, LB32 and LB33 for computing and processing the third event E3 and memorized a third logic configuration L3 for the third event E3 and the related data, information or outcomes of the third event E3. That was: the machine/system (a) formulated the logic units LB31, LB32 and LB33 at the third logic configuration L3 based on a third set of programming memories (PM3) in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB3 and/or the second set of data memories DM2 and (b) stored a third set of data memories (DM3) in the data memory cells **490-1**, **490-2** and **490-3** of the programmable logic block LB3. The integral state of GPS functions in the programmable logic block LB3 after the third event E3 may be defined as S3LB3 relating to the third logic configuration L3 for the third event E3, the third set of programming memories PM3 and the third set of data memories DM3. The third set of data memories DM3 may include newly added information relating to the third event E3 and the data and information reorganized based on the first and second sets of data memories DM1 and DM2, and thereby keeps useful and important information of the first and second events E1 and E2.

(4) In a fourth event E4 after two months of the third event E3, the driver and/or machine/system drove from San Francisco to San Jose through Freeway 280. The machine/system used the logic units LB31, LB32, LB33 and LB34 for computing and processing the fourth event E4 and memorized a fourth logic configuration L4 for the fourth event E4 and the related data, information or outcomes of the fourth event E4. That was: the machine/system (a) formulated the logic units LB31, LB32, LB33 and LB34 at the fourth logic configuration L4 based on a fourth set of programming memories (PM4) in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB3 and/or the third set of data memories DM3 and (b) stored a fourth set of data memories (DM4) in the data memory cells **490-1**, **490-2**, **490-3** and **490-4** of the programmable logic block LB3. The integral state of GPS functions in the programmable logic block LB3 after the fourth event E4 may be defined as S4LB3 relating to the fourth logic configuration L4 for the fourth event E4, the fourth set of programming memories PM4 and the fourth set of data memories DM4. The fourth set of data memories DM4 may include newly added information relating to the fourth event E4 and the data and information reorganized based on the first, second and third sets of data memories DM1, DM2 and DM3, and thereby keeps useful and important information of the first, second and third events E1, E2 and E3.

(5) In a fifth event E5 after one week of the fourth event E4, the driver and/or machine/system drove from San Francisco to Cupertino through Freeway 280. Cupertino was in the middle way of the route in the fourth event E4. The machine/system used the logic units LB31, LB32, LB33 and LB34 at the fourth logic configuration L4 for computing and processing the fifth event E5 and memorized the fourth logic configuration L4 for the fifth event E5 and the related data, information or outcomes of the fifth event E5. That was: the machine/system (a) formulated the logic units LB31, LB32, LB33 and LB34 at the fourth logic configuration IA based on the fourth set of programming memories (PM4) in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB3 and/or the fourth set of data memories DM4 and (b) stored a fifth set of data memories (DM5) in the data memory cells **490-1**, **490-2**, **490-3** and **490-4** of the programmable logic block LB3. The integral state of GPS functions in the programmable logic block LB3 after the fifth event E5 may be defined as S5LB3 relating to the fourth logic configuration L4 for the fifth event E5, the fourth set of programming memories PM4 and the fifth set of data memories DM5. The fifth set of data memories DM5 may include newly added information relating to the fifth event E5 and the data and information reorganized based on the first through fourth sets of data memories DM1-DM4, and thereby keeps useful and important information of the first through fourth events E1-E4.

(6) In a sixth event E6 after six months of the fifth event E5, the driver and/or machine/system was planning to drive from San Francisco to Los Angeles. The driver and/or machine/system looked up a map and found two Freeways 101 and 5 to get to Los Angeles from San Francisco. The machine/system used the logic unit LB31 of the programmable logic block LB3 and the logic unit LB41 of the programmable logic block LB4 for computing and processing the sixth event E6 and memorized a sixth logic configuration L6 for the sixth event E6 and the related data, information or outcomes of the sixth event E6. The programmable logic block LB4 may have the same architecture as the programmable logic block LB3 illustrated in FIG. 31C, but the four logic units LB31, LB32, LB33 and LB34 in the programmable logic block LB3 are renumbered as LB41, LB42, LB43 and LB44 in the programmable logic block LB4 respectively. That was: the machine/system (a) formulated the logic units LB31 and LB41 at the sixth logic configuration L6 based on a sixth set of programming memories PM6 in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB3 and those of the programmable logic block LB4 and/or the fifth set of data memories DM5 and (b) stored a sixth set of data memories DM6 in the data memory cell **490-1** of the programmable logic block LB3 and that of the programmable logic block LB4. The integral state of GPS functions in the programmable logic blocks LB3 and LB4 after the sixth event E6 may be defined as S6LB3&4 relating to the sixth logic configuration L6 for the sixth event E6, the sixth set of programming memories PM6 and the sixth set of data memories DM6. The sixth set of data memories DM6 may include newly added information relating to the sixth event E6 and the data and information reorganized based on the first through fifth sets of data memories DM1-DM5, and thereby keeps useful and important information of the first through fifth events E1-E5.

(7) In a seventh event E7, the driver and/or machine/system decided to take Freeway 5 to get to Los Angeles from San Francisco. The machine/system used the logic units LB31 and LB33 at the second logic configuration L2 and/or the sixth set of data memories DM6 for computing and processing the seventh event E7 and memorized the second logic configuration L2 for the seventh event E7 and the related data, information or outcomes of the seventh event E7. That was: the machine/system (a) used the sixth set of data memories DM6 for logic processing with the logic units LB31 and LB33 at the second logic configuration L2 based on the second set of programming memories PM2 in the programming memory cells **362-1**, **362-2**, **362-3** and **3624** of the programmable logic block LB3 and (b) stored a seventh

set of data memories DM7 in the data memory cells **490-1** and **490-3** of the programmable logic block LB3. The integral state of GPS functions in the programmable logic block LB3 after the seventh event E7 may be defined as S7LB3 relating to the second logic configuration L2 for the seventh event E7, the second set of programming memories PM2 and the seventh set of data memories DM7. The seventh set of data memories DM7 may include newly added information relating to the seventh event E7 and the data and information reorganized based on the first through sixth sets of data memories DM1-DM6, and thereby keeps useful and important information of the first through sixth events E1-E6.

(8) In an eighth event E8 after two weeks of the seventh event E7, the driver and/or machine/system drove from San Francisco to Los Angeles through Freeway 5. The machine/system used the logic units LB32, LB33 and LB34 of the programmable logic block LB3 and the logic units LB41 and LB42 of the programmable logic block LB4 for computing and processing the eighth event E8 and memorized an eighth logic configuration L8 of the eighth event E8 and the related data, information or outcomes of the eighth event E8. The machine/system used the logic units LB32, LB33 and LB34 of the programmable logic block LB3 and the logic units LB41 and LB42 of the programmable logic block LB4 for computing and processing the eighth event E8 and memorized the eighth logic configuration L8 for the eighth event E8 and the related data, information or outcomes of the eighth event E8. The programmable logic block LB4 may have the same architecture as the programmable logic block LB3 illustrated in FIG. **31**C, but the four logic units LB31, LB32, LB33 and LB34 in the programmable logic block LB3 are renumbered as LB41, LB42, LB43 and LB44 in the programmable logic block LB4 respectively. FIG. **31**D is a schematic diagram for a reconfigurable plastic, elastic and/or integral architecture for the eighth event E8 in accordance with an embodiment of the present application. Referring to FIGS. **31**A-**31**D, the cross-point switch **379** of the programmable logic block LB3 may have its top terminal switched not to couple to the logic unit LB31 (not shown in FIG. **31**D but shown in FIG. **31**C) but to a first portion of the FISC **20** and SISC **29** of the second semiconductor chip **200-2**, like one of the dendrites **481** of the neurons for the programmable logic block LB3. The cross-point switch **379** of the programmable logic block LB4 may have its right terminal switched not to couple to the logic unit LB44 (not shown) but to a second portion of the FISC **20** and SISC **29** of the second semiconductor chip **200-2**, like one of the dendrites **481** of the neurons for the programmable logic block LB4, connecting to the first portion of the FISC **20** and SISC **29** of the second semiconductor chip **200-2** through a third portion of the FISC **20** and SISC **29** of the second semiconductor chip **200-2**. The cross-point switch **379** of the programmable logic block LB4 may have its bottom terminal switched not to couple to the logic unit LB43 (now shown) but to a fourth portion of the FISC **20** and SISC **29** of the second semiconductor chip **200-2**, like one of the dendrites **481** of the neurons for the programmable logic block LB4. That was: the machine/system (a) formulated the logic units LB32, LB33, LB34, LB41 and LB42 at the eighth logic configuration L8 based on an eighth set of programming memories PM8 in the programming memory cells **362-1**, **362-2**, **362-3** and **362-4** of the programmable logic block LB3 and those of the programmable logic block LB4 and/or the seventh set of data memories DM7 and (b) stored an eighth set of data memories (DM8) in the data memory cells **490-1**, **490-2** and **490-3** of the programmable logic block LB3 and the data memory cells **490-1** and **490-2** of the programmable logic block LB4. The integral state of GPS functions in the programmable logic blocks LB3 and LB4 after the eighth event E8 may be defined as S8LB3&4 relating to the eighth logic configuration L8 for the eighth event E8, the eighth set of programming memories PM8 and the eighth set of data memories DM8. The eighth set of data memories DM8 may include newly added information relating to the eighth event E8 and the data and information reorganized based on the first through seventh sets of data memories DM1-DM7, and thereby keeps useful and important information of the first through seventh events E1-E7.

(9) The event E8 is quite different from the previous first through seventh events E1-E7, and is categorized as a grand event E9, resulting in an integral state S9LB3. In the grand event E9 for grand reconfiguration after the first through eighth events E1-E8, the driver and/or machine/system may reconfigure the first through eighth logic configurations L1-L8 into a ninth logic configuration L9 (1) to formulate the logic units LB31, LB32, LB33 and LB34 of the programmable logic block LB3 at the ninth logic configuration L9 based on a ninth set of programming memories PM9 in the programming memory cells **362-1**, **362-2**, **362-3** and **3624** of the programmable logic block LB3 and/or the first through eighth sets of data memories DM1-DM8 for the GPS functions for the locations in the California area between San Francisco and Los Angeles and (2) to store a ninth set of data memories DM9 in the data memory cells **490-1**, **490-2**, **490-3** and **490-4** of the programmable logic block LB3.

The machine/system may perform the grand reconfiguration with a certain given criteria. The grand reconfiguration is like the human brain reconfiguration after a deep sleep. The grand reconfiguration comprises condense or concise processes and learning processes, mentioned as below:

In the condense or concise processes for reconfiguration of data memories (DM) in the event E9, the machine/system may check the eighth set of data memories DM8 to find identical data memories, and keep only one of the identical data memories in the programmable logic block LB3; alternatively, the machine/system may check the eighth set of data memories DM8 to find similar data memories with more than 70%, e.g., between 80% and 99%, of similarity among them, and select only one or two from the similar data memories as representative data memories for the similar data memories.

In the condense or concise processes for reconfiguration of programming memories (PM) in the event E9, the machine/system may check the eighth set of programming memories PM8 for corresponding logic functions to find identical programming memories for the corresponding logic functions, and keep only one of the identical programming memories in the programmable logic block LB3 for the corresponding logic functions; alternatively, the machine/system may check the eighth set of programming memories PM8 for the corresponding logic functions to find similar programming memories with 70%, e.g., between 80% and 99%, of similarity among them, for the corresponding logic functions and keep only one or two from the similar programming memories for the corresponding logic functions as representative programming memories for the similar programming memories for the corresponding logic functions.

In the learning processes in the event E9, an algorithm may be performed to (1) the programming memories PM1-PM4, PM6 and PM8 for the logic configurations L1-L4, L6 and L8 and (2) the data memories DM1-DM8, for optimiz-

ing, e.g., selecting or screening, the programming memories PM1-PM4, PM6 and PM8 into useful, significant and important ones as the ninth set of programming memories PM9 and optimizing, e.g., selecting or screening, the data memories DM1-DM8 into useful, significant and important ones as the ninth set of data memories DM9. Further, the algorithm may be performed to (1) the programming memories PM1-PM4, PM6 and PM8 for the logic configurations L1-L4, L6 and L8 and (2) the data memories DM1-DM8 for deleting non-useful, non-significant or non-important ones of the programming memories PM1-PM4, PM6 and PM8 and deleting non-useful, non-significant or non-important ones of the data memories DM1-DM8. The algorithm may be performed based on a statistical method, e.g., the frequency of use of the programming memories PM1-PM4, PM6 and PM8 in the events E1-E8 and/or the frequency of use of the data memories DM1-DM8 in the events E1-E8.

Combinations of POP Assembly for Logic Drive and Memory Drive

As mentioned above, the COIP logic drive **300** may be packaged with the semiconductor chips **100** as illustrated in FIGS. **11**A-**11**N. A plurality of the logic drive **300** may be incorporated with one or more memory drives **310** into a module. The memory drives **310** are configured to store data or applications. The memory drives **310** may be divided into two types, one of which is a non-volatile memory drive **322**, and the other one of which is a volatile memory drive **323**, as seen in FIGS. **32**A-**32**K. FIGS. **32**A-**32**K are schematically views showing multiple combinations of POP assemblies for logic and memory drives in accordance with embodiments of the present application. The structure for the memory drives **310** and the process for forming the same may be referred to the illustration for FIGS. **14**A through **30**C but the semiconductor chips **100** are non-volatile memory chips for the non-volatile memory drive **322**; the semiconductor chips **100** are volatile memory chips for the volatile memory drive **323**.

Referring to FIG. **32**A, the POP assembly may be stacked with only the COIP logic drives **300** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C. An upper one of the COIP logic drives **300** may have the metal pillars or bumps **570** mounted onto its metal pads **77***e* of a lower one of the COIP logic drives **300** at the backside thereof, but a bottommost one of the COIP logic drives **300** may have the metal pillars or bumps **570** mounted onto its metal pads **109** of the substrate unit **113** at the topside thereof.

Referring to FIG. **32**B, the POP assembly may be stacked with only the COIP non-volatile memory drives **322** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C. An upper one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of a lower one of the COIP non-volatile memory drives **322** at the backside thereof, but a bottommost one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof.

Referring to FIG. **32**C, the POP assembly may be stacked with only the COIP volatile memory drives **323** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C. An upper one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of a lower one of the COIP volatile memory drives **323** at the backside thereof, but a bottommost one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof.

Referring to FIG. **32**D, the POP assembly may be stacked with a group of the COIP logic drives **300** and a group of the COIP volatile memory drives **323** in accordance with the process as illustrated in FIGS. **14**A through **30**C. The group of the COIP logic drives **300** may be arranged over the substrate unit **113** and under the group of the COIP volatile memory drives **323**. For example, a group of two COIP logic drives **300** may be arranged over the substrate unit **113** and under a group of two COIP volatile memory drives **323**. A first one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a second one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP logic drives **300** at the backside thereof, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP logic drives **300** at the backside thereof, and a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof.

Referring to FIG. **32**E, the POP assembly may be alternately stacked with the COIP logic drives **300** and the COIP volatile memory drives **323** in accordance with the process as illustrated in FIGS. **14**A through **30**C. For example, a first one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP logic drives **300** at the backside thereof, a second one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof, and a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP logic drives **300** at the backside thereof.

Referring to FIG. **32**F, the POP assembly may be stacked with a group of the COIP non-volatile memory drives **322** and a group of the COIP volatile memory drives **323** in accordance with the process as illustrated in FIGS. **14**A through **30**C. The group of the COIP volatile memory drives **323** may be arranged over the substrate unit **113** and under the group of the COIP non-volatile memory drives **322**. For example, a group of two COIP volatile memory drives **323** may be arranged over the substrate unit **113** and under a group of two COIP non-volatile memory drives **322**. A first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof, a first one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP volatile memory drives **323** at the backside thereof, and a second one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP non-volatile memory drives **322** at the backside thereof.

Referring to FIG. **32**G, the POP assembly may be stacked with a group of the COIP non-volatile memory drives **322** and a group of the COIP volatile memory drives **323** in accordance with the process as illustrated in FIGS. **14**A through **30**C. The group of the COIP non-volatile memory drives **322** may be arranged over the substrate unit **113** and under the group of the COIP volatile memory drives **323**. For example, a group of two COIP non-volatile memory drives **322** may be arranged over the substrate unit **113** and under a group of two COIP volatile memory drives **323**. A first one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a second one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP non-volatile memory drives **322** at the backside thereof, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP non-volatile memory drives **322** at the backside thereof, and a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof.

Referring to FIG. **32**H, the POP assembly may be alternately stacked with the COIP volatile memory drives **323** and the COIP non-volatile memory drives **322** in accordance with the process as illustrated in FIGS. **14**A through **30**C. For example, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a first one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof, a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP non-volatile memory drives **322** at the backside thereof, and a second one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP volatile memory drives **323** at the backside thereof.

Referring to FIG. **32**I, the POP assembly may be stacked with a group of the COIP logic drives **300**, a group of the COIP non-volatile memory drives **322** and a group of the COIP volatile memory drives **323** in accordance with the process as illustrated in FIGS. **14**A through **30**C. The group of the COIP logic drives **300** may be arranged over the substrate unit **113** and under the group of the COIP volatile memory drives **323**, and the group of the COIP volatile memory drives **323** may be arranged over the group of the COIP logic drives **300** and under the group of the COIP non-volatile memory drives **322**. For example, a group of two COIP logic drives **300** may be arranged over the substrate unit **113** and under a group of two COIP volatile memory drives **323**, and the group of two COIP volatile memory drives **323** may be arranged over the group of two COIP logic drives **300** and under a group of two COIP non-volatile memory drives **322**. A first one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a second one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP logic drives **300** at the backside thereof, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP logic drives **300** at the backside thereof, a second one of the COT volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof, a first one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP volatile memory drives **323** at the backside thereof, and a second one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP non-volatile memory drives **322** at the backside thereof.

Referring to FIG. **32**J, the POP assembly may be alternately stacked with the COIP logic drives **300**, the COIP volatile memory drives **323** and the COIP non-volatile memory drives **322** in accordance with the process as illustrated in **14**A through **30**C. For example, a first one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **109** of the substrate unit **113** at the topside thereof, a first one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP logic drives **300** at the backside thereof, a first one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP volatile memory drives **323** at the backside thereof, a second one of the COIP logic drives **300** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the first one of the COIP non-volatile memory drives **322** at the backside thereof, a second one of the COIP volatile memory drives **323** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP logic drives **300** at the backside thereof, and a second one of the COIP non-volatile memory drives **322** may have its metal pillars or bumps **570** mounted onto the metal pads **77***e* of the second one of the COIP volatile memory drives **323** at the backside thereof.

Referring to FIG. **32**K, the POP assembly may be stacked with three stacks, one of which is stacked with only the COIP logic drives **300** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C, another of which is stacked with only the COIP non-volatile memory drives **322** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C, and the other of which is stacked with only the COIP volatile memory drives **323** on the substrate unit **113** in accordance with the process as illustrated in FIGS. **14**A through **30**C. With respect to the process for forming the same, after the three stacks of the COIP logic drives **300**, the COIP non-volatile memory drives **322** and the COIP volatile memory drives **323** are stacked on a circuit carrier or substrate, like the one **110** as seen in FIG. **29**A, the solder balls **325** are planted on a backside of the circuit carrier or substrate and then the circuit carrier or structure **110** may be separated, cut or diced into multiple individual substrate units **113**, such as printed circuit boards (PCB) or BGA (Ball-Grid-array) substrates, by a laser cutting process or by a mechanical cutting process.

FIG. **32**L is a schematically top view of multiple POP assemblies, which is a schematically cross-sectional view along a cut line A-A shown in FIG. **32**K. Furthermore, multiple I/O ports **305** may be mounted onto the substrate unit **113** to have one or more universal-serial-bus (USB) plugs, high-definition-multimedia-interface (HDMI) plugs, audio plugs, Internet plugs, power plugs and/or video-graphic-array (VGA) plugs inserted therein.

Application for Logic Drive

The current system design, manufactures and/or product business may be changed into a commodity system/product business, like current commodity DRAM, or flash memory business, by using the standard commodity logic drive **300**. A system, computer, processor, smart-phone, or electronic equipment or device may become a standard commodity hardware comprises mainly the memory drive **310** and the logic drive **300**. FIGS. **33**A-**33**C are schematically views showing various applications for logic and memory drives in accordance with multiple embodiments of the present application. Referring to FIGS. **33**A-**33**C, the logic drive **300** in the aspect of the disclosure may have big enough or adequate number of inputs/outputs (I/Os) to support multiple I/O ports **305** used for programming all or most applications. The logic drive **300** may have I/Os, provided by the metal bumps **570**, to support required I/O ports for programming, for example, to perform all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP), and etc. The logic drive **300** may be configured for (1) programming or configuring Inputs/Outputs (1/Os) for software or application developers to load application software or program codes stored in the memory drive **310** to program or configure the logic drive **300** through the I/O ports **305** or connectors connecting or coupling to the I/Os of the logic drive **300**; and (2) executing the I/Os for the users to perform their instructions through the I/O ports **305** or connectors connecting or coupling to the I/Os of the logic drive **300**, for example, generating a Microsoft Word file, or a PowerPoint presentation file, or an Excel file. The I/O ports **305** or connectors connecting or coupling to the corresponding I/Os of the logic drive **300** may comprise one or multiple (2, 3, 4, or more than 4) Universal Serial Bus (USB) ports, one or more IEEE 1394 ports, one or more Ethernet ports, one or more high-definition-multimedia-interface (HDMI) ports, one or more video-graphic-array (VGA) ports, one or more power-supply ports, one or more audio ports or serial ports, for example, RS-232 or COM (communication) ports, wireless transceiver I/Os, and/or Bluetooth transceiver I/Os, and etc. The I/O ports **305** or connector may be placed, located, assembled, or connected onto a substrate, film or board, such as printed circuit board (PCB), silicon substrate with interconnection schemes, metal substrate with interconnection schemes, glass substrate with interconnection schemes, ceramic substrate with interconnection schemes, or the flexible film **126** with interconnection schemes. The logic drive **300** is assembled on the substrate, film or board using its metal pillars or bumps **570**, similar to the flip-chip assembly of the chip packaging technology, or the Chip-On-Film (COF) assembly technology used in the LCD driver packaging technology.

FIG. **33**A is a schematically view showing an application for logic and memory drives in accordance with an embodiment of the present application. Referring to FIG. **33**A, a laptop or desktop computer, mobile or smart phone or artificial-intelligence (AI) robot **330** may include the logic drive **300** that may be programmed for multiple processors including a baseband processor **301**, application processor **302** and other processors **303**, wherein the application processor **302** may include a central processing unit (CPU), southbridge, northbridge and graphical processing unit (GPU), and the other processors **303** may include a radio frequency (RF) processor, wireless connectivity processor and/or liquid-crystal-display (LCD) control module. The logic drive **300** may further include a function of power management **304** to put each of the processors **301**, **302** and **303** into the lowest power demand state available via software. Each of the I/O ports **305** may connect a subset of the metal pillars or bumps **570** of the logic drive **300** to various external devices. For example, these I/O ports **305** may include I/O port **1** for connection to wireless communication components **306**, such as global-positioning-system (GPS) component, wireless-local-area-network (WLAN) component, bluetooth components or RF devices, of the computer, phone or robot **330**. These I/O ports **305** may include I/O port **2** for connection to various display devices **307**, such as LCD display device or organic-light-emitting-diode (OLED) display device, of the computer, phone or robot **330**. These I/O ports **305** may include I/O port **3** for connection to a camera **308** of the computer, phone or robot **330**. These I/O ports **305** may include I/O port **4** for connection to various audio devices **309**, such as microphone or speaker, of the computer, phone or robot **330**. These I/O ports **305** or connectors connecting or coupling to the corresponding I/Os of the logic drive may include I/O port **5**, such as Serial Advanced Technology Attachment (SATA) ports or Peripheral Components Interconnect express (PCIe) ports, for communication with the memory drive, disk or device **310**, such as hard disk drive, flash drive and/or solid-state drive, of the computer, phone or robot **330**. These I/O ports **305** may include I/O port **6** for connection to a keyboard **311** of the computer, phone or robot **330**. These I/O ports **305** may include I/O port **7** for connection to Ethernet networking **312** of the computer, phone or robot **330**.

Alternatively, FIG. **33**B is a schematically view showing an application for logic and memory drives in accordance with an embodiment of the present application. The scheme shown in FIG. **33**B is similar to that illustrated in FIG. **33**A, but the difference therebetween is that the computer, phone or robot **330** is further provided with a power-management chip **313** therein but outside the logic drive **300**, wherein the power-management chip **313** is configured to put each of the logic drive **300**, wireless communication components **306**, display devices **307**, camera **308**, audio devices **309**, memory drive, disk or device **310**, keyboard **311** and Ethernet networking **312** into the lowest power demand state available via software.

Alternatively, FIG. **33**C is a schematically view showing an application for logic and memory drives in accordance with an embodiment of the present application. Referring to FIG. **33**C, a laptop or desktop computer, mobile or smart phone or artificial-intelligence (AI) robot **331** in another embodiment may include a plurality of the logic drive **300** that may be programmed for multiple processors. For example, a first one, i.e., left one, of the logic drives **300** may be programmed for the baseband processor **301**; a second one, i.e., right one, of the logic drives **300** may be programmed for the application processor **302** including a central processing unit (CPU), southbridge, northbridge and graphical processing unit (GPU). The first one of the logic drives **300** may further include a function of power management **304** to put the baseband processor **301** into the lowest power demand state available via software. The second one of the logic drives **300** may further include a function of power management **304** to put the application processor **302** into the lowest power demand state available via software. The first and second ones of the logic drives **300** may further include various I/O ports **305** for various connections to various devices. For example, these I/O ports

305 may include I/O port 1 set on the first one of the logic drives 300 for connection to wireless communication components 306, such as global-positioning-system (GPS) component, wireless-local-area-network (WLAN) component, bluetooth components or RF devices, of the computer, phone or robot 330. These I/O ports 305 may include I/O port 2 set on the second one of the logic drives 300 for connection to various display devices 307, such as LCD display device or organic-light-emitting-diode (OLED) display device, of the computer, phone or robot 330. These I/O ports 305 may include I/O port 3 set on the second one of the logic drives 300 for connection to a camera 308 of the computer, phone or robot 330. These I/O ports 305 may include I/O port 4 set on the second one of the logic drives 300 for connection to various audio devices 309, such as microphone or speaker, of the computer, phone or robot 330. These I/O ports 305 may include I/O port 5 set on the second one of the logic drives 300 for connection to a memory drive, disk or device 310, such as hard disk or solid-state disk or drive (SSD), of the computer, phone or robot 330. These I/O ports 305 may include I/O port 6 set on the second one of the logic drives 300 for connection to a keyboard 311 of the computer, phone or robot 330. These I/O ports 305 may include I/O port 7 set on the second one of the logic drives 300 for connection to Ethernet networking 312 of the computer, phone or robot 330. Each of the first and second ones of the logic drives 300 may have dedicated I/O ports 314 for data transmission between the first and second ones of the logic drives 300. The computer, phone or robot 330 is further provided with a power-management chip 313 therein but outside the first and second ones of the logic drives 300, wherein the power-management chip 313 is configured to put each of the first and second ones of the logic drives 300, wireless communication components 306, display devices 307, camera 308, audio devices 309, memory drive, disk or device 310, keyboard 311 and Ethernet networking 312 into the lowest power demand state available via software.

Memory Drive

The disclosure also relates to a standard commodity memory drive, package, package drive, device, module, disk, disk drive, solid-state disk, or solid-state drive 310 (to be abbreviated as "drive" below, that is when "drive" is mentioned below, it means and reads as "drive, package, package drive, device, module, disk, disk drive, solid-state disk, or solid-state drive"), in a multi-chip package comprising plural standard commodity non-volatile memory IC chips 250 for use in data storage, as seen in FIG. 34A. FIG. 34A is a schematically top view showing a standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. 34A, a first type of memory drive 310 may be a non-volatile memory drive 322, which may be used for the drive-to-drive assembly as seen in FIGS. 32A-32K, packaged with multiple high speed, high bandwidth, wide bitwidth non-volatile memory (NVM) IC chips 250 for the semiconductor chips 100 arranged in an array, wherein the architecture of the memory drive 310 and the process for forming the same may be referred to that of the logic drive 300 and the process for forming the same, but the difference therebetween is the semiconductor chips 100 are arranged as shown in FIG. 34A. Each of the high speed, high bandwidth, wide bitwidth non-volatile memory IC chips 250 may be NAND flash chip in a bare-die format or in a multi-chip flash package format. Data stored in the non-volatile memory IC chips 250 of the standard commodity memory drive 310 are kept even if the memory drive 310 is powered off. Alternatively, the high speed, high bandwidth, wide bitwidth non-volatile memory IC chips 250 may be Non-Volatile Radom-Access-Memory (NVRAM) IC chips in a bare-die format or in a package format. The NVRAM may be a Ferroelectric RAM (FRAM), Magnetoresistive RAM (MRAM), Resistive RAM (RRAM) or Phase-change RAM (PRAM). Each of the NAND flash chips 250 may have a standard memory density, capacity or size of greater than or equal to 64 Mb, 512 Mb, 1 Gb, 4 Gb, 16 Gb, 64 Gb, 128 Gb, 256 Gb, or 512 Gb, wherein "b" is bits. Each of the NAND flash chips 250 may be designed and fabricated using advanced NAND flash technology nodes or generations, for example, more advanced than or equal to 45 nm, 28 nm, 20 nm, 16 nm, and/or 10 nm, wherein the advanced NAND flash technology may comprise Single Level Cells (SLC) or multiple level cells (MLC) (for example, Double Level Cells DLC, or triple Level cells TLC) in a 2D-NAND or a 3D NAND structure. The 3D NAND structures may comprise multiple stacked layers or levels of NAND cells, for example, greater than or equal to 4, 8, 16, 32 stacked layers or levels of NAND cells. Accordingly, the standard commodity memory drive 310 may have a standard non-volatile memory density, capacity or size of greater than or equal to 8 MB, 64 MB, 128 GB, 512 GB, 1 GB, 4 GB, 16 GB, 64 GB, 256 GB, or 512 GB, wherein "B" is bytes, each byte has 8 bits.

FIG. 34B is a schematically top view showing another standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. 34B, a second type of memory drive 310 may be a non-volatile memory drive 322, which may be used for the drive-to-drive assembly as seen in FIGS. 32A-32K, packaged with multiple non-volatile memory IC chips 250 as illustrated in FIG. 34A, multiple dedicated I/O chips 265 and a dedicated control chip 260 for the semiconductor chips 100, wherein the non-volatile memory IC chips 250 and dedicated control chip 260 may be arranged in an array. The architecture of the memory drive 310 and the process for forming the same may be referred to that of the logic drive 300 and the process for forming the same, but the difference therebetween is the semiconductor chips 100 are arranged as shown in FIG. 34B. The dedicated control chip 260 may be surrounded by the non-volatile memory IC chips 250. Each of the dedicated I/O chips 265 may be arranged along a side of the memory drive 310. The specification of the non-volatile memory IC chip 250 may be referred to that as illustrated in FIG. 34A. The specification of the dedicated control chip 260 packaged in the memory drive 310 may be referred to that of the dedicated control chip 260 packaged in the logic drive 300 as illustrated in FIG. 11A. The specification of the dedicated I/O chip 265 packaged in the memory drive 310 may be referred to that of the dedicated I/O chip 265 packaged in the logic drive 300 as illustrated in FIGS. 11A-11N.

FIG. 34C is a schematically top view showing another standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. 34C, the dedicated control chip 260 and dedicated I/O chips 265 have functions that may be combined into a single chip 266, i.e., dedicated control and I/O chip, to perform above-mentioned functions of the control and I/O chips 260 and 265. A third type of memory drive 310 may be a non-volatile memory drive 322, which may be used for the drive-to-drive assembly as seen in FIGS. 32A-32K, packaged with multiple non-volatile memory IC chips 250 as illustrated in FIG. 34A, multiple dedicated I/O chips 265 and a dedicated control and I/O chip 266 for the semiconductor chips 100, wherein the non-volatile memory IC chips 250 and dedicated control and I/O chip 266 may be arranged in an array.

The architecture of the memory drive **310** and the process for forming the same may be referred to that of the logic drive **300** and the process for forming the same, but the difference therebetween is the semiconductor chips **100** are arranged as shown in FIG. **34**C. The dedicated control and I/O chip **266** may be surrounded by the non-volatile memory IC chips **250**. Each of the dedicated I/O chips **265** may be arranged along a side of the memory drive **310**. The specification of the non-volatile memory IC chip **250** may be referred to that as illustrated in FIG. **34**A. The specification of the dedicated control and I/O chip **266** packaged in the memory drive **310** may be referred to that of the dedicated control and I/O chip **266** packaged in the logic drive **300** as illustrated in FIG. **11**B. The specification of the dedicated I/O chip **265** packaged in the memory drive **310** may be referred to that of the dedicated I/O chip **265** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N.

FIG. **34**D is a schematically top view showing a standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. **34**D, a fourth type of memory drive **310** may be a volatile memory drive **323**, which may be used for the drive-to-drive assembly as seen in FIGS. **32**A-**32**K, packaged with multiple volatile memory (VM) IC chips **324**, such as high speed, high bandwidth, wide bitwidth DRAM IC chips as illustrated for the one **321** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N or high speed, high bandwidth, wide bitwidth cache SRAM chips, for the semiconductor chips **100** arranged in an array, wherein the architecture of the memory drive **310** and the process for forming the same may be referred to that of the logic drive **300** and the process for forming the same, but the difference therebetween is the semiconductor chips **100** are arranged as shown in FIG. **34**D. In a case, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be DRAM IC chips **321**. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be SRAM chips. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be a combination of DRAM IC chips and SRAM chips.

FIG. **34**E is a schematically top view showing another standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. **34**E, a fifth type of memory drive **310** may be a volatile memory drive **323**, which may be used for the drive-to-drive assembly as seen in FIGS. **32**A-**32**K, packaged with multiple volatile memory (VM) IC chips **324**, such as high speed, high bandwidth, wide bitwidth DRAM IC chips or high speed, high bandwidth, wide bitwidth cache SRAM chips, multiple dedicated I/O chips **265** and a dedicated control chip **260** for the semiconductor chips **100**, wherein the volatile memory (VM) IC chips **324** and dedicated control chip **260** may be arranged in an array, wherein the architecture of the memory drive **310** and the process for forming the same may be referred to that of the logic drive **300** and the process for forming the same, but the difference therebetween is the semiconductor chips **100** are arranged as shown in FIG. **34**E. In this case, the locations for mounting each of the DRAM IC chips **321** may be changed for mounting a SRAM chip. The dedicated control chip **260** may be surrounded by the volatile memory chips such as DRAM IC chips **321** or SRAM chips. Each of the dedicated I/O chips **265** may be arranged along a side of the memory drive **310**. In a case, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be DRAM IC chips **321**. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be SRAM chips. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be a combination of DRAM IC chips and SRAM chips. The specification of the dedicated control chip **260** packaged in the memory drive **310** may be referred to that of the dedicated control chip **260** packaged in the logic drive **300** as illustrated in FIG. **11**A. The specification of the dedicated I/O chip **265** packaged in the memory drive **310** may be referred to that of the dedicated I/O chip **265** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N.

FIG. **34**F is a schematically top view showing another standard commodity memory drive in accordance with an embodiment of the present application. Referring to FIG. **34**F, the dedicated control chip **260** and dedicated I/O chips **265** have functions that may be combined into a single chip **266**, i.e., dedicated control and I/O chip, to perform above-mentioned functions of the control and I/O chips **260** and **265**. A sixth type of memory drive **310** may be a volatile memory drive **323**, which may be used for the drive-to-drive assembly as seen in FIGS. **32**A-**32**K, packaged with multiple volatile memory (VM) IC chips **324**, such as high speed, high bandwidth, wide bitwidth DRAM IC chips as illustrated for the one **321** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N or high speed, high bandwidth, wide bitwidth cache SRAM chips, multiple dedicated I/O chips **265** and the dedicated control and I/O chip **266** for the semiconductor chips **100**, wherein the volatile memory (VM) IC chips **324** and dedicated control and I/O chip **266** may be arranged in an array as shown in FIG. **34**F. The dedicated control and I/O chip **266** may be surrounded by the volatile memory chips such as DRAM IC chips **321** or SRAM chips. In a case, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be DRAM IC chips **321**. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be SRAM chips. Alternatively, all of the volatile memory (VM) IC chips **324** of the memory drive **310** may be a combination of DRAM IC chips and SRAM chips. The architecture of the memory drive **310** and the process for forming the same may be referred to that of the logic drive **300** and the process for forming the same, but the difference therebetween is the semiconductor chips **100** are arranged as shown in FIG. **34**F. Each of the dedicated I/O chips **265** may be arranged along a side of the memory drive **310**. The specification of the dedicated control and I/O chip **266** packaged in the memory drive **310** may be referred to that of the dedicated control and I/O chip **266** packaged in the logic drive **300** as illustrated in FIG. **11**B. The specification of the dedicated I/O chip **265** packaged in the memory drive **310** may be referred to that of the dedicated I/O chip **265** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N. The specification of the DRAM IC chips **321** packaged in the memory drive **310** may be referred to that of the DRAM IC chips **321** packaged in the logic drive **300** as illustrated in FIGS. **11**A-**11**N.

Alternatively, another type of memory drive **310** may include a combination of non-volatile memory (NVM) IC chips **250** and volatile memory chips. For example, referring to FIGS. **26**A-**26**C, some of the locations for mounting the NVMIC chips **250** may be changed for mounting the volatile memory chips, such as high speed, high bandwidth, wide bitwidth DRAM IC chips **321** or high speed, high bandwidth, wide bitwidth SRAM chips.

Interposer-to-Interposer Assembly for Logic and Memory Drives

Alternatively, FIGS. **35**A-**35**E are cross-sectional views showing various assemblies for COIP logic and memory drives in accordance with an embodiment of the present

application. Referring to FIGS. **35**A and **35**D, the COIP memory drive **310** may have the metal bumps **570** provided with the solder bumps **569** to be bonded respectively to the solder bumps **569** of the metal bumps **570** of the COIP logic drive **300** to form multiple bonded contacts **586** between the COIP memory and logic drives **310** and **300**. For example, one of the logic and memory drives **300** and **310** may be provided with the metal pillars or bumps **570** of the fourth type having the solder balls or bumps **569** as illustrated in FIG. **18**W, or the metal pillars or bumps **570** as illustrated in **19**T, to be bonded to the copper layer **568**, as seen in FIG. **18**U, of the metal pillars or bumps **570** of the first type of the other of the logic and memory drives **300** and **310** or to an exposed surface of the via **558**, as seen in FIG. **19**R, of the other of the logic and memory drives **300** and **310** so as to form the bonded contacts **586** between the memory and logic drives **310** and **300**.

For high speed, high bandwidth and wide bitwidth communications between one of the semiconductor chips **100**, e.g., non-volatile or volatile memory chip **250** or **324** as illustrated in FIGS. **34**A-**34**F, of the COIP memory drive **310** and one of the semiconductor chips **100**, e.g., FPGA IC chip **200** or PCIC chip **269** as illustrated in FIGS. **11**A-**11**N, of the COIP logic drive **300**, said one of the semiconductor chips **100** of the COIP memory drive **310** may be aligned with and positioned vertically over said one of the semiconductor chips **100** of the COIP logic drive **300**.

Referring to FIGS. **35**A and **35**D, the COIP memory drive **310** may include multiple first stacked portions provided by the vias **558** and interconnection metal layers **6** and/or **27** of its interposer **551**, wherein each of the first stacked portions may be aligned with and positioned vertically over one of the bonded contacts **586** and positioned between said one of its semiconductor chips **100** and said one of the bonded contacts **586**. Further, for the COIP memory drive **310**, multiple of its bonded contacts **563** may be aligned with and stacked on or over its first stacked portions respectively and positioned between said one of its semiconductor chips **100** and its first stacked portions to connect said one of its semiconductor chips **100** to its first stacked portions respectively.

Referring to FIGS. **35**A and **35**D, the COIP logic drive **300** may include multiple second stacked portions provided by the vias **558** and interconnection metal layers **6** and/or **27** of its interposer **551**, wherein each of the second stacked portions may be aligned with and stacked under or below one of the bonded contacts **586** and positioned between said one of its semiconductor chips **100** and said one of the bonded contacts **586**. Further, for the COIP logic drive **300**, multiple of its bonded contacts **563** may be aligned with and stacked under or below its second stacked portions respectively and positioned between said one of its semiconductor chips **100** and its second stacked portions to connect said one of its semiconductor chips **100** to its second stacked portions respectively.

Accordingly, referring to FIGS. **35**A and **35**D, from bottom to top, one of the bonded contacts **563** of the COIP logic drive **300**, one of the second stacked portions of the interposer **551** of the COIP logic drive **300**, one of the bonded contacts **586**, one of the first stacked portions of the interposer **551** of the COIP memory drive **310** and one of the bonded contacts **563** of the COIP memory drive **310** may be stacked together in a vertical direction to form a vertical stacked path **587** between said one of the semiconductor chips **100** of the COIP logic drive **300** and said one of the semiconductor chips **100** of the COIP memory drive **310** for signal transmission or power or ground delivery. In an aspect, a plurality of the vertical stacked path **587** having the number equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K, for example, may be connected between said one of the semiconductor chips **100** of the COIP logic drive **300** and said one of the semiconductor chips **100** of the COIP memory drive **310** for parallel signal transmission or power or ground delivery.

Referring to FIGS. **35**A and **35**D, said one of the semiconductor chips **100** of the COIP logic drive **300** may include the small I/O circuits **203** as seen in FIG. **5**B having the driving capability, loading, output capacitance or input capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, 0.01 pF and 2 pF or 0.01 pF and 1 pF, or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, 0.5 pF or 0.1 pF, each of which may couple to one of the vertical stacked paths **587** through one of its I/O pads **372**, and said one of the semiconductor chips **100** of the COIP memory drive **310** may include the small I/O circuits **203** as seen in FIG. **5**B having the driving capability, loading, output capacitance or input capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, 0.01 pF and 2 pF or 0.01 pF, each of which may couple to said one of the vertical stacked paths **587** through one of its I/O pads **372**. For example, each of the small I/O circuits **203** may be composed of the small ESD protection circuit **373**, small receiver **375**, and small driver **374**.

Referring to FIGS. **35**A and **35**D, each of the COIP logic and memory drives **300** and **310** may have the metal bumps **583** formed on the metal pads **77***e* of its BISD **79** for connecting said each of the COIP logic and memory drives **300** and **310** to an external circuitry. For each of the COIP logic and memory drives **300** and **310**, one of its metal bumps **583** may (1) couple to one of its semiconductor chips **100** through the interconnection metal layers **77** of its BISD **79**, one or more of its TPVs **582**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of its interposer **551** and one or more of its bonded contacts **563** in sequence, (2) couple to one of the semiconductor chips **100** of the other of the COIP logic and memory drives **300** and **310** through the interconnection metal layers **77** of its BISD **79**, one or more of its TPVs **582**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and FISIP **560** of its interposer **551**, one or more of the vias **558** of its interposer **551**, one or more of the bonded contacts **586**, one or more of the vias **558** of the interposer **551** of the other of the COIP logic and memory drives **300** and **310**, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **577** of the interposer **551** of the other of the COIP logic and memory drives **300** and **310**, and one or more of the bonded contacts **563** of the other of the COIP logic and memory drives **300** and **310** in sequence, or (3) couple to one of the metal bumps **583** of the other of the COIP logic and memory drives **300** and **310** through the interconnection metal layers **77** of its BISD **79**, one or more of its TPVs **582**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and FISIP **560** of its interposer **551**, one or more of the vias **558** of its interposer **551**, one or more of the bonded contacts **586**, one or more of the vias **558** of the interposer **551** of the other of the COIP logic and memory drives **300** and **310**, the interconnection metal layers **6** and/or **27** of the FISIP **560** and/or SISIP **588** of the interposer **551** of the other of the COIP logic and memory drives **300** and **310**, one or more of the TPVs **582** of the other of the COIP logic and memory drives **300** and **310**, and the interconnection metal layers **77** of the BISD **79** of the other of the COIP logic and memory drives **300** and **310** in sequence.

Alternatively, referring to FIGS. **35**B, **35**C and **35**E, their structures are similar to that shown in FIG. **35**A. For an

element indicated by the same reference number shown in FIGS. **35**A-**35**E, the specification of the element as seen in FIGS. **35**B, **35**C and **35**E may be referred to that of the element as illustrated in FIG. **35**A. The difference between the structures shown in FIGS. **35**A and **35**B is that the COIP memory drive **310** may not be provided with the metal bumps **583**, BISD **79** and TPVs **582** for external connection and each of the semiconductor chips **100** of the COIP memory drive **310** may have a backside exposed to the ambient of the COIP memory drive **310**. The difference between the structures shown in FIGS. **35**A and **35**C is that the COIP logic drive **300** may not be provided with the metal bumps **583**, BISD **79** and TPVs **582** for external connection and each of the semiconductor chips **100** of the COIP logic drive **300** may have a backside exposed to the ambient of the COIP logic drive **300**. The difference between the structures shown in FIGS. **35**A and **35**E is that the COIP logic drive **300** may not be provided with the metal bumps **583**, BISD **79** and TPVs **582** for external connection and each of the semiconductor chips **100** of the COIP logic drive **300** may have a backside joining a heat sink **316** made of copper or aluminum for example.

Referring to FIGS. **35**A-**35**E, for an example of parallel signal transmission, the vertical stacked paths **587** in parallel may be arranged between said one of the semiconductor chip **100**, e.g. graphic-procession-unit (GPU) chip as illustrated in FIGS. **11**F-**11**N, of the COIP logic drive **300** and one of the semiconductor chips **100**, e.g., high speed, high bandwidth, wide bitwidth cache SRAM chip, DRAM IC chip, or NVMIC chip for MRAM or RRAM as illustrated in FIGS. **34**A-**34**F, of the COIP memory drive **310** with a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. Alternatively, for an example of parallel signal transmission, the vertical stacked paths **587** in parallel may be arranged between one of the semiconductor chip **100**, e.g. tensor-procession-unit (TPU) chip as illustrated in FIGS. **11**F-**11**N, of the COIP logic drive **300** and one of the semiconductor chips **100**, e.g., high speed, high bandwidth, wide bitwidth cache SRAM chip, DRAM IC chip, or NVM chip for MRAM or RRAM as illustrated in FIGS. **34**A-**34**F, of the COIP memory drive **310** with a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

Alternatively, FIGS. **35**F and **35**G are cross-sectional views showing a COIP logic drive assembled with one or more memory IC chips in accordance with an embodiment of the present application. Referring to FIG. **35**F, each of one or more memory IC chips **317**, such as high speed, high bandwidth, wide bitwidth cache SRAM chip, DRAM IC chip, or NVM IC chip for MRAM or RRAM, may be provided with multiple electrical contacts, such as tin-containing bumps or pads or copper bumps or pads, on an active surface thereof to be bonded to the solder bumps **569** of the solder bumps **570** of the COIP logic drive **300** to form multiple bonded contacts **586** between the COIP logic drive **300** and said each of the one or more memory IC chips **317**. For an example, the COIP logic drive **300** may be provided with the metal pillars or bumps **570** of the fourth type having the solder balls or bumps **569** as illustrated in FIG. **18**W, or the metal pillars or bumps **570** as illustrated in **19**T, to be bonded to a copper layer of the electrical contacts of each of the memory IC chips **317** so as to form the bonded contacts **586** between the COIP logic drive **300** and said each of the memory IC chips **317**. For another example, the COIP logic drive **300** may be provided with the metal pillars or bumps **570** of the first type having the copper layer as illustrated in FIG. **18**U to be bonded to a tin-containing layer or bumps of the electrical contacts of each of the memory IC chips **317** so as to form the bonded contacts **586** between the COIP logic drive **300** and said each of the memory IC chips **317**. Next, an underfill **114**, such as polymer, may be filled into a gap between the COIP logic drive **300** and each of the memory IC chips **317**, covering a sidewall of each of the bonded contacts **586**.

For high speed, high bandwidth and wide bitwidth communications between one of the memory IC chips **317** and one of the semiconductor chips **100**, e.g., FPGA IC chip **200** or PCIC chip **269** as illustrated in FIGS. **11**A-**11**N, of the COIP logic drive **300**, said one of the memory IC chips **317** may be aligned with and positioned vertically over said one of the semiconductor chips **100** of the COIP logic drive **300**. Said one of the memory IC chips **317** may have a group of the electrical contacts aligned with and positioned vertically over the second stacked portions of the COIP logic drive **300** respectively for data or signal transmission or power/ground delivery between said one of the memory IC chips **317** and said one of the semiconductor chips **100** of the COIP logic drive **300**, wherein each of the second stacked portions is positioned between said one of the memory IC chips **317** and said one of the semiconductor chips **100** of the COIP logic drive **300**. Each of the memory IC chips **317** may have the group of the electrical contacts each positioned vertically over one of the second stacked portions and connected to said one of the second stacked portions through one of the bonded contacts **586** between said each of the electrical contacts in the group and said one of the second stacked portions. Thus, said each of the electrical contacts in the group, said one of the bonded contacts **586** and said one of the second stacked portions may be stacked together to form a stacked path **587**.

In an aspect, referring to FIG. **35**F, a plurality of the vertical stacked path **587** having the number equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K, for example, may be connected between said one of the semiconductor chips **100** of the COIP logic drive **300** and said one of the memory IC chips **317** for parallel signal transmission or power or ground delivery. In an aspect, said one of the semiconductor chips **100** of the COIP logic drive **300** may include the small I/O circuits **203** as seen in FIG. **5**B having the driving capability, loading, output capacitance or input capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, 0.01 pF and 2 pF or 0.01 pF and 1 pF, or smaller than 10 pF, 5 pF, 3 pF, 2 pF, 1 pF, 0.5 pF or 0.1 pF, each of which may couple to one of the vertical stacked paths **587** through one of its I/O pads **372**, and said one of the memory IC chips **317** may include the small I/O circuits **203** as seen in FIG. **5**B having the driving capability, loading, output capacitance or input capacitance between 0.01 pF and 10 pF, 0.05 pF and 5 pF, 0.01 pF and 2 pF or 0.01 pF, each of which may couple to said one of the vertical stacked paths **587** through one of its I/O pads **372**. For example, each of the small I/O circuits **203** may be composed of the small ESD protection circuit **373**, small receiver **375**, and small driver **374**.

Referring to FIG. **35**F, the COIP logic drive **300** may have the metal bumps **583** formed on the metal pads **77***e* of its BISD **79** for connecting the COIP logic drive **300** to an external circuitry. For the COIP logic drive **300**, one of its metal bumps **583** may (1) couple to one of its semiconductor chips **100** through the interconnection metal layers **77** of its BISD **79**, one or more of its TPVs **582**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of its interposer **551** and one or more of its bonded contacts **563** in sequence, or (2) couple to one of the memory IC chips **317** through the interconnection metal layers **77** of its BISD

79, one or more of its TPVs **582**, the interconnection metal layers **27** and/or **6** of the SISIP **588** and/or FISIP **560** of its interposer **551** and one or more of the bonded contacts **586** in sequence.

Alternatively, referring to FIG. **35**G, its structure is similar to that shown in FIG. **35**F. For an element indicated by the same reference number shown in FIGS. **35**F and **35**G, the specification of the element as seen in FIG. **35**G may be referred to that of the element as illustrated in FIG. **35**F. The difference between the structures shown in FIGS. **35**F and **35**G is that a polymer layer **318**, such as resin, is formed by molding to cover the memory IC chips **317**. Alternatively, the underfill **114** may be skipped and the polymer layer **318** may be further filled into a gap between the logic drive **300** and each of the memory IC chips **317**, covering a sidewall of each of the bonded contacts **586**.

Referring to FIGS. **35**F and **35**G, for an example of parallel signal transmission, the vertical stacked paths **587** in parallel may be arranged between said one of the semiconductor chip **100**, e.g. GPU chip as illustrated in FIGS. **11**F-**11**N, of the COIP logic drive **300** and one of the memory IC chips **317**, e.g., high speed, high bandwidth, wide bitwidth cache SRAM chip, DRAM IC chip, or NVM IC chip for MRAM or RRAM, with a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K. Alternatively, for an example of parallel signal transmission, the vertical stacked paths **587** in parallel may be arranged between one of the semiconductor chip **100**, e.g. tensor-procession-unit (TPU) chip as illustrated in FIGS. **11**F-**11**N, of the COIP logic drive **300** and one of the memory IC chips **317**, e.g., high speed, high bandwidth, wide bitwidth cache SRAM chip, DRAM IC chip, or NVM IC chip for MRAM or RRAM, with a data bit width of equal to or greater than 64, 128, 256, 512, 1024, 2048, 4096, 8K, or 16K.

Internet or Network Between Data Centers and Users

FIG. **36** is a block diagram illustrating networks between multiple data centers and multiple users in accordance with an embodiment of the present application. Referring to FIG. **36**, in the cloud **590** are multiple data centers **591** connected to each other or one another via the internet or networks **592**. In each of the data centers **591** may be a plurality of one of the above-mentioned standard commodity logic drives **300** and/or a plurality of one of the above-mentioned memory drives **310** allowed for one or more of user devices **593**, such as computers, smart phones or laptops, to offload and/or accelerate service-oriented functions of all or any combinations of functions of artificial intelligence (AI), machine learning, deep learning, big data, internet of things (TOT), industry computing, virtual reality (VR), augmented reality (AR), car electronics, graphic processing (GP), video streaming, digital signal processing (DSP), micro controlling (MC), and/or central processing (CP) when said one or more of the user devices **593** is connected via the internet or networks to the standard commodity logic drives **300** and/or memory drives **310** in one of the data centers **591** in the cloud **590**. In each of the data centers **591**, the standard commodity logic drives **300** may couple to each other or one another via local circuits of said each of the data centers **591** and/or the internet or networks **592** and to the memory drives **310** via local circuits of said each of the data centers **591** and/or the Internet or networks **592**, wherein the memory drives **310** may couple to each other or one another via local circuits of said each of the data centers **591** and/or the internet or networks **592**. Accordingly, the standard commodity logic drives **300** and memory drives **310** in the data centers **591** in the cloud **590** may be used as an infrastructure-as-a-service (IaaS) resource for the user devices **593**. Similarly to renting virtual memories (VMs) in a cloud, the field programmable gate arrays (FPGAs), which may be considered as virtual logics (VL), may be rented by users. In a case, each of the standard commodity logic drives **300** in one or more of the data centers **591** may include the FPGA IC chips **200** fabricated using a semiconductor IC process technology node more advanced than 28 nm technology node. A software program may be written on the user devices **593** in a common programing language, such as Java, C++, C#, Scala, Swift, Matlab, Assembly Language, Pascal, Python, Visual Basic, PL/SQL or JavaScript language. The software program may be uploaded by one of the user devices **590** via the internet or networks **592** to the cloud **590** to program the standard commodity logic drives **300** in the data centers **591** or cloud **590**. The programmed logic drives **300** in the cloud **590** may be used by said one or another of the user devices **593** for an application via the internet or networks **592**.

CONCLUSION AND ADVANTAGES

Accordingly, the current logic ASIC or COIP IC chip business may be changed into a commodity logic IC chip business, like the current commodity DRAM, or commodity flash memory IC chip business, by using the standard commodity logic drive **300**. Since the performance, power consumption, and engineering and manufacturing costs of the standard commodity logic drive **300** may be better or equal to that of the ASIC or COIP IC chip for a same innovation or application, the standard commodity logic drive **300** may be used as an alternative for designing an ASIC or COIP IC chip. The current logic ASIC or COIP IC chip design, manufacturing and/or product companies (including fabless IC design and product companies, IC foundry or contracted manufactures (may be product-less), and/or vertically-integrated IC design, manufacturing and product companies) may become companies like the current commodity DRAM, or flash memory IC chip design, manufacturing, and/or product companies; or like the current DRAM module design, manufacturing, and/or product companies; or like the current flash memory module, flash USB stick or drive, or flash solid-state drive or disk drive design, manufacturing, and/or product companies. The current logic ASIC or COIP IC chip design and/or manufacturing companies (including fabless IC design and product companies, IC foundry or contracted manufactures (may be product-less), vertically-integrated IC design, manufacturing and product companies) may become companies in the following business models: (1) designing, manufacturing, and/or selling the standard commodity FPGA IC chips **200**; and/or (2) designing, manufacture, and/or selling the standard commodity logic drives **300**. A person, user, customer, or software developer, or application developer may purchase the standard commodity logic drive **300** and write software codes to program them for his/her desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP). The logic drive **300** may be programed to perform functions like a graphic chip, or a baseband chip, or an Ethernet chip, or a wireless (for example, 802.11ac) chip, or an AI chip. The logic drive **300** may be alternatively programmed to perform functions of all or any combinations of functions of Artificial Intelli-

gence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

The disclosure provides a standard commodity logic drive in a multi-chip package comprising plural FPGA IC chips and one or more non-volatile memory IC chips for use in different applications requiring logic, computing and/or processing functions by field programming. Uses of the standard commodity logic drive is analogues to uses of a standard commodity data storage solid-state disk (drive), data storage hard disk (drive), data storage floppy disk, Universal Serial Bus (USB) flash drive, USB drive, USB stick, flash-disk, or USB memory, and differs in that the latter has memory functions for data storage, while the former has logic functions for processing and/or computing.

For another aspect, in accordance with the disclosure, the standard commodity logic drive may be arranged in a hot-pluggable device to be inserted into and couple to a host device in a power-on mode such that the logic drive in the hot-pluggable device may operate with the host device.

For another aspect, the disclosure provides the method to reduce Non-Recurring Engineering (NRE) expenses for implementing an innovation or an application in semiconductor IC chips or to accelerate workload processing by using the standard commodity logic drive. A person, user, or developer with an innovation or an application concept or idea or an aim for accelerating workload processing needs to purchase the standard commodity logic drive and develops or writes software codes or programs to load into the standard commodity logic drive to implement his/her innovation or application concept or idea. Compared to the implementation by developing a logic ASIC or COIP IC chip, the NRE cost may be reduced by a factor of larger than 2, 5, or 10. For advanced semiconductor technology nodes or generations (for example more advanced than or below 30 nm or 20 nm), the NRE cost for designing an ASIC or COIP chip increases greatly, more than US $5M, US $10M or even exceeding US $20M, US $50M, or US $100M. The cost of a photo mask set for an ASIC or COIP chip at the 16 nm technology node or generation may be over US $2M, US$5M, or US $10M. Implementing the same or similar innovation or application using the logic drive may reduce the NRE cost down to smaller than US $10M or even less than US $7M, US $5M, US $3M or US $1M. The aspect of the disclosure inspires the innovation and lowers the barrier for implementing the innovation in IC chips designed and fabricated using an advanced IC technology node or generation, for example, a technology node or generation more advanced than or below 30 nm, 20 nm or 10 nm.

For another aspect, the disclosure provides the method to change the current logic ASIC or COIP IC chip business into a commodity logic IC chip business, like the current commodity DRAM, or commodity flash memory IC chip business, by using the standardized commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standardized commodity logic drive may be better or equal to that of the ASIC or COIP IC chip for a same innovation or application or an aim for accelerating workload processing, the standardized commodity logic drive may be used as an alternative for designing an ASIC or COIP IC chip. The current logic ASIC or COIP IC chip design, manufacturing and/or product companies (including fabless IC design and product companies, IC foundry or contracted manufactures (may be product-less), and/or vertically-integrated IC design, manufacturing and product companies) may become companies like the current commodity DRAM, or flash memory IC chip design, manufacturing, and/or product companies; or like the current DRAM module design, manufacturing, and/or product companies; or like the current flash memory module, flash USB stick or drive, or flash solid-state drive or disk drive design, manufacturing, and/or product companies. The current logic ASIC or COIP IC chip design and/or manufacturing companies (including fabless IC design and product companies, IC foundry or contracted manufactures (may be product-less), vertically-integrated IC design, manufacturing and product companies) may become companies in the following business models: (1) designing, manufacturing, and/or selling the standard commodity FPGA IC chips; and/or (2) designing, manufacture, and/or selling the standard commodity logic drives. A person, user, customer, or software developer, or application developer may purchase the standardized commodity logic drive and write software codes to program them for his/her desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP). The logic drive may be programed to perform functions like a graphic chip, or a baseband chip, or an Ethernet chip, or a wireless (for example, 802.11ac) chip, or an AI chip. The logic drive may be alternatively programmed to perform functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP).

For another aspect, the disclosure provides the method to change the logic ASIC or COIP IC chip hardware business into a software business by using the standard commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standard commodity logic drive may be better or equal to that of the ASIC or COIP IC chip for a same innovation or application or an aim for accelerating workload processing, the current ASIC or COIP IC chip design companies or suppliers may become software developers or suppliers; they may adapt the following business models: (1) become software companies to develop and sell software for their innovation or application, and let theft customers to install software in the customers' own standard commodity logic drive; and/or (2) still hardware companies by selling hardware without performing ASIC or COIP IC chip design and production. They may install their in-house developed software for the innovation or application in the non-volatile memory chips in the purchased standard commodity logic drive; and sell the program-installed logic drive to their customers. They may write software codes into the standard commodity logic drive (that is, loading the software codes in the non-volatile memory IC chip or chips in or of the standard commodity logic drive) for their desired applications, for example, in applications of Artificial Intelligence (AI), machine learning, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), Graphic Processing, Digital Signal Processing, micro controlling, and/or Central Processing. A design, manufacturing, and/or product companies for a system, computer, processor, smart-phone, or electronic equipment or device may become companies to (1) design, manufacture and/or sell the standard commodity

hardware comprising the memory drive and the logic drive; in this case, the companies are still hardware companies; (2) develop system and application software for users to install in the users' own standard commodity hardware; in this case, the companies become software companies; (3) install the third party's developed system and application software or programs in the standard commodity hardware and sell the software-loaded hardware; and in this case, the companies are still hardware companies.

For another aspect, the disclosure provides the method to change the current logic ASIC or COIP IC chip hardware business into a network business by using the standardized commodity logic drive. Since the performance, power consumption, and engineering and manufacturing costs of the standardized commodity logic drive may be better or equal to that of the ASIC or COIP IC chip for a same innovation or application or an aim for accelerating workload processing, the standardized commodity logic drive may be used as an alternative for designing an ASIC or COIP IC chip. The commodity logic drive comprising standard commodity FPGA chips may be used in a datacenter or cloud in networks for innovation or application or an aim for accelerating workload processing. The commodity logic drive attached to the networks may serve to offload and accelerate service-oriented functions of all or any combinations of functions of Artificial Intelligence (AI), machine learning, deep learning, big data, Internet Of Things (IOT), industry computing, Virtual Reality (VR), Augmented Reality (AR), car electronics, Graphic Processing (GP), Video Streaming, Digital Signal Processing (DSP), Micro Controlling (MC), and/or Central Processing (CP). The commodity logic drive used in the data center or cloud in the networks offers FPGAs as an IaaS resource to cloud users. Using the commodity logic drive in the data center or cloud, users can rent FPGAs, similarly to renting Virtual Memories (VMs) in the cloud. The commodity logic drive used in the data center or cloud is the Virtual Logics (VLs) just like Virtual Memories (VMs).

For another aspect, the disclosure provides a development kit or tool for a user or developer to implement an innovation or an application using the standard commodity logic drive. The user or developer with innovation or application concept or idea may purchase the standard commodity logic drive and use the corresponding development kit or tool to develop or to write software codes or programs to load into the non-volatile memory of the standard commodity logic drive for implementing his/her innovation or application concept or idea.

For another aspect, the disclosure provides a "public innovation platform" for innovators to easily and cheaply implement or realize their innovation in semiconductor IC chips using advanced IC technology nodes more advanced than 28 nm, for example, 20 nm, 16 nm, 10 nm, 7 nm, 5 nm or 3 nm IC technology nodes. In early days, 1990's, innovators could implement their innovation by designing IC chips and fabricate the IC chips in a semiconductor foundry fab using technology nodes at 1 um, 0.8 um, 0.5 um, 0.35 um, 0.18 um or 0.13 um, at a cost of about several hundred thousands of US dollars. The IC foundry fab was then the "public innovation platform". However, when IC technology nodes migrate to a technology node more advanced than 28 nm, for example, 20 nm, 16 nm, 10 nm, 7 nm, 5 nm or 3 nm IC technology nodes, only a few giant system or IC design companies, not the public innovators, can afford to use the semiconductor IC foundry fab. It costs about or over 10 million US dollars to develop and implement an IC chip using these advanced technology nodes. The semiconductor IC foundry fab is now not "public innovation platform" anymore, they are "club innovation platform" for club innovators. The concept of the disclosed logic drives, comprising standard commodity FPGA IC chips, provides public innovators "public innovation platform" back to semiconductor IC industry again; just as in 1990's. The innovators can implement or realize their innovation by using logic drives and writing software programs in common programing languages, for example, C, Java, C++, C#, Scala, Swift, Matlab, Assembly Language, Pascal, Python, Visual Basic, PL/SQL or JavaScript languages, at cost of less than 500K or 300K US dollars. The innovators can use their own commodity logic drives or they can rent logic drives in data centers or clouds through networks.

The components, steps, features, benefits and advantages that have been discussed are merely illustrative. None of them, nor the discussions relating to them, are intended to limit the scope of protection in any way. Numerous other embodiments are also contemplated. These include embodiments that have fewer, additional, and/or different components, steps, features, benefits and advantages. These also include embodiments in which the components and/or steps are arranged and/or ordered differently.

Unless otherwise stated, all measurements, values, ratings, positions, magnitudes, sizes, and other specifications that are set forth in this specification, including in the claims that follow, are approximate, not exact. They are intended to have a reasonable range that is consistent with the functions to which they relate and with what is customary in the art to which they pertain. Furthermore, unless stated otherwise, the numerical ranges provided are intended to be inclusive of the stated lower and upper values. Moreover, unless stated otherwise, all material selections and numerical values are representative of preferred embodiments and other ranges and/or materials may be used.

The scope of protection is limited solely by the claims, and such scope is intended and should be interpreted to be as broad as is consistent with the ordinary meaning of the language that is used in the claims when interpreted in light of this specification and the prosecution history that follows, and to encompass all structural and functional equivalents thereof.

What is claimed is:

1. A chip package comprising:

an interposer comprising a silicon substrate, a plurality of metal vias passing through the silicon substrate, and a first interconnection scheme over the silicon substrate, wherein the first interconnection scheme comprises a first interconnection metal layer over the silicon substrate, a second interconnection metal layer over the silicon substrate and the first interconnection metal layer, and a first insulating dielectric layer over the silicon substrate and between the first and second interconnection metal layers;

a semiconductor integrated-circuit (IC) chip over the interposer, wherein the semiconductor integrated-circuit (IC) chip is configured to perform a function, comprising a static-random-access-memory (SRAM) cell for storing a first data therein, a selection circuit comprising a first set of input points for a first input data set having data associated with the first data stored in the static-random-access-memory (SRAM) cell, and a plurality of programmable interconnects coupling respectively to a second set of input points of the selection circuit for a second input data set of the selection circuit, wherein the selection circuit is configured to select, in accordance with the first input data

set, an input data from the second input data set as an output data at an output point of the selection circuit, wherein the semiconductor integrated-circuit (IC) chip comprises a first input/output (I/O) circuit coupling to the first interconnection scheme, wherein the first input/output (I/O) circuit has a driving capability smaller than 2 pF;

a first metal bump between the interposer and the semiconductor integrated-circuit (IC) chip, wherein the first metal bump couples the semiconductor integrated-circuit (IC) chip to the first interconnection scheme; and

a non-volatile memory (NVM) integrated-circuit (IC) chip over the interposer, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip couples to the semiconductor integrated-circuit (IC) chip, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip is used to store a second data therein for configuring the function of the semiconductor integrated-circuit (IC) chip, wherein the first data is associated with the second data.

2. The chip package of claim **1**, wherein the first metal bump comprises a copper layer having a thickness between 3 and 60 micrometers between the interposer and the semiconductor integrated-circuit (IC) chip.

3. The chip package of claim **2**, wherein the first metal bump comprises a solder layer between the copper layer and the interposer.

4. The chip package of claim **1** further comprising a polymer layer between the semiconductor integrated-circuit (IC) chip and non-volatile memory (NVM) integrated-circuit (IC) chip, wherein the polymer layer has a top surface coplanar to a top surface of the semiconductor integrated-circuit (IC) chip and a top surface of the non-volatile memory (NVM) integrated-circuit (IC) chip.

5. The chip package of claim **4** further comprising a through polymer via in the polymer layer, on the interposer and between the semiconductor integrated-circuit (IC) chip and non-volatile memory (NVM) integrated-circuit (IC) chip, wherein the through polymer via has a top surface coplanar to the top surface of the polymer layer, wherein the through polymer via extends vertically through the polymer layer.

6. The chip package of claim **5**, wherein the through polymer via comprises a copper layer having a thickness between 5 and 300 micrometers, wherein the copper layer has a top surface coplanar to the top surface of the polymer layer.

7. The chip package of claim **1** further comprising a central-processing-unit (CPU) chip over the interposer, and a second metal bump between the interposer and the central-processing-unit (CPU) chip, wherein the second metal bump couples the central-processing-unit (CPU) chip to the first interconnection scheme.

8. The chip package of claim **1** further comprising a graphic-processing-unit (GPU) chip over the interposer, and a second metal bump between the interposer and the graphic-processing-unit (GPU) chip, wherein the second metal bump couples the graphic-processing-unit (GPU) chip to the first interconnection scheme.

9. The chip package of claim **1** further comprising an underfill between the interposer and the semiconductor integrated-circuit (IC) chip, wherein the underfill encloses the first metal bump.

10. The chip package of claim **1** further comprising a second metal bump between the interposer and the non-volatile memory (NVM) integrated-circuit (IC) chip, wherein the second metal bump couples the non-volatile memory (NVM) integrated-circuit (IC) chip to the first interconnection scheme, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip couples to the semiconductor integrated-circuit (IC) chip through, in sequence, the second metal bump, first interconnection scheme and first metal bump.

11. The chip package of claim **1** further comprising an input/output (I/O) chip over the interposer, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip is coupled to the semiconductor integrated-circuit (IC) chip through the input/output (I/O) chip.

12. The chip package of claim **11**, wherein a data bit width between the semiconductor integrated-circuit (IC) chip and input/output (I/O) chip is greater than a data bit width between the non-volatile memory (NVM) integrated-circuit (IC) chip and input/output (I/O) chip.

13. The chip package of claim **11**, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip has a second input/output (I/O) circuit coupling to a third input/output (I/O) circuit of the input/output (I/O) chip, wherein each of the second and third input/output (I/O) circuits has a driving capability greater than 2 pF.

14. The chip package of claim **1** further comprising a second interconnection scheme over the semiconductor integrated-circuit (IC) chip and non-volatile memory (NVM) integrated-circuit (IC) chip and across over an edge of the semiconductor integrated-circuit (IC) chip and an edge of the non-volatile memory (NVM) integrated-circuit (IC) chip, wherein the second interconnection scheme comprises a third interconnection metal layer over the semiconductor integrated-circuit (IC) chip and the non-volatile memory (NVM) integrated-circuit (IC) chip, a fourth interconnection metal layer over the third interconnection metal layer and a second insulating dielectric layer between the third and fourth interconnection metal layers.

15. The chip package of claim **14**, wherein the third interconnection metal layer comprises a copper layer having a thickness between 3 and 20 micrometers.

16. The chip package of claim **1**, wherein the non-volatile memory (NVM) integrated-circuit (IC) chip comprises is a flash chip.

17. The chip package of claim **1**, wherein the first insulating dielectric layer comprises a polymer layer having a thickness greater than or equal to 3 micrometers, and the second interconnection metal layer comprises a metal line having a thickness between 2 and 10 micrometers, wherein the metal line comprises a copper layer and an adhesion layer at a bottom of the copper layer but not at a sidewall of the copper layer.

18. The chip package of claim **1**, wherein the first insulating dielectric layer comprises silicon and has a thickness between 10 and 2,000 nanometers, and the first interconnection metal layer comprises a metal line having a thickness between 10 and 2,000 nanometers, wherein the metal line comprises a copper layer and an adhesion layer at a bottom of the copper layer and a sidewall of the copper layer.

19. The chip package of claim **1**, wherein the semiconductor integrated-circuit (IC) chip is a field-programmable-gate-array (FPGA) integrated-circuit (IC) chip.

20. The chip package of claim **1**, wherein the first input/output (I/O) circuit has a driving capability smaller than 1 pF.

* * * * *